

Service Manual

LG-P895

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1. INTRODUCTION

1.1 Purpose

This manual provides the information necessary to repair, calibration, description and download the features of this model.

1.2 Regulatory Information

A. Security

Toll fraud, the unauthorized use of telecommunications system by an unauthorized part (for example, persons other than your company's employees, agents, subcontractors, or person working on your company's behalf) can result in substantial additional charges for your telecommunications services. System users are responsible for the security of own system. There are may be risks of toll fraud associated with your telecommunications system. System users are responsible for programming and configuring the equipment to prevent unauthorized use. The manufacturer does not warrant that this product is immune from the above case but will prevent unauthorized use of commoncarrier telecommunication service of facilities accessed through or connected to it. The manufacturer will not be responsible for any charges that result from such unauthorized use.

B. Incidence of Harm

If a telephone company determines that the equipment provided to customer is faulty and possibly causing harm or interruption in service to the telephone network, it should disconnect telephone service until repair can be done. A telephone company may temporarily disconnect service as long as repair is not done.

C. Changes in Service

A local telephone company may make changes in its communications facilities or procedure. If these changes could reasonably be expected to affect the use of the phones or compatibility with the net work, the telephone company is required to give advanced written notice to the user, allowing the user to take appropriate steps to maintain telephone service.

D. Maintenance Limitations

Maintenance limitations on the phones must be performed only by the manufacturer or its authorized agent. The user may not make any changes and/or repairs except as specifically noted in this manual. Therefore, note that unauthorized alternations or repair may affect the regulatory status of the system and may void any remaining warranty.

E. Notice of Radiated Emissions

This model complies with rules regarding radiation and radio frequency emission as defined by local regulatory agencies. In accordance with these agencies, you may be required to provide information such as the following to the end user.

F. Pictures


The pictures in this manual are for illustrative purposes only; your actual hardware may look slightly different.

G. Interference and Attenuation

A phone may interfere with sensitive laboratory equipment, medical equipment, etc. Interference from unsuppressed engines or electric motors may cause problems.

H. Electrostatic Sensitive Devices

ATTENTION

Boards, which contain Electrostatic Sensitive Device (ESD), are indicated by the  sign. Following information is ESD handling:

- Service personnel should ground themselves by using a wrist strap when exchange system boards.
- When repairs are made to a system board, they should spread the floor with anti-static mat which is also grounded.
- Use a suitable, grounded soldering iron.
- Keep sensitive parts in these protective packages until these are used.
- When returning system boards or parts like EEPROM to the factory, use the protective package as described.

1.3 Abbreviations

For the purposes of this manual, following abbreviations apply:

APC	Automatic Power Control
BB	Baseband
BER	Bit Error Ratio
CC-CV	Constant Current – Constant Voltage
DAC	Digital to Analog Converter
DCS	Digital Communication System
dBm	dB relative to 1 milli watt
DSP	Digital Signal Processing
EEPROM	Electrical Erasable Programmable Read-Only Memory
ESD	Electrostatic Discharge
FPCB	Flexible Printed Circuit Board
GMSK	Gaussian Minimum Shift Keying
GPIO	General Purpose Interface Bus
GSM	Global System for Mobile Communications
IPUI	International Portable User Identity
IF	Intermediate Frequency
LCD	Liquid Crystal Display
LDO	Low Drop Output
LED	Light Emitting Diode
OPLL	Offset Phase Locked Loop

1. INTRODUCTION

PAM	Power Amplifier Module
PCB	Printed Circuit Board
PGA	Programmable Gain Amplifier
PLL	Phase Locked Loop
PSTN	Public Switched Telephone Network
RF	Radio Frequency
RLR	Receiving Loudness Rating
RMS	Root Mean Square
RTC	Real Time Clock
SAW	Surface Acoustic Wave
SIM	Subscriber Identity Module
SLR	Sending Loudness Rating
SRAM	Static Random Access Memory
PSRAM	Pseudo SRAM
STMR	Side Tone Masking Rating
TA	Travel Adapter
TDD	Time Division Duplex
TDMA	Time Division Multiple Access
UART	Universal Asynchronous Receiver/Transmitter
VCO	Voltage Controlled Oscillator
VCTCXO	Voltage Control Temperature Compensated Crystal Oscillator
WAP	Wireless Application Protocol

2. PERFORMANCE

2.1 Product Name

LG-P895 : WCDMA 850/900/1900/2100+GSM850/EGSM/DCS/PCS

(HSUPA 5.8Mbps(cat6)/HSDPA 21Mbps(cat14)/GPRS Class33/EDGE Class33)

2.2 Supporting Standard

Item	Feature	Comment
Supporting Standard	WCDMA(FDD1,2,5,8)/EGSM/GSM850/DCS1800/PCS1900 with seamless handover Phase 2+(include AMR) SIM Toolkit : Class 1, 2, 3, C-E	
Frequency Range	WCDMA(FDD1) TX : 1920 – 1980 MHz WCDMA(FDD1) RX : 2110 – 2170 MHz WCDMA(FDD2) TX : 1850 – 1910 MHz WCDMA(FDD2) RX : 1930 – 1990 MHz WCDMA(FDD5) TX : 824 – 849 MHz WCDMA(FDD5) RX : 869 – 894 MHz WCDMA(FDD8) TX : 880 – 915 MHz WCDMA(FDD8) RX : 925 – 960 MHz EGSM TX : 880 – 915 MHz EGSM RX : 925 – 960 MHz GSM850 TX : 824 – 849 MHz GSM850 RX : 869 – 894 MHz GSM900 TX : 880 – 915 MHz GSM900 RX : 925 – 960 MHz DCS1800 TX : 1710 – 1785 MHz DCS1800 RX : 1805 – 1880 MHz PCS1900 TX : 1850 – 1910 MHz PCS1900 RX : 1930 – 1990 MHz	
Application Standard		

2.3 Main Parts : GSM Solution

Item	Part Name	Comment
AP Chip	AP 33 : NVIDIA	
CP Chip	XMM6260 : IMC	

2.4 HW Features

Item		Feature	Comment
Form Factor		DOP type	
Battery	1) Capacity Standard : Li-Ion Polymer, 2080mAh		
	2) Packing Type : Inner Pack		
Size		Standard : 139.6 x 90.4 x 8.5 (unit : mm)	
Weight		170 g - Check	with Battery
PCB		L1F3, 12 Layers , 0.8t	
Stand by time		2G Up to 460 hrs - Check 3G Up to 460 hrs - Check	@ Paging Period 5 (2G) @ DRX 7 (3G)
Charging time		3 hrs 30min	@ Power Off / 2150mAh
Talk time		2G Up to 7 hrs 3G Up to 8 hrs	@ Tx=Max(2G) @ Tx = 12dBm (3G)
RX sensitivity		WCDMA(FDD1) : -106.7 dBm WCDMA(FDD2) : -106.7 dBm WCDMA(FDD5) : -106.7 dBm WCDMA(FDD8) : -106.7 dBm EGSM : -105 dBm GSM850 : -105 dBm DCS 1800 : -105 dBm PCS 1900 : -105 dBm	
TX output power		WCDMA/ GSM/ GPRS	WCDMA : 24dBm/3.84MHz,+1/-3dBm EGSM : 33dBm GSM850 : 33 dBm DCS 1800 : 30 dBm PCS 1900 : 30 dBm
GPRS compatibility	EDGE	EGSM : 26 dBm GSM850 : 26 dBm DCS 1800 : 25 dBm PCS 1900 : 25 dBm	Class3(WCDMA) Class4 (EGSM) Class4 (GSM850) Class1 (PCS) Class1 (DCS)
	GPRS Class 33		E2 (GSM900) E2 (PCS) E2 (DCS)
EDGE compatibility		EDGE Class 12	
SIM card type		Micro SIM 2.85V /1.8V	

2. PERFORMANCE

Display	Main LCD (HD) TFT Main LCD(5.0", 1024X768)	
Built-in Camera	8M Camera, 1.3M secondary	8M: Sensor) Sony Module) LGIT 1.3M: Sensor) Aptina Module) LGIT
Status Indicator	No	
Keypad	Function Key : 4 Side Key : 4	Function Key : Back, Home, menu, recent application key Side Key : Volume up, down, power key, mode key
ANT	Main : LDS(Laser Direct Structure) type Sub : FPCB type Antenna NFC : Attached Battery cover	
System connector	5 Pin Micro USB	2.0 HS
Ear Phone Jack	3.5Phi, 4 Pole, Stereo	
PC synchronization	Yes	
Memory(AP)	eMMC : 32GB LP-DDR2 : 8Gb	
Speech coding	FR, EFR, HR, AMR,AMR-WB	
Data & Fax	Built in Data & Fax support	
Vibrator	Built in Vibrator	
BlueTooth	V4.0 BLE (BT Low Energy)	
MIDI(for Buzzer Function)	72 Poly, MP3 Ringtone	
Music Player	MP3/WMA/AAC/AAC+/WAV/AC3/ SP- MIDI	
Video Player	MPEG4, H.263, H.264 @ 1080p 30fps/ Divx HD	
Camcorder	MPEG4, H.264, H.263 @ 1080p 30pfs	
Voice Recording	Yes	
Speaker Phone mode Support	Yes	
Travel Adapter	Yes	
CDROM	No	
Stereo Headset	Yes	
Data Cable	Yes	
T-Flash (External Memory)	No	

2.5 SW Features

Item	Feature	Comment
RSSI	0 ~ 5 Levels	
Battery Charging	0 ~ 21 Levels	Android 4.0 (ICS)
Key Volume	0 ~ 7 Level	
Audio Volume	1 ~ 15 Level	
Time / Date Display	Yes	
Multi-Language	Yes	English, Espanol, Franch, Korea, Chinese, etc
Quick Access Mode	Phone / Space / Browser / Menu	
PC Sync	Yes	LG PC Suite
Speed Dial	Yes	Voice mail center -> 1 key
Profile	Yes	not same with feature phone setting
CLIP / CLIR	Yes	
Phone Book	Name / Number / Email / Chat Id / Website / Postal addresses / Organizations / Groups / BirthdayNotes / Ringtone	There is no limitation on the number of items. It depends on available memory amount.
Last Received Number	Yes	There is no limitation on the number of items. It depends on available memory amount.
Last Missed Number	Yes	There is no limitation on the number of items. It depends on available memory amount.
Search by Number / Name	Name / Number	
Group	Yes	There is no limitation on the number of items. It depends on available memory amount.
Fixed Dial Number	Yes	
Service Dial Number	No	
Own Number	Yes	Read only (add/edit/delete are not supported)
Voice Memo	Yes	Support voice recorder
Call Reminder	No	Missed call popup
Network Selection	Automatic	
Mute	Yes	
Call Divert	Yes	

2. PERFORMANCE

Call Barring	Yes	
Call Charge (AoC)	Yes	
Call Duration	Yes	
SMS (EMS)	There is no limitation on the number of items. It depends on available memory amount.	EMS does not support.
SMS Over GPRS	No	
EMS Melody / Picture Send / Receive / Save	No	
MMS MPEG4 Send / Receive / Save	Yes	
Long Message	MAX 765 characters	SMS 5 concatenated
Cell Broadcast	Yes	
Download	Yes	Web Download
Game	No	
Calendar	Yes	
Memo	Yes	There is no limitation on the number of items. It depends on available memory amount.
World Clock	Yes	
Unit Convert	No	
Stop Watch	Yes	
Wall Paper	Yes	
WAP Browser	No	WAP stack and wml are not supported.
Download Melody / Wallpaper	Yes	Over web browser
SIM Lock	Yes	Operator Dependent
SIM Toolkit	Class 1, 2, 3, C, E	
MMS	Yes	
EONS	Yes	
CPHS	Yes	V4.2
ENS	Yes	
Camera	Yes	8M AF / Digital Zoom : x8
JAVA	No	Android do not support JAVA
Voice Dial	No	
IrDa	No	
Bluetooth	Yes	Ver. 4.0 BLE (GAP, A2DP, AVRCP, DUN, FTP, GAVDP, GOEP, HFP, HSP, OPP, SDAP, SPP)

2. PERFORMANCE

FM radio	No	
GPRS	Yes	Class 33
EDGE	Yes	Class 33
Hold / Retrieve	Yes	
Conference Call	Yes	Max. 7
DTMF	Yes	
Memo pad	Yes	Rich Note
TTY	Yes	
AMR	Yes	
SyncML	Yes	
IM	Yes	Gtalk
Email	Yes	

2.6 . HW SPEC

1) GSM transceiver specification

Item	Specification
Phase Error	Rms : 5° Peak : 20 °
Frequency Error	GSM : 0.1 ppm DCS / PCS : 0.1 ppm
EMC (Radiated Spurious Emission Disturbance)	GSM/DCS : < -28dBm
Transmitter Output power	GSM850, EGSM : 5dBm ~ 33dBm ± 3dB DCS/PCS : 0dBm ~ 30dBm ± 3dB
Burst Timing	< 3.69us
Spectrum due to modulation out to less than 1800kHz offset	200kHz : -36dBm 600kHz : -51dBm/-56dBm
Spectrum due to modulation out to larger than 1800kHz offset to the edge of the transmit band	GSM850, EGSM : 1800-3000kHz : < -63dBc(-46dBm) 3000kHz-6000kHz : < -65dBc(-46dBm) 6000kHz < : < -71dBc(-46dBm) DCS, PCS : 1800-3000kHz : < -65dBc(-51dBm) 6000kHz < : < -73dBc(-51dBm)
Spectrum due to switching transient	400kHz : -19dBm/-22dBm(5/0), -23dBm 600kHz : -21dBm/-24dBm(5/0), -26dBm
Reference Sensitivity – TCH/FS	Class II(RBER) : -105dBm(2.439%)
Usable receiver input level range	0.012(-15 ~ -40dBm)
Intermodulation rejection – Speech channels	± 800kHz, ± 1600kHz : -98dBm / -96dBm (2.439%)
AM Suppression – GSM : -31dBm – DCS : -29dBm	-98dBm/-96dBm (2.439%)
Timing Advance	± 0.5T

2) WCDMA transmitter specification

Item	Specification
Transmit Frequency	BD1: 1920MHz ~ 1980 MHz BD2: 1850~1910 MHz BD5: 824 MHz ~849 MHz BD8: 880 MHz ~960 MHz
Maximum Output Power	+24 dBm / 3.84 MHz, +1 / -3 dB
Frequency Error	within ± 0.1 PPM
Open Loop Power Control	Normal Conditions : within ± 9 dB, Extreme Conditions : within ± 12 dB
Minimum Transmit Power	< -50 dBm / 3.84 MHz
Occupied Bandwidth	< 5 MHz at 3.84 Mcps (99% of power)
Adjacent Channel Leakage Power Ratio (ACLR)	> 33 dB @ ± 5 MHz, > 43 dB @ ± 10 MHz
Spurious Emissions $ f-f_c > 12.5$ MHz	< -36 dBm / 1 kHz RW @ $9 \text{ kHz} \leq f < 150 \text{ kHz}$ < -36 dBm / 10 kHz RW @ $150 \text{ kHz} \leq f < 30 \text{ MHz}$ < -36 dBm / 100 kHz RW @ $30 \text{ MHz} \leq f < 1 \text{ GHz}$ < -30 dBm / 1 MHz RW @ $1 \text{ GHz} \leq f < 12.75 \text{ GHz}$ < -60 dBm / 3.84 MHz RW @ $869 \text{ MHz} \leq f \leq 894 \text{ MHz}$ < -60 dBm / 3.84 MHz RW @ $1930 \text{ MHz} \leq f \leq 1900 \text{ MHz}$ < -60 dBm / 3.84 MHz RW @ $2110 \text{ MHz} \leq f \leq 2155 \text{ MHz}$ < -67 dBm / 100 kHz RW @ $925 \text{ MHz} \leq f \leq 935 \text{ MHz}$ < -79 dBm / 100 kHz RW @ $935 \text{ MHz} < f \leq 960 \text{ GHz}$ < -71 dBm / 100 kHz RW @ $1805 \text{ MHz} \leq f \leq 1880 \text{ MHz}$ < -41 dBm / 300 kHz RW @ $1884.5 \text{ MHz} < f < 1919.6 \text{ MHz}$
Transmit Intermodulation	< -31 dBc @ 5 MHz & < -41 dBc @ 10 MHz when Interference CW Signal Level = -40 dBc
Error Vector Magnitude	< 17.5 %, when $P_{out} \geq -20$ dBm
Peak Code Domain Error	< -15 dB at $P_{out} \geq -20$ dBm

3) WCDMA receiver specification

Item	Specification																			
Receive Frequency	BD1: 2110 MHz ~2170 MHz BD2: 1850~1910 MHz BD5: 869 MHz ~ 894 MHz BD8: 880 MHz ~960 MHz																			
Reference Sensitivity Level	Band1 : BER < 0.001 when $\hat{I}_{or} = -106.7$ dBm / 3.84 MHz Band2 : BER < 0.001 when $\hat{I}_{or} = -106.7$ dBm / 3.84 MHz Band5 : BER < 0.001 when $\hat{I}_{or} = -106.7$ dBm / 3.84 MHz Band8 : BER < 0.001 when $\hat{I}_{or} = -106.7$ dBm / 3.84 MHz																			
Maximum Input Level	BER < 0.001 when $\hat{I}_{or} = -25$ dBm / 3.84 MHz																			
Adjacent Channel Selectivity (ACS)	ACS > 33 dB where BER < 0.001 when $\hat{I}_{or} = -92.7$ dBm / 3.84 MHz & $I_{oac} = -52$ dBm / 3.84 MHz @ ± 5 MHz																			
Blocking Characteristic	BER < 0.001 when $\hat{I}_{or} = -103.7$ dBm / 3.84 MHz & $I_{blocking} = -56$ dBm / 3.84 MHz @ $F_{uw}(\text{offset}) = \pm 10$ MHz or $I_{blocking} = -44$ dBm / 3.84 MHz @ $F_{uw}(\text{offset}) = \pm 15$ MHz																			
Spurious Response	BER < 0.001 when $\hat{I}_{or} = -103.7$ dBm / 3.84 MHz & $I_{blocking} = -44$ dBm																			
Intermodulation	BER < 0.001 when $\hat{I}_{or} = -103.7$ dBm / 3.84 MHz & $I_{ouw1} = -46$ dBm @ $F_{uw1}(\text{offset}) = \pm 10$ MHz & $I_{ouw2} = -46$ dBm / 3.84 MHz @ $F_{uw2}(\text{offset}) = \pm 20$ MHz																			
Spurious Emissions	< -57 dBm / 100 kHz BW @ $9 \text{ kHz} \leq f < 1 \text{ GHz}$ < -47 dBm / 1 MHz BW @ $1 \text{ GHz} \leq f \leq 12.75 \text{ GHz}$																			
Inner Loop Power Control In Uplink	<div>Adjust output(TPC command)</div> <table><tr><td>cmd</td><td>1dB</td><td>2dB</td><td>3dB</td></tr><tr><td>+1</td><td>+0.5 / 1.5</td><td>+1 / 3</td><td>+1.5 / 4</td></tr><tr><td>0</td><td>-0.5 / +0.5</td><td>-0.5 / +0.5</td><td>-0.5 / +0.5</td></tr><tr><td>-1</td><td>-0.5 / -1.5</td><td>-1 / -3</td><td>-1.5 / -4</td></tr></table> <div>group(10equal command group)</div> <table><tr><td>+1</td><td>+8 / +12</td><td>+16 / +24</td></tr></table>	cmd	1dB	2dB	3dB	+1	+0.5 / 1.5	+1 / 3	+1.5 / 4	0	-0.5 / +0.5	-0.5 / +0.5	-0.5 / +0.5	-1	-0.5 / -1.5	-1 / -3	-1.5 / -4	+1	+8 / +12	+16 / +24
cmd	1dB	2dB	3dB																	
+1	+0.5 / 1.5	+1 / 3	+1.5 / 4																	
0	-0.5 / +0.5	-0.5 / +0.5	-0.5 / +0.5																	
-1	-0.5 / -1.5	-1 / -3	-1.5 / -4																	
+1	+8 / +12	+16 / +24																		

4) HSDPA transmitter specification

Item	Specification															
Transmit Frequency	BD1: 1920MHz ~ 1980 MHz BD2: 1850~1910 MHz BD5: 880 MHz ~ 915 MHz BD8: 824 MHz ~ 849 MHz															
Maximum Output Power	Sub-Test 1=2/15 25.7~20.3dBm / 3.84 MHz 2=12/15 25.7~20.3dBm / 3.84 MHz 3=15/8 25.7~19.8dBm / 3.84 MHz 4=15/4 25.7~19.8dBm / 3.84 MHz															
Spectrum Emission Mask	Sub-Test : 1=2/15, 2=12/15, 3=15/8, 4=15/4 <table><tr><th>Frequency offset from carrier Δf</th><th>Minimum requirement</th><th>Measurement Bandwidth</th></tr><tr><td>2.5 ~ 3.5 MHz</td><td>-35-15$\times(\Delta f$-2.5)dBc</td><td>30 kHz</td></tr><tr><td>3.5 ~ 7.5 MHz</td><td>-35-1$\times(\Delta f$-3.5)dBc</td><td>1 MHz</td></tr><tr><td>7.5 ~ 8.5 MHz</td><td>-35-10$\times(\Delta f$-7.5)dBc</td><td>1 MHz</td></tr><tr><td>8.5 ~ 12.5 MHz</td><td>-49dBc</td><td>1 MHz</td></tr></table>	Frequency offset from carrier Δf	Minimum requirement	Measurement Bandwidth	2.5 ~ 3.5 MHz	-35-15 $\times(\Delta f$ -2.5)dBc	30 kHz	3.5 ~ 7.5 MHz	-35-1 $\times(\Delta f$ -3.5)dBc	1 MHz	7.5 ~ 8.5 MHz	-35-10 $\times(\Delta f$ -7.5)dBc	1 MHz	8.5 ~ 12.5 MHz	-49dBc	1 MHz
Frequency offset from carrier Δf	Minimum requirement	Measurement Bandwidth														
2.5 ~ 3.5 MHz	-35-15 $\times(\Delta f$ -2.5)dBc	30 kHz														
3.5 ~ 7.5 MHz	-35-1 $\times(\Delta f$ -3.5)dBc	1 MHz														
7.5 ~ 8.5 MHz	-35-10 $\times(\Delta f$ -7.5)dBc	1 MHz														
8.5 ~ 12.5 MHz	-49dBc	1 MHz														
Adjacent Channel Leakage Power Ratio (ACLR)	Sub-Test : 1=2/15, 2=12/15, 3=15/8, 4=15/4 > 33 dB @ \pm 5 MHz > 43 dB @ \pm 10 MHz															
Error Vector Magnitude	< 17.5 %, when Pout \geq -20 dBm															

5) HSDPA receiver specification

Item	Specification
Receive Frequency	BD1: 2110 MHz ~2170 MHz BD2: 1850~1910 MHz BD5: 869MHz ~ 894 MHz BD8: 925MHz ~ 960 MHz
Maximum Input Level (BLER or R), 16QAM Only	Sub-Test : 1=2/15, 2=12/15, 3=15/8, 4=15/4 BLER < 10% or R >= 700kbps

6) HSUPA Tx, Rx specification

Item	Specification															
Maximum Output Power	<div>Sub-Test</div> <div>1=11/15 25.7~17.3dBm / 3.84 MHz</div> <div>2=6/15 25.7~16.8dBm / 3.84 MHz</div> <div>3=15/9 25.7~17.8dBm / 3.84 MHz</div> <div>4=2/15 25.7~16.8dBm / 3.84 MHz</div> <div>5=15/15 25.7~20.3dBm / 3.84 MHz</div>															
Spectrum Emission Mask	<div>Sub-Test : 1=11/15, 2=6/15, 3=15/9, 4=2/15, 5=15/15</div> <table><tr><th>Frequency offset from carrier Δf</th><th>Minimum Requirement</th><th>Measurement Bandwidth</th></tr><tr><td>2.5 ~ 3.5 MHz</td><td>-35-15$\times(\Delta f-2.5)$dBc</td><td>30 kHz</td></tr><tr><td>3.5 ~ 7.5 MHz</td><td>-35-1$\times(\Delta f-3.5)$dBc</td><td>1 MHz</td></tr><tr><td>7.5 ~ 8.5 MHz</td><td>-35-10$\times(\Delta f-7.5)$dBc</td><td>1 MHz</td></tr><tr><td>8.5 ~ 12.5 MHz</td><td>-49dBc</td><td>1 MHz</td></tr></table>	Frequency offset from carrier Δf	Minimum Requirement	Measurement Bandwidth	2.5 ~ 3.5 MHz	-35-15 $\times(\Delta f-2.5)$ dBc	30 kHz	3.5 ~ 7.5 MHz	-35-1 $\times(\Delta f-3.5)$ dBc	1 MHz	7.5 ~ 8.5 MHz	-35-10 $\times(\Delta f-7.5)$ dBc	1 MHz	8.5 ~ 12.5 MHz	-49dBc	1 MHz
Frequency offset from carrier Δf	Minimum Requirement	Measurement Bandwidth														
2.5 ~ 3.5 MHz	-35-15 $\times(\Delta f-2.5)$ dBc	30 kHz														
3.5 ~ 7.5 MHz	-35-1 $\times(\Delta f-3.5)$ dBc	1 MHz														
7.5 ~ 8.5 MHz	-35-10 $\times(\Delta f-7.5)$ dBc	1 MHz														
8.5 ~ 12.5 MHz	-49dBc	1 MHz														
Adjacent Channel Leakage Power Ratio (ACLR)	<div>Sub-Test : 1=11/15, 2=6/15, 3=15/9, 4=2/15, 5=15/15</div> <div>> 33 dB @ ± 5 MHz</div> <div>> 43 dB @ ± 10 MHz</div>															

6) WLAN 802.11a transceiver specification

Item	Specification
Transmit Frequency	5150 MHz ~ 5725 MHz (CH36~CH140)
Tx Power Level	$\leq 23\text{dBm}$ (5150 ~ 5350 MHz), $\leq 30\text{dBm}$ (5470 ~ 5725 MHz)
Frequency Tolerance	within ± 20 PPM
Chip clock Frequency Tolerance	within ± 20 PPM
Spectrum Mask	≤ -20 @ $\pm 11\text{MHz}$ offset (9Mhz ~ 11MHz) ≤ -28 @ $\pm 20\text{MHz}$ offset (11MHz ~ 20Mhz) ≤ -40 @ $\pm 30\text{MHz}$ offset (20MHz ~ 30Mhz)
Transmitter constellation error (rms EVM)	$\leq -5\text{dB@6Mbps}$, $\leq -8\text{dB@9Mbps}$, $\leq -10\text{dB@12Mbps}$, $\leq -13\text{dB@18Mbps}$, $\leq -16\text{dB@24Mbps}$, $\leq -19\text{dB@36Mbps}$, $\leq -22\text{dB@48Mbps}$, $\leq -25\text{dB@54Mbps}$
Spurious Emissions	$< -36\text{ dBm @ } 30\text{ MHz to } 47\text{ MHz}$ $< -54\text{ dBm @ } 47\text{ MHz to } 74\text{ MHz}$ $< -36\text{ dBm @ } 74\text{ MHz to } 87,5\text{ MHz}$ $< -54\text{ dBm @ } 87,5\text{ MHz to } 118\text{ MHz}$ $< -36\text{ dBm @ } 118\text{ MHz to } 174\text{ MHz}$ $< -54\text{ dBm @ } 174\text{ MHz to } 230\text{ MHz}$ $< -36\text{ dBm @ } 230\text{ MHz to } 470\text{ MHz}$ $< -54\text{ dBm @ } 470\text{ MHz to } 862\text{ MHz}$ $< -36\text{ dBm @ } 862\text{ MHz to } 1\text{ GHz}$ $< -30\text{ dBm @ } 1\text{ GHz to } 5.15\text{ GHz}$ $< -30\text{ dBm @ } 5.35\text{ GHz to } 5.47\text{ GHz}$ $< -30\text{ dBm @ } 5.725\text{ GHz to } 26.5\text{ GHz}$
Rx Min input Sensitivity	PER $\leq 10\%$ -82dBm@6Mbps , -81dBm@9Mbps , -79dBm@12Mbps -77dBm@18Mbps , -74dBm@24Mbps , -70dBm@36Mbps -66dBm@48Mbps , -65dBm@54Mbps
Rx Max input Sensitivity	$\geq -30\text{dBm}$ (6,9,12,18,24,36,48,54Mbps) @ PER $\leq 10\%$
Rx Adjacent Channel Rejection	PER $\leq 10\%$, ACR $\geq 16\text{dB@6Mbps}$, ACR $\geq 15\text{dB@9Mbps}$, ACR $\geq 13\text{dB@12Mbps}$, ACR $\geq 11\text{dB@18Mbps}$, ACR $\geq 8\text{dB@24Mbps}$, ACR $\geq 4\text{dB@36Mbps}$ ACR $\geq 0\text{dB@48Mbps}$, ACR $\geq -1\text{dB@54Mbps}$ ※ ACR shall be measured by setting the desired signal's strength 3 dB above the rate-dependent sensitivity specified in min input sensitivity

7) WLAN 802.11b transceiver specification

Item	Specification
Transmit Frequency	2400 MHz ~ 2483.5 MHz (CH1~CH13)
Tx Power Level	≤ 20dBm
Frequency Tolerance	within ±25 PPM
Chip clock Frequency Tolerance	within ±25 PPM
Spectrum Mask	≤ -30 @ $f_c - 22\text{MHz} < f < f_c - 11\text{MHz}$ and $f_c + 11\text{MHz} < f < f_c + 22\text{MHz}$ ≤ -50 @ $f < f_c - 22\text{MHz}$ and $f > f_c + 22\text{MHz}$
Power ramp on/off time	≤ 2us
Carrier Suppression	≤ -15dB
Modulation Accuracy(Peak EVM)	≤ 35%
Spurious Emissions	< -36 dBm @ 30MHz ~ 1GHz < -30 dBm above @ 1GHz ~ 12.75GHz < -47 dBm @ 1.8GHz ~ 1.9GHz < -47 dBm @ 5.15GHz ~ 5.3GHz
Rx Min input Sensitivity	≤ -76dBm(1Mbps,2Mbps,5.5Mbps,11Mbps) @ FER ≤ 8%
Rx Max input Sensitivity	≥ -10dBm(1Mbps,2Mbps,5.5Mbps,11Mbps) @ FER ≤ 8%
Rx Adjacent Channel Rejection	≥ 35dB @FER ≤ 8%, interference input signal -70dBm@ $f_c \pm 25\text{MHz}$ (11Mbps)

8) WLAN 802.11g transceiver specification

Item	Specification
Transmit Frequency	2400 MHz ~ 2483.5 MHz (CH1~CH13)
Tx Power Level	≤ 20dBm
Frequency Tolerance	within ±25 PPM
Chip clock Frequency Tolerance	within ±25 PPM
Spectrum Mask	≤ -20 @ ±11MHz offset (9Mhz ~ 11MHz) ≤ -28 @ ±20MHz offset (11MHz ~ 20Mhz) ≤ -40 @ ±30MHz offset (20MHz ~ 30Mhz)
Transmitter constellation error (rms EVM)	≤ -5dB@6Mbps, ≤ -8dB@9Mbps, ≤ -10dB@12Mbps, ≤ -13dB@18Mbps, ≤ -16dB@24Mbps, ≤ -19dB@36Mbps, ≤ -22dB@48Mbps, ≤ -25dB@54Mbps
Spurious Emissions	< -36 dBm @ 30MHz ~ 1GHz < -30 dBm above @ 1GHz ~ 12.75GHz < -47 dBm @ 1.8GHz ~ 1.9GHz < -47 dBm @ 5.15GHz ~ 5.3GHz
Rx Min input Sensitivity	PER ≤ 10% -82dBm@6Mbps, -81dBm@9Mbps, -79dBm@12Mbps -77dBm@18Mbps, -74dBm@24Mbps, -70dBm@36Mbps -66dBm@48Mbps, -65dBm@54Mbps
Rx Max input Sensitivity	≥ -20dBm(6,9,12,18,24,36,48,54Mbps) @ PER ≤ 10%
Rx Adjacent Channel Rejection	PER ≤ 10%, ACR ≥ 16dB@6Mbps, ACR ≥ 15dB@9Mbps, ACR ≥ 13dB@12Mbps, ACR ≥ 11dB@18Mbps, ACR ≥ 8dB@24Mbps, ACR ≥ 4dB@36Mbps ACR ≥ 0dB@48Mbps, ACR ≥ -1dB@54Mbps ※ ACR shall be measured by setting the desired signal's strength 3 dB above the rate-dependent sensitivity specified in min input sensitivity

9) WLAN 802.11n transceiver specification

Item	Specification
Transmit Frequency	2400.0 MHz ~ 2483.5 MHz (CH1~CH13) 5150.0 MHz ~ 5725.0 MHz (CH36~CH140)
Tx Power Level	≤ 20dBm(2400 ~ 2483.5 MHz) ≤ 23dBm(5150 ~ 5350.0 MHz), ≤ 30dBm(5470 ~ 5725.0 MHz)
Frequency Tolerance	within ±25 PPM(2400 ~ 2483.5 MHz) within ±20 PPM(5150 ~ 5725.0 MHz)
Chip clock Frequency Tolerance	within ±25 PPM(2400 ~ 2483.5 MHz) within ±20 PPM(5150 ~ 5725 MHz)
Spectrum Mask	≤ -20 @ ±11MHz offset (09Mhz ~ 11MHz) ≤ -28 @ ±20MHz offset (11MHz ~ 20Mhz) ≤ -45 @ ±30MHz offset (20MHz ~ 30Mhz)
Transmitter constellation error (rms EVM)	≤ -5dB@6.5Mbps, ≤ -10dB@13Mbps, ≤ -13dB@19.5Mbps, ≤ -16dB@26Mbps, ≤ -19dB@39Mbps, ≤ -22dB@52Mbps, ≤ -25dB@58.5Mbps, ≤ -28dB@65Mbps
Spurious Emissions	[2400 MHz ~ 2483.5 MHz (CH1~CH13)] < -36 dBm @ 30MHz ~ 1GHz < -30 dBm above @ 1GHz ~ 12.75GHz < -47 dBm @ 1.8GHz ~ 1.9GHz < -47 dBm @ 5.15GHz ~ 5.3GHz [5150 MHz ~ 5725 MHz (CH36~CH140)] < -36 dBm @ 30 MHz to 47 MHz < -54 dBm @ 47 MHz to 74 MHz < -36 dBm @ 74 MHz to 87,5 MHz < -54 dBm @ 87,5 MHz to 118 MHz < -36 dBm @ 118 MHz to 174 MHz < -54 dBm @ 174 MHz to 230 MHz < -36 dBm @ 230 MHz to 470 MHz < -54 dBm @ 470 MHz to 862 MHz < -36 dBm @ 862 MHz to 1 GHz < -30 dBm @ 1 GHz to 5.15 GHz < -30 dBm @ 5.35 GHz to 5.47 GHz < -30 dBm @ 5.725 GHz to 26.5 GHz
Rx Min input Sensitivity	PER ≤ 10% -82dBm@6.5Mbps, -79dBm@13Mbps, -77dBm@19.5Mbps -74dBm@26Mbps, -70dBm@39Mbps, -66dBm@52Mbps -65dBm@58.5Mbps, -64dBm@65Mbps
Rx Max input Sensitivity	≥ -20dBm @ PER ≤ 10%(2400 ~ 2483.5 MHz) ≥ -30dBm @ PER ≤ 10%(5150 ~ 5725.0 MHz)

2. PERFORMANCE

Rx Adjacent Channel Rejection	<p>PER ≤ 10%, ACR ≥ 16dB@6.5Mbps, ACR ≥ 13dB@13Mbps, ACR ≥ 11dB@19.5Mbps, ACR ≥ 8dB@26Mbps, ACR ≥ 4dB@39Mbps, ACR ≥ 0dB@52Mbps ACR ≥ -1dB@58.5Mbps, ACR ≥ -2dB@65Mbps ※ ACR shall be measured by setting the desired signal's strength 3 dB above the rate-dependent Sensitivity specified in min input sensitivity</p>
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10) GPS receiver specification

Item	Specification
Receive Frequency	1574.42 MHz ~ 1576.42 MHz
Minimum Sensitivity	1 satellite ≥ -142dBm, 7 satellites ≥ -147dBm at coarse time aiding

11) Current consumption

	Stand by		Voice Call	VT
	Bluetooth Off	Bluetooth Connected		
WCDMA Only	4.5 mA under (DRX=1.28)	6 mA under (DRX=1.28)	270 mA under (Tx=12dBm)	NA
GSM Only	4.5 mA under (Paging=5 period)	6 mA under (Paging=5 period)	340 mA under (Tx=Max)	

** Test condition for Standby current consumption should be as below.

: Measurement time 1hr, with Agilent & CMT JIG

12) Battery life time

	Stand by	Voice Call	VT
WCDMA	460 hours over (DRX = 1.28)	8 hours over (TX = 12dBm, Low Pwr mode)	NA
GSM	460 hours over (Paging Period = 5)	7 hours over (TX Level = Max)	

13) NFC

Operate below 3 mode.

1)Card mode : Smart Card capability for mobile device(recognition distance : over 40mm)

2)Reader mode : Get information from tag(recognition distance : over 30mm)

3)Peer-to-peer mode : Device to device communication(recognition distance : over 5mm)

14) Charging hour

3hour 30min. under (2080mAh battery, 1.2A TA)

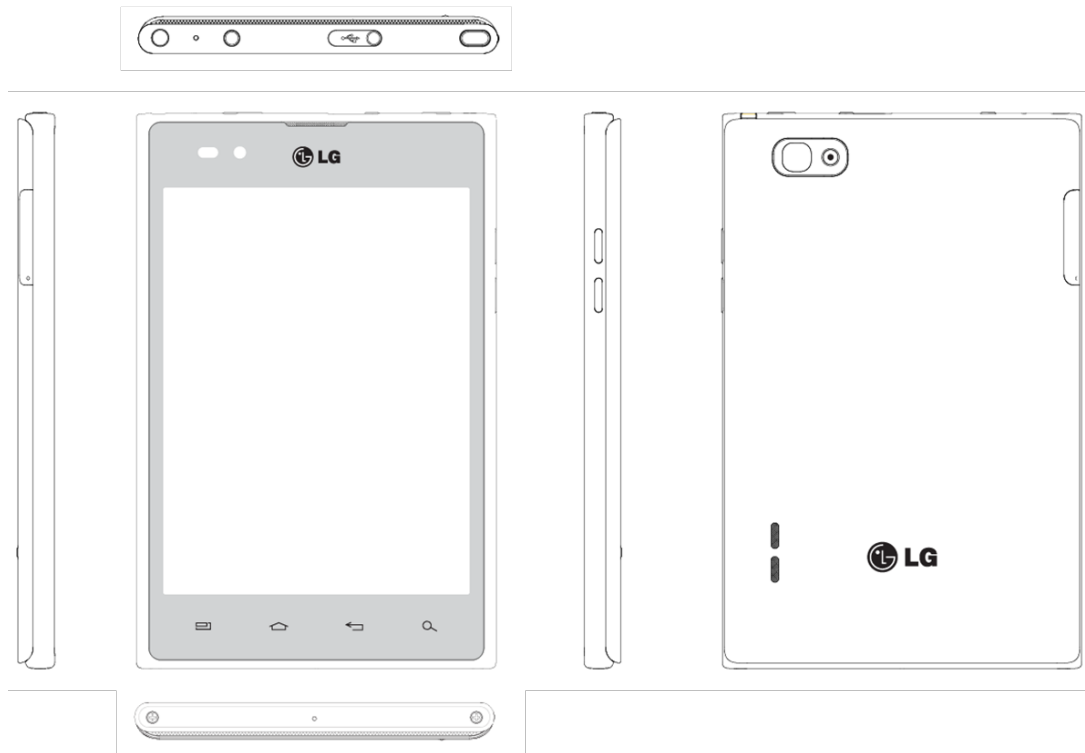
15) RSSI indicator (Based on Cell power)

BAR	WCDMA	GSM/DCS/PCS
4	$> -88 \pm 2\text{dBm}$	$> -91 \pm 2\text{dBm}$
4 \rightarrow 3	$-88 \pm 2\text{dBm}$	$-91 \pm 2\text{dBm}$
3 \rightarrow 2	$-96 \pm 2\text{dBm}$	$-99 \pm 2\text{dBm}$
2 \rightarrow 1	$-104 \pm 2\text{dBm}$	$-103 \pm 2\text{dBm}$
1 \rightarrow 0	$-110 \pm 2\text{dBm}$	$-105 \pm 2\text{dBm}$
No service	$< -110 \text{ dBm}$	$< -105 \text{ dBm}$

16) Battery indicator

Battery Bar	Specification	Unit
BAR 20 (Full)	98% over	Remain%
BAR 20 -> 19	98% → 97%	
BAR 19 -> 18	93% → 92%	
BAR 18 -> 17	88% → 87%	
BAR 17 -> 16	83% → 82%	
BAR 16 -> 15	78% → 77%	
BAR 15 -> 14	73% → 72%	
BAR 14 -> 13	68% → 67%	
BAR 13 -> 12	63% → 62%	
BAR 12 -> 11	58% → 57%	
BAR 11 -> 10	53% → 52%	
BAR 10 -> 9	48% → 47%	
BAR 9 -> 8	43% → 42%	
BAR 8 -> 7	38% → 37%	
BAR 7 -> 6	33% → 32%	
BAR 6 -> 5	28% → 27%	
BAR 5 -> 4	23% → 22%	
BAR 4 -> 3	16% → 15%	
BAR 3 -> 2	13% → 12%	
BAR 2 -> 1	8% → 7%	
BAR 1 -> 0	3% → 2%	
Low Battery Pop-up	4% ~ 15% : One Time popup at 15% (No call)	
Critical Low Battery Pop-up	0% ~ 3% : Every Level change popup (No call)	
POWER OFF	1% under	

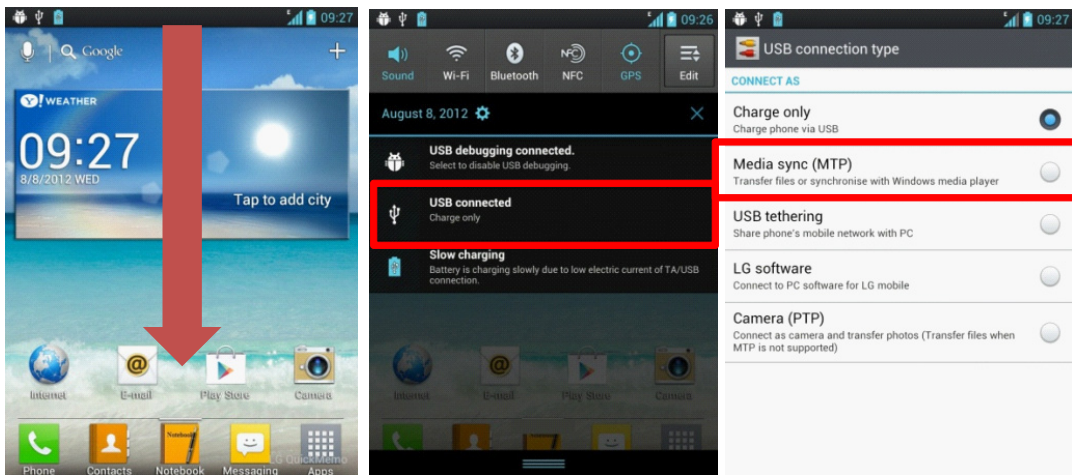
2.7 LGP895 Figures

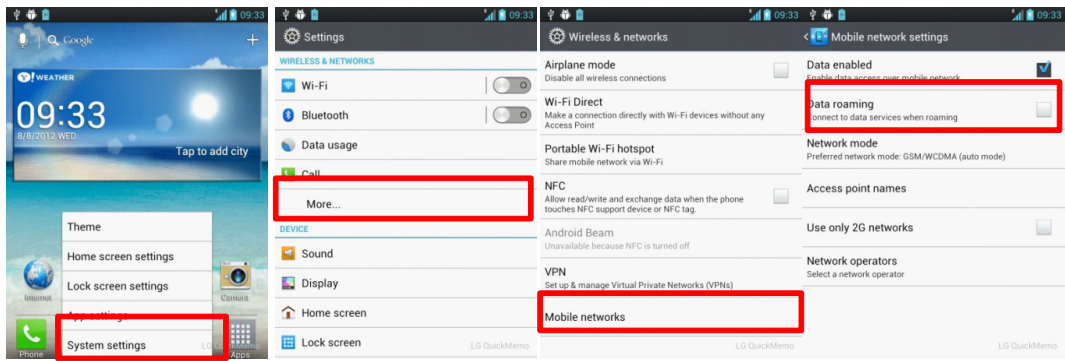


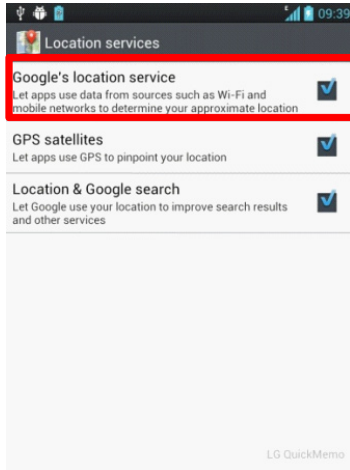
3.CIC_AND SERVICE CENTER

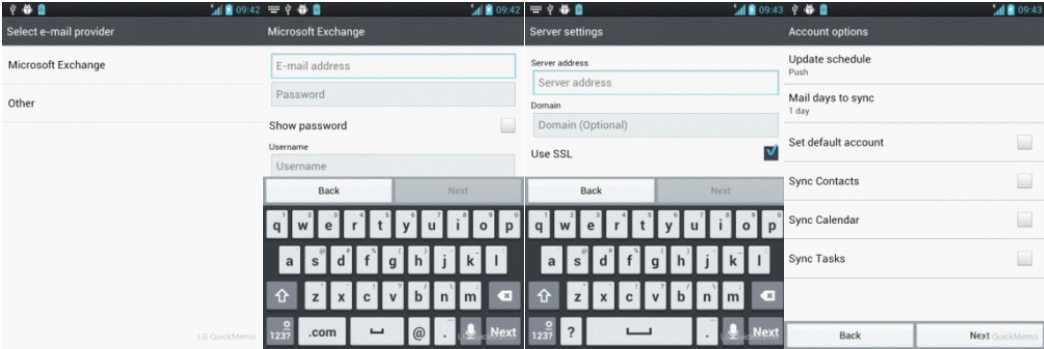
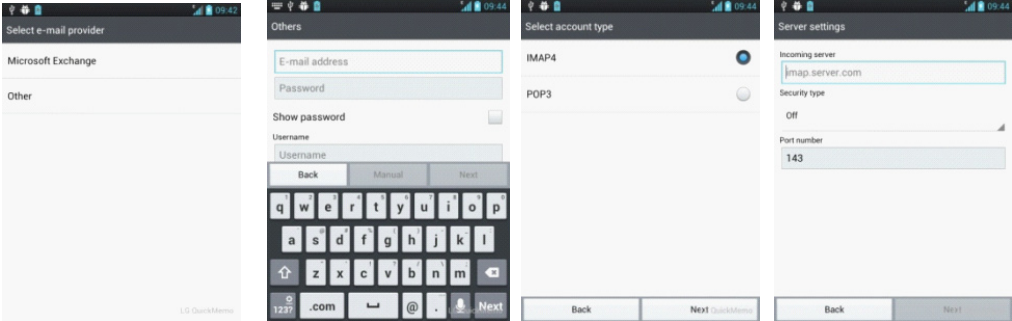
3.1 CIC FAQ

No	FAQ	Q&A
1	Q	I can't remember the PhoneLock password.
	A	<p>With Power Off, press the power key + volume up key + quick memo key for 4-5 seconds (until the first LG logo disappears). Release those keys, and you will enter the RECOVERY Mode Menu. Then, see the menu with the Home Key. Browse the menu with the Col Up/Down Keys. Select a menu item with the Power Key.</p> <p>- In case of pattern lock or Gmail setting, press the Forgot Button to set a new pattern.</p>
Request for development		<ol style="list-style-type: none"> 1. How to disable Pattern Lock, Password and PIN. 2. Request to check out if it is specified in the user manual. 3. Description on HW Factory Reset Key combination and how to do it.

No	FAQ	Q&A
2	Q	How do I put in and take out files from the SD card?
A		<p>SD card is not supported. Internal memory is supported.</p> <p>To write or delete a file on the Internal memory, the unit must be connected to a PC by portable disk.</p> <p>First, download and install the USB driver. Then, confirm the order below as the USB data communication cable is connected.</p>  <ol style="list-style-type: none"> 1. Status Bar Slide Down 2. "USB connected" Touch 3. Select "Media sync(MTP)"
Request for development		<p>1.PC<-> SD CARD</p> <p>2.PHONE<-> SD CARD</p>

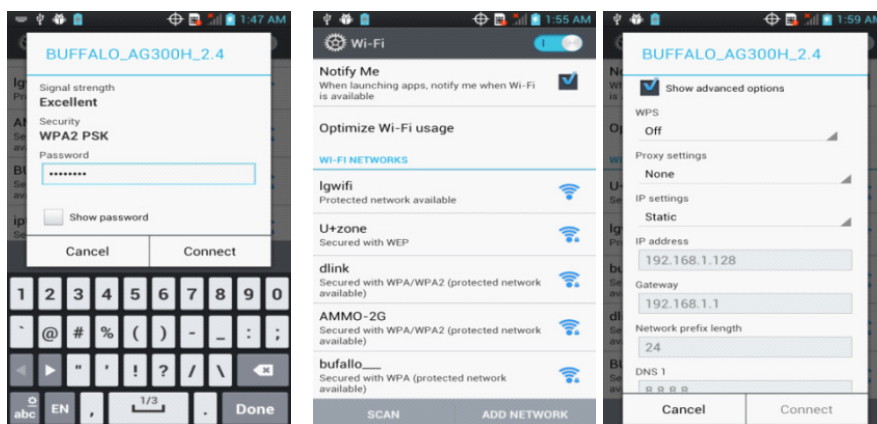
No	FAQ	Q&A
3	Q	I use it abroad, but 3G connection doesn't work.
A		<p>Check if Settings > More > Mobile networks > Data roaming is checked. If it is in uncheck condition, please check.</p> 
Request for development		<p>ex) 1. Europe<->Europe 2. Europe<->Continents(North America, Asia etc)</p>

No	FAQ	Q&A
4	Q	The GPS location isn't right, what should I do?
	A	<p>GPS signals are affected much by weather conditions or surroundings (Indoor, Urban etc).</p> <p>If Settings -> Location Services -> Google's location service Use wireless Network item is checked, use the Network Info (Cell, WIFI AP etc) to see the location info.</p> <p>However, this results in a wider margin of error compared to GPS-based positioning, and thus an incorrect location.</p> <p>Menu > Settings > Location Services</p> <p>- Google's location service : Check</p>  <p>The screenshot shows the 'Location services' settings page. At the top, there's a header 'Location services'. Below it, three options are listed: 'Google's location service' (checked), 'GPS satellites' (checked), and 'Location & Google search' (checked). The 'Google's location service' option is highlighted with a red rectangular box. The text for 'Google's location service' reads: 'Let apps use data from sources such as Wi-Fi and mobile networks to determine your approximate location'. The text for 'GPS satellites' reads: 'Let apps use GPS to pinpoint your location'. The text for 'Location & Google search' reads: 'Let Google use your location to improve search results and other services'. The bottom of the screen shows 'LG QuickMemo'.</p>
5	Q	The downloaded application isn't compatible?
	A	<p>Specific explanation on how compatibility doesn't fit is needed.</p> <p>Generally for issues of incompatibility of APPs, it is shown that these problems occur when compatibility isn't considered when making APPs.</p> <p>It will be confirmed if the APP with incompatibility is informed.</p> <p>Thank you.</p>

No	FAQ	Q&A
6	Q	How do I make an e-mail account?
	A	<p>Email supports EAS, IMAP4, POP3 protocol.</p> <p>The registration order is as follows.</p> <p>(If no account is registered, the registration screen is automatically connected when using the e-mail.)</p> <p>* EAS account</p> <p>Among e-mail service providers, choose MS Exchange > enter e-mail address, password (The user name isn't changed unless the e-mail ID and user name is different.)> Sync item, Set receiving interval, e-mail activating term > (Security setting following the server setting) > Account name setting > Confirm</p>  <p>* IMAP4, POP3</p> <p>Select Other among e-mail service providers > enter e-mail address, password > (Check if your account supports IMAP4 or POP3 service)> Choose receiving server and security type(Automatic enter and progress if the service provider is already entered) > Select sending server and security connection(Automatic enter and progress if the service provider is already entered)> (Generally, SMTP user name and password is the same as the e-mail address and password entered in the first place) > Confirm</p> 

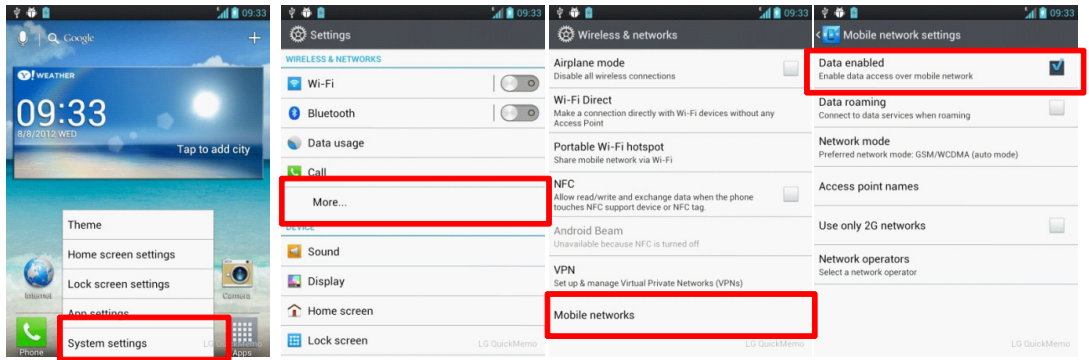
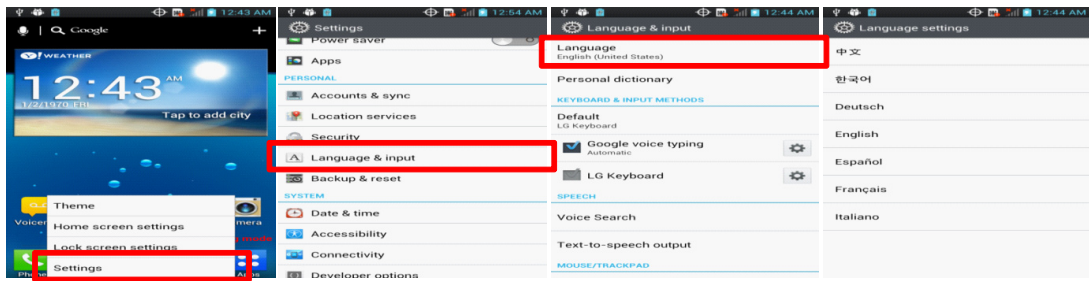
No	FAQ	Q&A
7	Q	E-mail registration doesn't work.
	A	<ol style="list-style-type: none">1. Check if wifi or data can be used because the e-mail service uses data.2. Check e-mail address and password.3. Check account setting information(IMAP, POP3, SMTP) of the service corresponding to your mail.4. For EAS, check server information from the corresponding service manager.
8	Q	Unused application shows up as a using program even though it is all killed. What should I do?
	A	<p>It is because service is in progress from back ground of the application.</p> <p>For example, it is because e-mails and calls must be informed to the user even if kill is in progress.</p>

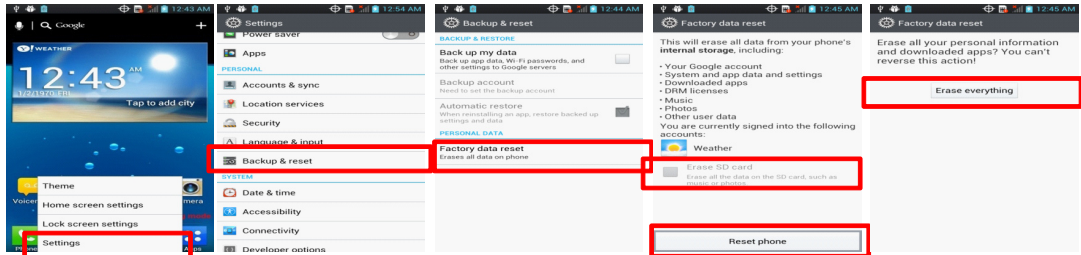
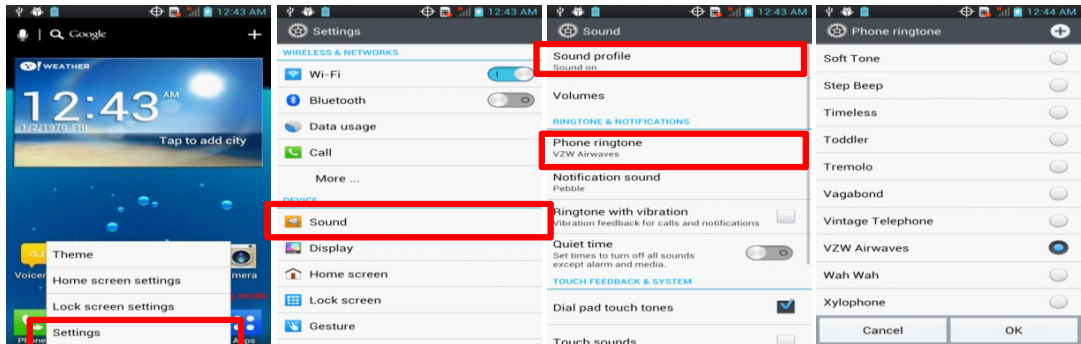
No	FAQ	Q&A
9	Q	Wifi connection doesn't work well.
	A	<p>There can be several reasons in why WiFi connection doesn't work well, but try connecting with the methods below.</p> <ol style="list-style-type: none"> 1. Check if WiFi is ON. 2. Entered information on the PHONE can simply be different from the AP information. <ol style="list-style-type: none"> 1) Check if AP information which is to be connected, thus Security type, password is precisely entered on the PHONE.(picture. 1) 2) AP information might be newly updated. Click the corresponding AP and choose "Forget", press "Option key > Scan" button and update the AP list. After that, attempt connection.(picture. 2) 3. The IP might not be dynamically allocated if there is problem in the DHCP server. At this time, receive IP allocation using a static IP. <ol style="list-style-type: none"> 1) In Fig. 1, go to "Show advanced options"(Check) > "IP Settings"(Static) and set "IP adress", "Gateway", "Network prefix length", "DNS 1" and "DNS 2" to access the AP. (Fig. 3)





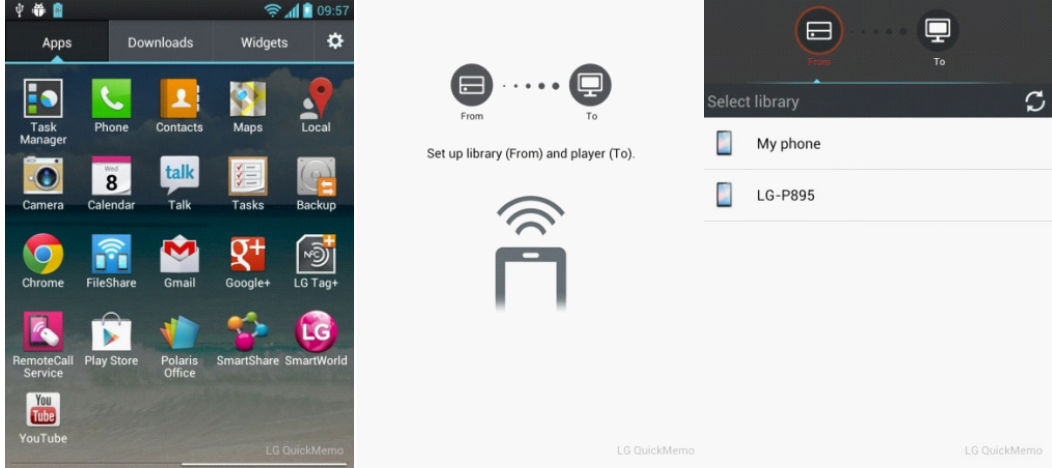
3. CIC AND SERVICE CENTER

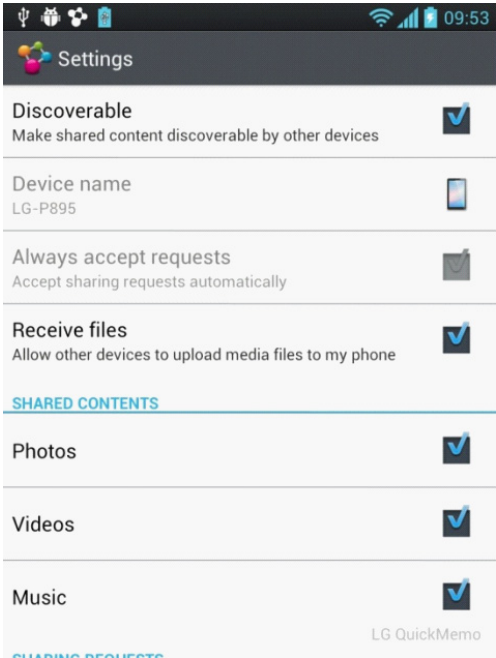
No	FAQ	Q&A
10	Q	How do you install the PC Sync Program?
	A	Search the model on LG mobile web site and download.
11	Q	How do you install the Phone driver?
	A	Download the USB Driver fitting the model from the communication company web site. Delete the USB cable and install the USB Driver installation file. When the installation is completed, connect the USB cable with the PC and use it with the unit.

No	FAQ	Q&A
12	Q	How to connect internet/data network
	A	<p>Users can choose to turn ON/OFF the cell phone's data connection status. With data connection set OFF, MMS text messages and internet are not available. Do the following. Setting > More > Mobile Network > choose Data Connection Permitted</p> 
13	Q	What should I do to connect PC Sync program with the phone?
	A	With the PC Sync program running, automatic recognition works upon the phone being connected.
14	Q	Can language be changed?
	A	<p>Do the following. Setting > Language and Input > choose the language you want</p> 

No	FAQ	Q&A
15	Q	How do you Reset and Factory Reset?
	A	<p>Do the following.</p> <p>Setting > Backup and Reset > Reset > Phone Reset > Delete All</p> <p>For Phone Reset, choose the internal memory checkbox, and the data on the internal memory will be deleted as well.</p> 
16	Q	I want to change the bell sound.
	A	<p>Change the bell sound under the 'Setting.' Or you can use SD-card-based sound sources.</p> <p>Do the following.</p> <ol style="list-style-type: none"> 1. Go to Setting > Sound > 'Sound Setting' and set the sound on. 2. Choose various bell sounds under the 'Phone Bell Sound' menu. 

No	FAQ	Q&A
17	Q	Is it compatible with other devices?
	A	It is basically compatible only with external Bluetooth devices.
Request for development		ex) 1. Bluetooth 2. other
18	Q	How do you use HDMI?
	A	<p>1. Prepare for MHL Gender, HDMI Cable, and charger as shown in the picture.</p>  <p>2. Connect as shown in the picture.</p>  <p>3. Connect HDMI terminal to devices(monitor, TV), and change to the external input mode(HDMI mode) on the device.</p>

No	FAQ	Q&A
19	Q	HDMI error occurs.
	A	<ol style="list-style-type: none"> 1. Confirm that HDMI Cable, MHL Gender, TA are properly connected. 2. Confirm that external input mode of devices(monitor, TV) is set to HDMI mode.
20	Q	How do you use Smart Share?
	A	<p>Pictures, videos and musics can be shared among DLNA-certified devices connected to same network by using SmartShare.</p> <ol style="list-style-type: none"> 1. Select SmartShare after pressing Applications. 2. Select library that has contents on From (My Phone, other phones, PC etc.) 3. Select wanted contents through searching library. 4. It can be played through selecting player in the player set up category. 

No	FAQ	Q&A
21	Q	Smart Share error occurs.
	A	<p>1. P895 can't be searched on other devices.</p> <ul style="list-style-type: none"> - Confirm whether Discoverable is checked on Setting. - Confirm if you approved P895 on other devices' set up. <p>2. Even there is a device in the same AP, no device is searched on From.</p> <ul style="list-style-type: none"> - Confirm if the connected devices support DLNA, and check DLNA server function (DMS) is on. - Searching may not be smooth if network status is not good. <p>3. File doesn't get played.</p> <ul style="list-style-type: none"> - It could be a type of file that the device doesn't support. <p>4. Uploading can't be done.</p> <ul style="list-style-type: none"> - Uploading DMS may not support uploading function. <p>5. P895(including all of LG Phones) is not found under To.</p> <ul style="list-style-type: none"> -SmartShare-installed LG Phones do not support DMR. <p>6. When DMP is running, the pop-up for content loading won't disappear shortly.</p> <ul style="list-style-type: none"> - As data are transmitted through network, loading may take longer depending on network condition. 

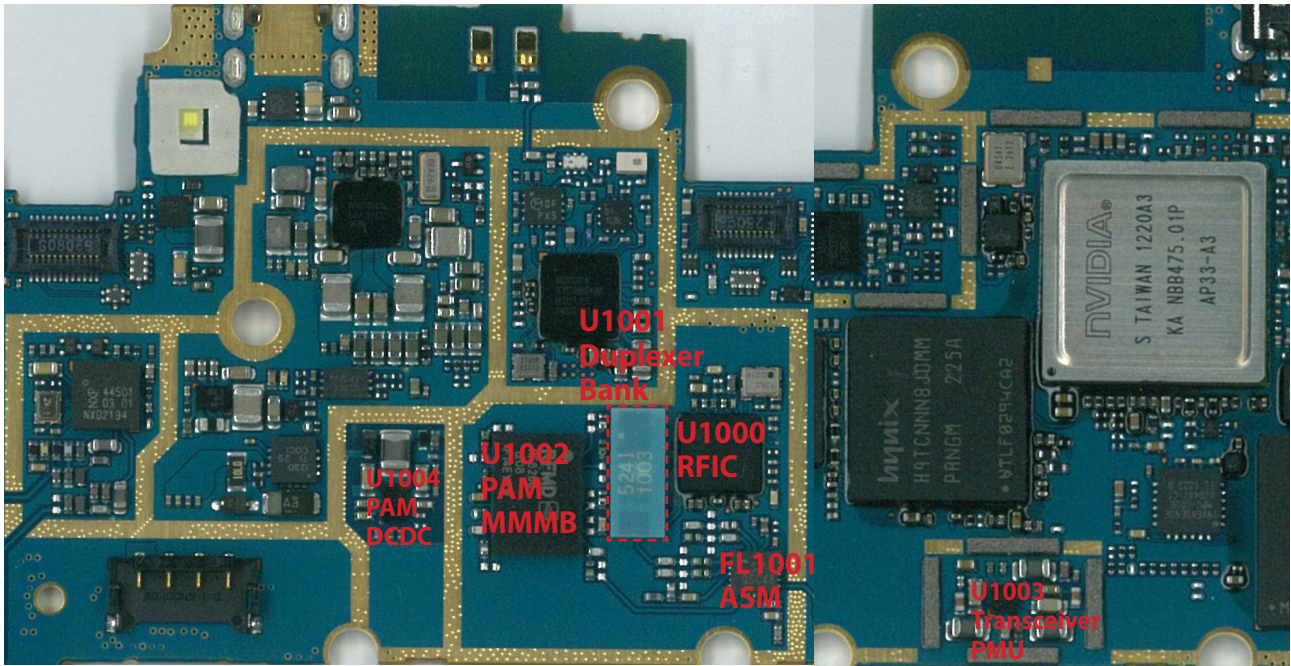
No	FAQ	Q&A
22	Q	Battery consumption is too fast.
	A	<ol style="list-style-type: none"> 1. Because it is thought that the phone is distant from the network at areas of low antenna(shaded areas), more power is needed to send and receive location registration information of the phone, so battery consumption is faster. 2. Because the screen(LCD Back Light) is on, battery consumption is faster because power consumption is high. For example) If the current of the LCD Back Light is 100mA/h, it means that the 1500mA battery allows 15 hours of LCD to be on, so setting the screen time limit to be short is good because battery consumption becomes faster if the screen time limit is set to be long. 3. After turning on the application and turning it off using the home key, invisible applications are still being used on the background, so battery consumption becomes faster. It is recommended that delete/before key is always used to end applications or programs. 4. When routing is sued, the Super user authority of the Android system area is taken, so battery consumption might become faster. 5. For applications like Dodolphone, Nateon, Kakaotalk, stocks/weather wizet which need regular data updates, battery consumption might become faster if the update interval is set short. 6. If several applications are installed at once, use after restarting and battery consumption might become faster if several wizet applications are installed on the background.
23	Q	How is the distribution schedule of OS or SW new version known?
	A	It can be checked at local LG Electronic service centers or LG Mobile homepage notice page.

3. CIC AND SERVICE CENTER

No	FAQ	Q&A
24	Q	How do you update the SW?
	A	Web Download : Connect the phone and the computer via USB. Then , use the SW Update Tool to download a new binary to your computer from the server via the internet and install it on your phone.
25	Q	Until when is it guaranteed after purchase? What is the warranty limit?
	A	Free warranty period is 1 year from the date of purchase. Any breakdown or failure caused by external shock may incur repair charge even within the free warranty period.
26	Q	What kinds of phone accessories are there?
	A	You can purchase it from a local LG Electronics service center or on the internet.

4. TROUBLE SHOOTING

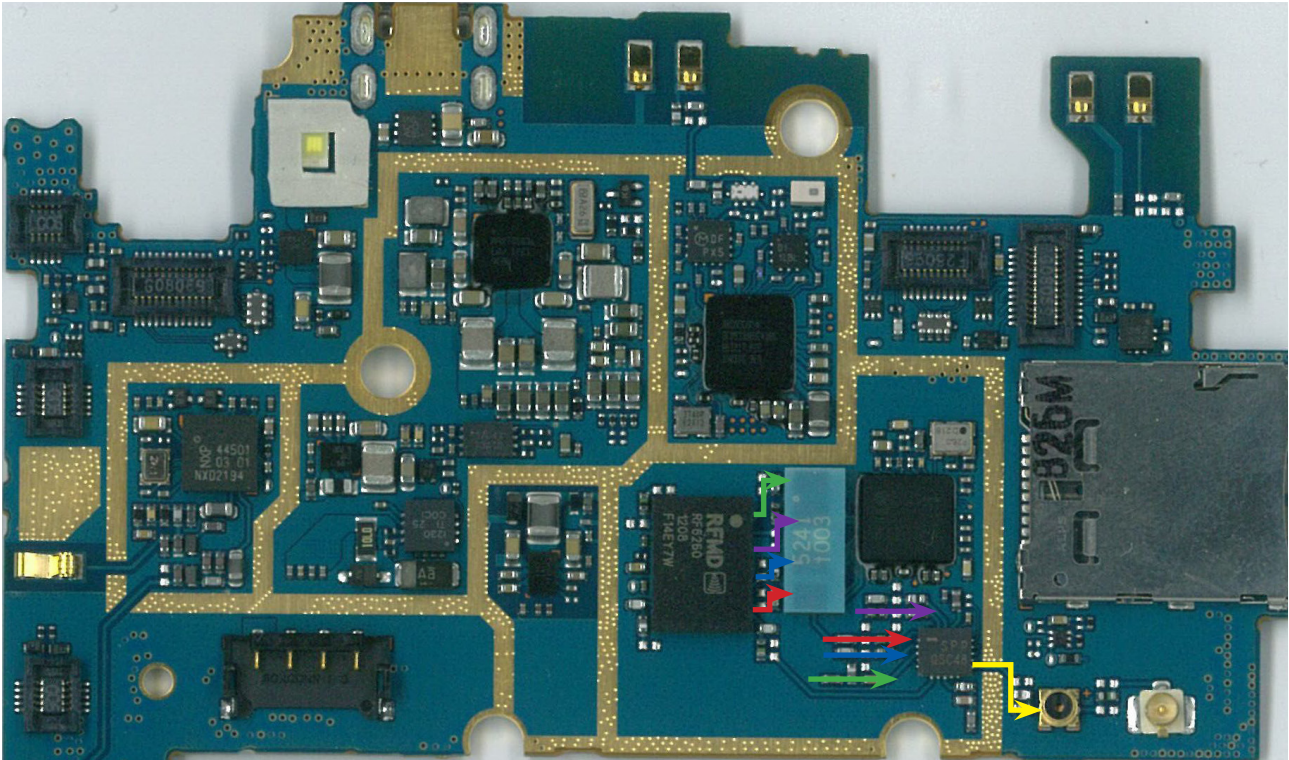
4.1 RF Component



RF component (WCDMA / GSM)

Reference No.	Description	Reference No.	Description
U1000	RFIC (Transceiver)	U1003	Transceiver PMU
U1001	Duplexer Bank	U1004	PAM DCDC
U1002	PAM MMB	FL1001	Filter (ASM)

4.2 SIGNAL PATH



WCDMA 1,2,5,8 Band TX Signal PATH

A. WCDMA 2100 TX PATH

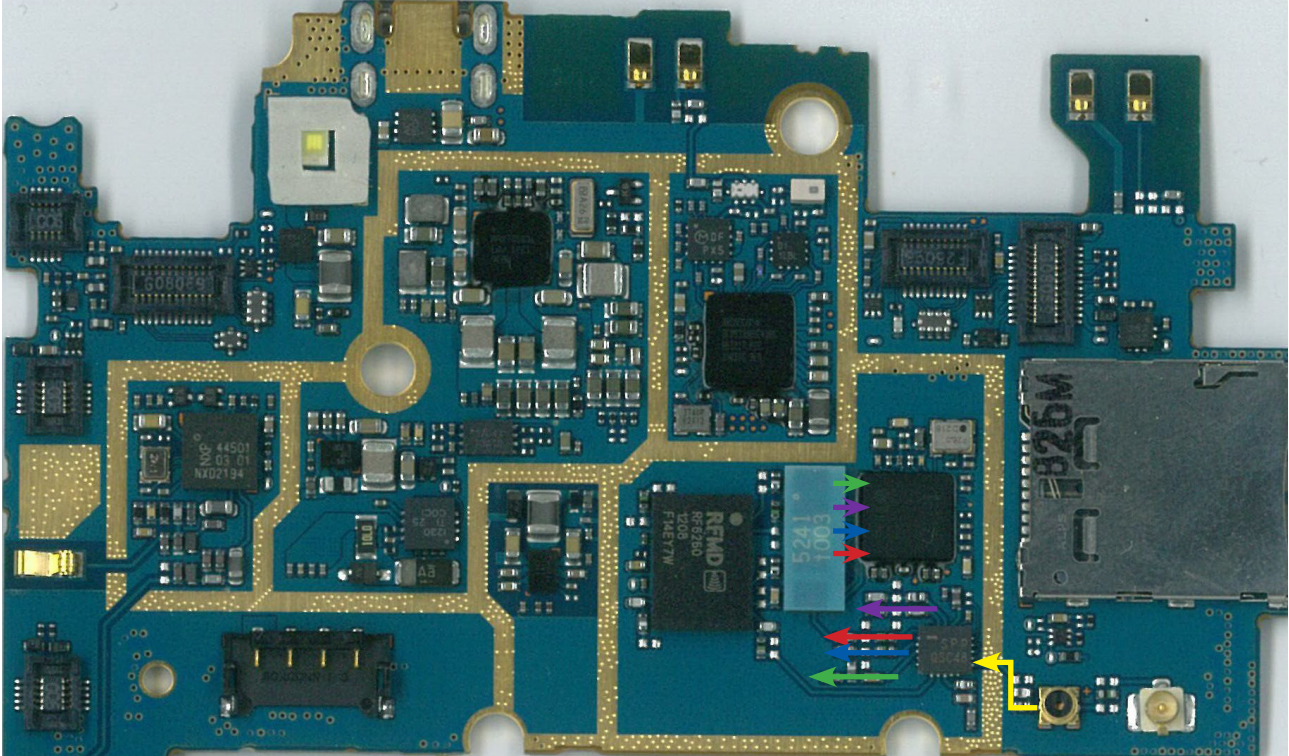
B. WCDMA 1900 TX PATH

C. WCDMA 900 TX PATH

D. WCDMA 850 TX PATH

E. COMMON TX/RX PATH

4. TROUBLE SHOOTING



WCDMA 1,2,5,8 Band RX Signal PATH

A. WCDMA 2100 RX PATH

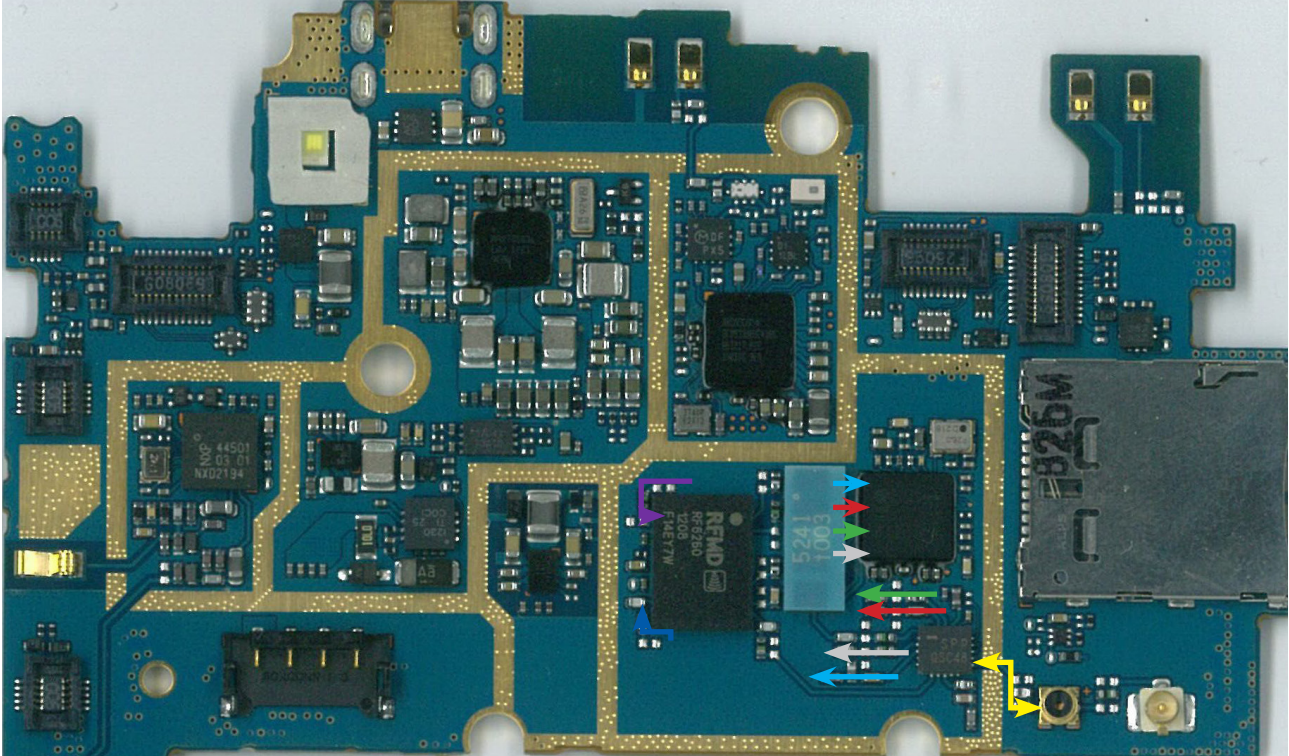
B. WCDMA 1900 RX PATH

C. WCDMA 900 RX PATH

D. WCDMA 850 RX PATH

E. COMMON TX/RX PATH

4. TROUBLE SHOOTING



GSM 850,900,1800,1900 Band TX/RX Signal PATH

A. GSM 850 RX PATH

B. GSM 900 RX PATH

C. GSM 1800 RX PATH

D. GSM 1900 RX PATH

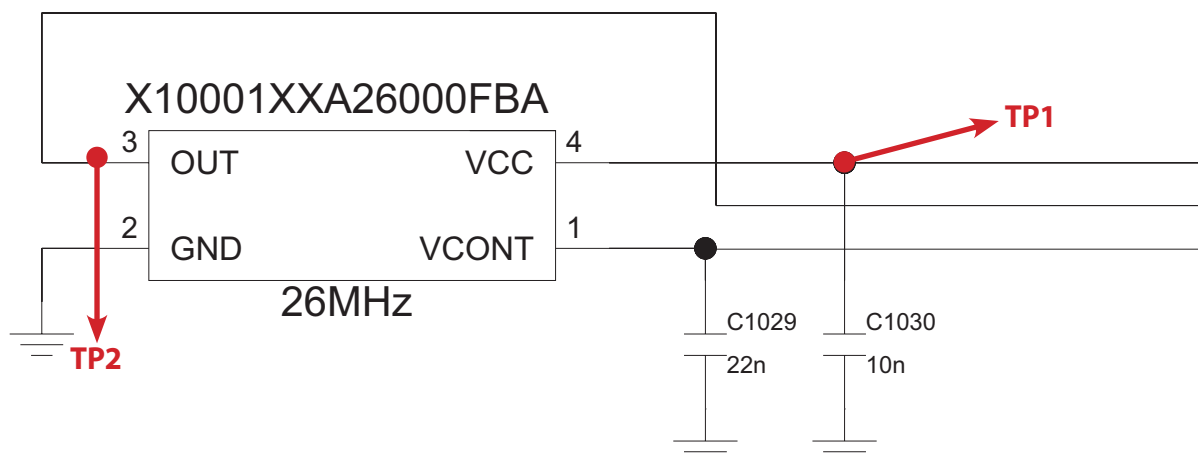
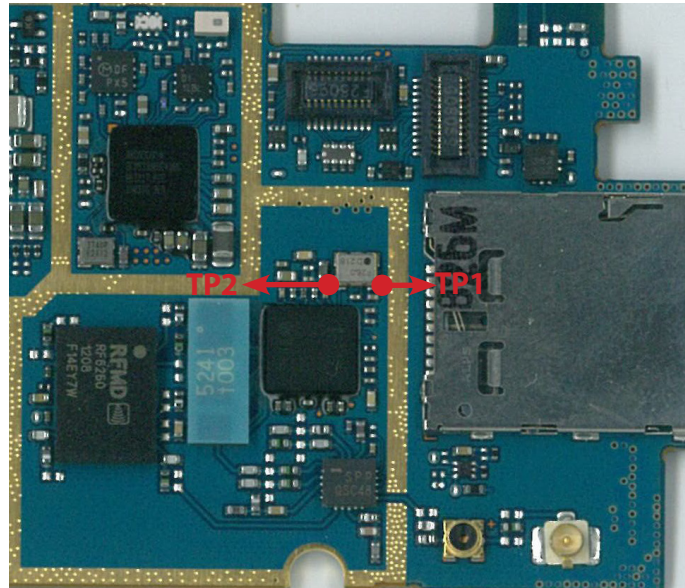
E. GSM 850,900 TX PATH

F. GSM 1800,1900 TX PATH

G. COMMON TX/RX PATH

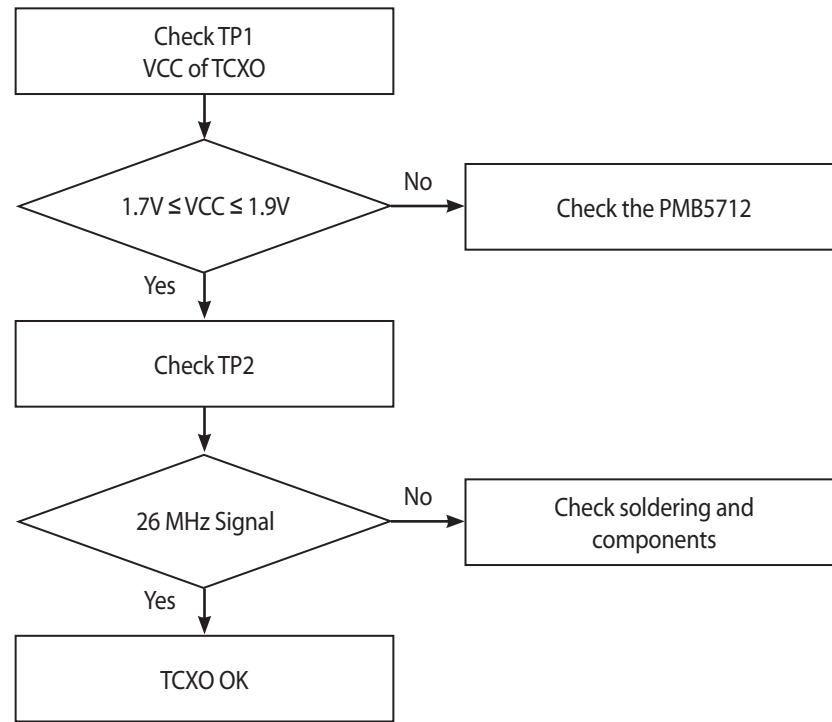
4.3 Checking TCXO Block

The output frequency (26MHz) of TCXO (X1000) is used as the reference one of PMB5712

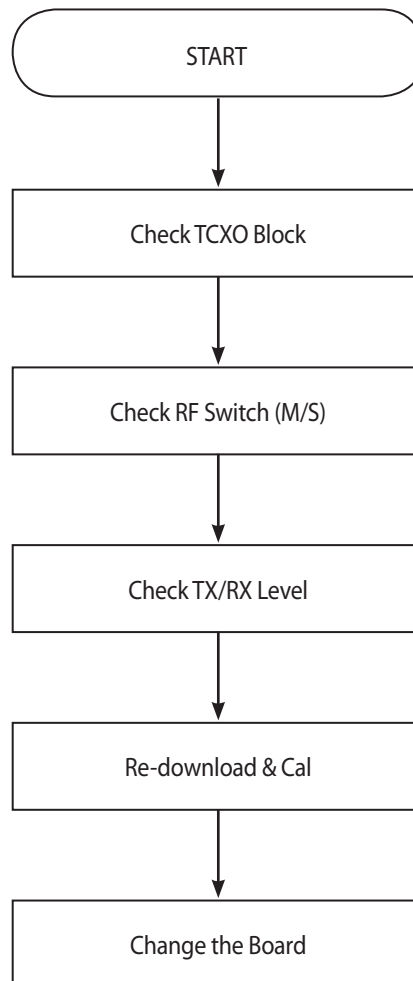


Schematic of the Crystal Part (26MHz)

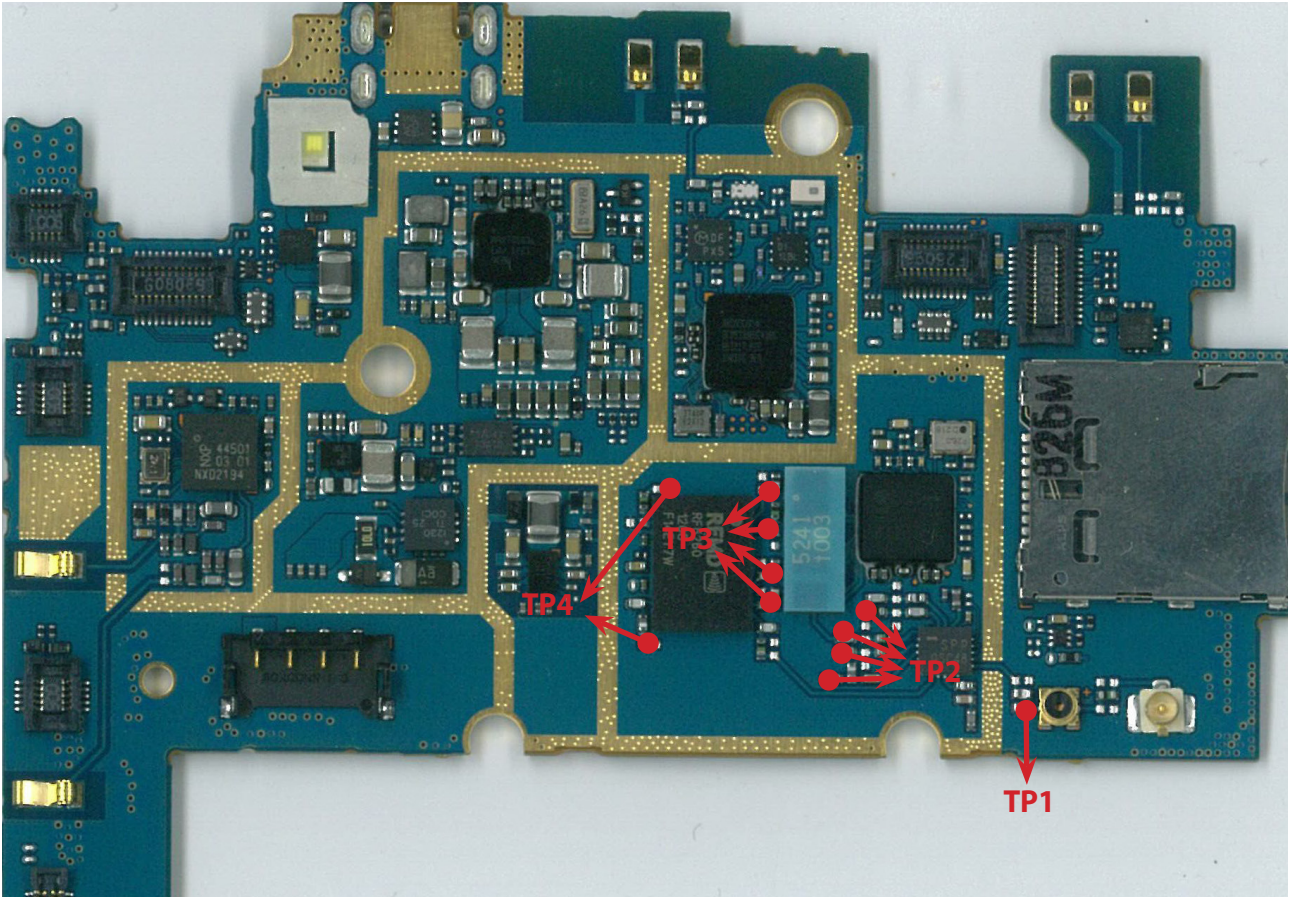
4. TROUBLE SHOOTING



4.4 Checking WCDMA Block

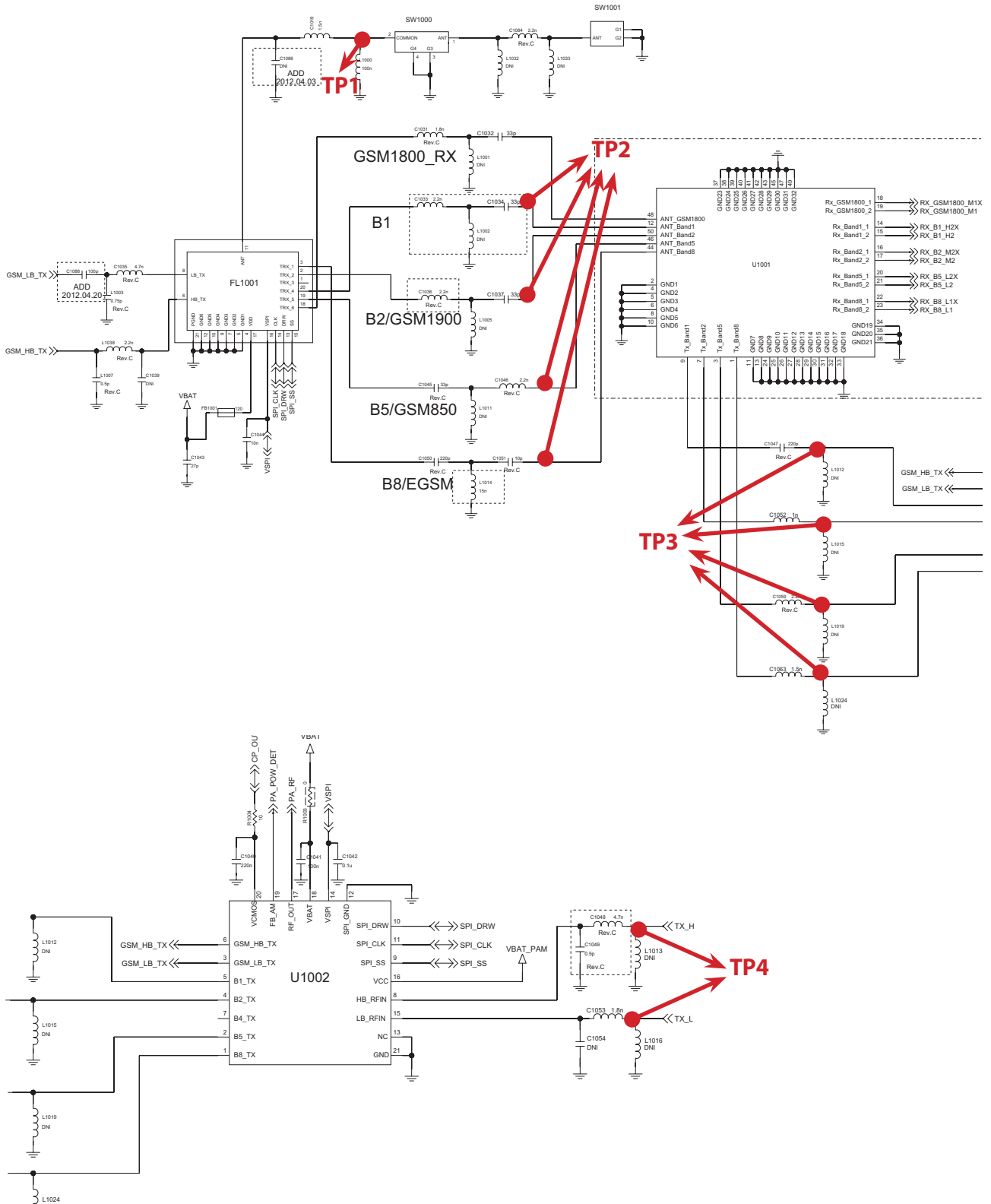


4.4.1. Checking RF TX Level (WCDMA)



Test Point (TX Level)

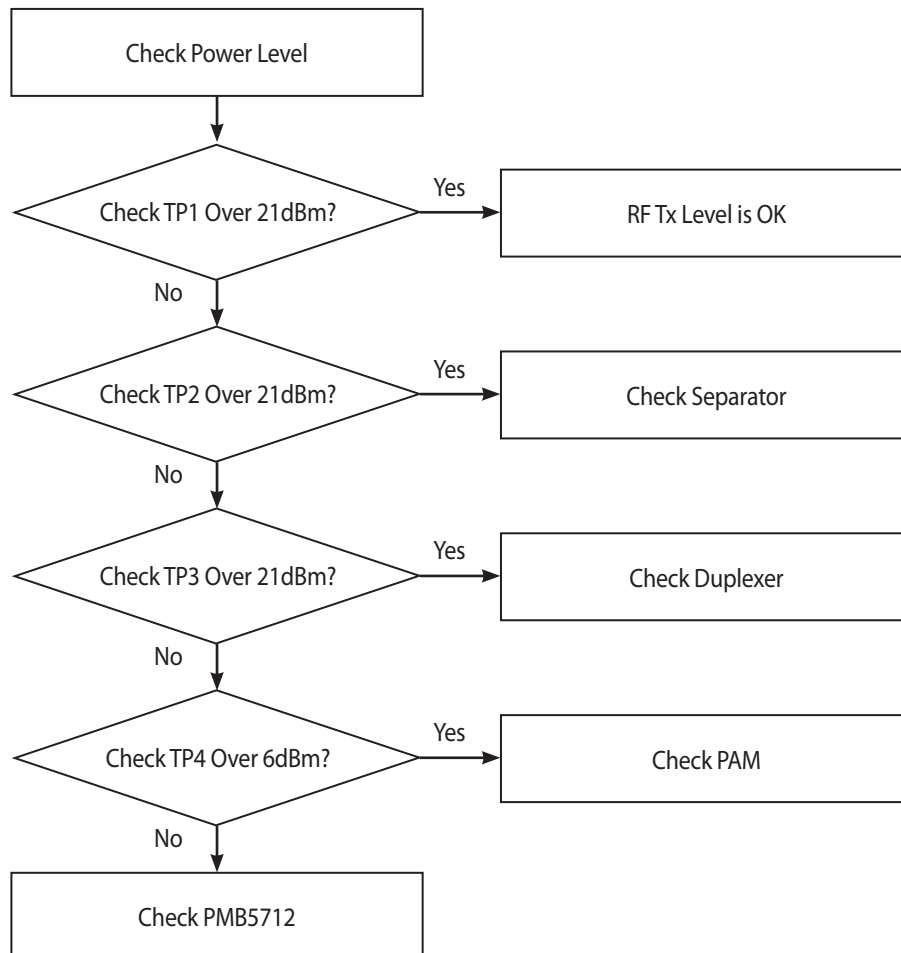
4. TROUBLE SHOOTING



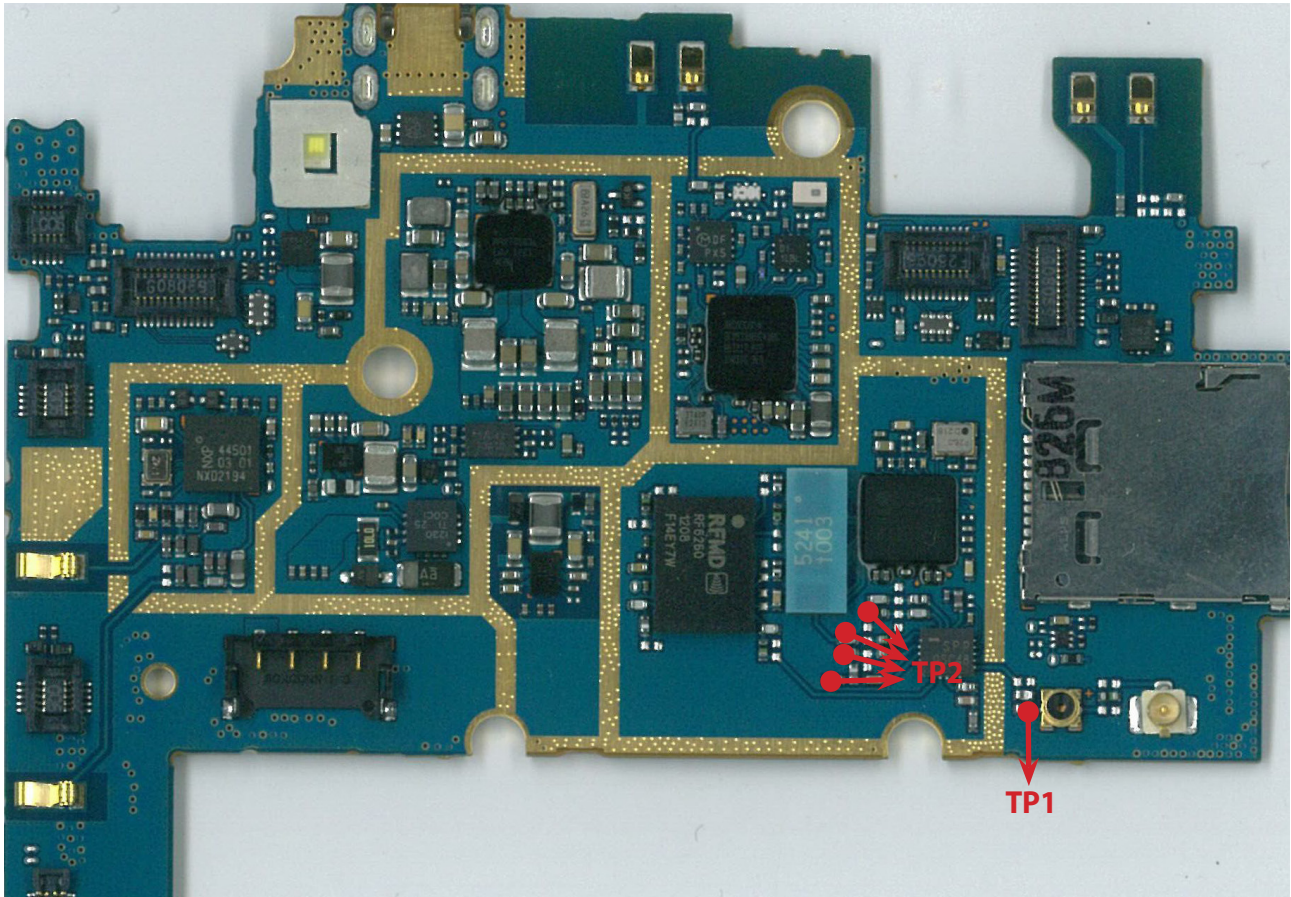
Schematic of WCDMA Band1,2,5,8 Tx Block

4. TROUBLE SHOOTING

For testing, Max power output is needed.

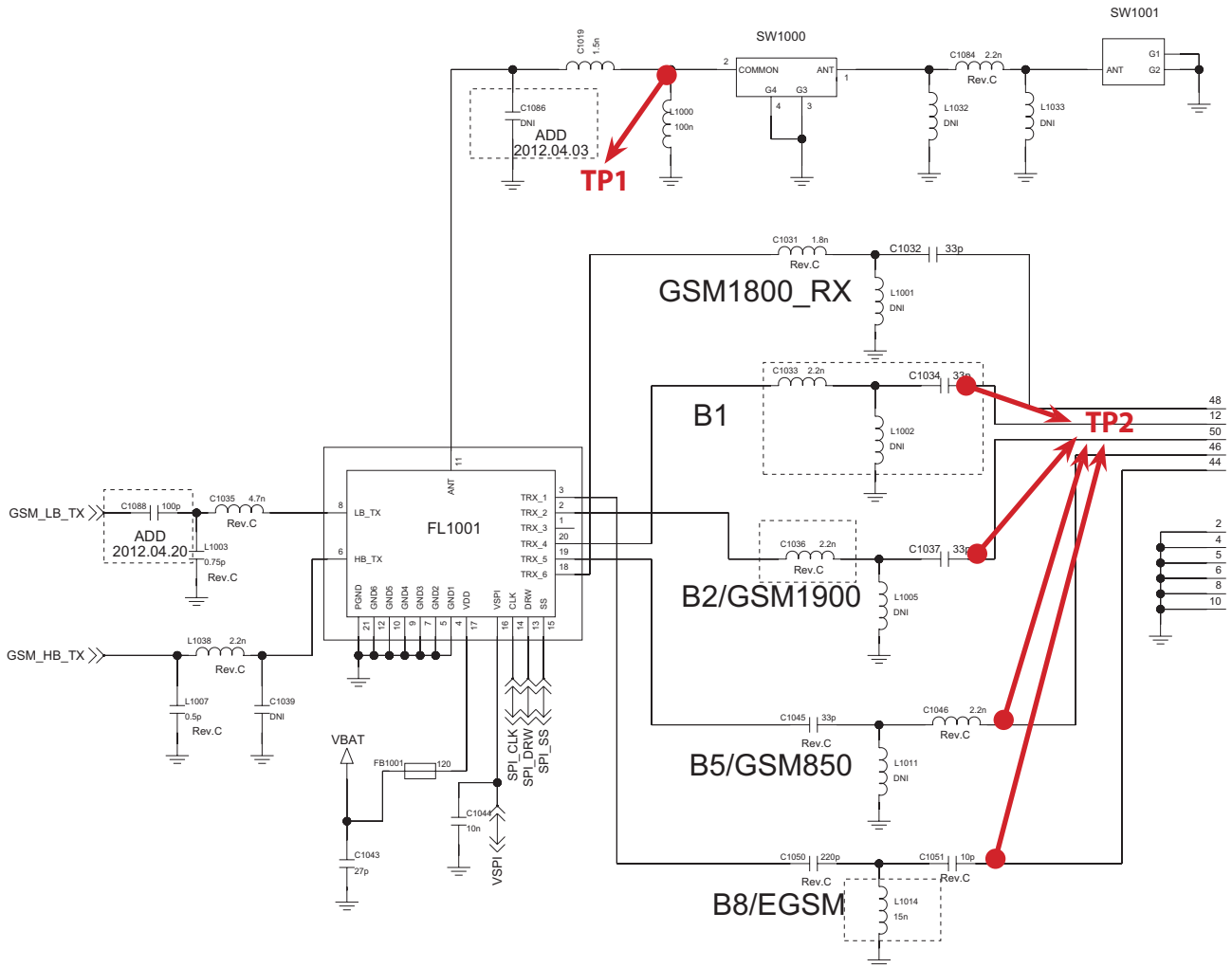


4.4.2. Checking RF Rx Level (WCDMA)



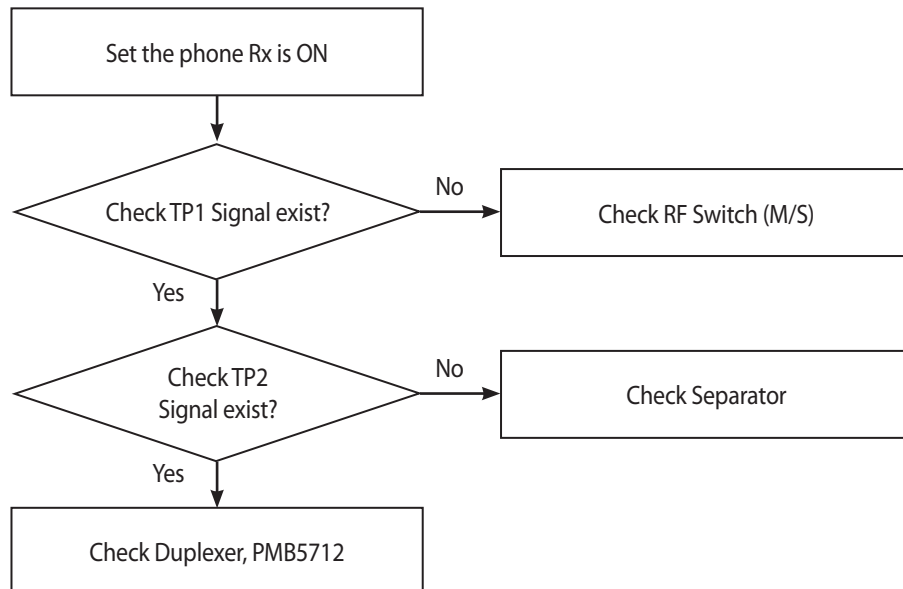
Test Point (Rx Level)

4. TROUBLE SHOOTING

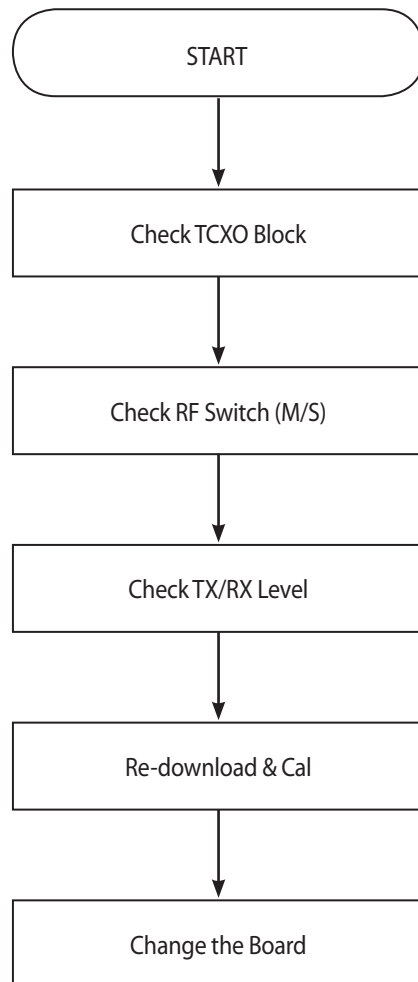


Schematic of WCDMA Band1,2,5,8 Rx Block

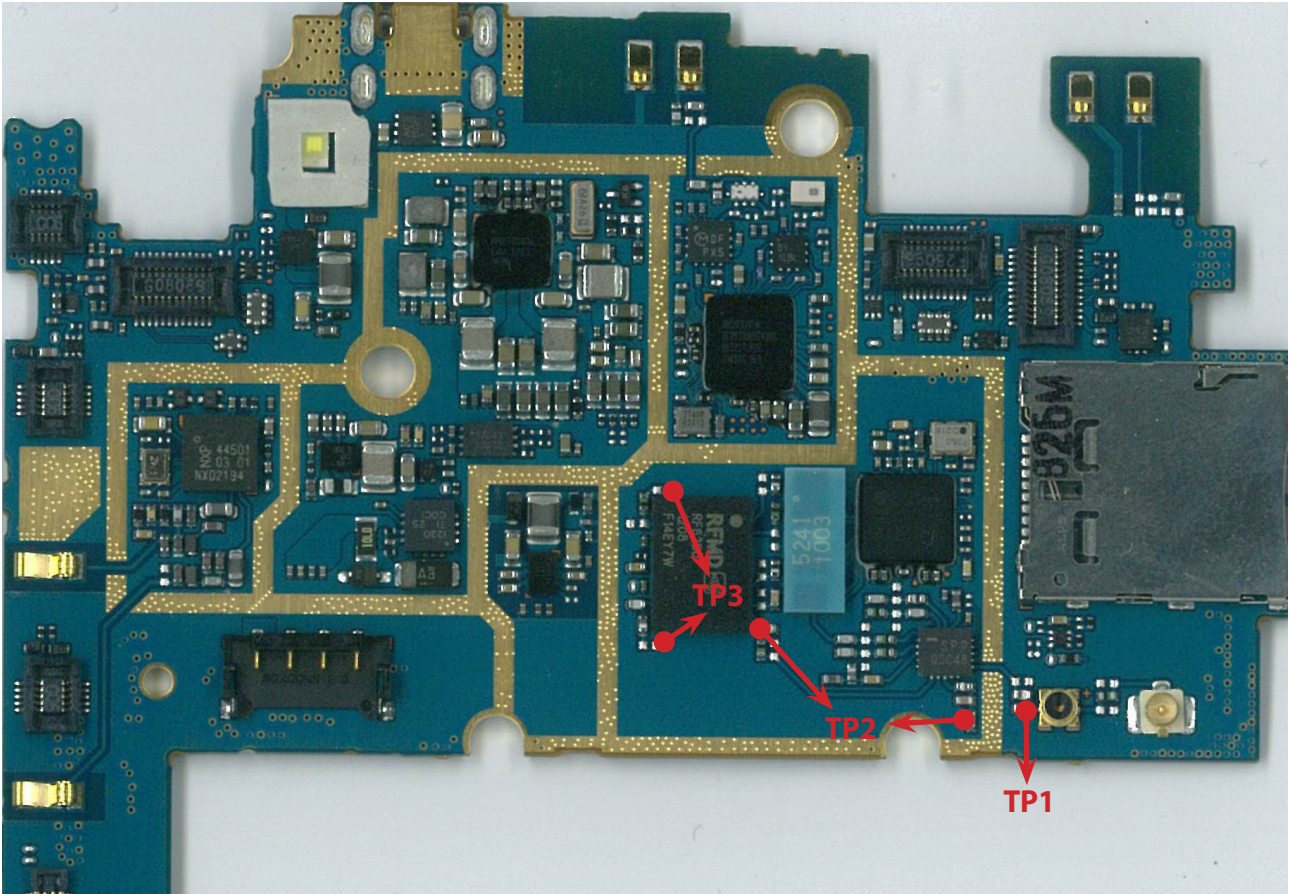
4. TROUBLE SHOOTING



4.5 Checking GSM Block

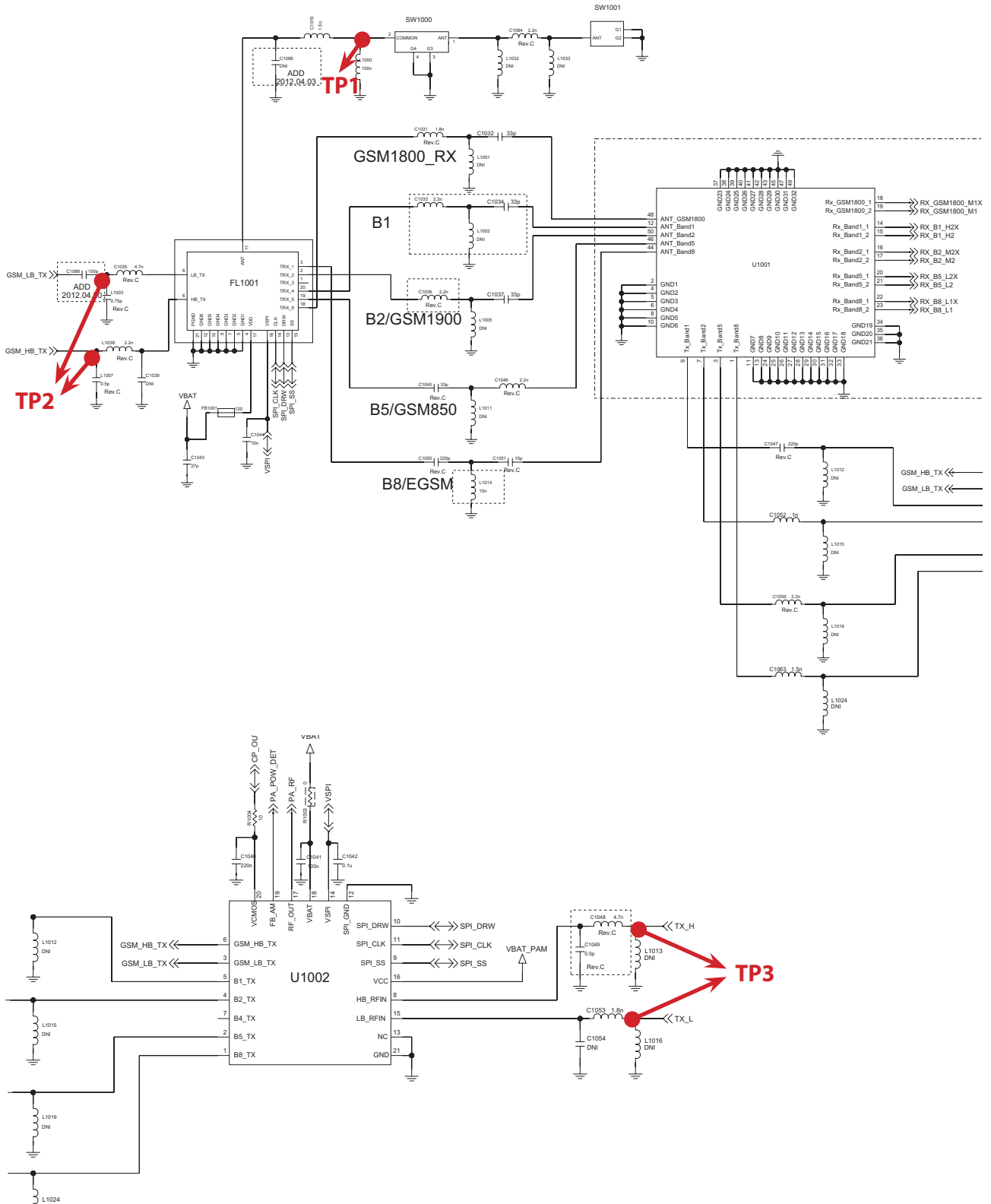


4.5.1 Checking RF Tx Block



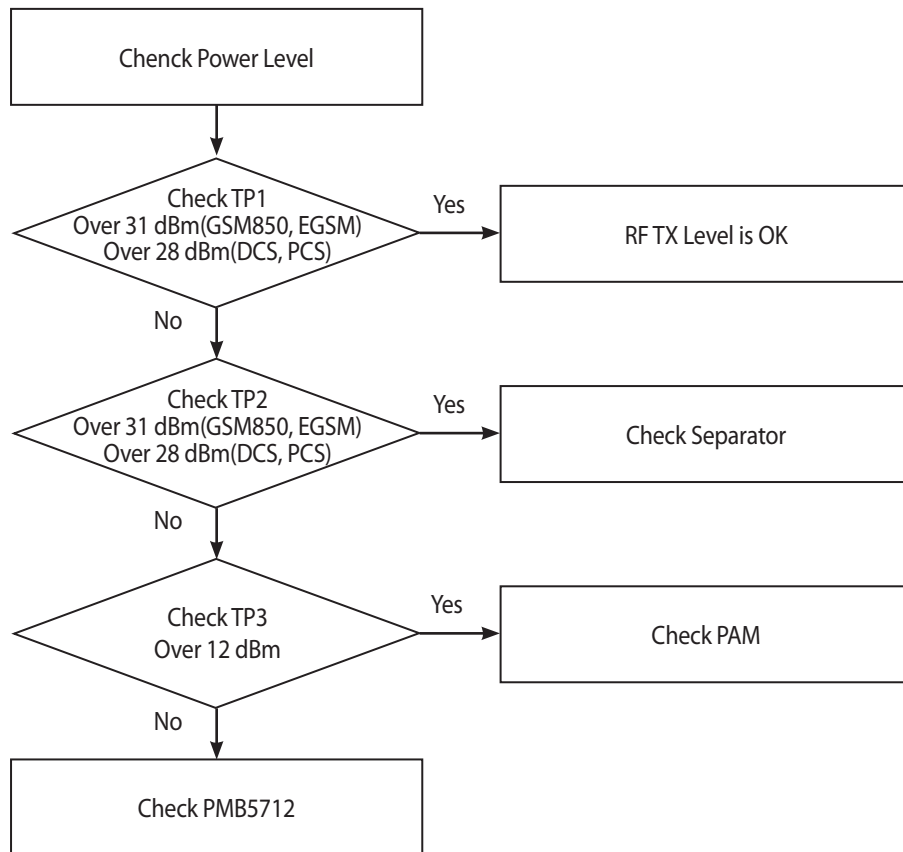
Test Point (Tx Level)

4. TROUBLE SHOOTING

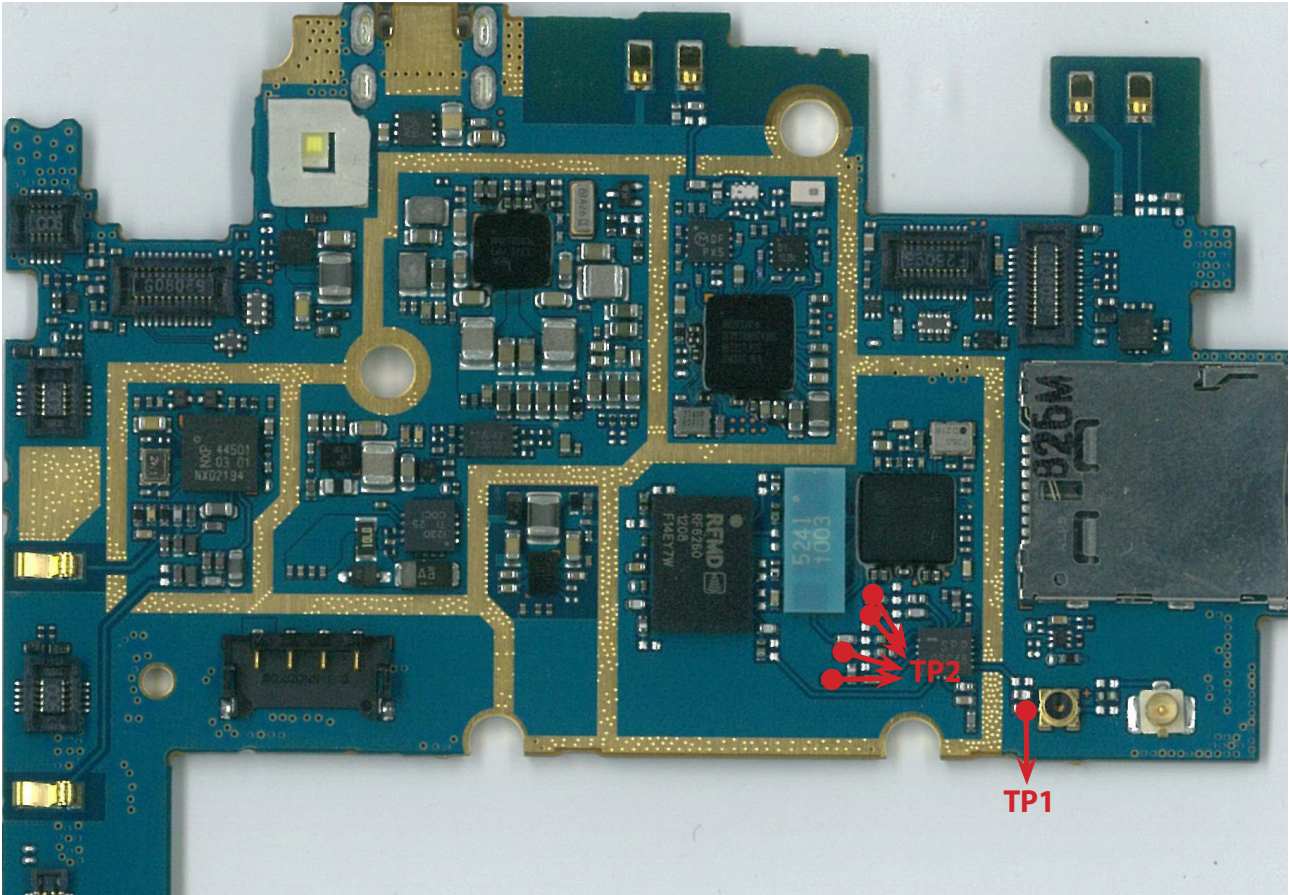


Schematic of GSM850/EGSM/DCS/PCS Tx Block

For testing, Max power output is needed



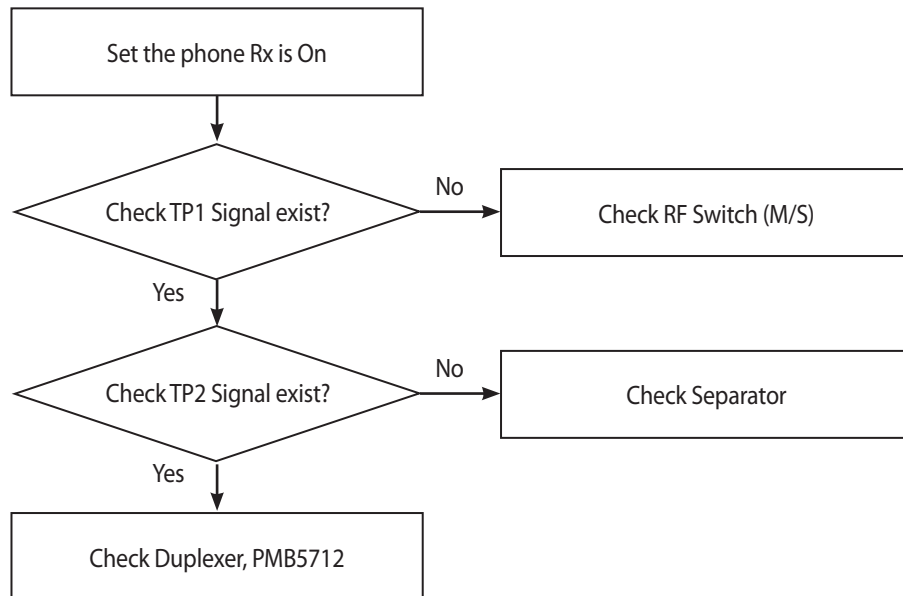
4.5.2 Checking RF Rx Block



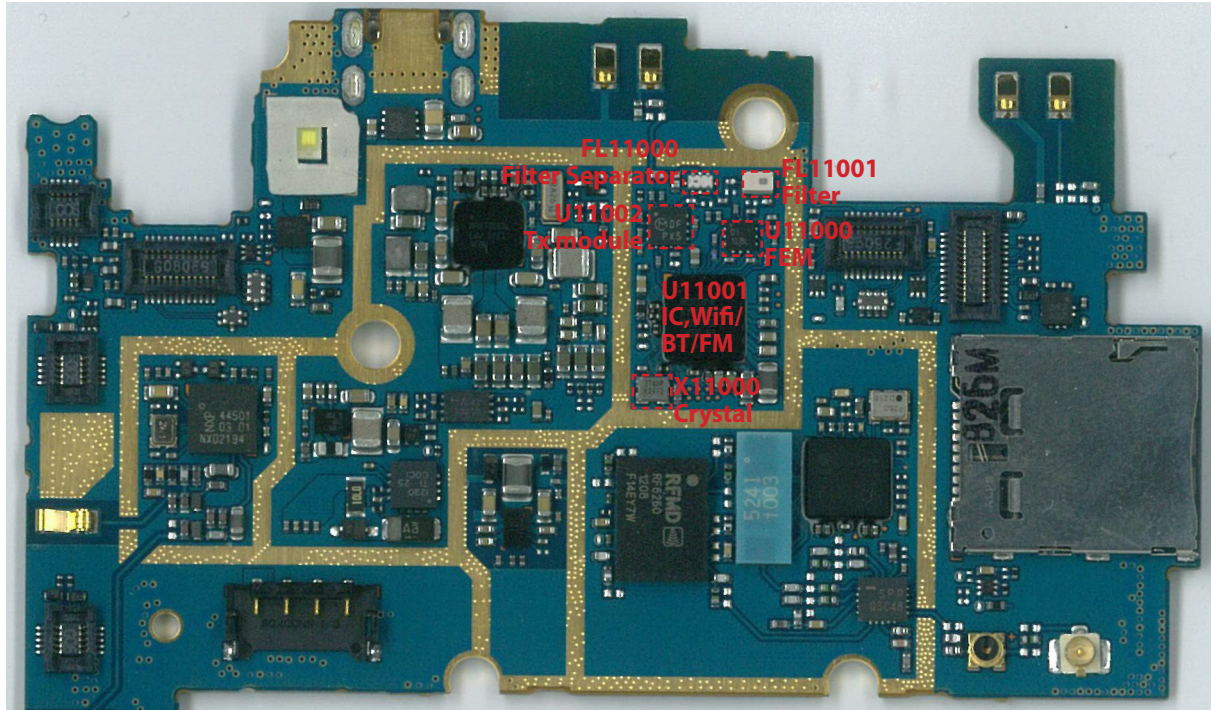
Test Point (Rx Level)



4. TROUBLE SHOOTING

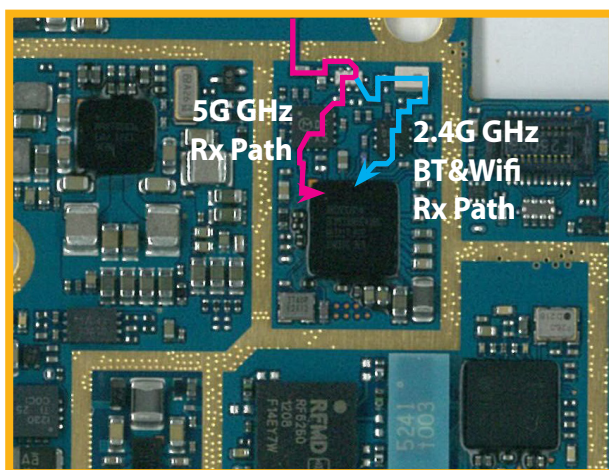
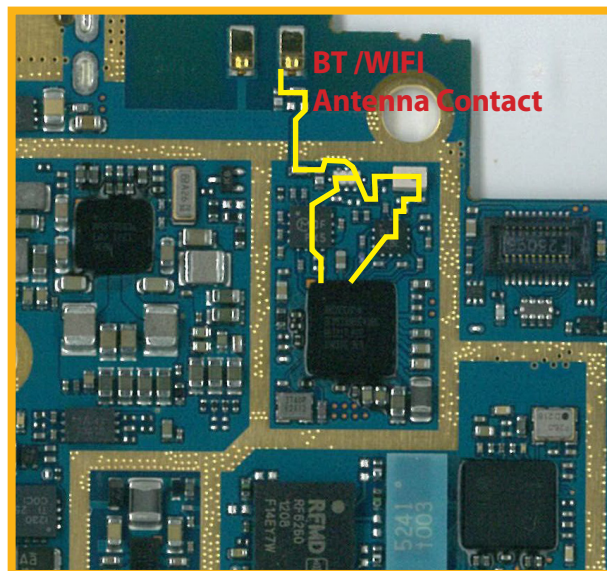


4.6. Wifi/BT/FM Module

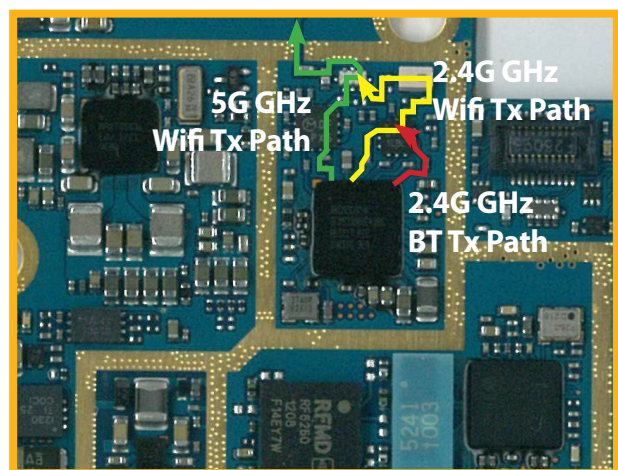


Reference No.	Description	Reference No.	Description
FL11000	Filter Separator	U11002	Tx module
FL11001	Filter	X11000	Crystal
U11000	FEM	U11001	IC, Wifi/BT/FM

4.6.2 Wifi/BT/FM Signal Path



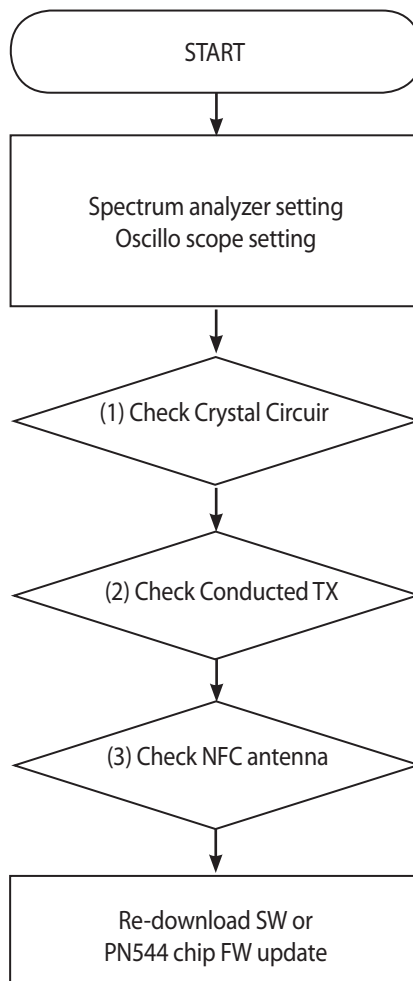
BT Rx / Wifi Rx Signal Path



BT Tx / Wifi Tx Signal Path

4.7 NFC trouble

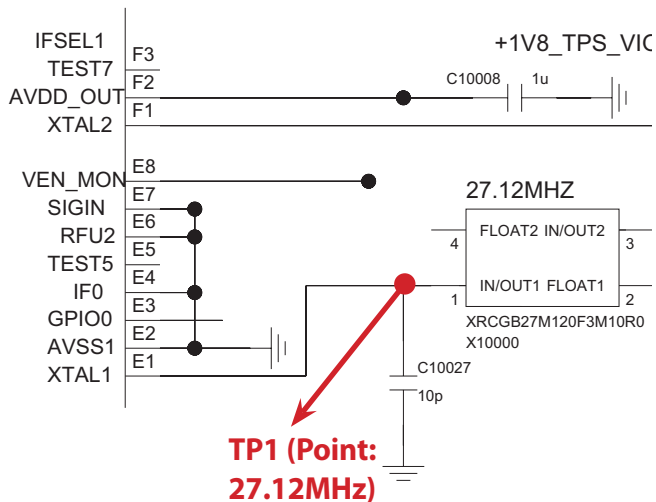
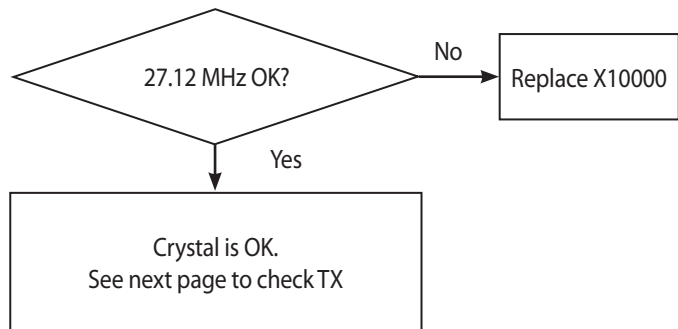
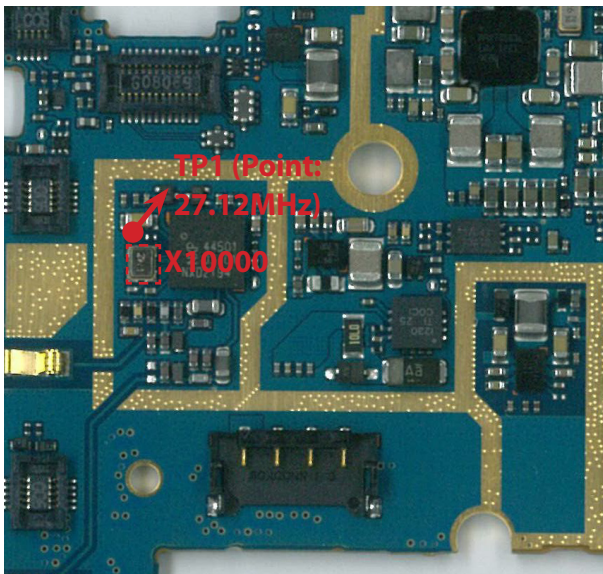
Check out the setting menu on the phone. If not, check Test points shown on the pictures.



4.7.1 Checking Crystal Circuit

Enter test mode `***#895***` -> NFC Test -> Press OK to Start ->

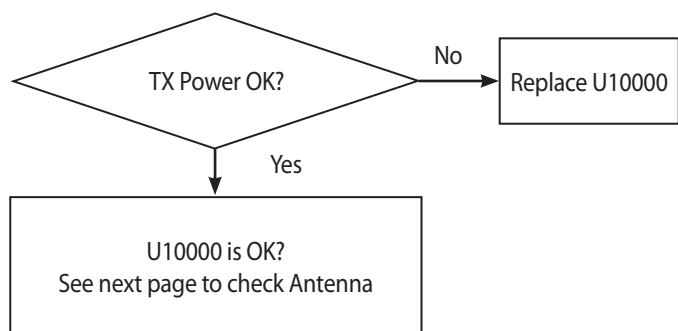
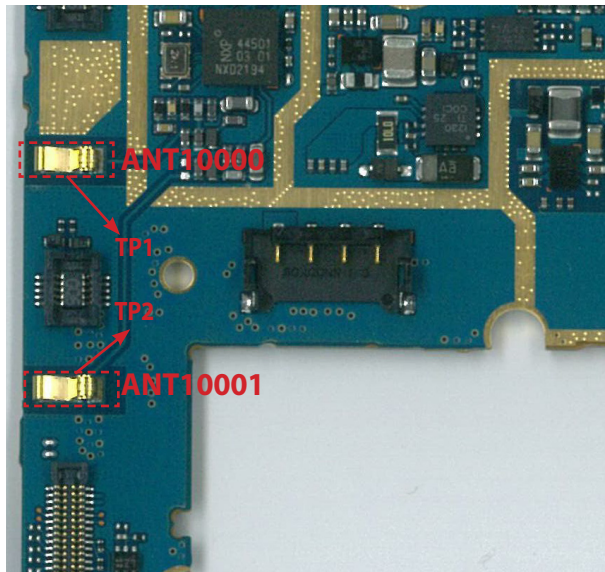
Generate Continuous Emission -> Check pop up "Test success": CE Test Start



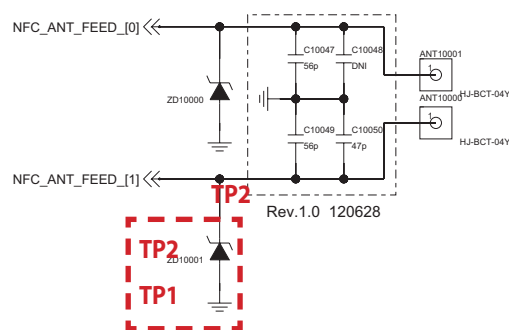
4.7.2 Checking conducted TX Power

Enter test mode `***#895***` -> NFC Test -> Press OK to Start ->

Generate Continuous Emission -> Check pop up "Test success": CE Test Start

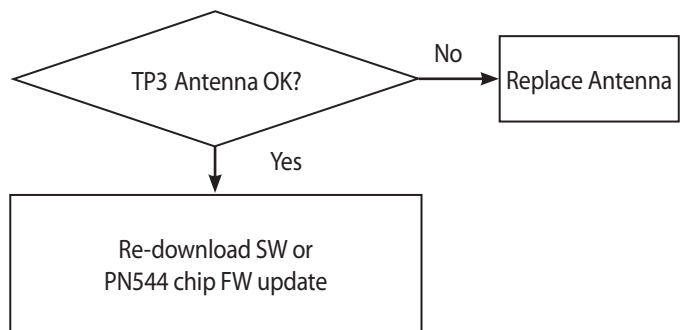
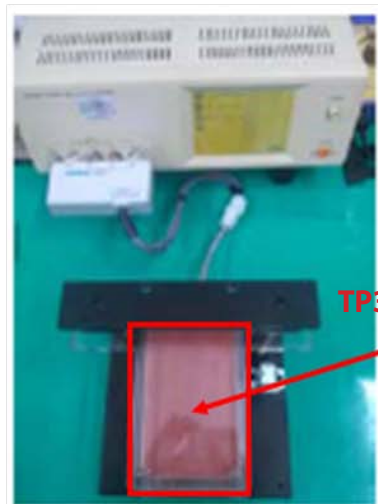


NFC ANT. FEEDING



4.7.3 Checking NFC Antenna (Battery Cover)

Using LCR meter equipment (Hioki 3532 LCR meter)



LCR	Inductance(uH)	Capacitance(nF)	Resistance(Ω)
Antenna	1.69 \pm 10%	14.87 \pm 10%	Under 1 Ω

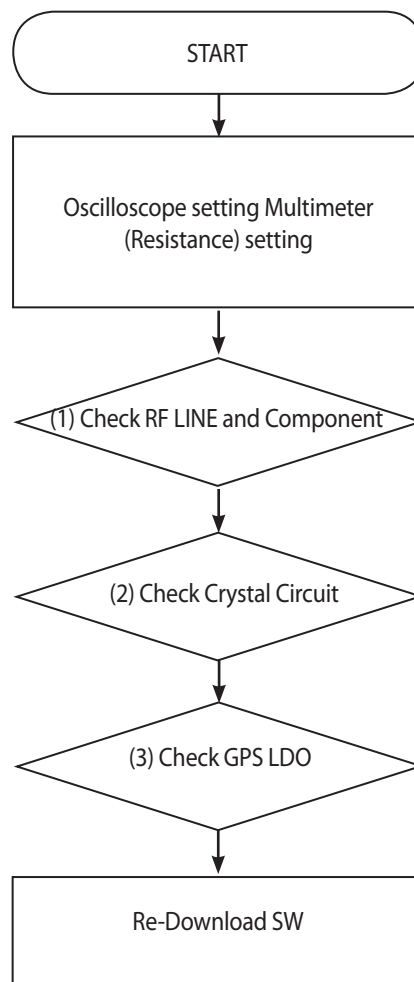
A displayed data isn't absolute value.

It has a deviation by means of equipment environment.

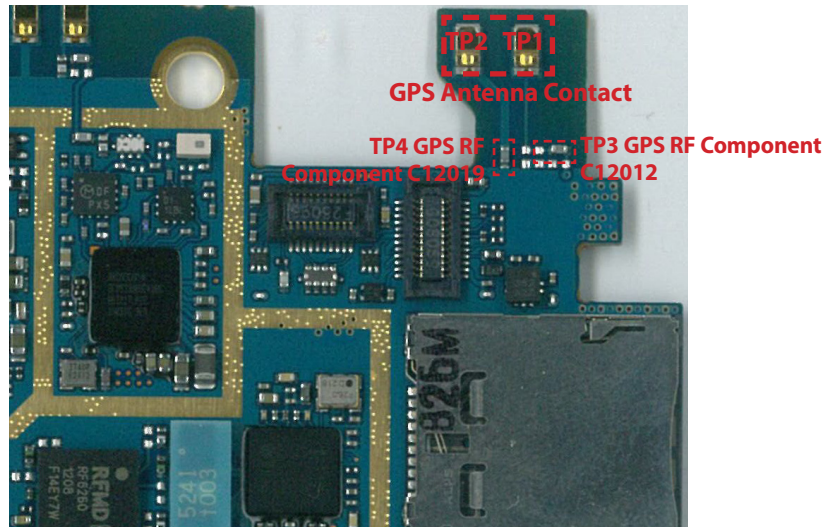
Therefore it should be compared with a normal sample.

4.8 GPS trouble

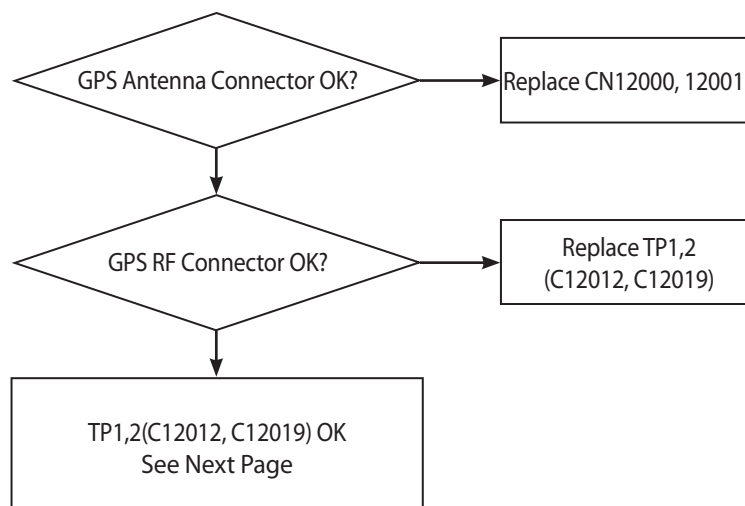
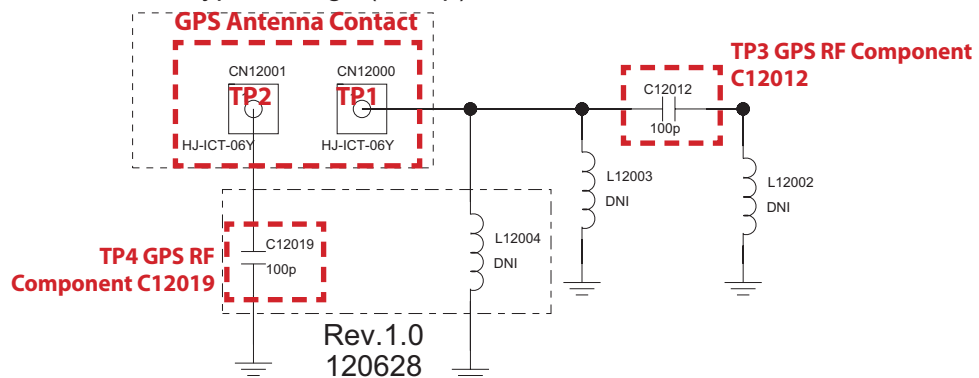
Check out the setting menu on the phone. If not, check Test points shown on the pictures.



4.8.1 Checking RF Line and Components



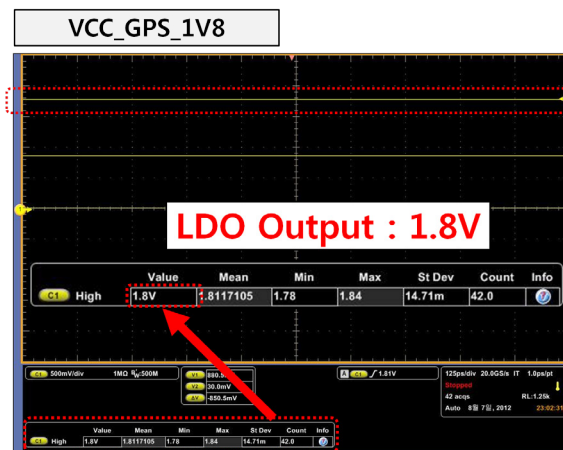
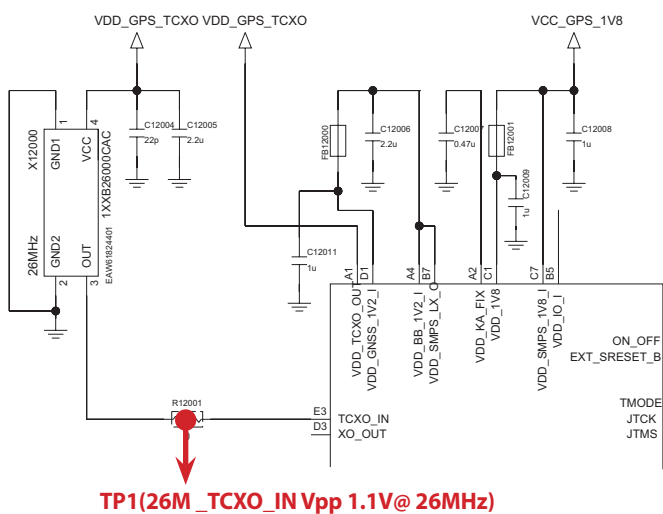
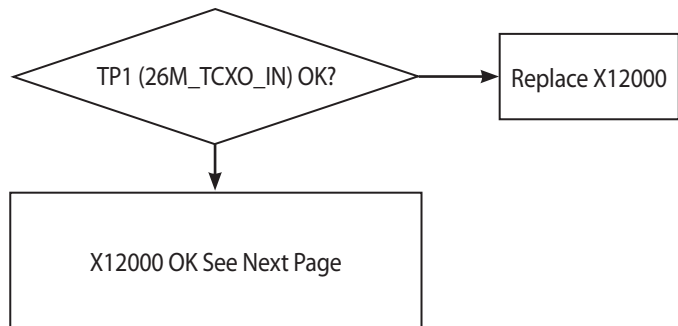
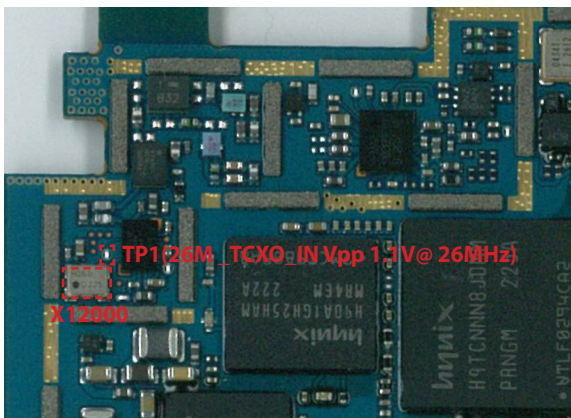
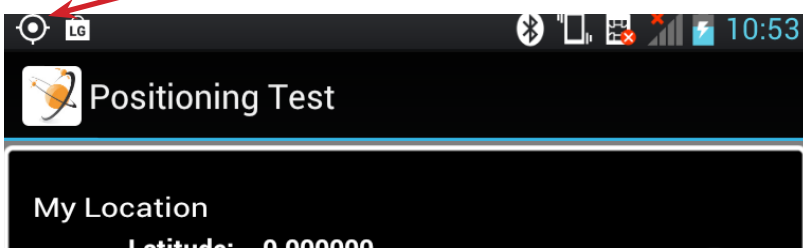
2012.05.14
Contact Type Change (C-Clip)



4.8.2 Checking Crystal Circuit

System Setting -> Location Service -> GPS satellites Check -> Enter test mode `***#895#***` -> GPS Test -> Positioning Test -> Setting Key 'Start GPS'

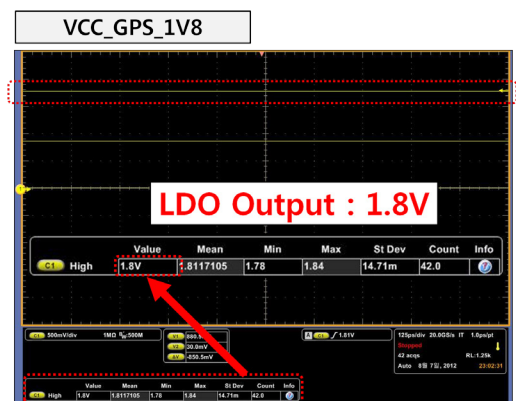
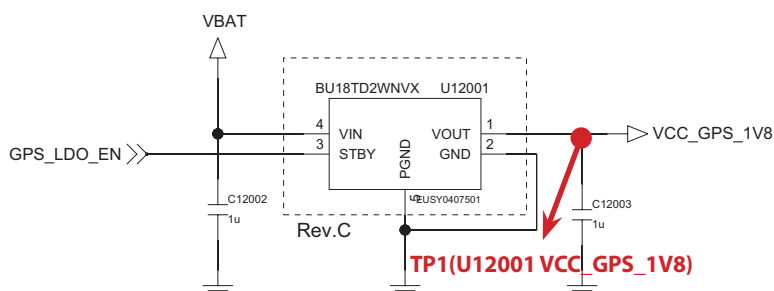
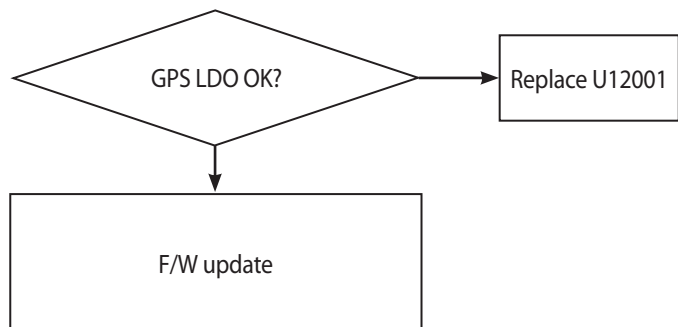
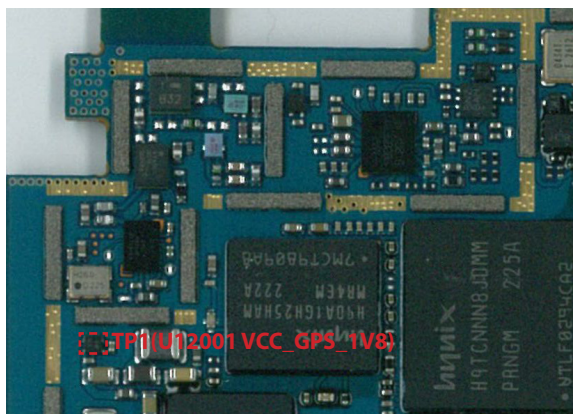
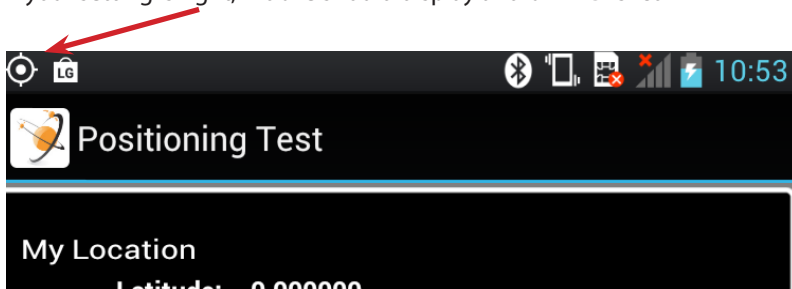
If Setting is right, mobile should display and blink GPS icon



4.8.2 Checking GPS LDO

System Setting -> Location Service -> GPS satellites Check -> Enter test mode *##895##* -> GPS Test -> Positioning Test -> Setting Key 'Start GPS'

If your setting is right, mobile should display and blink GPS icon

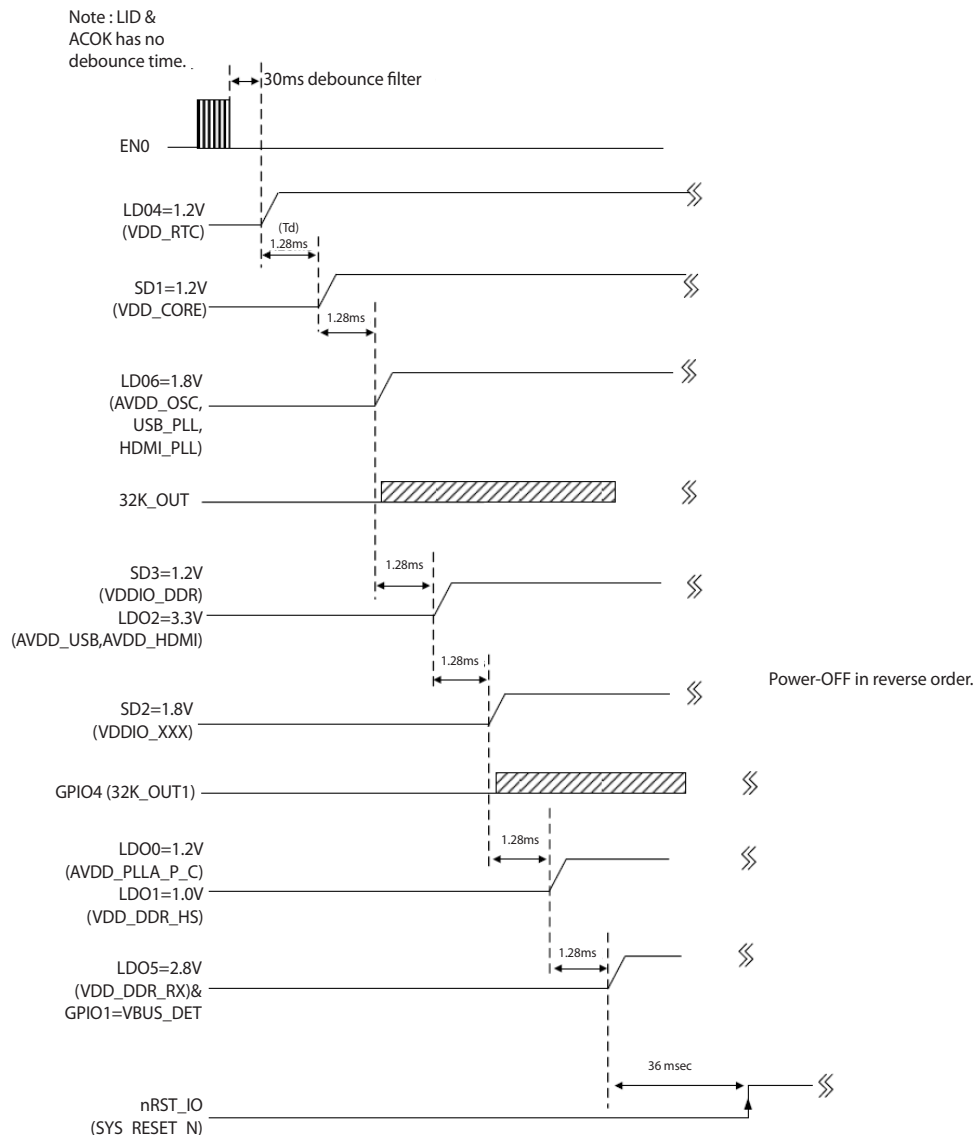


4.9 Circuit Power ON trouble Shooting

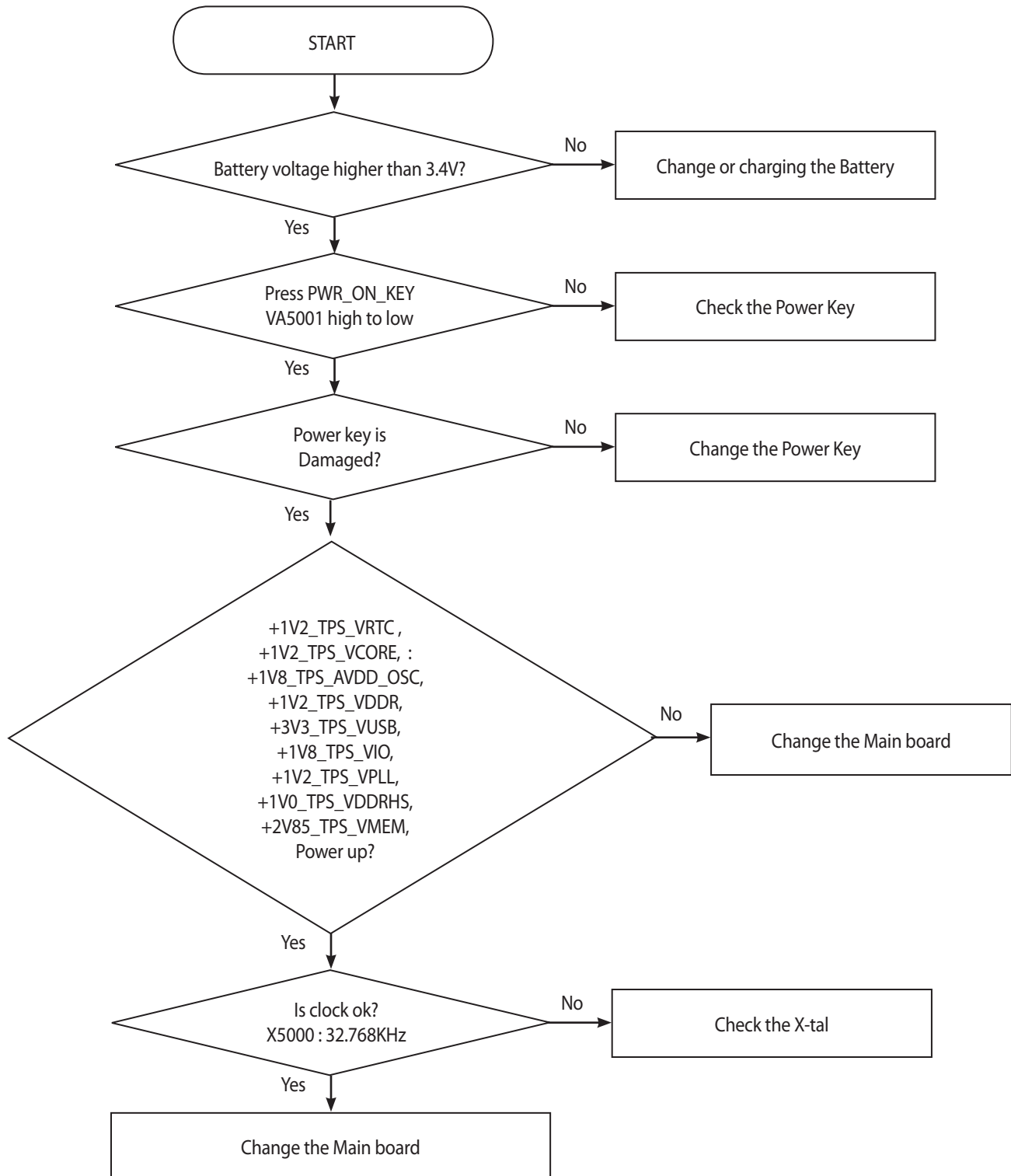
The main power source of LGP895 is provided by MAX77663.

Power ON sequence of LGP895 is,

PWR key press -> PWR_ON_KEY go to low (VA102) -> MAX77663 Power Up -> +1V2_TPS_VRTC (C5014) -> +1V2_TPS_VCORE (C5023) -> +1V8_TPS_AVDD_OSC(C5015) -> AP_32K_CLK_IN(R5015) -> +1V2_TPS_VDDR(C5028), +3V3_TPS_VUSB(C5010) -> +1V8_TPS_VIO(C5027) -> GPS_32K_CLK_IN, WLAN_32K_CLK_IN (R5036) -> +1V2_TPS_VPLL(C5008), +1V0_TPS_VDDRHS(C5009) -> +2V85_TPS_VMEM(C5011), AP_VBUS_DET(R5030) -> AP_SYS_RESET_N (R5008) goes to high



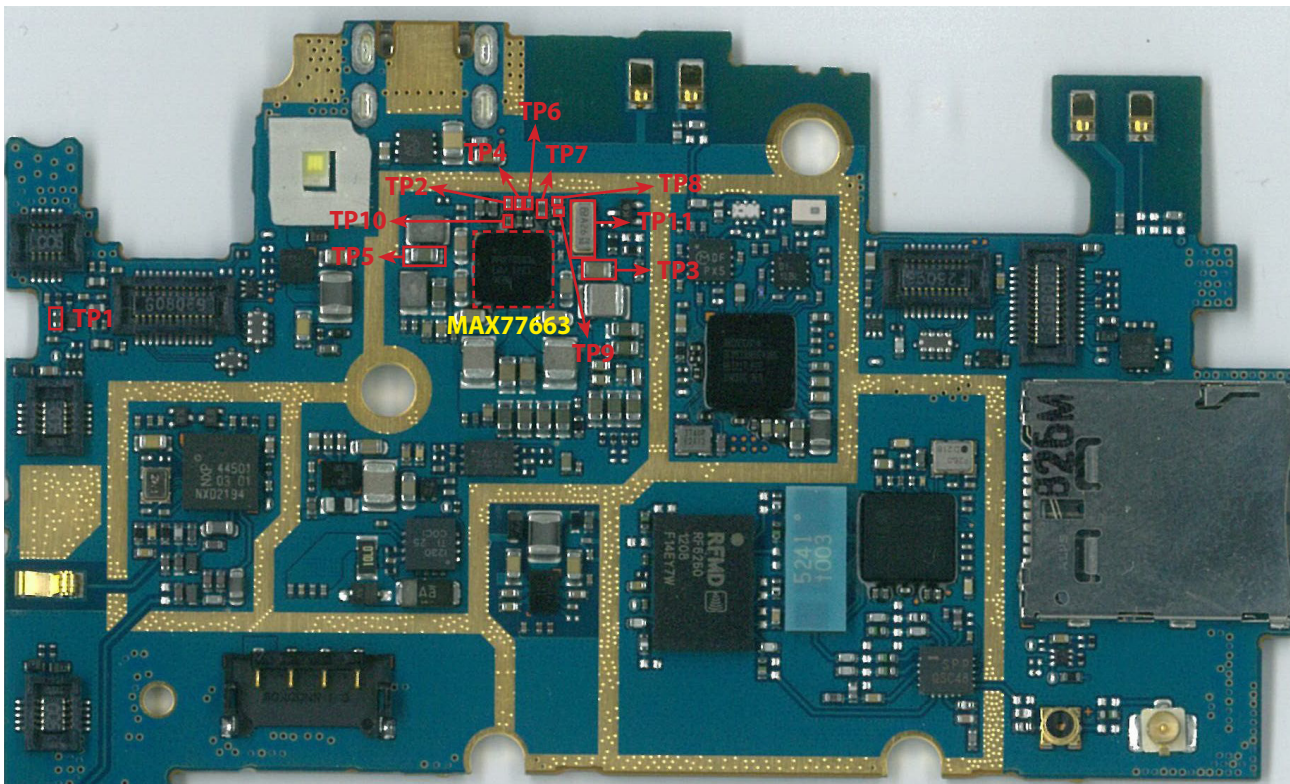
4. TROUBLE SHOOTING



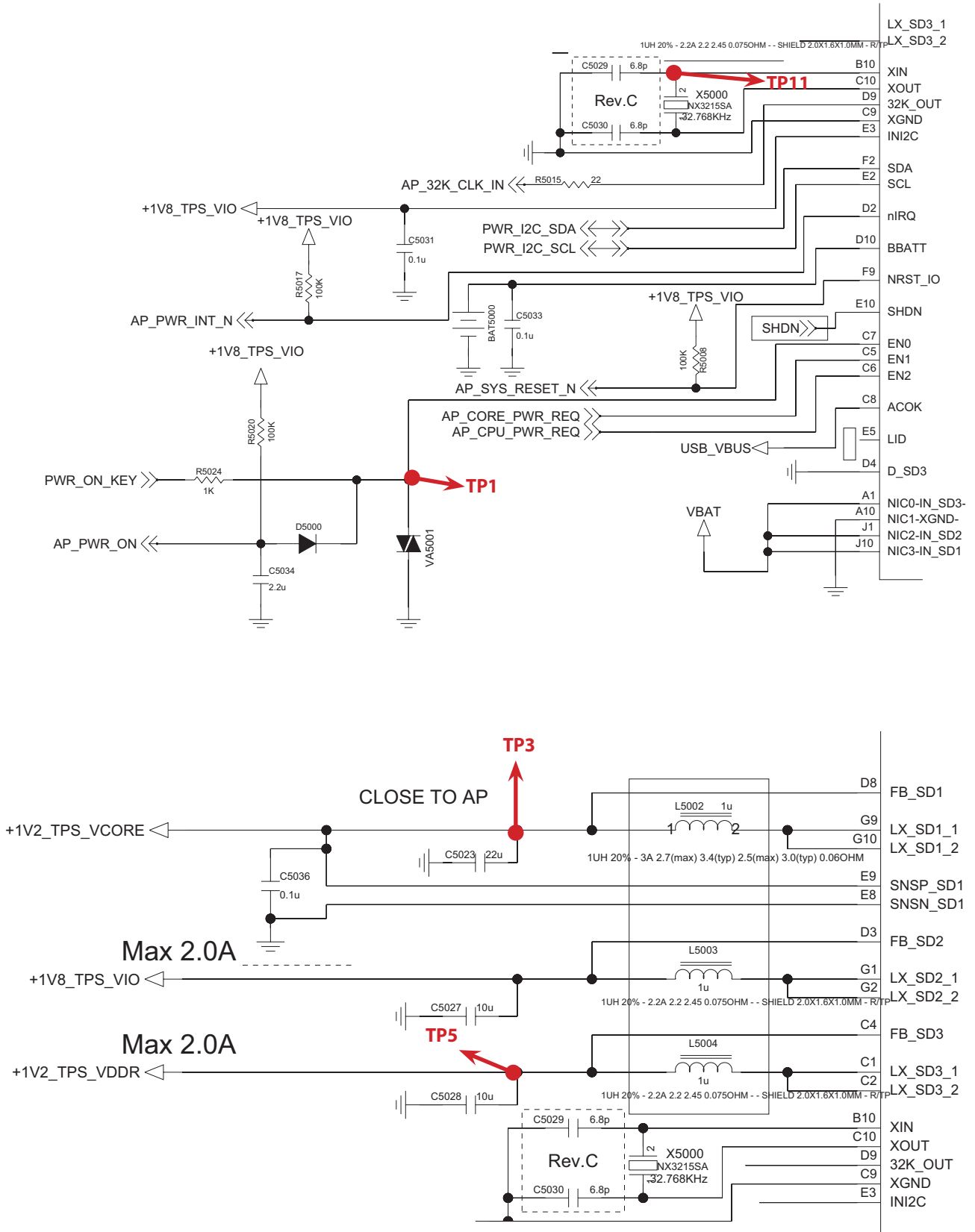
4. TROUBLE SHOOTING

TP1 : Power_On_KEY : VA5001
TP2 : +1V2_TPS_VRTC : C5014
TP3 : +1V2_TPS_VCORE, : C5023
TP4 : +1V8_TPS_AVDD_OSC : C5015
TP5 : +1V2_TPS_VDDR, : C5028
TP6 : +3V3_TPS_VUSB, : C5010
TP7 : +1V8_TPS_VIO, : C5002
TP8 : +1V2_TPS_VPLL : C5008
TP9 : +1V0_TPS_VDDRHS : C5009
TP10 : +2V85_TPS_VMEM, : C5011
TP11 : X5000

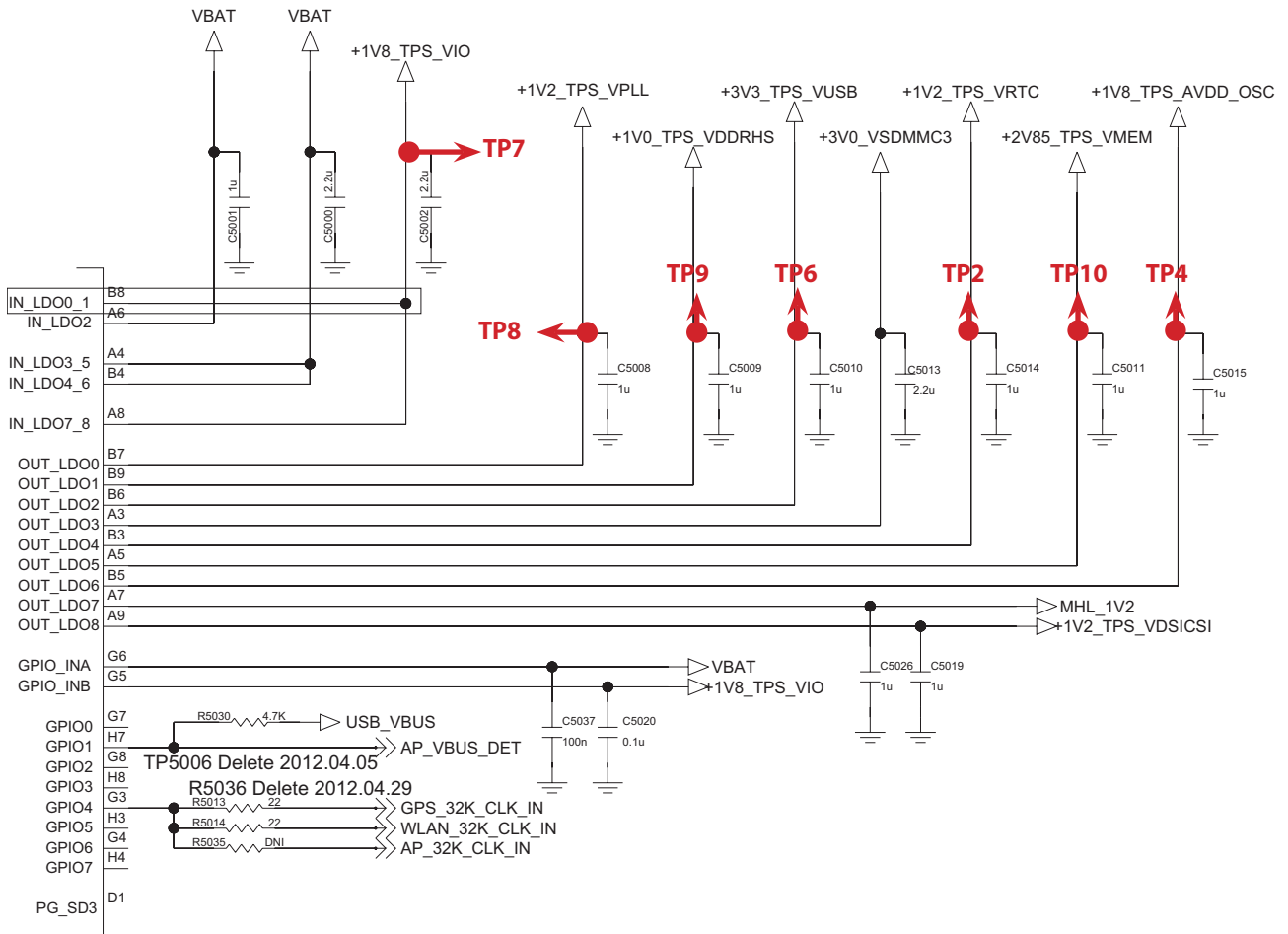
Main PCB BOTTOM place



4. TROUBLE SHOOTING



4. TROUBLE SHOOTING



a. Current flow

b. Charging current setting

[illegible]

- Micor USB connector
- Over protection IC
- Charging IC
- Battery

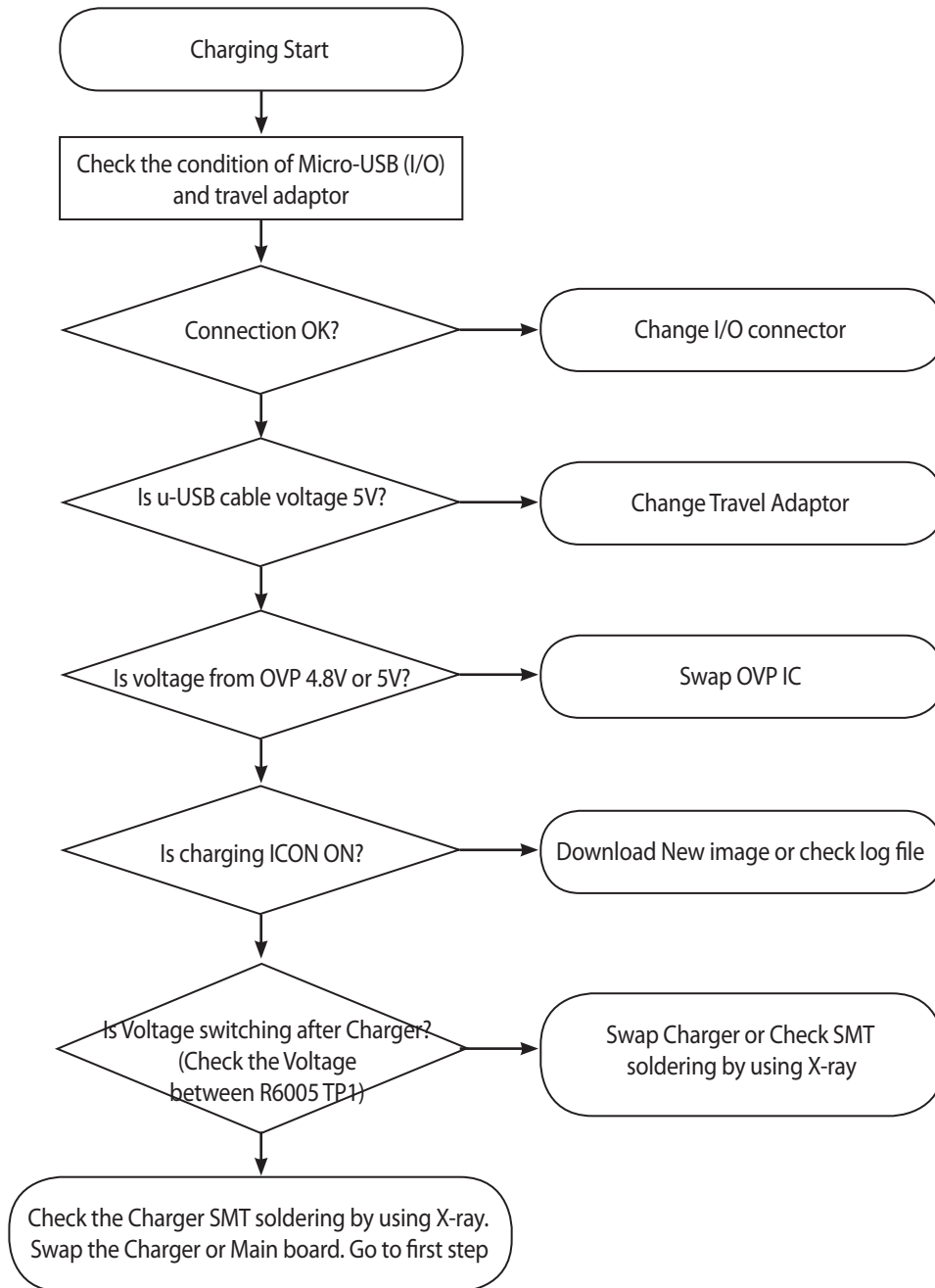
- Connect Travel Adaptor (Charging Cable) to Micro USB connector.
- Current flow to OVP IC to be protected from over voltage

- Current from charging IC flows to system and battery

- Connect TA to P895(with battery)

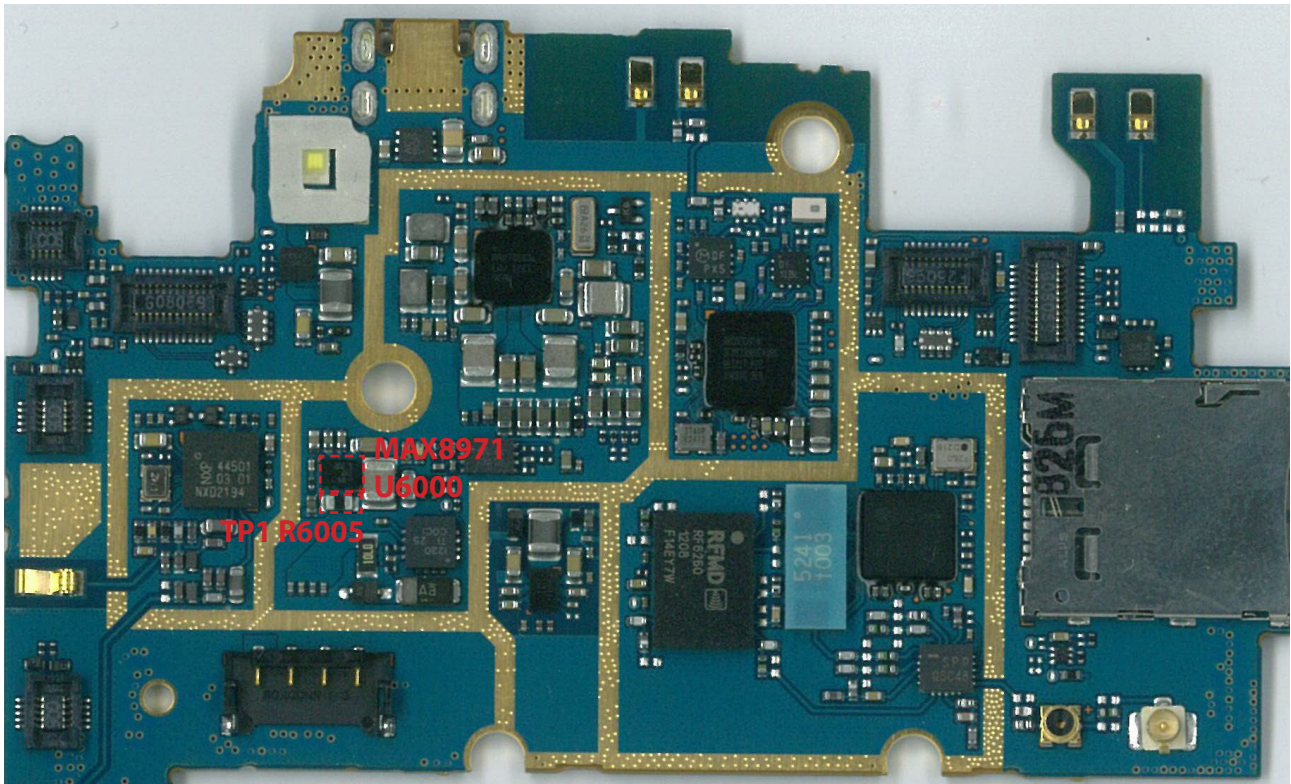
- -Check connection between TA(USB cable) and LGP895

4. TROUBLE SHOOTING

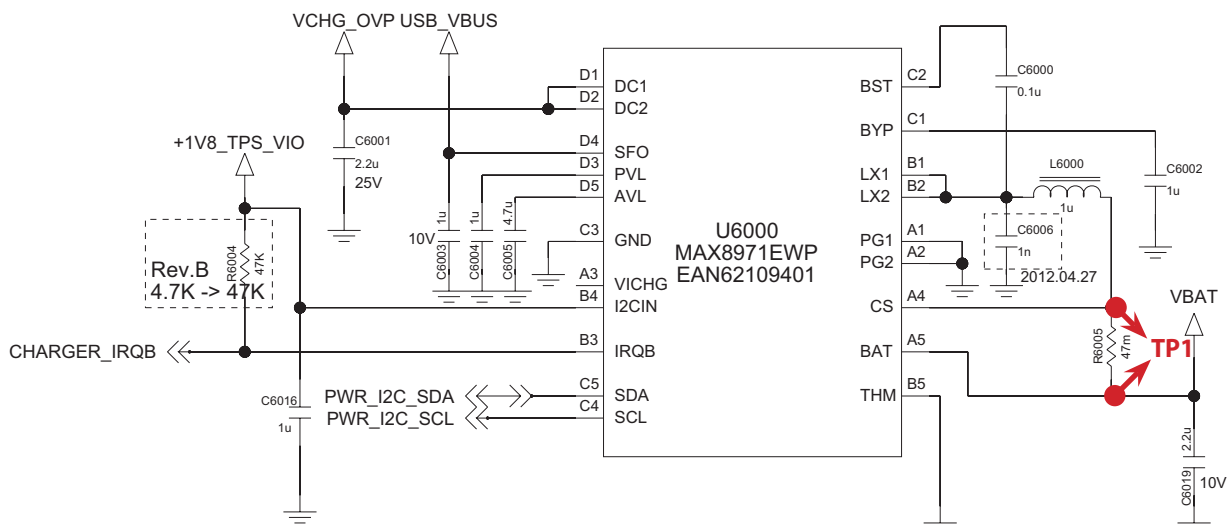


Charger Troubleshoot Flow

Bottom of LGP895 TP1: R6005



CHARGING IC



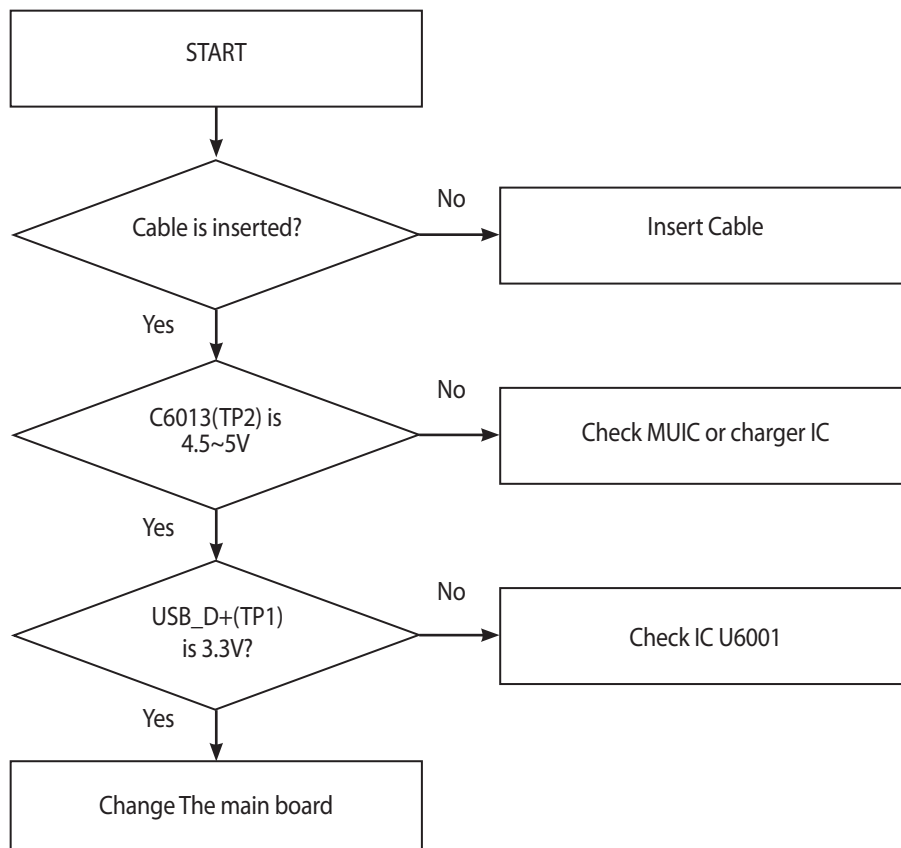
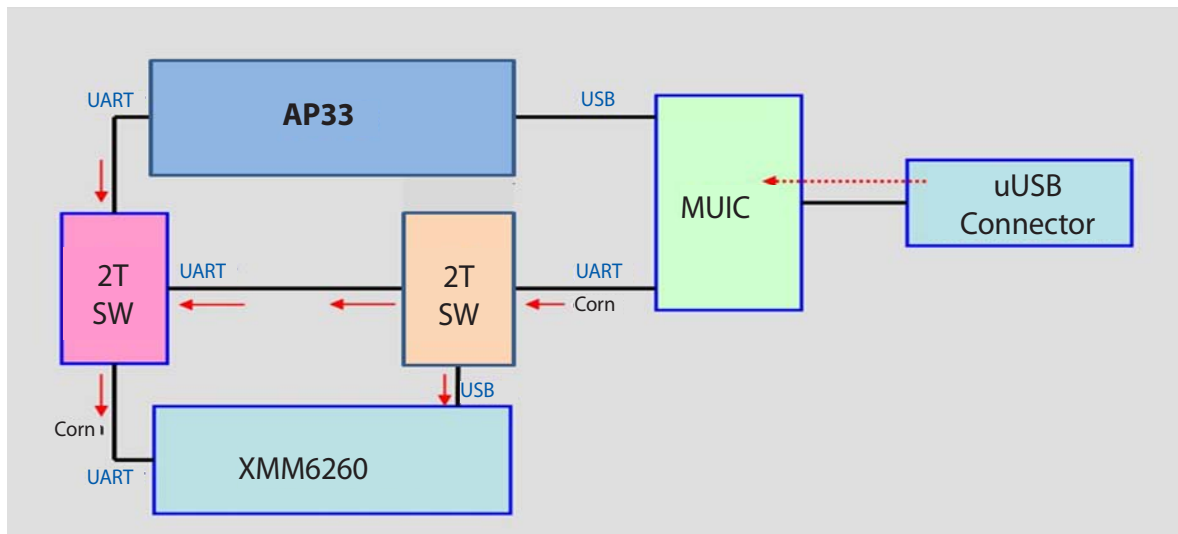
4.11 USB Trouble shooting

The sequence of LGP895 USB is,

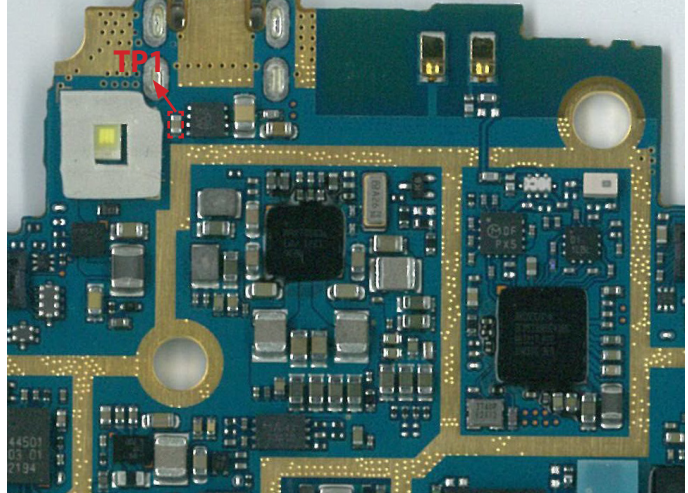
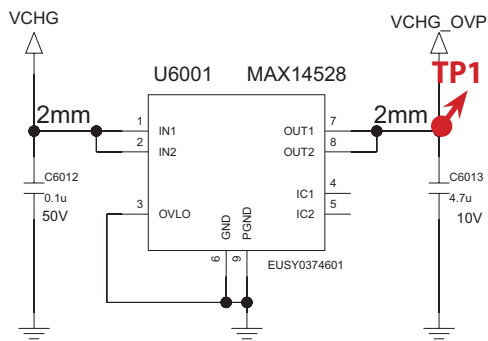
USB connected to

LGP895 -> USB_VBUS(C6027) goes to 4.5V~5V -> USB_D+ go to 3.3V -> USB work

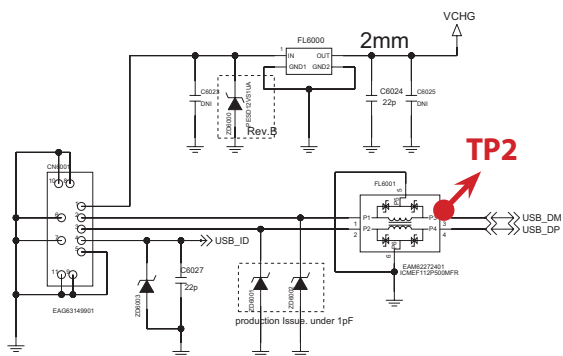
Block Diagram of USB & UART connection is shown below (TP1 : C6013, TP2, FL6001)



OVP_VCHG



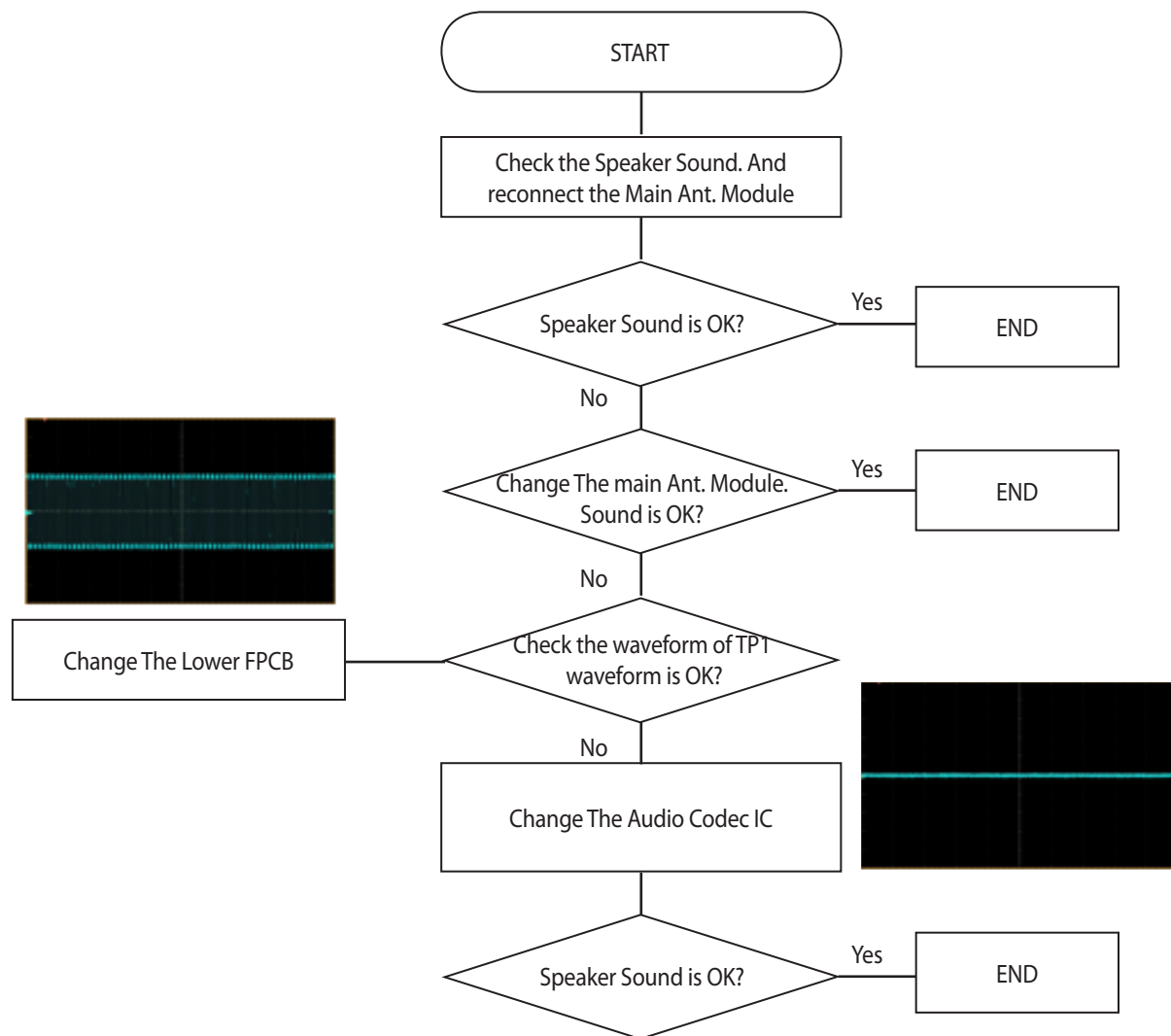
uUSB 5 pin connector



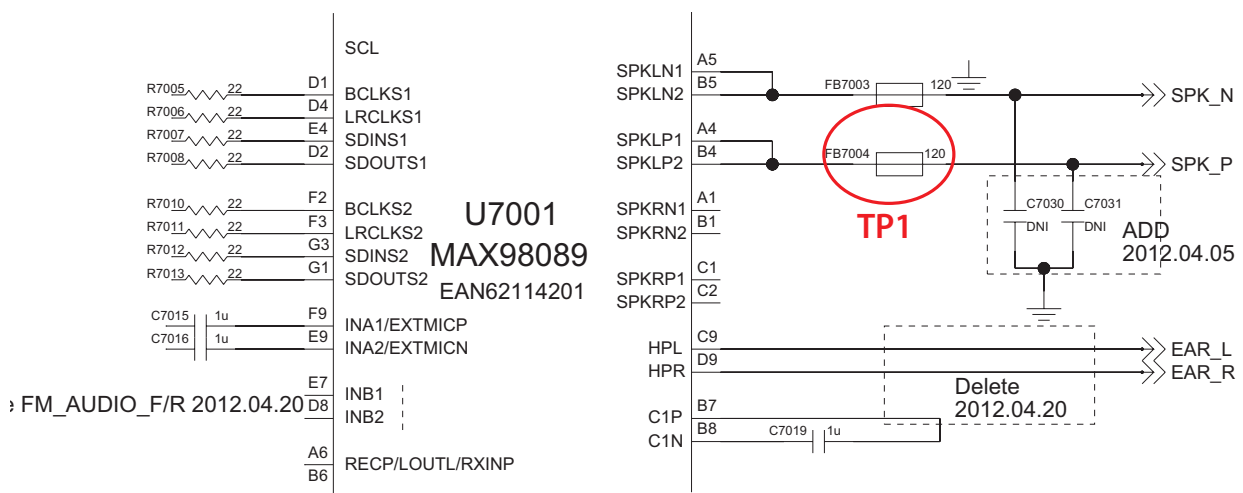
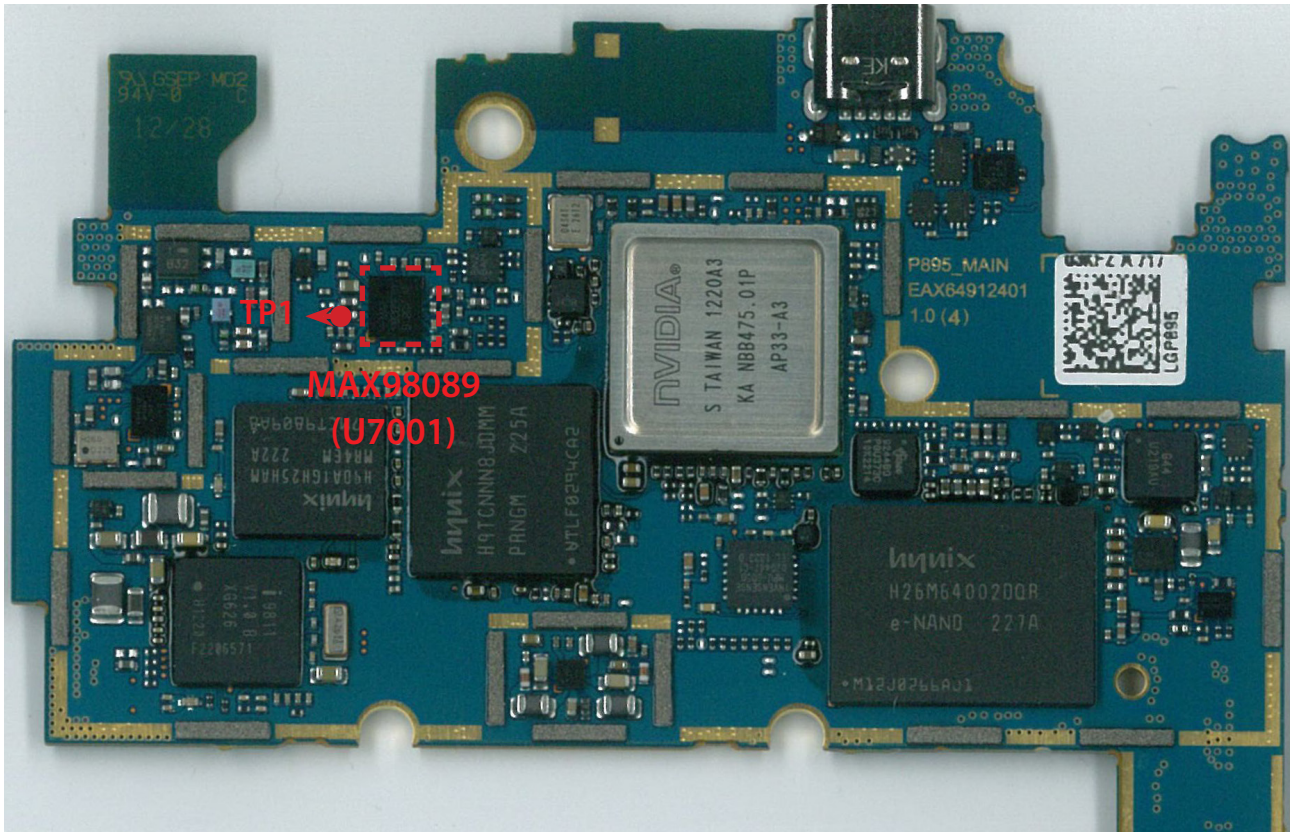
4.12 Audio troubleshooting

4.12.1 Speaker troubleshooting

Speaker control signals are generated by AP33 (U3000), amplified by MAX98089 (U7000), and Power is supplied by Battery (VBAT).

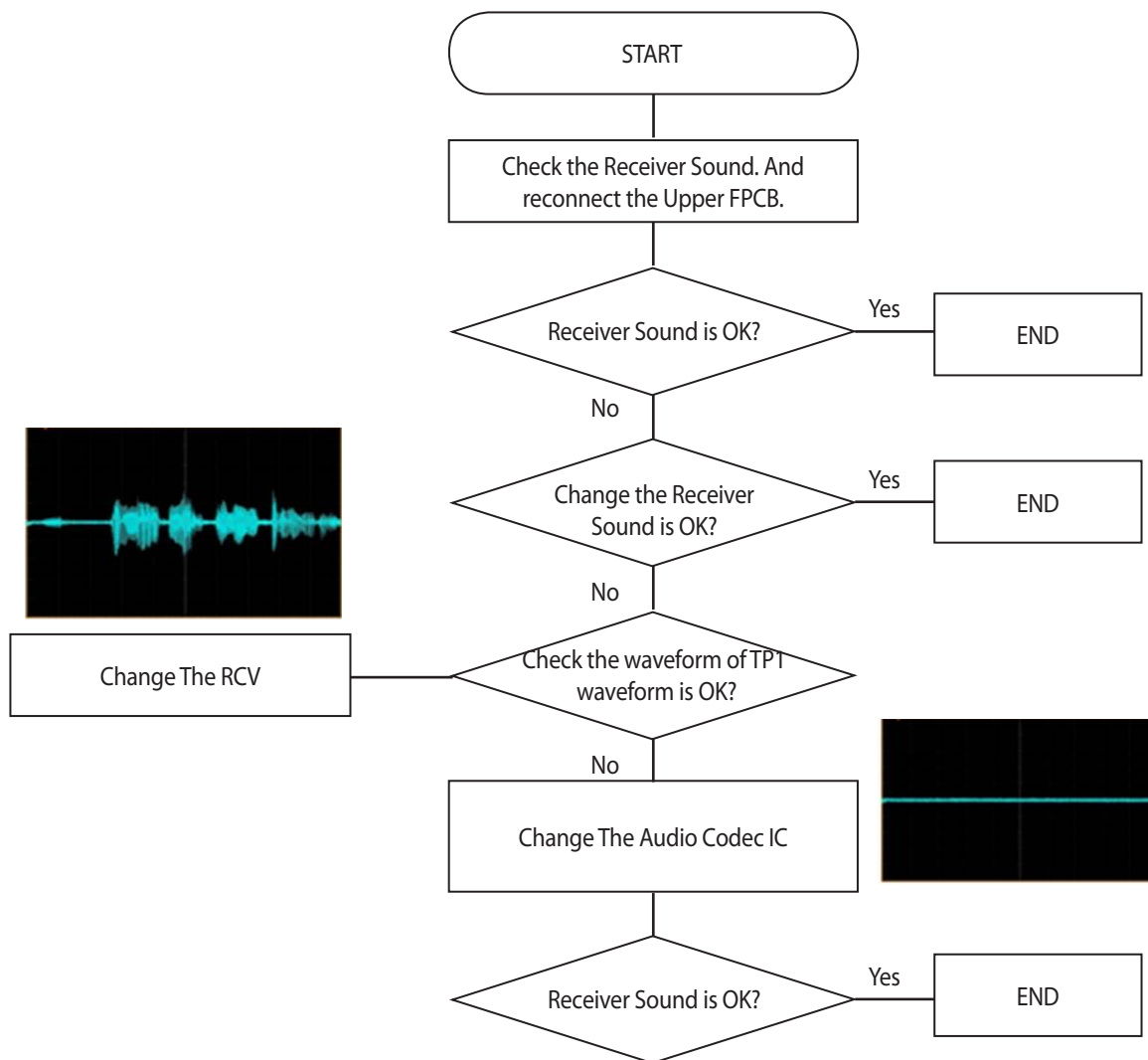


4. TROUBLE SHOOTING

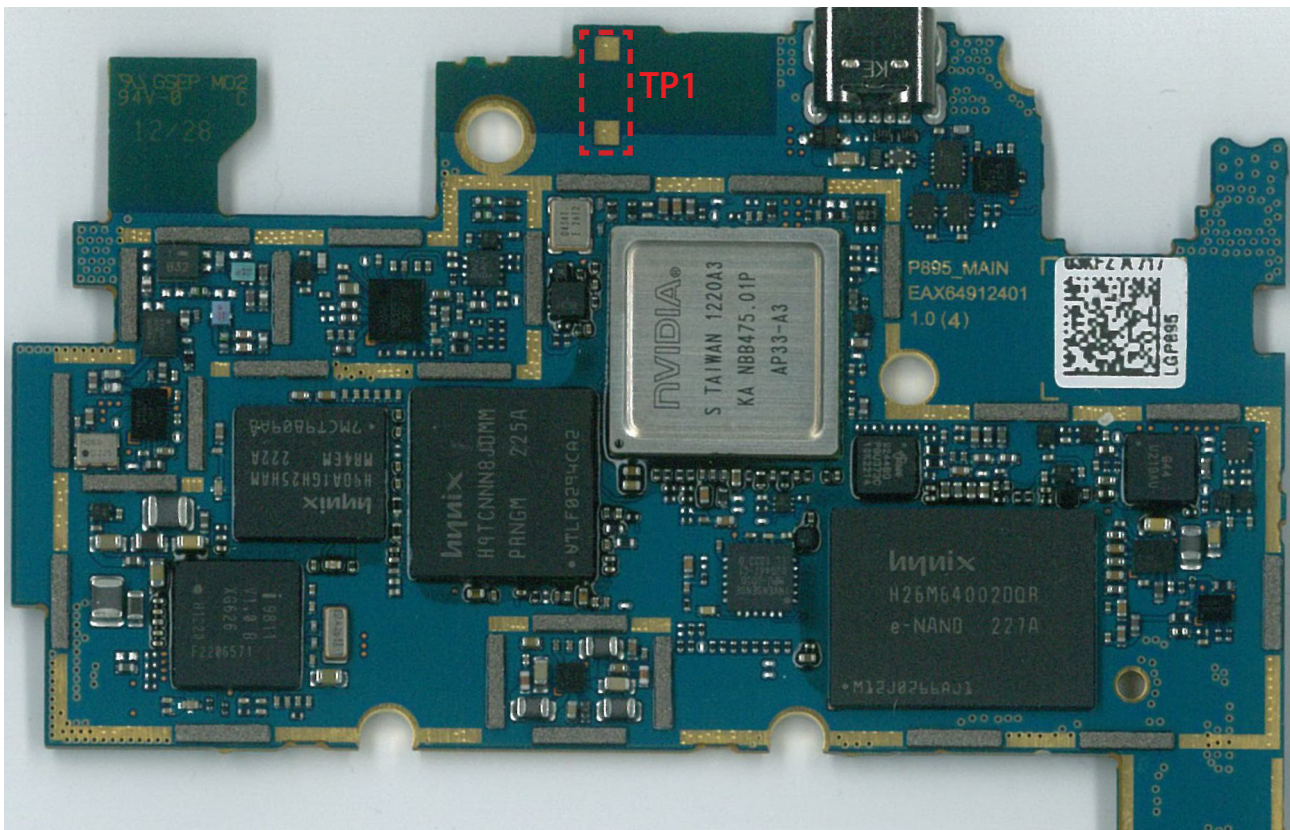
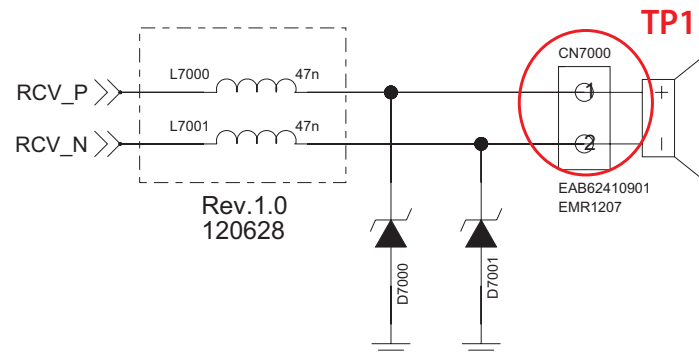


4.12.2 Receiver troubleshooting

Receiver control signals are generated by MAX98089(U7000), and Power is supplied by Battery (VBAT).

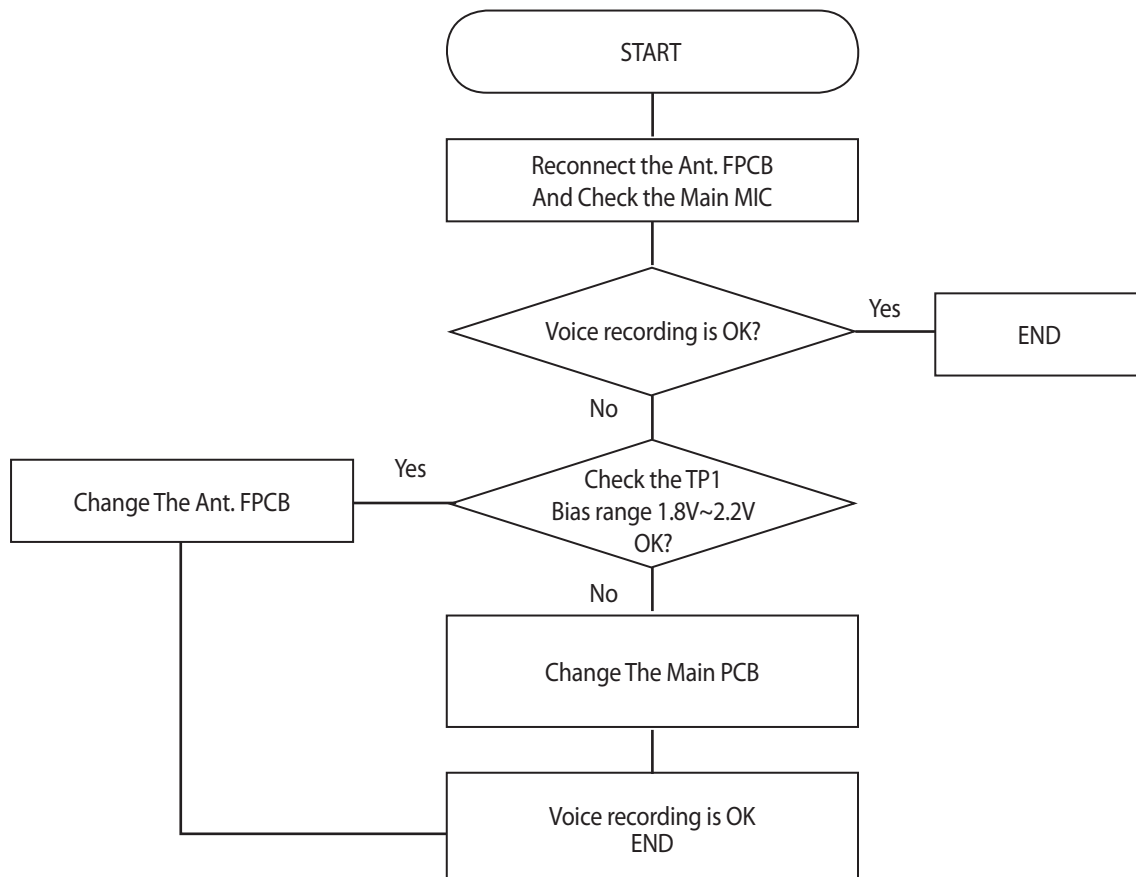


RECEIVER

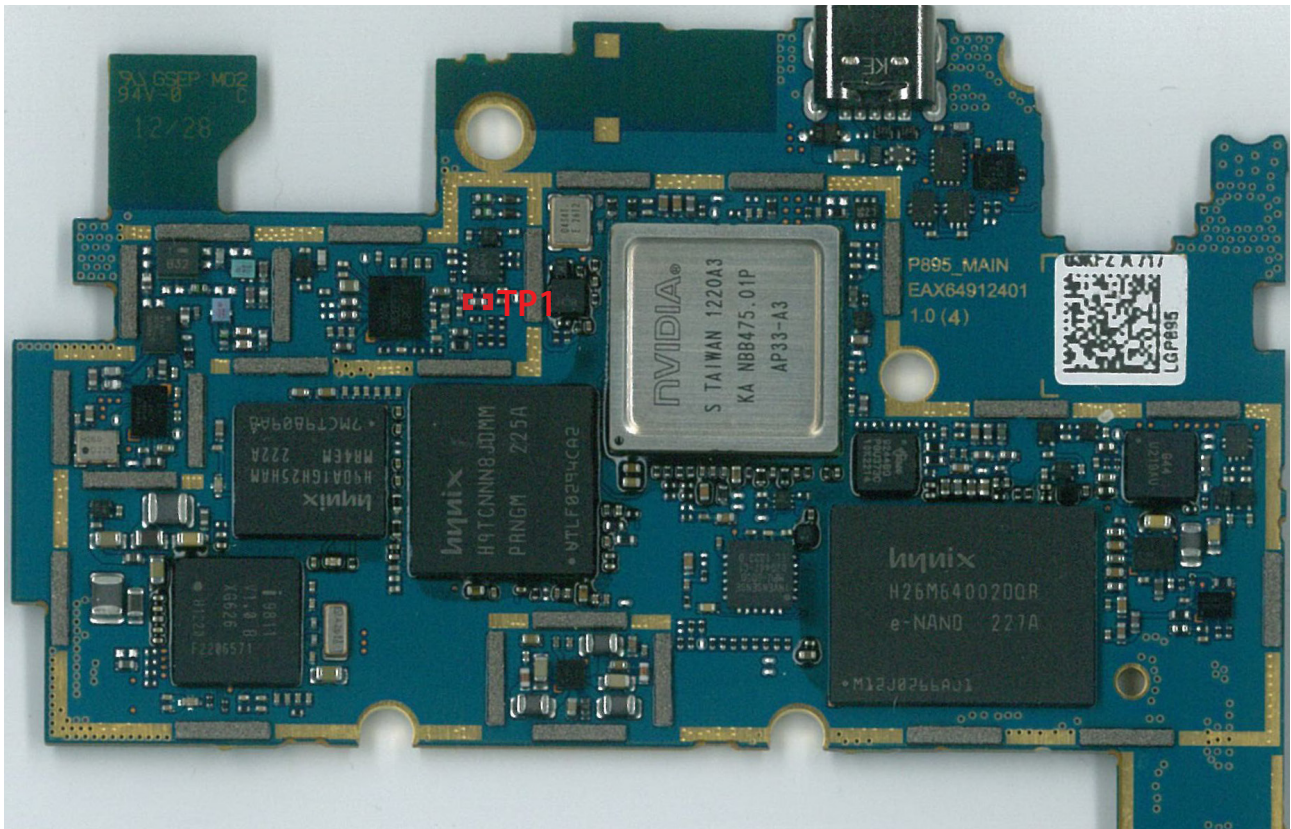
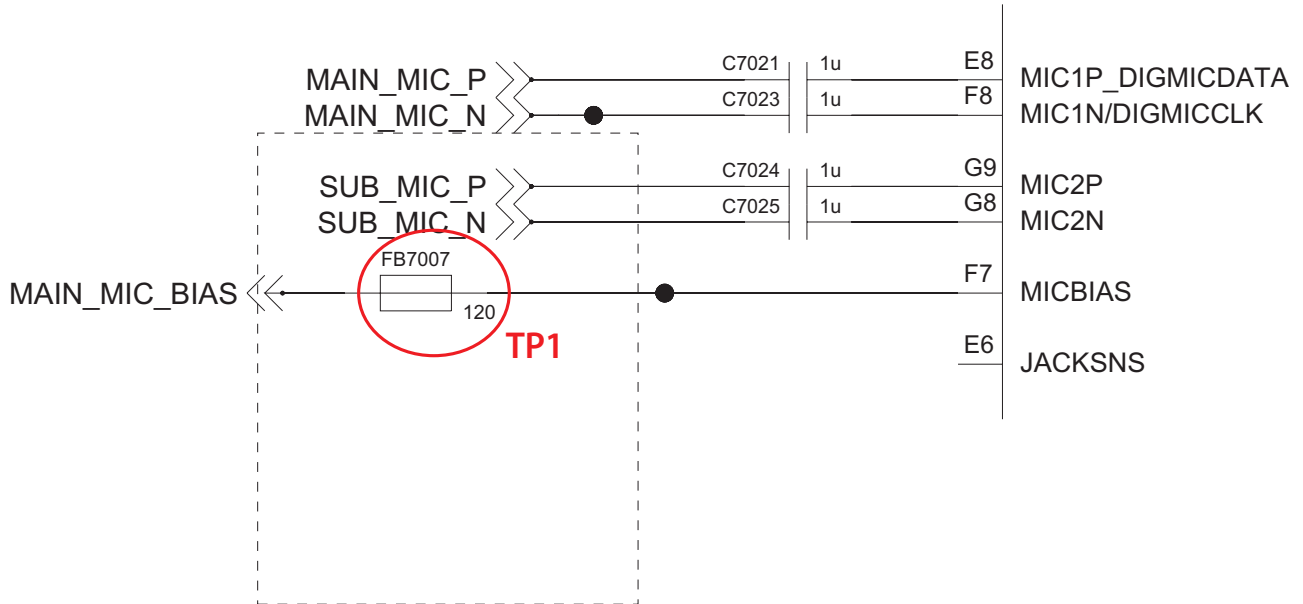


4.12.3 Main MIC troubleshooting

Main MIC control signals are generated by MAX98089(U7001), and Power is supplied by Battery (VBAT).

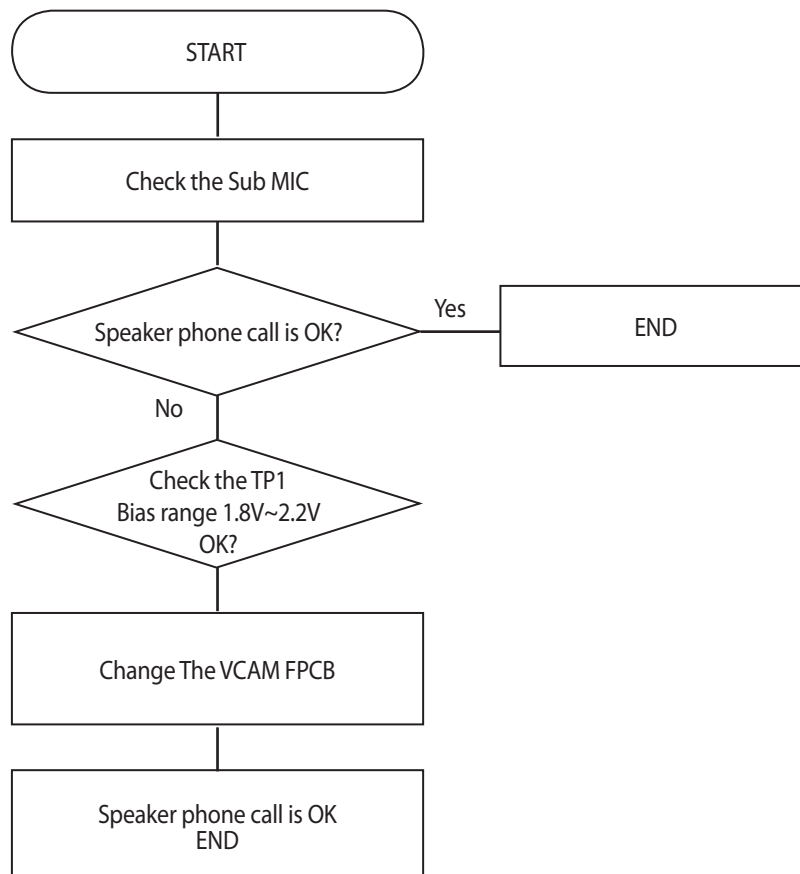


4. TROUBLE SHOOTING

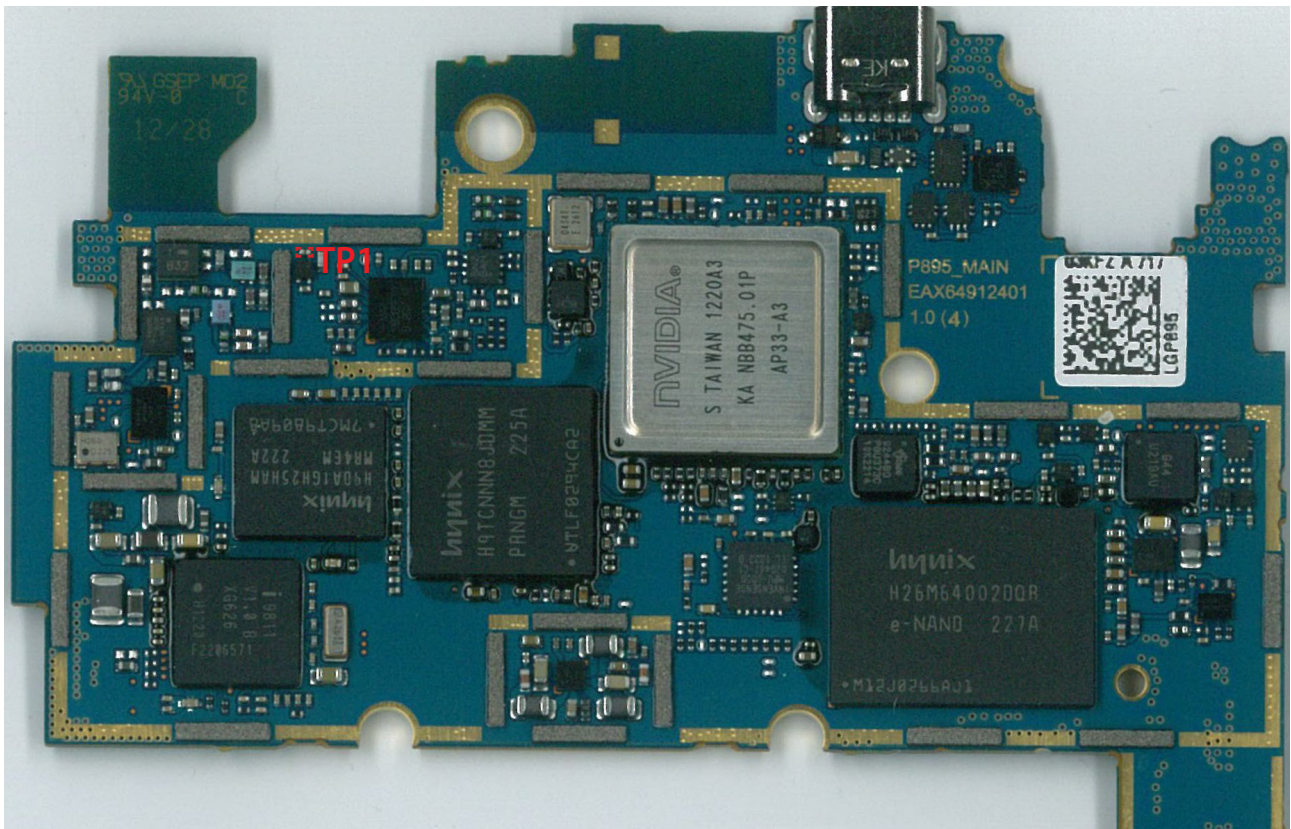
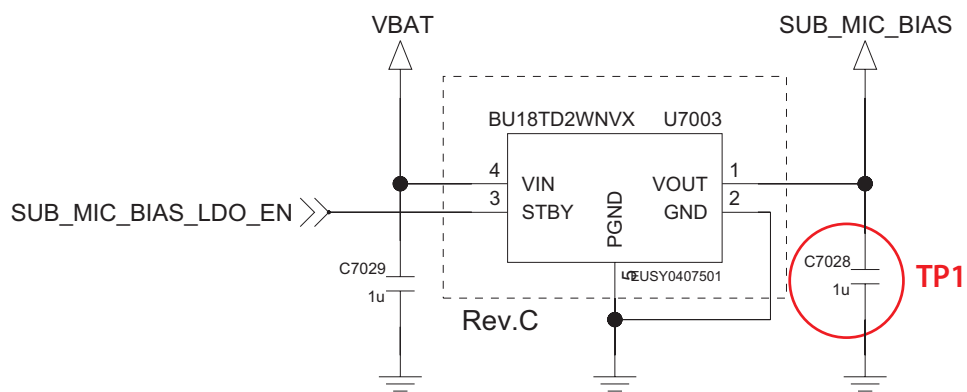


4.12. 4 SUB MIC troubleshooting

Sub MIC control signals are generated by LDO(U10001), and Power is supplied by Battery (VBAT).

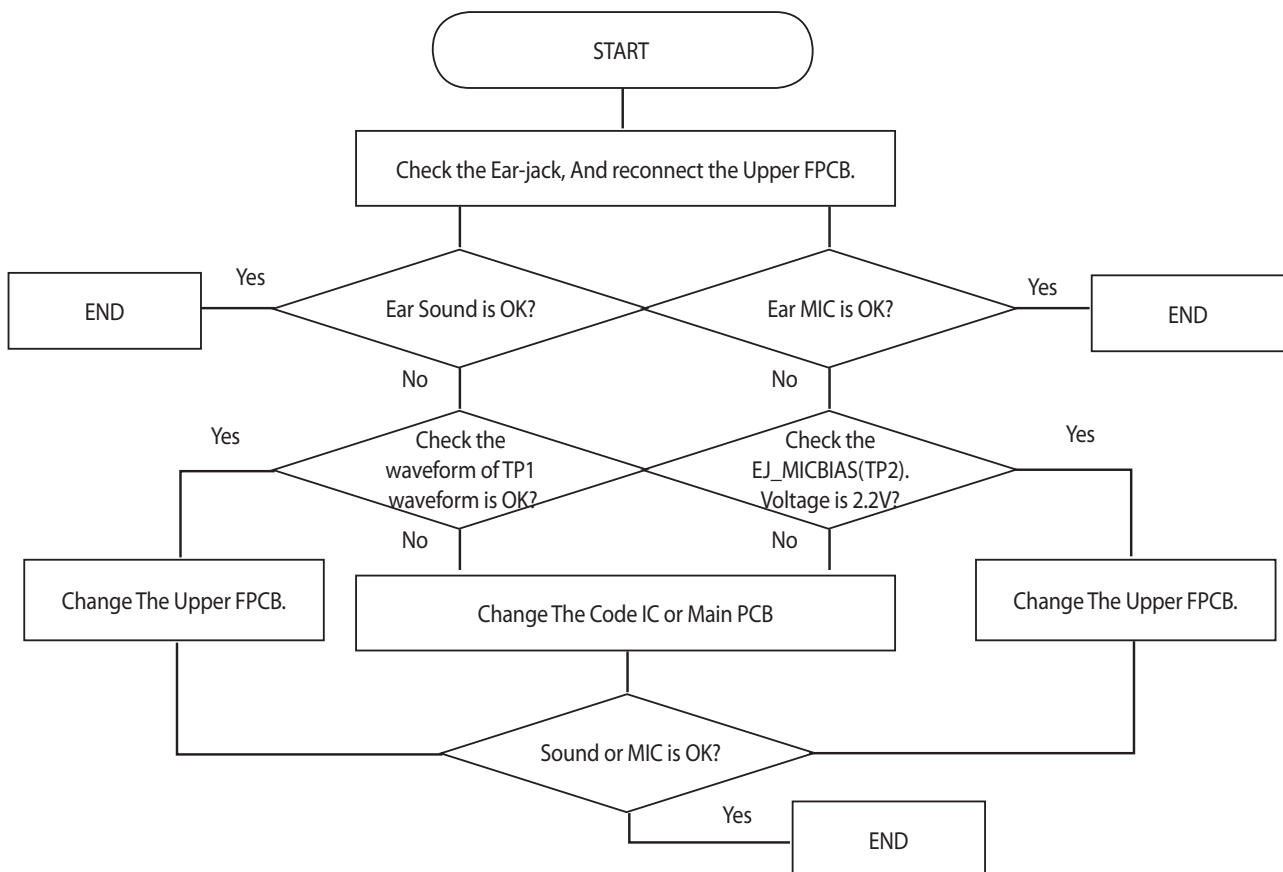


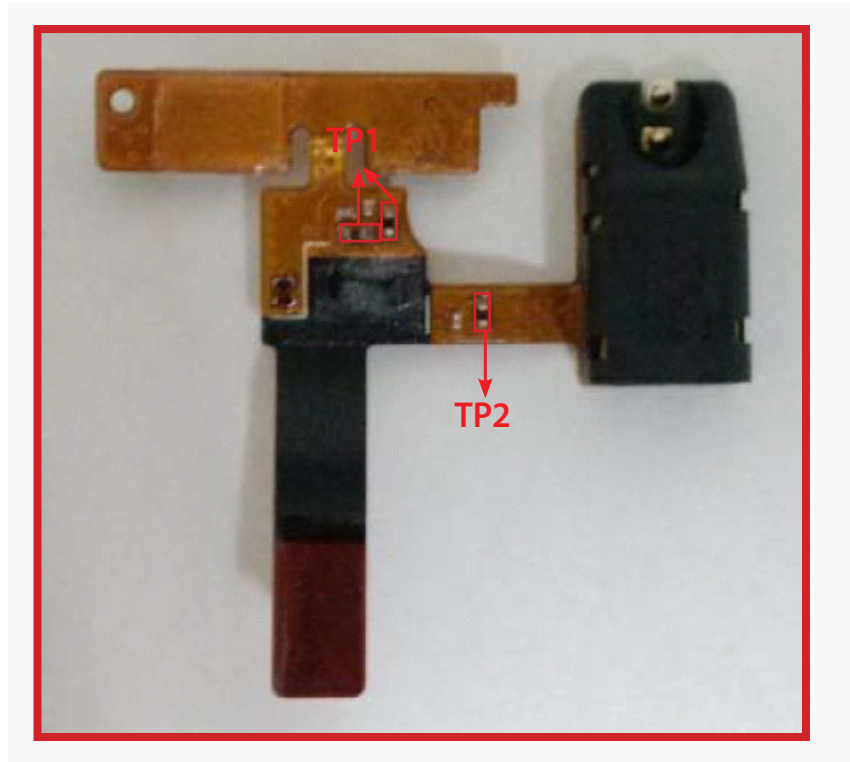
SUB-MIC BIAS LDO



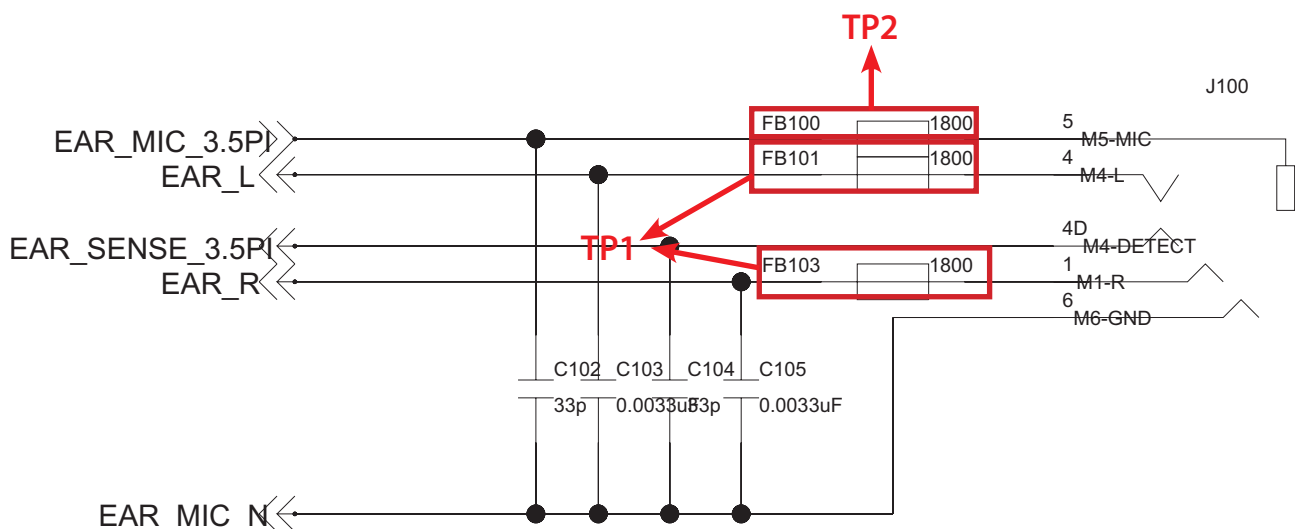
4.12. 5 Ear-MIC troubleshooting

Ear MIC control signals are generated by MAX14579E(U7000), and Power is supplied by Battery (VBAT).





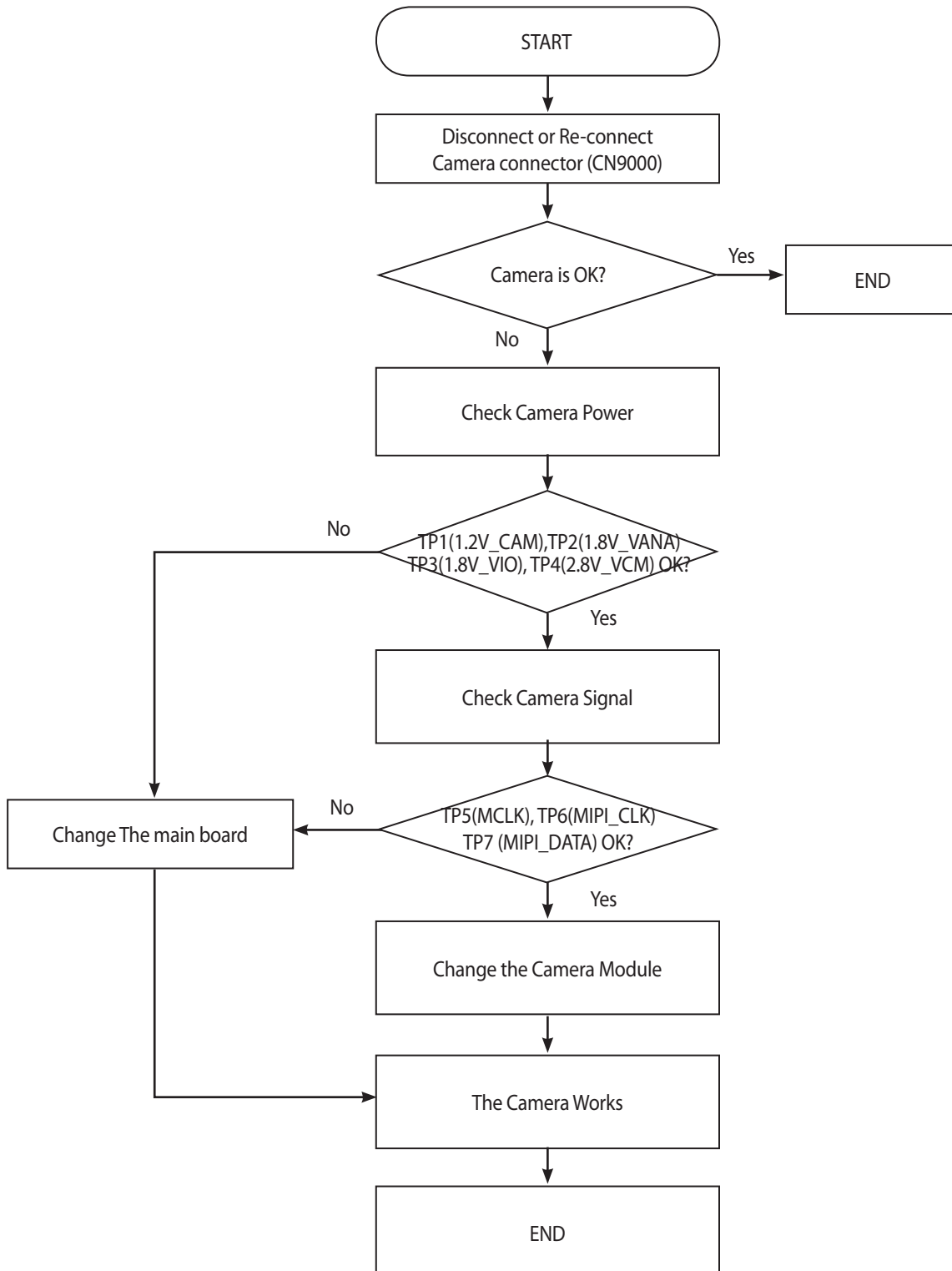
3.5pi EAR JACK



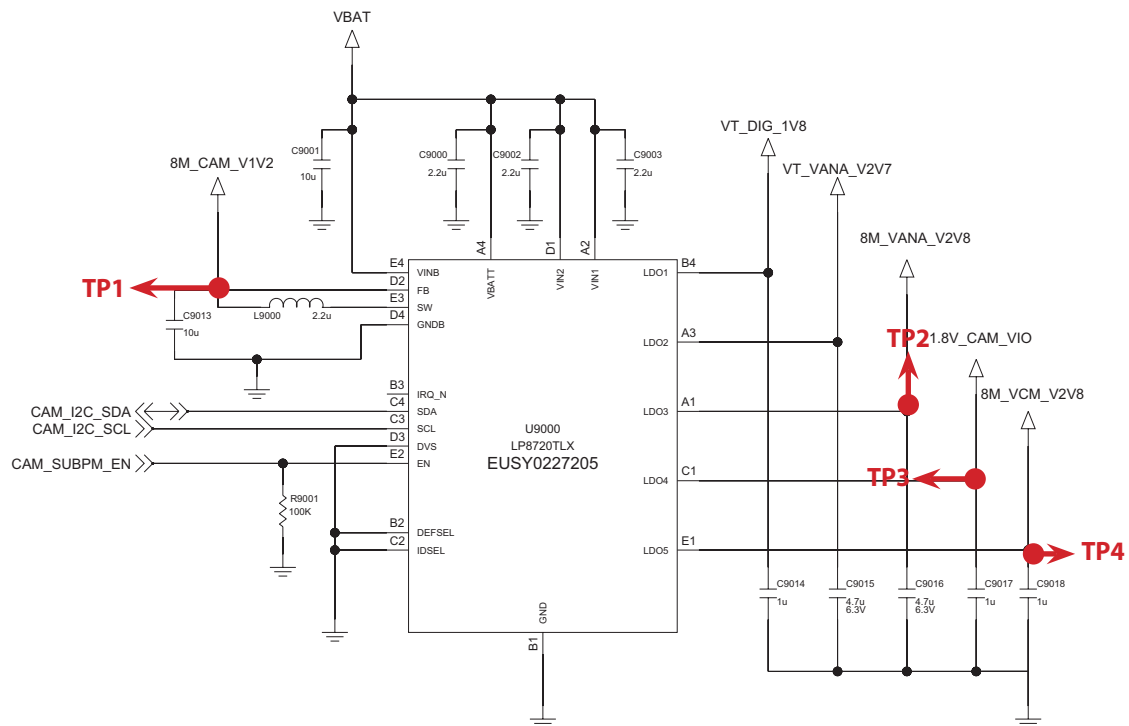
4.13 (8M) Camera troubleshooting

4.13.1 Main 8M AF Camera troubleshooting

8M camera control signals are generated by AP33(U3000), and Power is supplied by LP8720(U9000)



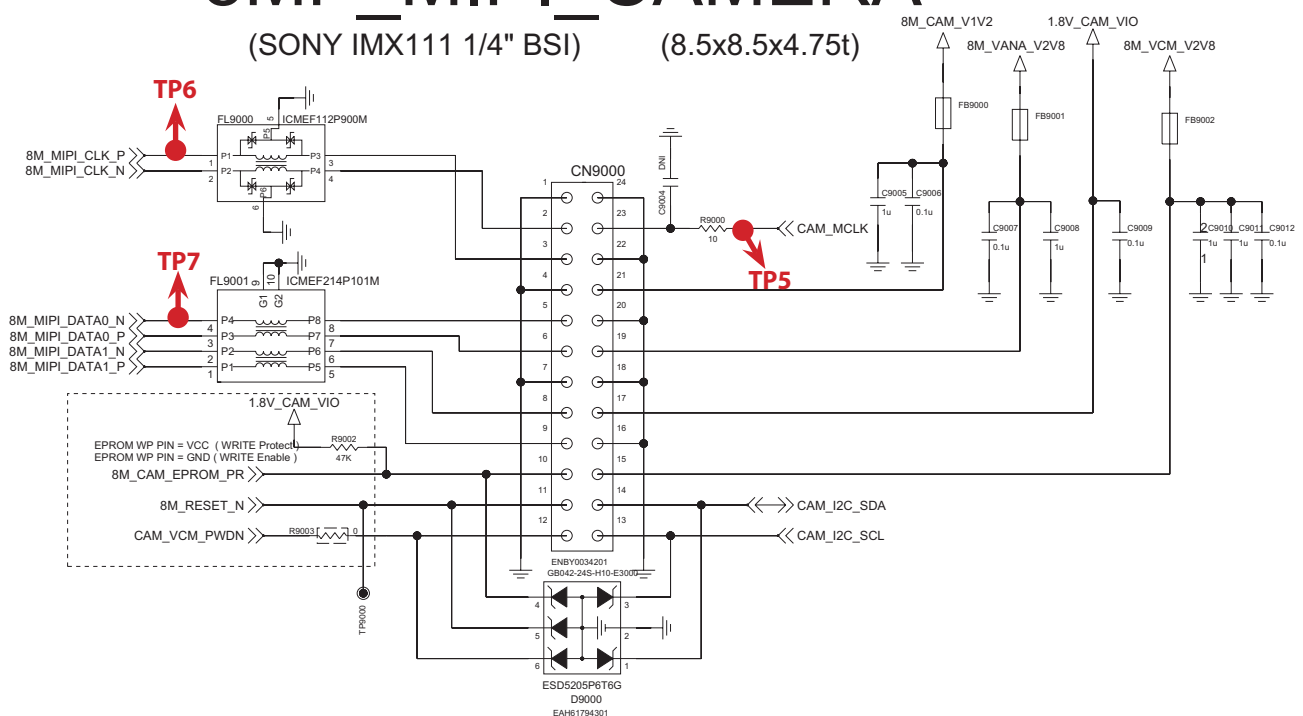
SUB PMIC-CAM POWER



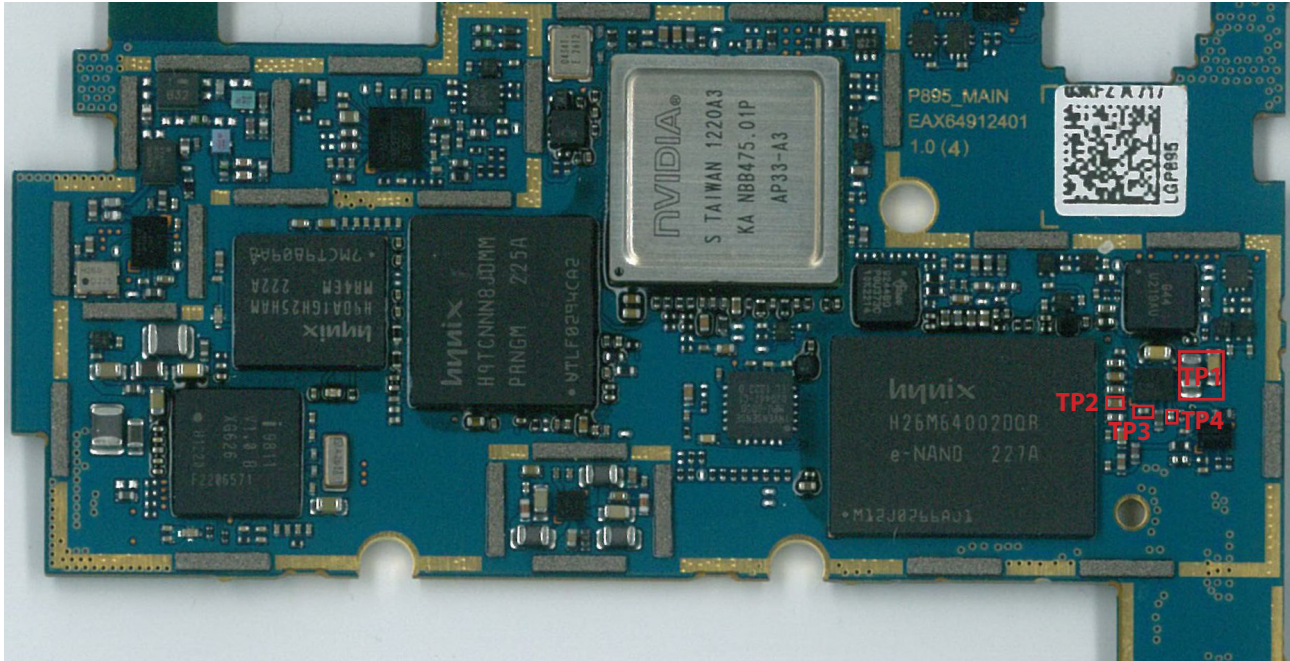
8MP_MIPI_CAMERA

(SONY IMX111 1/4" BSI)

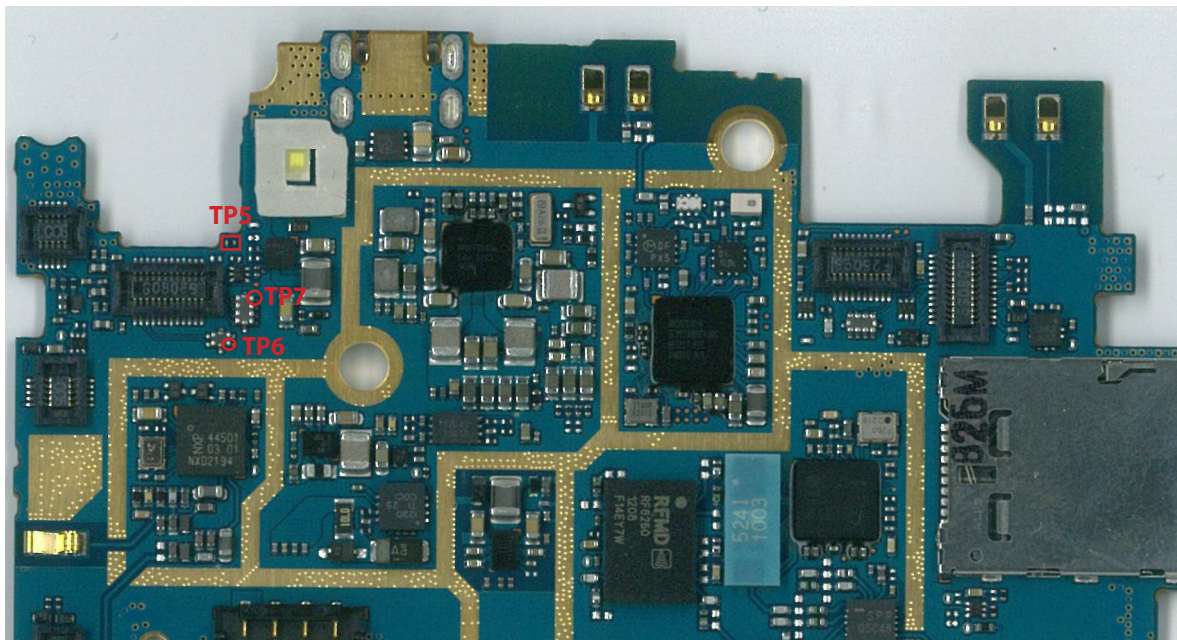
(8.5x8.5x4.75t)



4. TROUBLE SHOOTING



Top Side

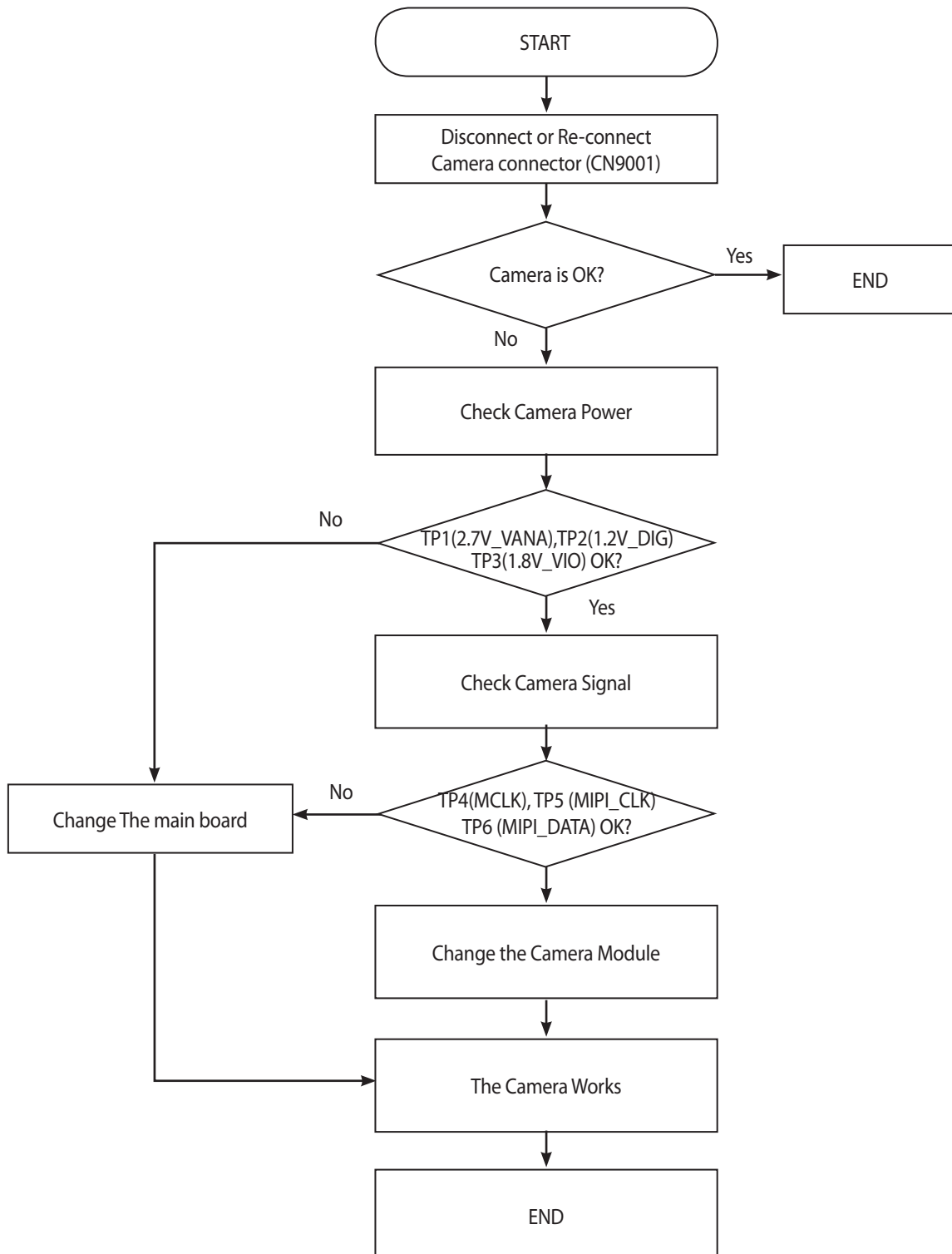


Bottom Side

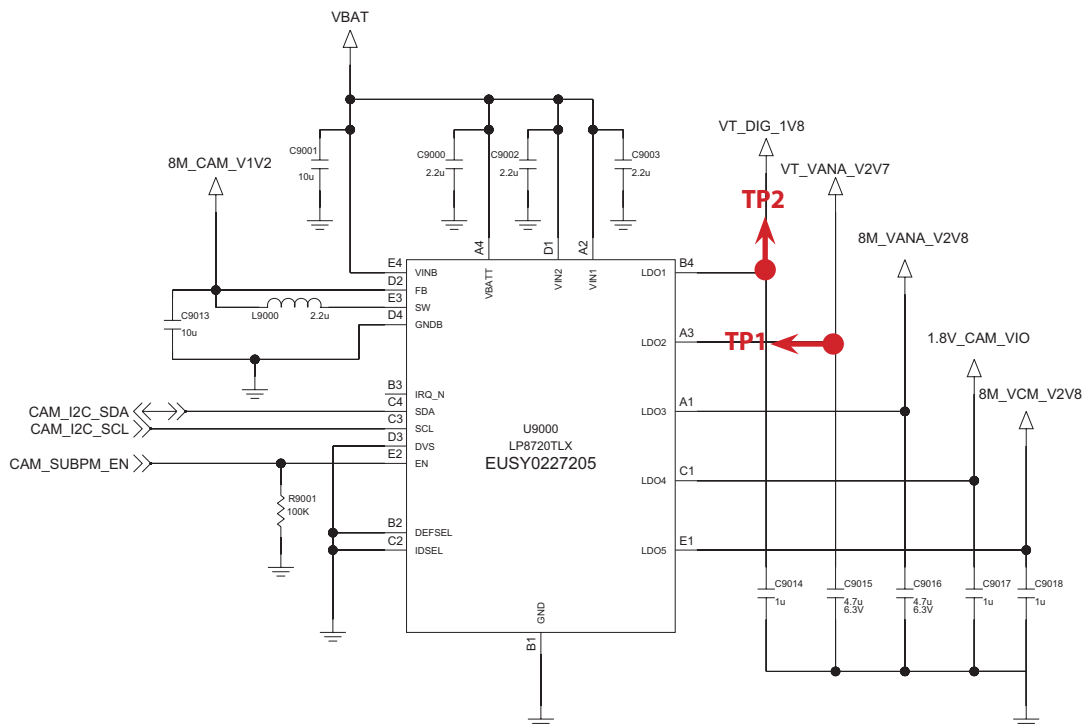
4.14.(1.26M) Camera troubleshooting

4.14.1 (1.26M) VT Camera troubleshooting

VT camera control signals are generated by AP33(U3000), and Power is supplied by LP8720(U9000)



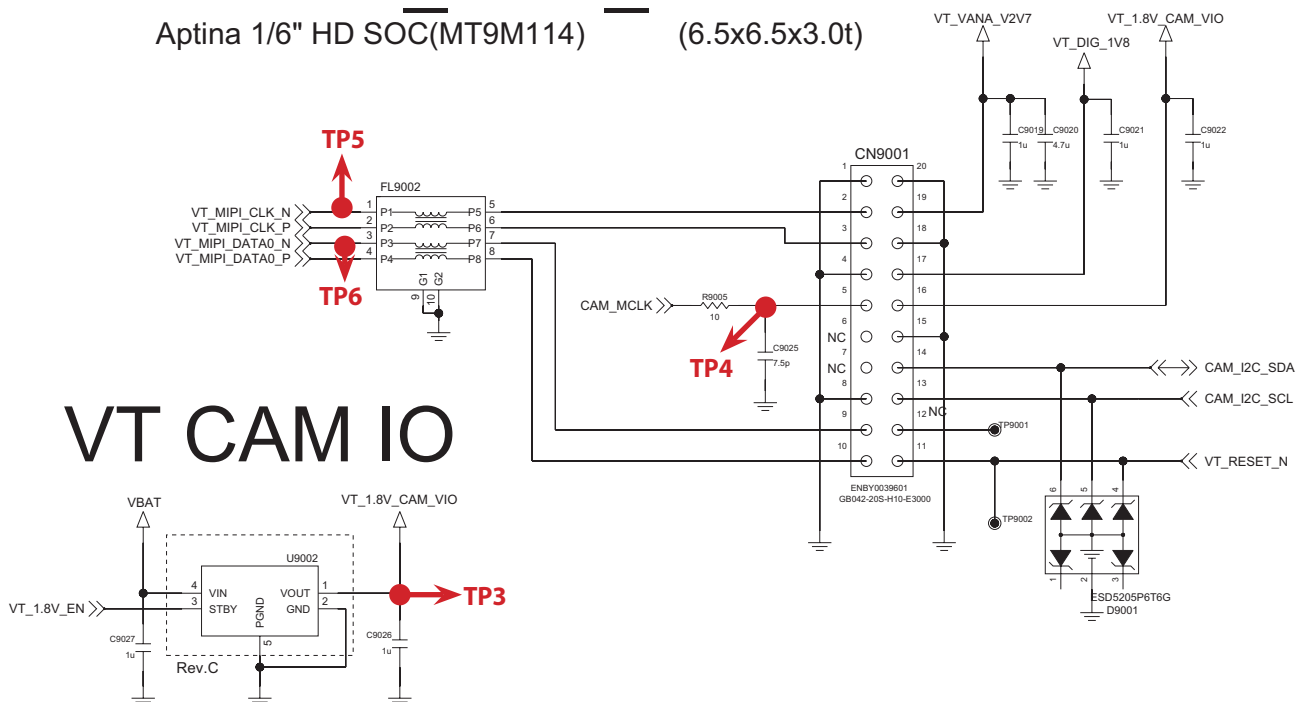
SUB PMIC-CAM POWER



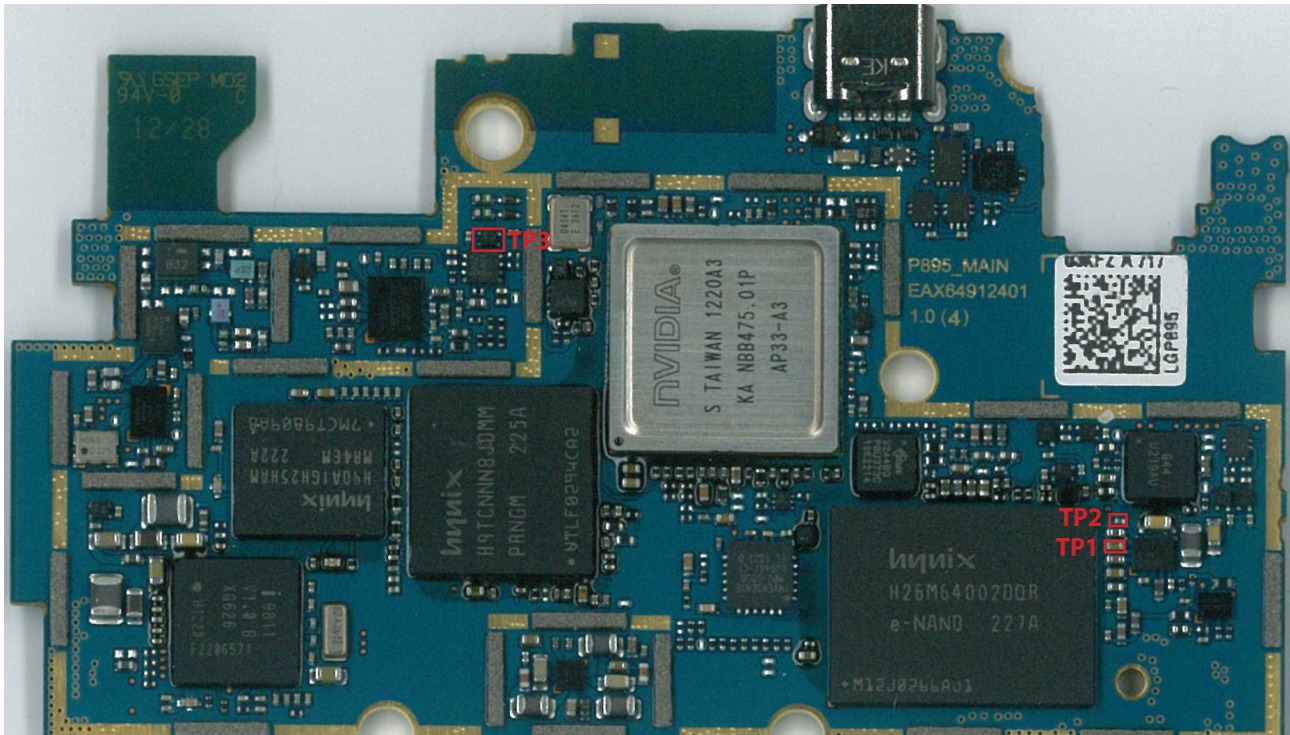
1.26MP_MIPI_CAMERA

Aptina 1/6" HD SOC(MT9M114) (6.5x6.5x3.0t)

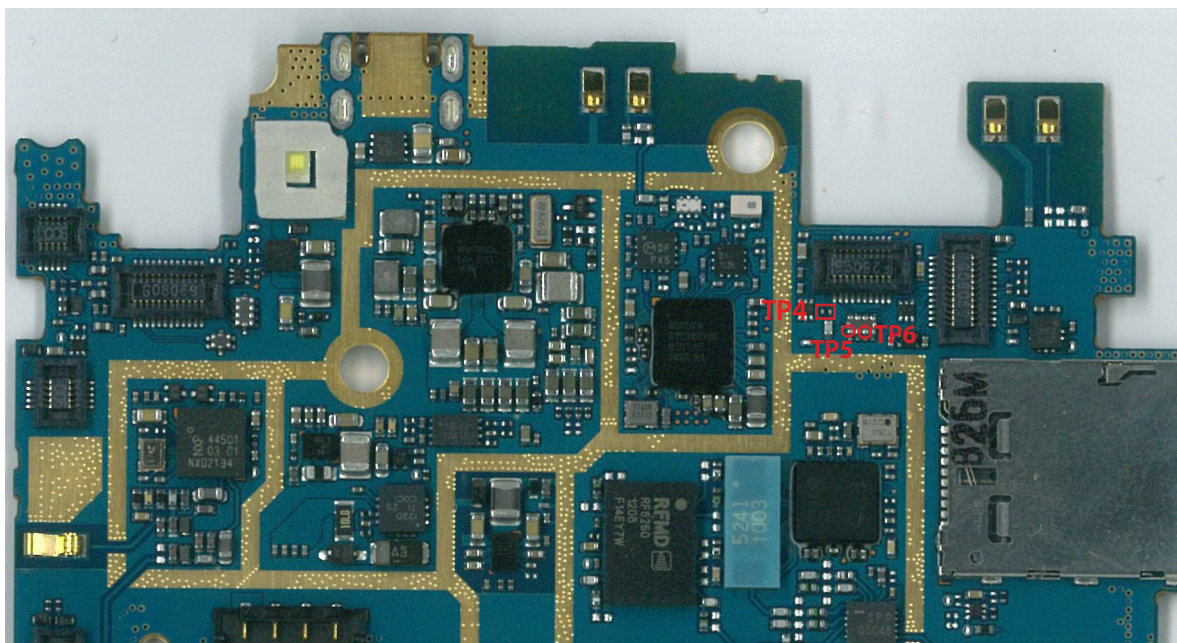
VT CAM IO



4. TROUBLE SHOOTING



Top Side

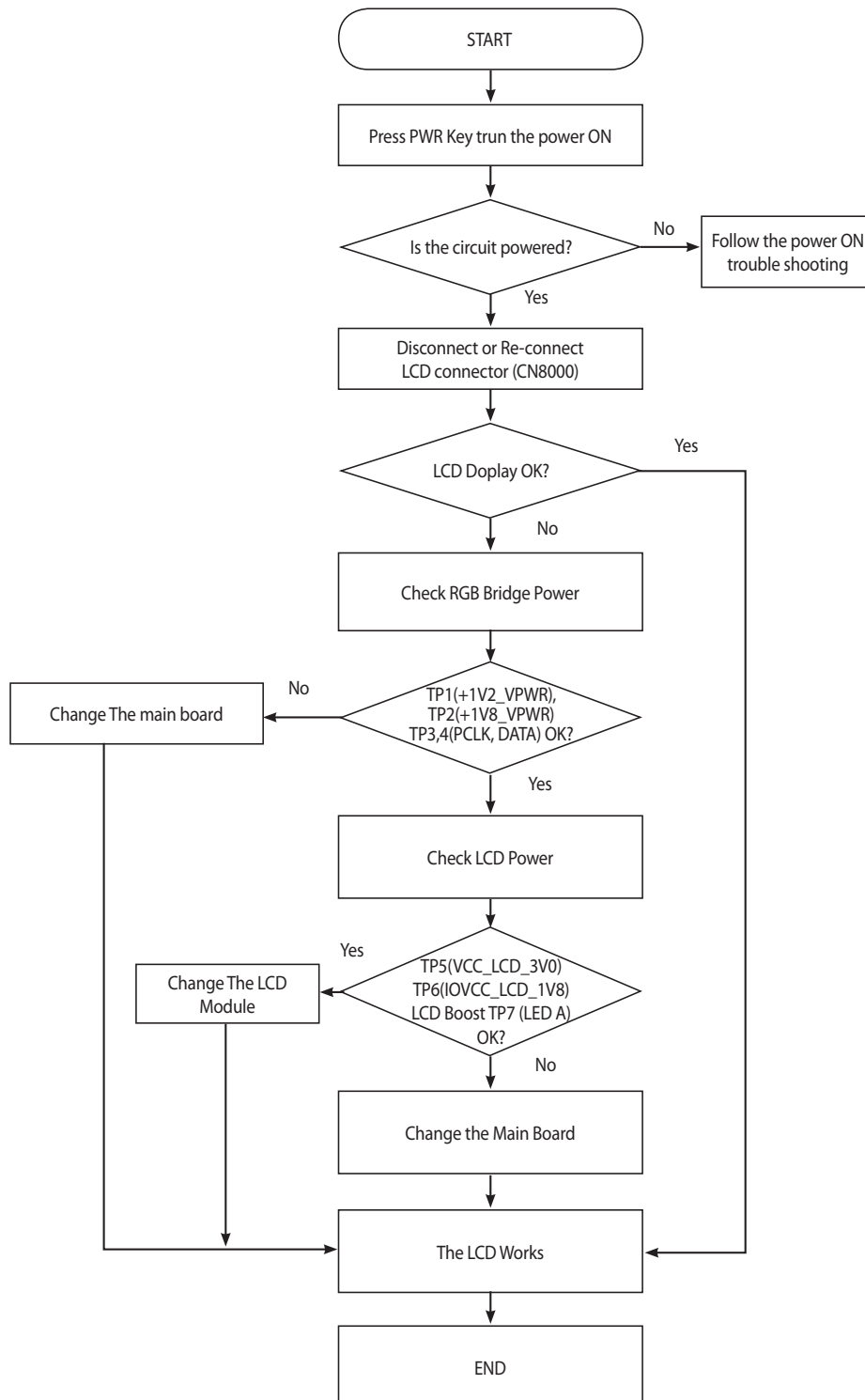


Bottom Side

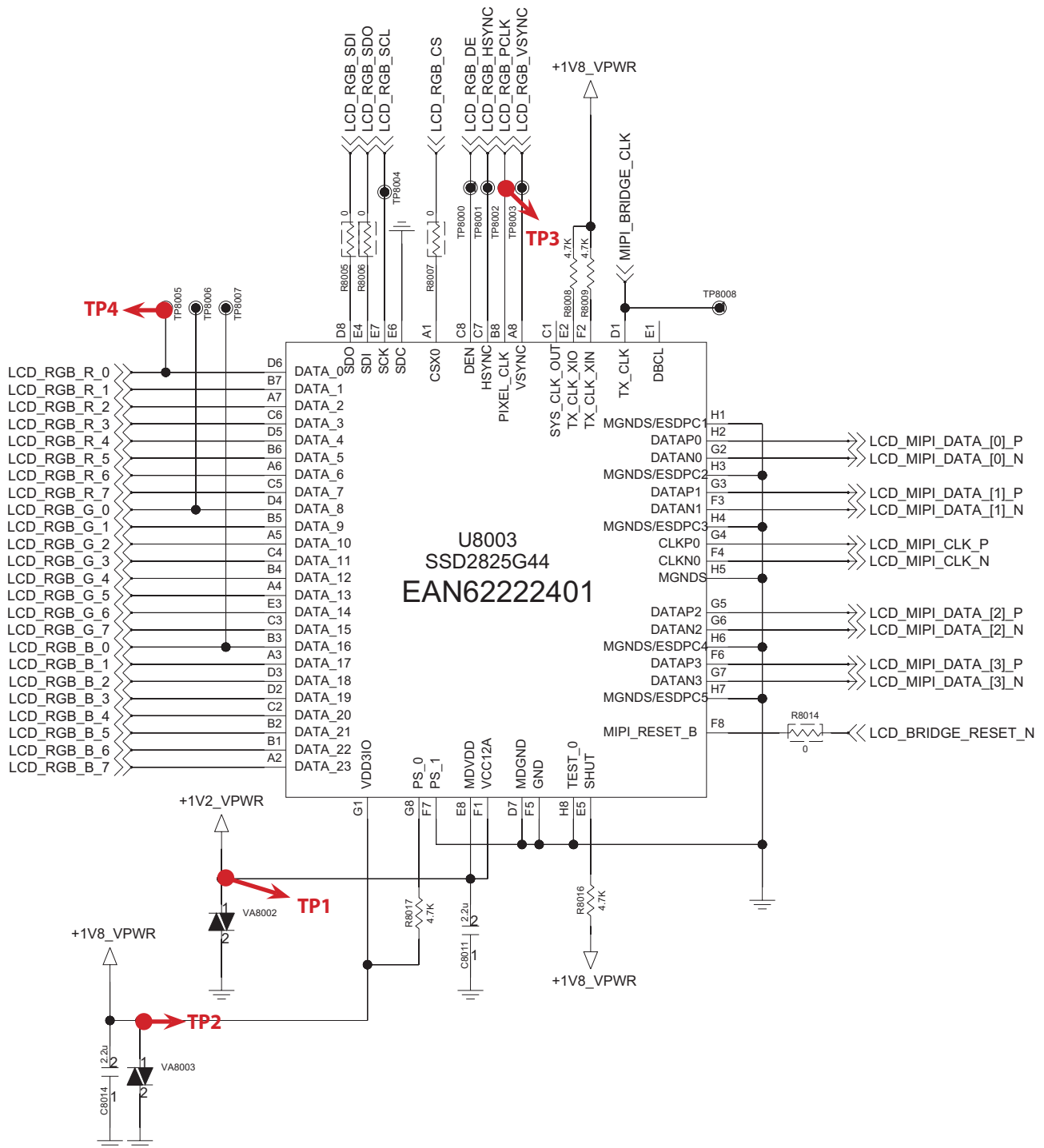
4.15 Main LCD trouble

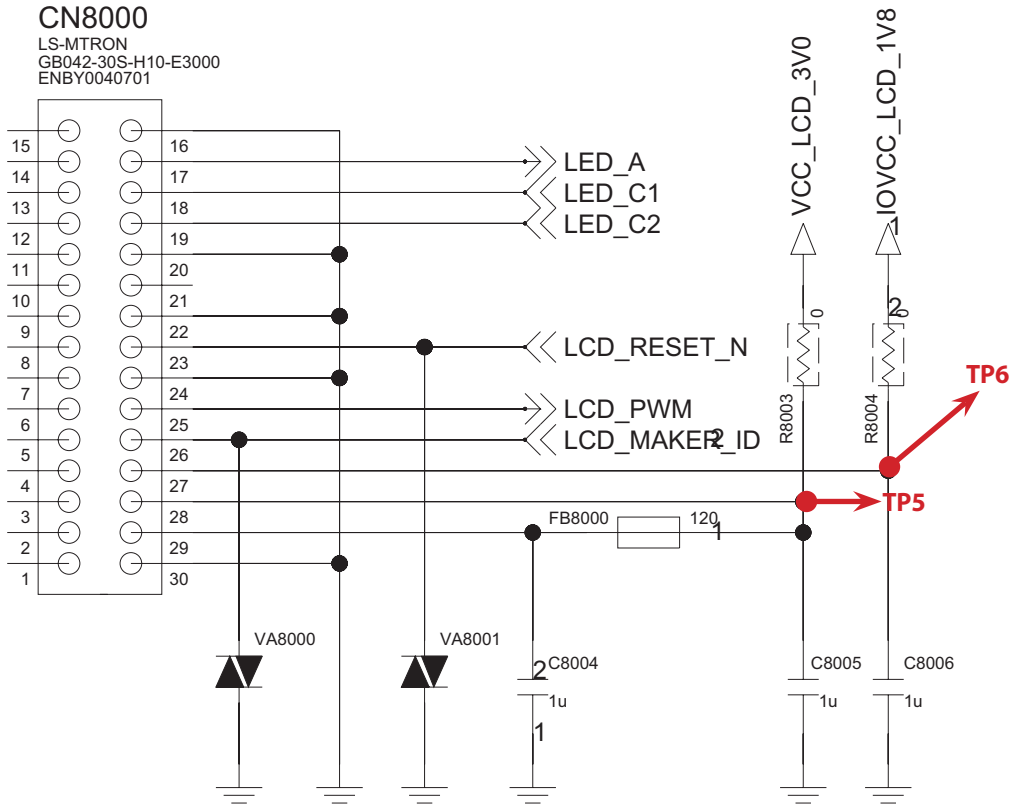
Main LCD control signals are generated by AP33 & SSD2825. Those signal's path are :

AP33 -> SSD2825 -> LCD Module

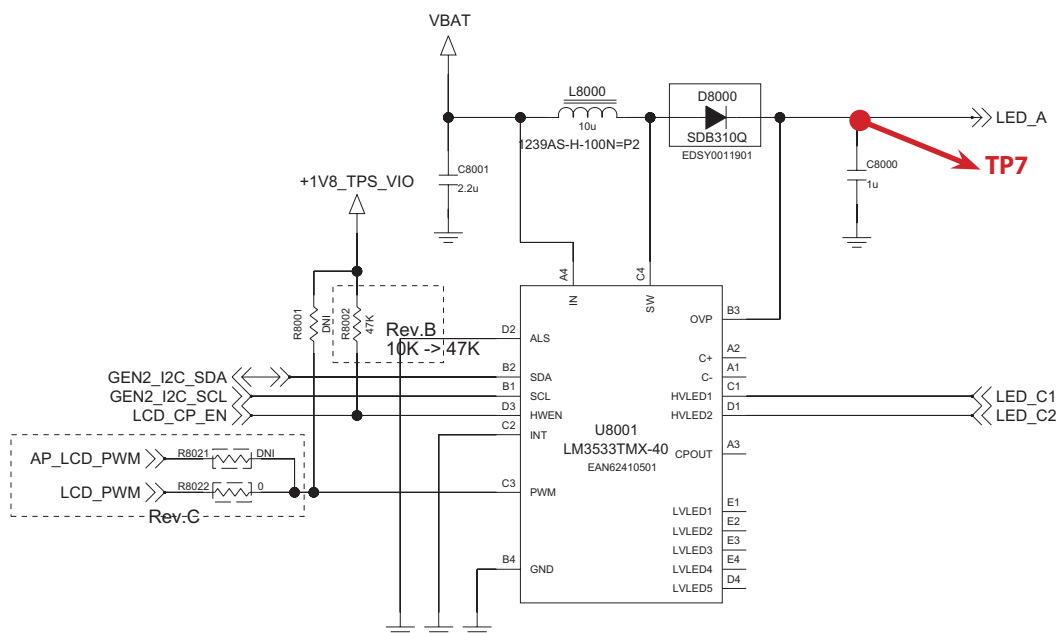


RGB CONVERTER

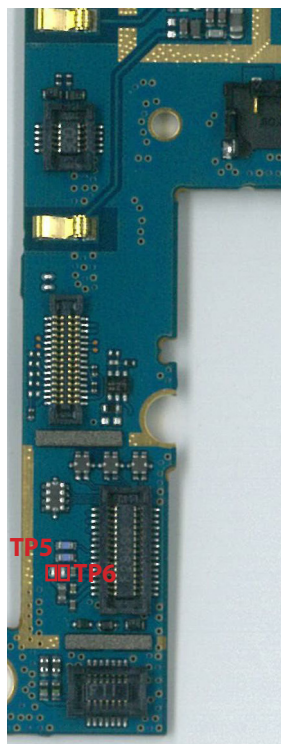
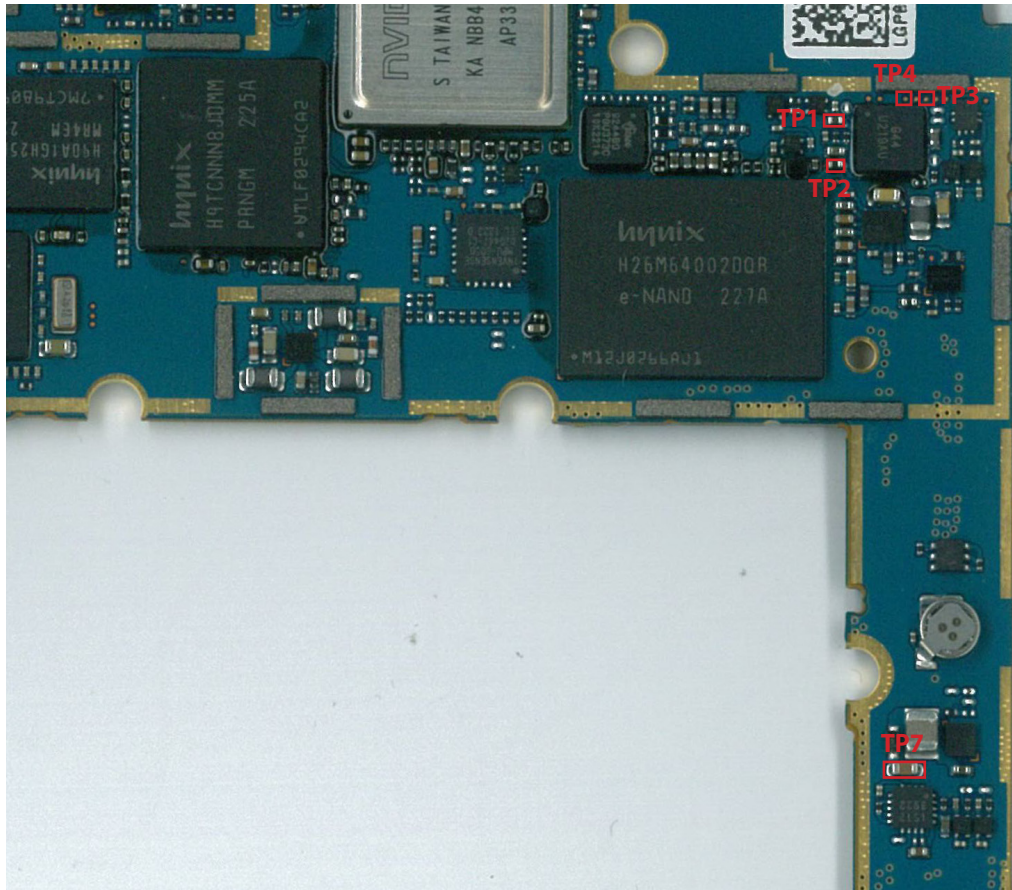




LCD BackLight Driver (2string)



4. TROUBLE SHOOTING

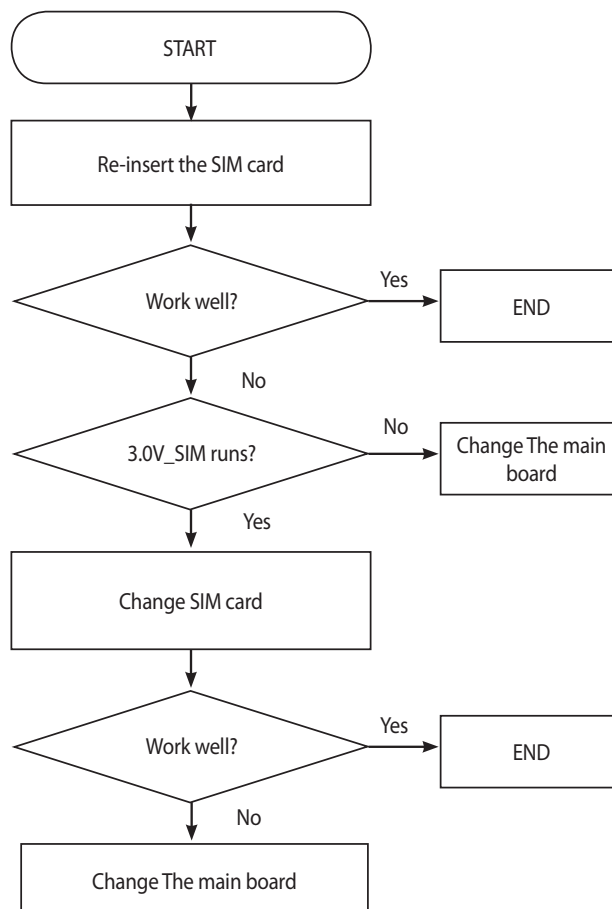
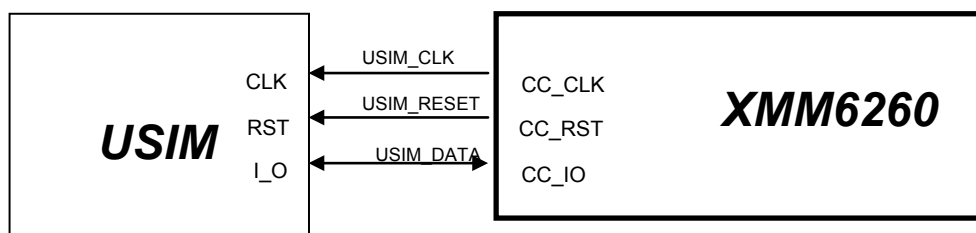


4.16 SIM detect Troubleshooting

The sequence of detecting LGP895 SIM is,

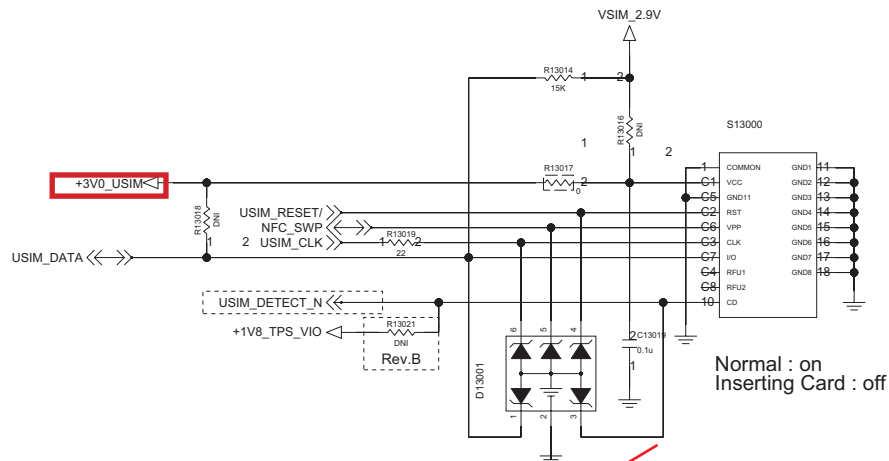
SIM inserted to LGP895 -> 3.0V_USIM goes to 3.0V-> Triggers SIM clock, reset and data.

Block Diagram of USB & UART connection is shown below



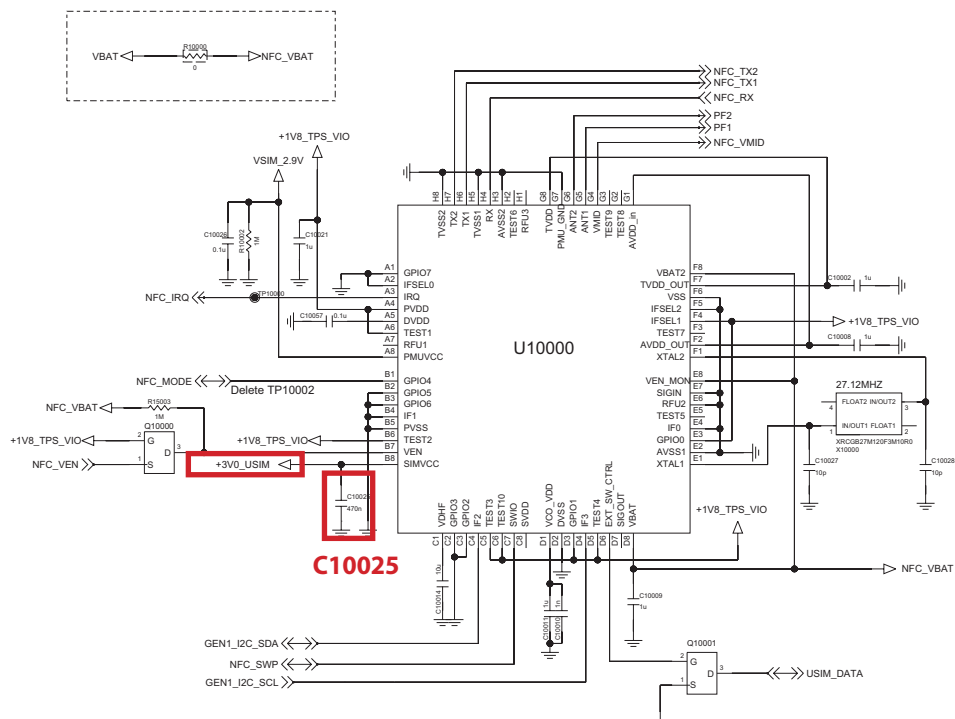
C10025 (+3V0_USIM)

micro USIM(push push)



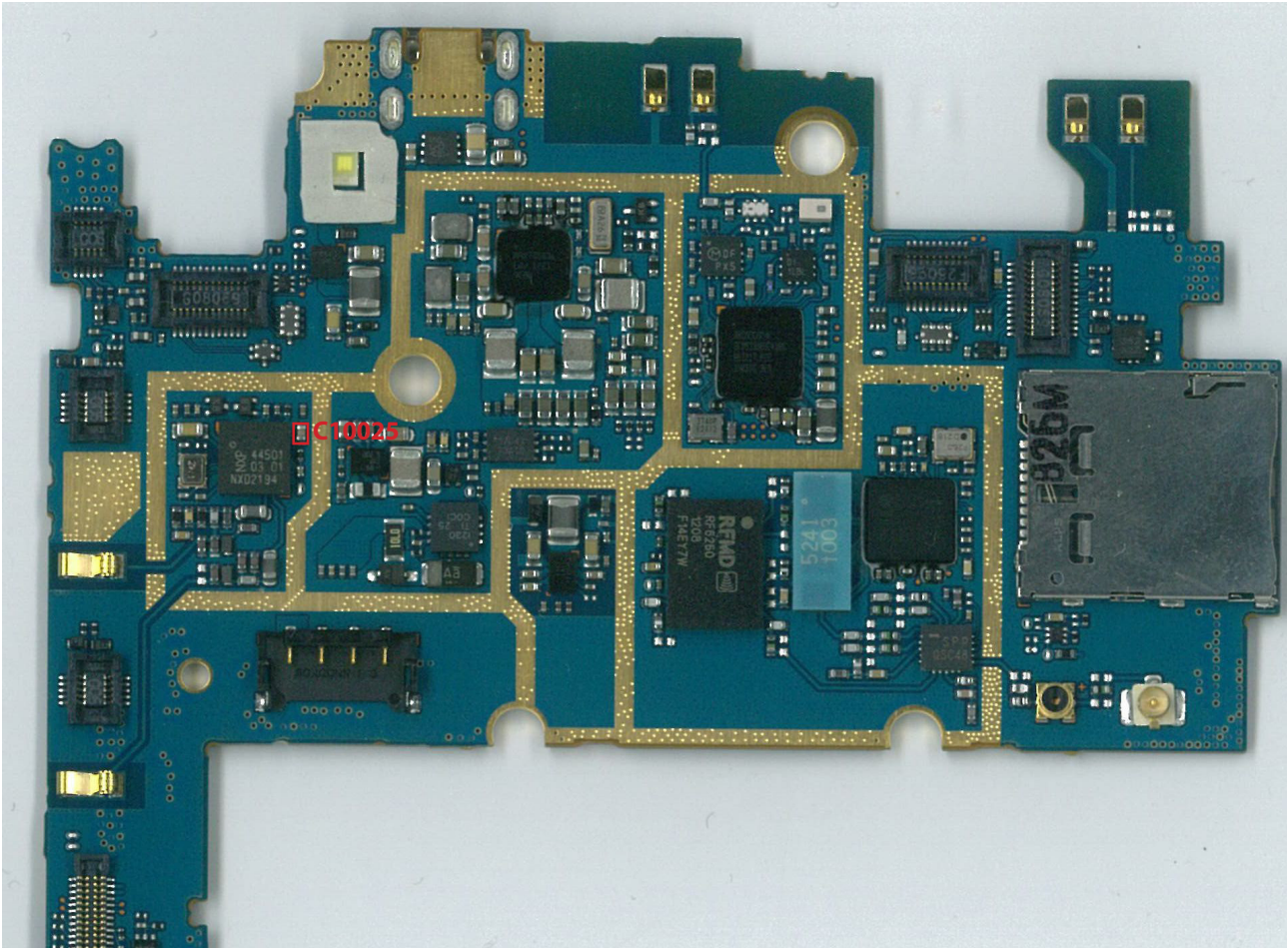
Normal : on
Inserting Card : off

NFC



4. TROUBLE SHOOTING

C10025 (+3V0_USIM)

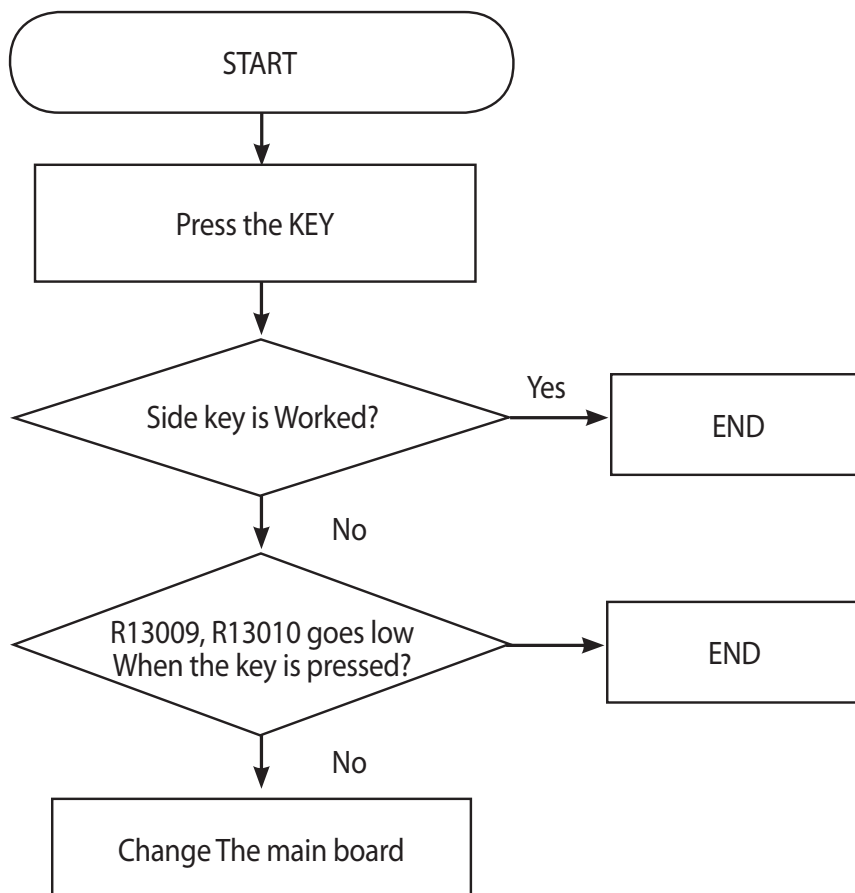
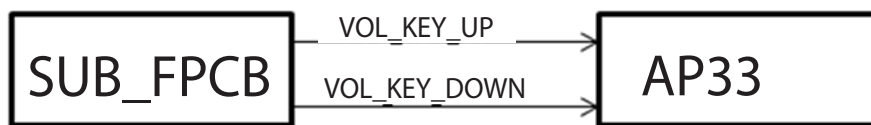


4.17 Side Key Troubleshooting

The sequence of detecting LGP895 Side key is,

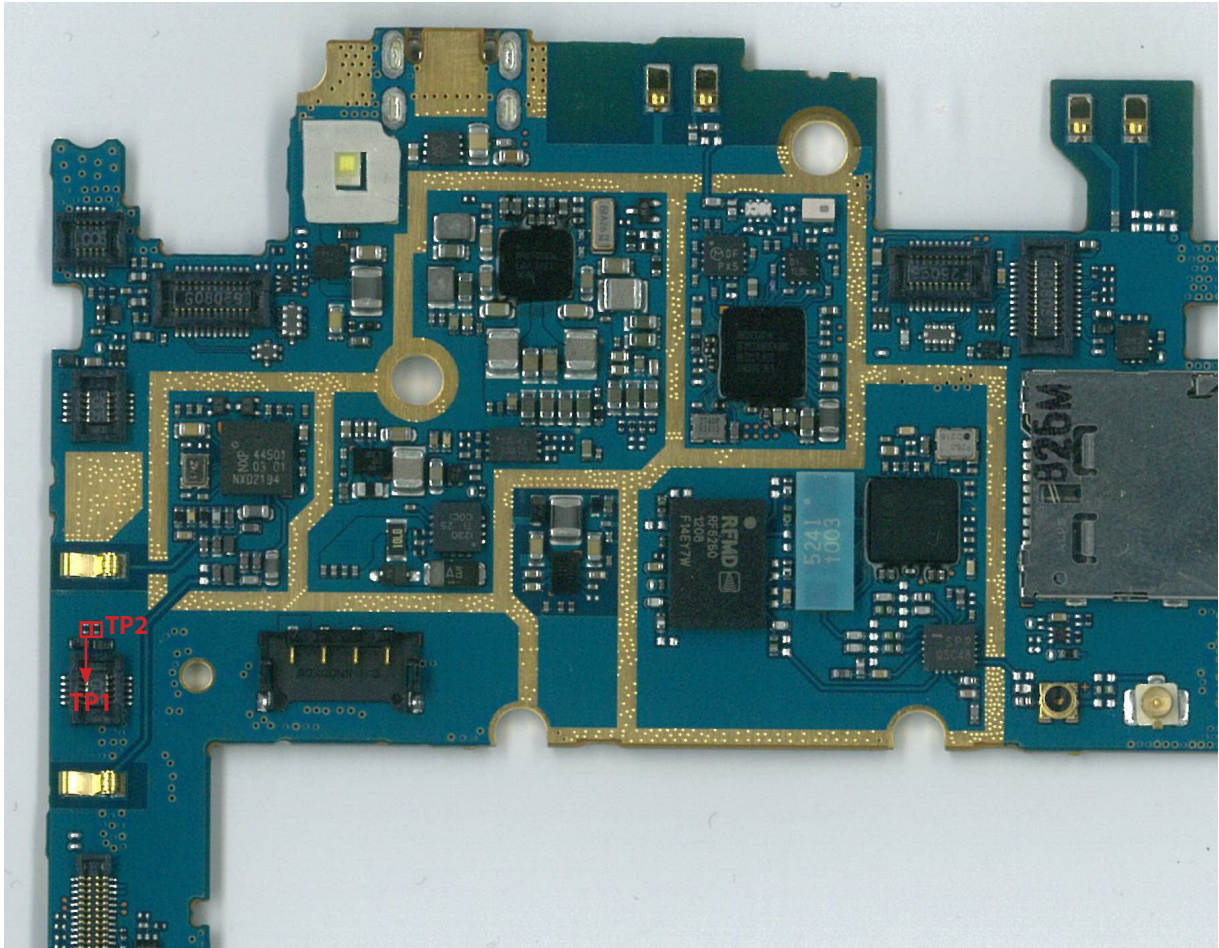
Side key pressed on LGP895 -> VOL_KEY_UP, VOL_KEY_DOWN goes low

Block Diagram of Side key connection is shown below



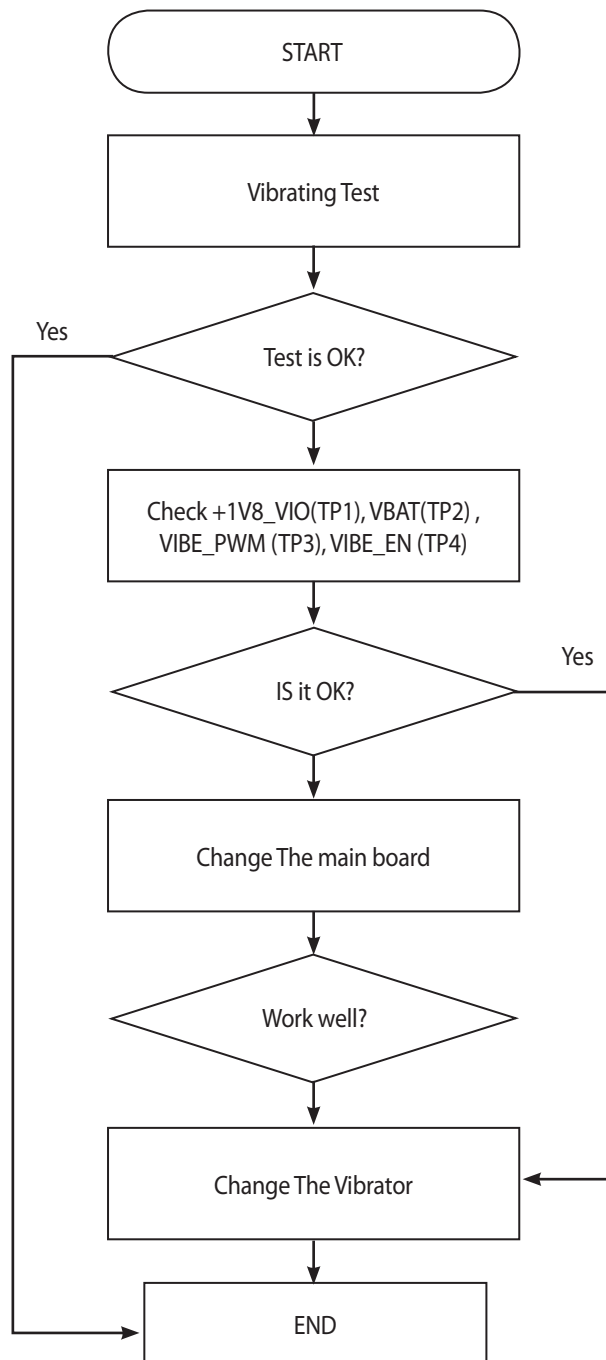
*** TP1 : R13009**
TP2 : R13010

4. TROUBLE SHOOTING

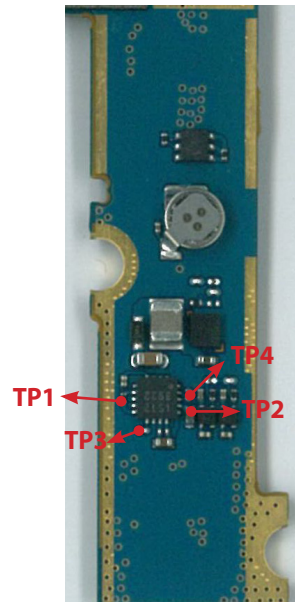
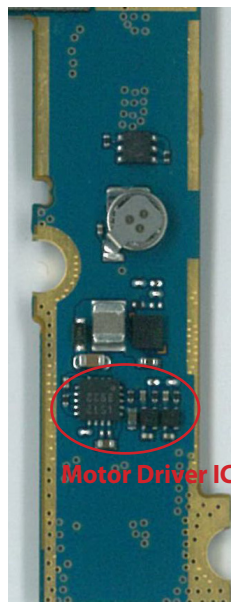
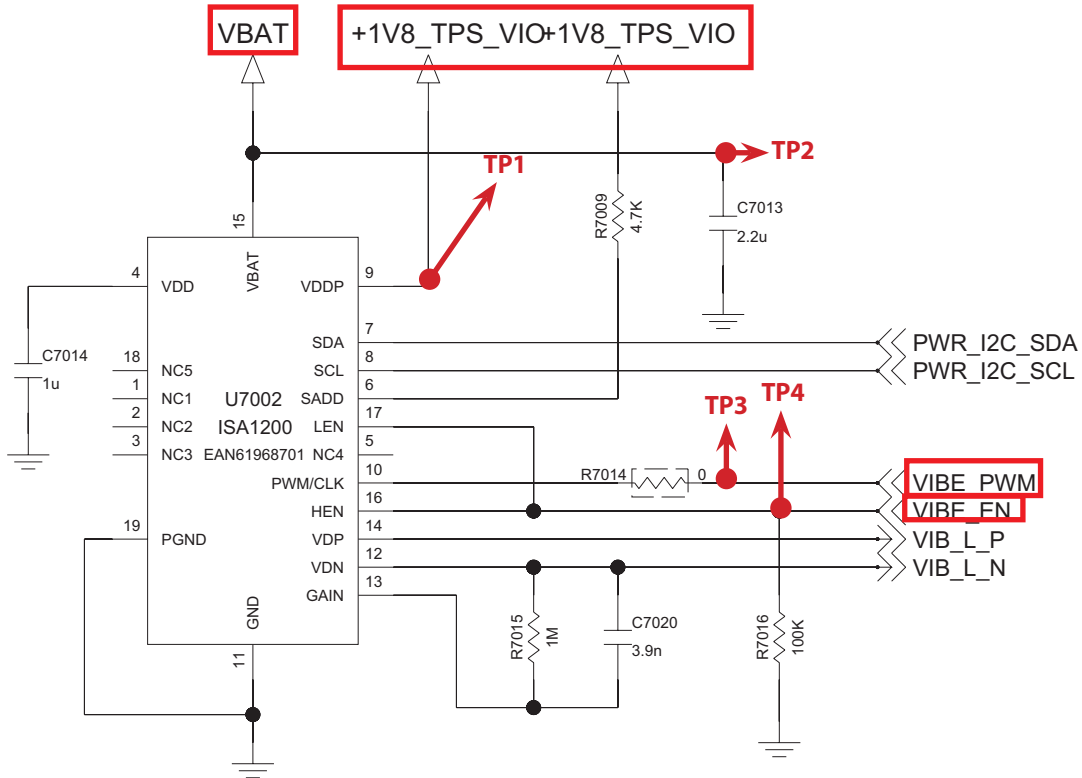


4.18 Vibrator Troubleshooting

Check out the setting menu on the phone. If not, check Test points shown on the pictures

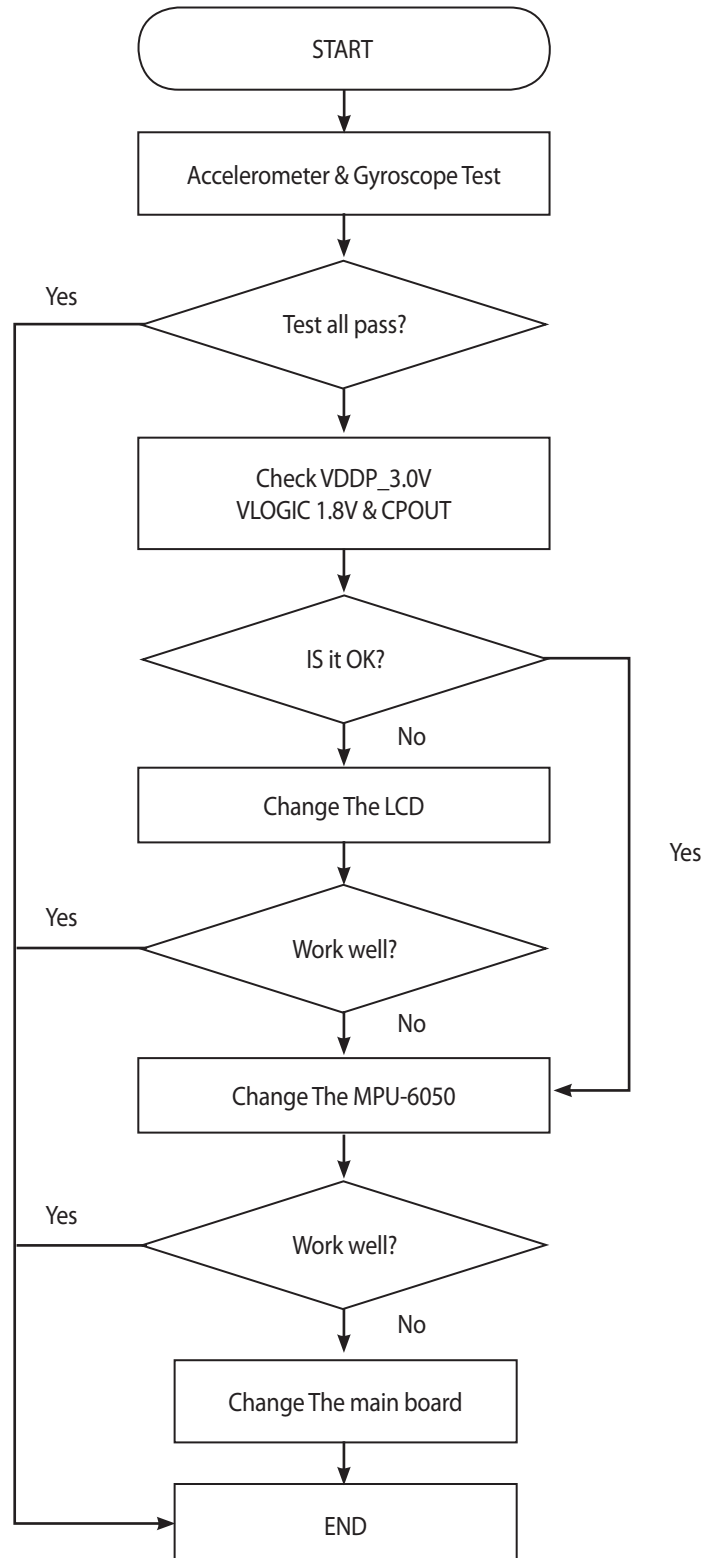


4. TROUBLE SHOOTING



4.19 Motion/Gyro sensor(MPU-6050) troubleshooting

When the motion/gyro sensor does not work, check the VDD and VLOGIC first, and then change the LDOs or MPU-6050 sensor.

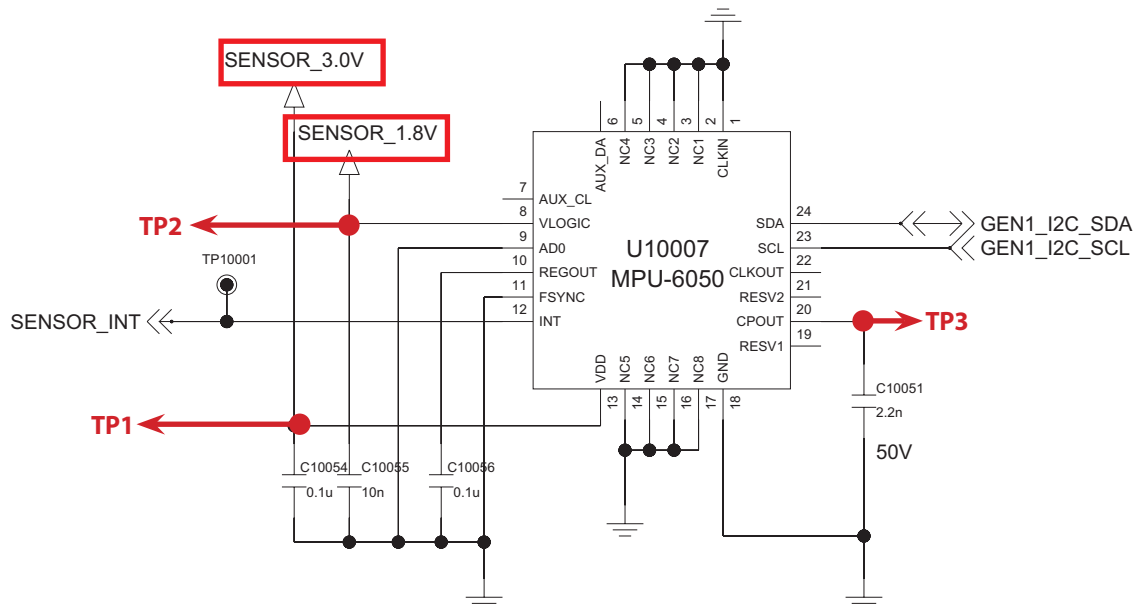


Measurement

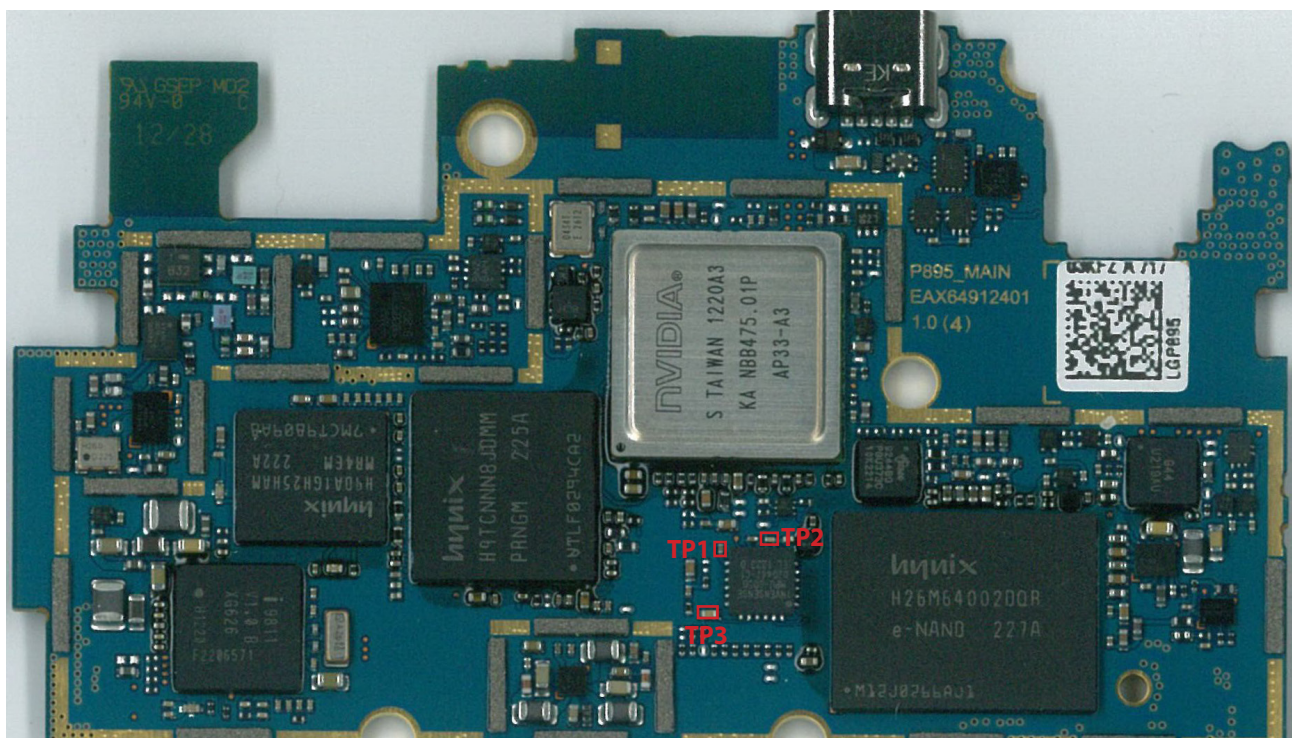
VDD 3.0V : SENSOR_3.0V (TP1)
VLOGIC 1.8V : SENSOR_1.8V (TP2)
CPOUT (TP3)

GYRO+MOTION Sensor In Main board

GYRO&MOTION



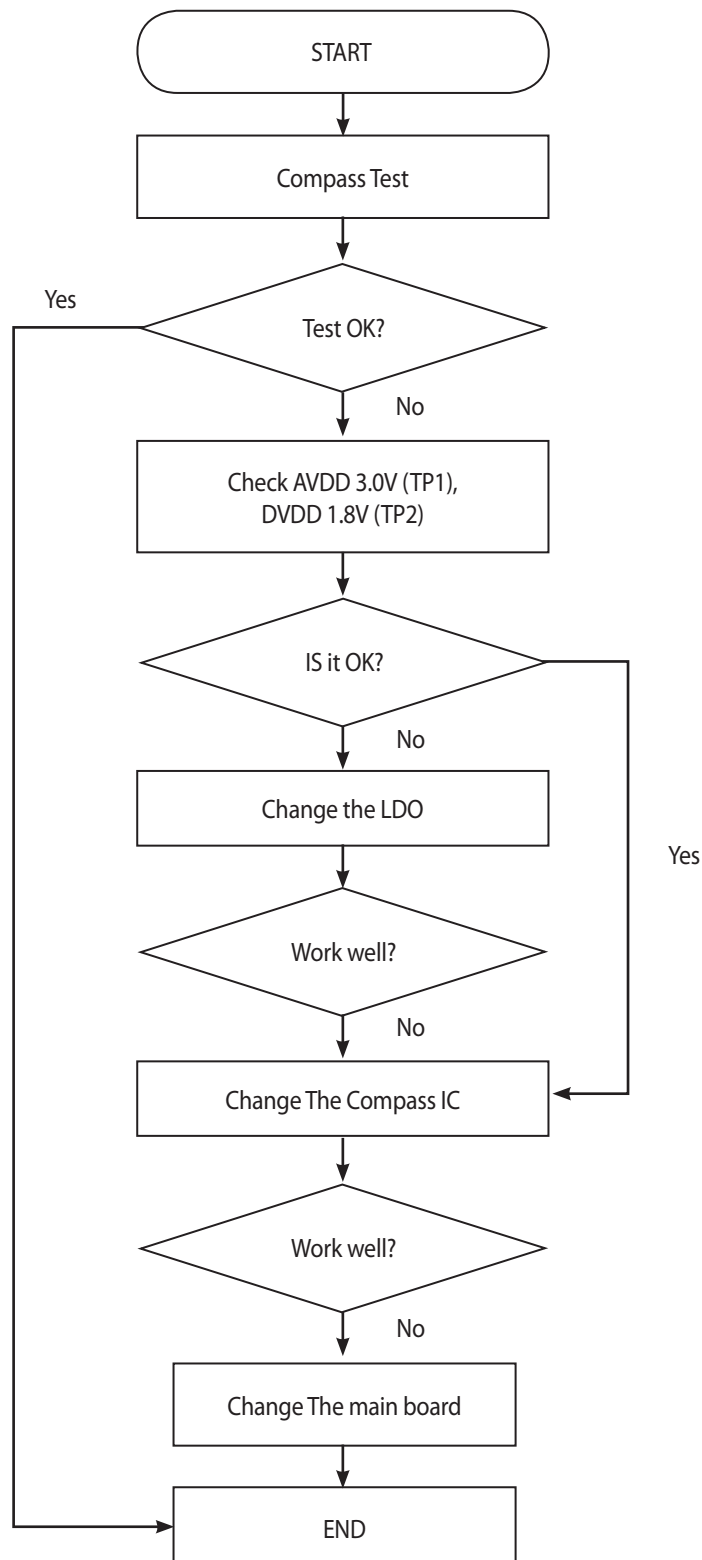
Gyro + Motion Sensor



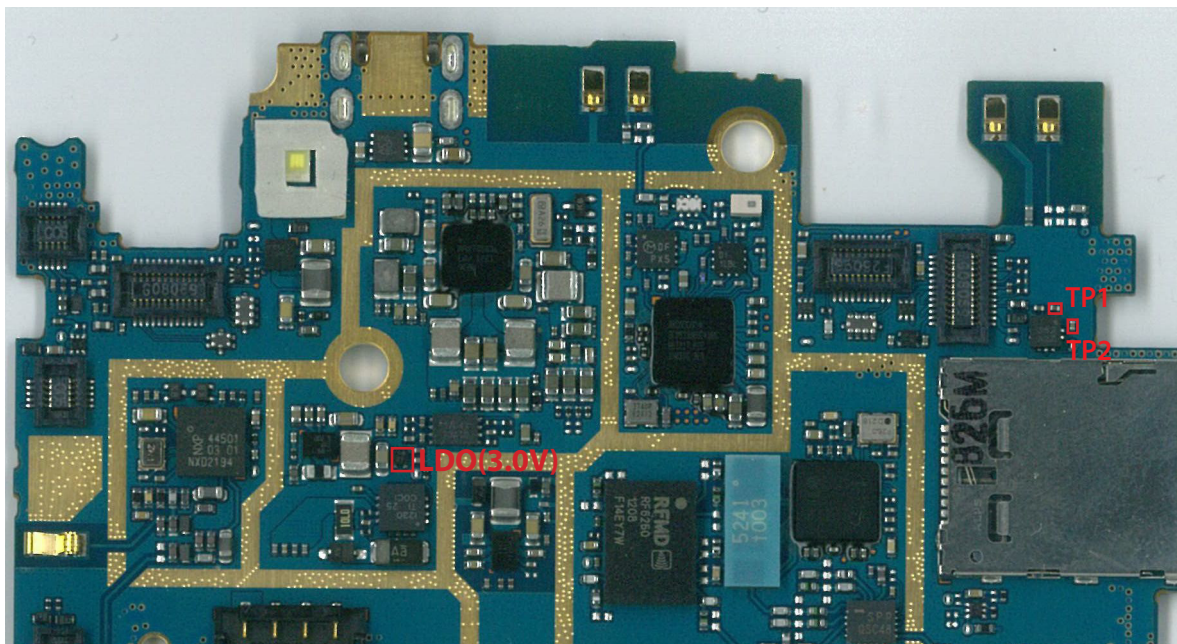
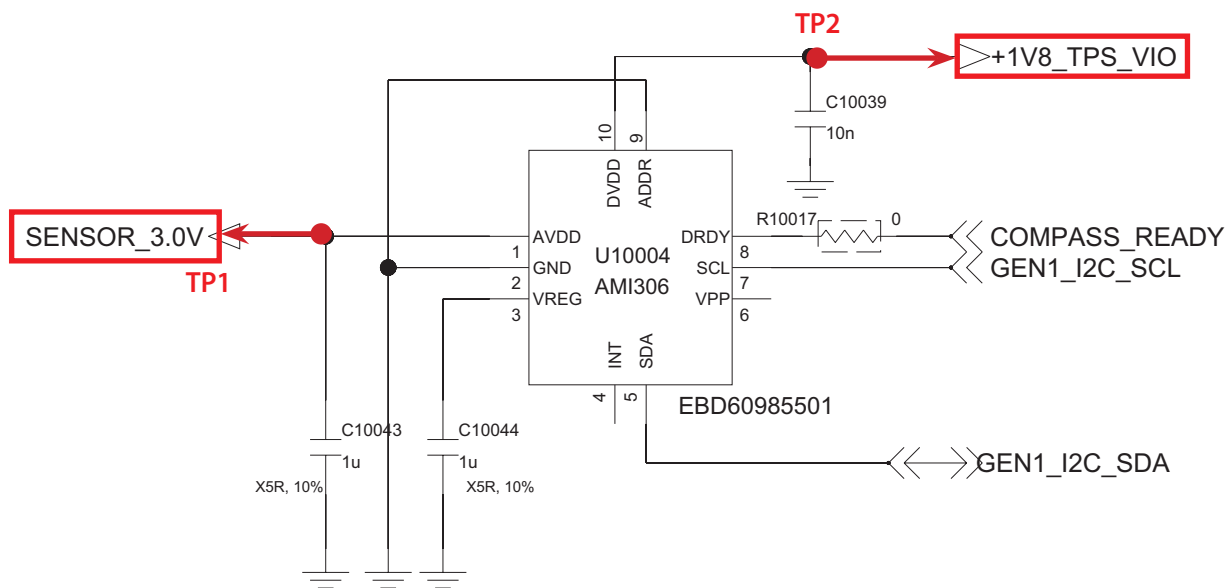
Top Of Main board

4.20 Compass sensor trouble

Check out the setting menu on the phone. If not, check Test points shown on the pictures.



Compass Sensor

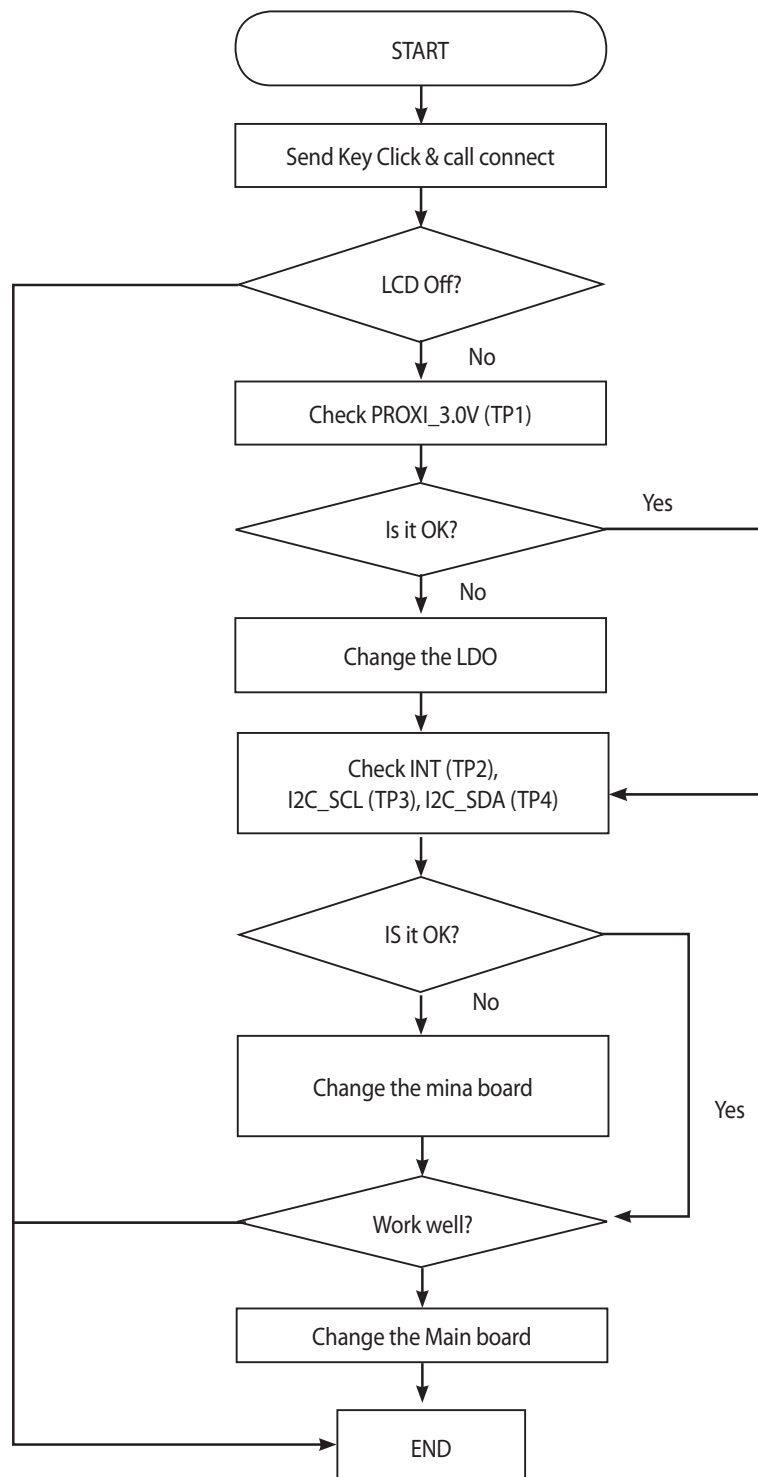


Bottom Of Main board

4.21 Proximity Sensor on/off trouble

Proximity Sensor is worked as below:

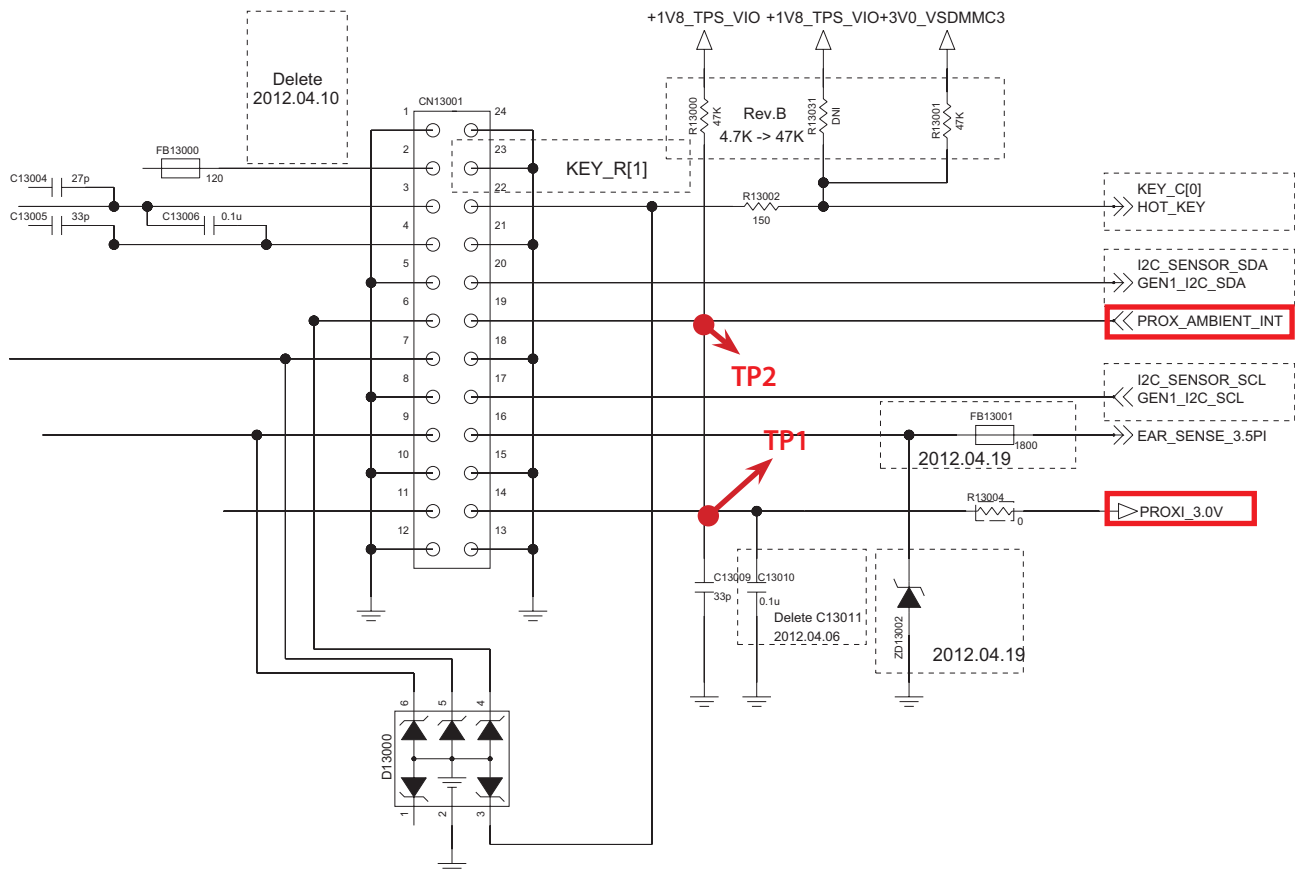
Send Key click -> Phone number click -> Call connected -> Object moved to/from the sensor -> Control the screen's on/off operation automatically



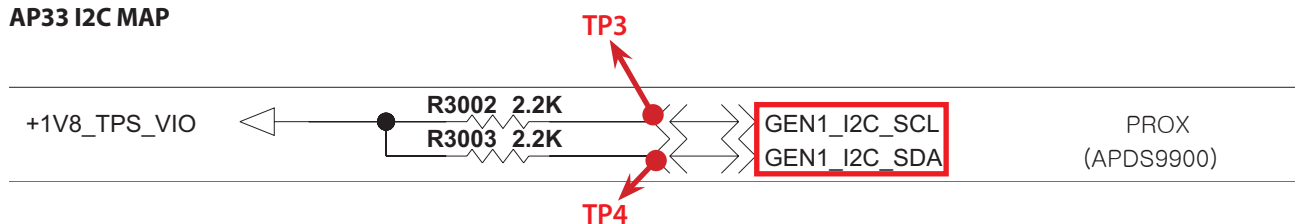
EARJACK_FPCB CONNECTOR

Earjack FPCB

earjack, hot key, prox&ALS, 2nd MIC

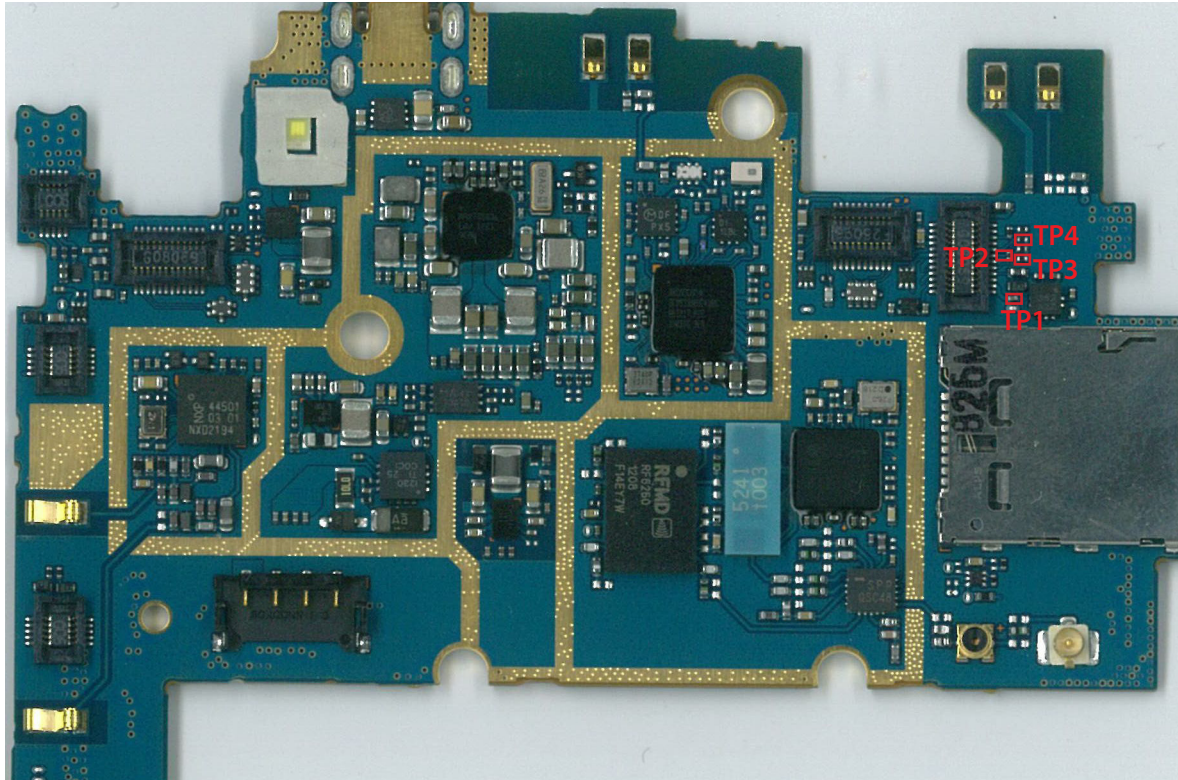


AP33 I2C MAP



4. TROUBLE SHOOTING

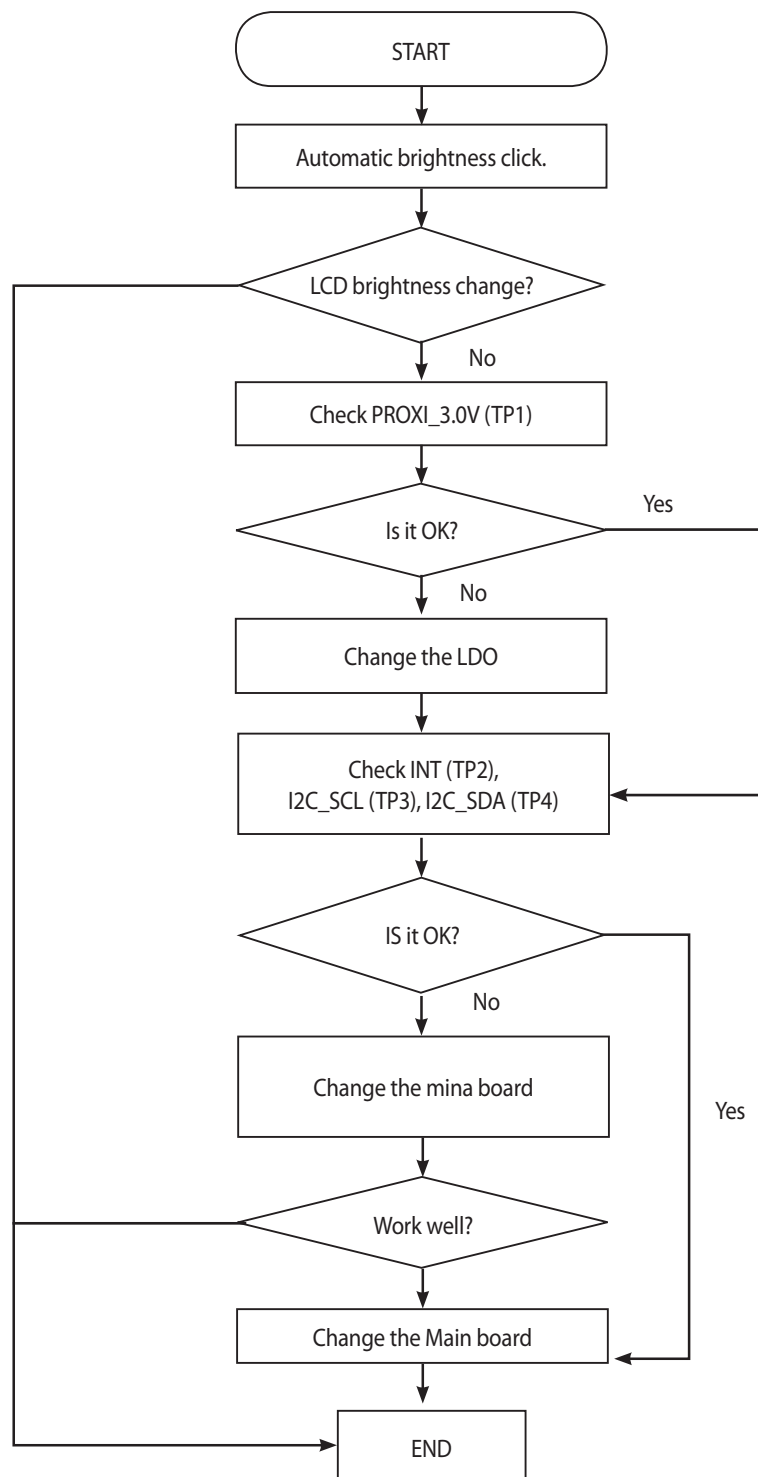
BOTTOM Of Main board



4.22 Illumination Sensor on/off trouble

Illumination Sensor is worked as below:

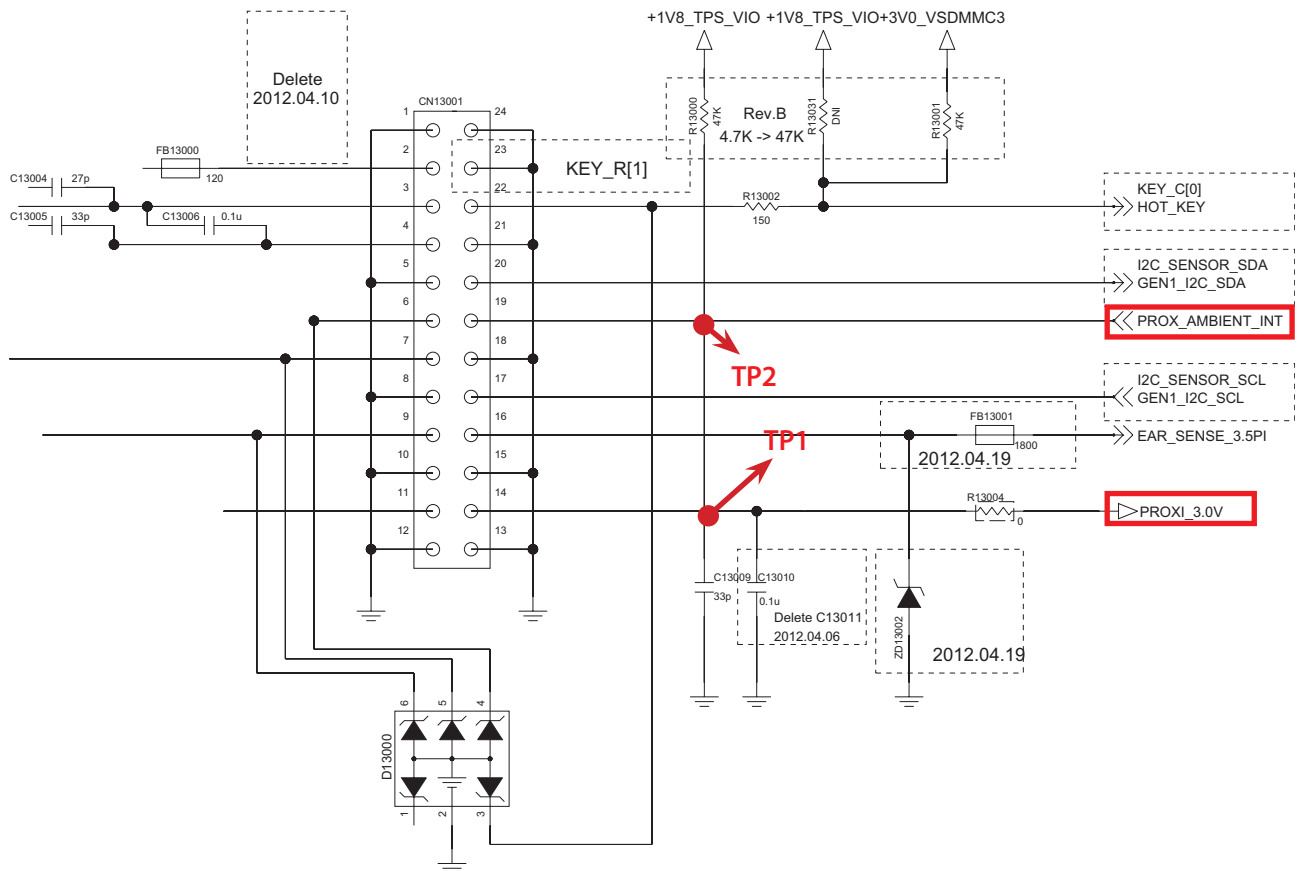
Menu Key click -> Settings click -> Display click -> Brightness click -> Automatic brightness click -> Move the UI bar to select the base brightness



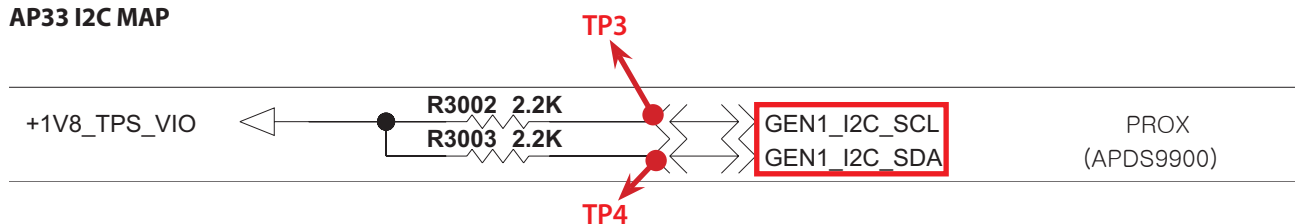
EARJACK_FPCB CONNECTOR

Earjack FPCB

earjack, hot key, prox&ALS, 2nd MIC

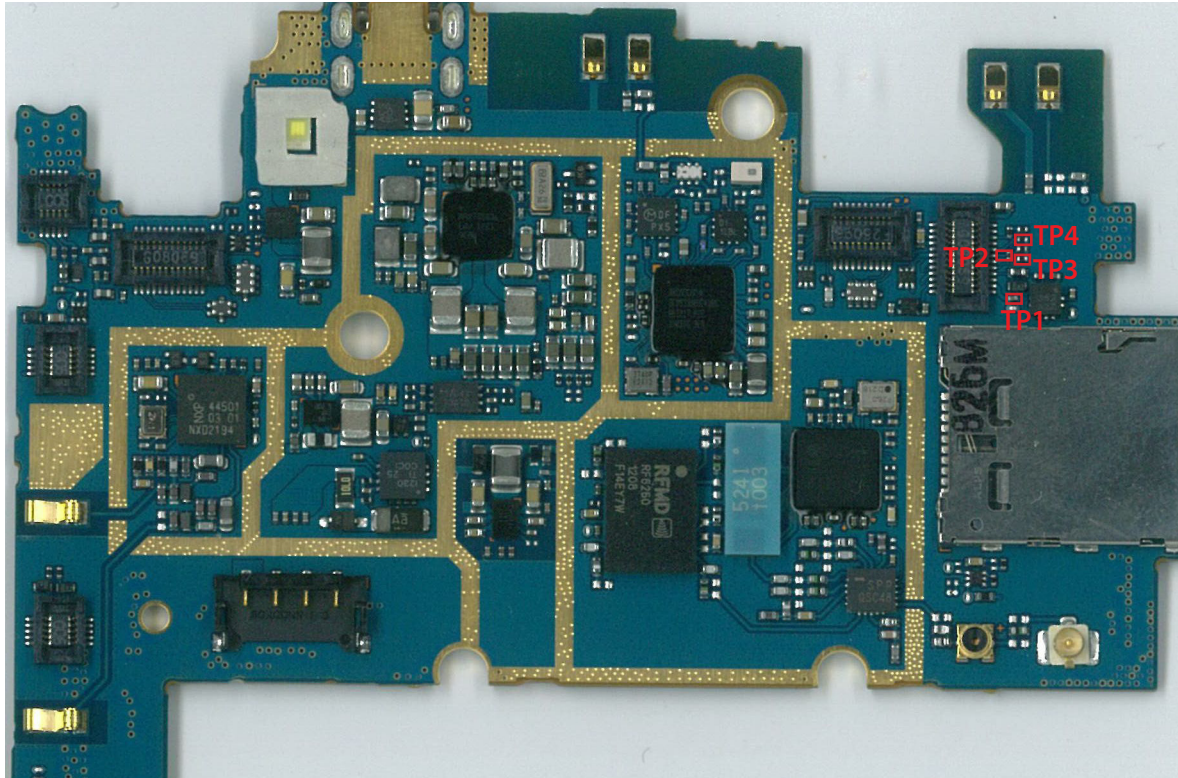


AP33 I2C MAP



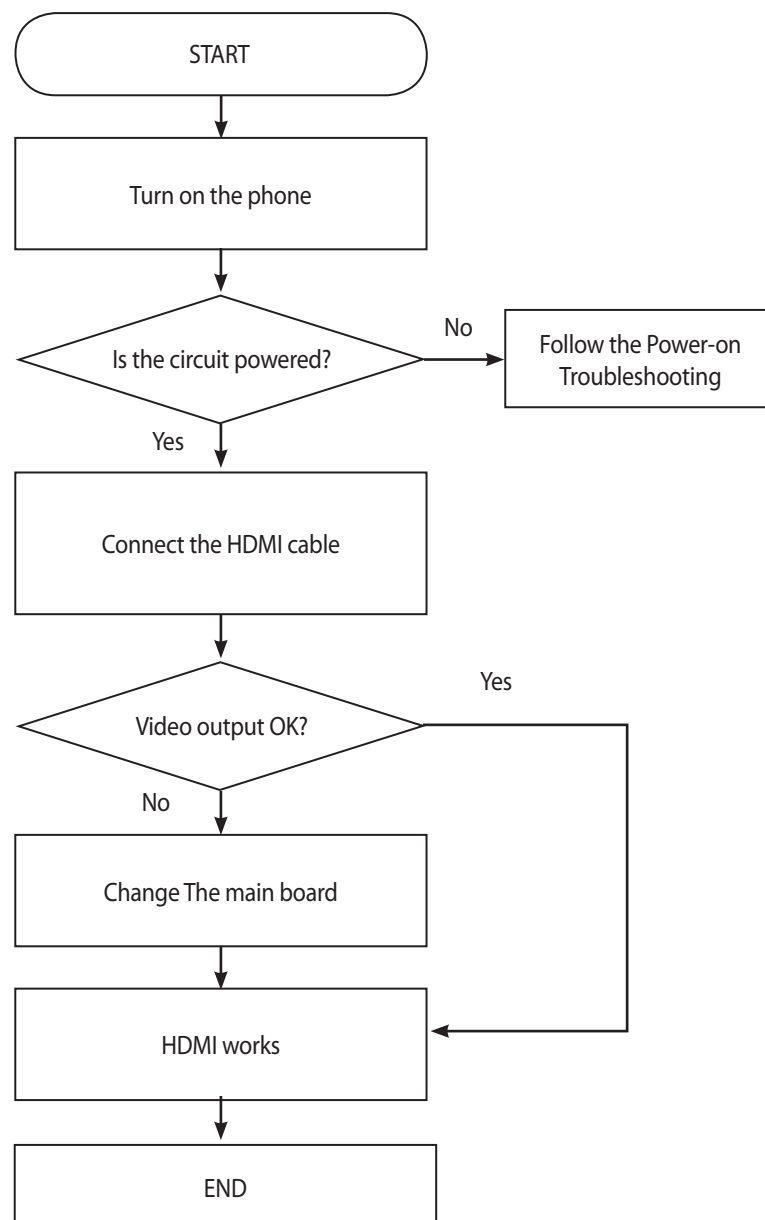
4. TROUBLE SHOOTING

BOTTOM Of Main board



4.23 HDMI Troubleshooting

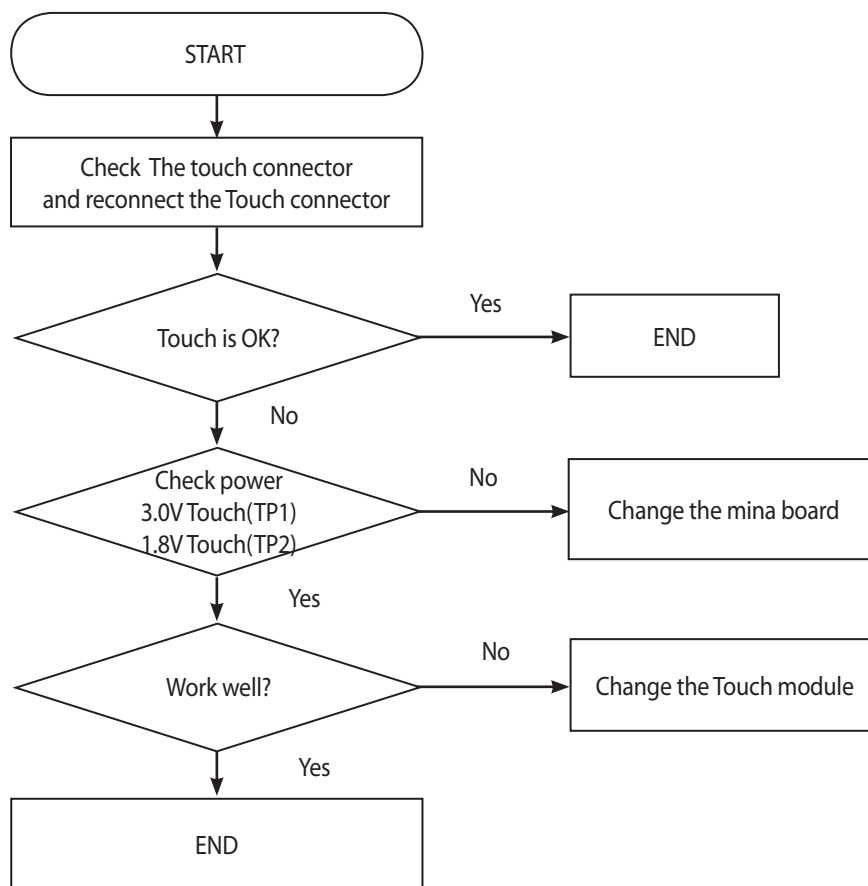
Check out the setting menu on the phone and then set the proper resolution for the outer display as shown below



4.24 Touch Troubleshooting

Touch control signals are generated by AP30. Those signal's path are :

AP30 -> Touch Module

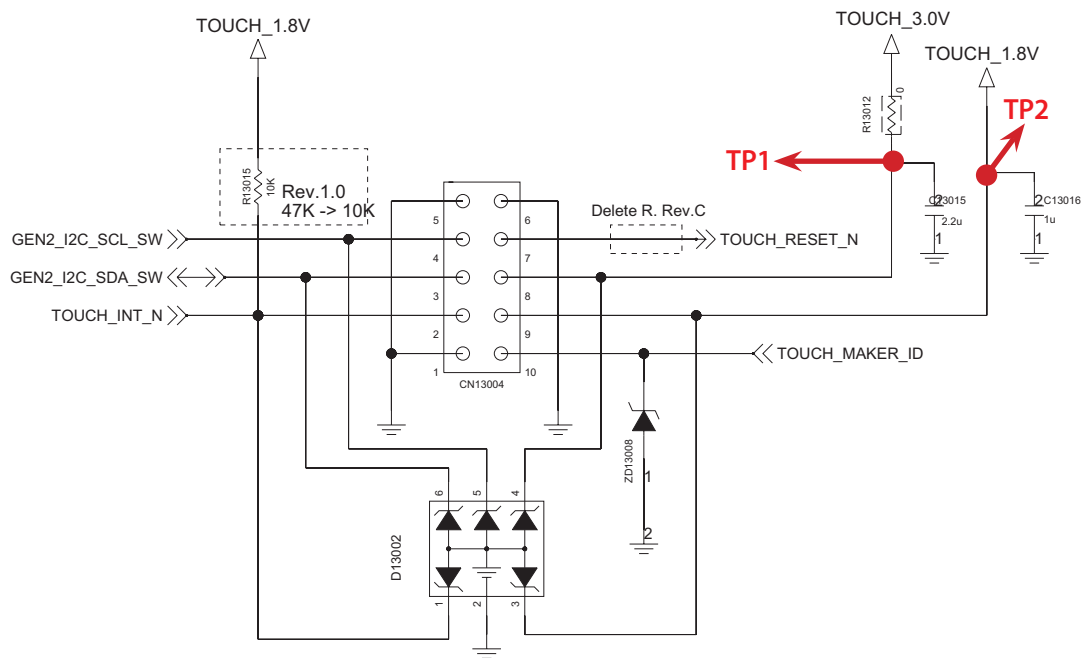


Measurement

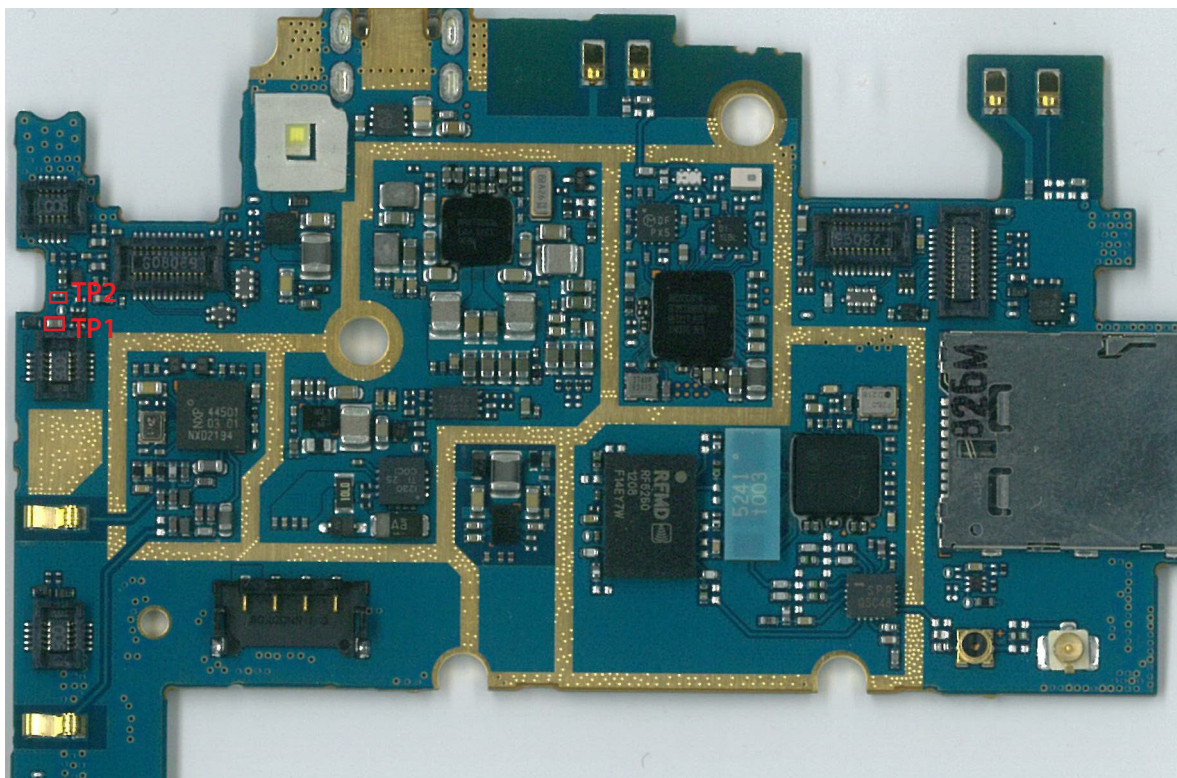
3.0V TOUCH (TP1)

1.8V TOUCH (TP2)

5" TOUCH CONN.

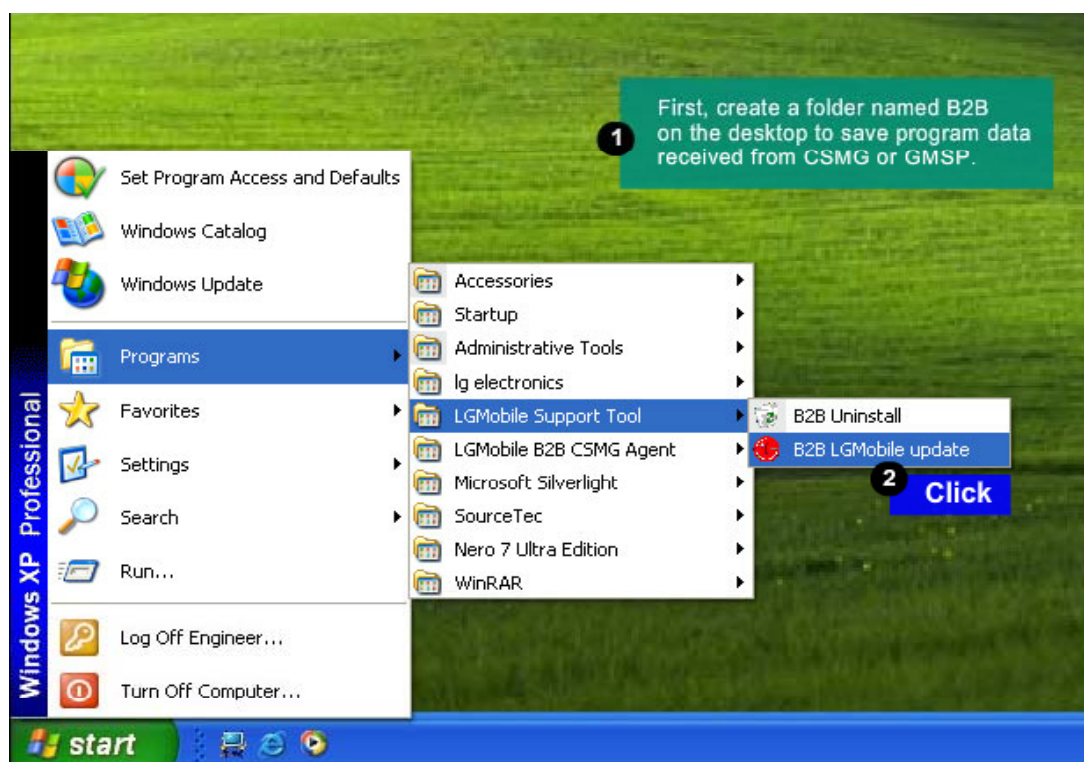


Bottom Side

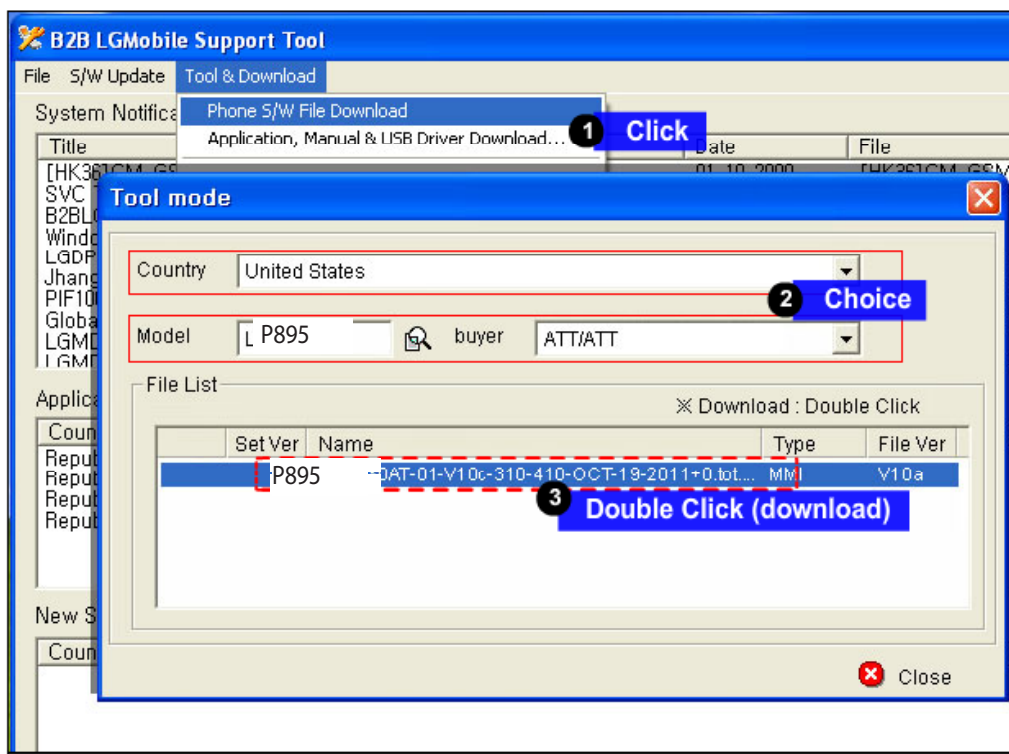
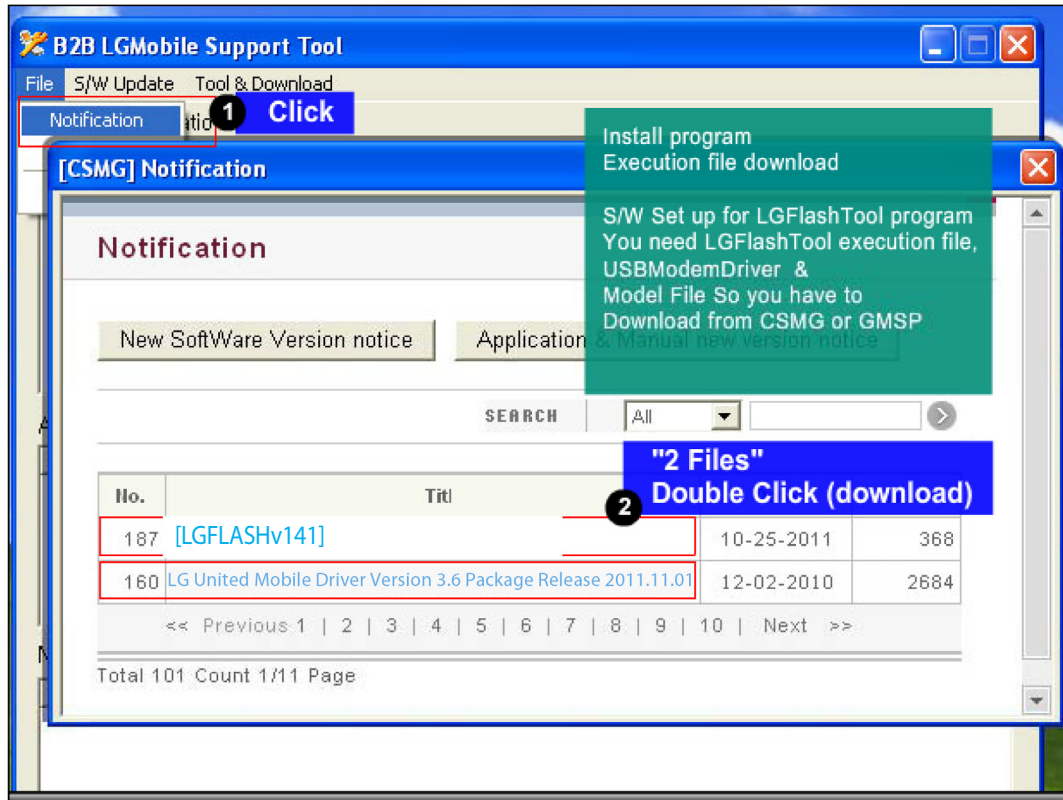


5. DOWNLOAD

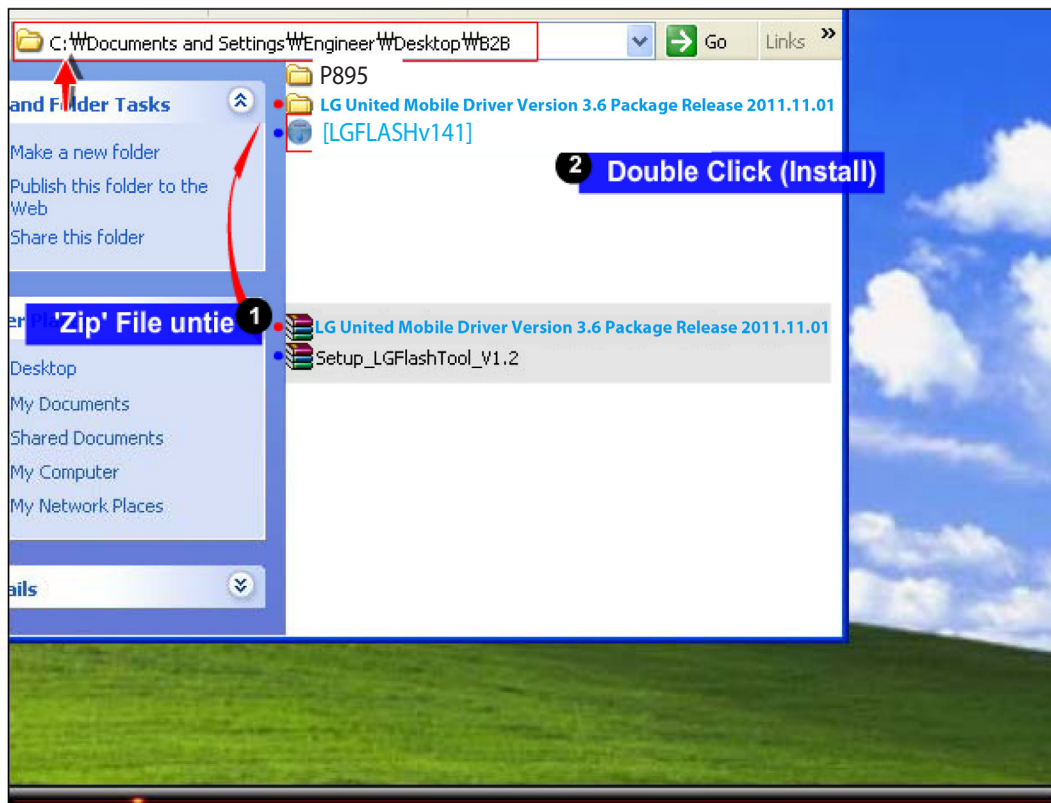
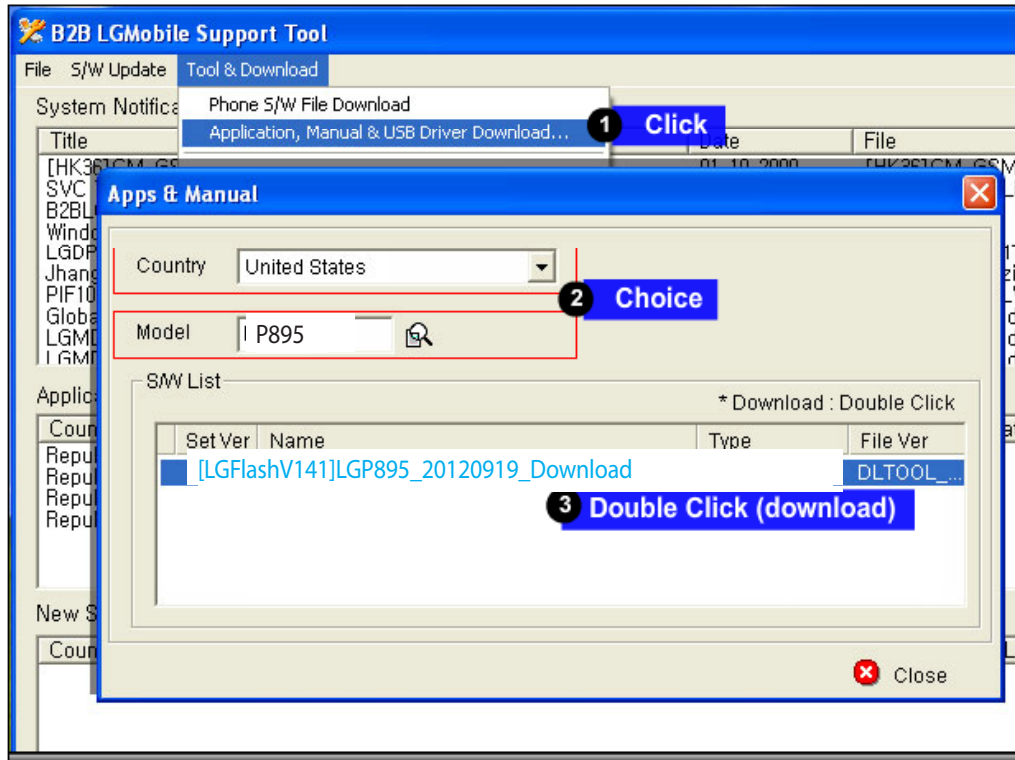
TOOL INFORMATION		
TOOL VERSION	DLL NAME	USB DRIVER
[LGFLASHv141]	[LGFlashV141]LGP895_20120919_ Download	LG United Mobile Driver Version 3.6 Package Release 2011.11.01
Please Check the Version to "B2B"		
H/W		
	Name	Part No.
D/L Cable	Micro 5P (56-open-910K) USB DLC	RAD32167835

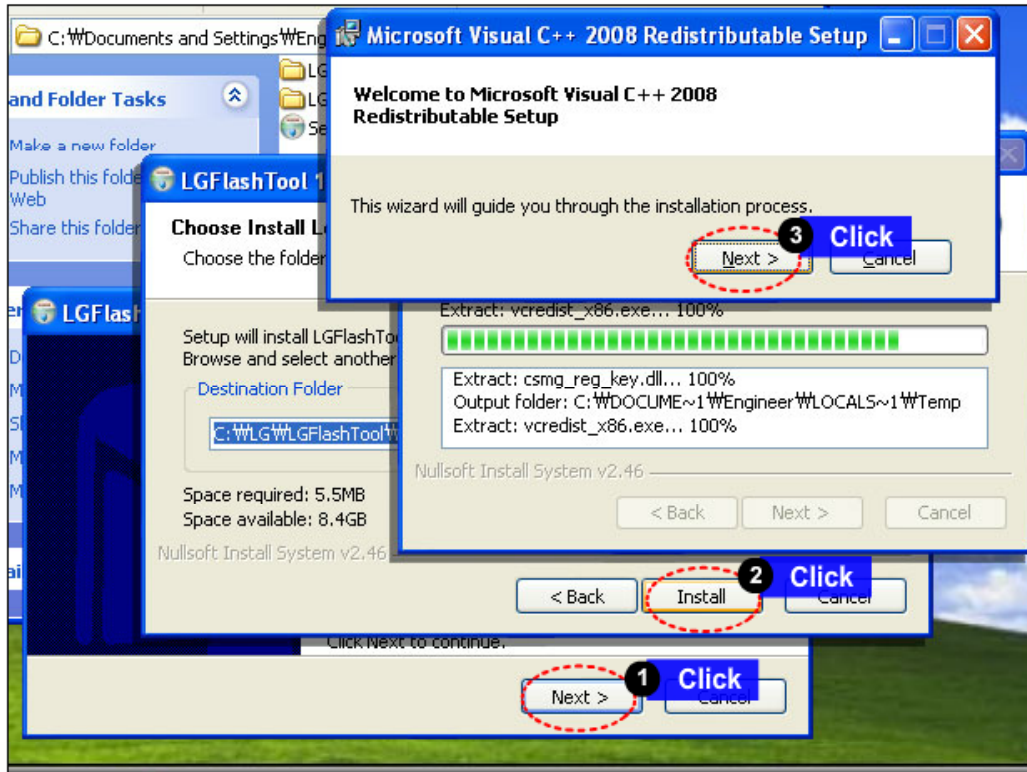


5. DOWNLOAD

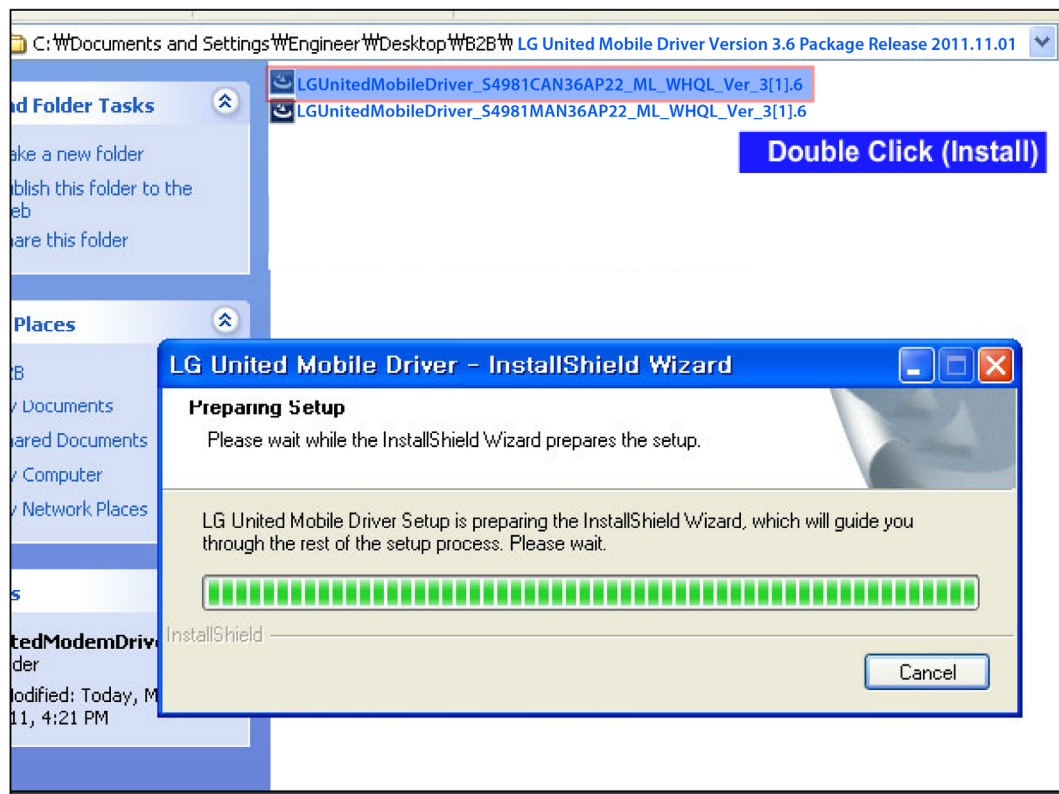
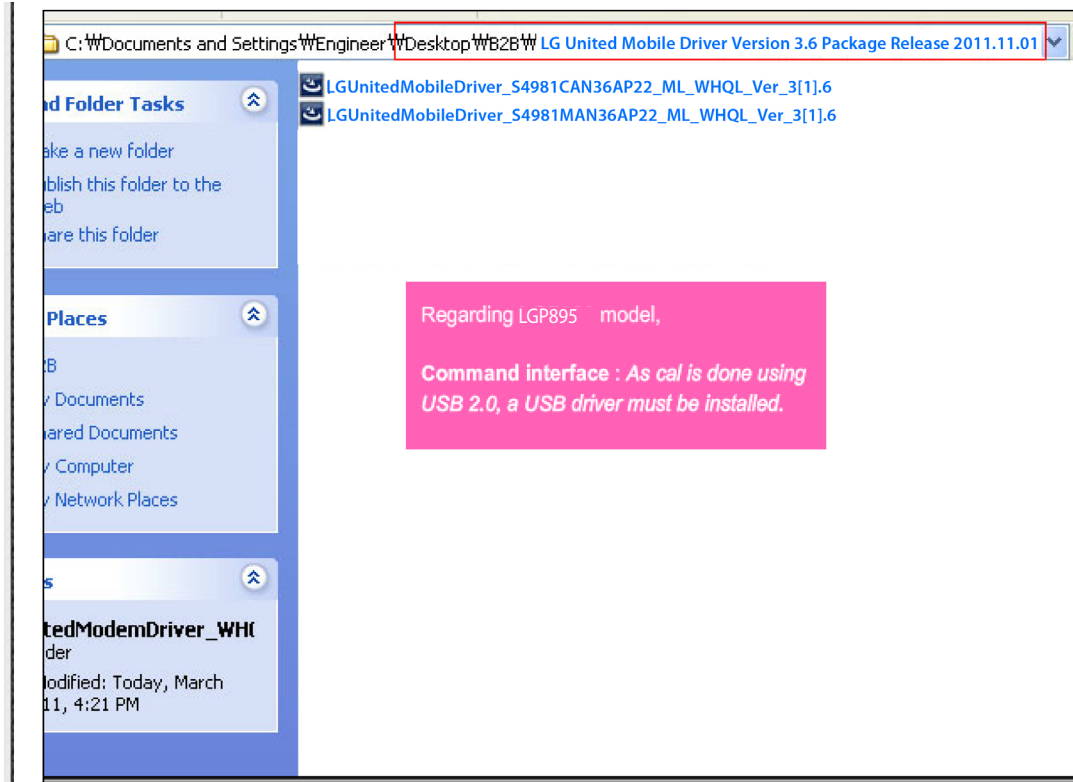


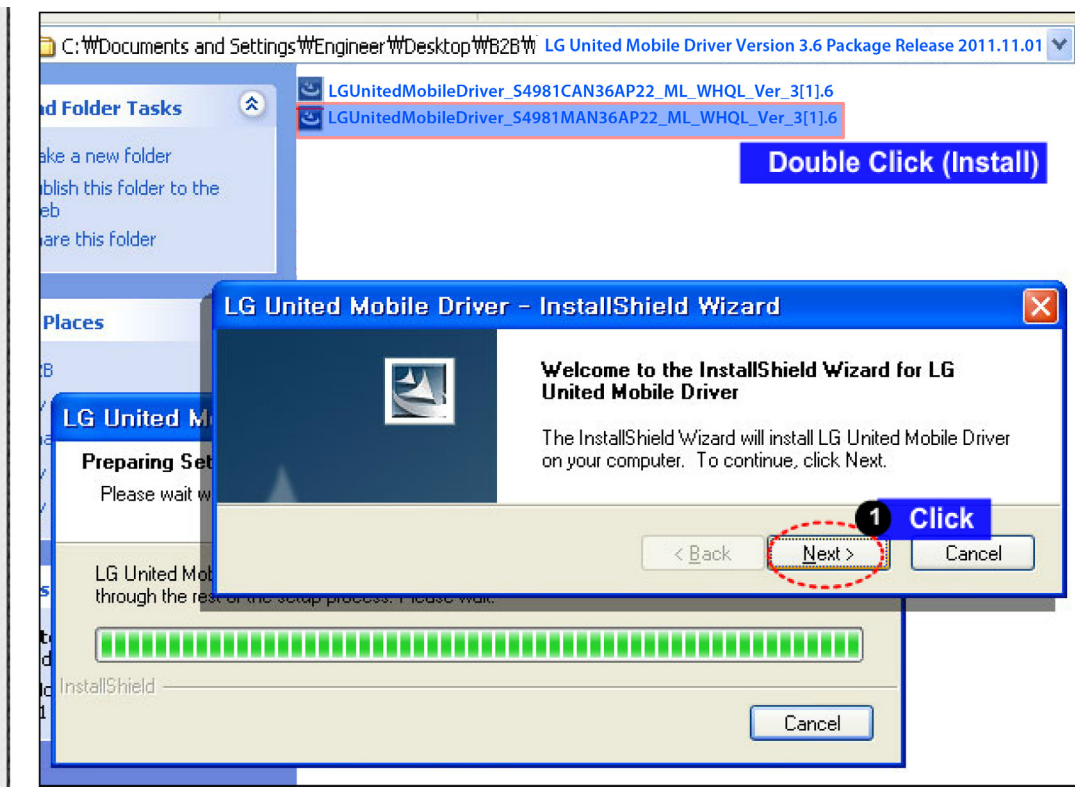
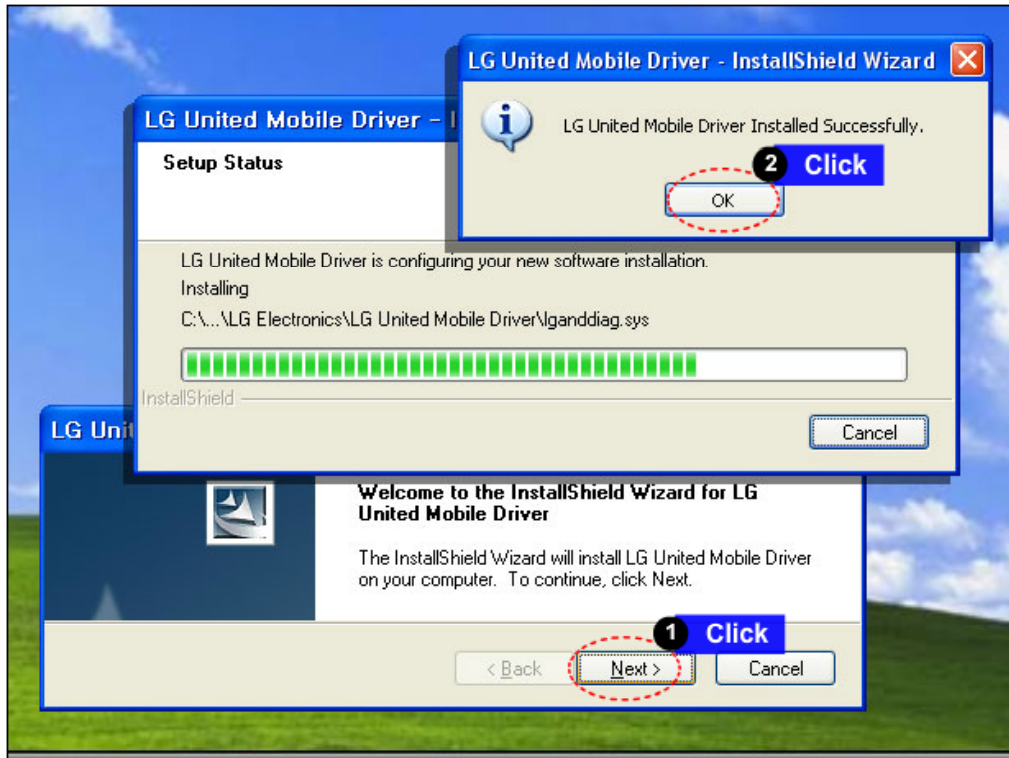
5. DOWNLOAD

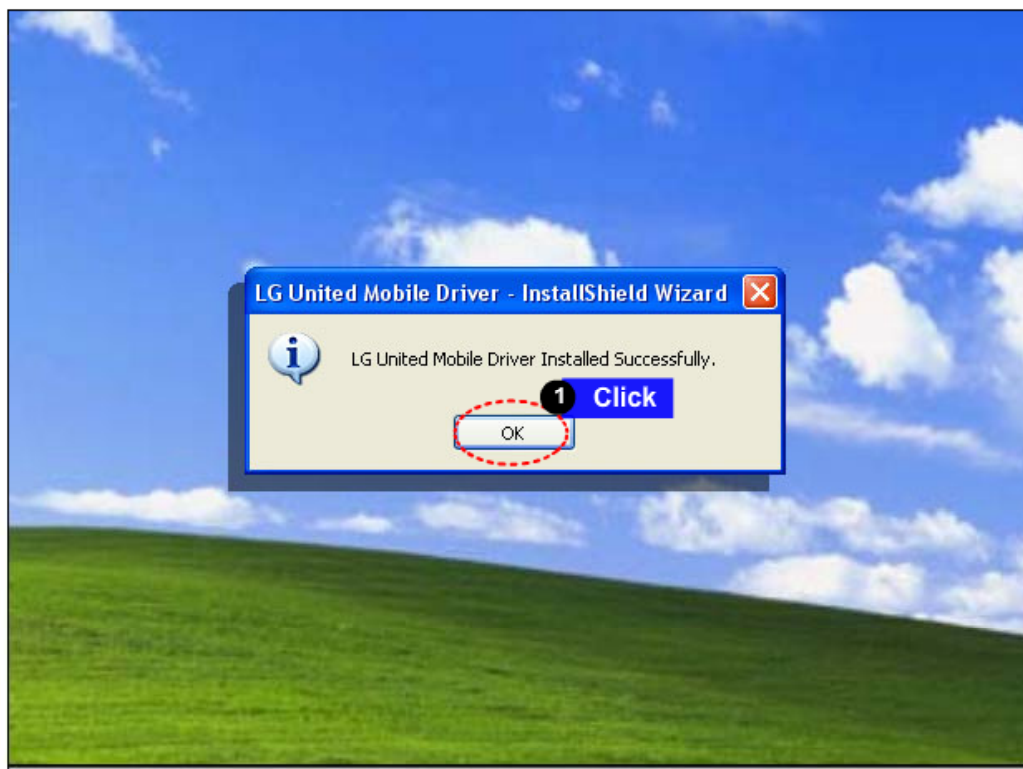
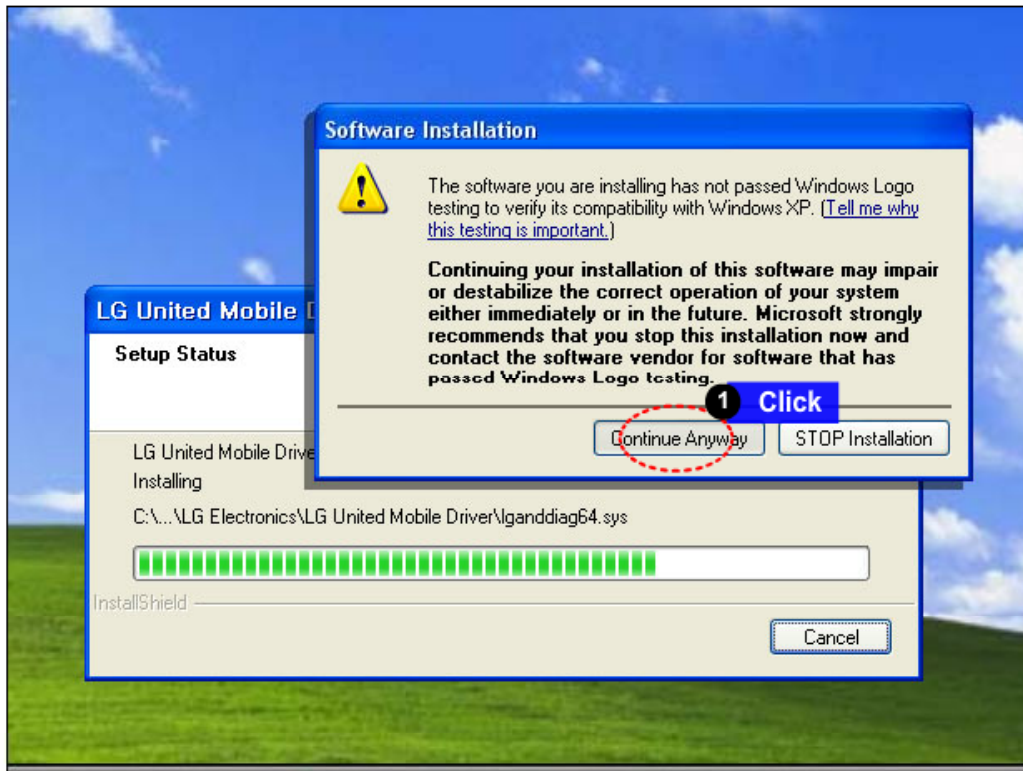




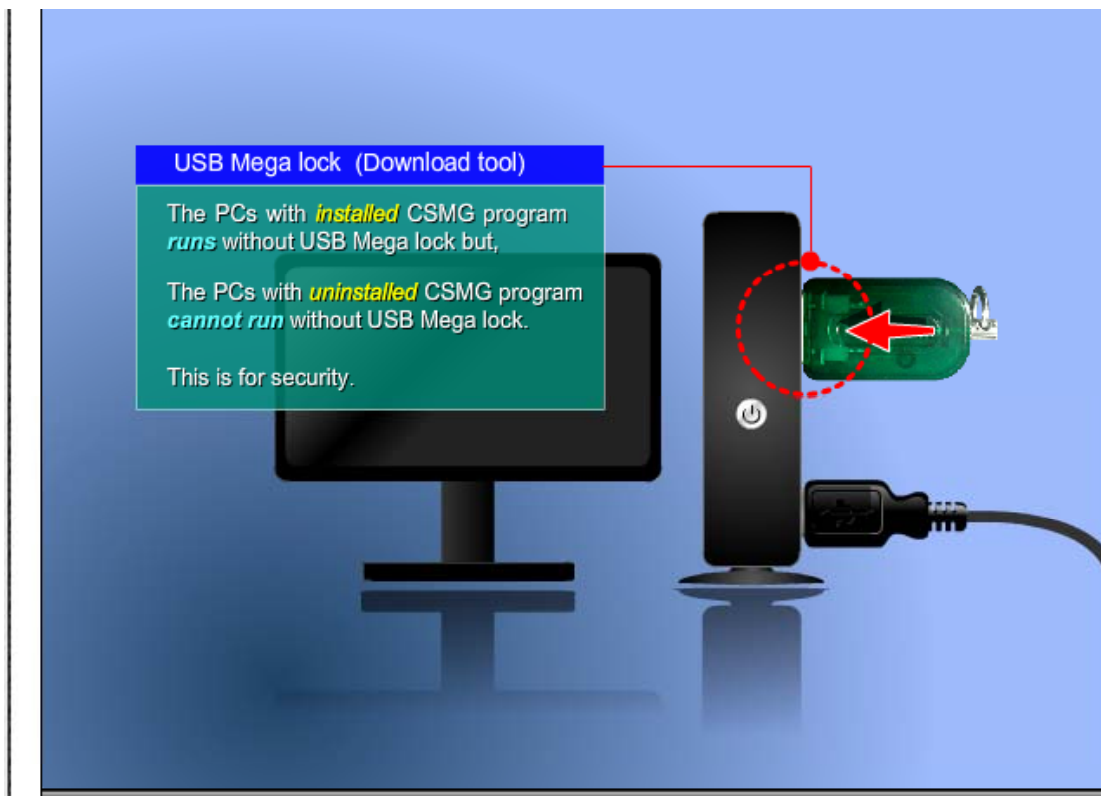
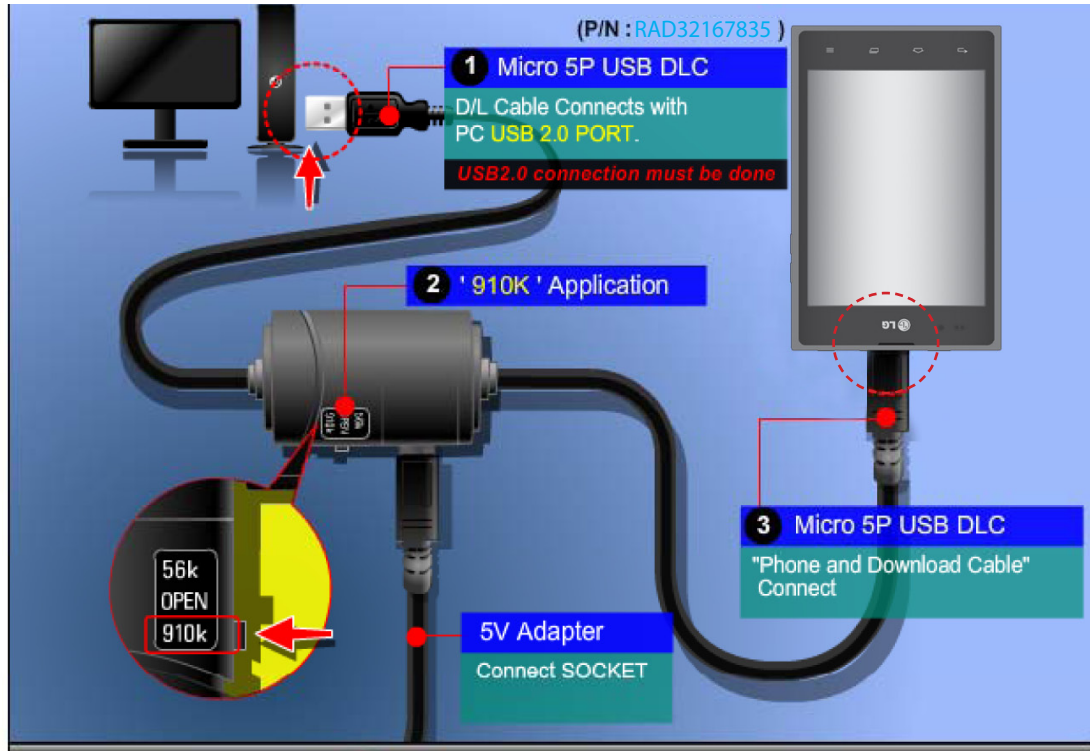
5. DOWNLOAD

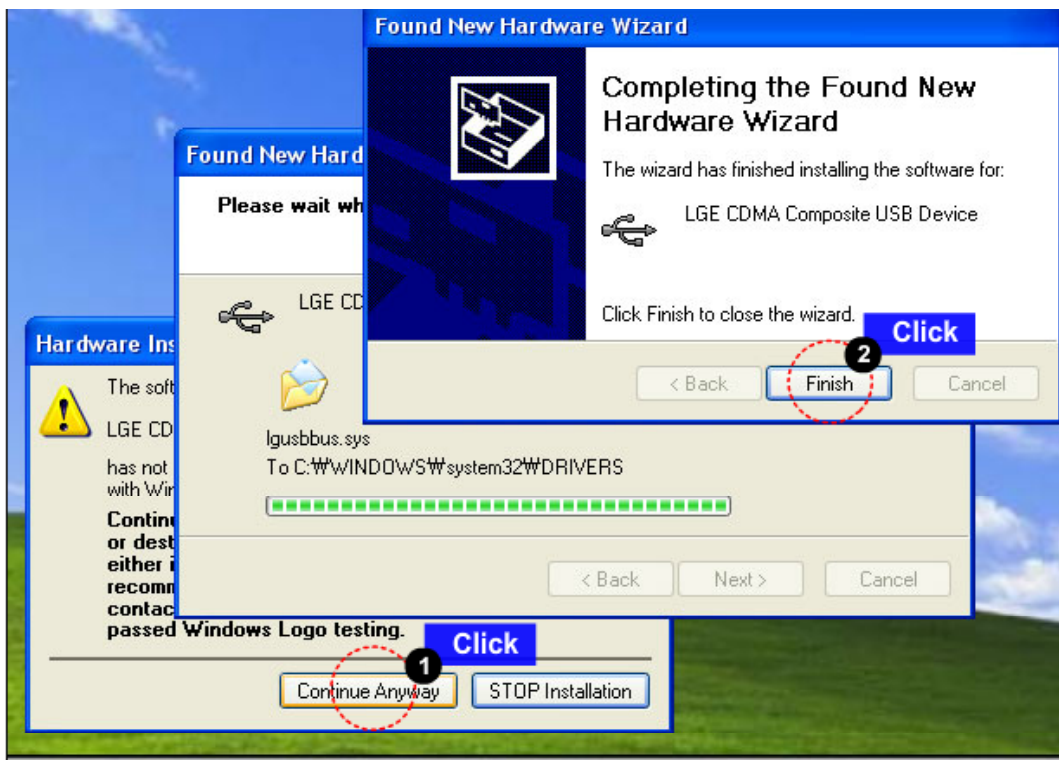
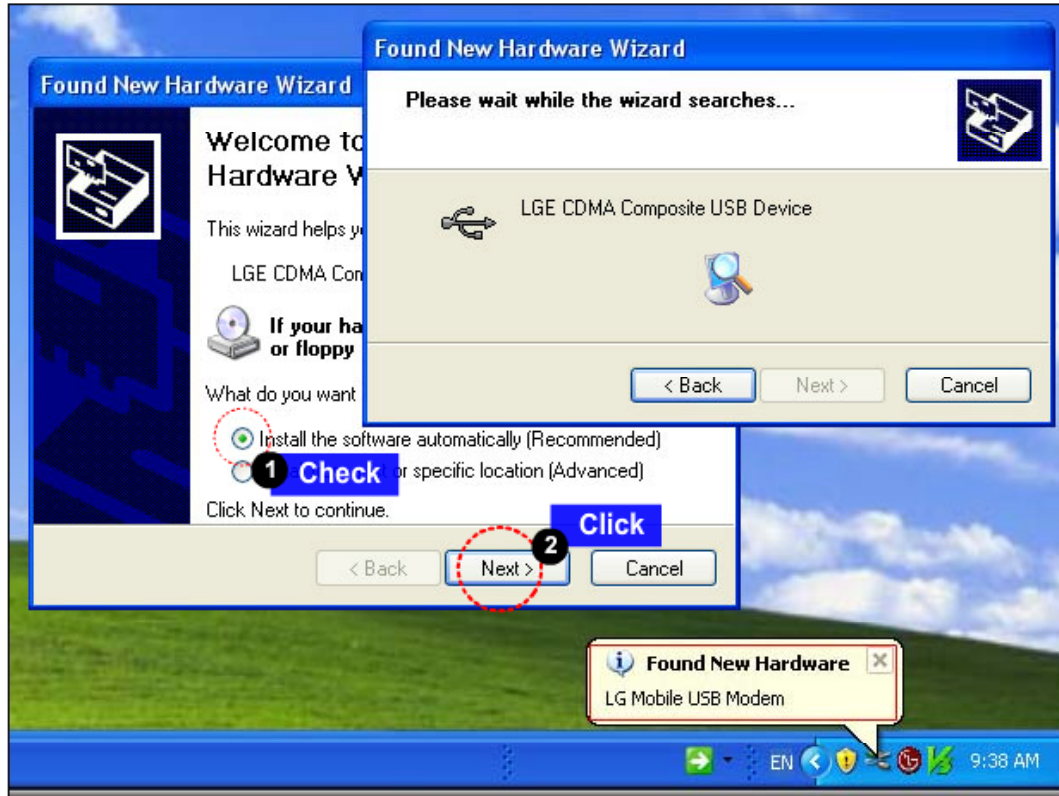




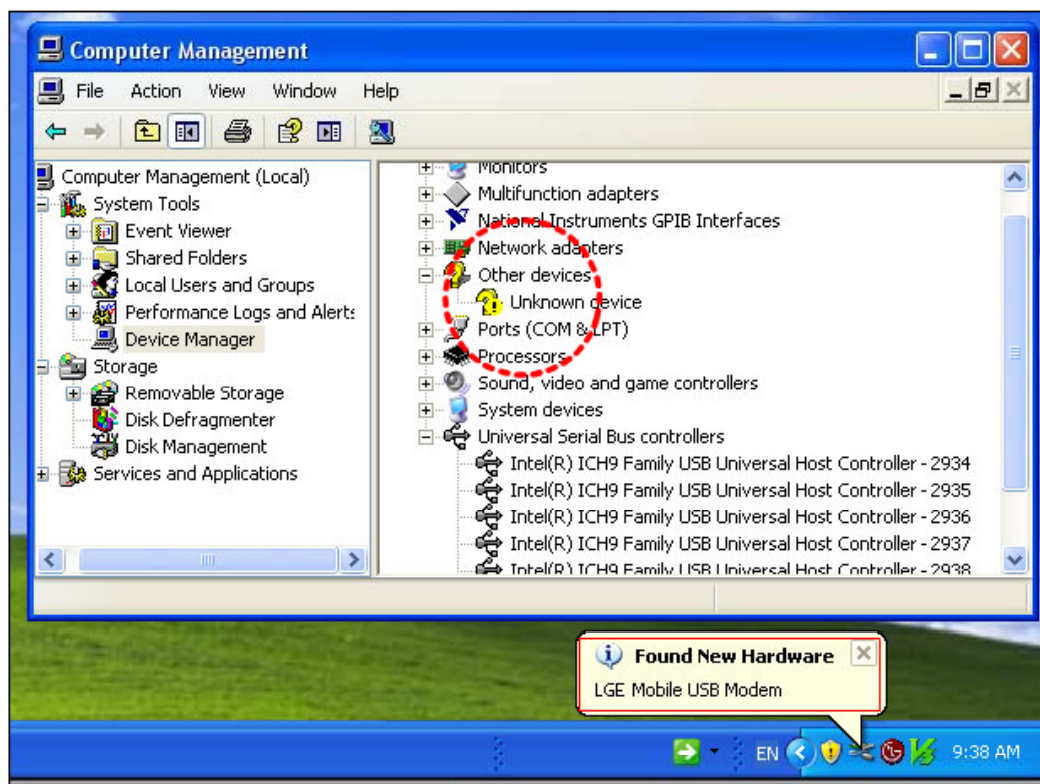
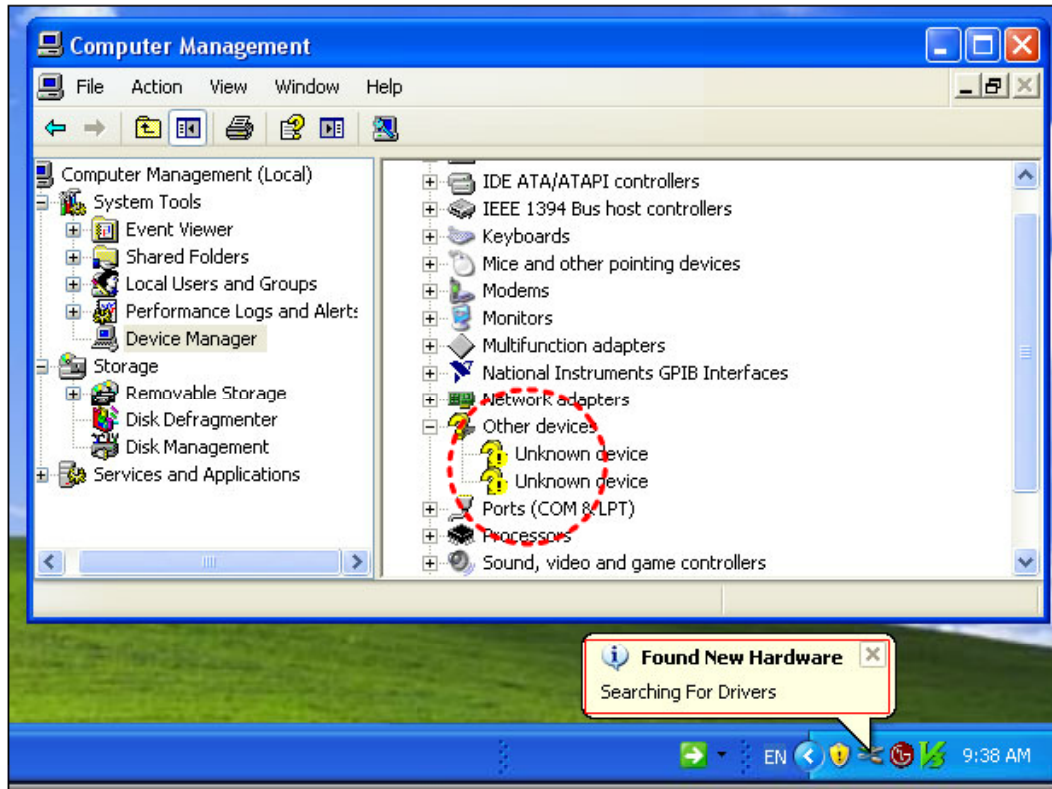


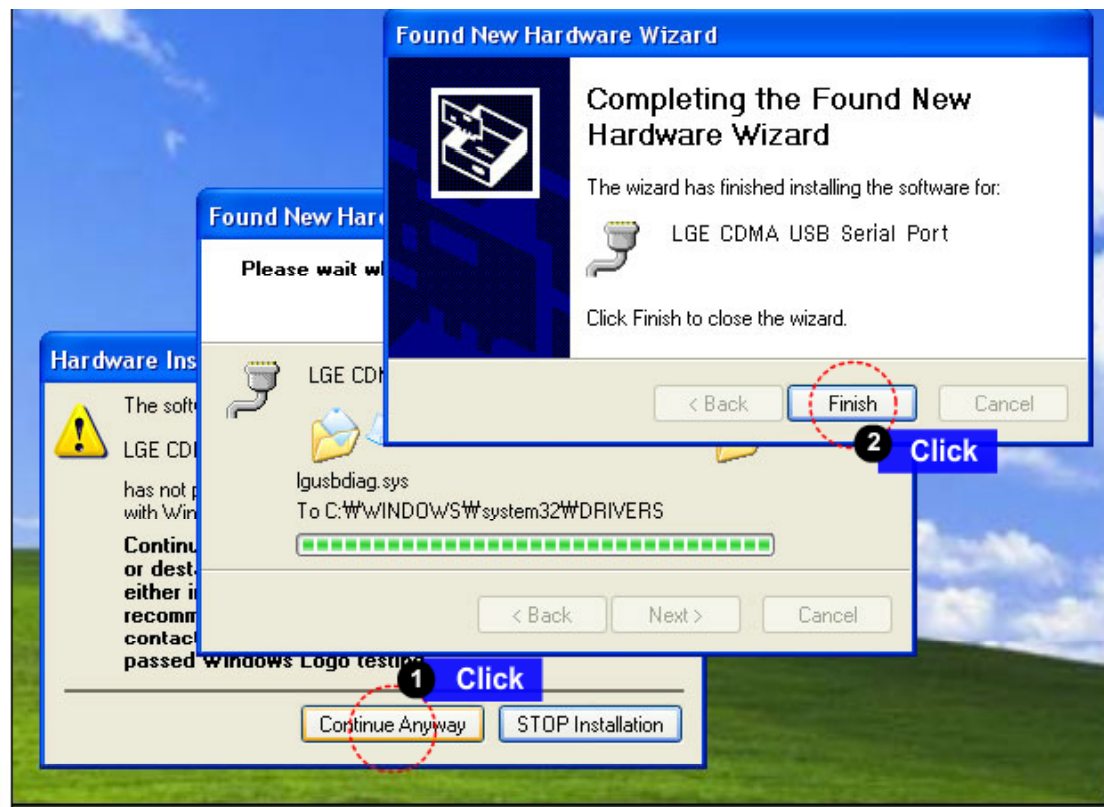
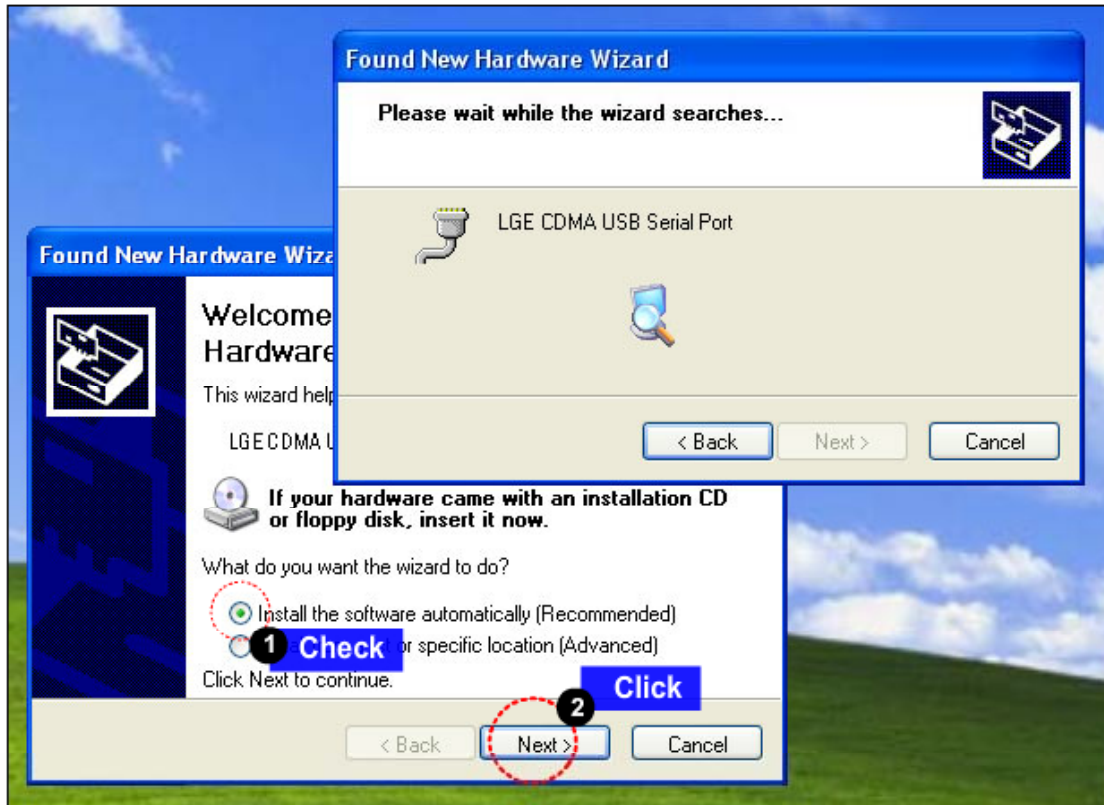
5. DOWNLOAD



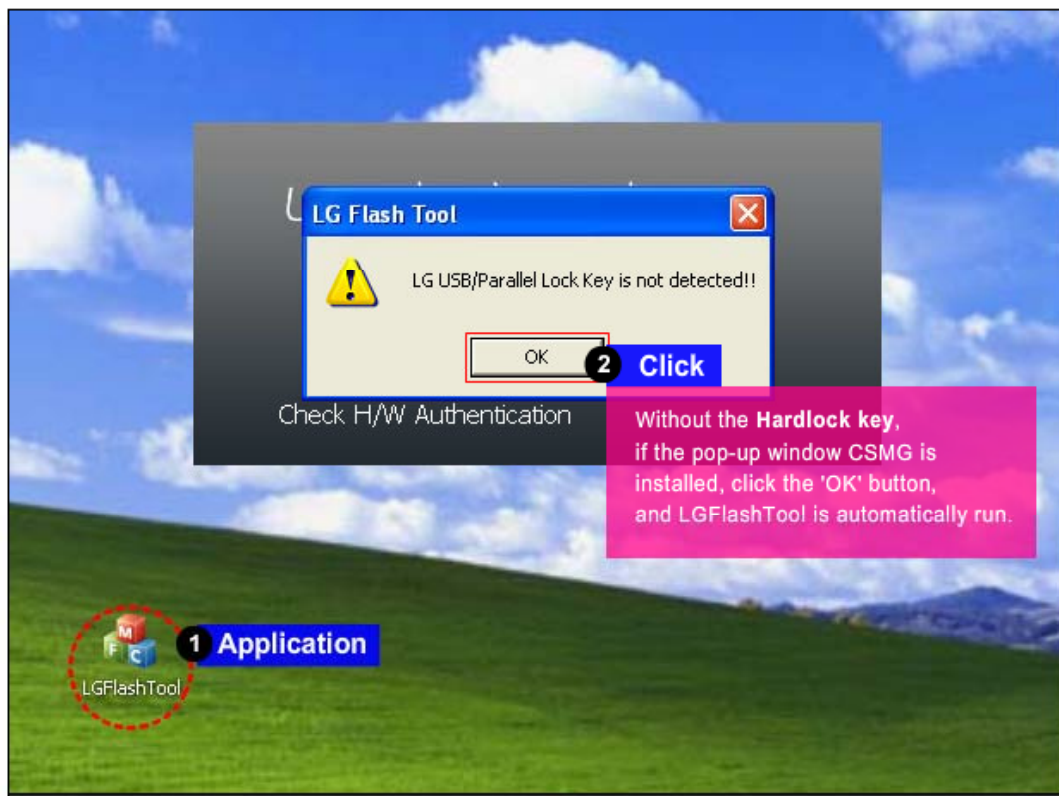
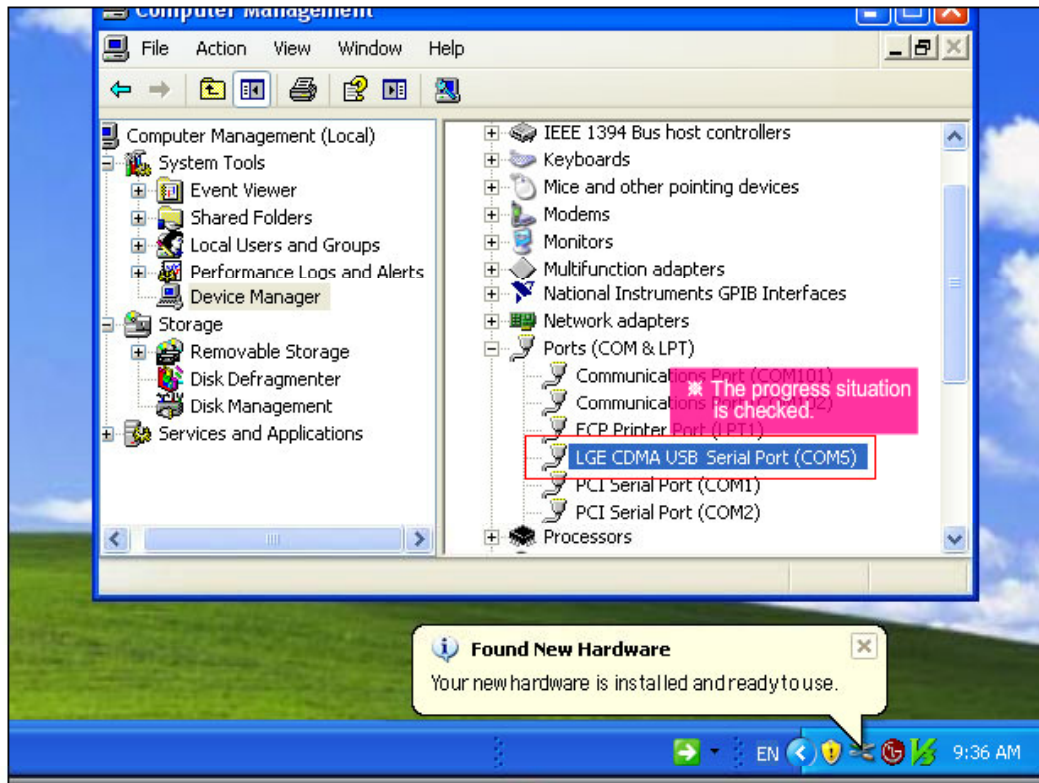


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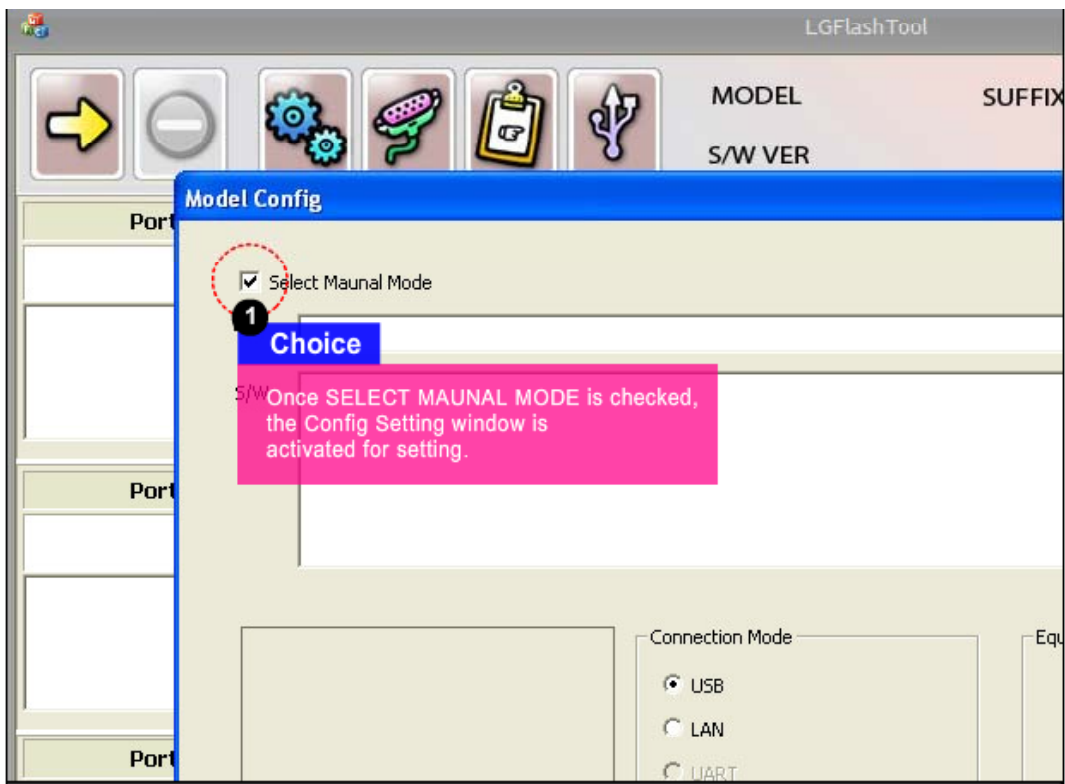
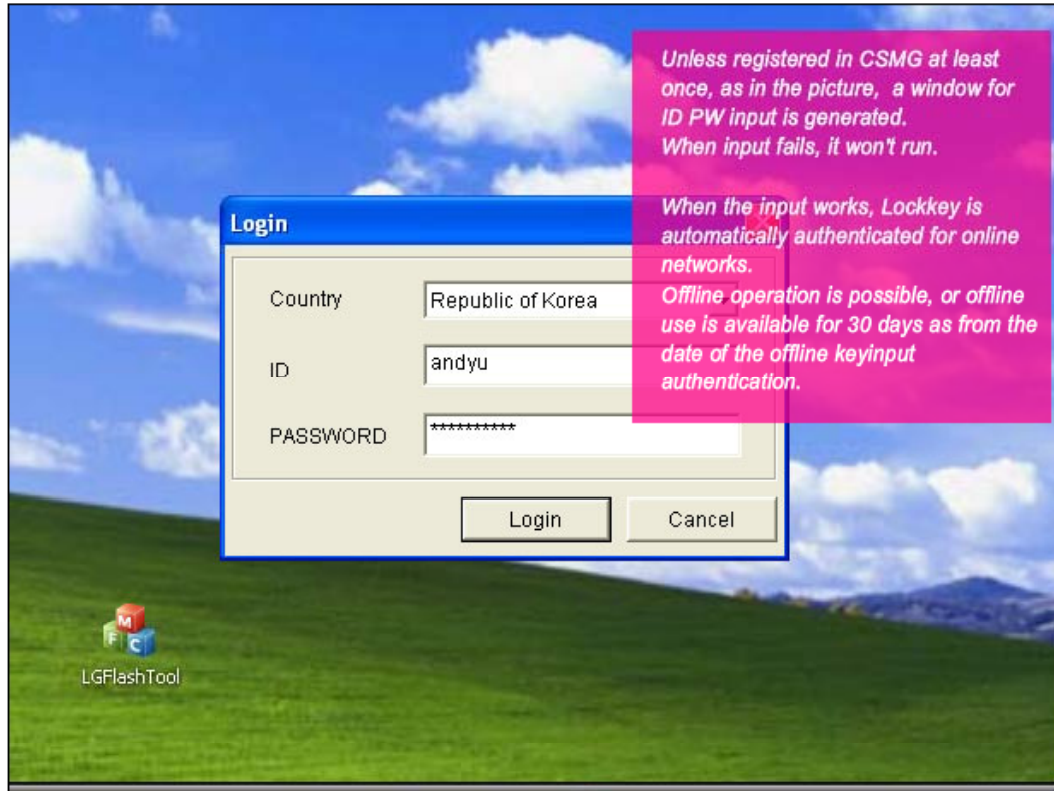




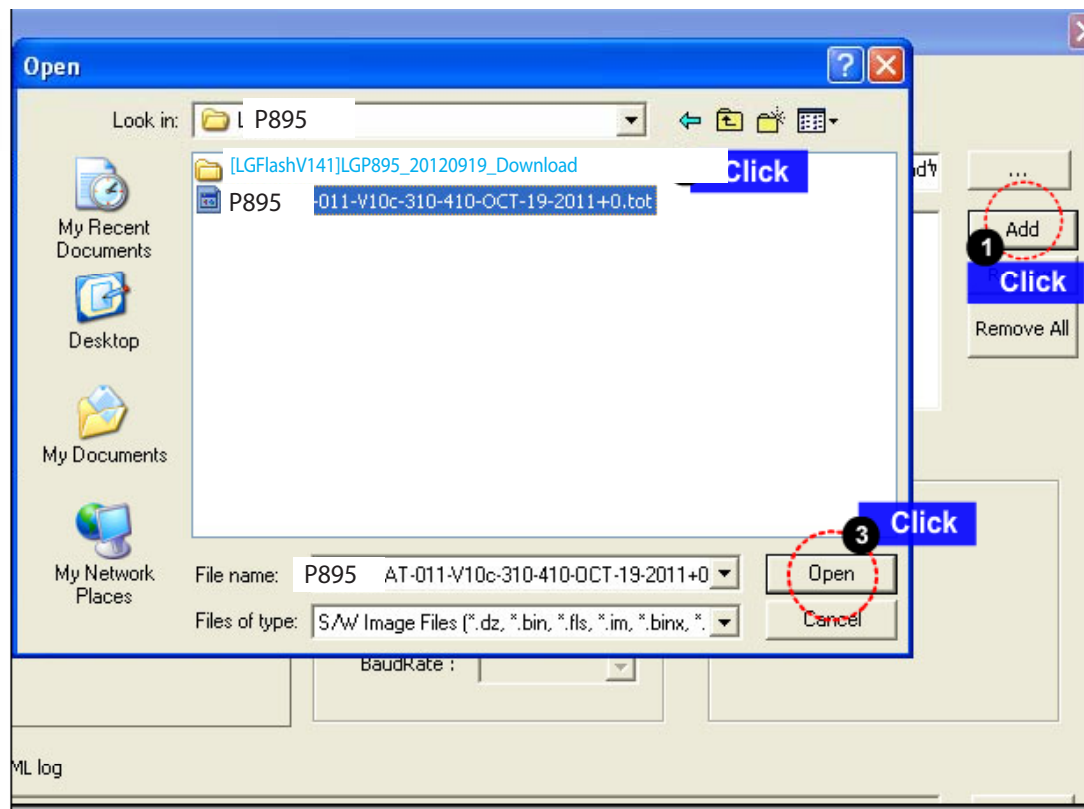
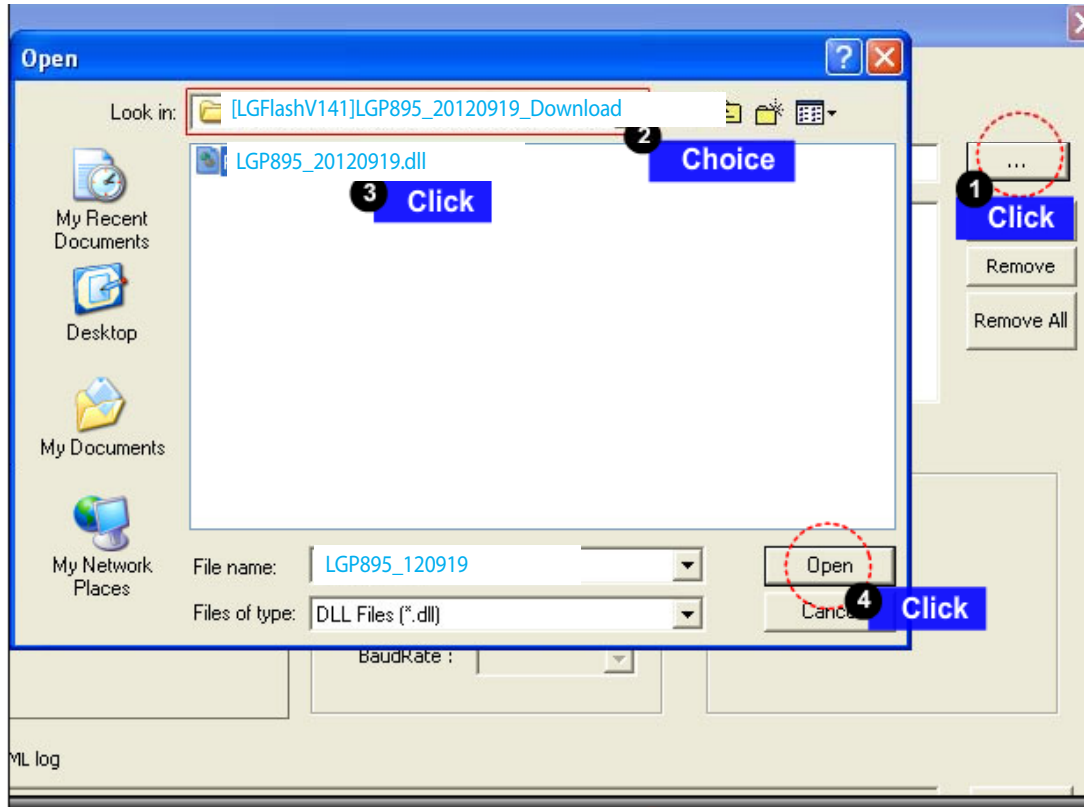
5. DOWNLOAD



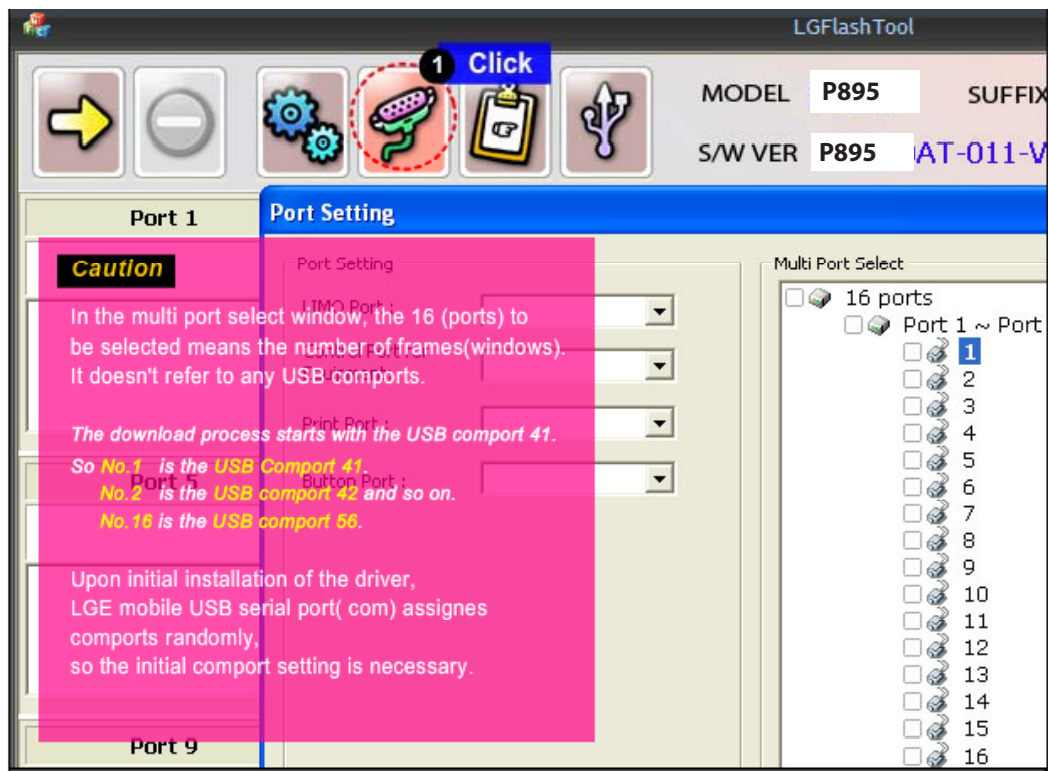
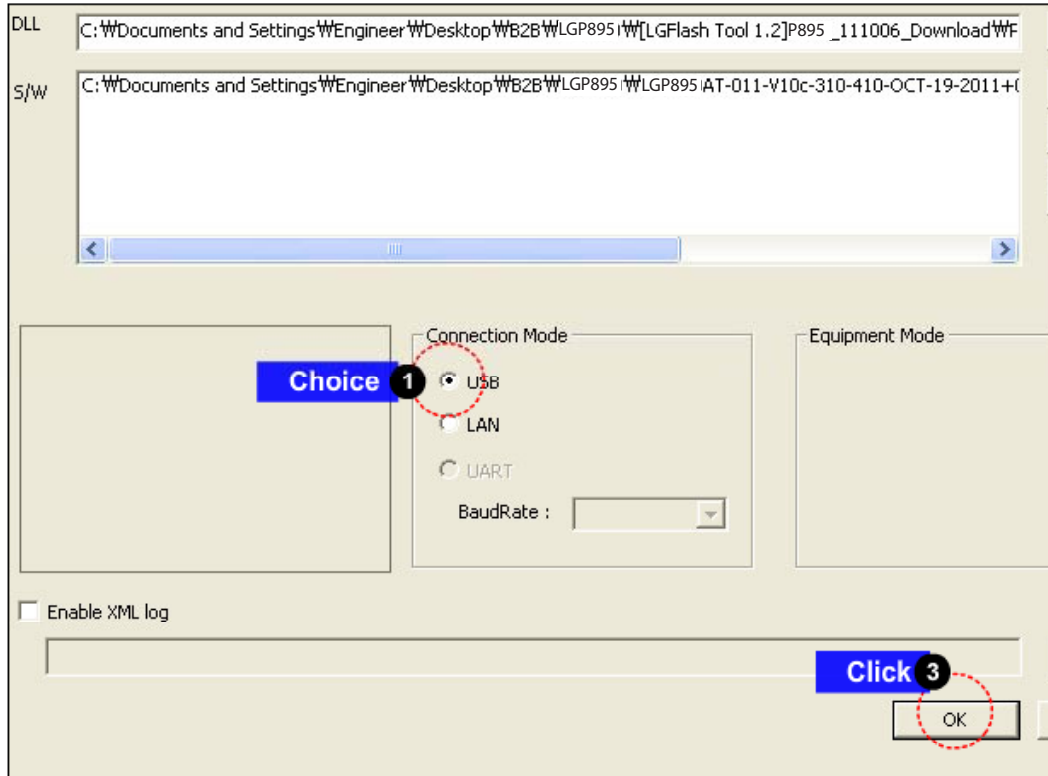
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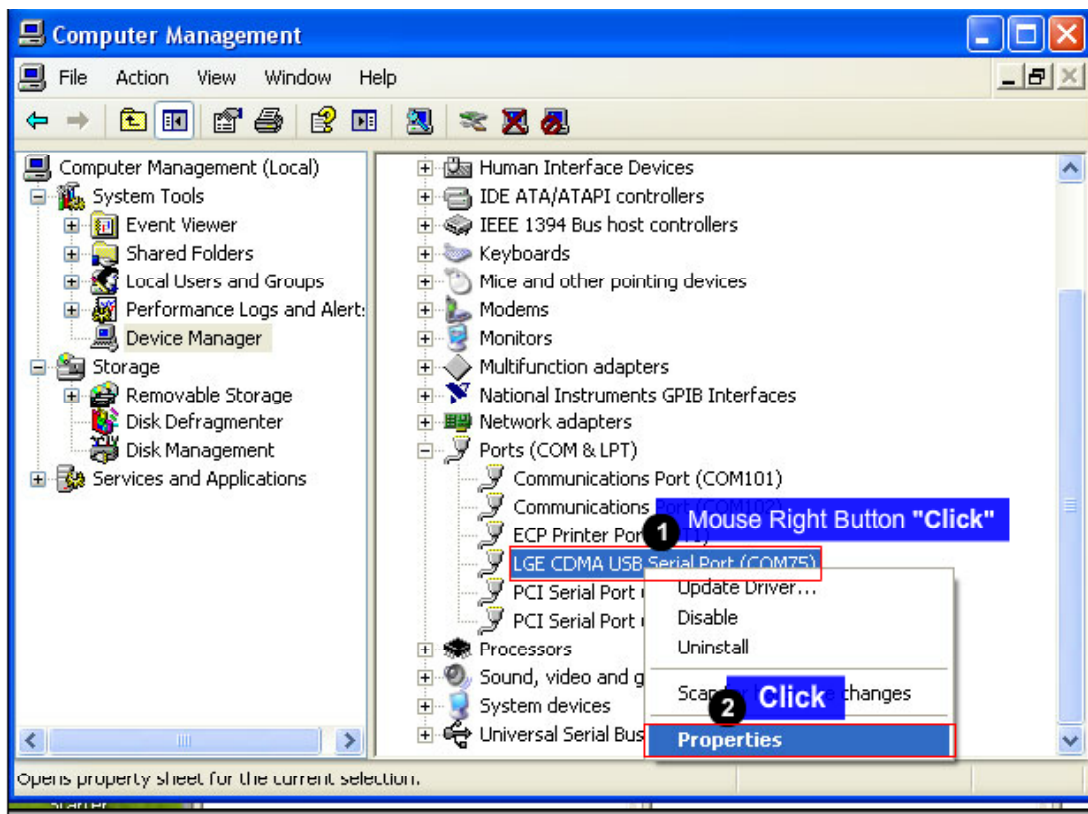
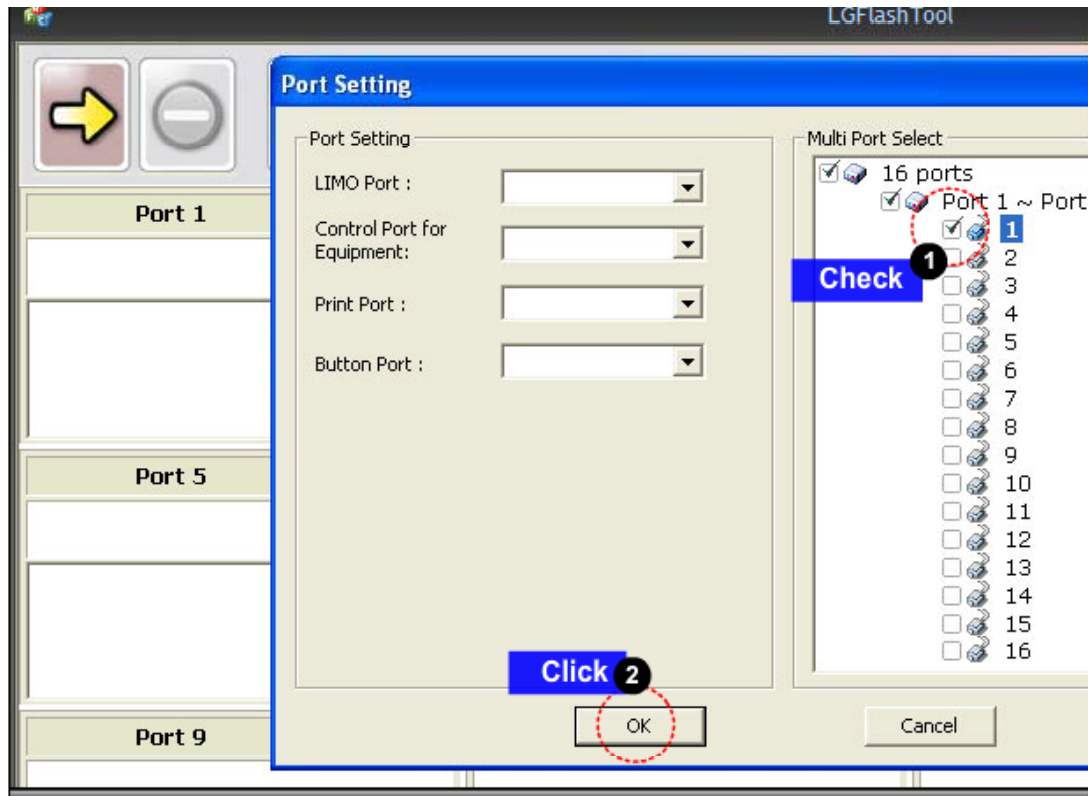
5. DOWNLOAD

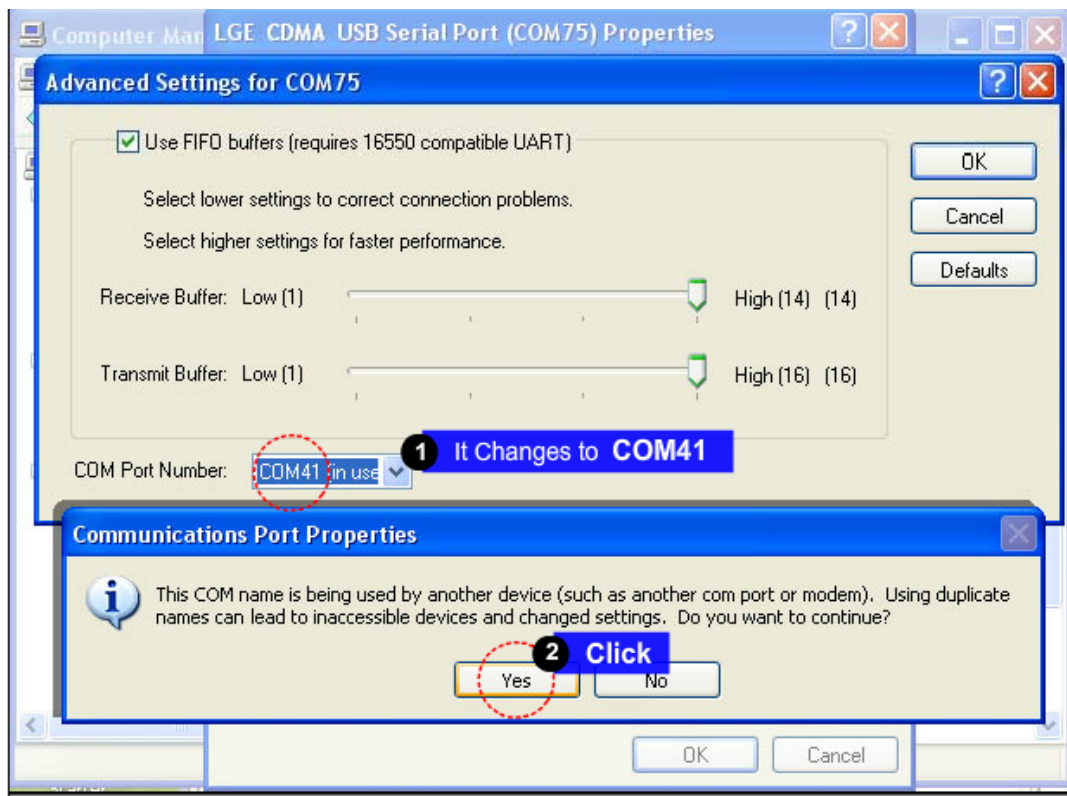
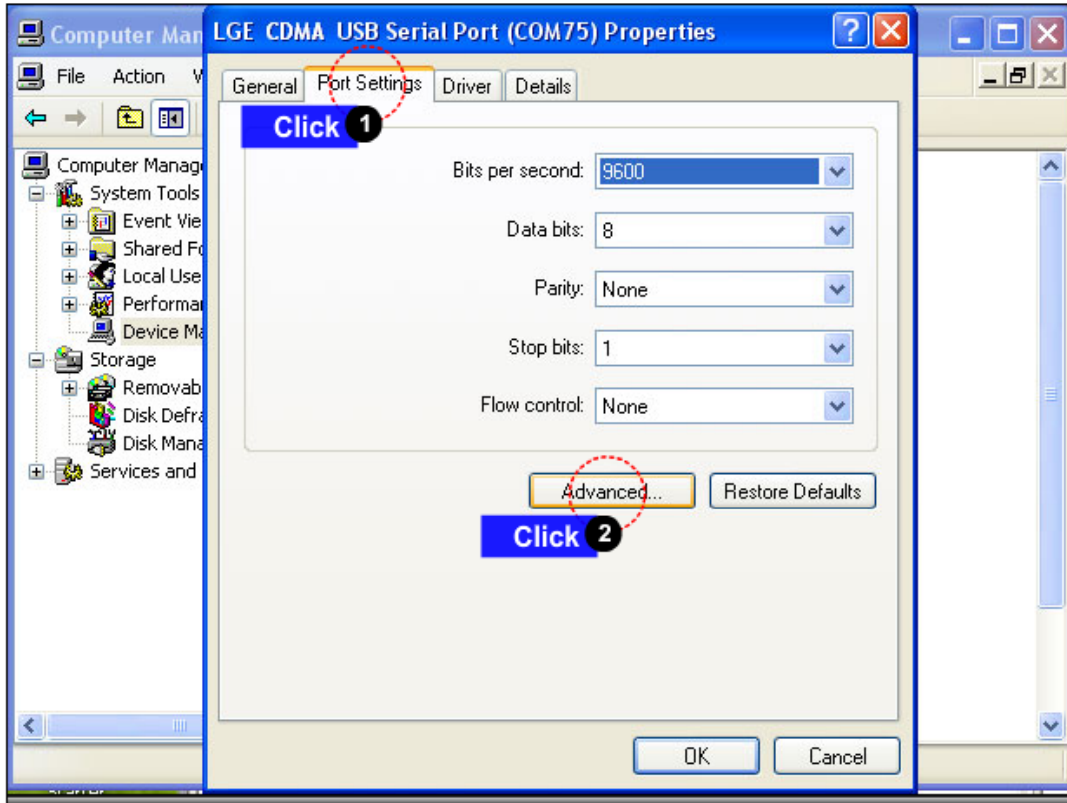


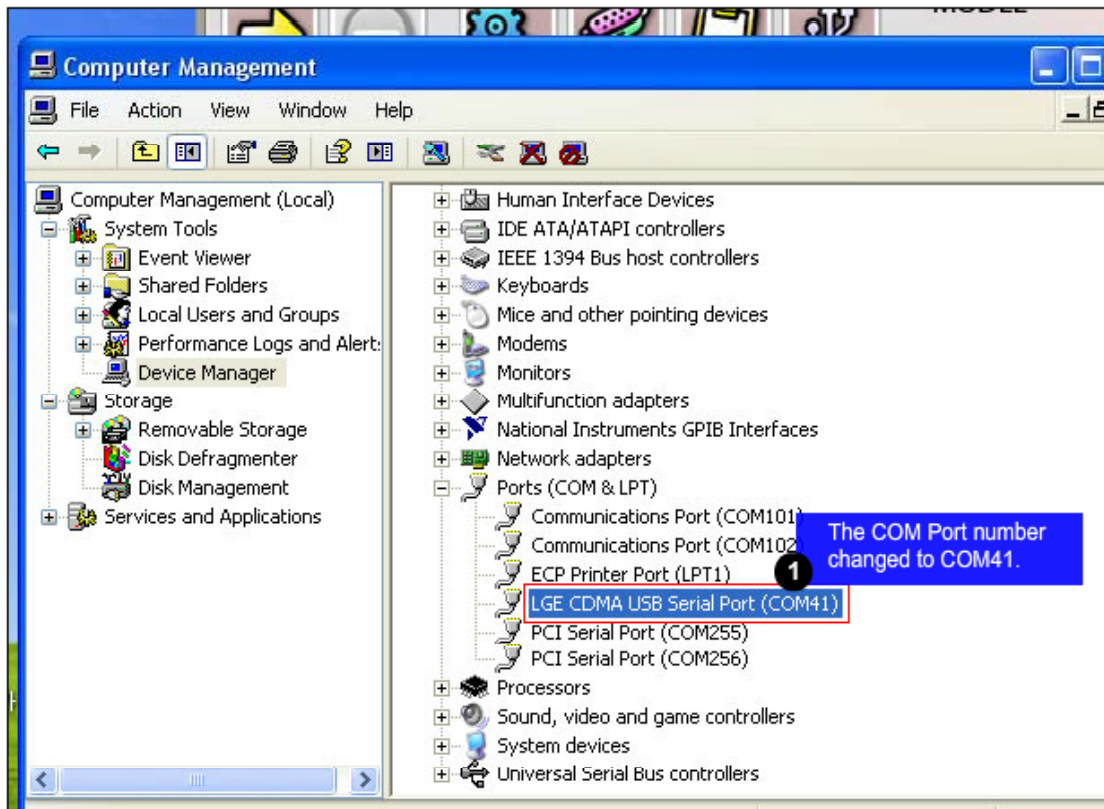
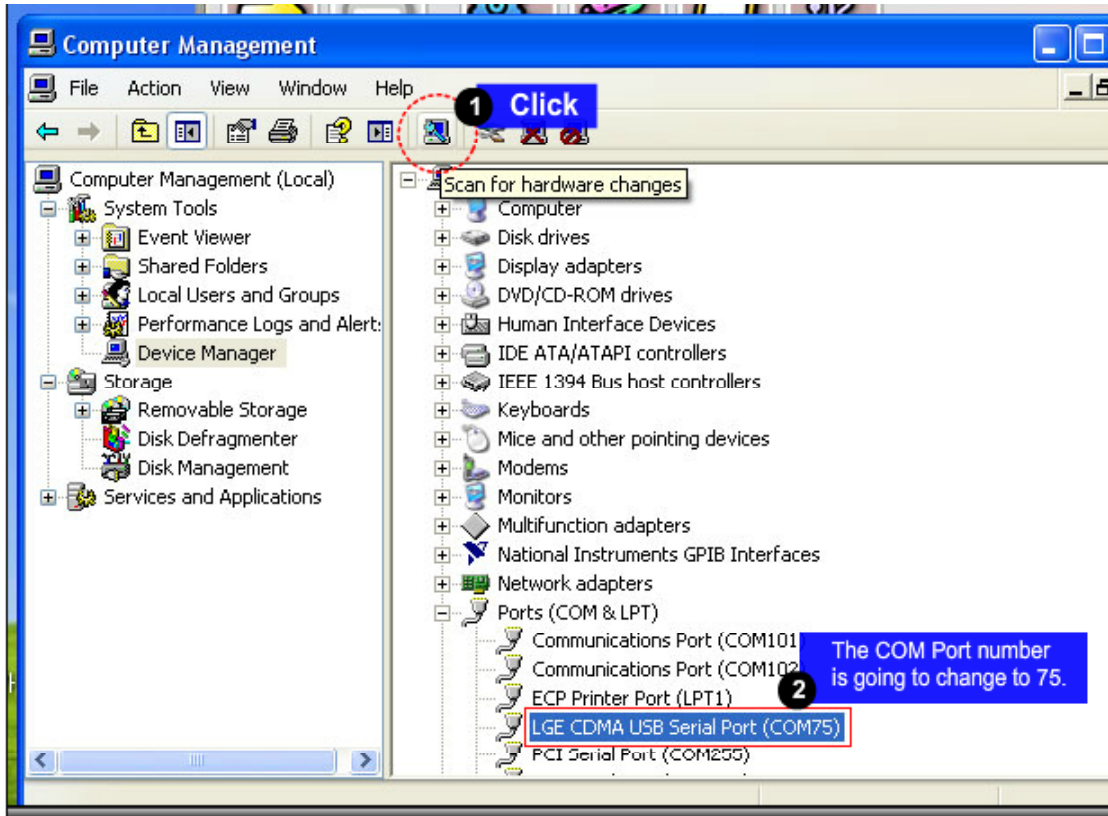
5. DOWNLOAD



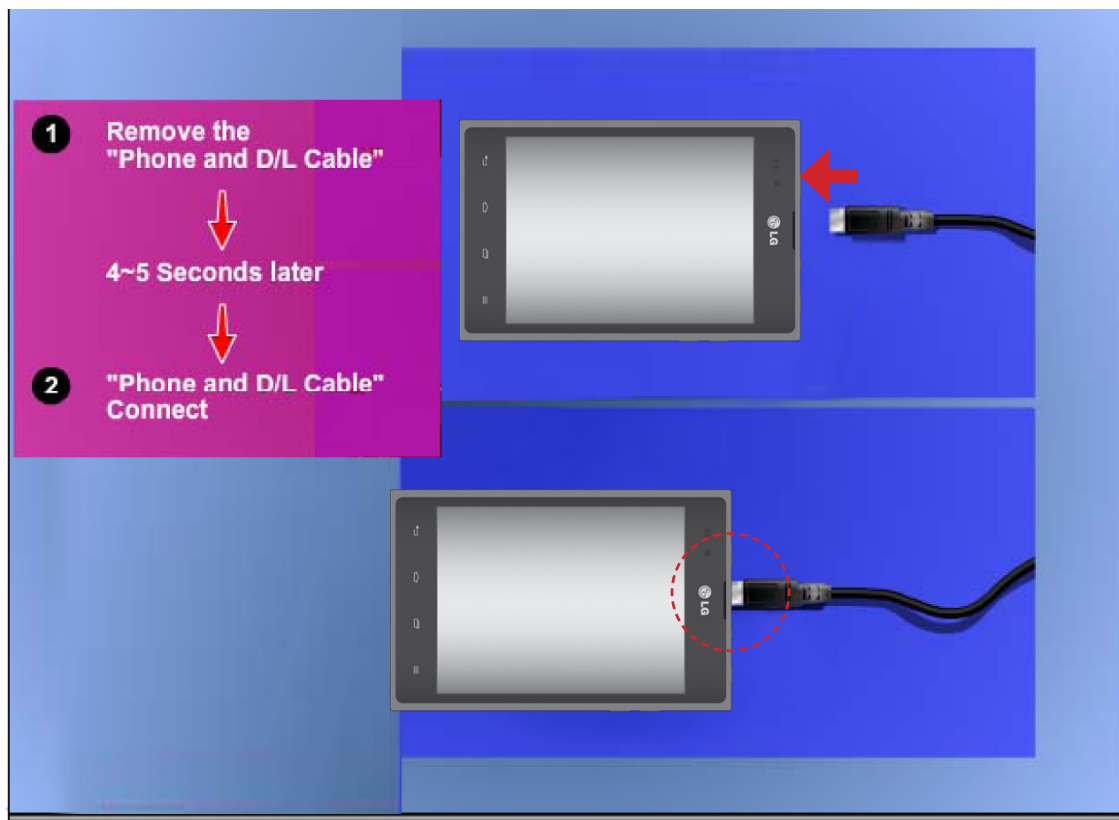
5. DOWNLOAD



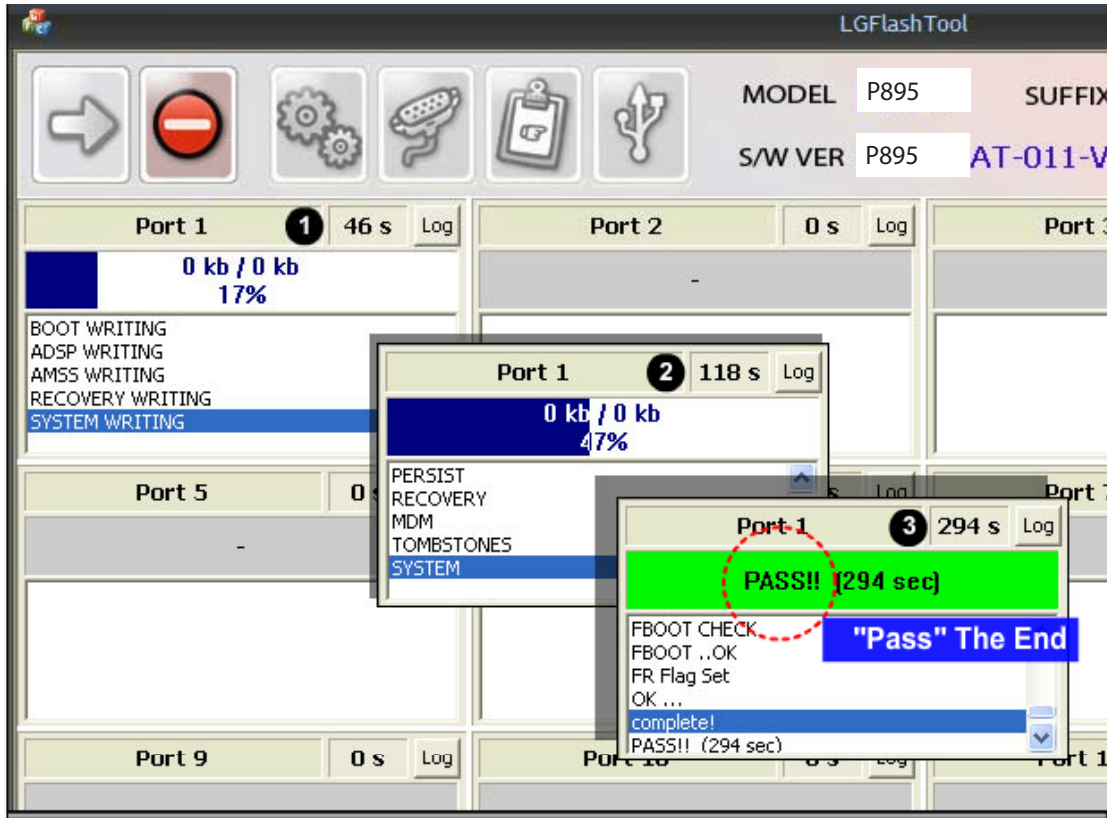




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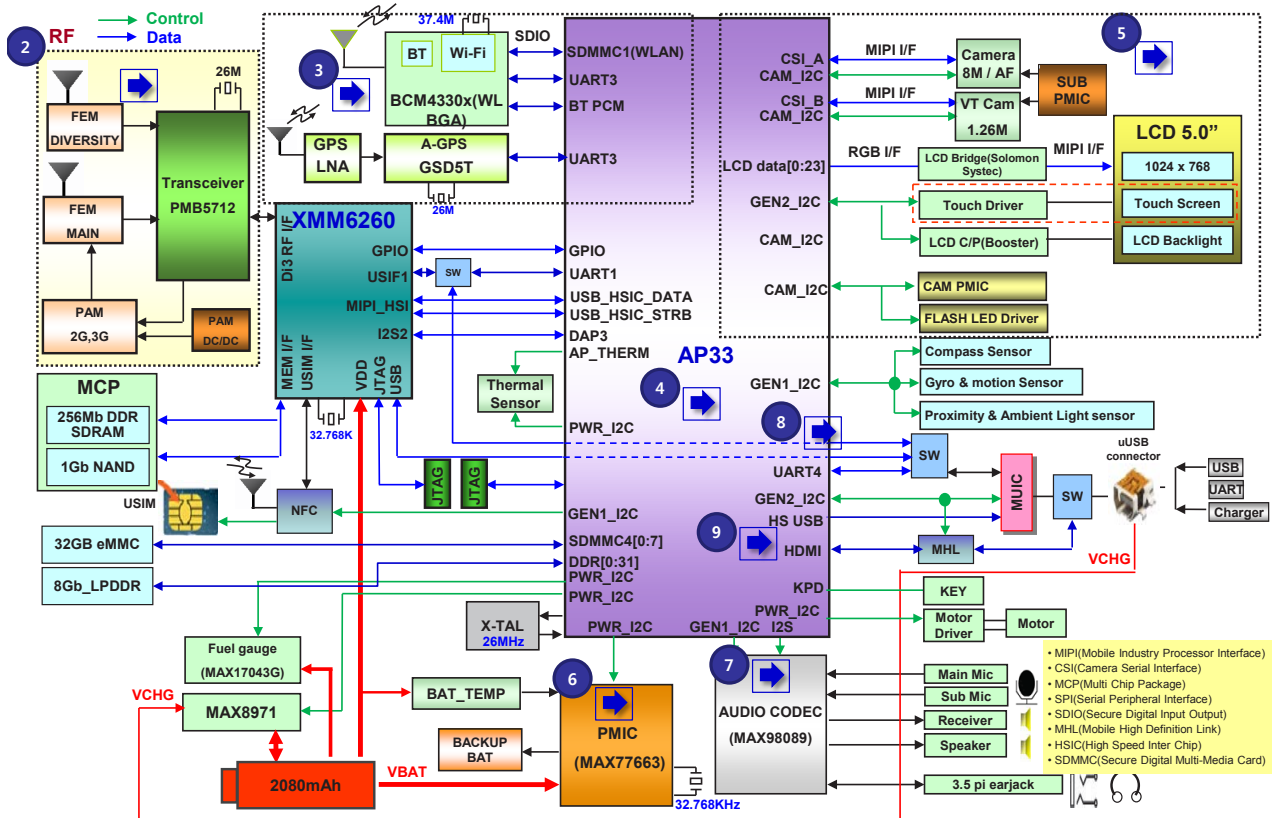


5. DOWNLOAD



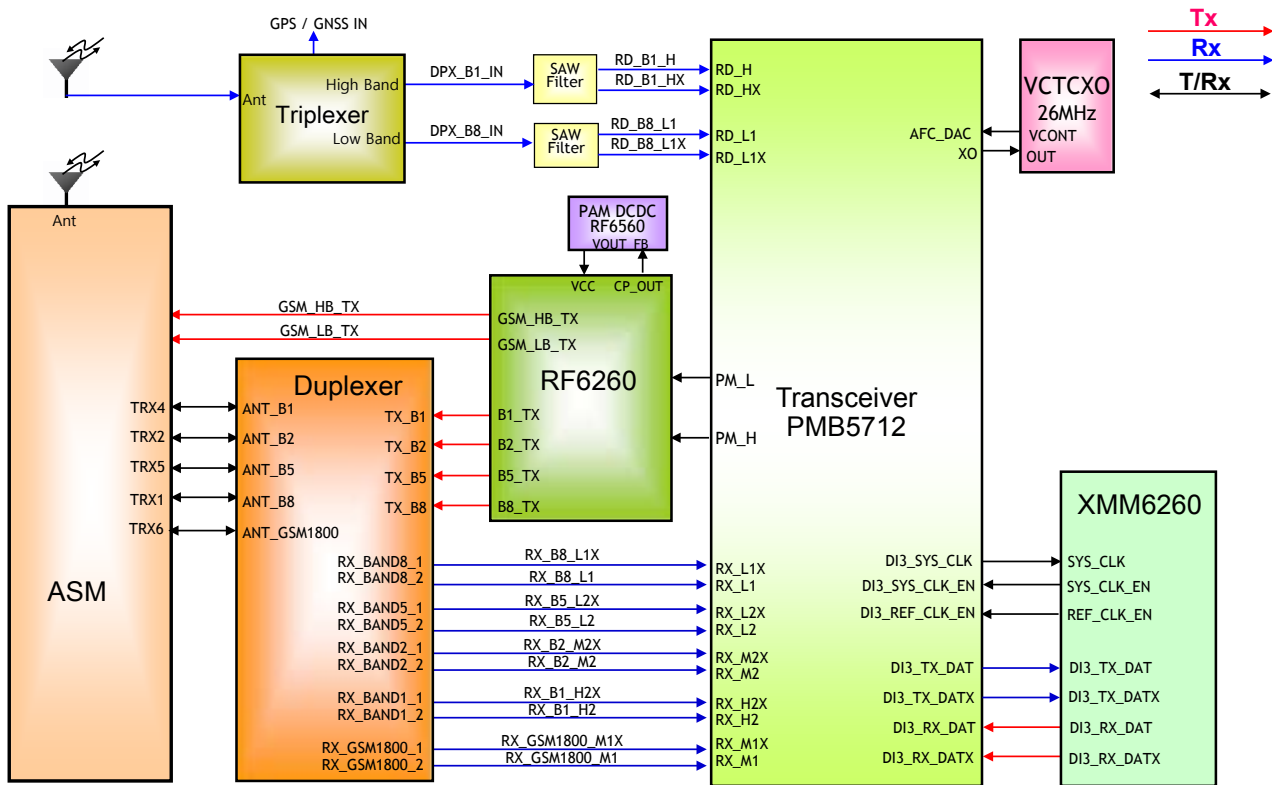
6.BLOCK DIAGRAM

(P895) Total Block Diagram(GLOBAL)



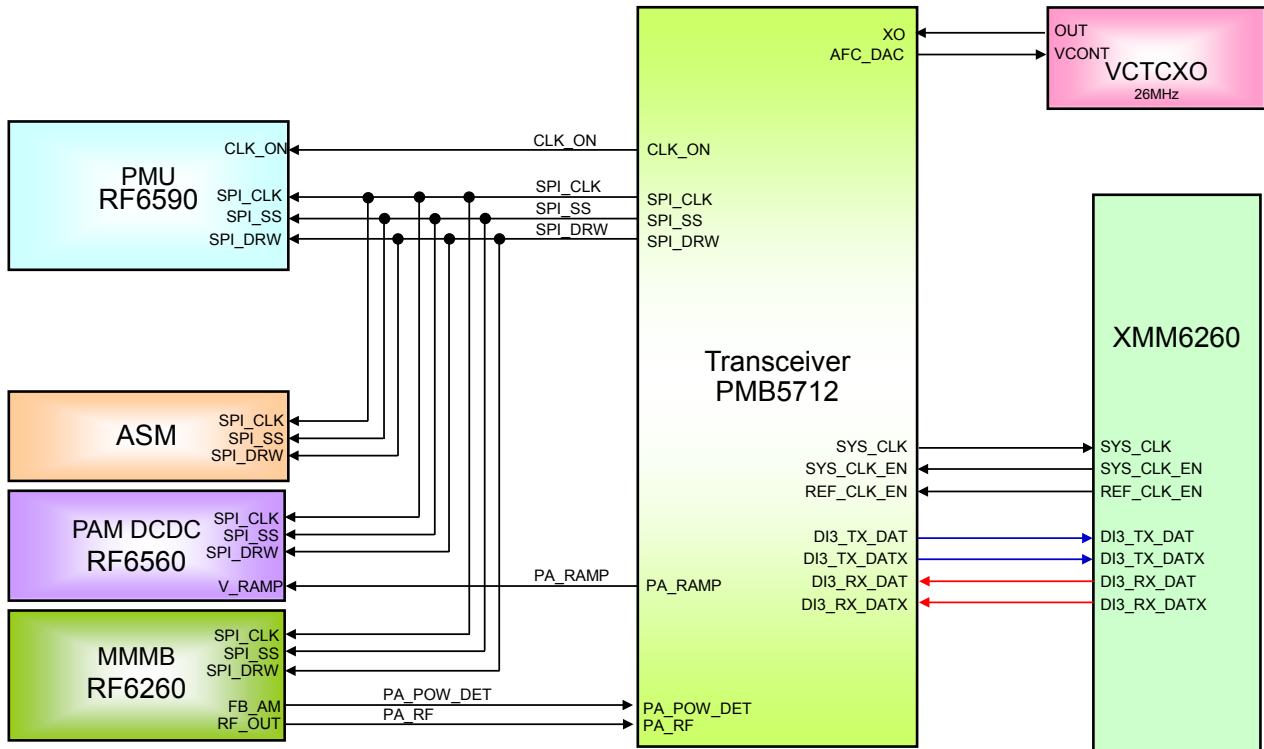
6. BLOCK DIAGRAM

(P895)RF Block Diagram



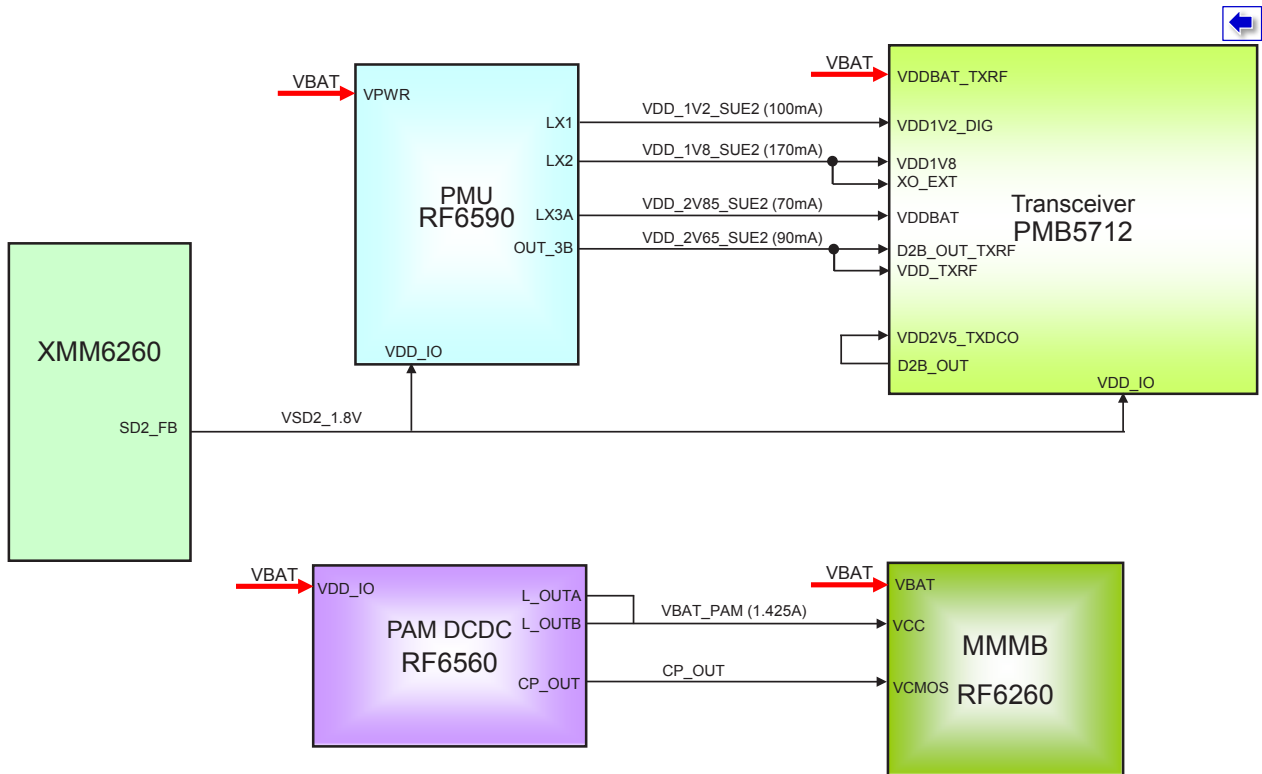
6. BLOCK DIAGRAM

(P895)RF Block Diagram : Control signal and clocks



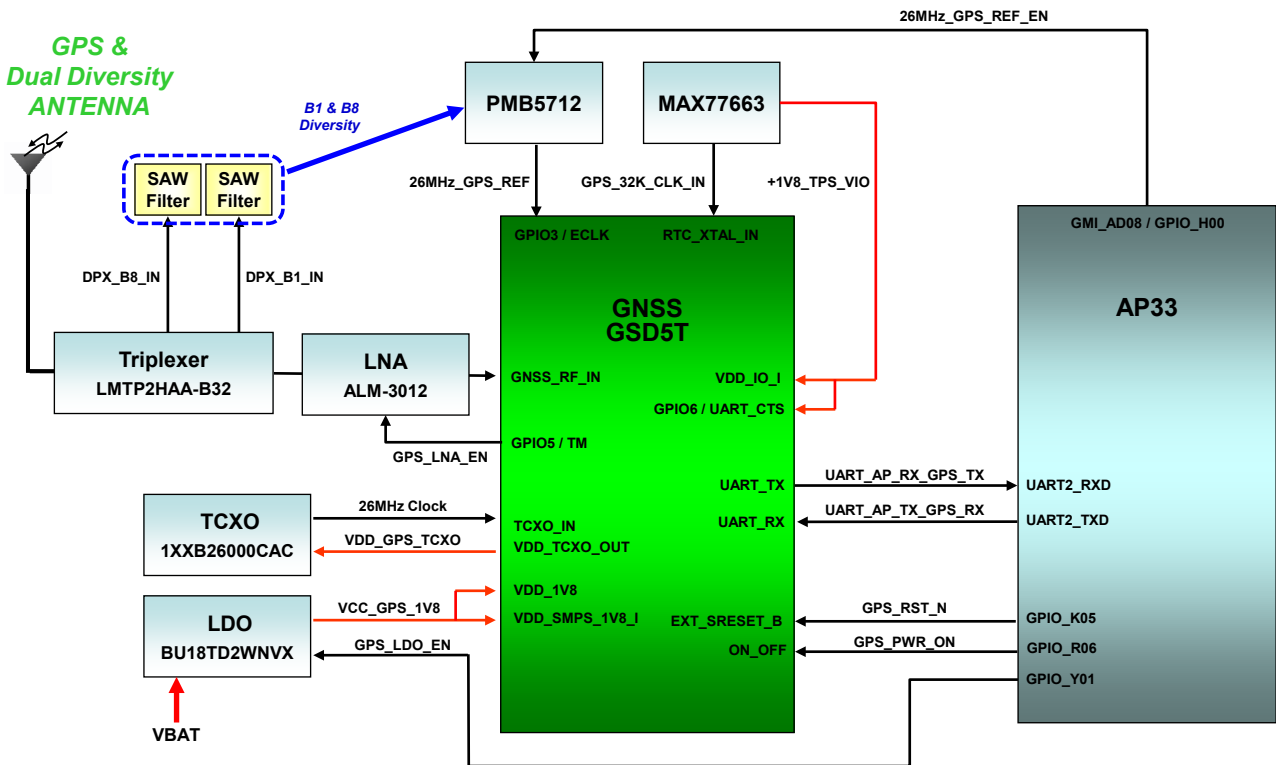
6. BLOCK DIAGRAM

(P895)RF Block Diagram ; Power



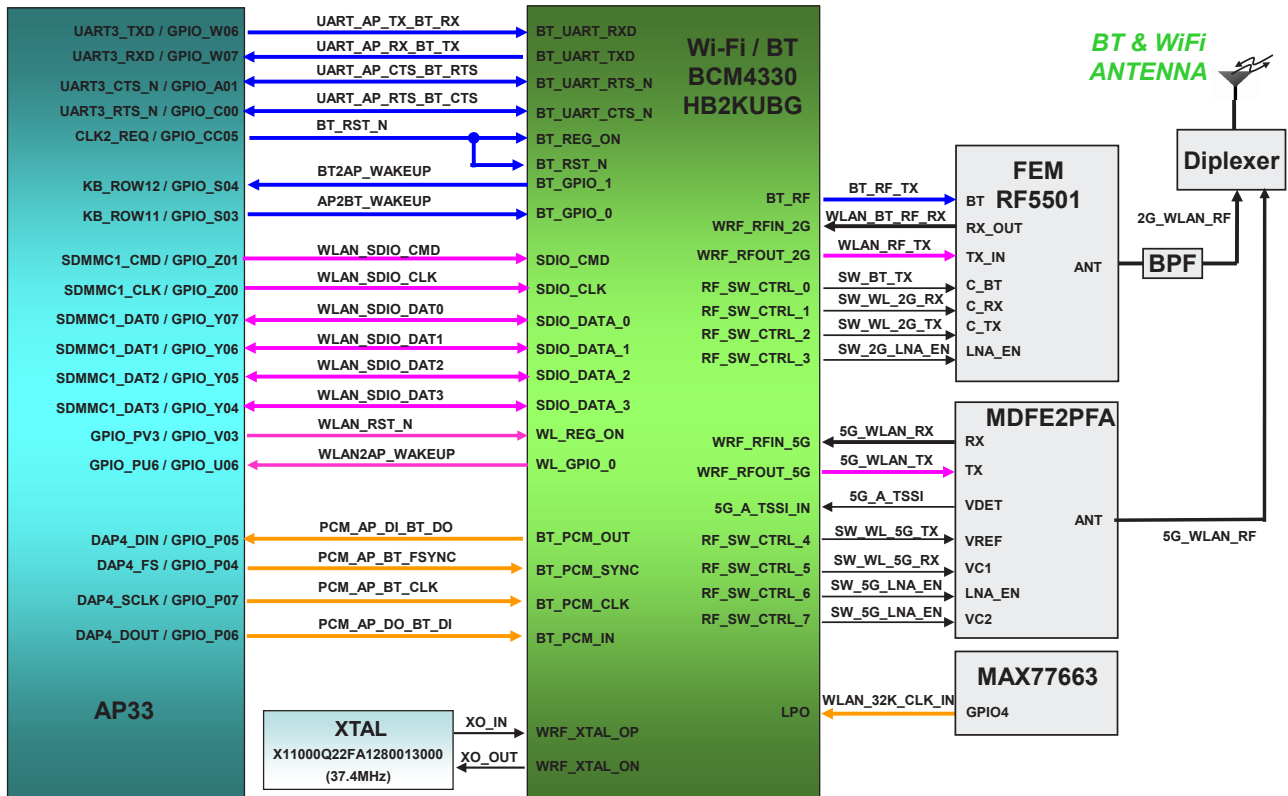
6. BLOCK DIAGRAM

(P895)Connectivity; GPS



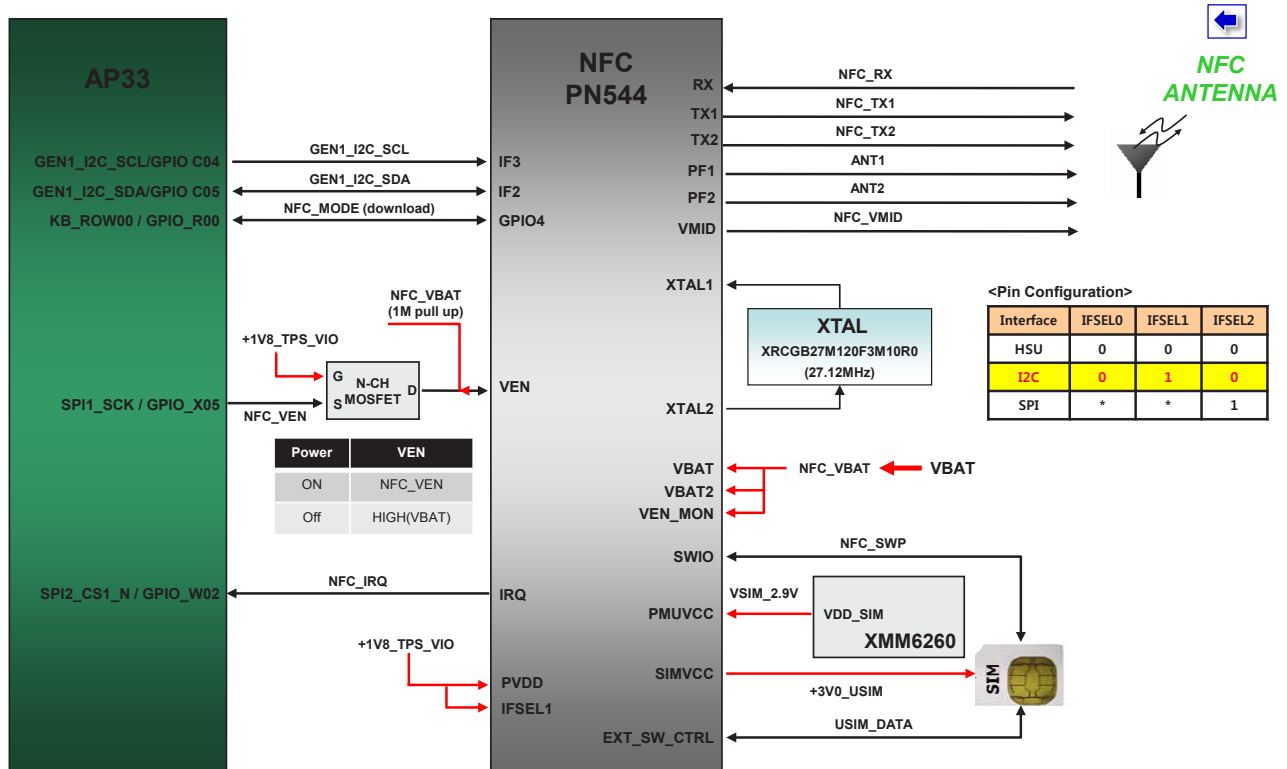
6. BLOCK DIAGRAM

(P895)Connectivity ; BLUETOOTH & Wi-Fi



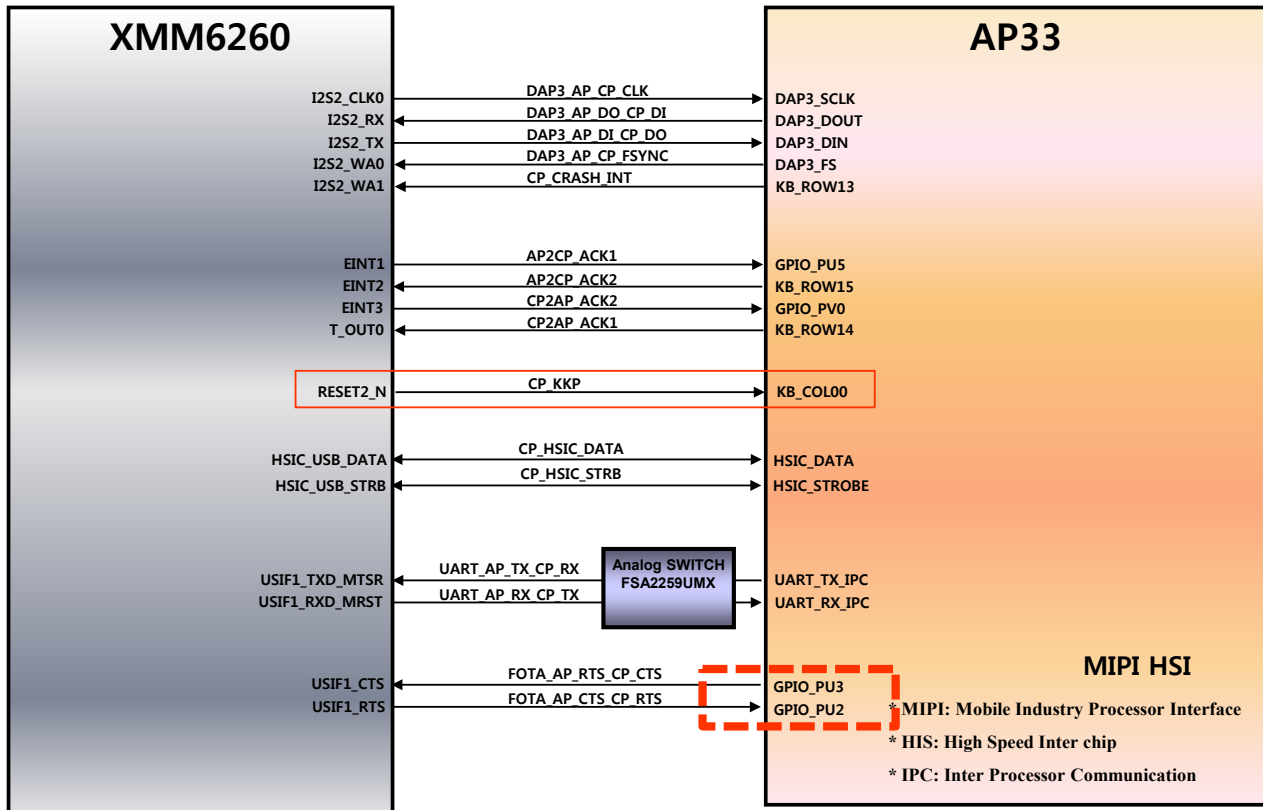
6. BLOCK DIAGRAM

(P895)Connectivity ; NFC



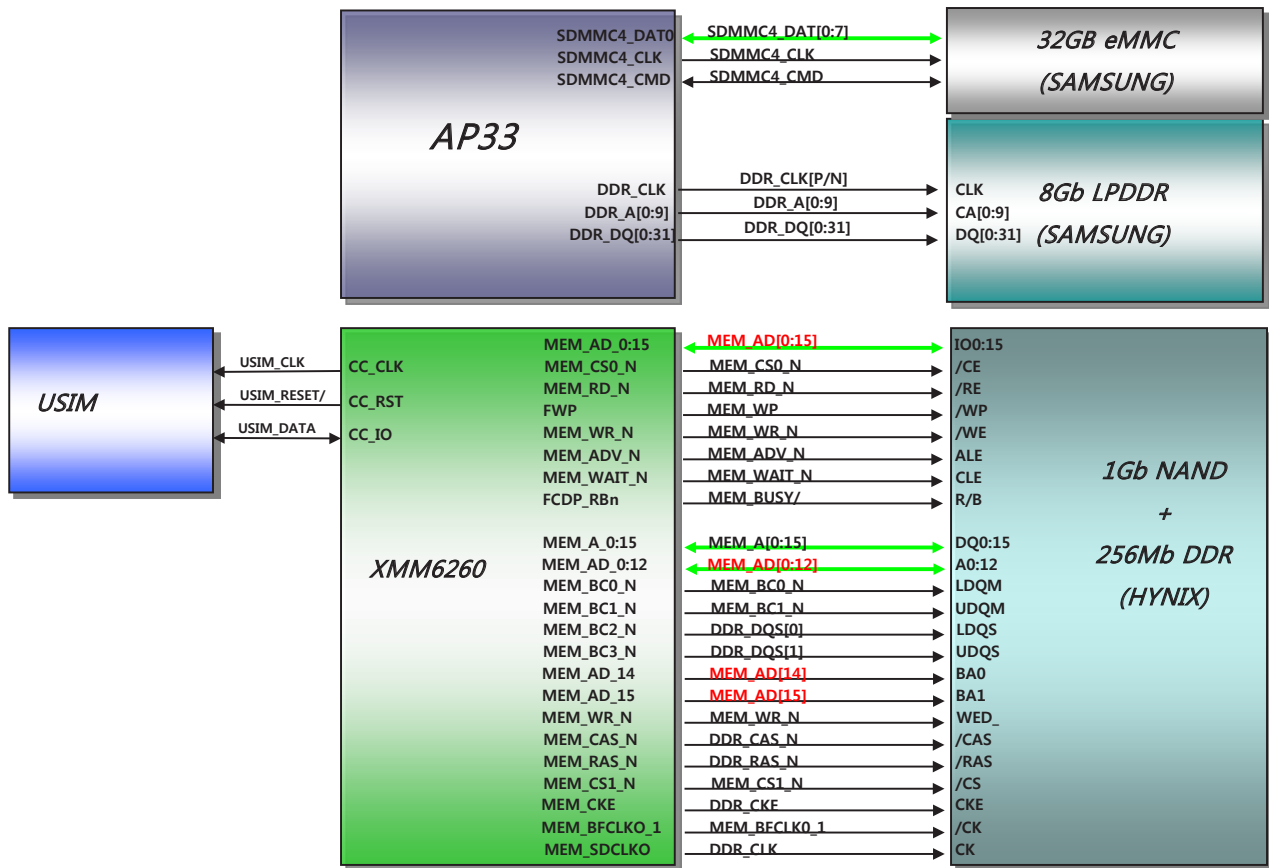
6. BLOCK DIAGRAM

(P895)XMM6260 – AP33 Interface / Control signal



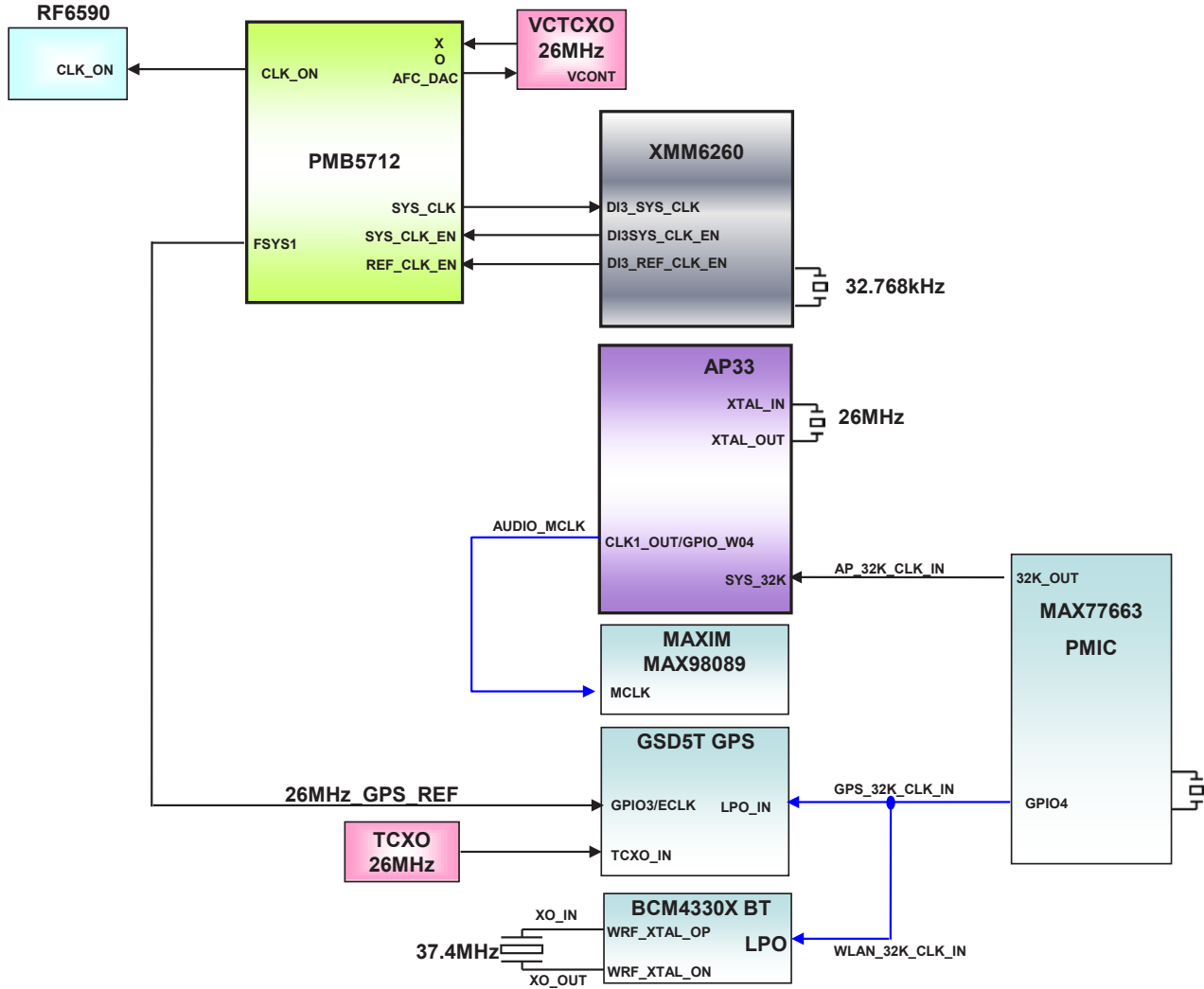
6. BLOCK DIAGRAM

(P895)Memory – XMM6260, USIM, MCP Block Diagram



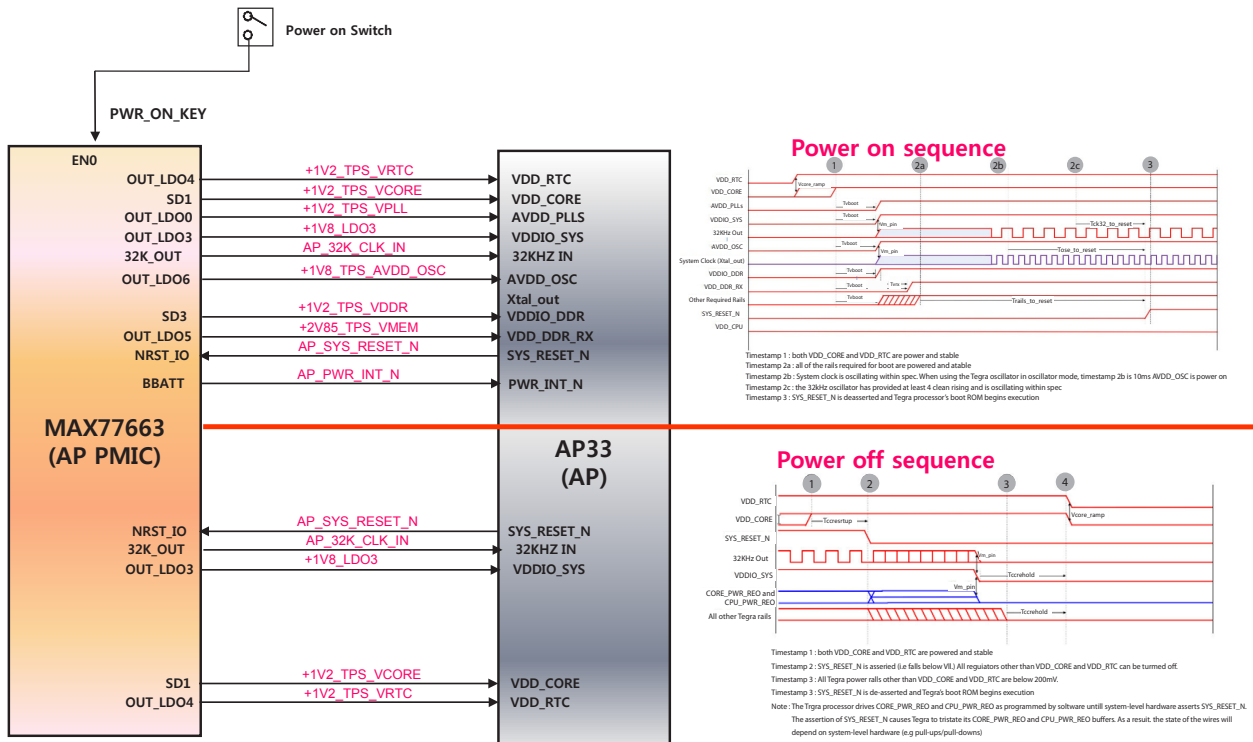
6. BLOCK DIAGRAM

(P895)System Clock

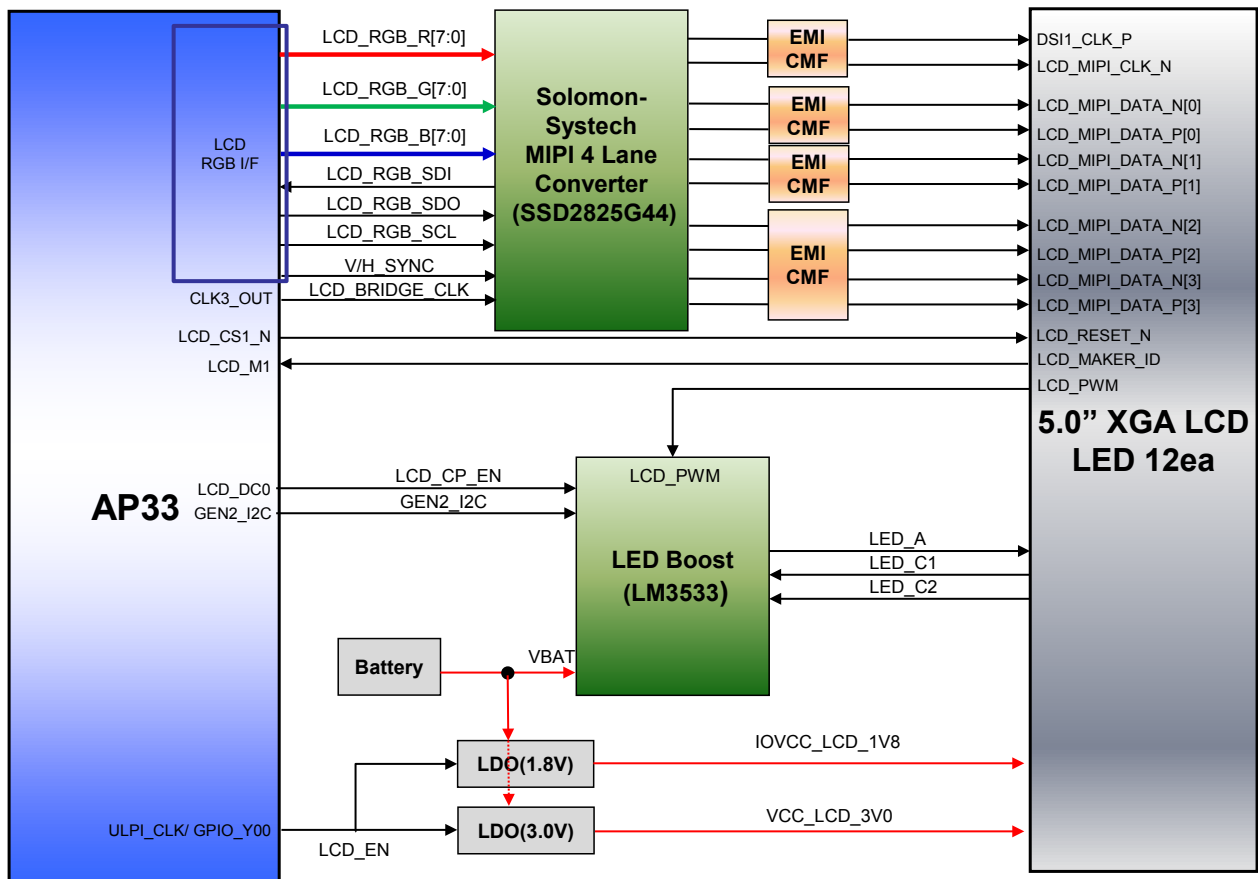


6. BLOCK DIAGRAM

(P895)System Power On/Off

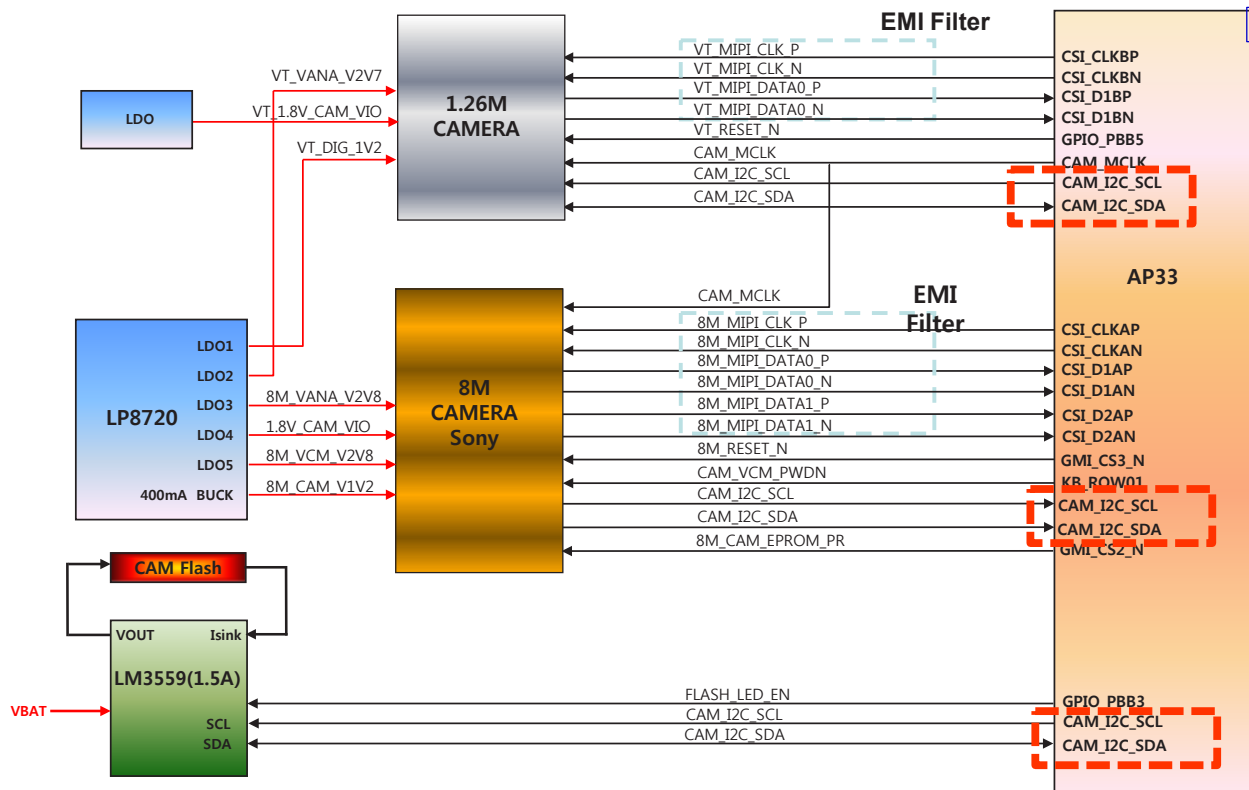


(P895)Display - LCD Block Diagram



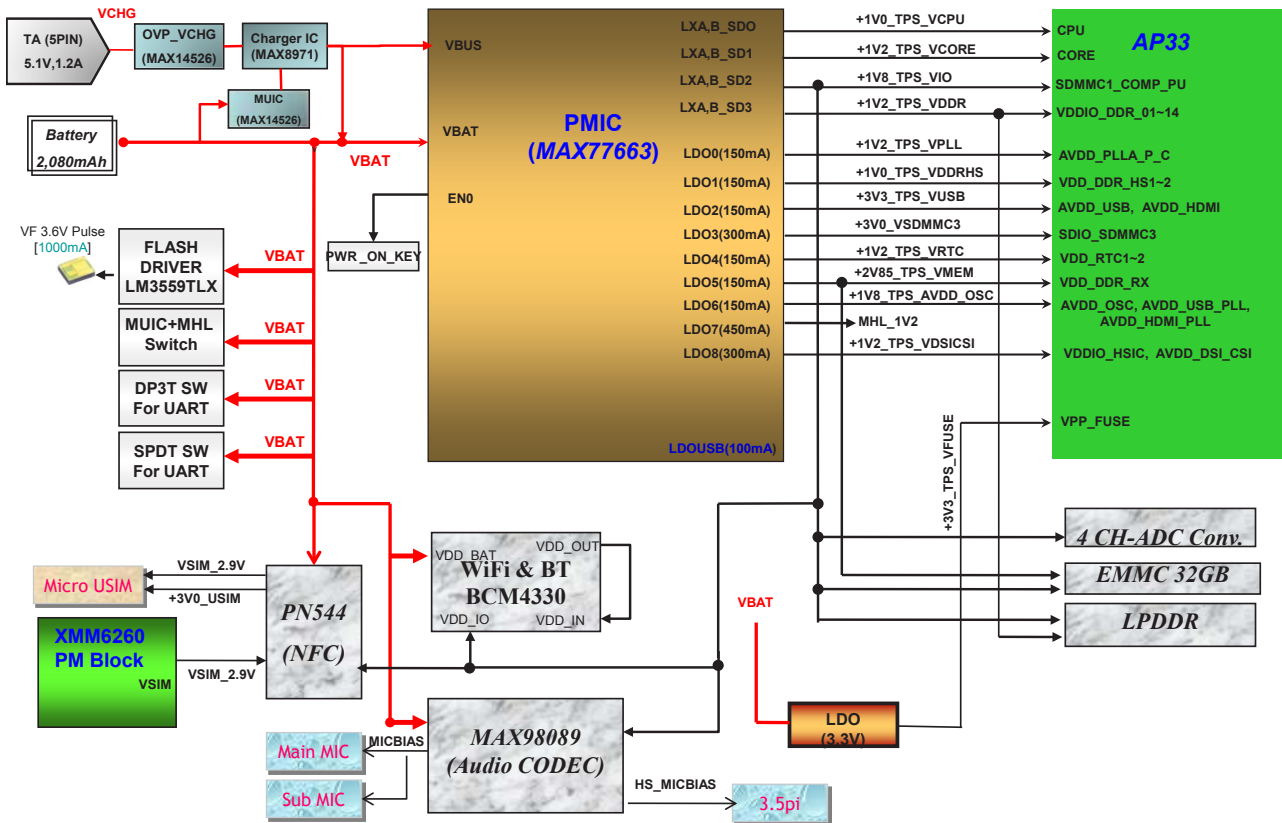
6. BLOCK DIAGRAM

(P895)Display - CAMERA Block Diagram



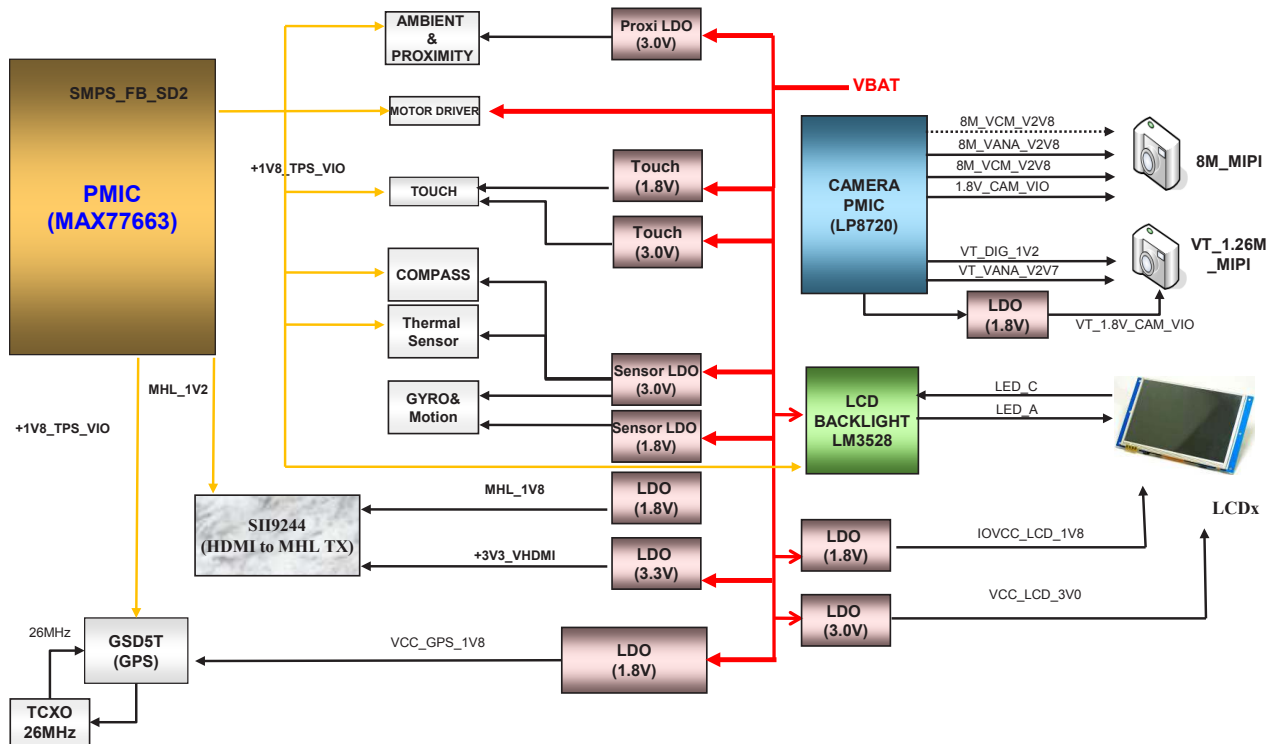
6. BLOCK DIAGRAM

(P895)Power Block Diagram (PMIC : MAXIM) - 1



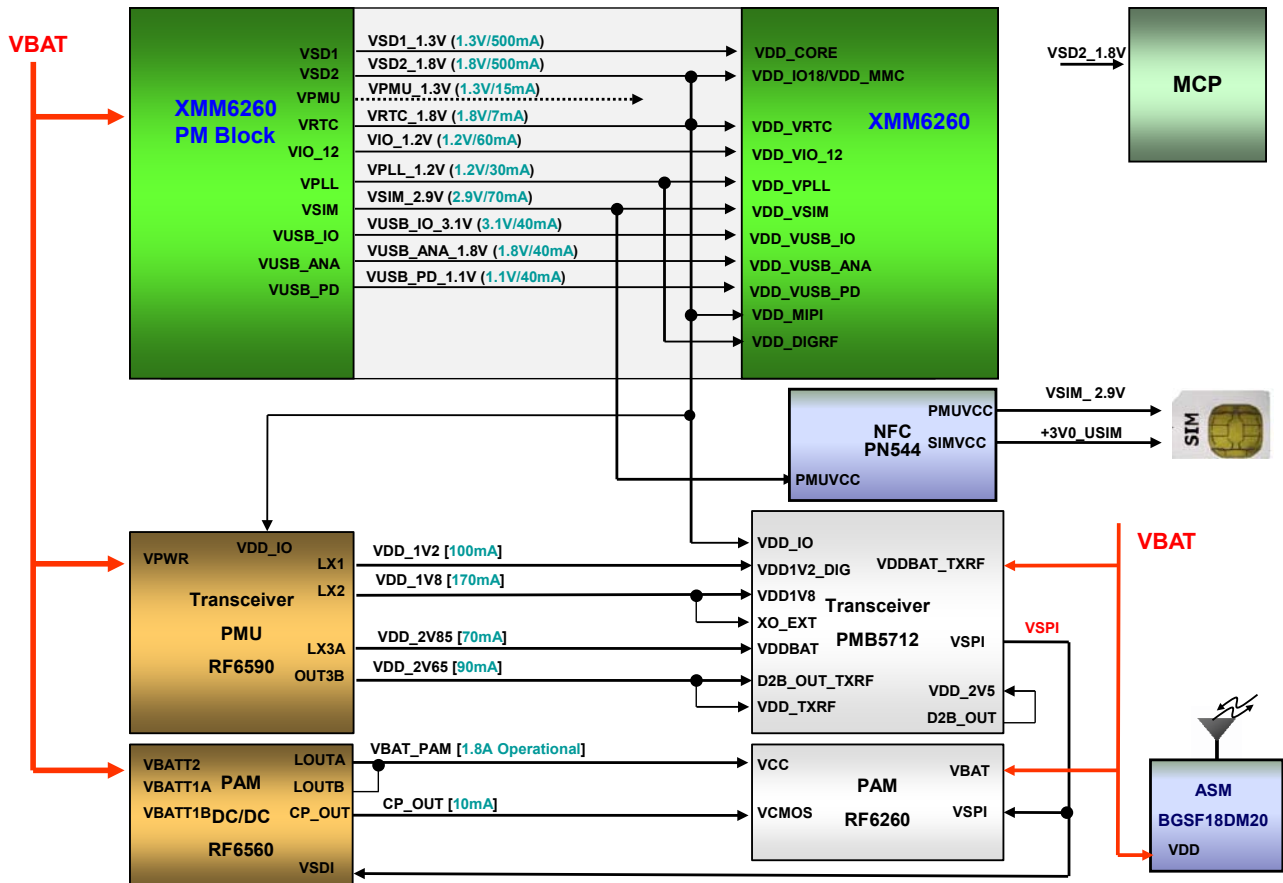
6. BLOCK DIAGRAM

(P895)Power Block Diagram (PMIC : MAXIM) - 2



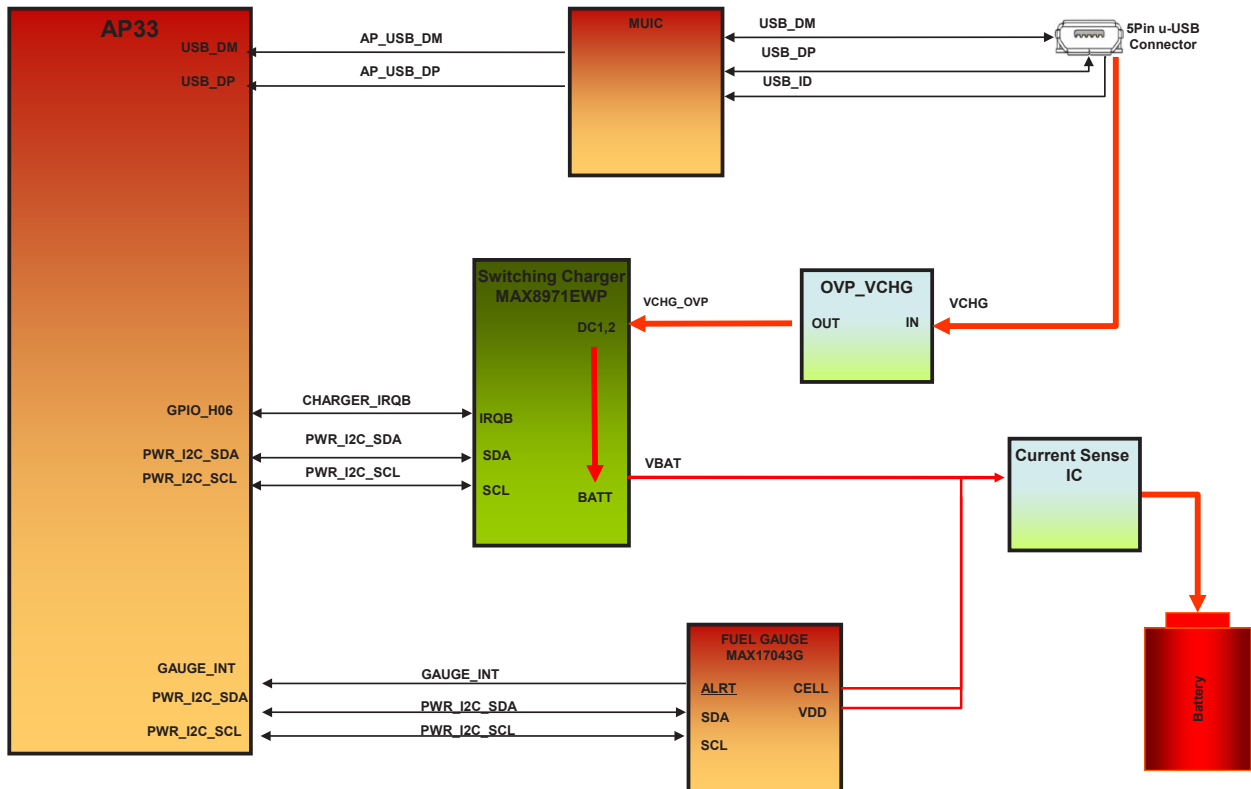
6. BLOCK DIAGRAM

(P895)Power Block Diagram (XMM6260 & RF)



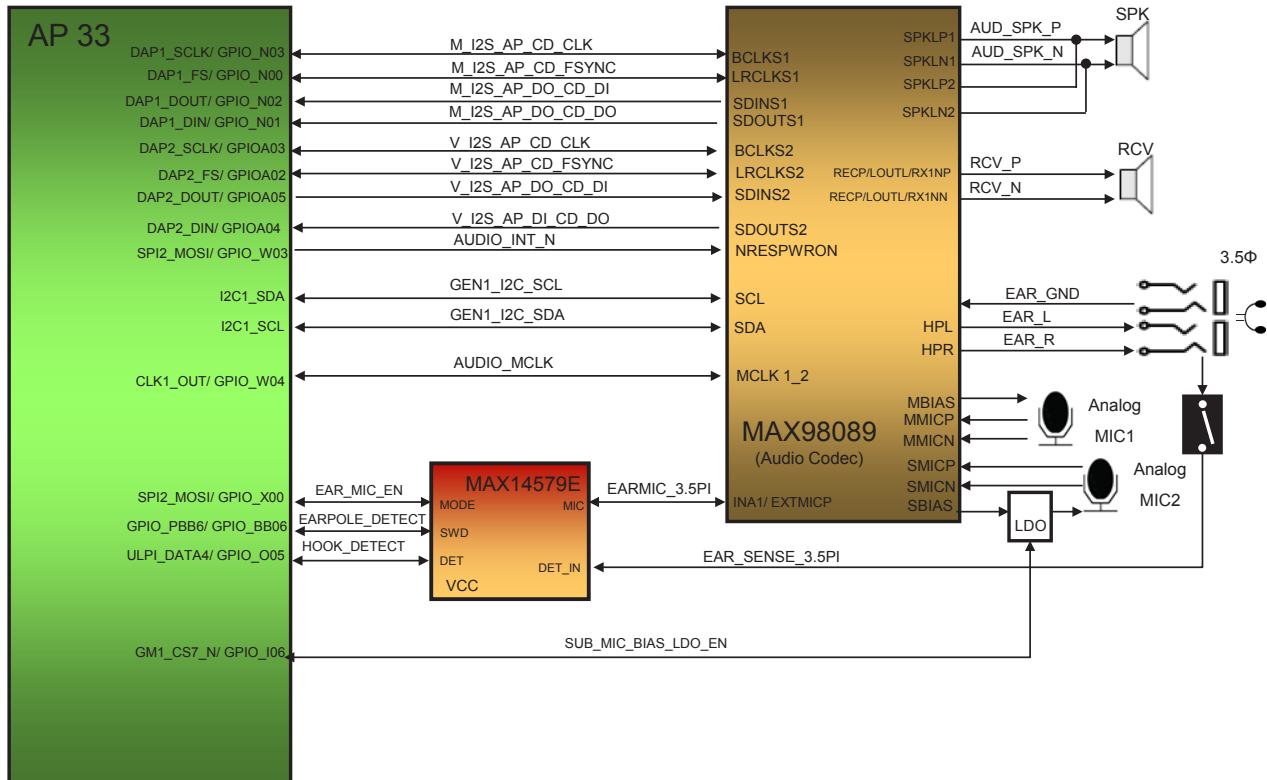
6. BLOCK DIAGRAM

(P895)Charging Block Diagram



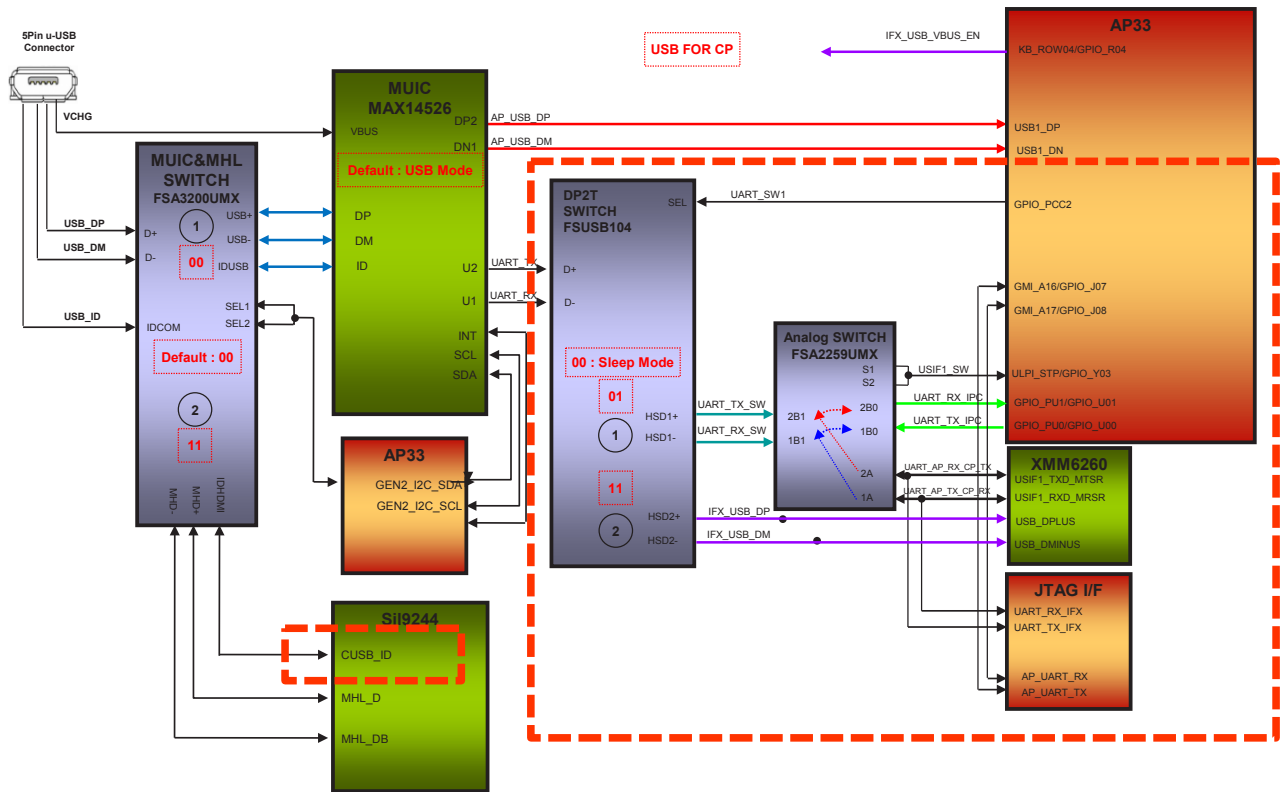
6. BLOCK DIAGRAM

(P895)AUDIO Block Diagram



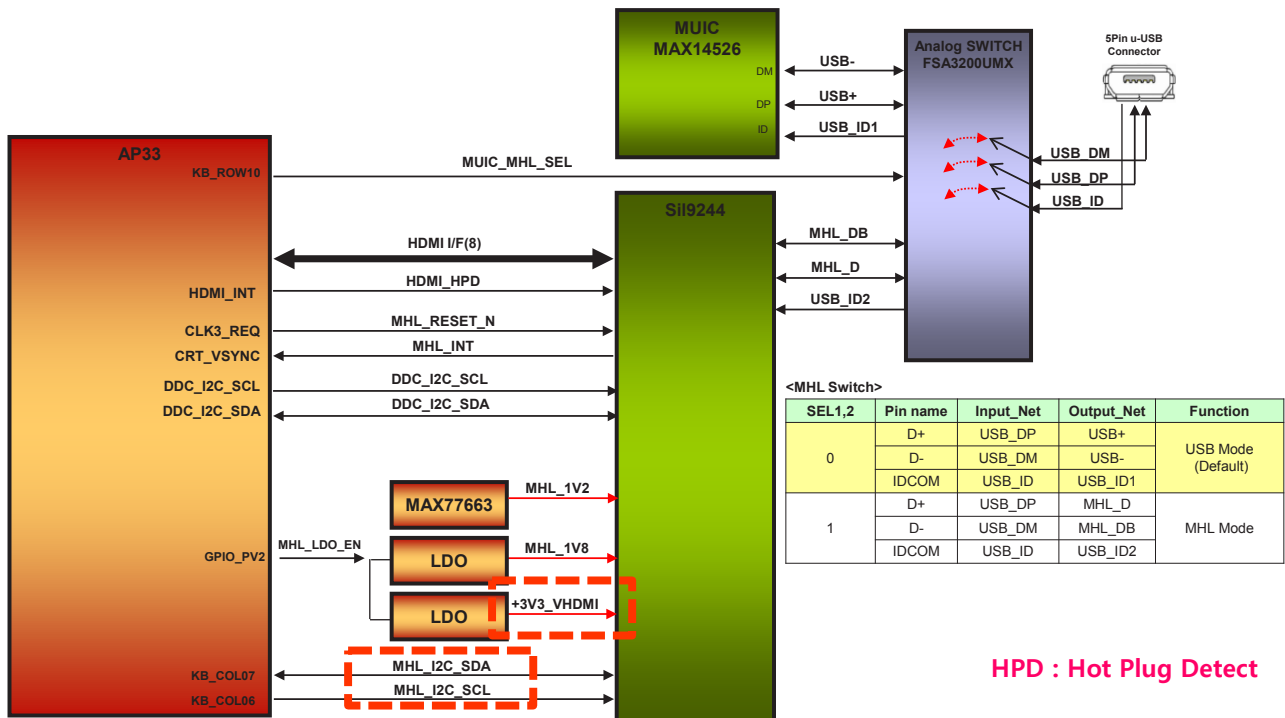
6. BLOCK DIAGRAM

(P895)USB, UART Block Diagram



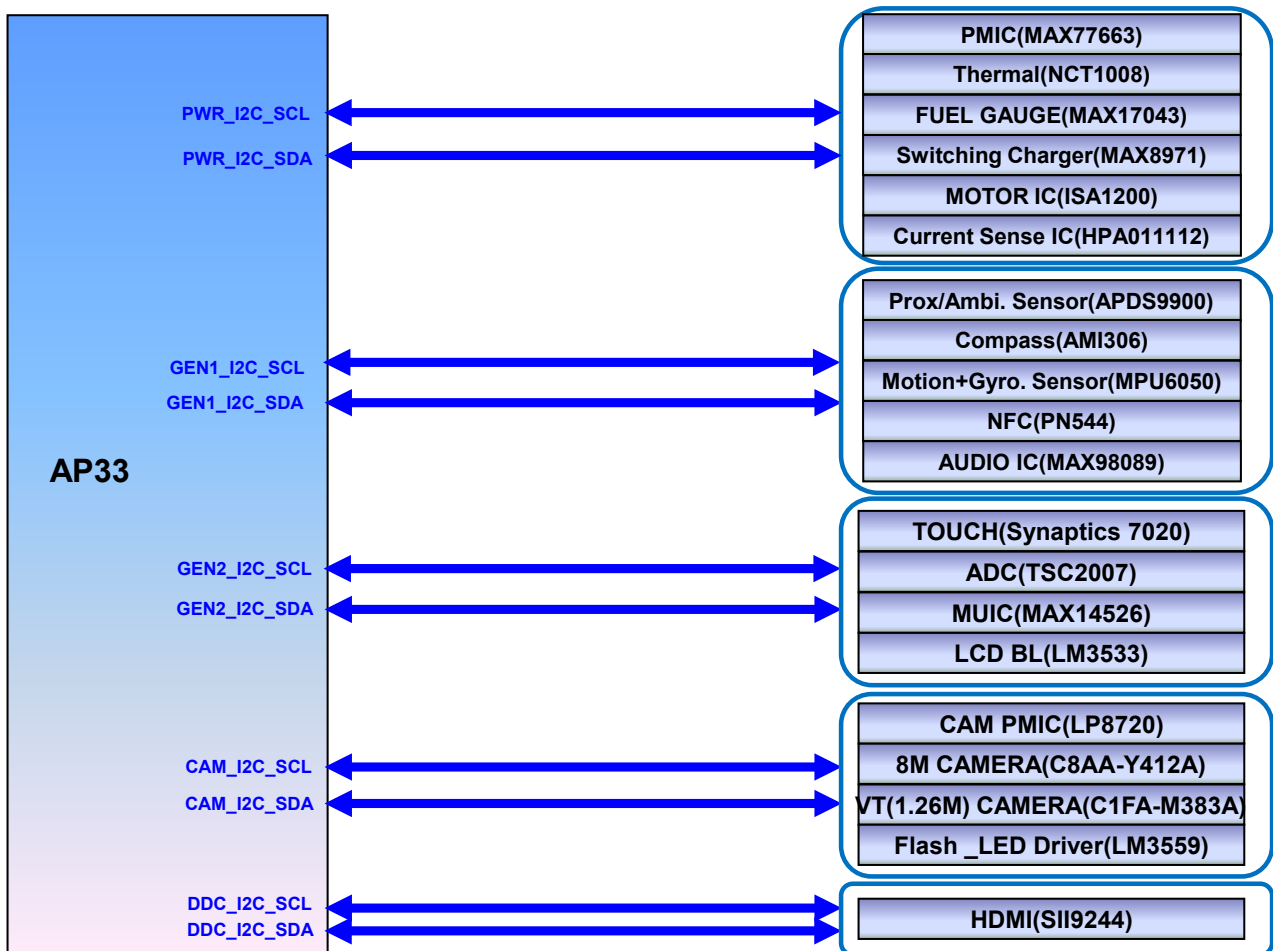
6. BLOCK DIAGRAM

(P895)MHL & HDMI



6. BLOCK DIAGRAM

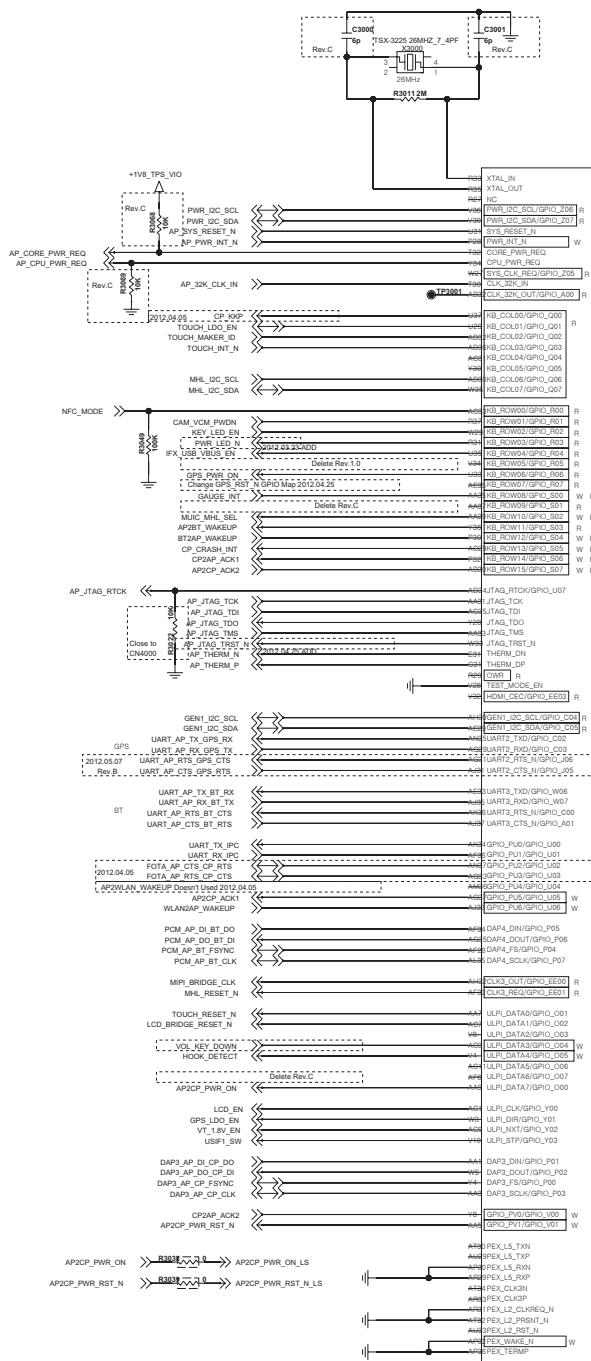
(P895)I2C Interface



BASE BAND PROCESSOR

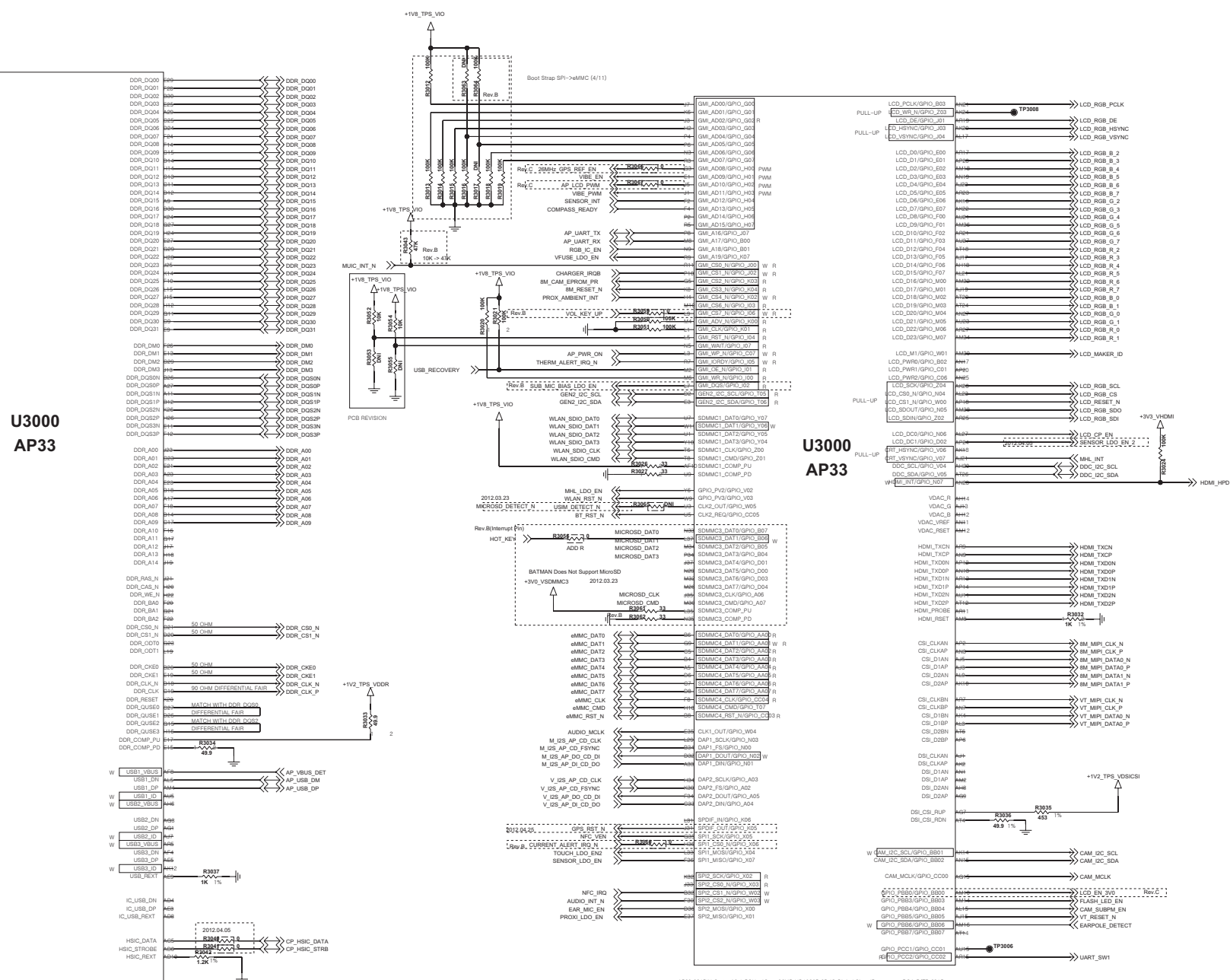
[illegible][illegible]

AP33 System



AP33, 681Pin, Cortex A9, 1.5GHz, 4Core, 36MP, HD1080P, 3D, IC, Digital Signal Processors BGA R/TP 681P

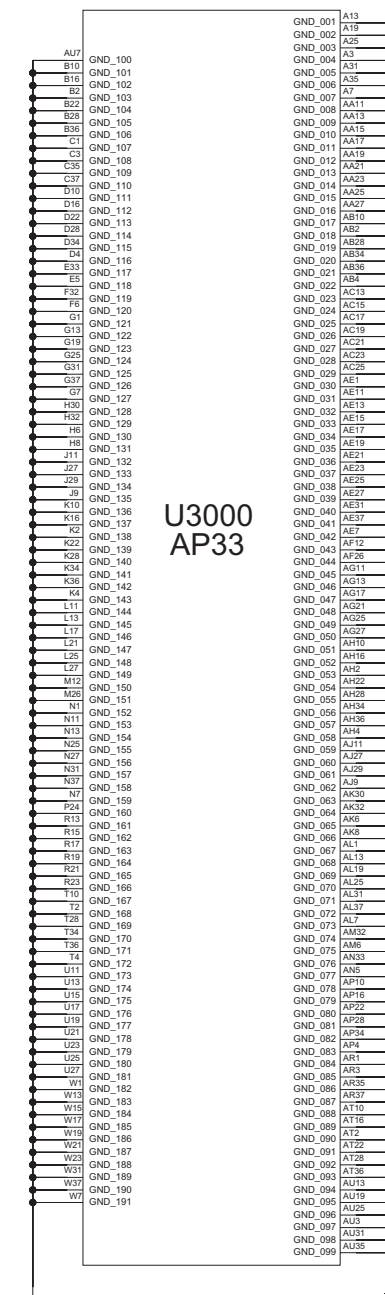
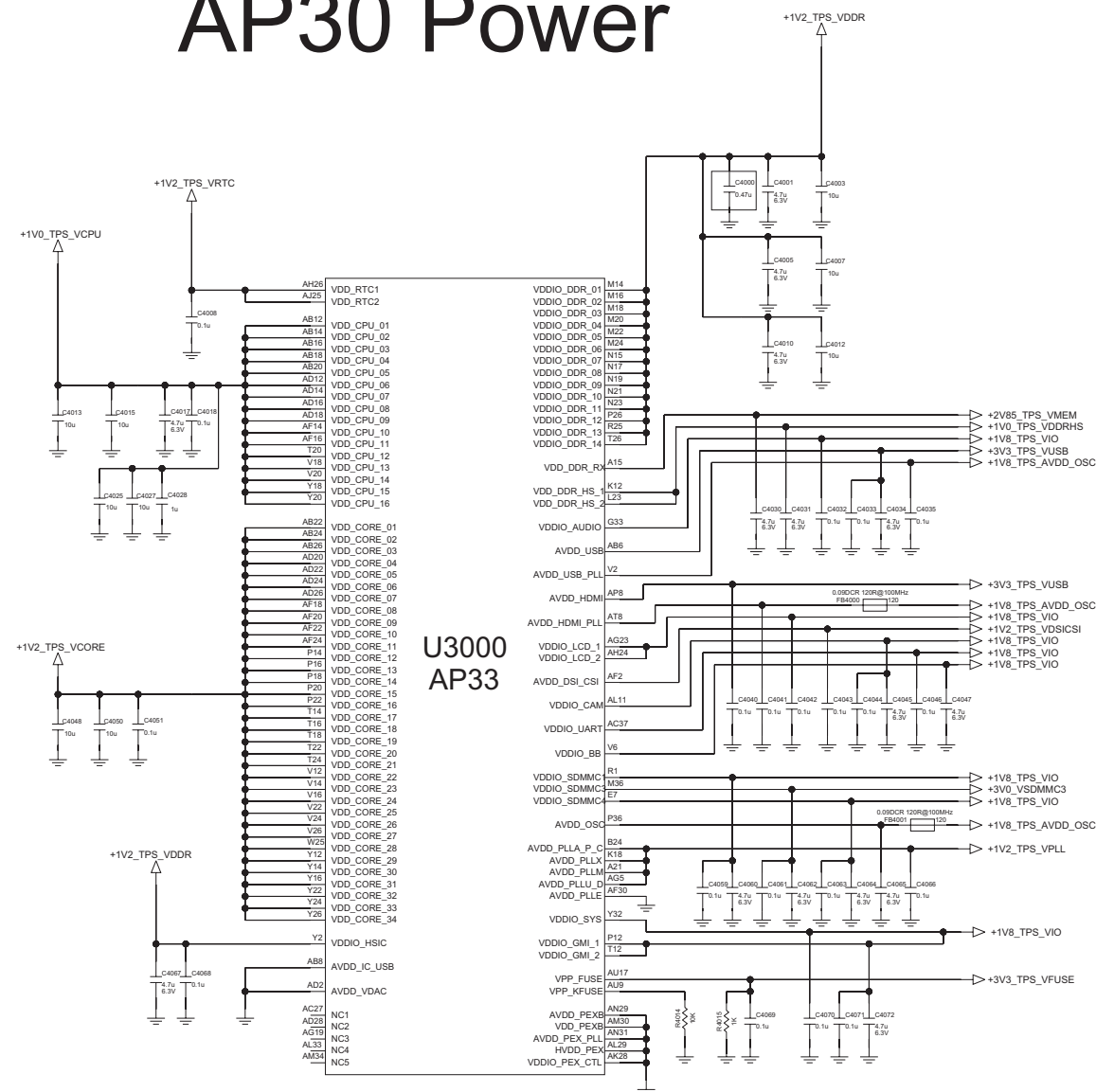
AP33 I2C MAP

[illegible]

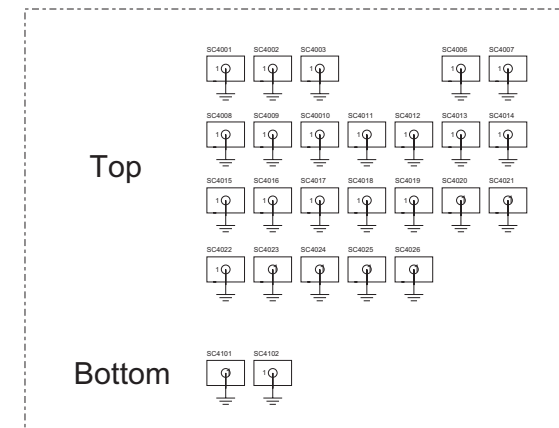
AP33,681PIN,CortexA9,1.5GHz,4Core,36MP,HD1080P,3D,IC,Digital SignalProcessors BGA R/TP 681P

LPDDR2+eMMC MCP DISCRETE

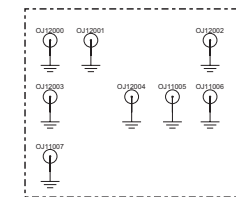
AP30 Power



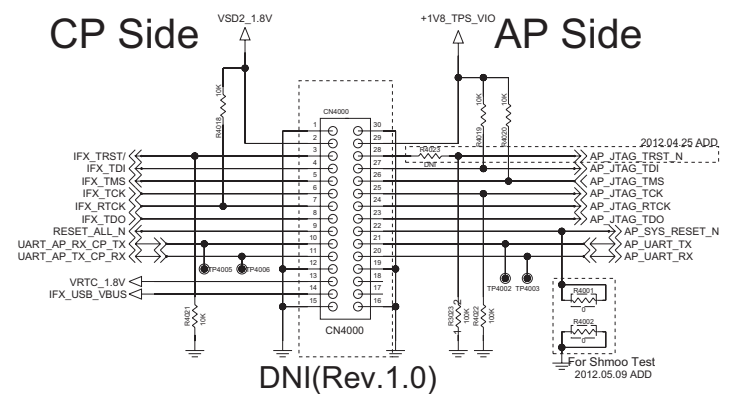
Shield Can



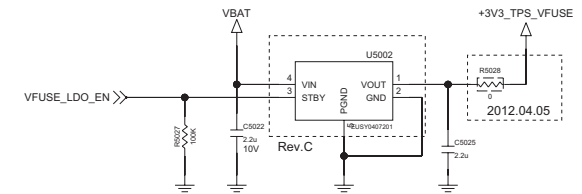
Screw



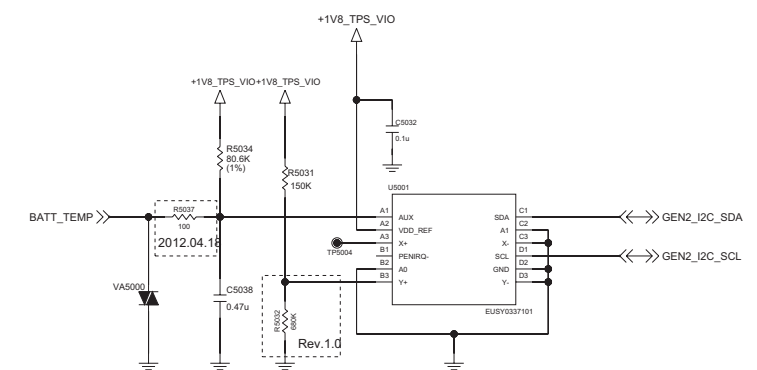
JTAG INTERFACE



Daisy Chain Rev.1.0



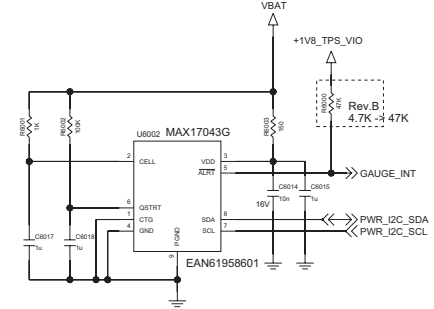
4ch. ADC



	ADC Voltage	R5031	R5032	PART NUMBER
REV A	0.211	150K	20K	ERHZ0000237
REV B	0.429	150K	47K	ERHZ0000287
REV C	0.561	150K	68K	ERHZ0000312
REV D	0.720	150K	100K	ERHZ0000204
REV E	0.900	150K	150K	ERHZ0000222
REV F	1.200	150K	300K	ERHZ0000265
REV G	1.364	150K	470K	ERHZ0000288
REV 1.0	1.474	150K	680K	ERHZ0000537
REV 1.1	1.500	150K	750K	ERHZ0000316

[illegible]

Close to batt. connector

[illegible]

Deleted Rev.1.0

SENSOR_3,0V

AP_THERM_P

AP_THERM_N

R0011 100

C0031

UCC

SCL

GND

EUS1943021

PWR_I2C_SCL

PWR_I2C_SDA

THERM_ALERT_IRQ

R0012 100

C0032

VS_TPS_VIO

R0022 100K

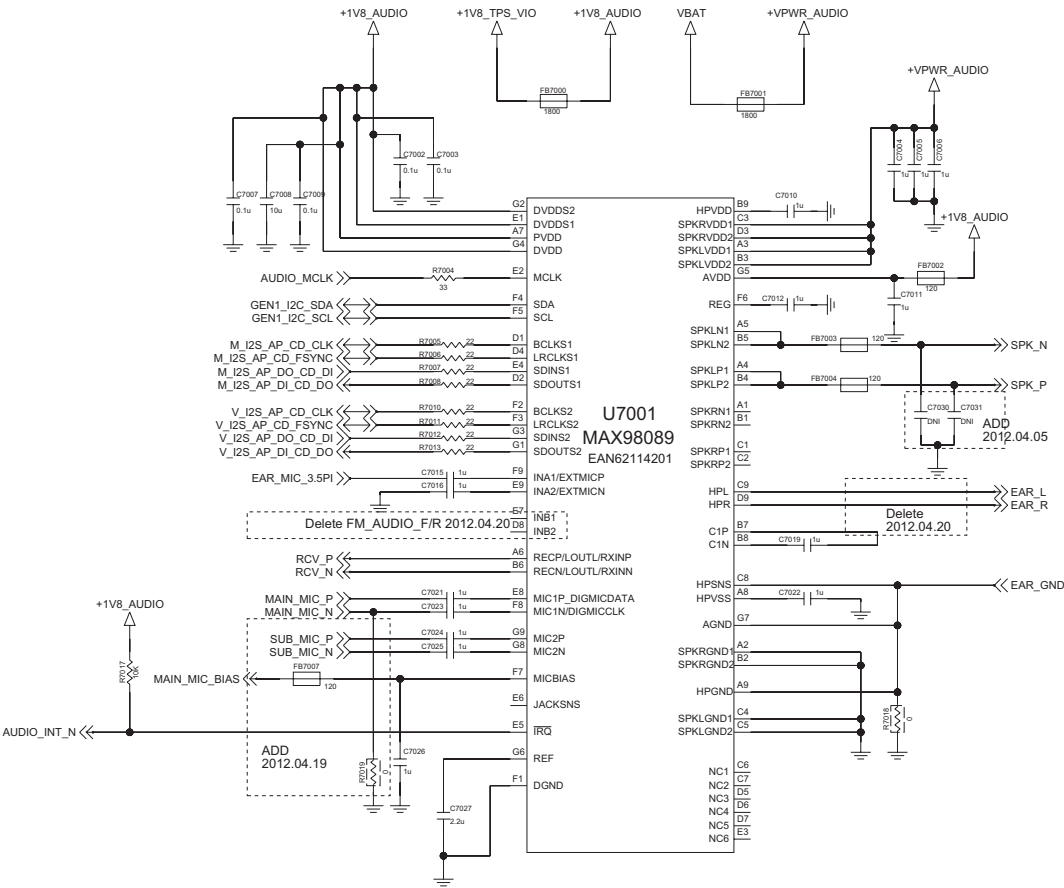
R0023

SHDN

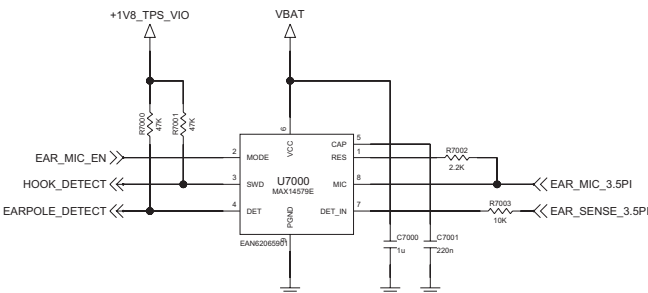
D0002

CHANGE 2012.04.05

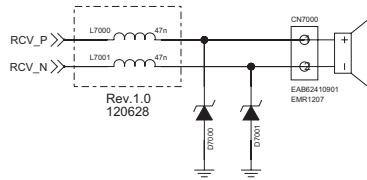
MAX98089 (AUDIO CODEC)



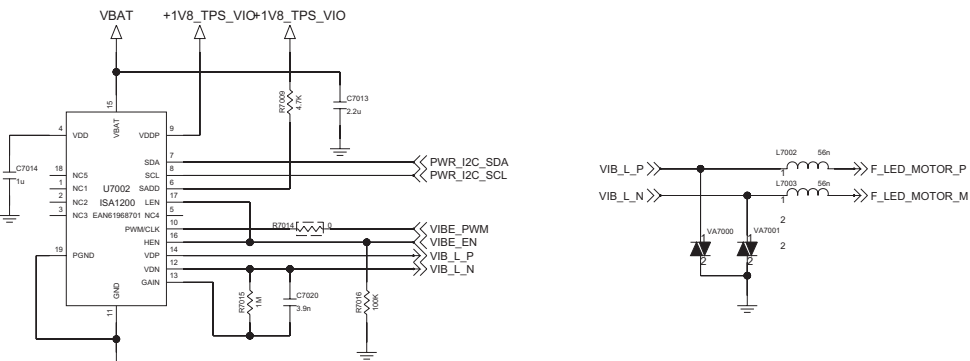
HEADSET_DETECT



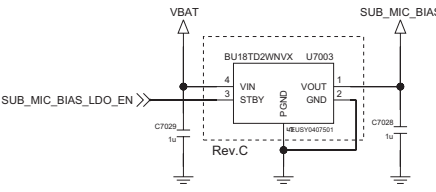
RECEIVER



Linear Motor Driver



SUB-MIC BIAS LDO



LCD BackLight Driver (2string)

LCD POWER

The image displays two circuit diagrams for LCD power regulation, both labeled 'Rev.C'.

Top Diagram: This circuit shows the LCD_EN signal connected to the VIN of a BU18TD2WNVX U8000 regulator. The regulator's PGND pin is connected to ground, and its VOUT pin is connected to the IOVCC_LCD_1V8 output. The input line is also connected to ground through capacitors C8002 and C8003.

Bottom Diagram: This circuit shows the LCD_EN_3V0 signal connected to the VIN of a BU30TD2WNVX U8002 regulator. The regulator's PGND pin is connected to ground, and its VOUT pin is connected to the VCC_LCD_3V0 output. The input line is also connected to ground through capacitors C8001 and C8008.

5" LCD CONNECTOR

12LEDs

The diagram illustrates the wiring for a 5-inch LCD connector supporting 12 LEDs. It features four LCD modules (FL8001, FL8002, FL8003, FL8004) and a central CN8000 connector. Each LCD module is connected to the CN8000 connector via its respective pins. The CN8000 connector has 31 pins, with pins 11 through 18 connected to 12 LEDs (LED A, LED C1, LED C2). Pins 19 through 21 are connected to LCD_RESET_N. Pins 22 through 24 are connected to LCD_PWM and LCD_MAKER_ID. Pins 25 through 27 are connected to a 15k resistor. Pins 28 through 31 are connected to a 15k resistor. The diagram also shows a VCC_LCD_3V0 supply and a GND connection.

Components and Connections:

- LCD Modules:** FL8001, FL8002, FL8003, FL8004 (ICMEF112P900M).
- Connector:** CN8000 (L8-411026, Q80A2-30S-410-E3000, ENR70500373).
- LEDs:** LED A, LED C1, LED C2.
- Resistors:** 15k (F88000), 15k (C8000).
- Diodes:** V8000, V8001, C8004, C8005, C8006.
- Supply:** VCC_LCD_3V0.
- Ground:** GND.

Pin Connections:

- FL8001:** 1 (LCD_MIPI_DATA_I0_N), 2 (LCD_MIPI_DATA_I0_P), 3 (GND), 4 (LCD_MIPI_DATA_I1_N), 5 (LCD_MIPI_DATA_I1_P), 6 (LCD_MIPI_CLK_N), 7 (LCD_MIPI_CLK_P), 8 (GND).
- FL8002:** 1 (LCD_MIPI_DATA_I0_N), 2 (LCD_MIPI_DATA_I0_P), 3 (GND), 4 (LCD_MIPI_DATA_I1_N), 5 (LCD_MIPI_DATA_I1_P), 6 (LCD_MIPI_CLK_N), 7 (LCD_MIPI_CLK_P), 8 (GND).
- FL8003:** 1 (LCD_MIPI_CLK_N), 2 (LCD_MIPI_CLK_P), 3 (GND), 4 (LCD_MIPI_DATA_I0_N), 5 (LCD_MIPI_DATA_I0_P), 6 (LCD_MIPI_DATA_I1_N), 7 (LCD_MIPI_DATA_I1_P), 8 (GND).
- FL8004:** 1 (LCD_MIPI_DATA_I2_N), 2 (LCD_MIPI_DATA_I2_P), 3 (LCD_MIPI_DATA_I3_N), 4 (LCD_MIPI_DATA_I3_P), 5 (GND), 6 (LCD_MIPI_CLK_N), 7 (LCD_MIPI_CLK_P), 8 (GND).

LED Connections:

- 11 (LED A), 12 (LED C1), 13 (LED C2), 14 (LED A), 15 (LED C1), 16 (LED C2), 17 (LED A), 18 (LED C1), 19 (LED C2).

Other Connections:

- 20 (LCD_RESET_N), 21 (LCD_RESET_N), 22 (LCD_PWM), 23 (LCD_MAKER_ID), 24 (LCD_MAKER_ID), 25 (15k), 26 (15k), 27 (15k), 28 (15k), 29 (15k), 30 (15k), 31 (15k).

RGB IC POWER

RGB CONVERTER

The schematic diagram illustrates the connection of the U8003 SSD2825G44 EAN62222401 IC to an LCD and a MIPI interface. The IC is a central component with multiple pins for data, control, and power.

Pin Connections:

- DATA Lines:** DATA_0 to DATA_23 are connected to the LCD data lines (LCD_RGB_R_0 to LCD_RGB_R_7, LCD_RGB_B_0 to LCD_RGB_B_7, LCD_RGB_G_0 to LCD_RGB_G_7).
- Control Lines:** SDO, SDI, SOC, SSC, CS, DEN, HSYNC, VSYNC, PCLK, TX_CLK_XO, TX_CLK_XIN, and MIPI_RESET_N are connected to the LCD control lines.
- Power Supply:** +1V8_VPWIR is connected to the VDDIO pin. +1V8_VPWIR is connected to the VDDIO pin. +1V8_VPWIR is connected to the VDDIO pin.
- MIPI Interface:** MIPI_CLK_P, MIPI_CLK_N, MIPI_DATA_0_P, MIPI_DATA_0_N, MIPI_DATA_1_P, MIPI_DATA_1_N, MIPI_DATA_2_P, MIPI_DATA_2_N, MIPI_DATA_3_P, MIPI_DATA_3_N, and MIPI_RESET_N are connected to the MIPI interface pins.

The IC is labeled U8003 SSD2825G44 EAN62222401.

SUB PMIC-CAM POWER

[illegible]

CAM. FLASH DRIVER

FLASH_LED

FLASH LED

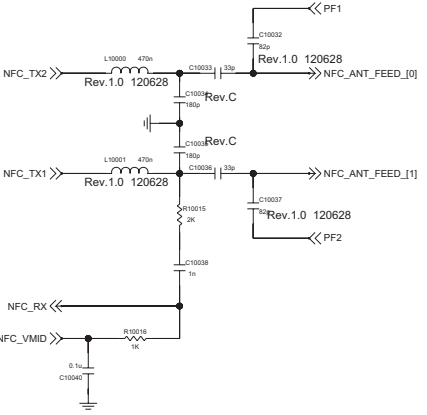
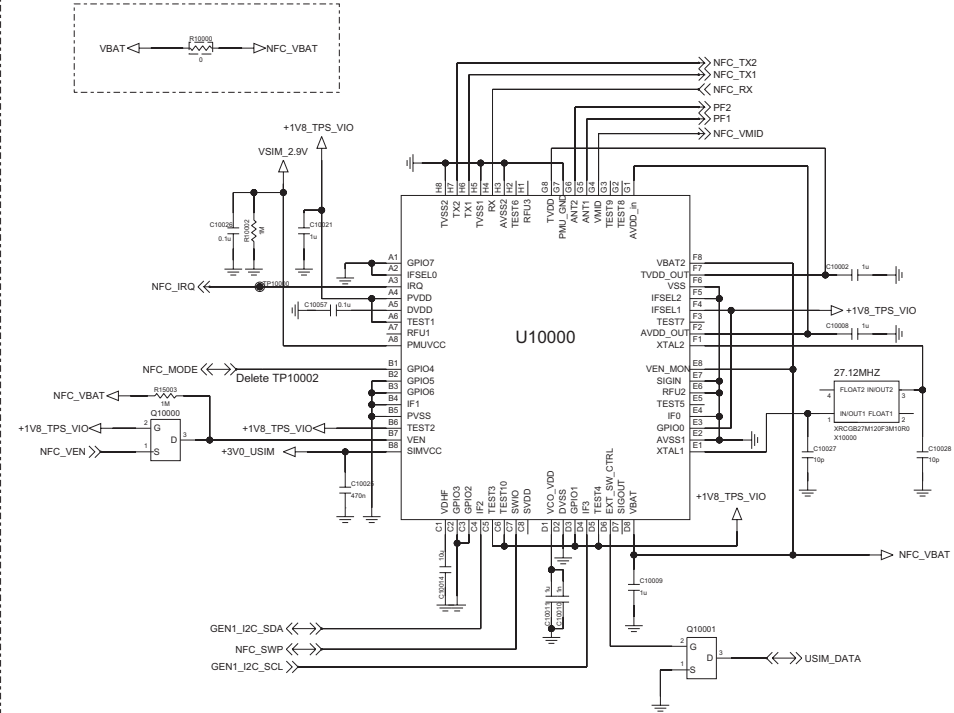
FLASH_LED

CAM. FLASH DRIVER

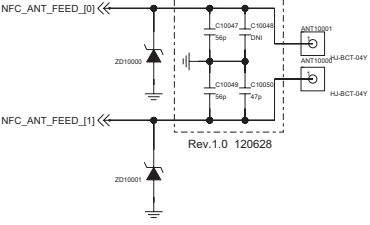
FLASH_LED

FLASH LED

NFC

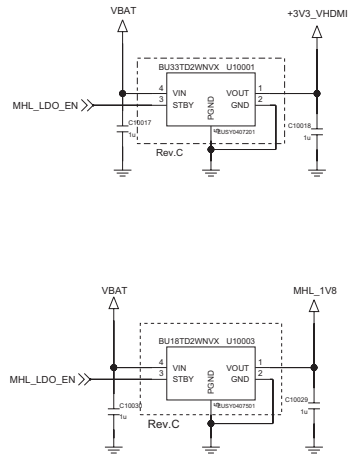


NFC ANT. FEEDING



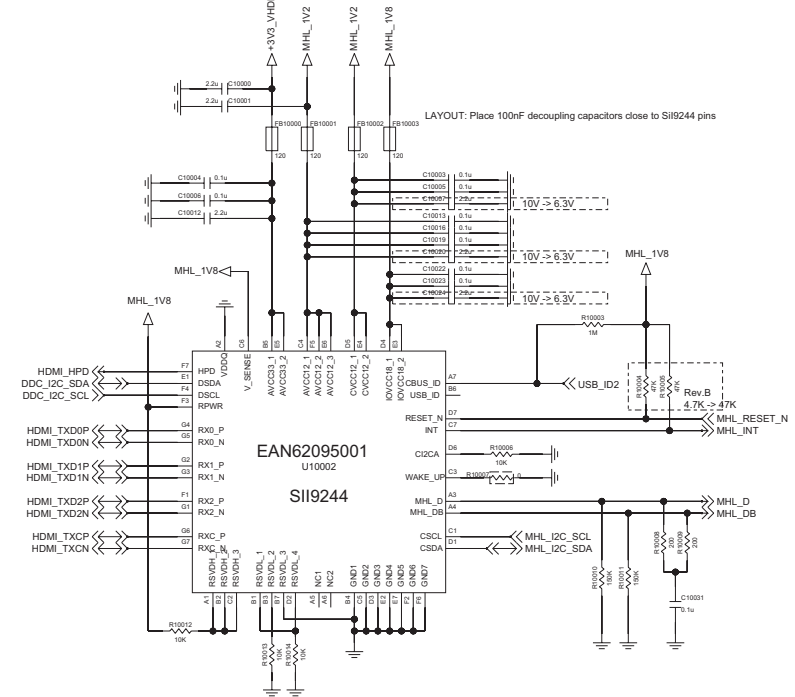
MHL LDO

have to check power on sequence

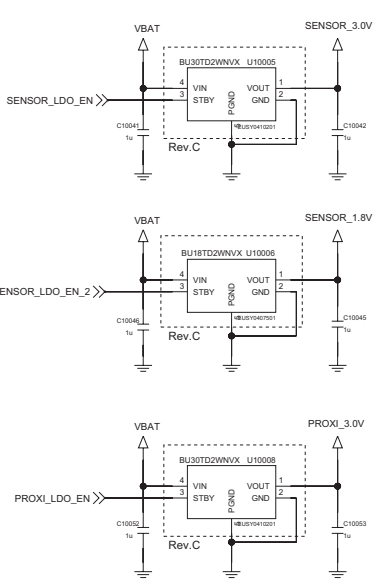


HDMI TO MHL TX

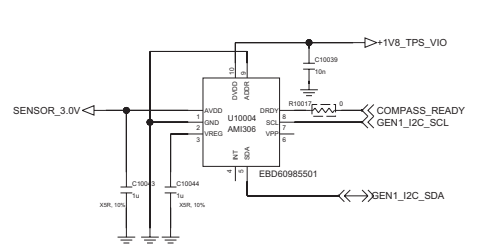
have to verify circuit, omap OUTPUT Voltage level / MHL input voltage level check!!!



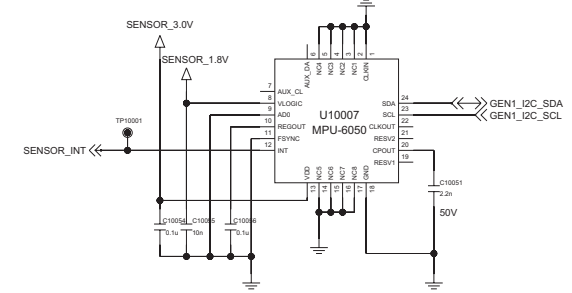
SENSOR LDO



Compass Sensor

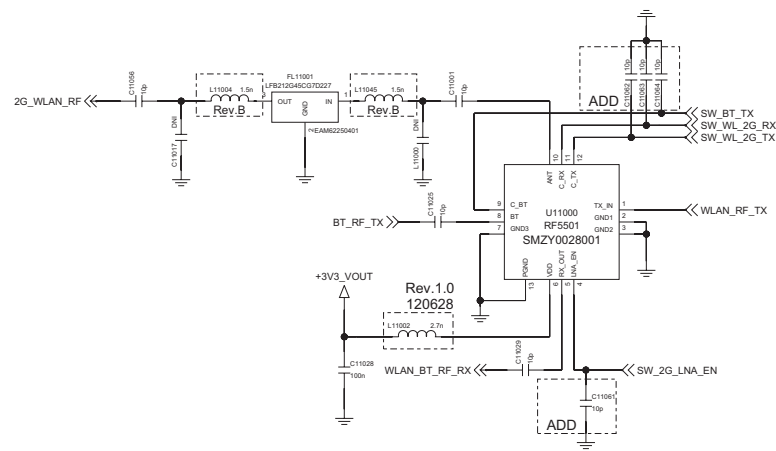


GYRO&MOTION

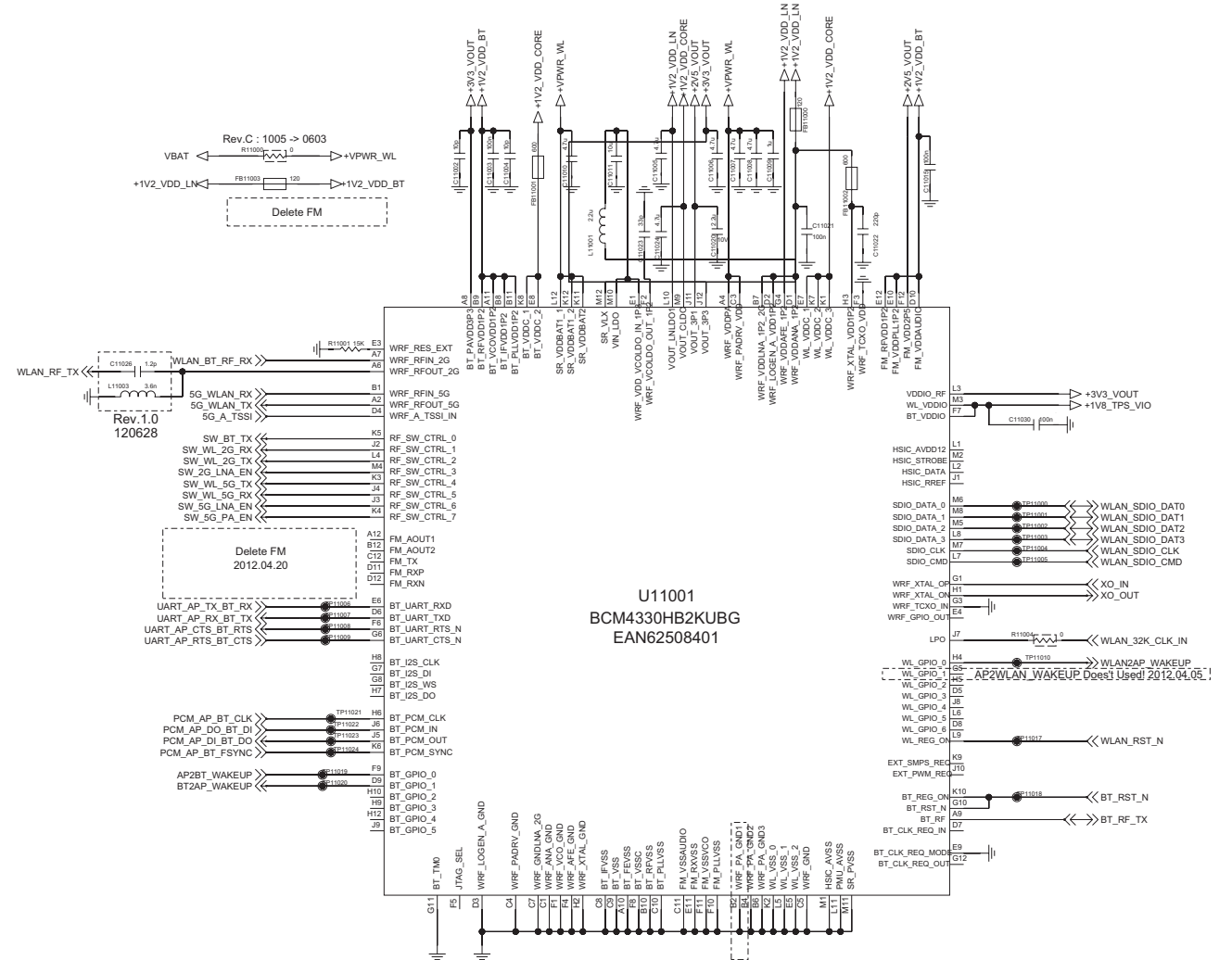


[CCDS] Connectivity_WIFI DualBand/BT/FM Combo

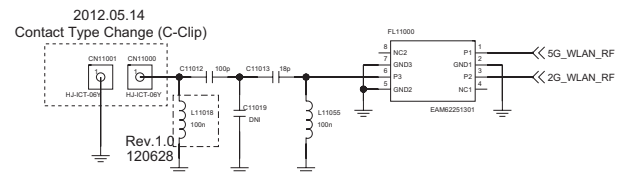
2.4GHz Wi-Fi & BT RF



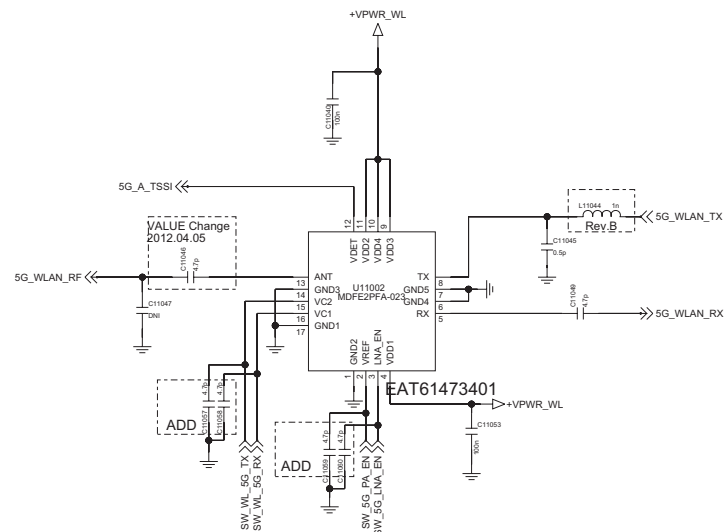
Wi-Fi & Bluetooth BB BCM4330X WLBGA



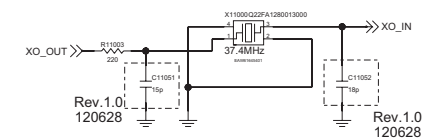
Antenna & Diplexer



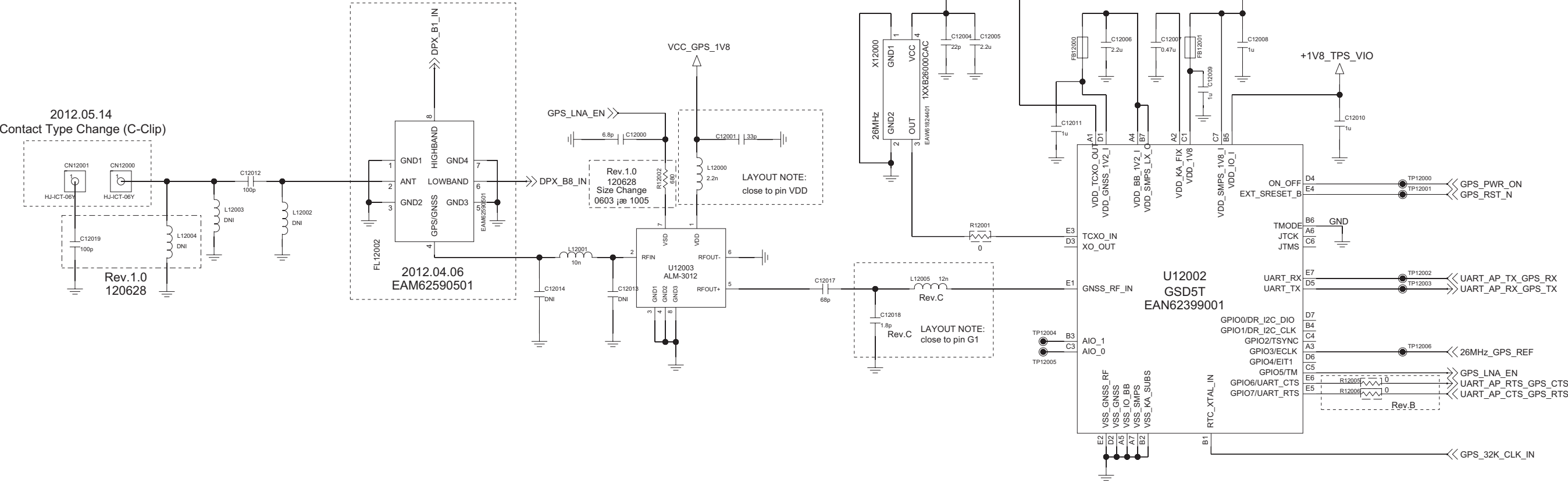
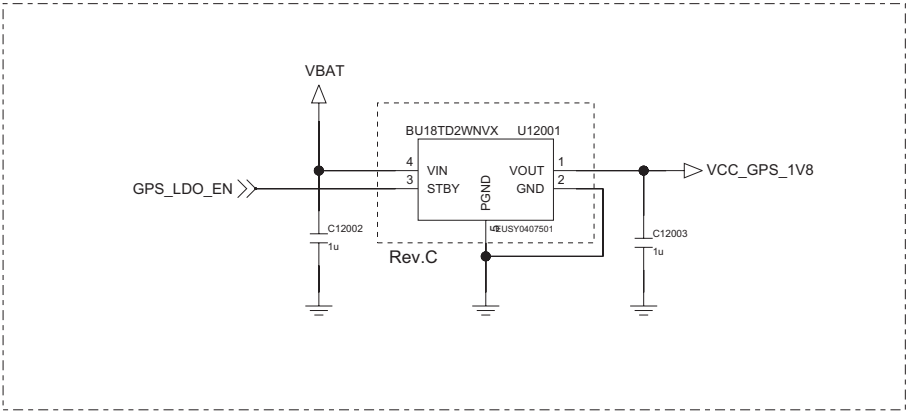
5GHz Wi-Fi RF



Must Check Schematic!!!



GNSS



[illegible][illegible]

Earjack FPCB

earjack, hot key, prox&ALS, 2nd MIC

The schematic diagram illustrates the Earjack FPCB layout. It features a central connector with 24 pins. Key components and connections include:

- Microphones:** SUB_MIC_P, SUB_MIC_N, and SUB_MIC_BIAS are connected to pins 1, 2, and 3 respectively. SUB_MIC_BIAS is also connected to pin 4.
- Earjack:** EAR_L and EAR_R are connected to pins 5 and 6 respectively. EAR_MIC_3_SPI is connected to pin 7.
- Hot Key:** KEY_R[1] is connected to pin 23. KEY_C0[0] and HOT_KEY are connected to pin 24.
- Proximity and Ambient Light Sensor:** I2C_SENSOR_SDA, GEN1_I2C_SDA, and PROX_AMBIENT_INT are connected to pin 21. I2C_SENSOR_SCL, GEN1_I2C_SCL, and EAR_SENSE_3_SPI are connected to pin 22.
- Power and Ground:** +1V8_TPS_VIO, +1V8_TPS_VIO+3V0_VSDMMC3, and GND are connected to pins 10, 11, and 12 respectively. EAR_GND is connected to pin 13.
- Other Components:** A 100k resistor (R100K) is connected between pins 23 and 24. A 100k resistor (R100K) is connected between pins 21 and 22. A 100k resistor (R100K) is connected between pins 23 and 24. A 100k resistor (R100K) is connected between pins 21 and 22. A 100k resistor (R100K) is connected between pins 23 and 24. A 100k resistor (R100K) is connected between pins 21 and 22.

Annotations include "Delete 2012.04.10" and "Change 2012.04.10".

USB RECOVERY

Must Check Schematic

VOLUME SIDEKEY

	COL[0]	COL[1]
ROW[0]	Vol Up	Vol Down
ROW[1]	Hot Key	

Touch LDO

5" TOUCH CONN.

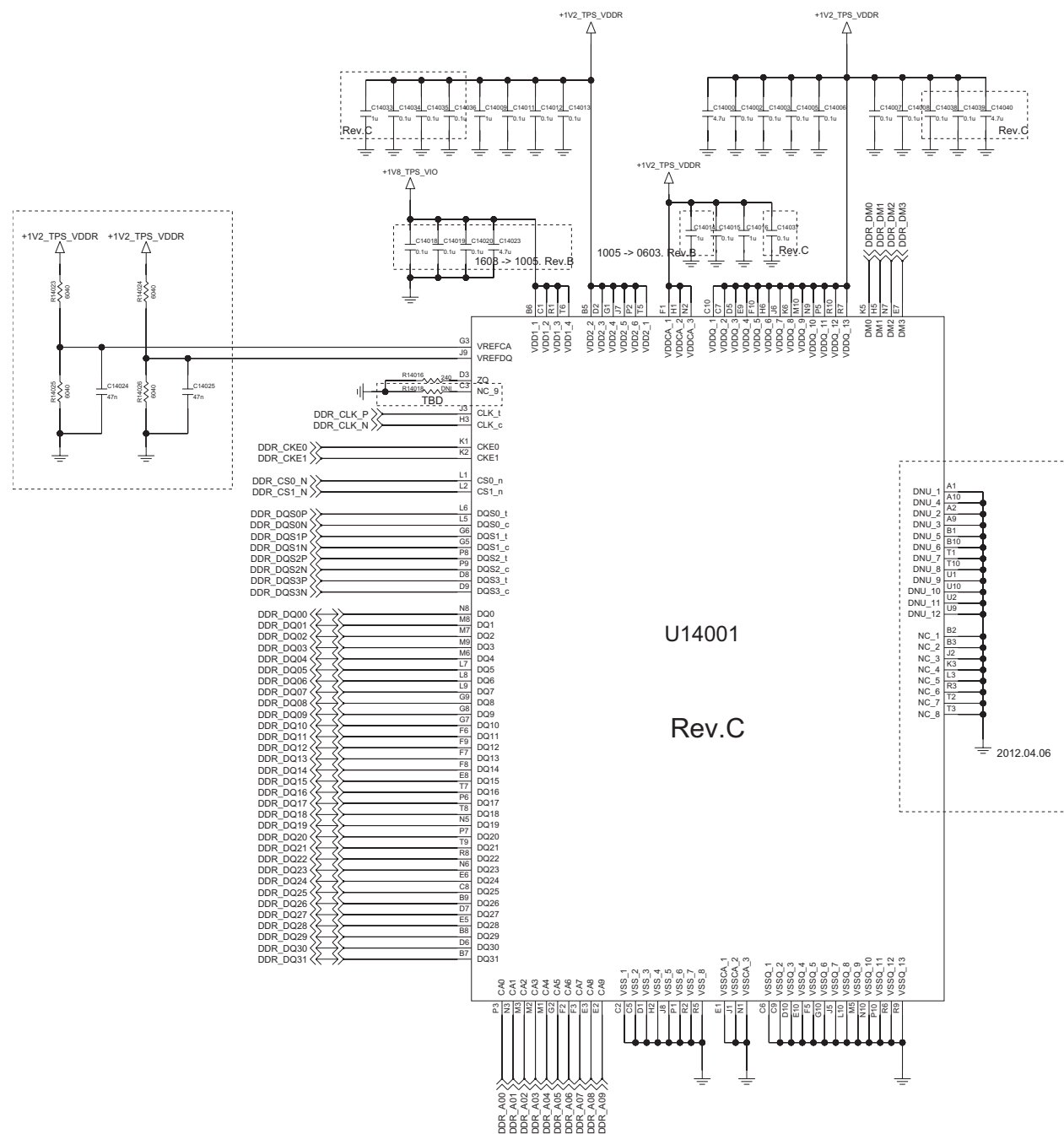
The diagram illustrates a 5-inch touch connection circuit. It features a 10k resistor network connected to TOUCH_1.8V and TOUCH_3.0V. The network includes a 47k resistor (Rev 1.0) and a 10k resistor (Delete R. Rev.C). The circuit also includes a 10k resistor (C13015), a 10k resistor (C13018), and a 10k resistor (C13019). The circuit is powered by a 5V supply and includes a 10k resistor (C13015) and a 10k resistor (C13018).

micro USIM(push push)

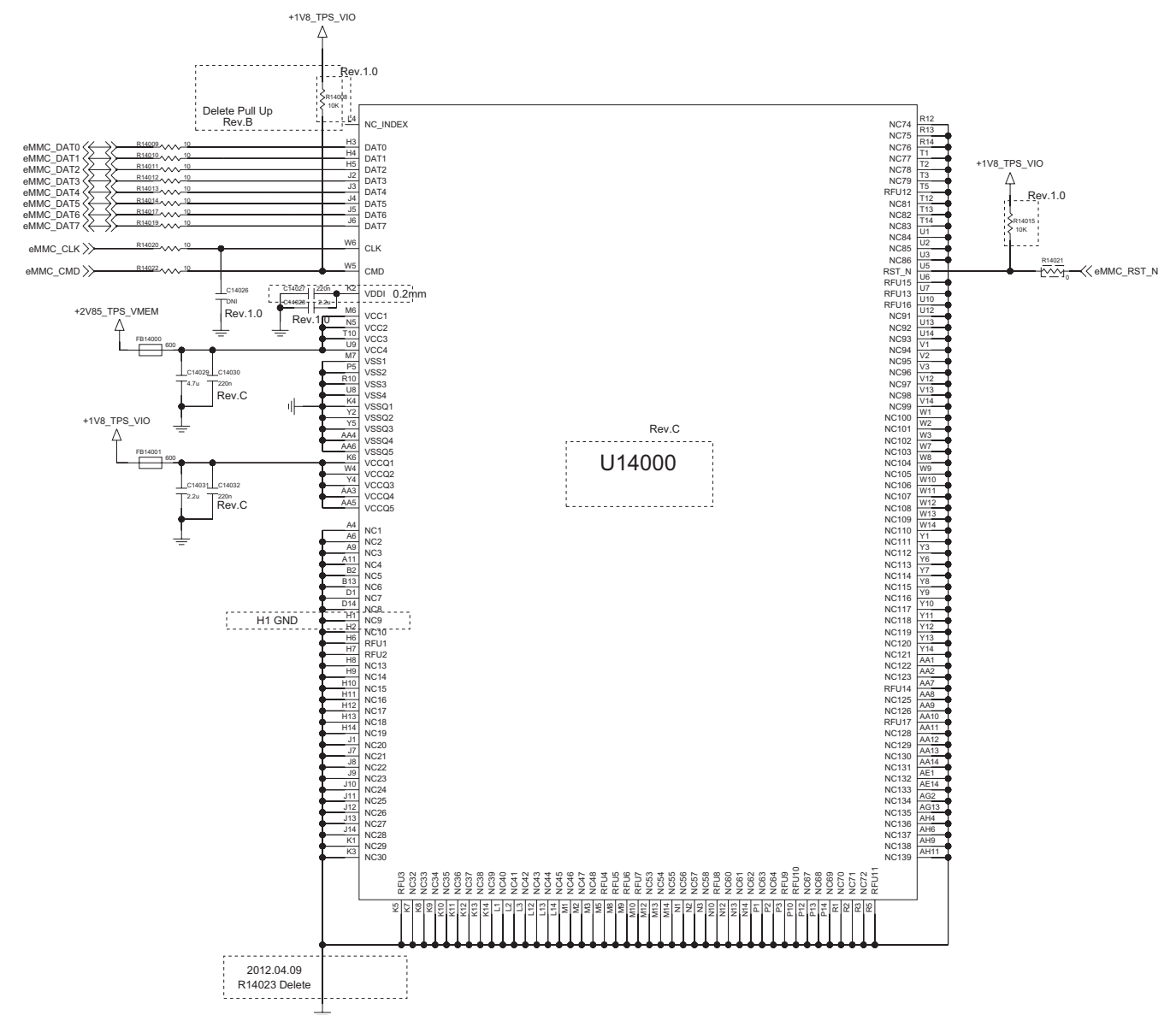
Figure 10: U1000B Rev.B Schematic

Control Input(Sn)	Function
LOW	nB0 Connected to nA
HIGH	nB1 Connected to nA

Must Check Schematic!!!

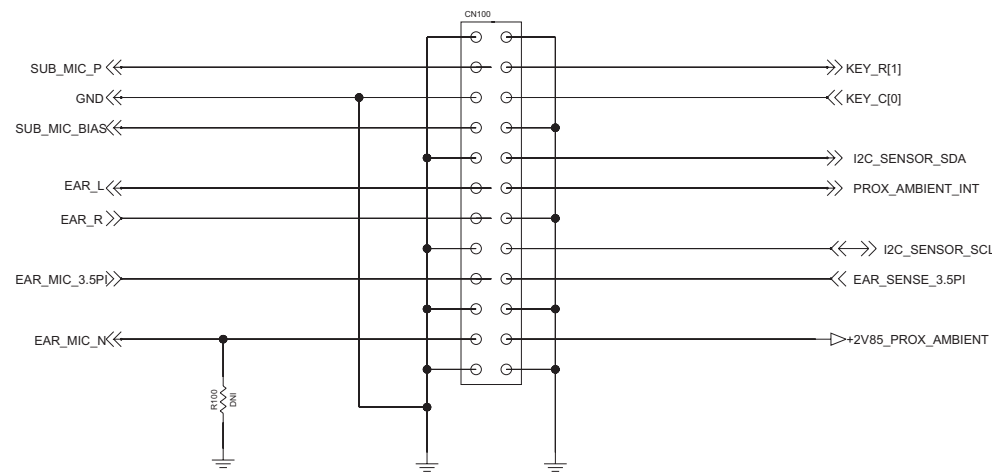


eMMC 32GB

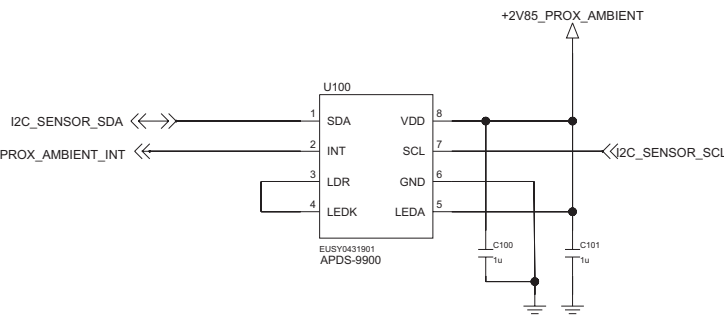


Earjack FPCB

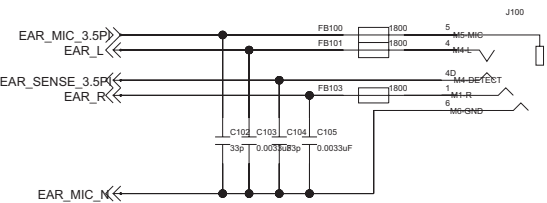
earjack, hot key, prox&ALS, 2nd MIC



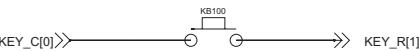
Proxi. Ambient Sensor



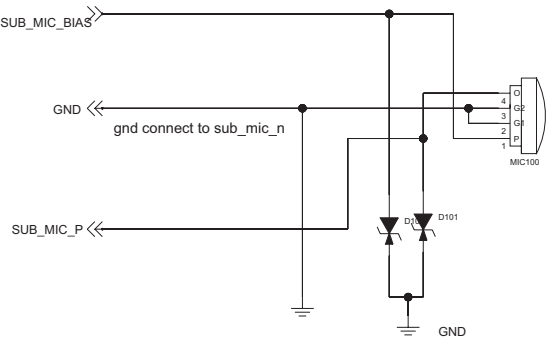
3.5pi EAR JACK



HOT KEY

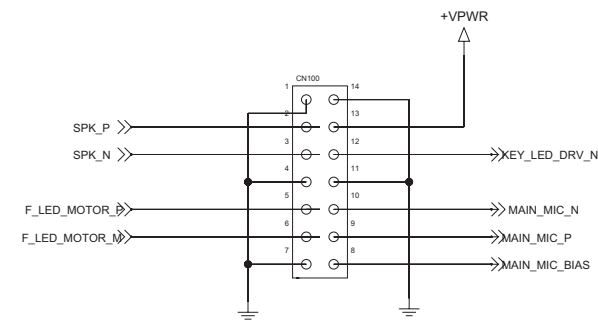


SUB MIC

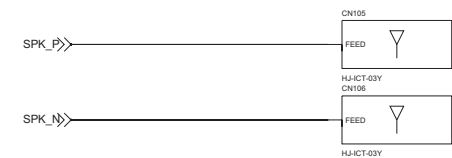


Lower RFPCB

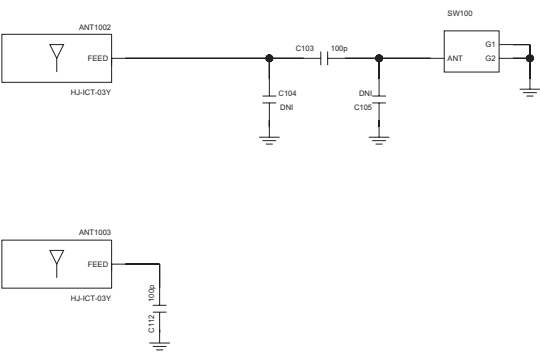
connector from main PCB



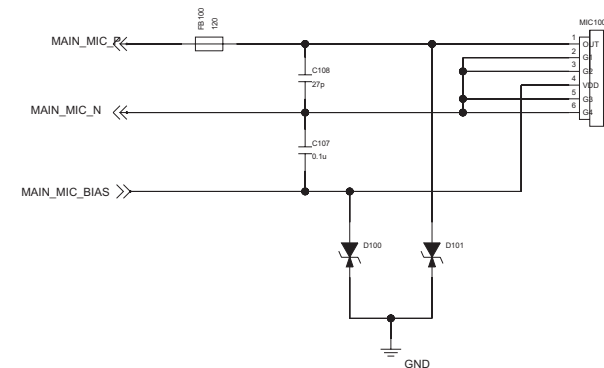
SPEAKER



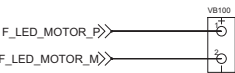
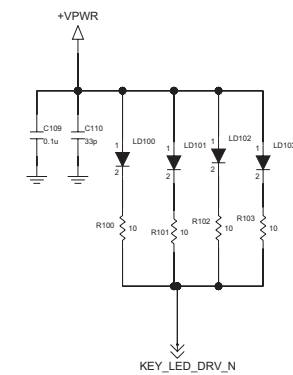
RF CONNECTOR



MAIN MIC



MAIN KEY LED



8. BGA PIN MAP

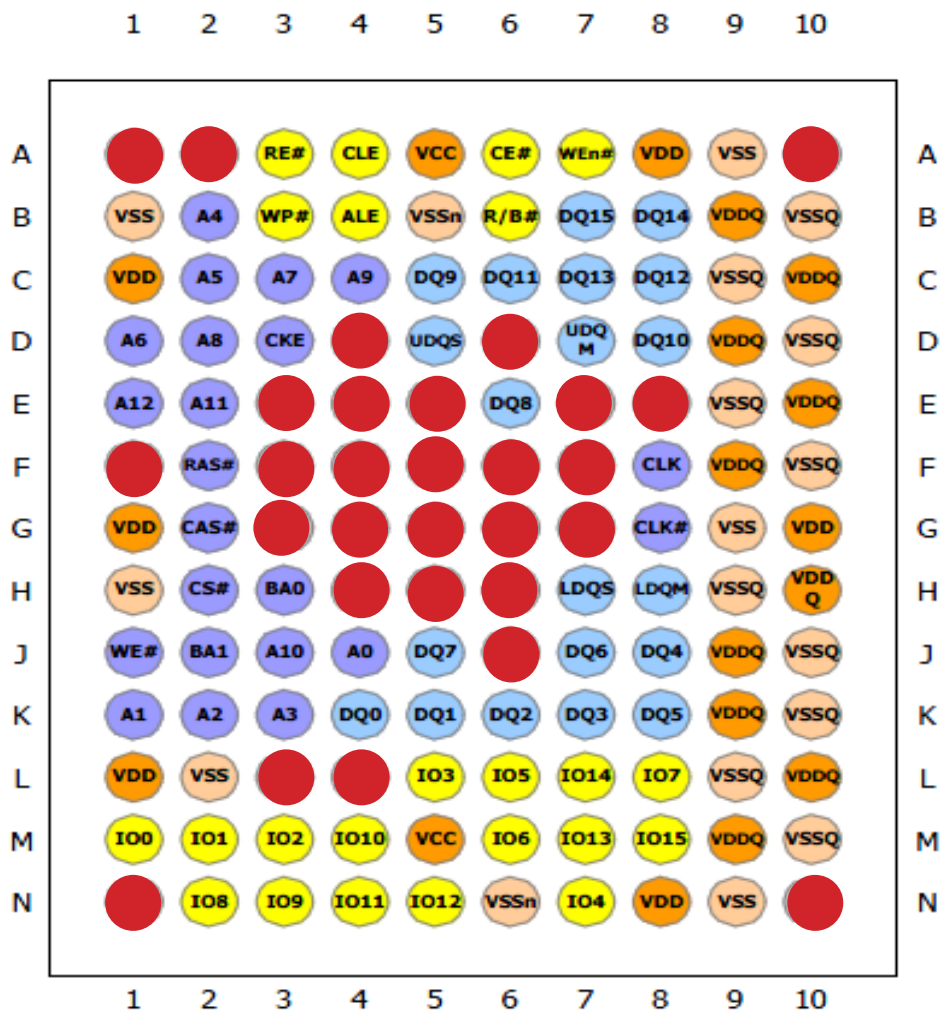
PMB5712,A2 (EAN62514301)

	1	2	3	4	5	6	7	8	9	10	11	12	13	
A	NC	PM_H	GND	PM_L		VDD1V8_TXDCO	GND	MI1	VDDBA_T	CEXT_XO	XO		R_EXT	A
B	VDDBA_T_TXRF	VDD_TXRF	NB	NB		NB	NB		D2B_OUT	AFC_DAC	XO_SUP	XO_EXT	VDD1V8_SCU	B
C	PA_RF	D2B_OUT_TXRF	GND	CEXT_TXMS	VDD2V5_TXB/AS	VDD2V5_TXDCO	GND	GND	VDD1V8_DIG	GND	GND	DI3_TX_DAT	DI3_RX_DAT	C
D	PA_PO_W_DET	VDD1V8_FBR	SPI_CLK	SPI_DRW	VDD1V8_TXLO	NB	NB	CEXT_TXPLL	GND	VDD2V5_FSYS	NB	DI3_TX_DATX	DI3_RX_DATX	D
E	GND	RX_L1	VSP1	SPI_SS	GND	GND		VDD1V8_TXMS	FUSE_SUP	NB	NB	VDDIO	REF_CLK_EN	E
F	RX_L2	RX_L1X	VDD1V8_RCB	GND	GND	GND	VDD1V8_RCMS	GND	VDD1V2_DIG	GND	NB	SYS_CLK_EN	SYS_CLK	F
G	RX_L2X	RX_M1	GND	GND	VDD1V8_RCL	GND	GND	GND	GND	GND	NB	FSYS1	FSYS1_EN	G
H	RX_M2	RX_M1X	GND	GND	GND	GND	NB	NB	CEXT_RXPLL	GND	NB	FSYS2_EN		H
J	RX_M2X		GND	VDD2V5_RCB	VDD2V5_RCRF	GND	GND	VDD2V5_RXDCO	GND	GND	DAP1		FSYS3_EN	J
K	RX_H2		NB	NB	GND	GND	NB	NB	VDD1V8_RXPLL	GND	DAP0		CLK_ON	K
L	RX_H2X	VDD1V8_RCRF	GND	RD_L1	RD_L1X	RD_H	RD_HX	GND	VDD1V8_RXDCO	VDD2V5_RFC	GND	GND	VDD1V8_RFC	L
M	NC	GND			RD_M	RD_MX	GND	GPO4				PA_RAMP	NC	M
	1	2	3	4	5	6	7	8	9	10	11	12	13	

 Not Used

8. BGA PIN MAP

H9DA1GH25HAMMR-4EM NAND/1G SDRAM/256M CP Memory (EAN62327101)



● Not Used

8. BGA PIN MAP

XMM6260(EUSY0432001)

XG626 Ball Map (Top View) 6/15/2010 7.5x7.5 FBGA

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	
A		SD1_SW	SD1_SW	VDD_VBA T SD1	VF1L	PCDP_RE _0	MEM_AD _9	MEM_A_4	MEM_A_3	MEM_A_2	MEM_A_1	MEM_BC9 _0	MEM_A_0	MEM_SDC LKG	MEM_EFC LKG_1	MEM_A_5		A
B	VSS_SD1			VIO_12		DSP_AUDM O_JNI	MEM_CAS _0_JNI	FWP	MEM_A_6	MEM_BC2 _0	VDD_IOH	MEM_WB _0	MEM_ED _0	MEM_CK _E	MEM_EFC LKG_0		MEM_A_9	B
C	VDD_VBA T SD1	SD1_FB	VDD_VSD _2	VUSE_PD					MEM_A_7			MEM_A_5					MEM_A_1 _0	C
D	SD1_SW		SD1_FB					MEM_AD _3	VSS	MEM_AD _7	MEM_AD _11	MEM_AD _12	MEM_AD _13	VSS			MEM_A_1 _1	D
E	SD1_SW			VSS				MEM_AD _5	MEM_AD _6	VDDCURI	MEM_AD _8	VDDCURI _E0	VDDCURI	MEM_RAS _0			MEM_A_1 _2	E
F	VSS_SD1	VUSE_AN _A	VDD_VBA T PMU	VRTC				MEM_AD _4					MEM_AD _15	VSS	VDD_I0H	MEM_BC1 _0	MEM_A_1 _3	F
G	VSSIM	VPMU						VSS	MEM_AD _2	MEM_AD _V_0	MEM_AD _1					MEM_BC2 _0	MEM_A_1 _4	G
H	VUSE_R0	GN1	AGND					RESERVE _D	VDDCURI	MEM_AD _10	MEM_AD _0						MEM_A_1 _5	H
J	VREF		RESET_P WRDWN _N	M0	M1	M2		VSS			VSS	MEM_AD _16	MEM_CN1 _0	MEM_CN0 _0			VDD_I0H	J
K	ETM11_T RACEPKT _7		REF_CLK _EN		ETM11_T RACEPKT _6		ETM11_T RACECLK	VDD_I0H	VDDCURI	ETM11_T RACEPKT _5	VDD_I0H		VSS	VDDCURI		VDD_MIP	MEM_WA IT_0	K
L	ETM11_T RACEPKT _1	ETM11_T RACEPKT _3		ETM11_T RACEPKT _2	ETM11_T RACEPKT _6		MMCH1_C MD	VDD_MW _C	ETM11_T RACEPKT _5	VSS	MP1_RSL TX_PLG			VSS		VSS	P32K	L
M	ETM11_T RACEPKT _0							ETM11_T RACEPKT _5	ETM11_T RACEPKT _5							VSS	OSC32K	M
N	I2S2_CLK _0			T_OUT9	MMCH1_C D			VTP	I2C1_SCL	VDD_I0H				VSS_USB			VDD_ETC	N
P	I2S2_RX	I2S2_TX	T_OUT1				HW_MGN _2	VSS	I2C1_SDA	CLKOUT2	VSS_PL1	VSS_CLK		VDD_I0H		VSS		P
R	I2S2_WA0	I2S2_WA1		NC		HW_MGN _1		VDDCURI	VSS			VDD_F1L				VDD_USB _0	USE_DMD _NIS	R
T		UNIF1_RX D_MIST	UNIF1_TX D_MISR	TRST_0	TRIG_IN	TCK	D0_TX_D AT	D0_TX_D ATA	ARESET_0 N	VDD_HG _0		VDD_SIM	CC_R0	CC_RST	VDD_USB _1D	USE_T1N _E	USE_D0F4 _IR	T
U			UNIF1_RX N_N	TDO	TDI	TMS	D0_RX_D AT	D0_RX_D ATA	SYSCLOCK _N			HSIC_USE _STER	HSIC_USE _DATA	CC_CLK	VDD_I0H2	VSS		U
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	

 Not Used

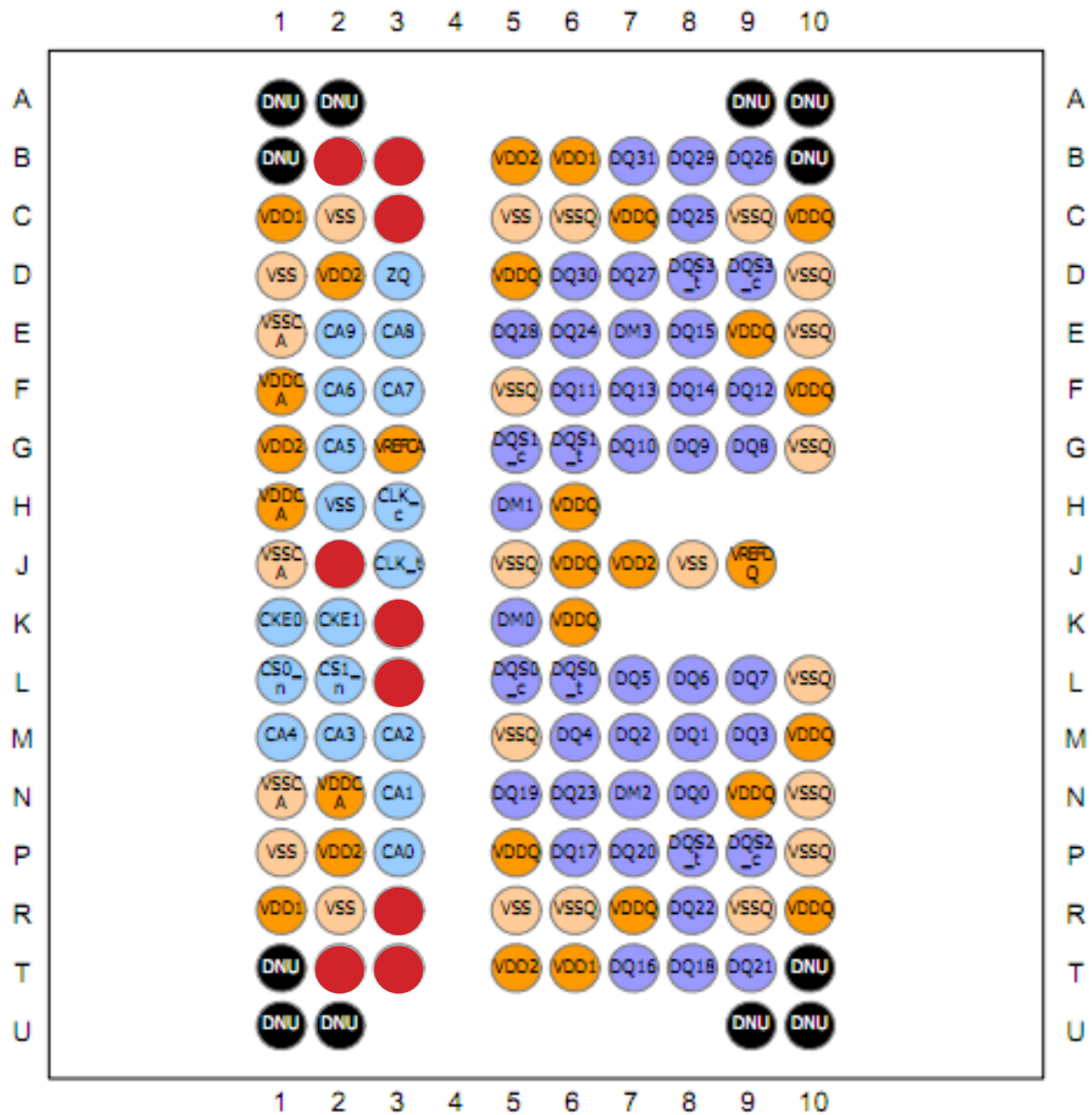
8. BGA PIN MAP

WIFI, BT Combo BCM4330HB2KUBG (EAN62508401)

	12	11	10	9	8	7	6	5	4	3	2	1	
A		BT_VCOVDD1P2	BT_FEVSS	BT_RF	BT_PAVDD3P3	WRF_RFIN_2G	WRF_RFOUT_2G		WRF_VDDPA		WRF_RFOUT_5G		A
B		BT_PLLVDD1P2	BT_RFVSS	BT_RFVDD1P2	BT_FVDD1P2	WRF_VDDANA_1P2_2G	WRF_PA_GND		WRF_PA_GND		WRF_PA_GND	WRF_RFIN_5G	B
C		FM_VSSAUDIO	BT_PLLVSS	BT_VSS	BT_FVSS	WRF_GNDANA_2G		WRF_GND	WRF_PADRV_GND	WRF_PADRV_VDD		WRF_ANA_GND	C
D			FM_VDDAUDIO	BT_GPIO_1			BT_UART_TXD		WRF_A_TSS1_IN	WRF_LOGEN_A_GND	WRF_LOGEN_A_VDD1P2	WRF_VDDANA_1P2	D
E	FM_RPVDD1P2	FM_RXVSS	FM_VDDPLL1P2	BT_CLK_REQ_MODE	BT_VDDC	WL_VDDC	BT_UART_RXD	WL_VSS_2		WRF_RES_EXT		WRF_VDD_VC_OLD0_IN_1P8	E
F	FM_VDD2P5	FM_VSSVCO	FM_PLLVSS	BT_GPIO_0	BT_VSSC	BT_VDDIO	BT_UART_RTS_N		WRF_AFE_GND	WRF_TCXO_VDD	WRF_VCOLOO_OUT_1P2	WRF_VCO_GND	F
G		BT_TMO	BT_RST_N				BT_UART_CTS_N		WRF_VDDAFE_1P2	WRF_TCXO_IN		WRF_XTAL_0P	G
H							BT_PCM_CLK		WL_GPIO_0	WRF_XTAL_VDD_1P2	WRF_XTAL_GND	WRF_XTAL_ON	H
J	VOUT_3P3	VOUT_3P1				LPO	BT_PCM_IN	BT_PCM_OUT	RF_SW_CTRL_5	RF_SW_CTRL_6	RF_SW_CTRL_1		J
K	SR_VDDBAT1	SR_VDDBAT2	BT_REG_ON		BT_VDDC	WL_VDDC	BT_PCM_SYNC	RF_SW_CTRL_0	RF_SW_CTRL_7	RF_SW_CTRL_4	WL_VSS_0	WL_VDDC	K
L	SR_VDDBAT1	PMU_AVSS	VOUT_LNLD01	WL_REG_ON	SDIO_DATA_3	SDIO_CMD		WL_VSS_1	RF_SW_CTRL_2	VDDIO_RF			L
M	SR_VLX	SR_FVSS	VIN_LDO	VOUT_CLDO	SDIO_DATA_1	SDIO_CLK	SDIO_DATA_0	SDIO_DATA_2	RF_SW_CTRL_3	WL_VDDO		HSIC_AVSS	M
	12	11	10	9	8	7	6	5	4	3	2	1	

■ Not Used

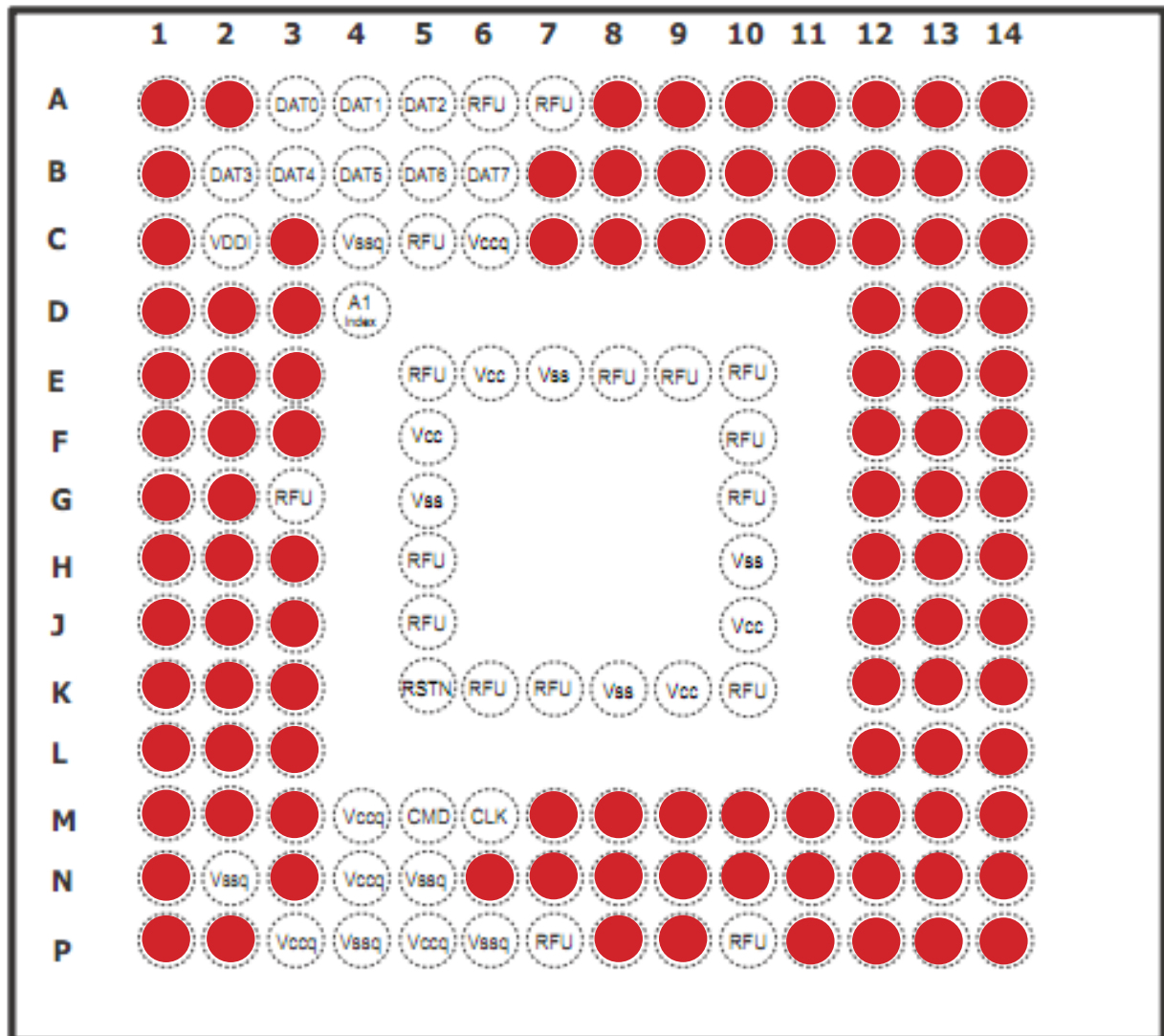
SK Hynix –LPDDR Memory
H9TCNNN8JDMMPR-NGM
// EAN62529201



● Not Used

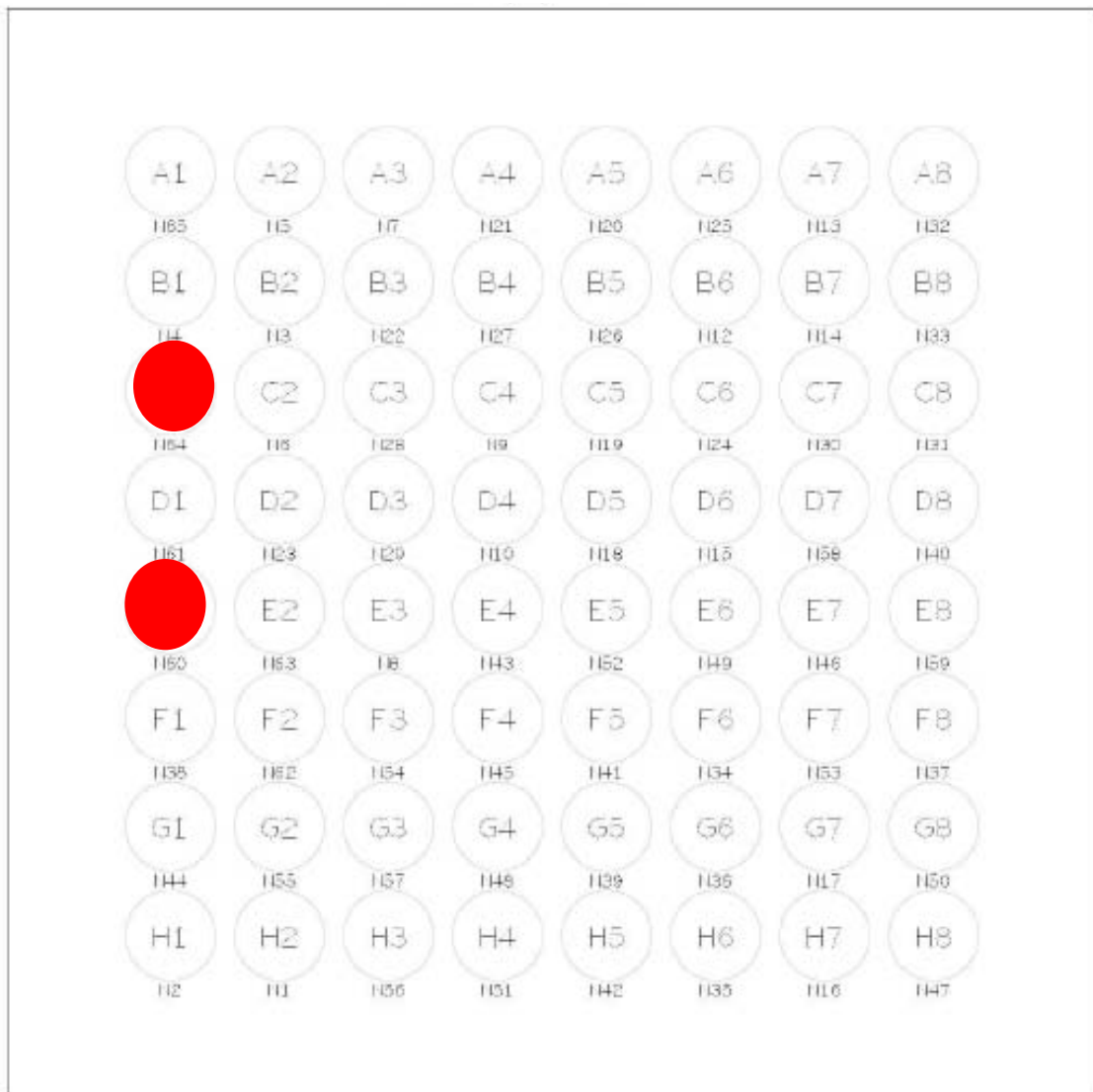
● Not Used

SK Hynix –LPDDR Memory
H9TCNNN8JDMMPR-NGM
// EAN62529201



● Not Used

SSD2825G44 (EAN62222401) RGB CONVERTER



● Not Used

MAX77663(EAN62216701)PMIC

eMGA Pinout Breakdown by Function

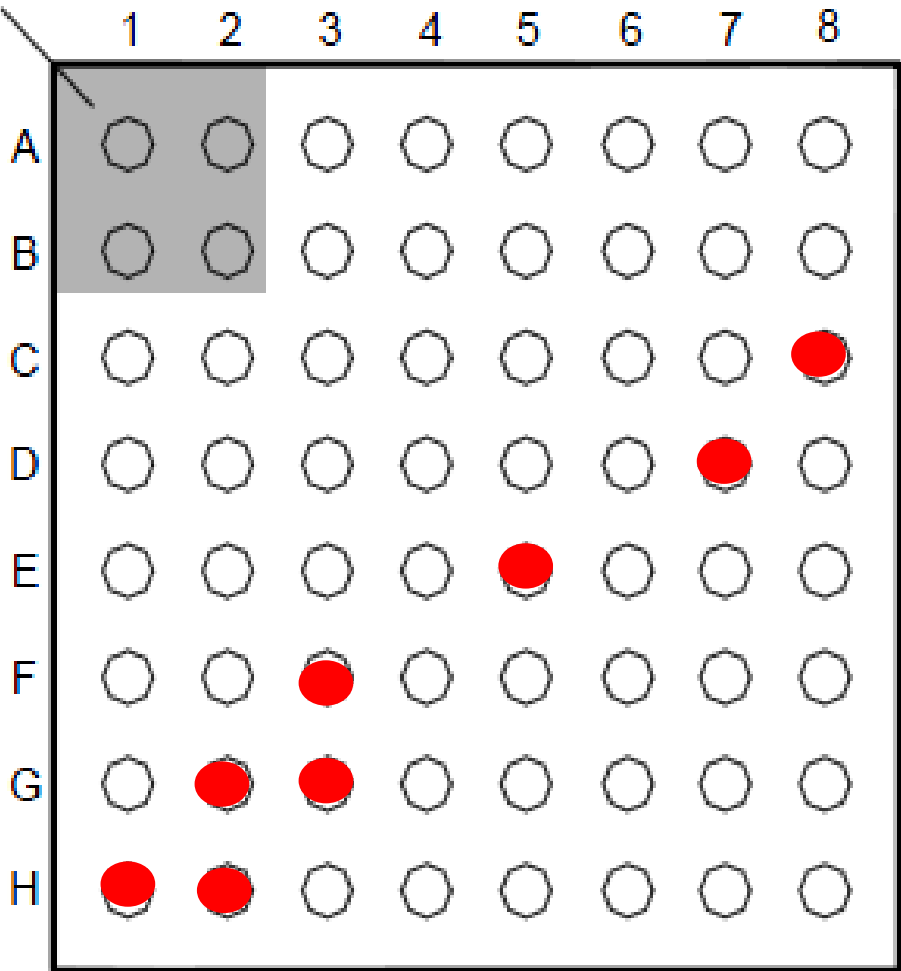
ROW/COL	1	2	3	4	5	6	7	8	9	10
A	IN_SD3	MON	OUT_LD03	IN_LD03-5	OUT_LD05	IN_LD02	OUT_LD07	IN_LD07-8	OUT_LD08	XGND
B	IN_SD3	AVSD	OUT_LD04	IN_LD04-6	OUT_LD06	OUT_LD02	OUT_LD00	IN_LD00-1	OUT_LD01	XIN
C	LX_SD3	LX_SD3	MBATT	FB_SD3	EN1	EN2	EN0	ACOK	XGND	XOUT
D	PG_SD3	nIRQ	FB_SD2	D_SD3	GND	GND	GND	FB_SD1	32K_OUT	BBATT
E	PG_SD2	SCL	INI2C	GND	LID	GND	GND	SNSN_SD1	SNSP_SD1	SHDN
F	PG_SD2	SDA	GND (SNSN_SD4)	GND (SNSP_SD4)	FB_SD0 (FB_SD4)	FB_SD0	SNSP_SD0	SNSN_SD0	nRST_IO	PG_SD1
G	LX_SD2	LX_SD2	GPIO4		GPIO_INB	GPIO_INA			LX_SD1	LX_SD1
H	IN_SD2	INB_SD0 (IN_SD4)			PGB_SD0 (PG_SD4)	PGA_SD0 (PG_SD0)	GPIO1		INA_SD0 (IN_SD0)	IN_SD1
J	IN_SD2	INB_SD0 (IN_SD4)	LXB_SD0 (LX_SD4)	LXB_SD0 (LX_SD4)	PGB_SD0 (PG_SD4)	PGA_SD0 (PG_SD0)	LXA_SD0 (LX_SD0)	LXA_SD0 (LX_SD0)	INA_SD0 (IN_SD0)	IN_SD1

Ins in parenthesis () are for the device where SD0 and SD4 operate as independent regulators.

■ Not Used

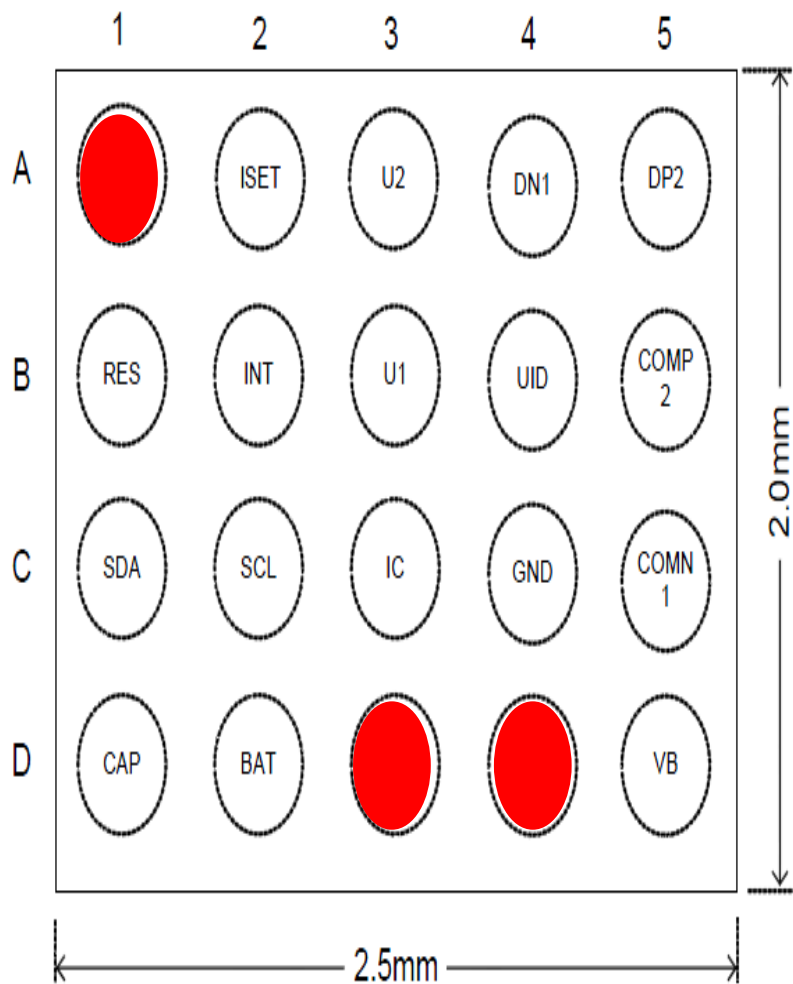
PN544(EUSY0397201)NFC

Ball A1
index area



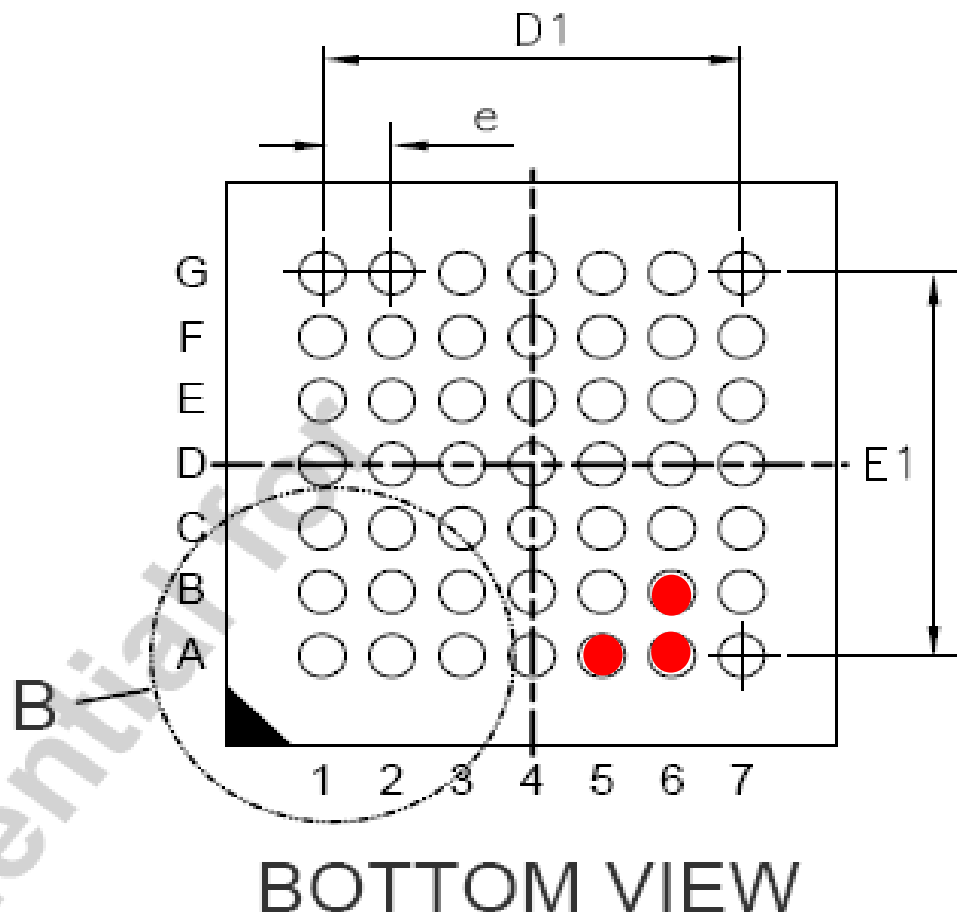
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MAX14526(EUSY0371201)MUIC



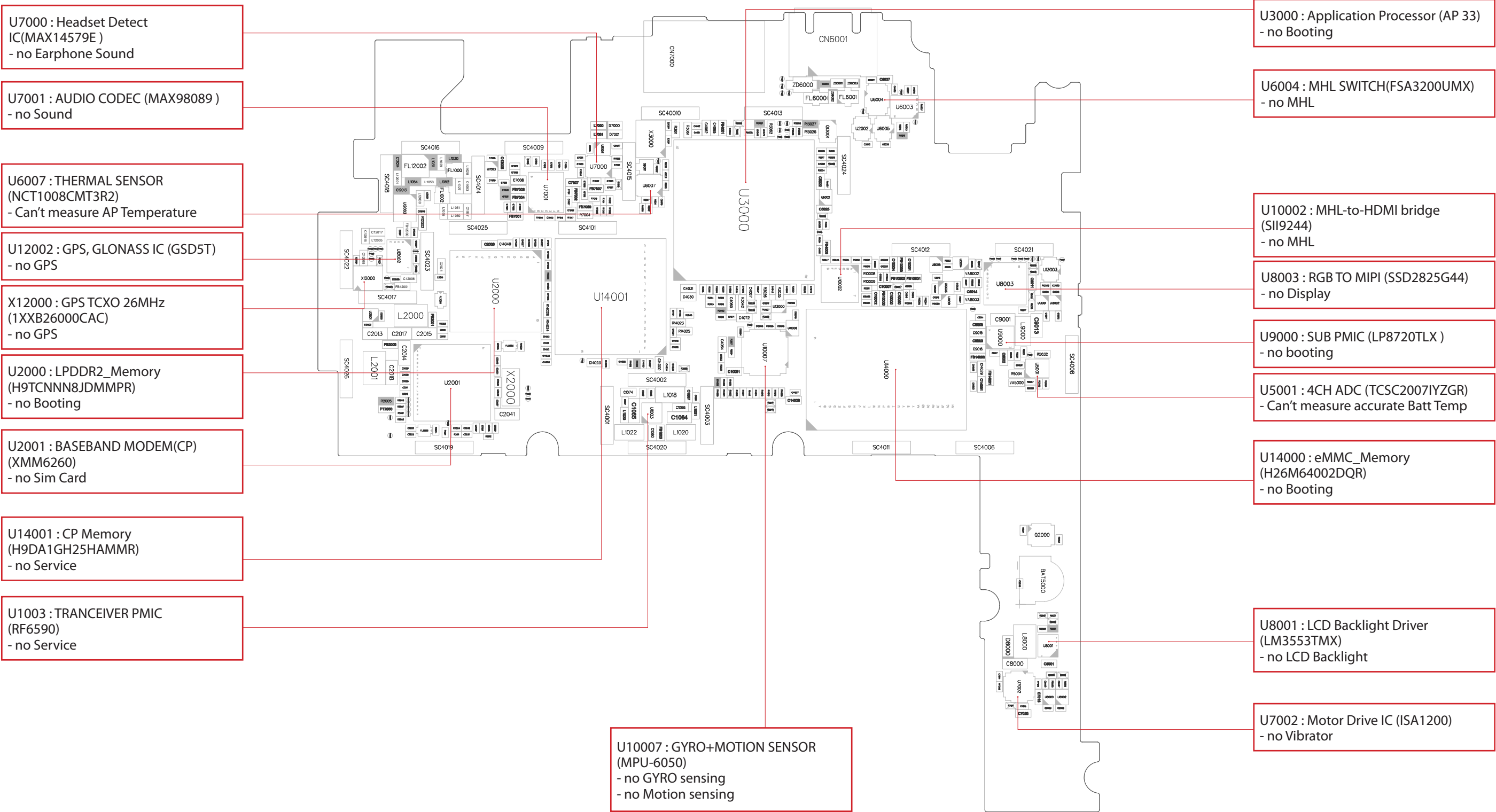
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MHL IC SiI9244 (EAN62095001)

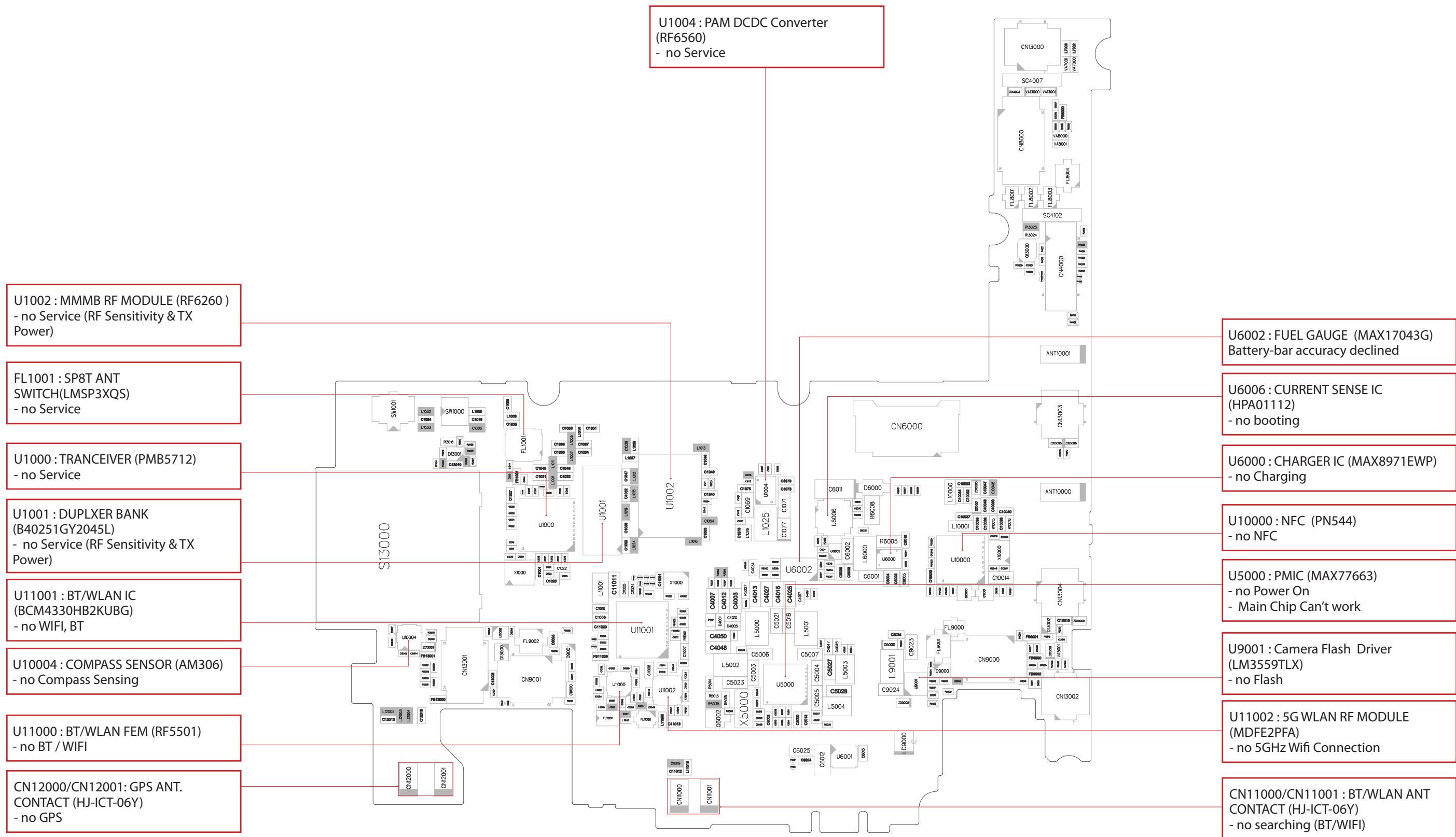


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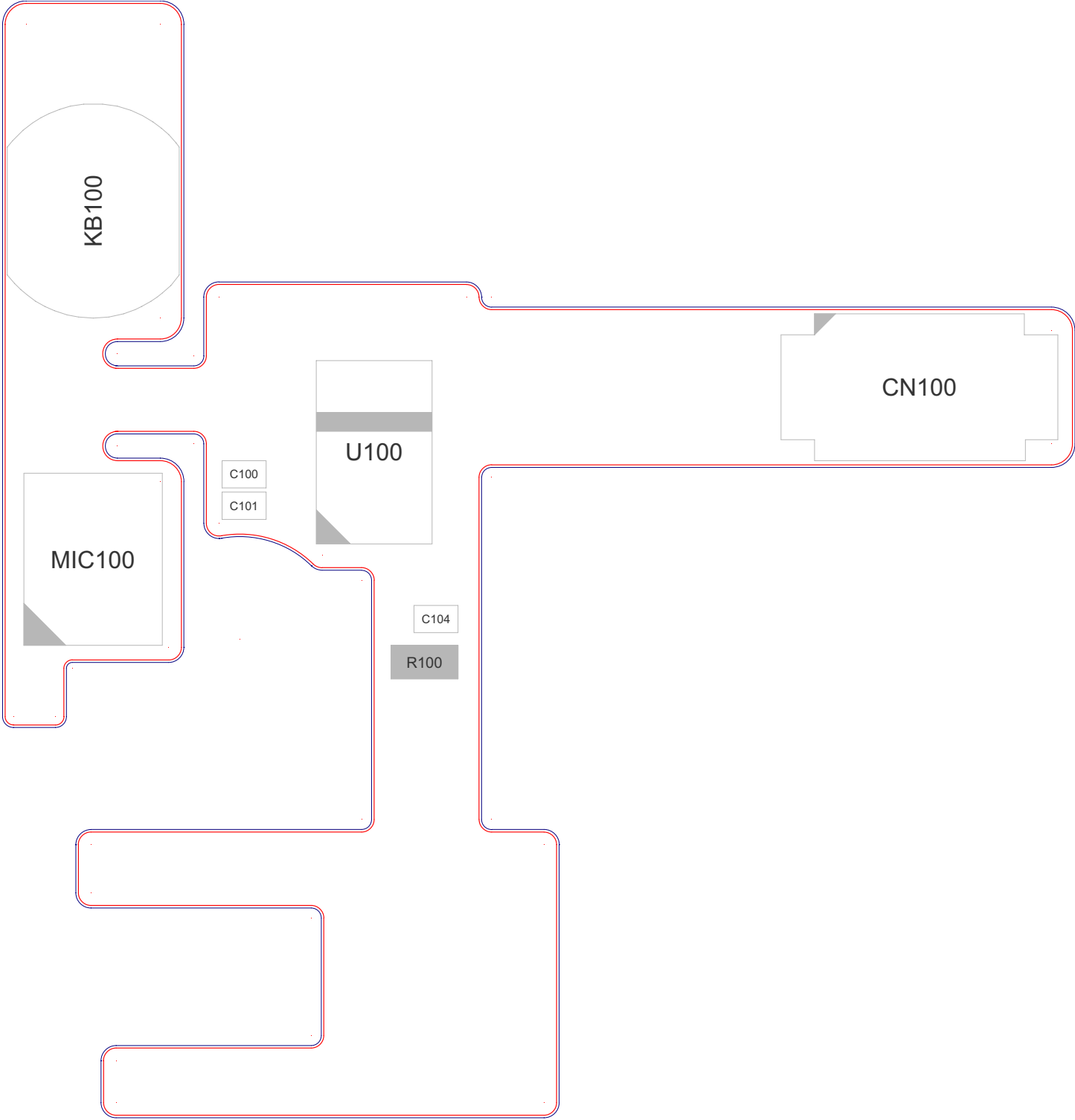
9. PCB LAYOUT



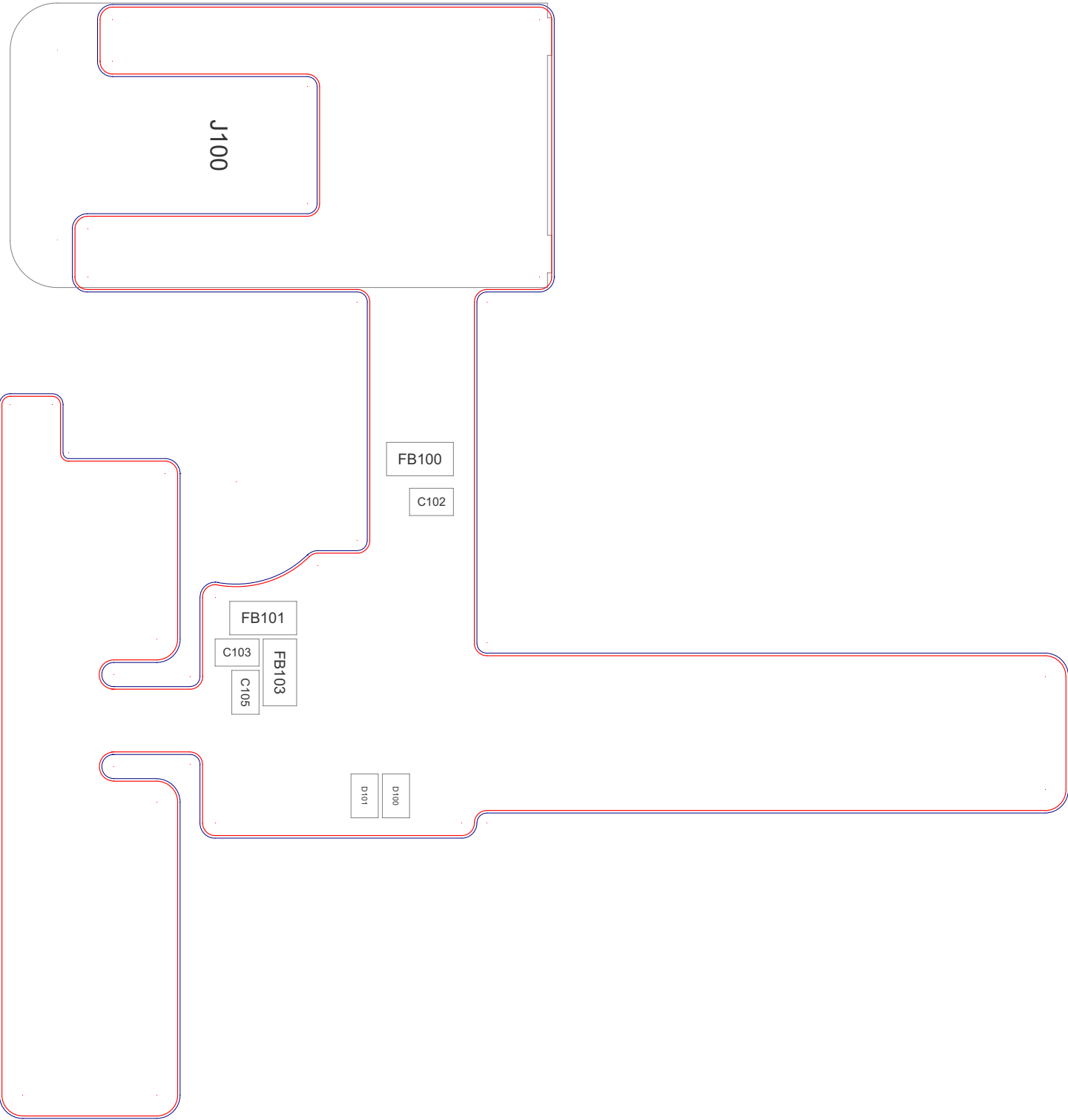
LG-P895_MAIN_EAX64912401-1.0-TOP



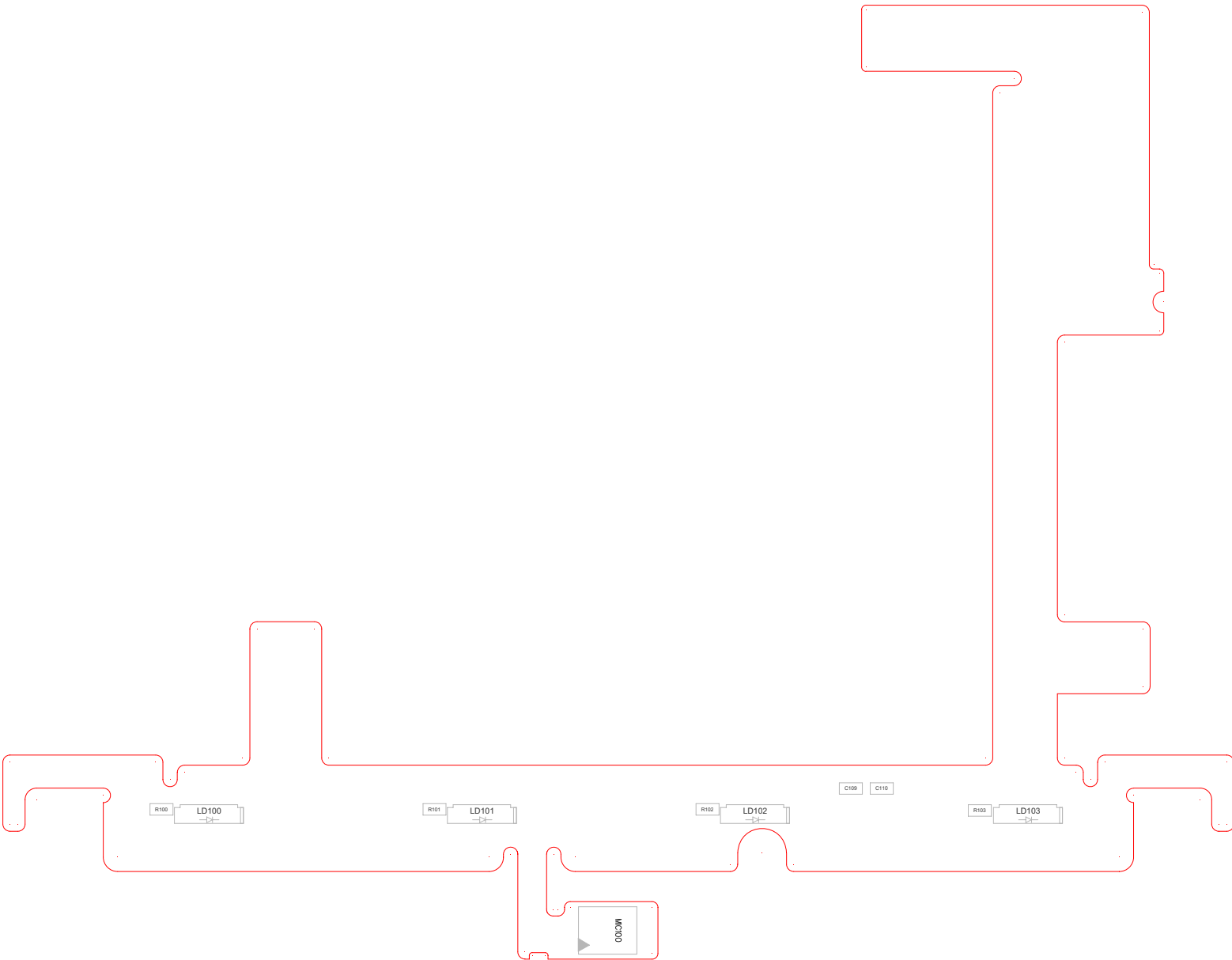
LG-P895_MAIN_EAX64912401-1.0-BOT



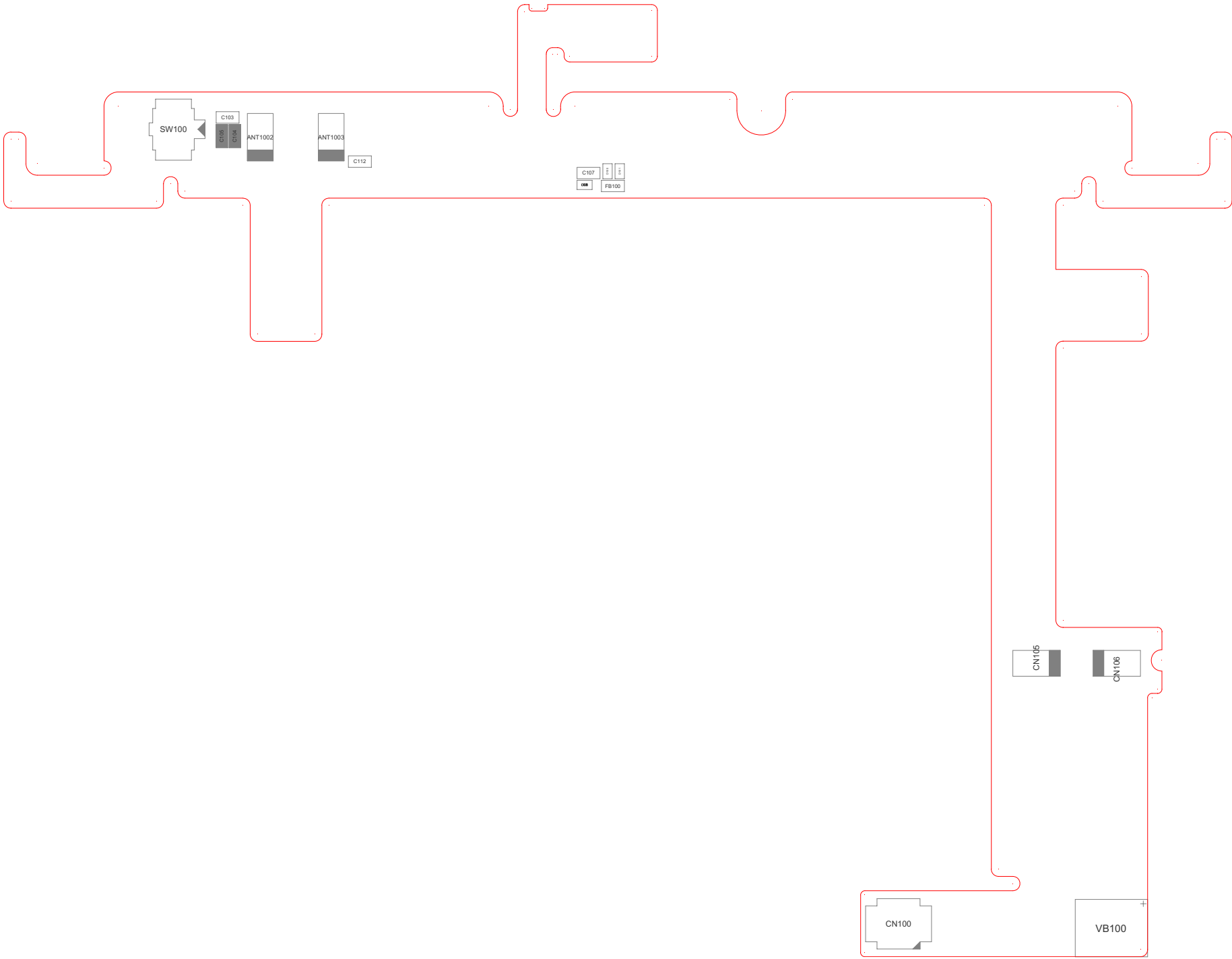
LG-P895_F_EAR_EAX65023501_1.0



LG-P895_ F_EAR_EAX65023501_1.0



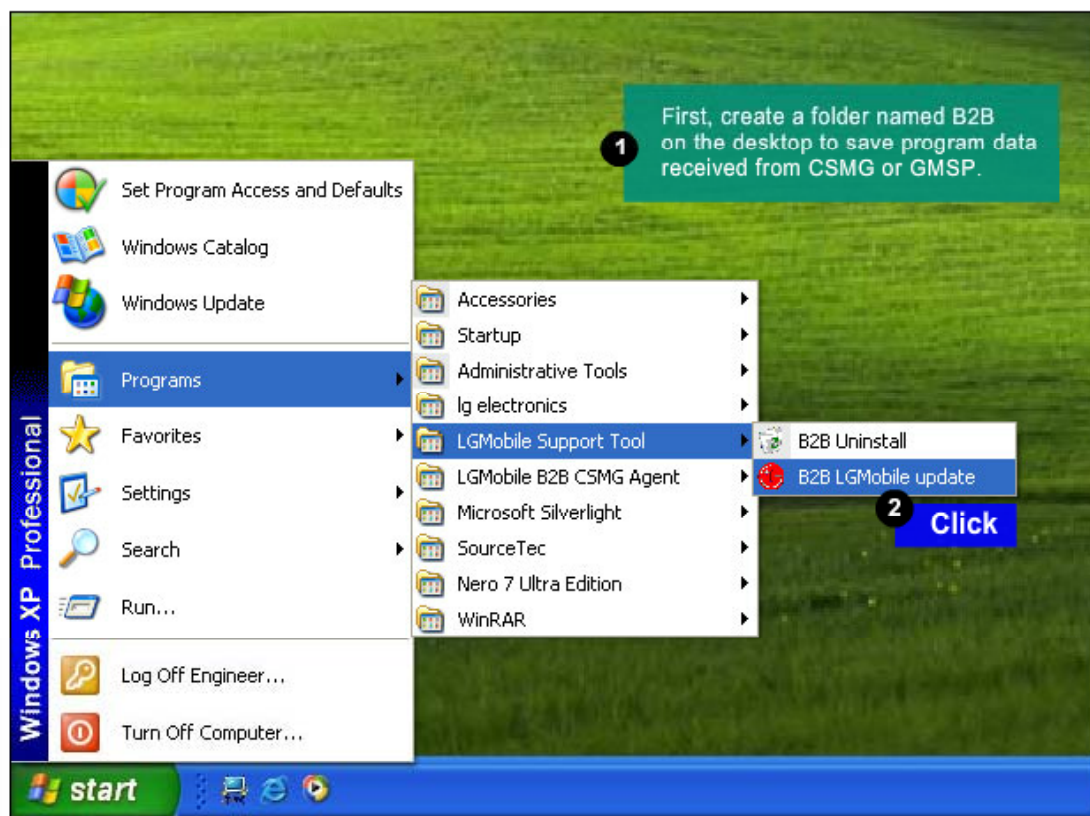
LG-P895_F_LED_EAX64881201_1.0_TOP

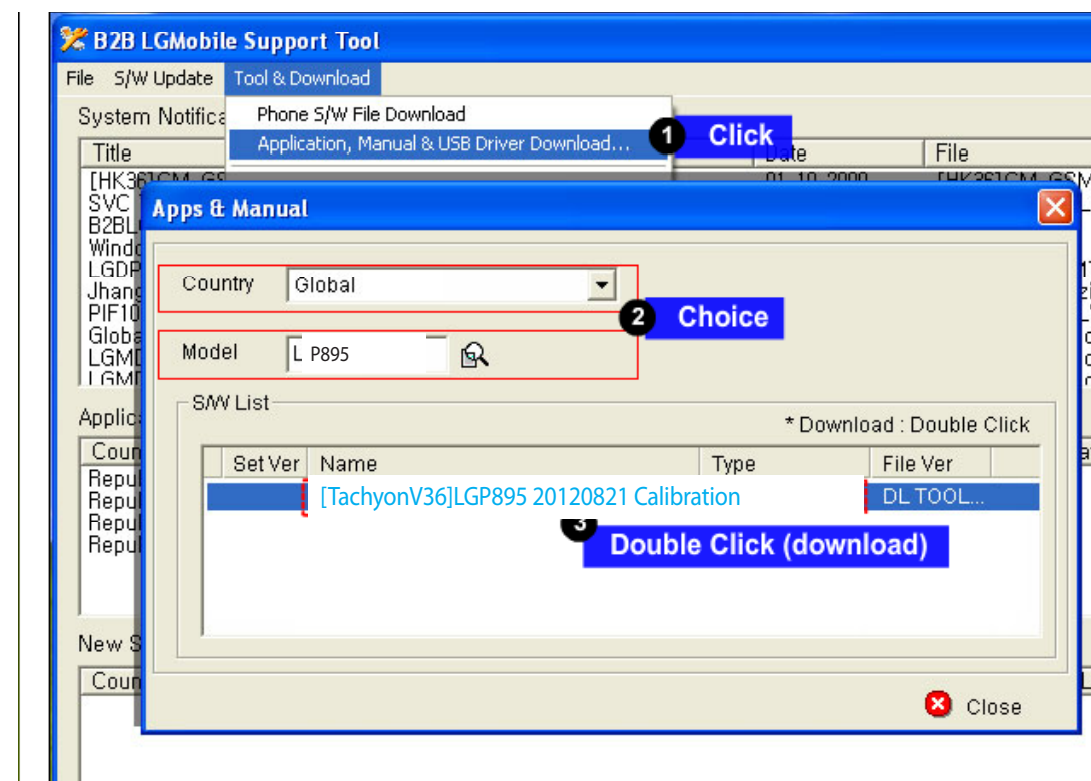
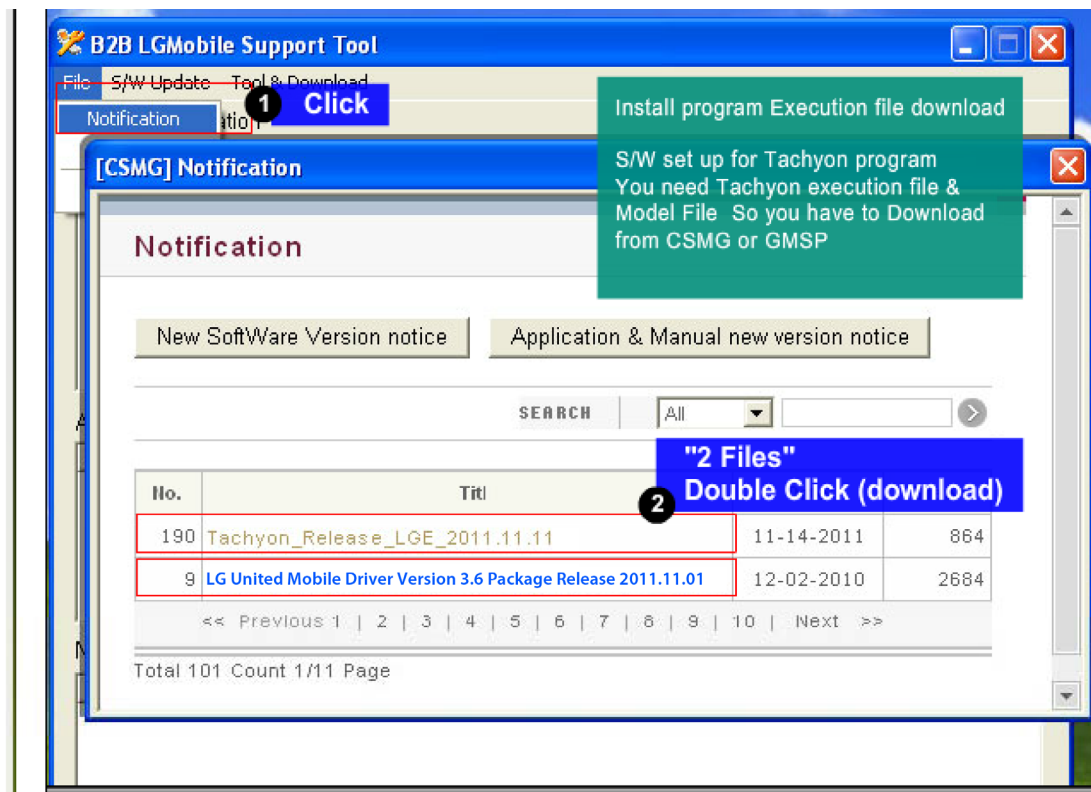


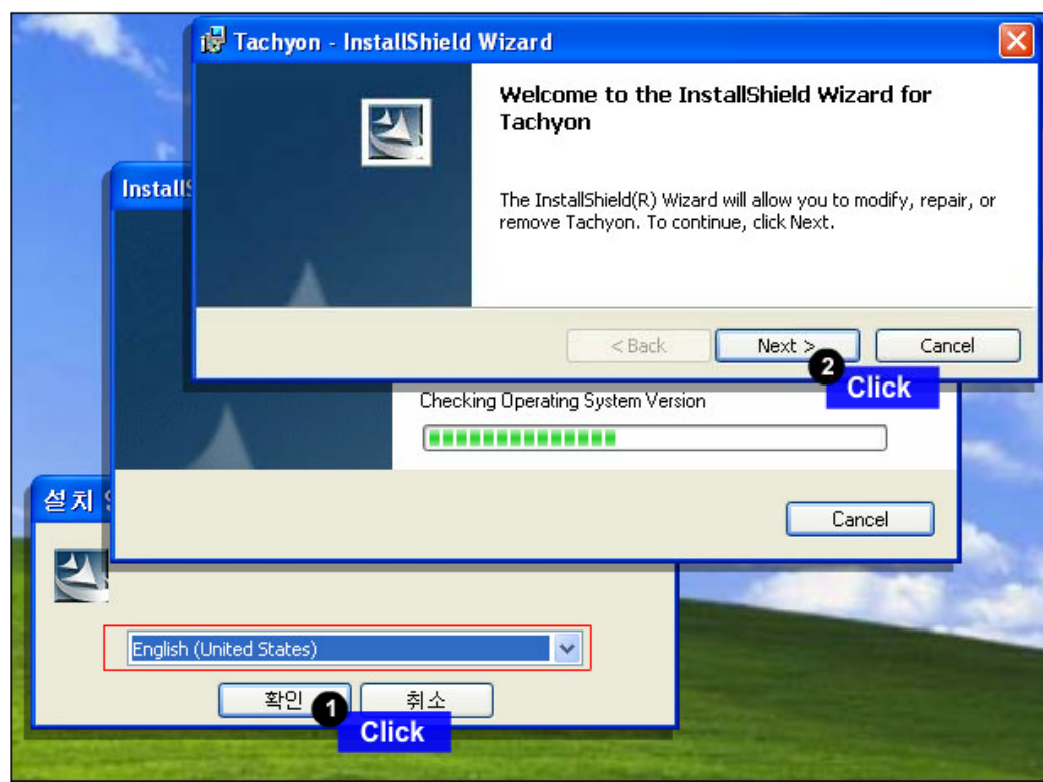
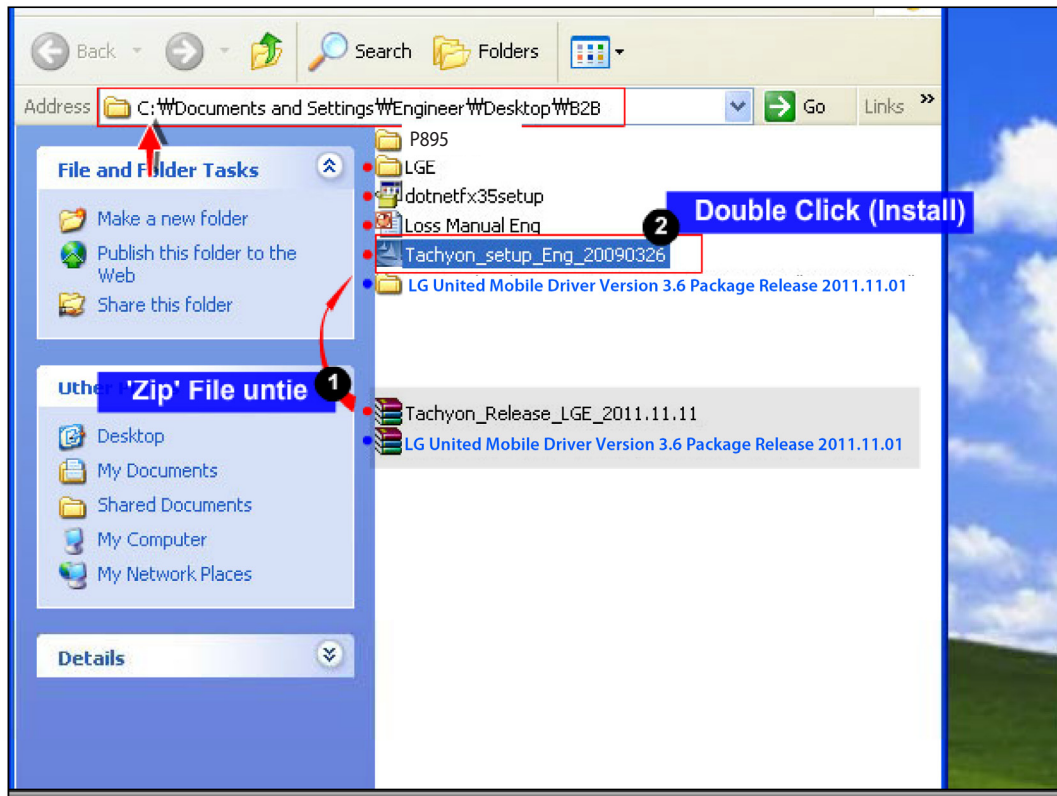
LG-P895__F_LED_EAX64881201-1.0-BOT

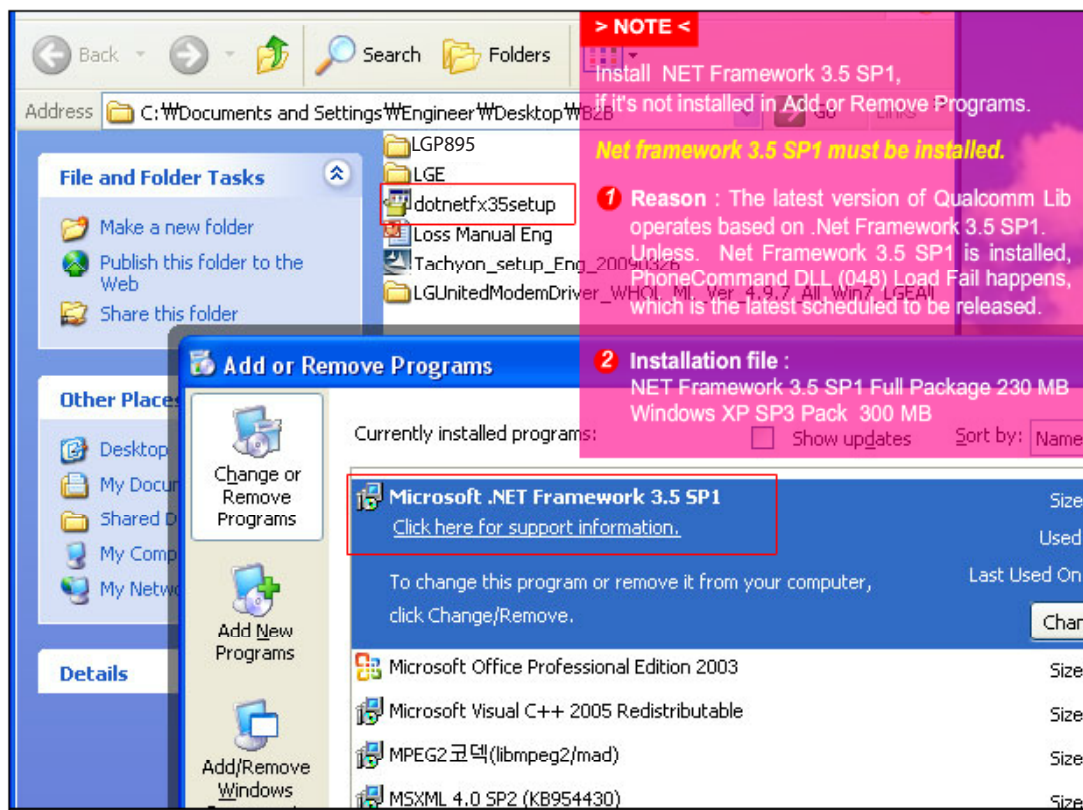
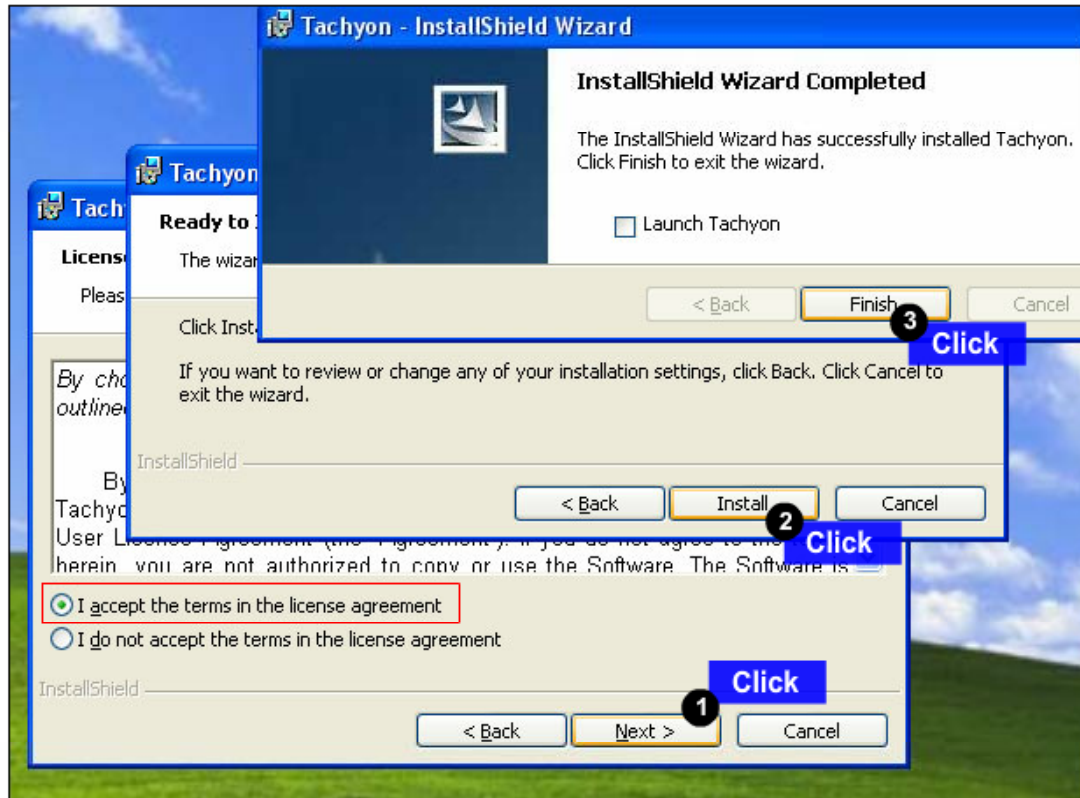
10. CALIBRATION

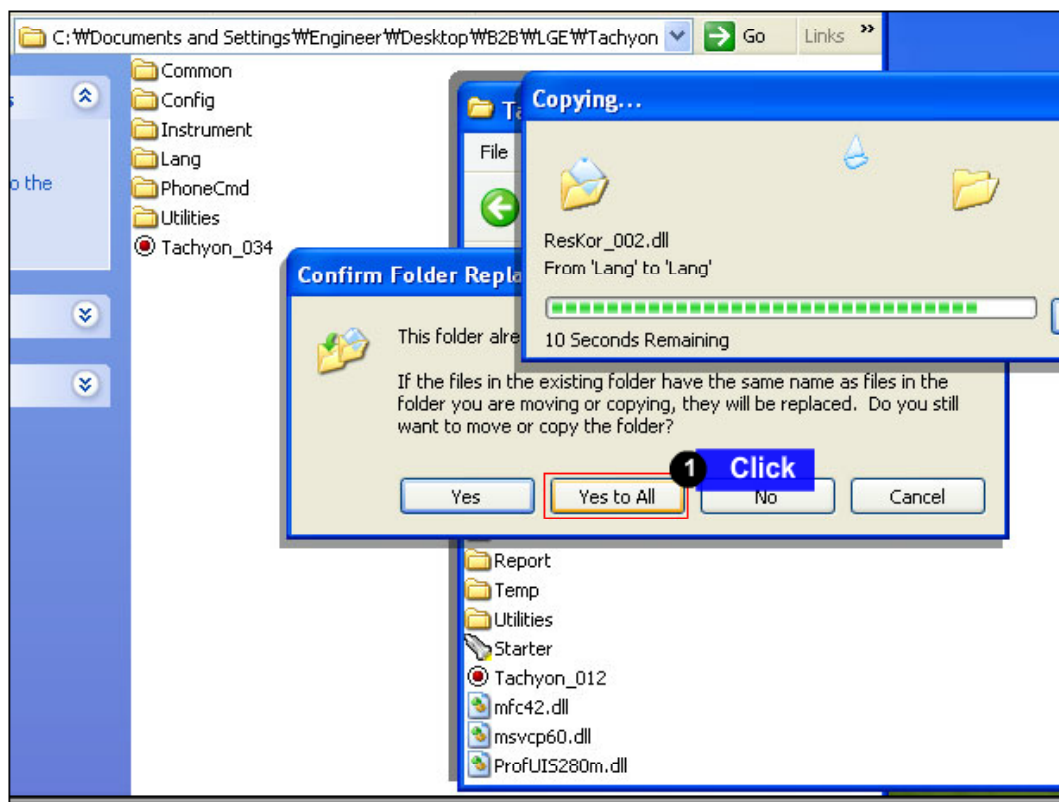
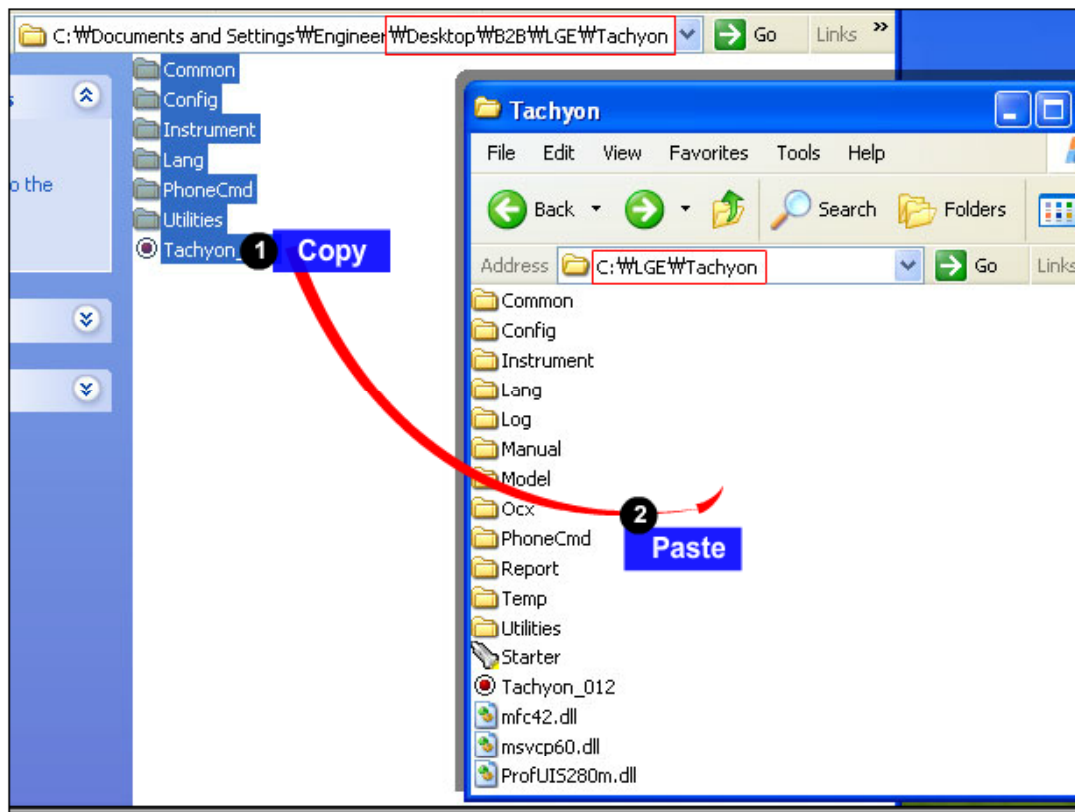
CAL INFORMATION		
S/W VERSION		
[TachyonV36]LGP895 20120821 Calibration		
Please Check the Version to "B2B"		
H/W		
	Name	Part No.
PIF	PIF200(All Type)	BJAY0024021
USB Cable	USB Cable	RAD32247898
Power Cable	DC Power Cable	RAD32247878
I/O Cable	5P E-SATA_DC_Plug	RAD32167861
RF Cable_Main	MS-156C	BJAY0024004
Power Supply_PIF	Power Supply 5.3V	
Power Supply_Phone	Power Supply 5.0V	
RF Test Equipment	E5515C(8960)	
NOTICE	1. Use the Battery	
CMW500 RF Cable connection	Reference to Attached image	

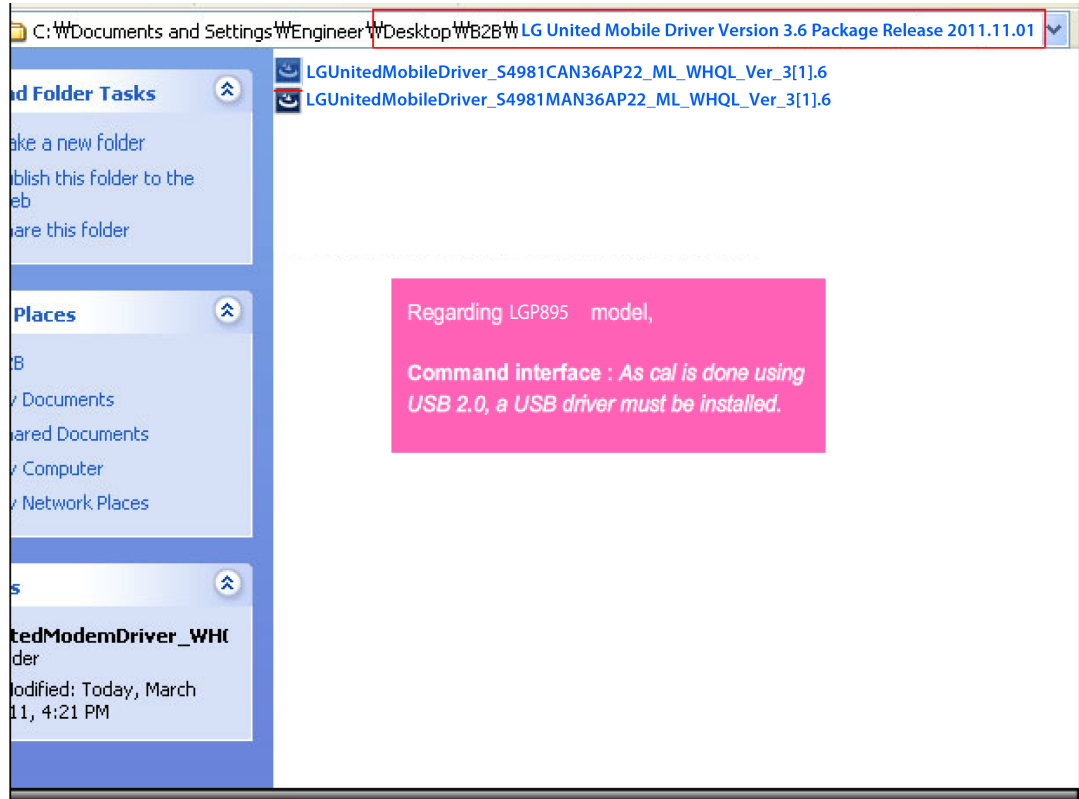


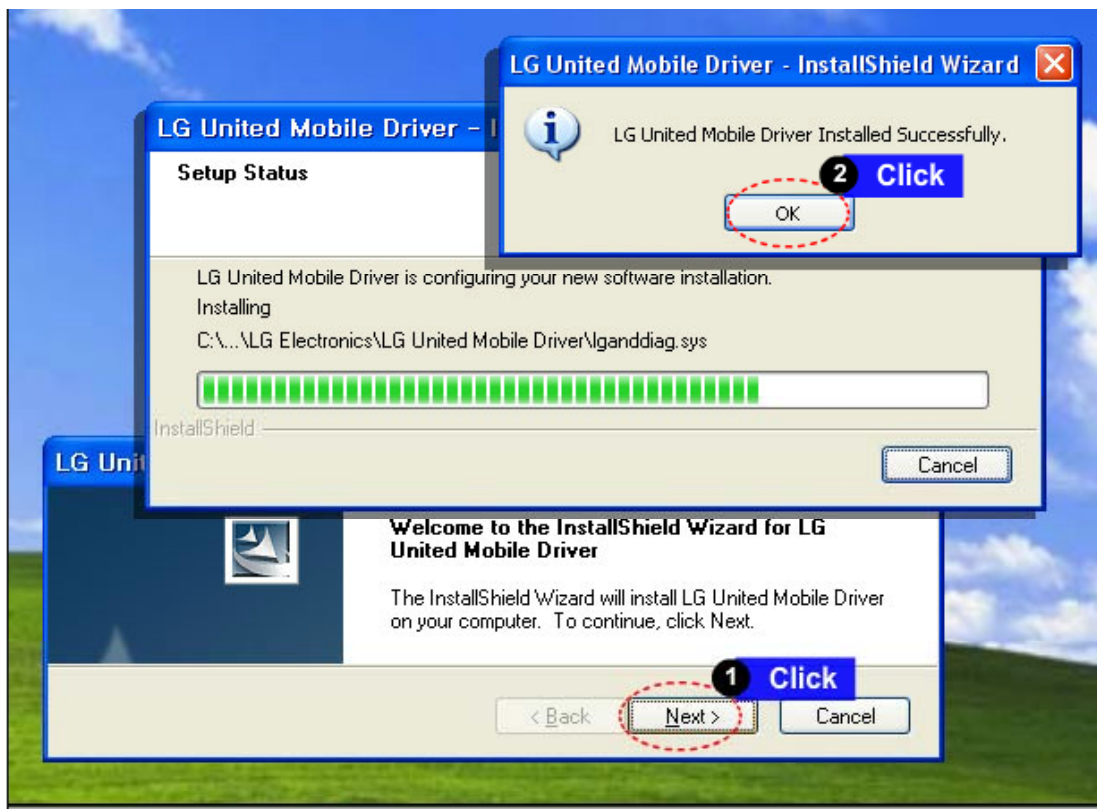
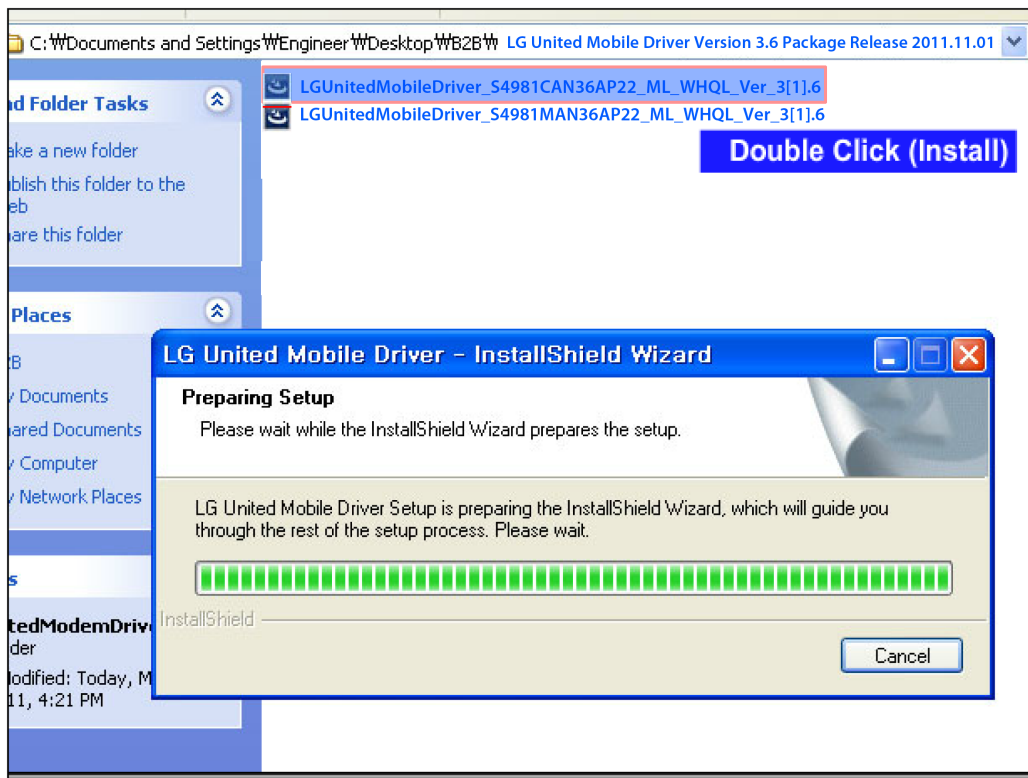


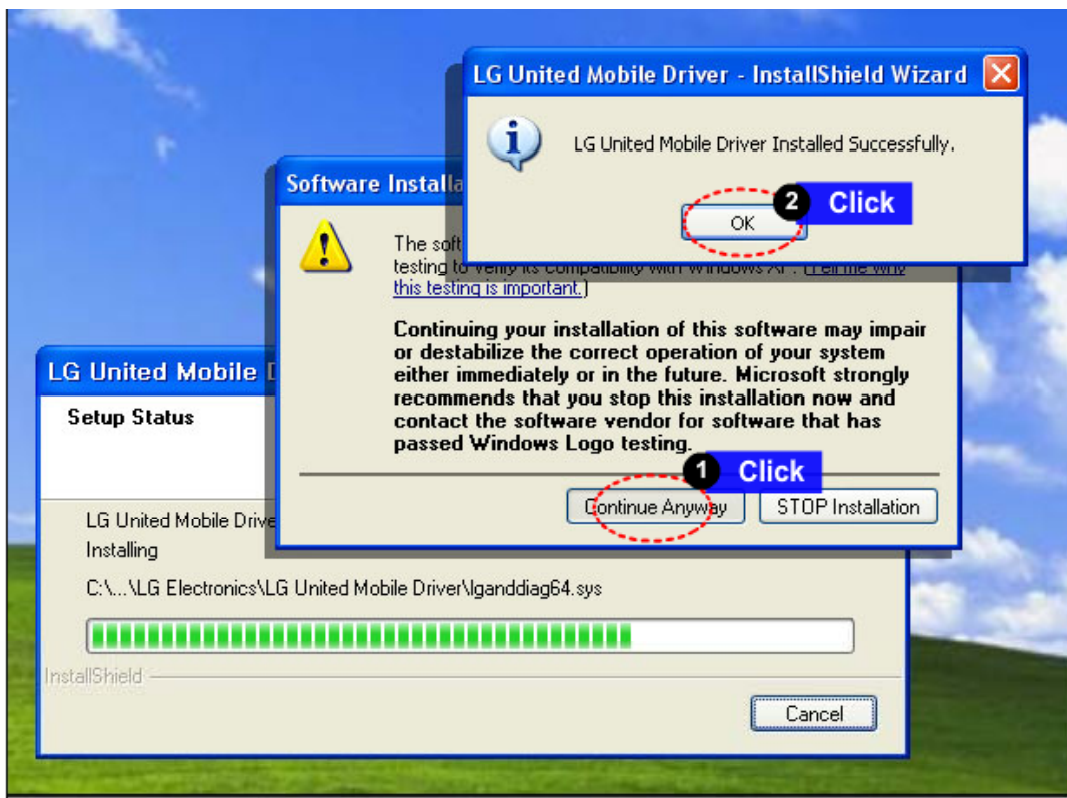
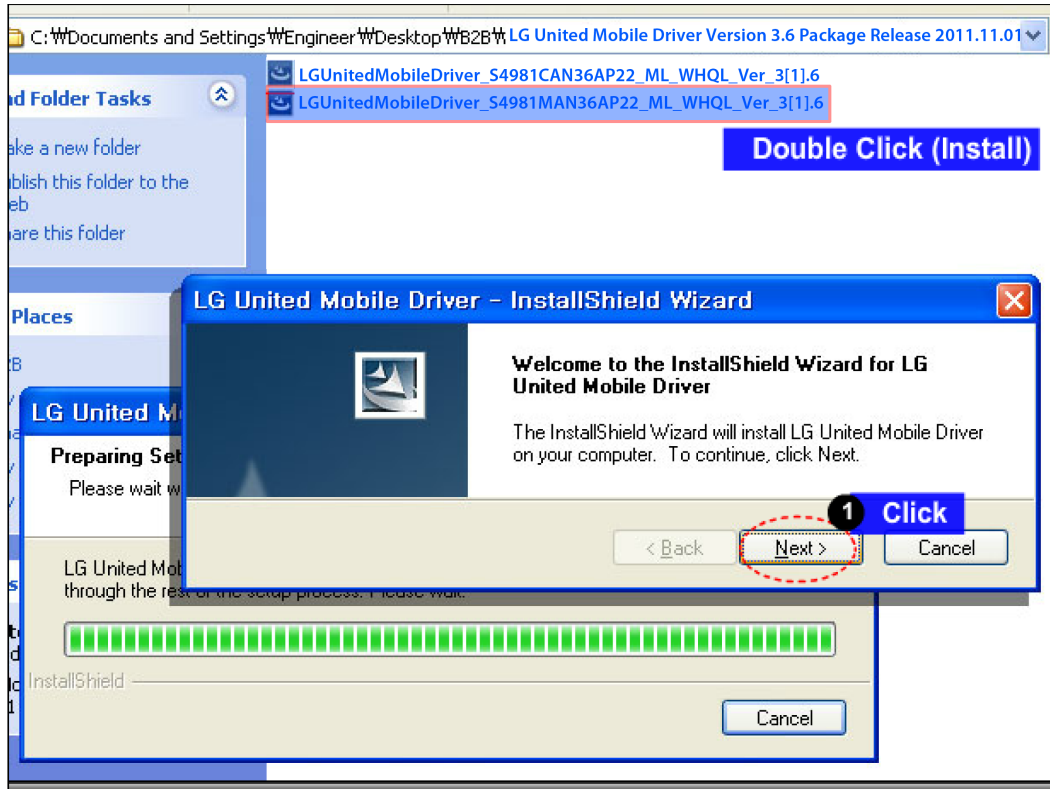


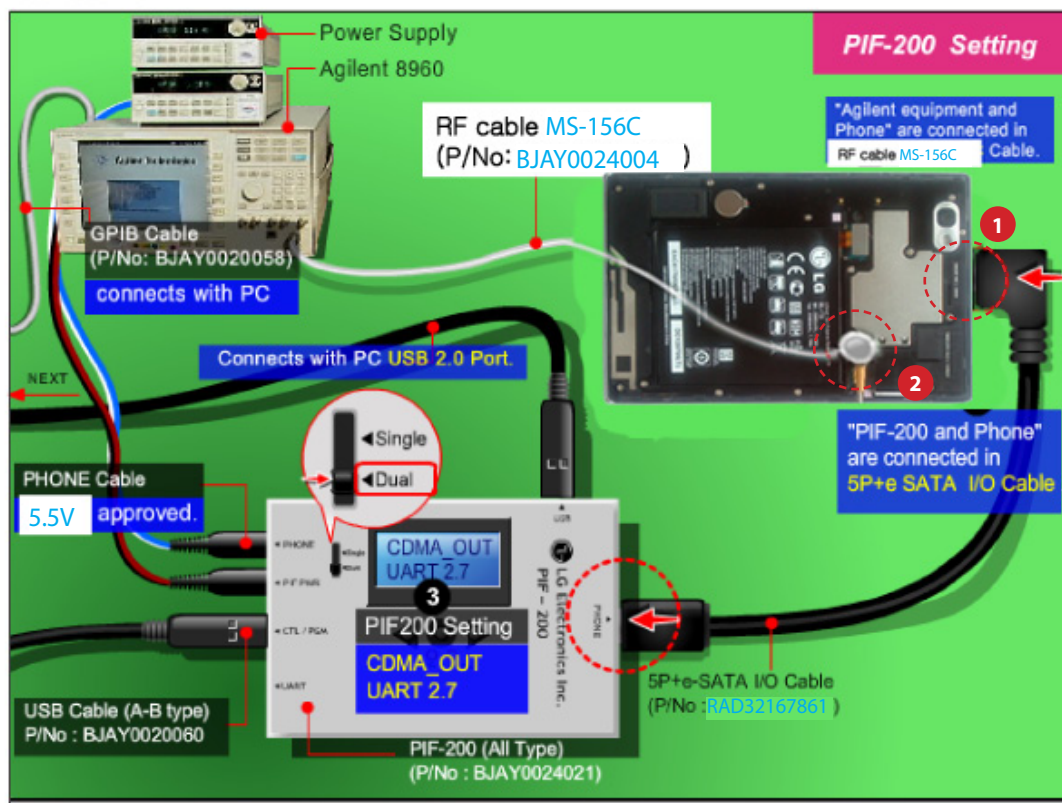
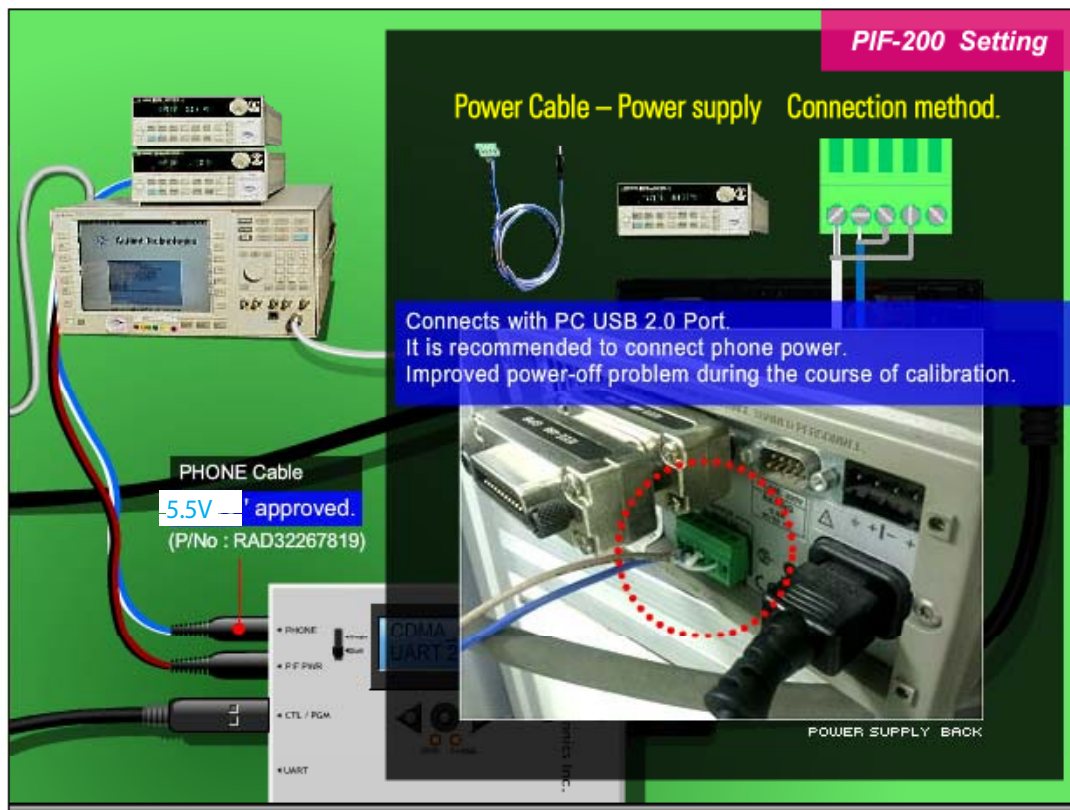


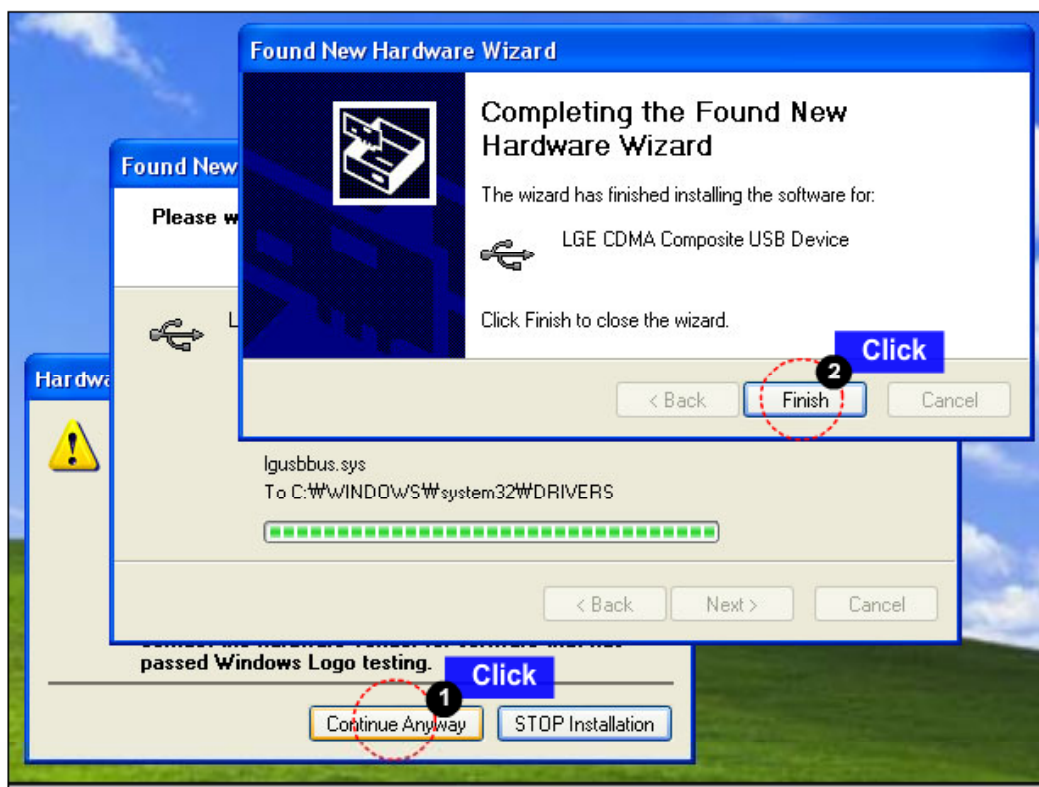
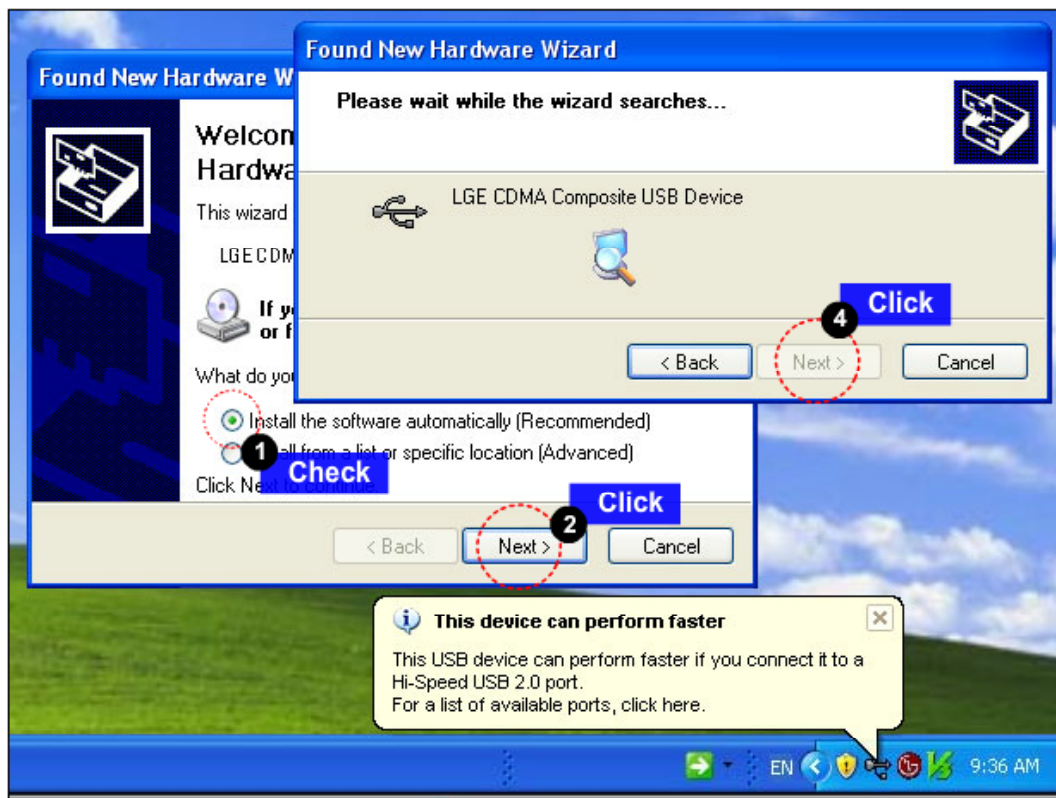


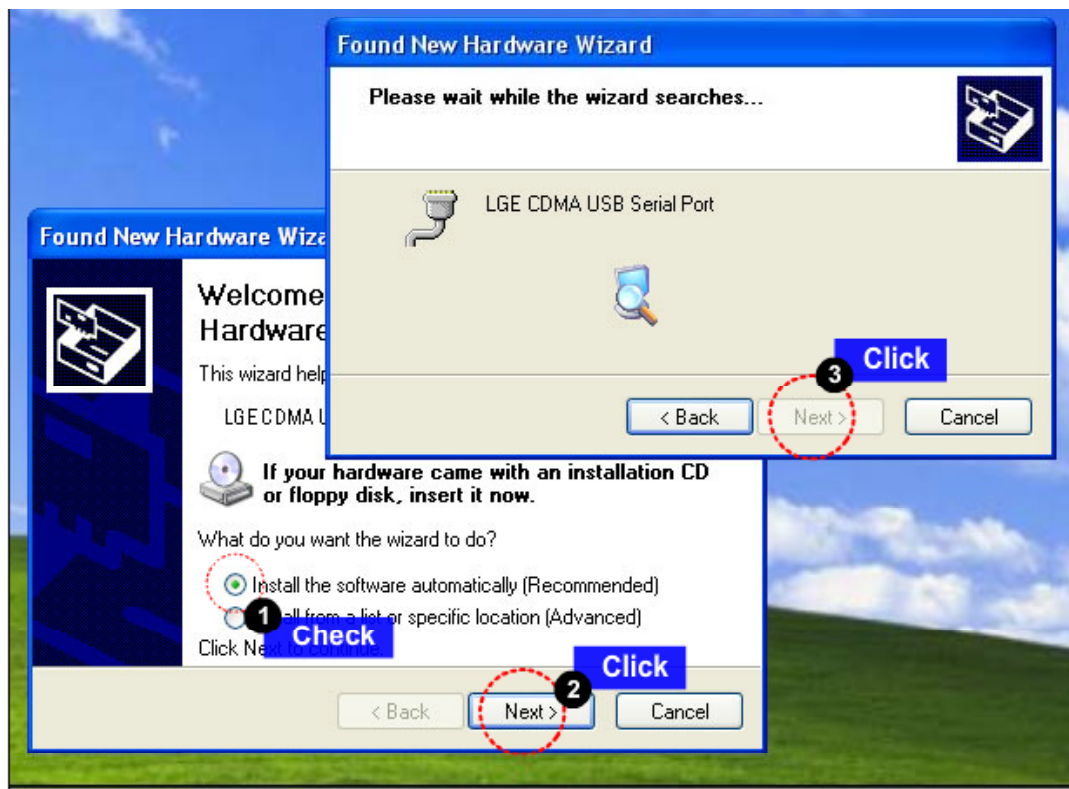
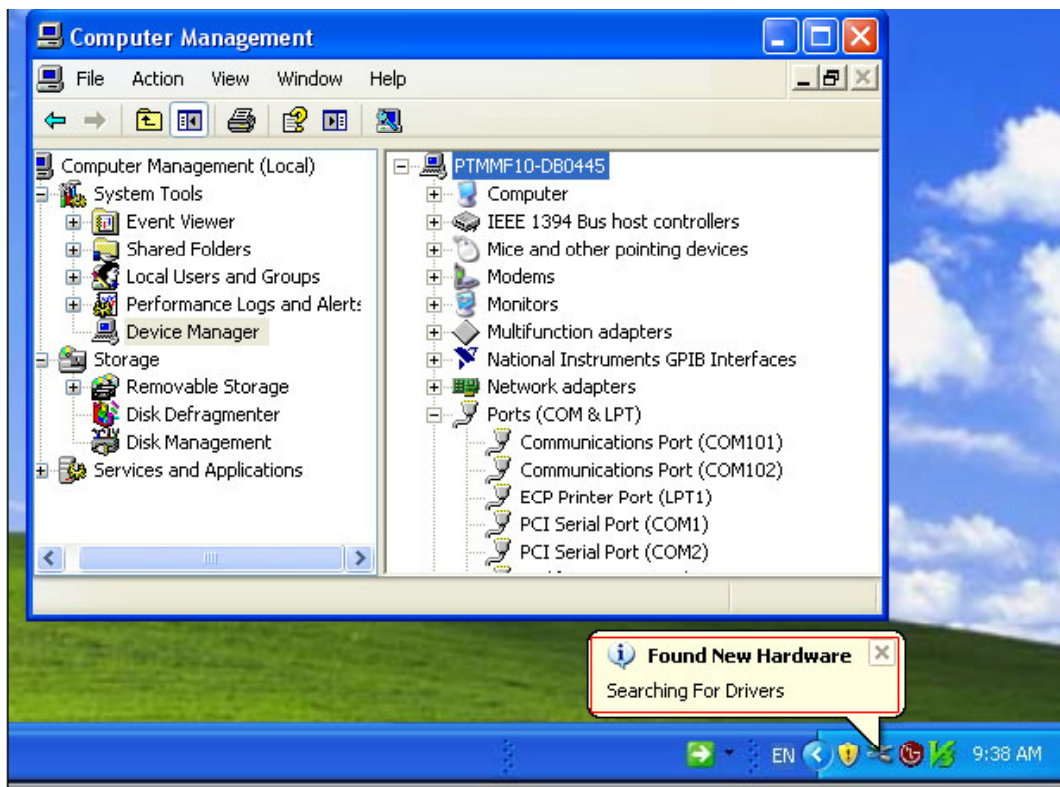


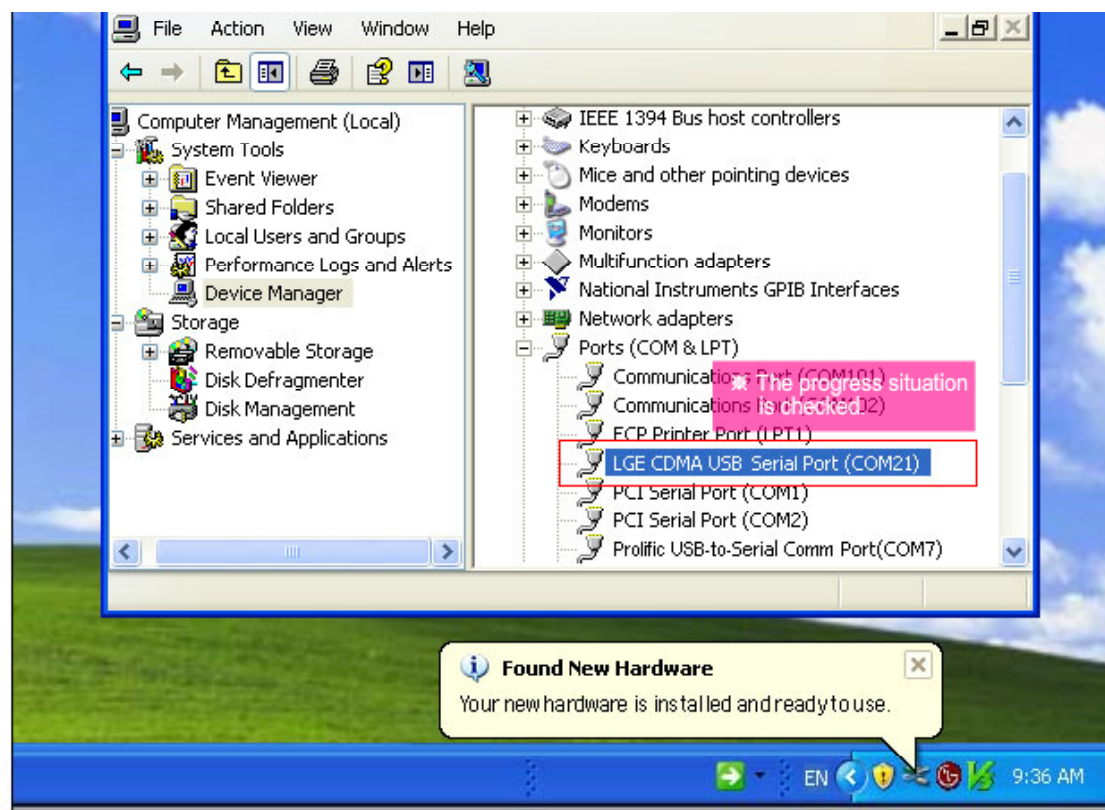
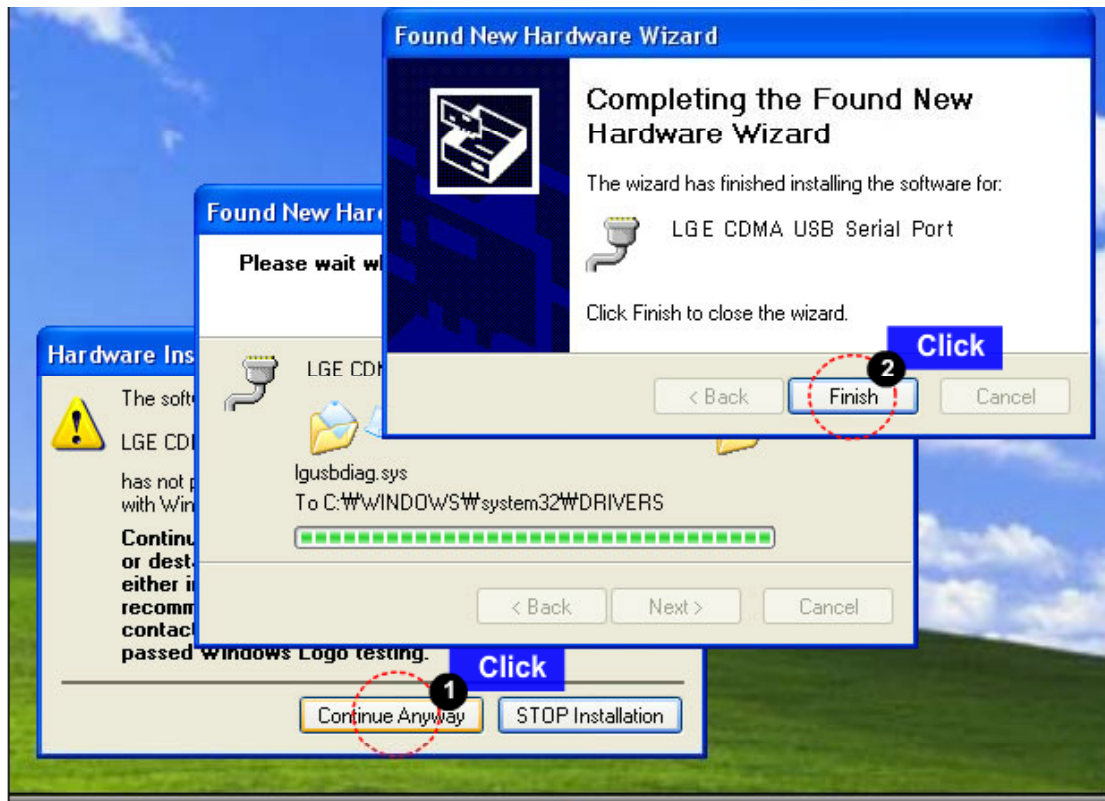




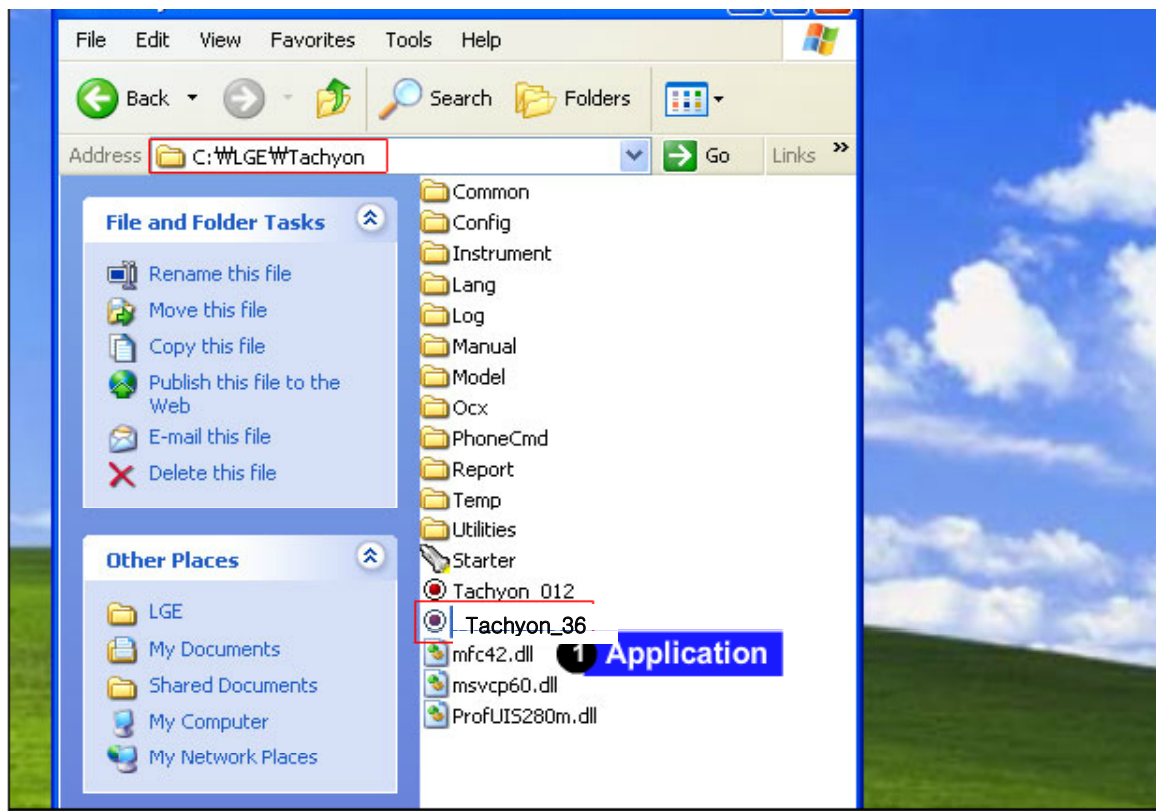
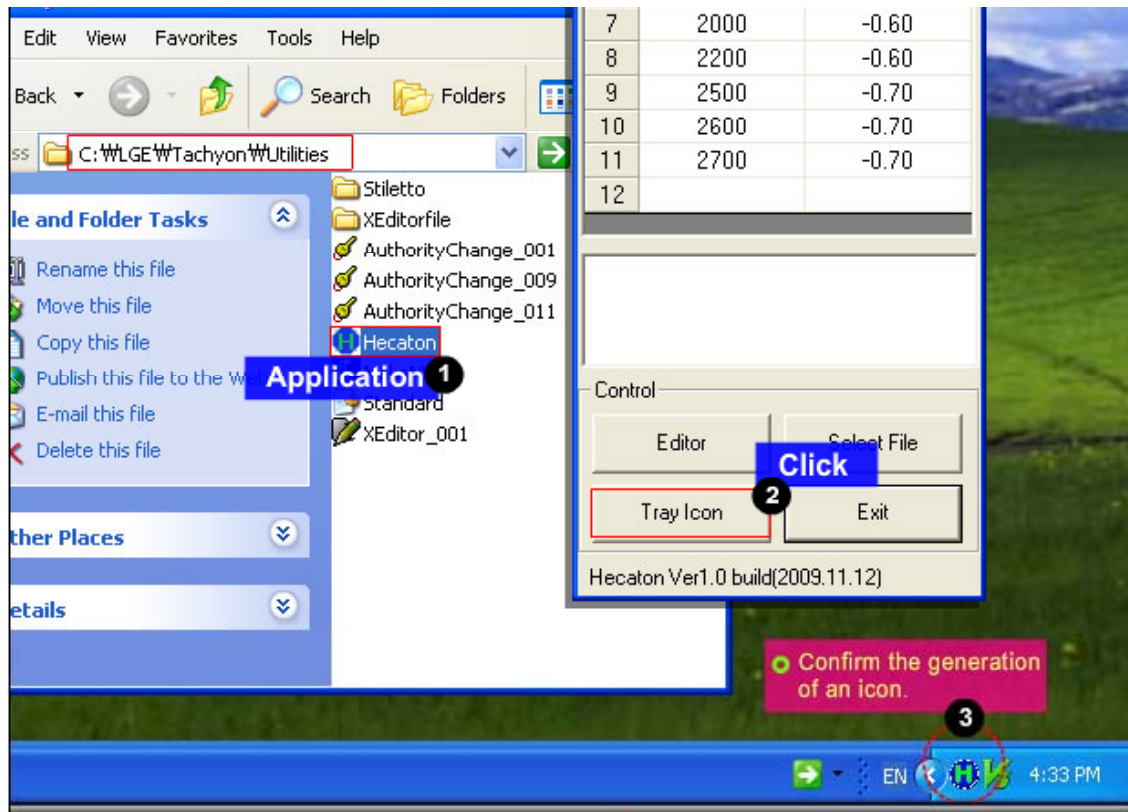


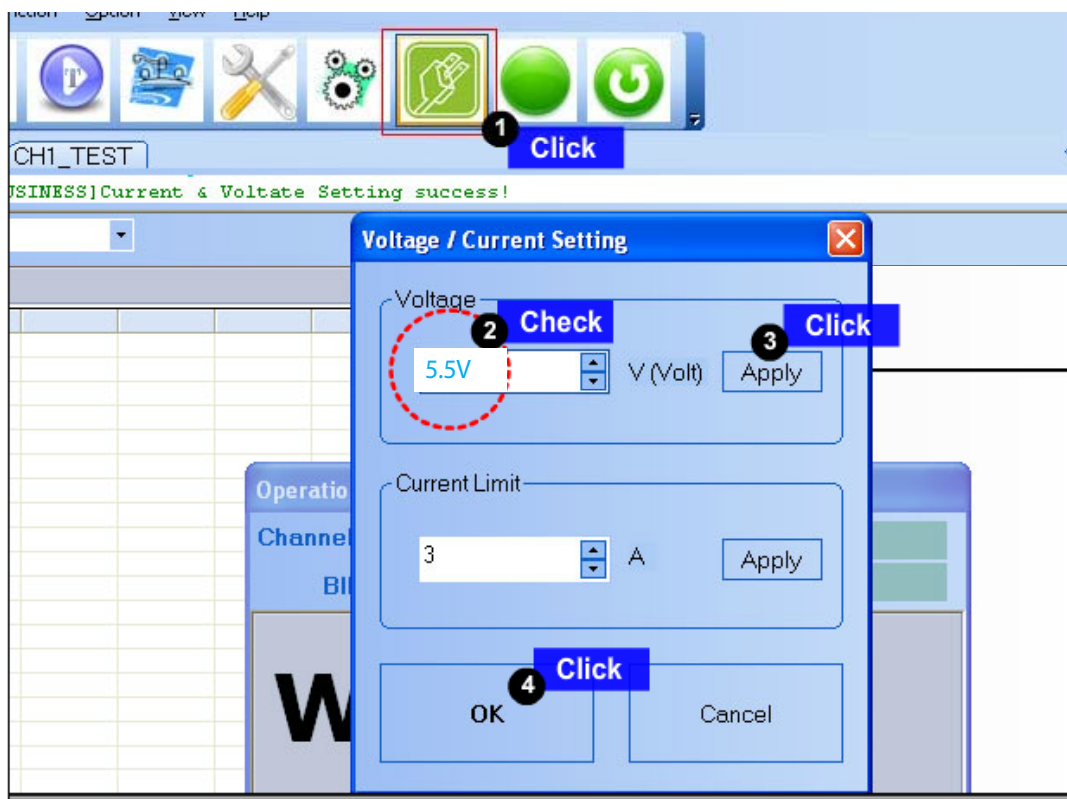
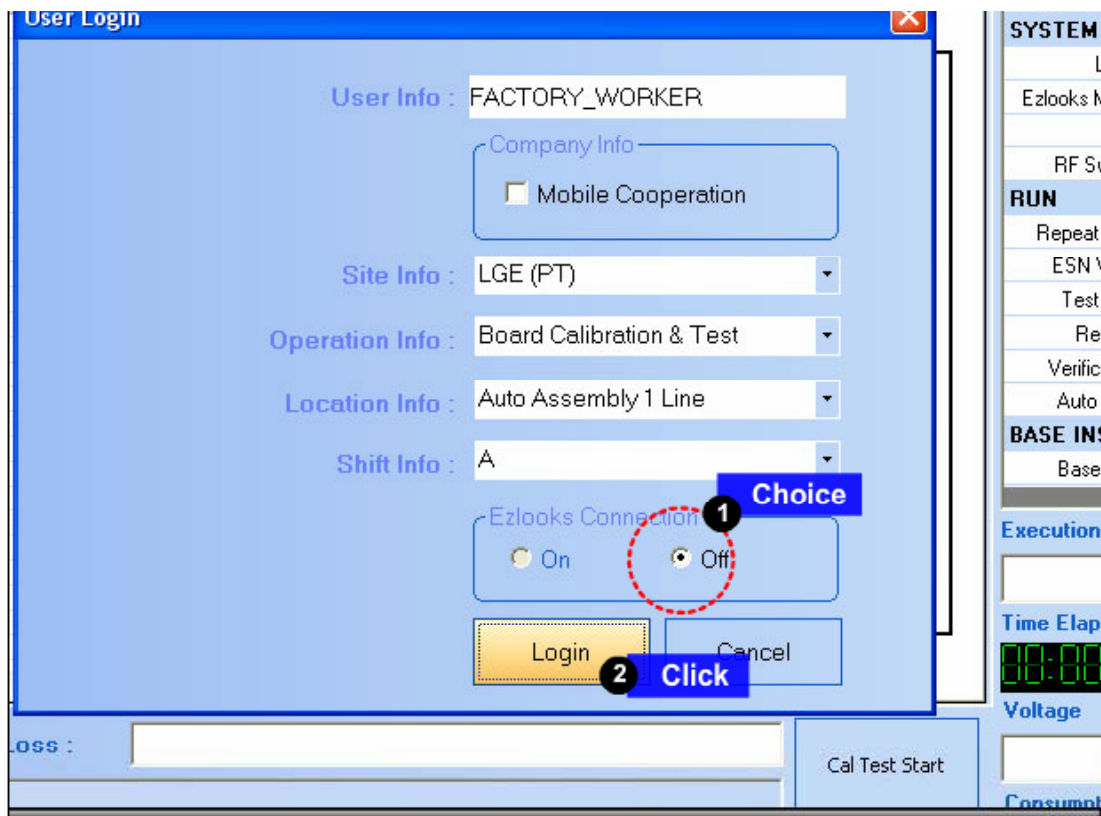




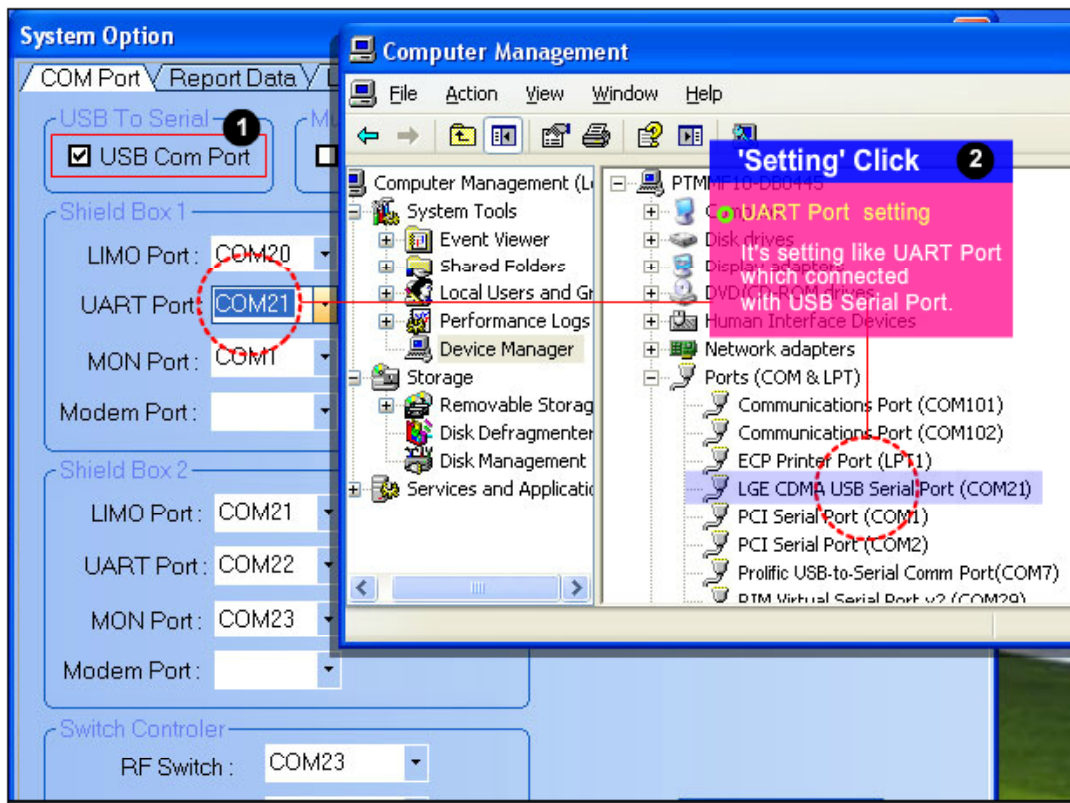
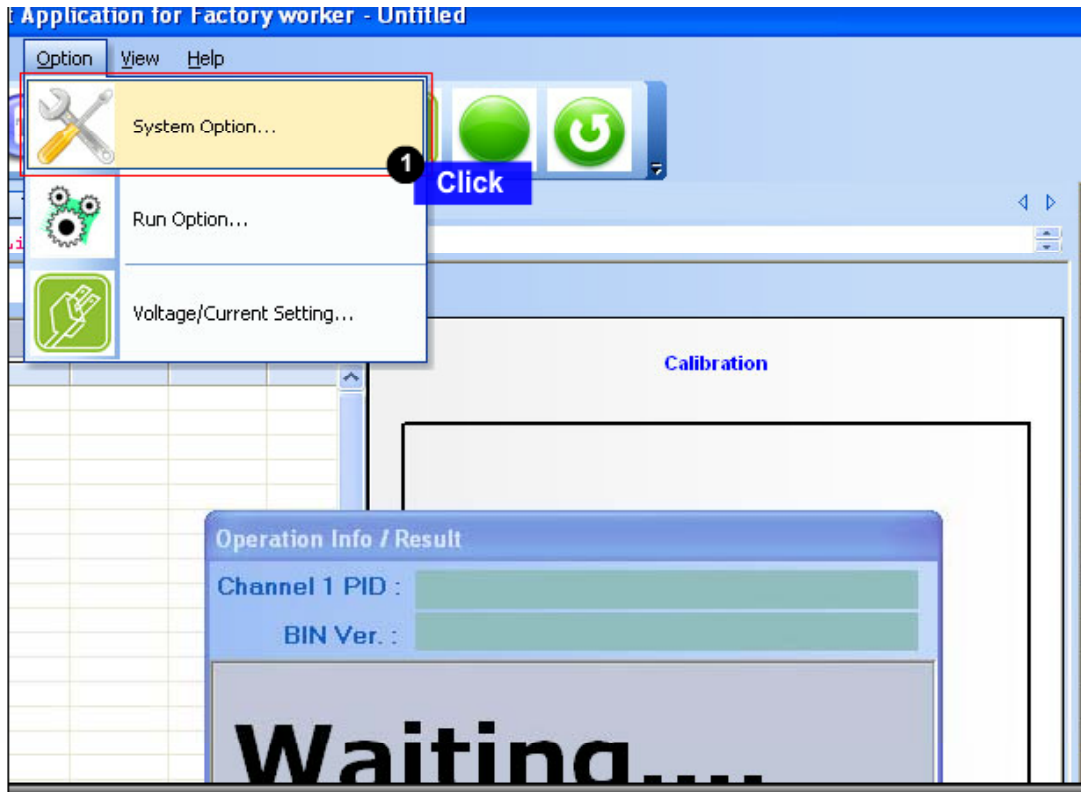


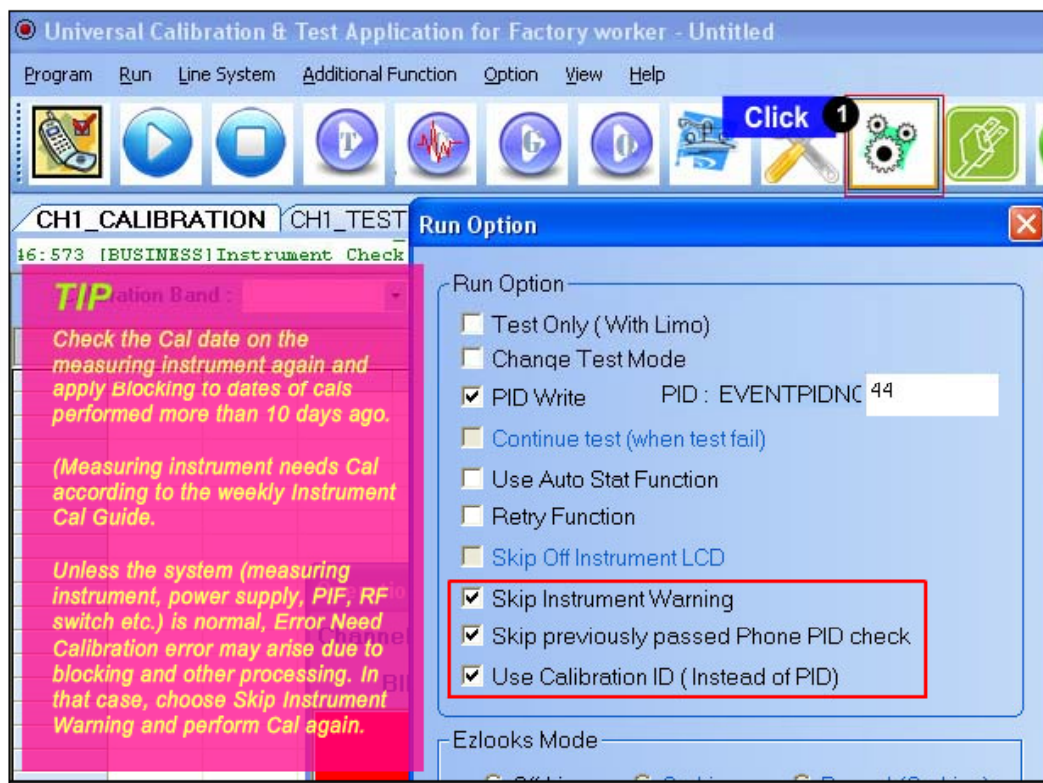
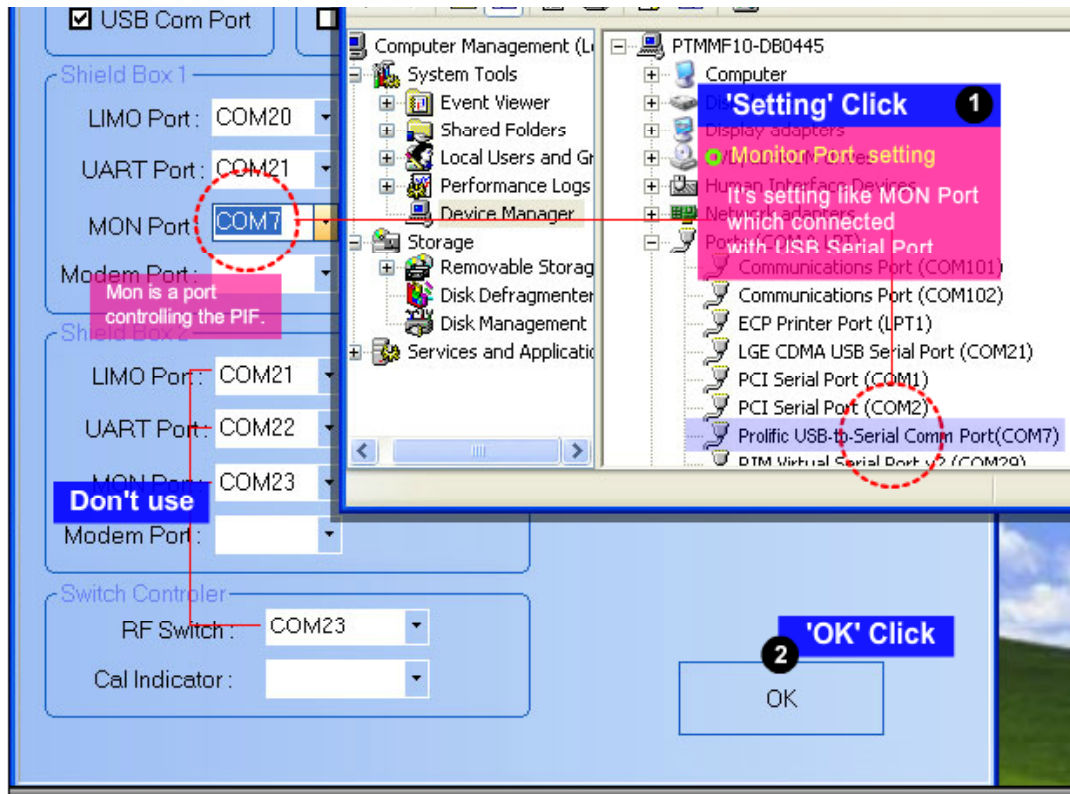
10. CALIBRATION



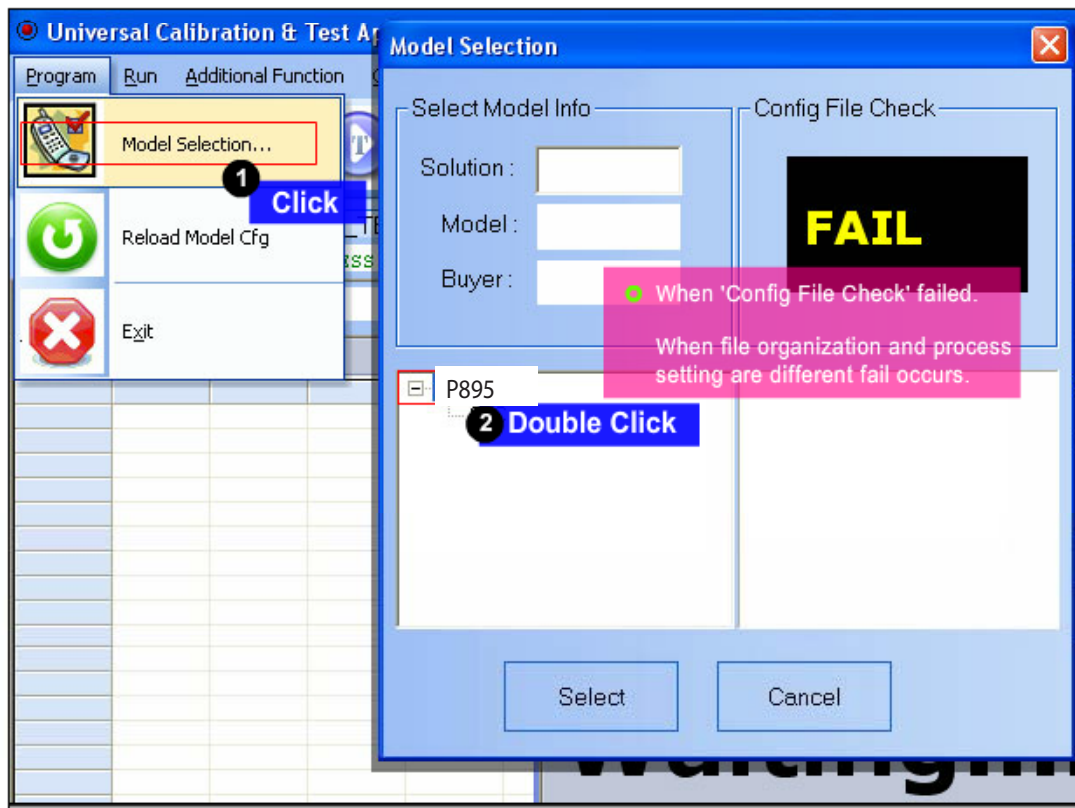
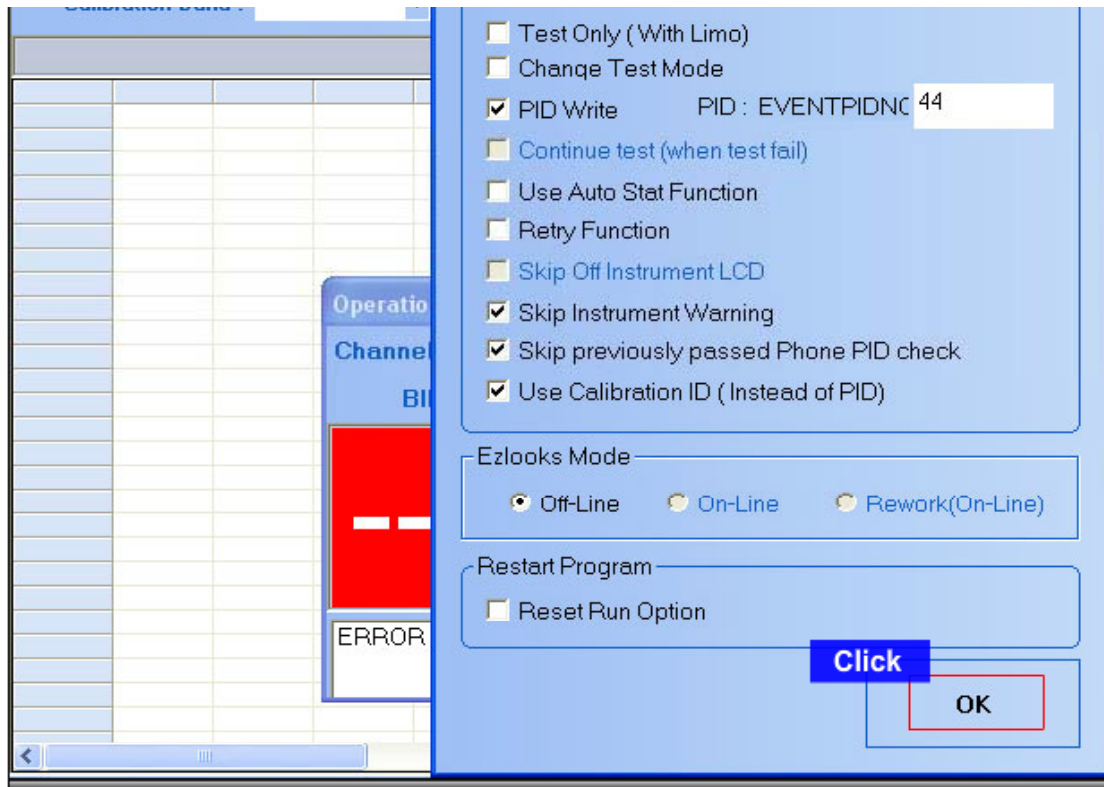


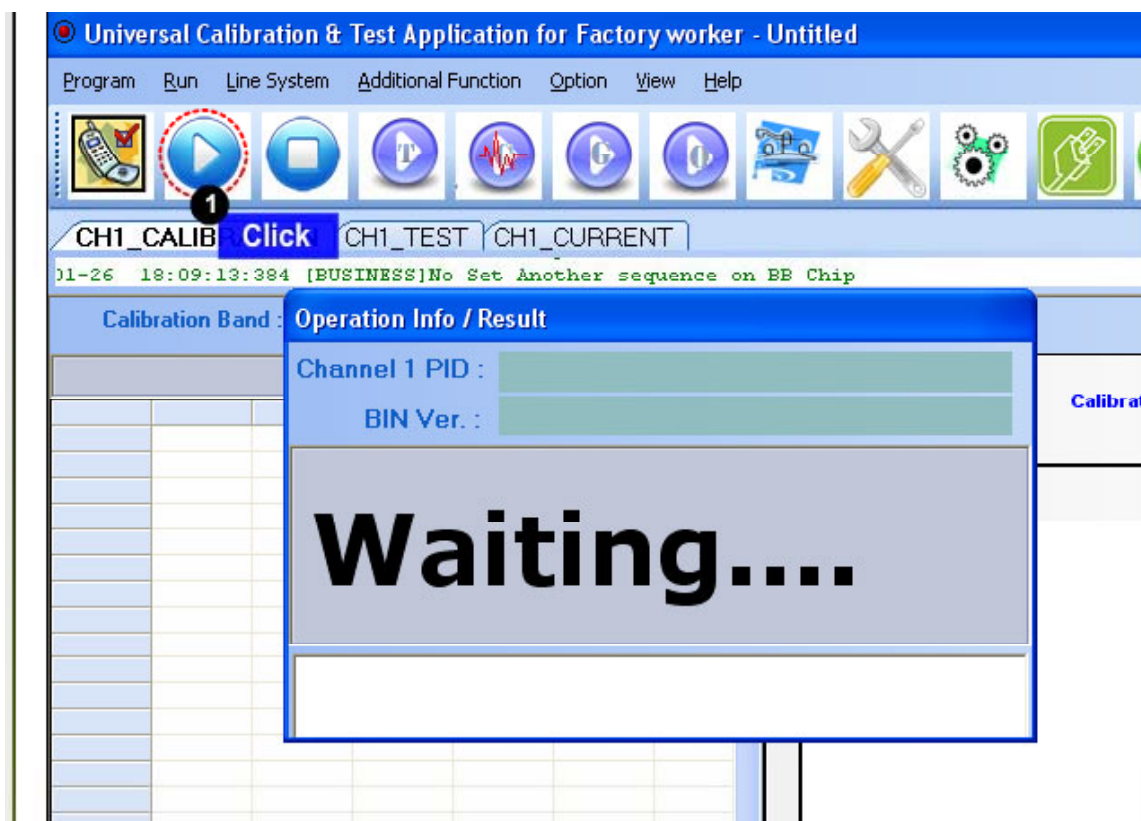
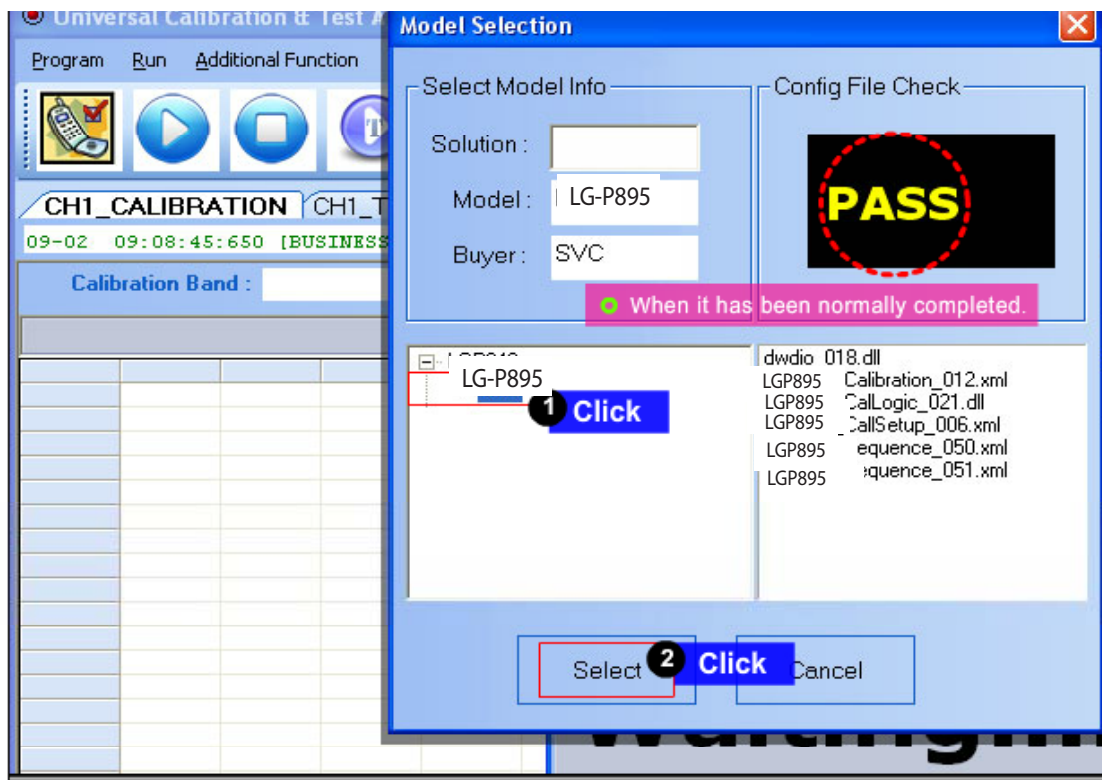
10. CALIBRATION

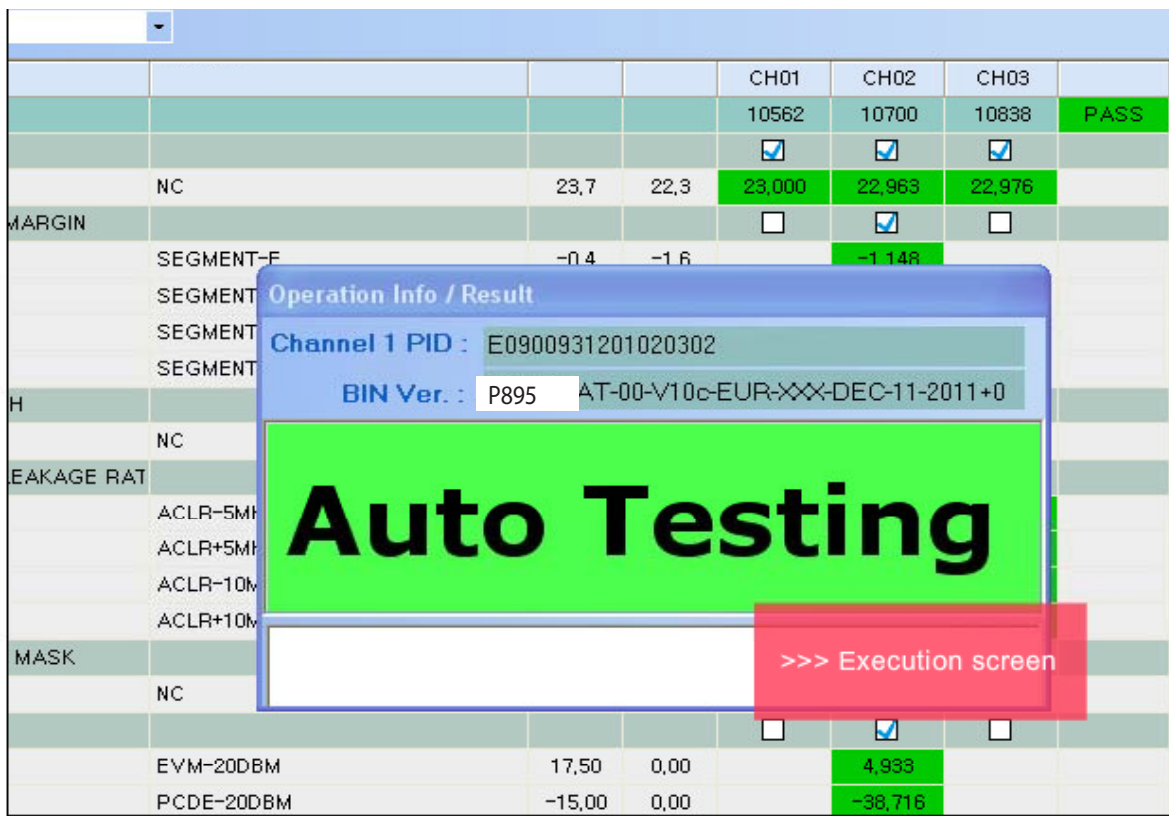
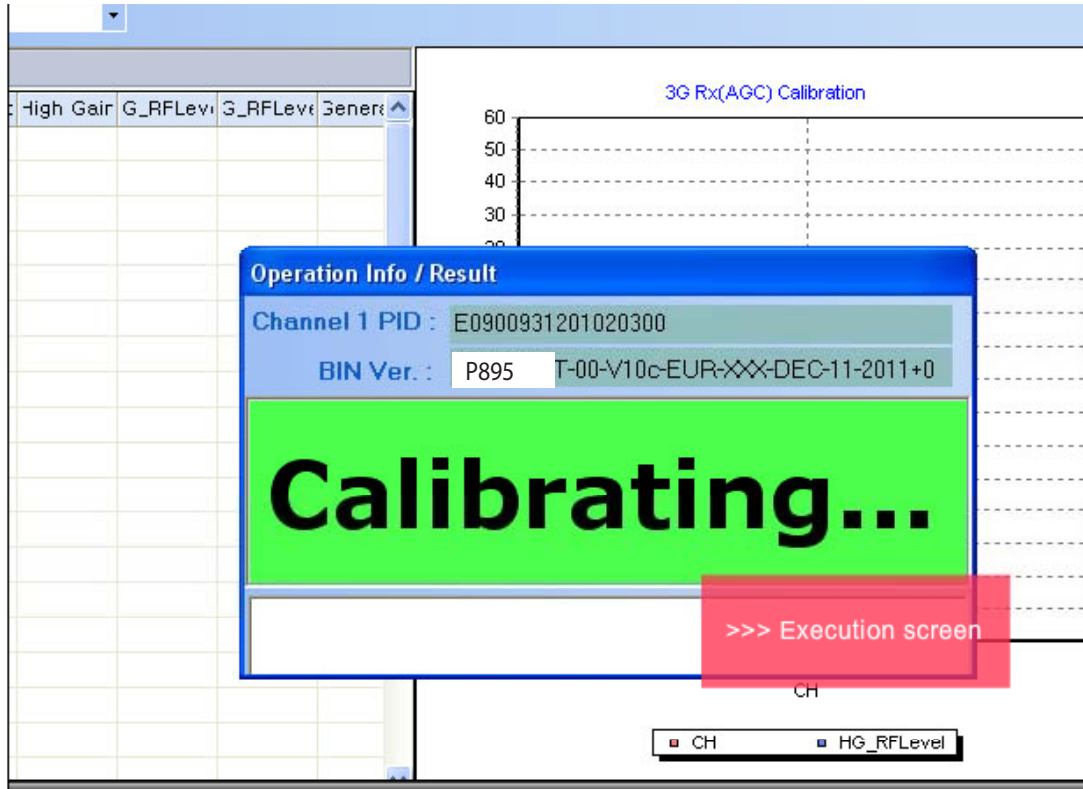




10. CALIBRATION



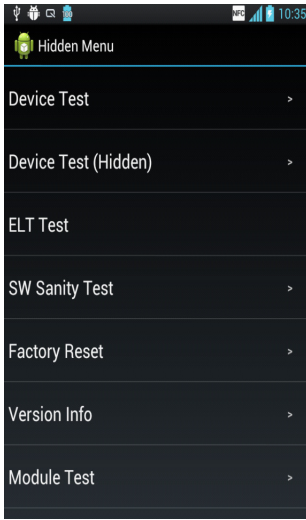




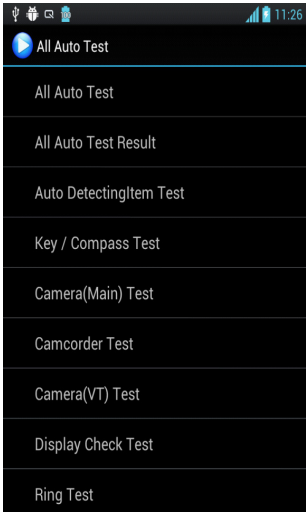


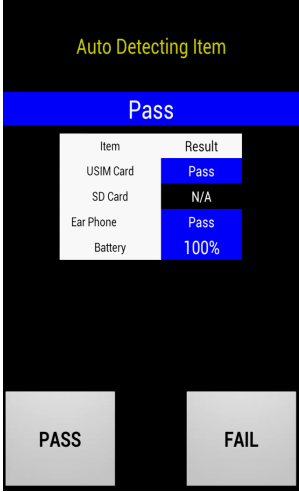
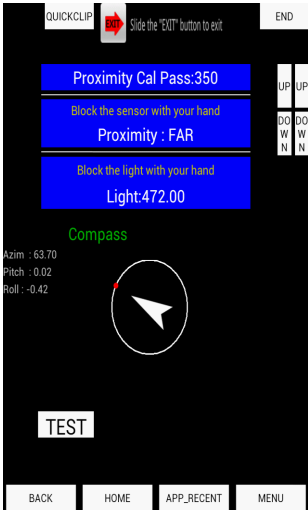
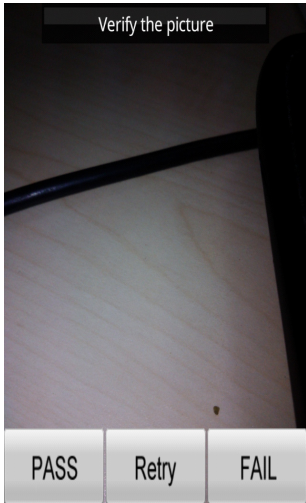
				10562	10700	10838	PASS
				<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	
	NC	23,7	22,3	23,065	22,983	23,013	
MARGIN				<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	
SEGMENT	<div> <div>Operation Info / Result</div> <div>Channel 1 PID : F09000931201020299</div> <div>BIN Ver. : P895 AT-00-V10c-EUR-XXX-DEC-11-2011+0</div> <div> <div>---</div> <div>PASS</div> <div>---</div> </div> </div>						
SEGMENT							
SEGMENT							
SEGMENT							
TH							
NC							
LEAKAGE RAT							
ACLR-5M							
ACLR+5M							
ACLR-10M							
ACLR+10M							
ON MASK							
NC		0,5	-0,5				
Y							<input type="checkbox"/>
EVM-20DBM		17,50	0,00		4,720		
PCDE-20DBM		-15,00	0,00		-38,441		
System Loss :				MySystem(MS).gms : RF900 6C.grf			

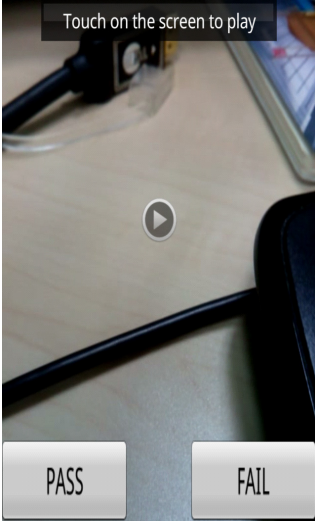

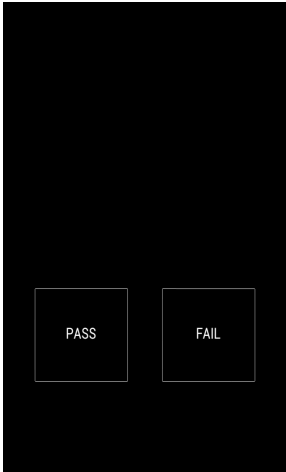

'PASS' The End

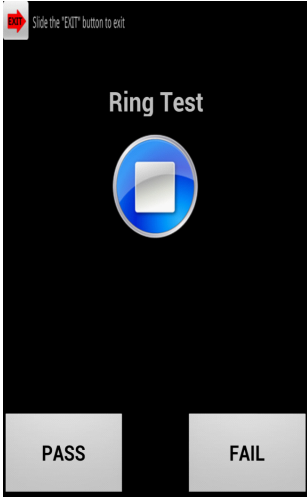
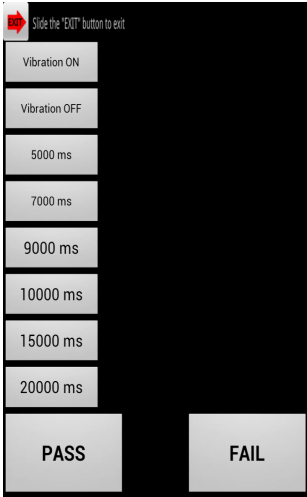
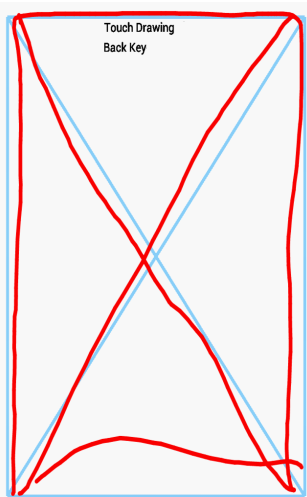
11. HIDDEN MENU

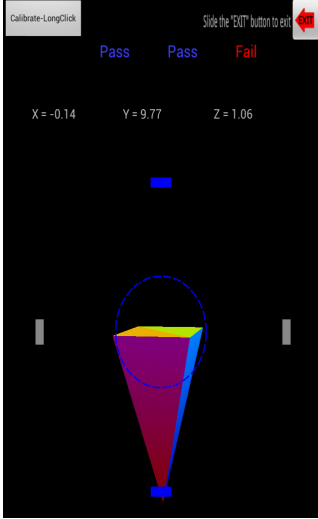

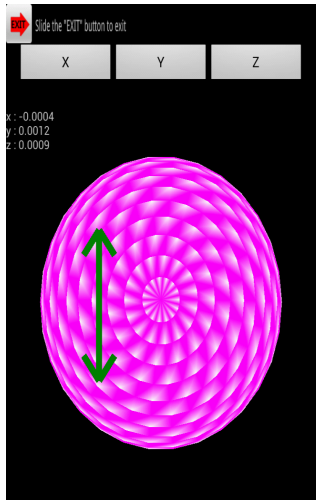
	<p>Hidden Menu Start Start shortcut keys:: 3845#*895#</p> <p>Hidden Menu List Start the desired menu: Menu, click</p>
	<p>Device Test List : All Auto Test – Partial All Auto Test Result – Partial All Auto Test – Full Normal Boot(+power key) FTM Boot(+power key)</p>

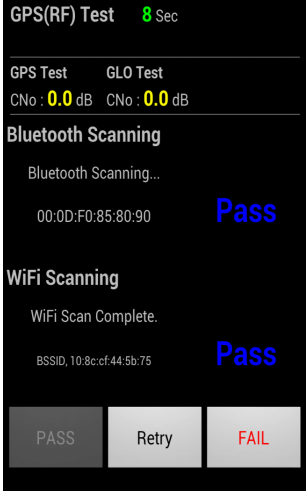
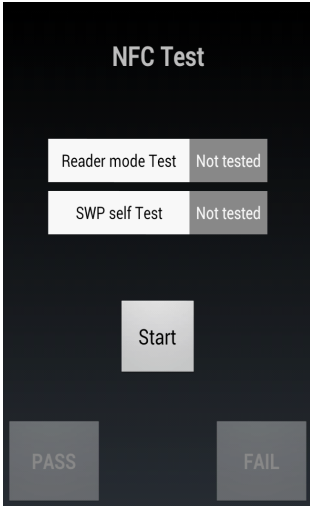
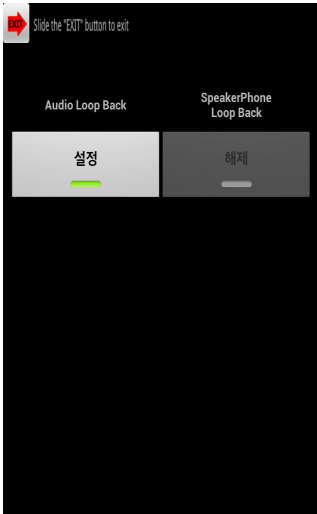
	<p>Device Test – All Auto Test - Full</p> <p>List :</p> <ul style="list-style-type: none"> All Auto Test All Auto Test Result Auto DetectingItem Test Key / Compass Test Camera(Main) Test Camcorder Test Camera(VT) Test Display Check Test Ring Test Vibrator Test Touch Draw Test Accelerometer Test Gesture Test Gyroscope Test GPS BT WIFI Test HDMI Test NFC Test Loopback Test LogService
	<p>All Auto Test List</p> <p>All Auto Test :</p> <ul style="list-style-type: none"> -> All Auto Test menu click -> Continuous information on the menu, giving you ability test

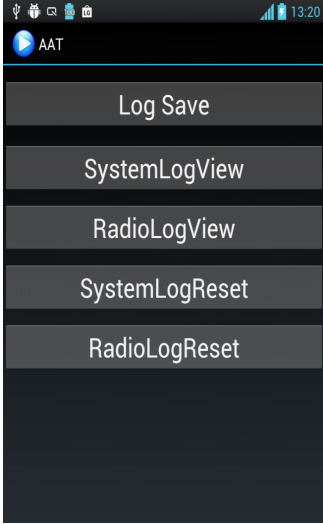
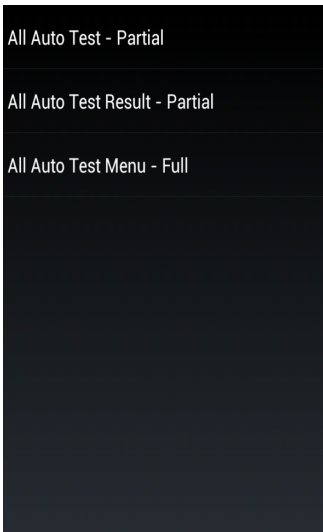
 <p>Auto Detecting Item</p> <p>Pass</p> <table border="1"> <thead> <tr> <th>Item</th> <th>Result</th> </tr> </thead> <tbody> <tr> <td>USIM Card</td> <td>Pass</td> </tr> <tr> <td>SD Card</td> <td>N/A</td> </tr> <tr> <td>Ear Phone</td> <td>Pass</td> </tr> <tr> <td>Battery</td> <td>100%</td> </tr> </tbody> </table> <p>PASS FAIL</p>	Item	Result	USIM Card	Pass	SD Card	N/A	Ear Phone	Pass	Battery	100%	<p>Auto DetectingItem Test</p> <p>Item list :</p> <ul style="list-style-type: none"> USIM Card SD Card Ear Phone Battery
Item	Result										
USIM Card	Pass										
SD Card	N/A										
Ear Phone	Pass										
Battery	100%										
 <p>QUICKCLIP END Slide the "END" button to exit</p> <p>Proximity Cal Pass:350</p> <p>Block the sensor with your hand</p> <p>Proximity : FAR</p> <p>Block the light with your hand</p> <p>Light:472.00</p> <p>Compass</p> <p>Azim : 63.70 Pitch : 0.02 Roll : -0.42</p> <p>TEST</p> <p>BACK HOME APP_RECENT MENU</p>	<p>Key / Proximity / ALC / Compass</p>										
 <p>Verify the picture</p> <p>PASS Retry FAIL</p>	<p>Camera(Main) Test</p>										

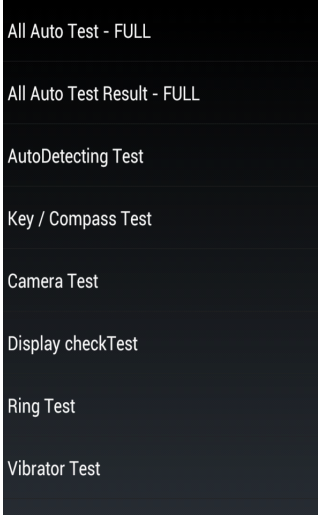
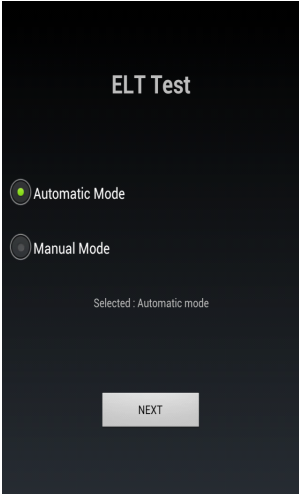
	Camcorder Test	
	Camera(VT) Test	
		Display Check Test

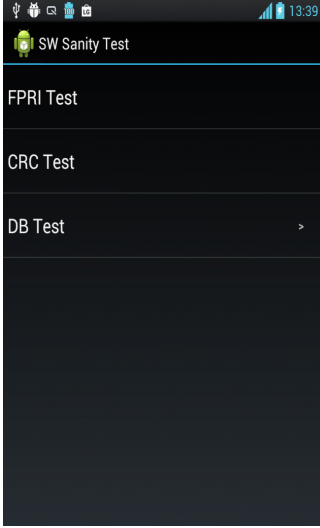
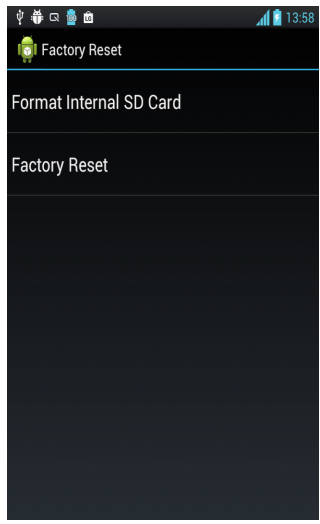
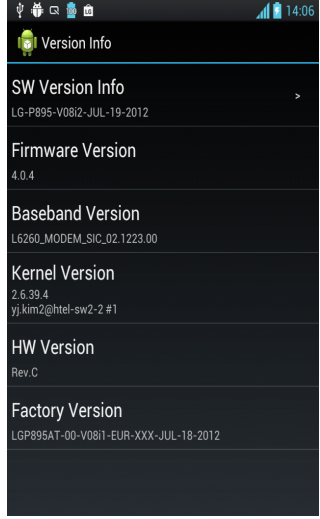
 The image shows a mobile application screen titled "Ring Test". At the top left, there is a small red icon with the word "EXIT" and the text "Slide the 'EXIT' button to exit". In the center, there is a blue circular button with a white square in the middle. At the bottom, there are two grey buttons labeled "PASS" and "FAIL".	<p>Ring Test</p>
 The image shows a mobile application screen titled "Vibrator Test". At the top left, there is a small red icon with the word "EXIT" and the text "Slide the 'EXIT' button to exit". Below this, there is a list of options: "Vibration ON", "Vibration OFF", "5000 ms", "7000 ms", "9000 ms", "10000 ms", "15000 ms", and "20000 ms". At the bottom, there are two grey buttons labeled "PASS" and "FAIL".	<p>Vibrator Test</p>
 The image shows a mobile application screen titled "Touch Drawing Back Key". It features a light blue square frame with a red 'X' drawn across it. The text "Touch Drawing Back Key" is displayed at the top.	<p>Touch Draw Test</p>

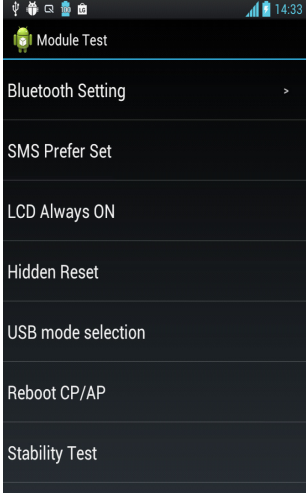
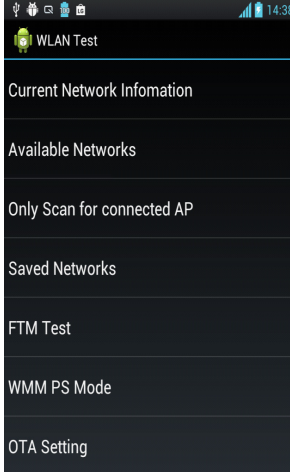
 <p>Calibrate-LongClick</p> <p>Slide the "EXIT" button to exit</p> <p>Pass Pass Fail</p> <p>X = -0.14 Y = 9.77 Z = 1.06</p> <p>Visual representation of a 3D coordinate system with a blue cone and a blue line.</p>	<h3>Accelerometer Test</h3>
 <p>Please tap left, right, top and bottom of the device to test the gesture recognition.</p> <p>Recognized</p> <p>4</p> <p>PASS FAIL</p>	<h3>Gesture Test</h3>
 <p>Slide the "EXIT" button to exit</p> <p>X Y Z</p> <p>x: -0.0004 y: 0.0012 z: 0.0009</p> <p>Visual representation of a gyroscope with a green double-headed arrow indicating rotation.</p>	<h3>Gyroscope Test</h3>

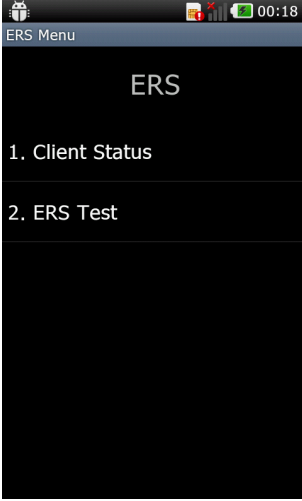
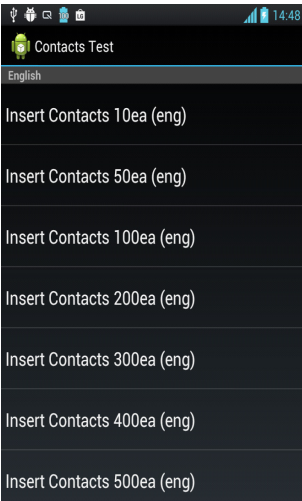
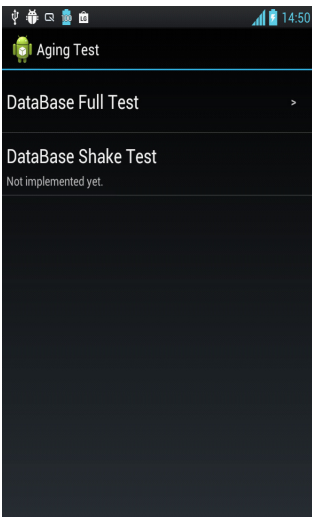
	<p>GPS BT WIFI Test</p>
	<p>NFC Test</p>
	<p>Loopback Test</p>

	<p>LogService List :</p> <ul style="list-style-type: none"> Log Save SystemLogView RadioLogView SystemLogReset RadioLogReset
	<p>Device Test (Hidden)</p> <p>List :</p> <ul style="list-style-type: none"> All Auto Test – Partial All Auto Test Result – Partial All Auto Test Menu – Full

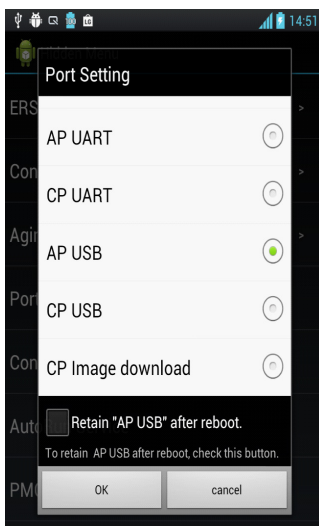
 <p>A screenshot of a dark-themed menu titled 'All Auto Test - FULL'. It lists several test options: 'All Auto Test - FULL', 'All Auto Test Result - FULL', 'AutoDetecting Test', 'Key / Compass Test', 'Camera Test', 'Display checkTest', 'Ring Test', and 'Vibrator Test'.</p>	<p>Device Test (Hidden) – All Auto Test Menu - Full</p> <p>List :</p> <ul style="list-style-type: none"> All Auto Test – Full All Auto Test Result – Full AutoDetecting Test Key / Compass Test Camera Test Display checkTest Ring Test Vibrator Test Touch Window Test Accelerometer Test Gesture Test Gyroscope Test GPS Test (BT, WI-FI) HDMI Output Test Audio LoopBack Test NFC Test ALC / Proximity Test Bluetooth Scan Test Compass Test EMI Test Font Test Gyro Cal Test LCD Test RGB Bridge IC Test RTC Test Sound Test Touch Test Touch LED Brightness Wifi Scan Test HDMI Connection Repeat
 <p>A screenshot of the 'ELT Test' screen. It shows two radio button options: 'Automatic Mode' (which is selected) and 'Manual Mode'. Below the options, it says 'Selected : Automatic mode'. At the bottom, there is a 'NEXT' button.</p>	<p>ELT Test</p>

 <p>The screenshot shows the 'SW Sanity Test' application interface. It has a dark background with white text. At the top, there's a status bar with icons for signal, battery, and time (13:39). Below the title 'SW Sanity Test', there are four menu items: 'FPRI Test', 'CRC Test', 'DB Test', and a right-pointing arrow. The 'DB Test' item is highlighted.</p>	<p>SW Sanity Test</p> <p>SW Sanity Test:</p> <ul style="list-style-type: none"> -FPRI Test -CRC Test : BIN CRC CAL CRC EFS CRC EFS CRC Detail -DB Test : DB CRC DB CUMP DB COPY
 <p>The screenshot shows the 'Factory Reset' application interface. It has a dark background with white text. At the top, there's a status bar with icons for signal, battery, and time (13:58). Below the title 'Factory Reset', there are two menu items: 'Format Internal SD Card' and 'Factory Reset'. The 'Factory Reset' item is highlighted.</p>	<p>Factory Reset:</p> <p>Format Internal SD card : Internal SD Card Data reset</p> <p>Factory Rest : Changing the Factory</p>
 <p>The screenshot shows the 'Version Info' application interface. It has a dark background with white text. At the top, there's a status bar with icons for signal, battery, and time (14:06). Below the title 'Version Info', there are several menu items: 'SW Version Info', 'Firmware Version', 'Baseband Version', 'Kernel Version', 'HW Version', and 'Factory Version'. The 'SW Version Info' item is highlighted. Below the highlighted item, there is a list of version information: 'LG-P895-V0812-JUL-19-2012', '4.0.4', 'LG260_MODEM_SIC_02.1223.00', '2.6.39.4', 'yj.kim2@intel-sw2-2 #1', 'Rev.C', and 'LGP895AT-00-V0811-EUR-XXX-JUL-18-2012'.</p>	<p>Version Info</p> <p>Classified Information representation</p>

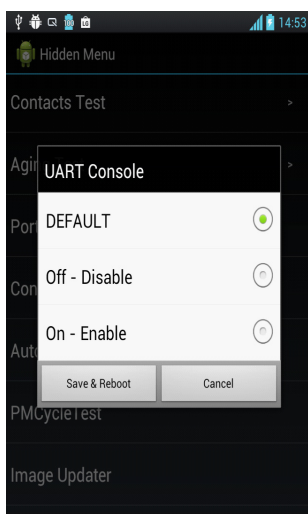
	<p>Module Test list:</p> <ul style="list-style-type: none"> Bluetooth Setting SMS Prefer Set LCD Always On Hidden Reset USB mode selection Reboot CP/AP Stability Test Charging Test Fuel Gauge Reset FOTA Test Crash Handling SMPL Setting SMPL Count Wakelock Monitoring Setting RIL Recovery
	<p>WLAN performance on SW</p>

	ERS Menu
	Contacts Test
	Aging Test

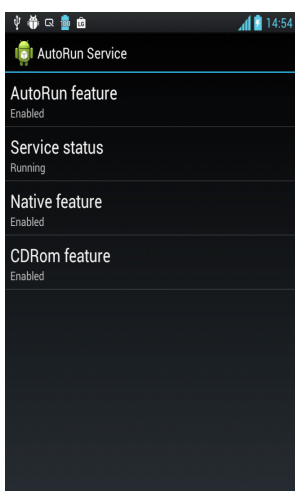
11. HIDDEN MENU



Port Setting



Console Setting



AutoRun Service

11. HIDDEN MENU

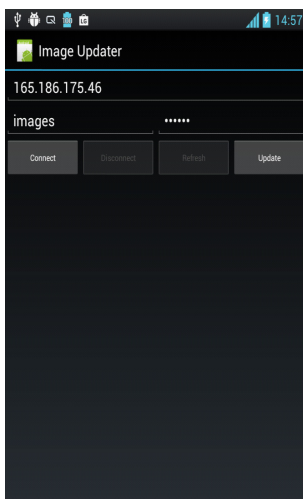
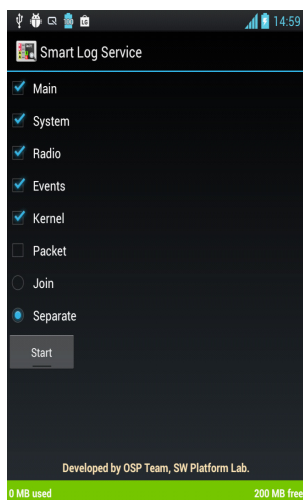
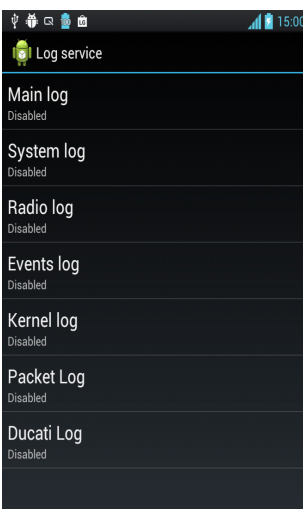


Image Updater



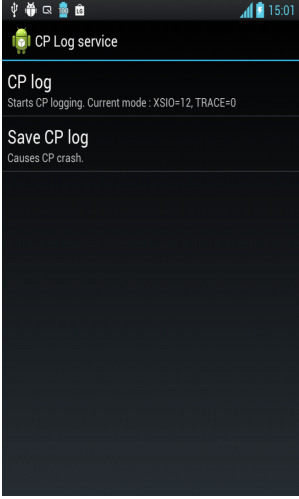
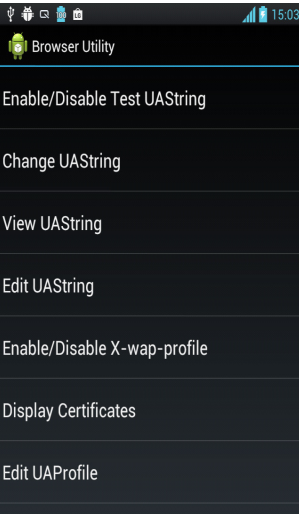
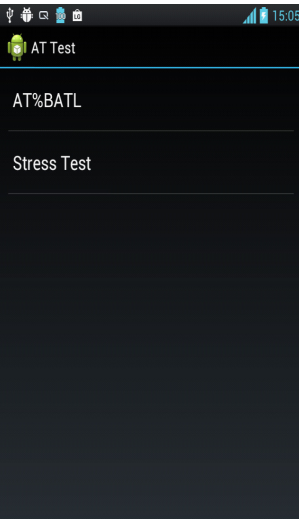
Smart Log Service


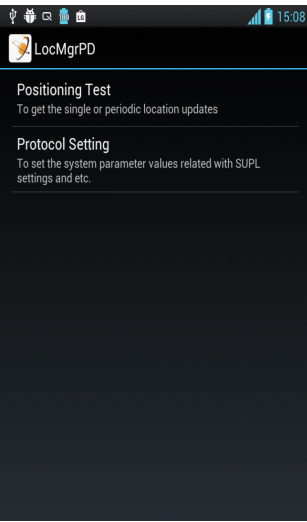



Log Service

Collect Log

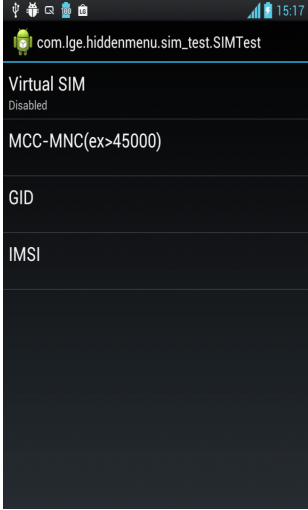
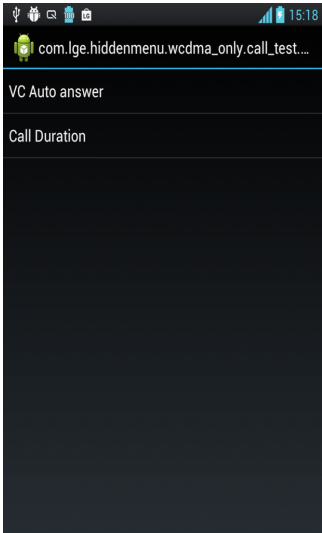
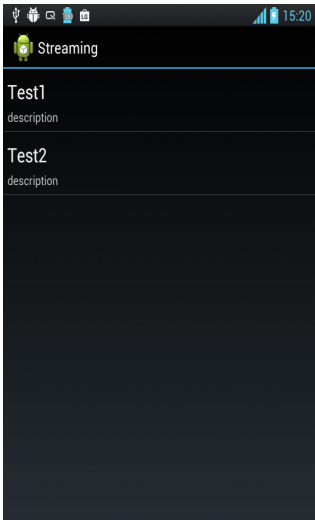
11. HIDDEN MENU

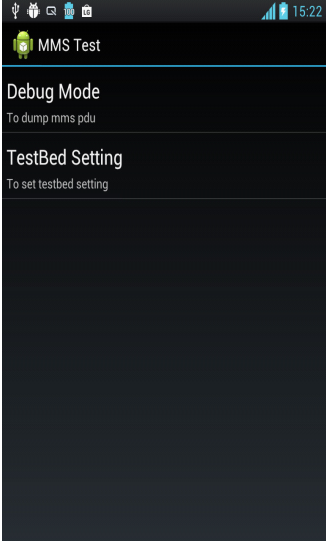
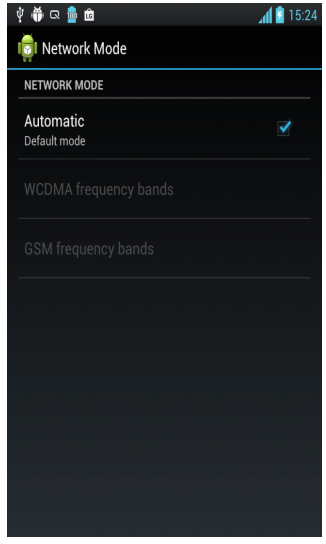
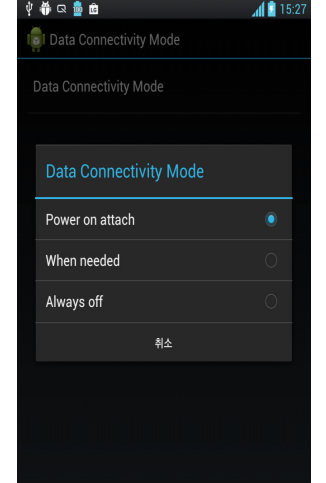
	CP Log Service
	Browser Utility
	AT Test

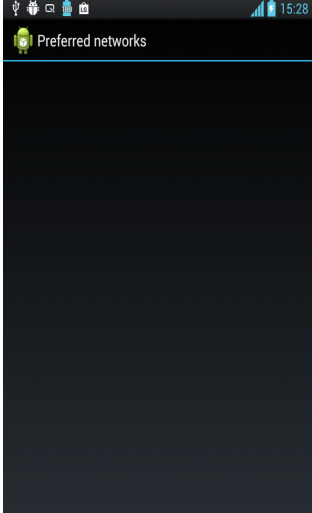
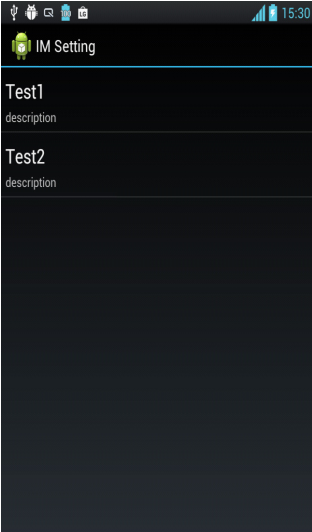
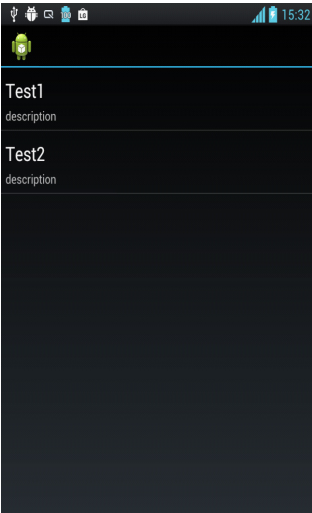
	<h2>Engineering Mode</h2>
	<h2>GPS Test</h2>
	<h2>GPS HW Test</h2>

 A screenshot of an Android phone screen showing the 'SMS Test' application. The status bar at the top shows the time as 15:11. The app title 'SMS Test' is at the top. Below it, the option 'Automatic Memfull Test' is visible.	SMS Test
 A screenshot of an Android phone screen showing the 'DRMTest' application. The status bar at the top shows the time as 15:13. The app title 'DRMTest' is at the top. Below it, the options 'DRM Cert Check' and 'DRM Cert Info' are visible.	DRM Test
 A screenshot of an Android phone screen showing the 'Widevine Keybox Test' application. The status bar at the top shows the time as 15:15. The app title 'Widevine Keybox Test' is at the top. Below it, the options 'Keybox Check' and 'Keybox Hash' are visible.	WVDRM Keybox

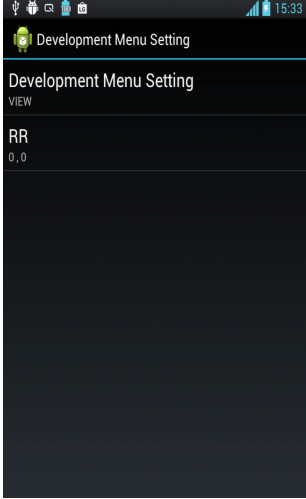
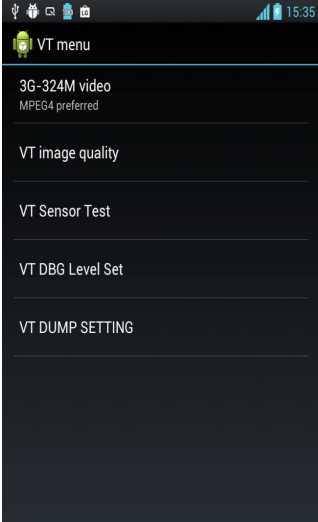
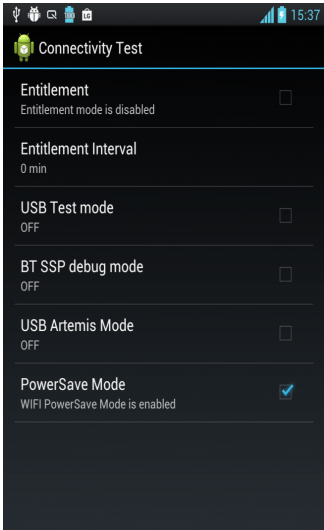
11. HIDDEN MENU

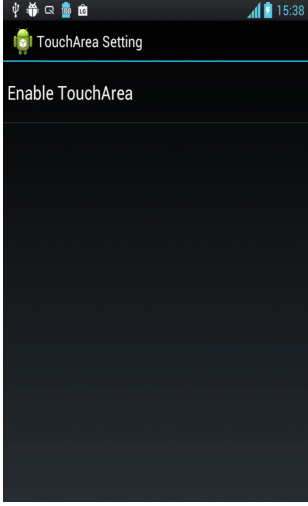
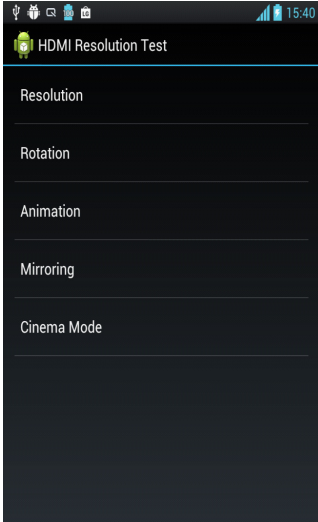
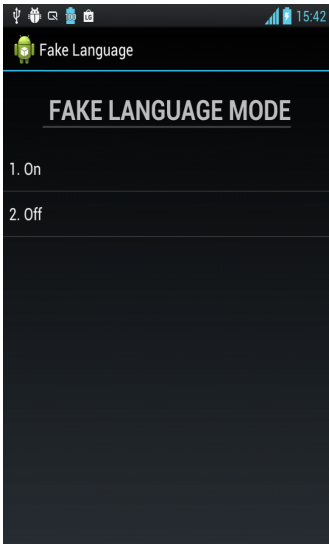
 <p>The screenshot shows the 'SIM Test' application interface. At the top, the status bar displays the time as 15:17. The app title bar reads 'com.lge.hiddenmenu.sim_test.SIMTest'. The main menu items are: 'Virtual SIM' (with a sub-item 'Disabled'), 'MCC-MNC(ex>45000)', 'GID', and 'IMSI'.</p>	<h3>SIM Test</h3>
 <p>The screenshot shows the 'Call Test' application interface. At the top, the status bar displays the time as 15:18. The app title bar reads 'com.lge.hiddenmenu.wcdma_only.call_test...'. The main menu items are: 'VC Auto answer' and 'Call Duration'.</p>	<h3>Call Test</h3>
 <p>The screenshot shows the 'Streaming' application interface. At the top, the status bar displays the time as 15:20. The app title bar reads 'Streaming'. The main menu items are: 'Test1' (with a sub-item 'description') and 'Test2' (with a sub-item 'description').</p>	<h3>Streaming</h3>

	<h3>MMS Test</h3>
	<h3>Network Mode</h3>
	<h3>Data Connectivity Mode</h3>

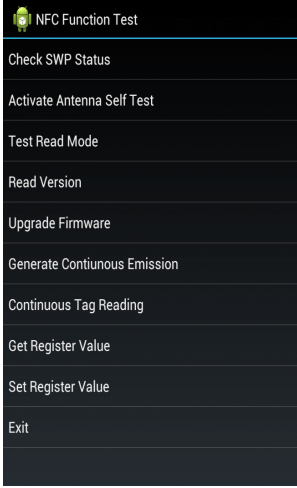
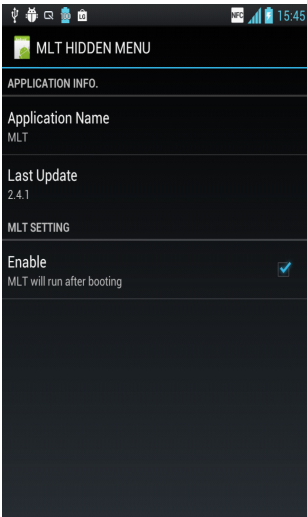
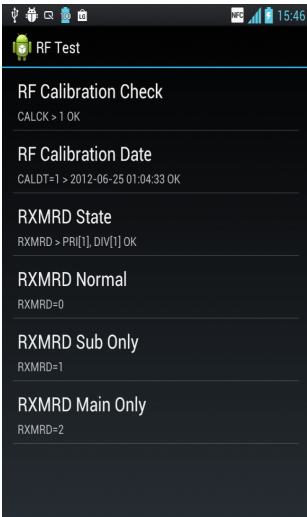
	Preferred networks
	IM Setting
	SyncML Test

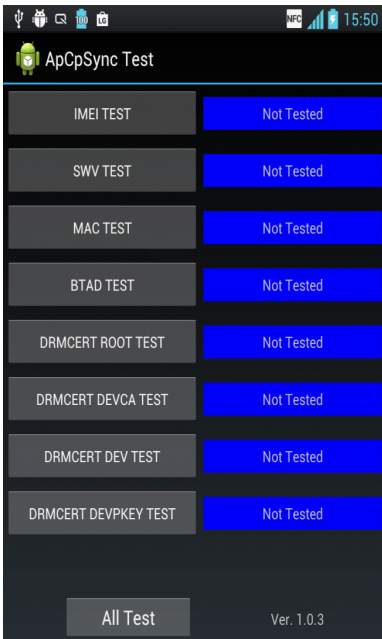
11. HIDDEN MENU

	Development Menu Setting
	VT menu
	

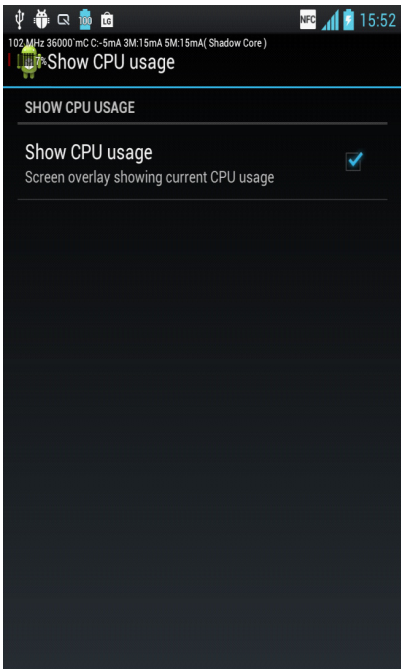
 <p>The screenshot shows the 'TouchArea Setting' menu. At the top, there's a status bar with icons for USB, Wi-Fi, and battery, and the time 15:38. Below the title bar, the text 'Enable TouchArea' is displayed on a dark background.</p>	<h3>TouchArea Setting</h3>
 <p>The screenshot shows the 'HDMI Resolution Test' menu. The status bar at the top shows the time 15:40. The menu lists several options: Resolution, Rotation, Animation, Mirroring, and Cinema Mode, each on a separate line with a horizontal separator.</p>	<h3>HDMI Resolution Test</h3>
 <p>The screenshot shows the 'Fake Language' menu. The status bar at the top shows the time 15:42. The menu title is 'FAKE LANGUAGE MODE' in all caps. Below it, there are two options: '1. On' and '2. Off', each on a separate line with a horizontal separator.</p>	<h3>Fake Language</h3>

11. HIDDEN MENU

 <p>The screenshot shows the 'NFC Function Test' application interface. It features a list of options: 'Check SWP Status', 'Activate Antenna Self Test', 'Test Read Mode', 'Read Version', 'Upgrade Firmware', 'Generate Continuous Emission', 'Continuous Tag Reading', 'Get Register Value', 'Set Register Value', and 'Exit'.</p>	NFC Test
 <p>The screenshot shows the 'MLT HIDDEN MENU' application interface. It displays 'APPLICATION INFO.' with 'Application Name' as 'MLT' and 'Last Update' as '2.4.1'. Under 'MLT SETTING', there is an 'Enable' option with a checked checkbox and the text 'MLT will run after booting'.</p>	MLT
 <p>The screenshot shows the 'RF Test' application interface. It lists several status checks: 'RF Calibration Check' (CALCK > 1 OK), 'RF Calibration Date' (CALDT=1 > 2012-06-25 01:04:33 OK), 'RXMRD State' (RXMRD > PRI[1], DIV[1] OK), 'RXMRD Normal' (RXMRD=0), 'RXMRD Sub Only' (RXMRD=1), and 'RXMRD Main Only' (RXMRD=2).</p>	RF Test



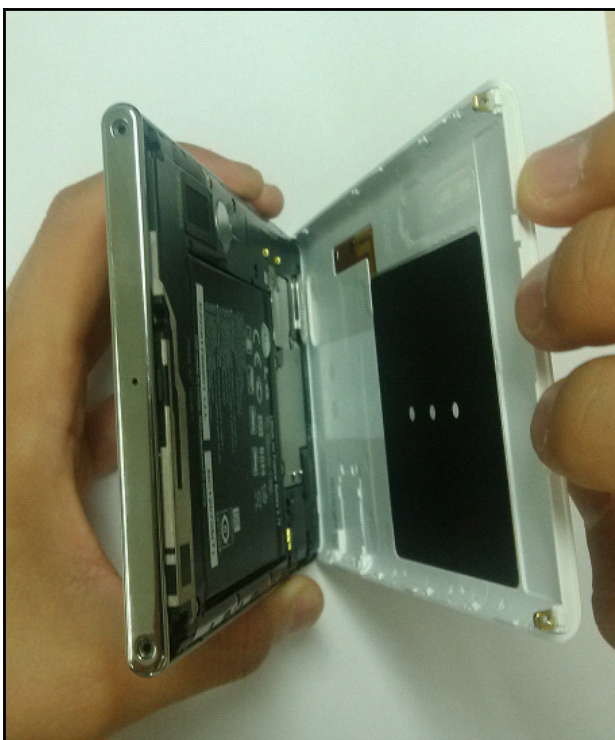
ApCpSync Test



Show CPU Usage

12. DISASSEMBLE GUIDE

1. Disassemble Battery Cover



Remove BATTERY COVER after
unscrewing 2 points
(Star-shaped screws on the bottom of the set)

2. Disassemble REAR



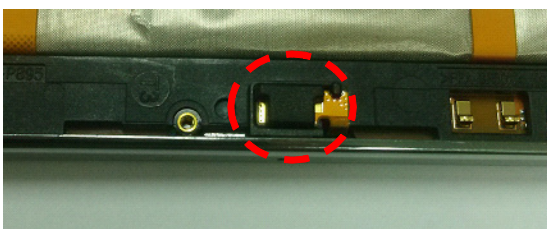
Remove REAR COVER by pulling the side of REAR COVER, after unscrewing 14 points (Follow the order of the pictures)

3. Disassemble BATTERY & PCB



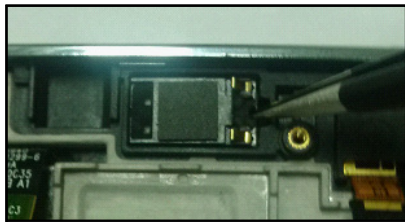
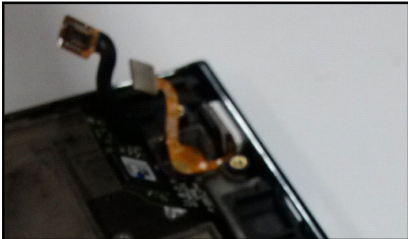
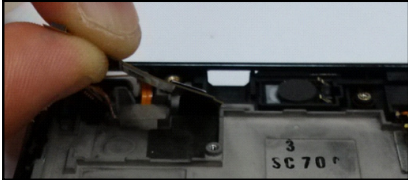
1. Remove FPCB CONNECTOR 9EA and COAXIAL CABLE CONNETTOR from PCB
2. After removing MAIN CAMERA, Remove POWER BUTTON FPCB
3. Remove BATTERY pushing tool on the right side of BATTERY

4. Disassemble MAIN ANTENNA

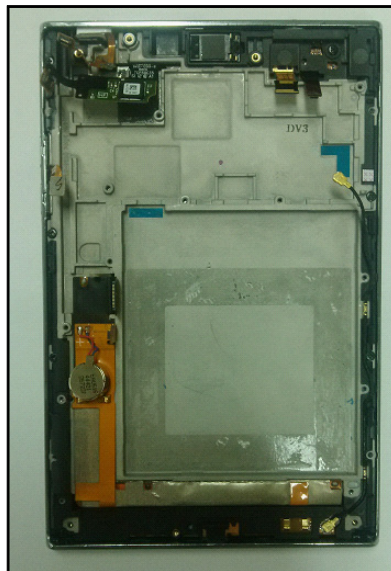
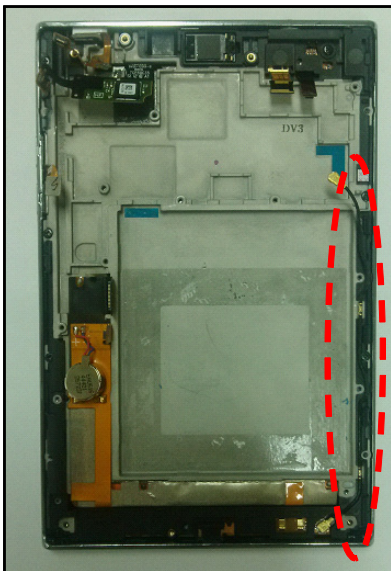


1. Unscrew 3 Points
2. Remove MOTOR
3. Remove MAIN ANTENNA by bending the bottom of the set
4. Remove MAIN MIC CAP

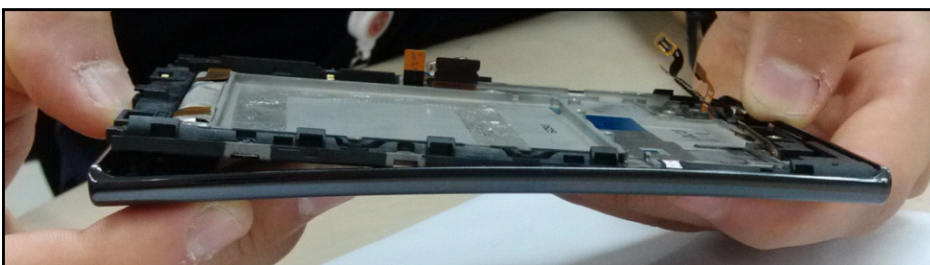
5. Disassemble FRAME



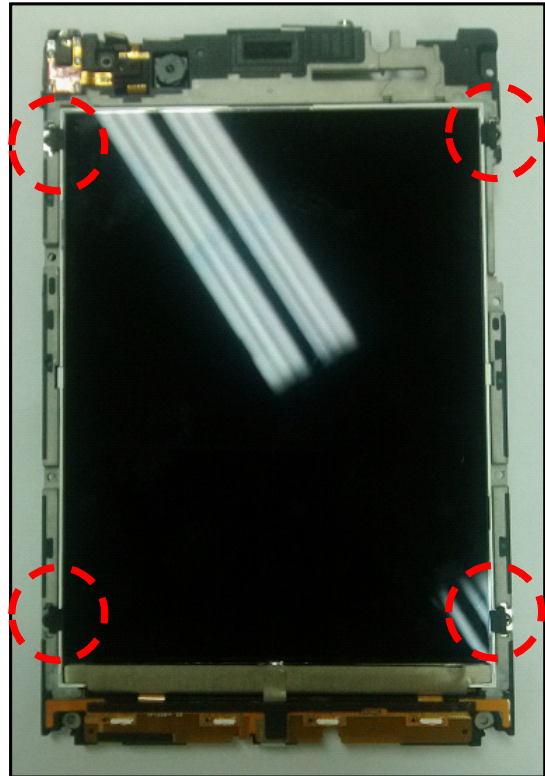
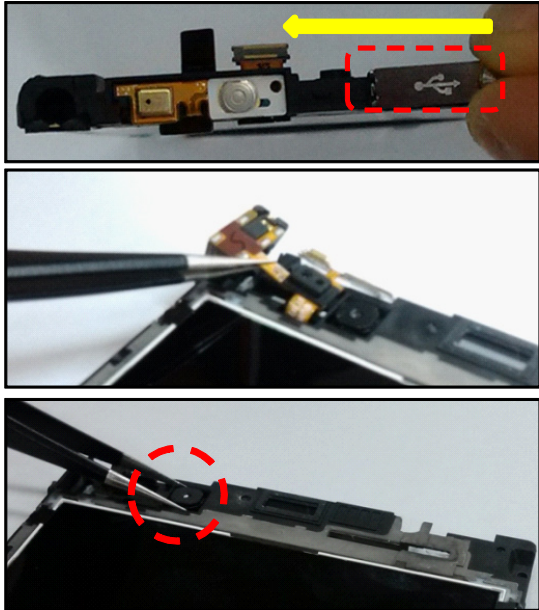
1. Remove TOUCH WINDOW FPCB from FRAME
2. Remove POWER BUTTON FPCB from FRAME
3. Remove RECEIVER using a pincette



4. Remove COAXIAL CABLE from FRAME
5. Unscrew 6 points
6. Separate FRAME from FRONT COVER by bending the bottom of the set
(Be careful not to give any damage to TOUCH WINDOW FPCB)

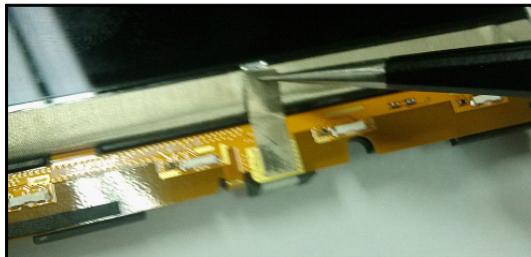
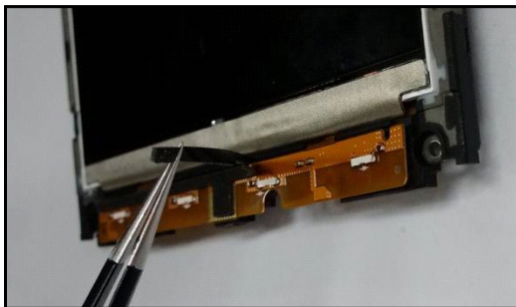
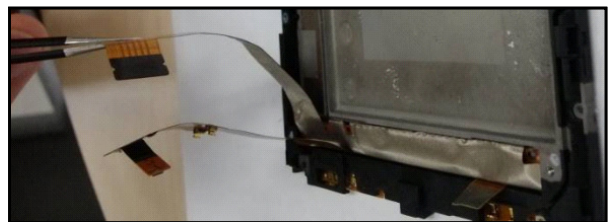
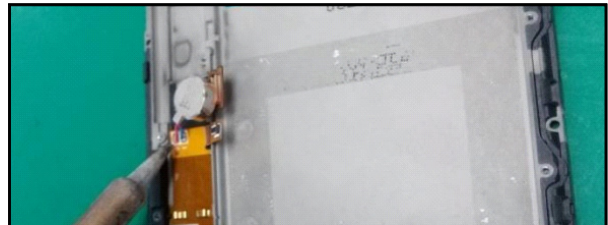
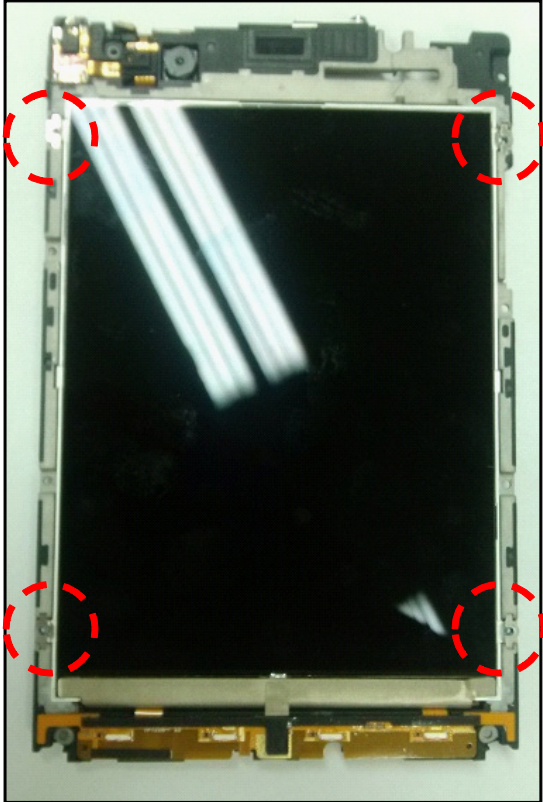


6.1 Disassemble LCD



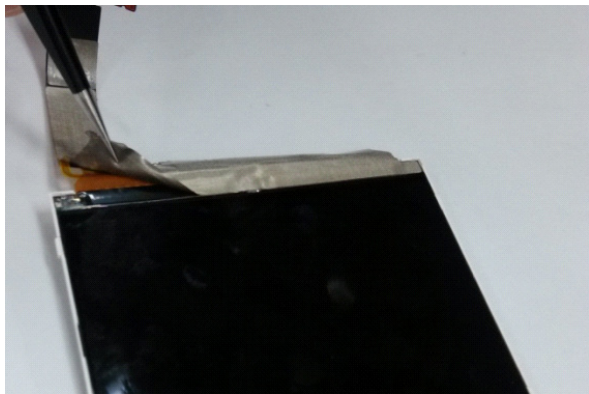
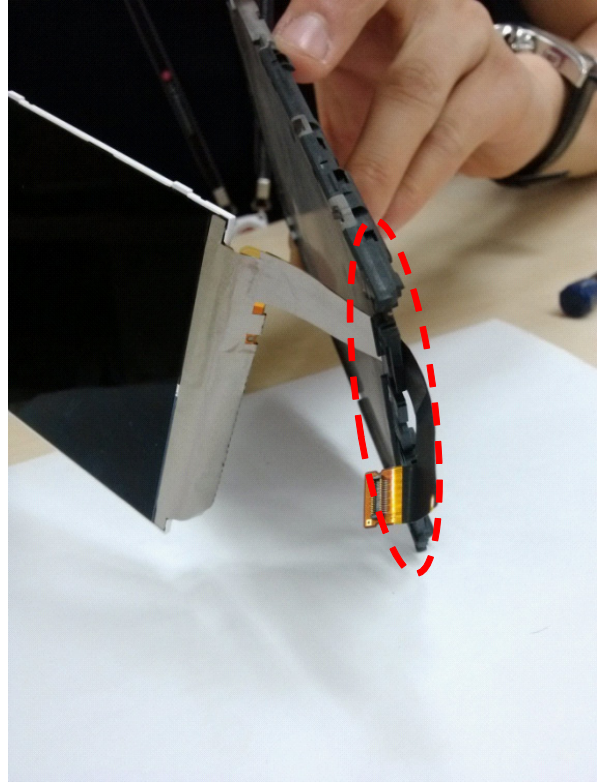
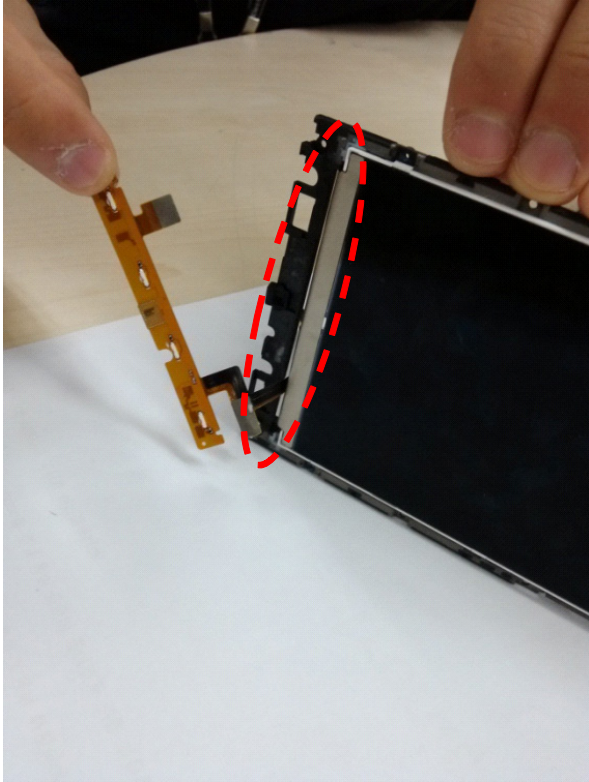
1. Remove USB CAP
2. Remove EAR JACK
3. Remove VT CAMERA with a pincette
4. Remove 4 PAD BRACKETS
5. Remove 4 LCD SCREWS

6.2 Disassemble LCD



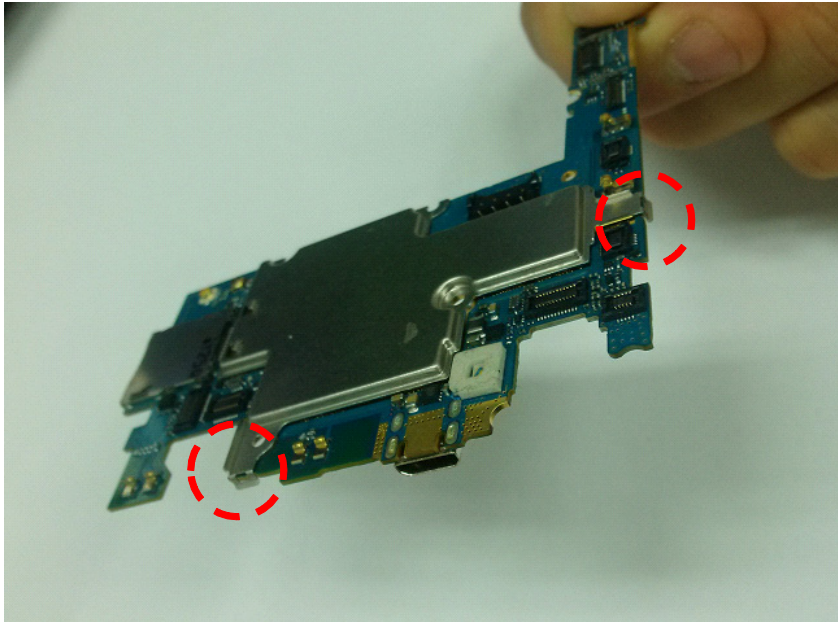
6. Remove 4 BRACKET LCD SCREWS
7. Remove MOTER using a solder iron
8. Remove LED FPCB from LCD FPCB
9. Remvove LCD FPCB from FRAME
10. Remove PAD GASKET from LED FPCB
11. Remove GASKET LCD 2
12. Remove LED FPCB from FRAME

6.3 Disassemble LCD



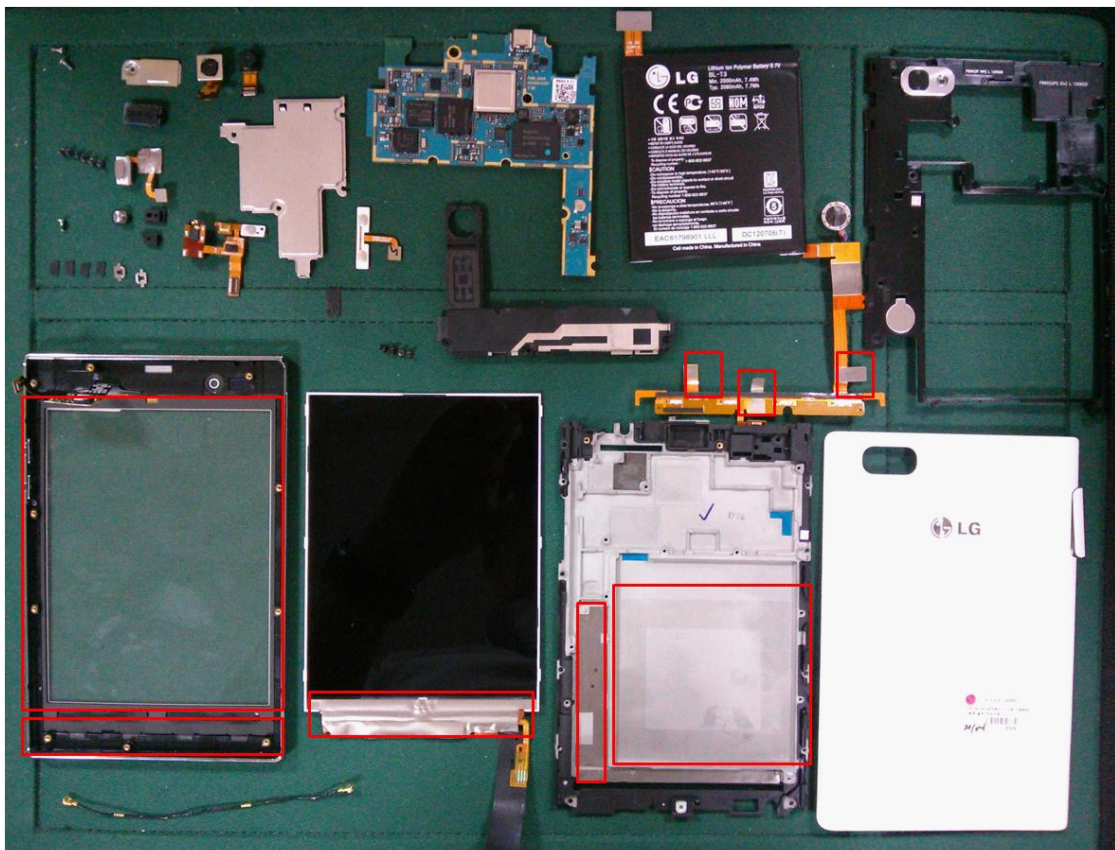
- 13. Remove LED FPCB from FRAME
[Going through the hole at the bottom part of the FRAME]
- 14. Remove LCD from FRAME
- 15. Remove GASKET LCD 1 from LCD

7. Disassemble MAIN PCB



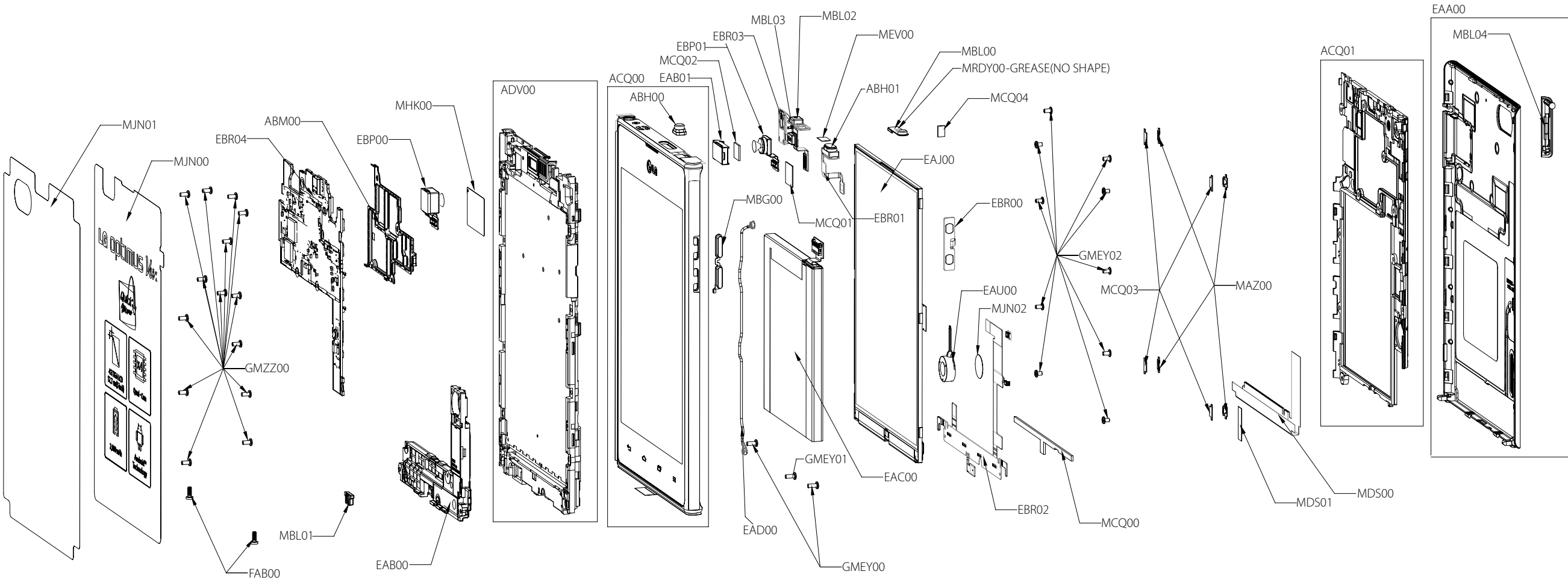
Remove SHIELD CAN
from MAIN PCB by
unhooking 2 points

8. Complete disassembling P895



13. EXPLODED VIEW & REPLACEMENT PART LIST

13.1 EXPLODED VIEW(SBOM)



Location	Description
EBP00	Camera Module
FAB00	Screw,Machine
GMZZ00	Screw,Machine
MHK00	Sheet
EAB00	Speaker Module
ADV00	Frame Assembly
ACQ00	Cover Assembly,Front
ABH00	Button Assembly
MBG00	Button,Side
MJN00	Tape,Protect
EAC00	Rechargeable Battery,Lithium Polymer
EAB01	Receiver
EAD00	Cable,Assembly
EAJ00	LCD,Module-TFT
EAU00	Motor,DC

Location	Description
EBP01	Camera Module
EBR00	PCB Assembly,Flexible
EBR01	PCB Assembly,Flexible
EBR02	PCB Assembly,Flexible
EBR03	PCB Assembly,Flexible
GMEY00	Screw,Machine
GMEY01	Screw,Machine
MCQ00	Damper
MCQ01	Damper,Camera
MRDY00	Reinforce
ABH01	Button Assembly
GMEY02	Screw,Machine
MAZ00	Bracket
MBL00	Cap,Receptacle
MBL01	Cap

Location	Description
MBL02	Cap
MBL03	Cap
MCQ02	Damper
MCQ03	Damper
MCQ04	Damper
MDS00	Gasket
MDS01	Gasket
MEV00	Insulator
MJN01	Tape,Protect
MJN02	Tape
ACQ01	Cover Assembly,Rear
EAA00	Antenna Assembly
MBL04	Cap,Multimedia Card
EBR04	PCB Assembly,Main
ABM00	Can Assembly,Shield

13. EXPLODED VIEW & REPLACEMENT PART LIST

13.2 ReplacementParts <Mechanic component>

Note: This Chapter is used for reference. Part order is ordered by SBOM standard on GCSC

Level	LocationNo.	Description	PartNumber	Spec	Remark
1	AGQ000000	Phone Assembly	AGQ86966303	LGP895.AFRABK BK:BLACK BLACK -	
2	ACQ100400	Cover Assembly,EMS	ACQ86284602	LGP895.AFRABK BK:BLACK BLACK -	
3	FAB00	Screw,Machine	FAB31622901	FH NONE 1.4M 4M XM-7 SILVER SPRING N	
3	GMZZ00	Screw,Machine	GMZZ0017701	GMZZ0017701 BH + 1.4mm 3mm MSWR NI PLT N - ASIA BOLT	
3	MHK00	Sheet	MHK63965211	COMPLEX LGP895.AFAWH ZZ:Without Color P895 IMEI LABEL SHEET	
3	MEZ002100	Label,Approval	MEZ64709901	COMPLEX LGP895.AGBRWH ZZ:Without Color P895 Label, Approval	
3	ACQ003400	Cover Assembly,Bar	ACQ86069121	LGP895.ADEUBK BK:BLACK BLACK P895 Bar Assy	
4	ADV00	Frame Assembly	ADV74305711	LGP895.ADEUWH ZZ:Without Color P895 FRAME ASSY	
5	MJN000005	Tape	MJN68113111	COMPLEX LGP895.AGBRWH ZZ:Without Color P895 Tape, LED FPCB	
5	MEZ000900	Label,After Service	MLAB0004801	COMPLEX LG-LB3300 LGT ZZ:Without Color -	
5	MEV000001	Insulator	MEV64333801	COMPLEX LGVS950.AVRZBK ZZ:Without Color VS950 Insulator Note Key	
5	MJN000007	Tape	MJN68315001	COMPLEX LGP895.AGBRWH ZZ:Without Color P895 Tape, Frame	
5	ADV076900	Frame Assembly,Sub	ADV74331211	LGP895.ADEUWH BK:BLACK BLACK P895 FRAME ASSY, SUB	
6	MET099500	INSERT,NUT	MICE0016903	MECH_COMMON ZY,ZZ,PRESS, STS, , , , ,	
6	MDQ000001	Frame	MDQ63316621	MOLD PC LGP895.ADEUBK BK:BLACK BLACK P895 FRAME, INSERT MOLD	
6	MDQ000000	Frame	MDQ63280121	CASTING MG LGP895.ADEUBK ZZ:Without Color P895 FRAME, INSERT DIECASTING	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
5	MCQ000000	Damper	MCQ66966911	COMPLEX LGP895.ADEUBK ZZ:Without Color -	
5	MCQ000001	Damper	MCQ66990911	COMPLEX LGP895.ADEUBK ZZ:Without Color -	
5	MEV000000	Insulator	MEV64210801	COMPLEX LGF100S.ASKTBK ZZ:Without Color F100_BATT_INSULATOR	
5	MJN000001	Tape	MJN68069001	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MJN000002	Tape	MJN68069201	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MJN000003	Tape	MJN68069301	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MJN000000	Tape	MJN68093001	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MJN000004	Tape	MJN68113001	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MJN000006	Tape	MJN68134001	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MJN061100	Tape,Protect	MJN68143211	COMPLEX LGVS950.AVRZBK ZZ:Without Color VS950 INSULATOR FRAME TOP	
5	MEV000002	Insulator	MEV64331501	COMPLEX LGP895.AGBRWH ZZ:Without Color P895 Insulator PCB	
4	ACQ00	Cover Assembly,Front	ACQ86069011	LGP895.ADEUBK ZY:Color Unfixed P895 Cover Assy, Front	
5	MEV000000	Insulator	MEV64312101	COMPLEX LGVS950.AVRZBK ZZ:Without Color VS950 Insulator LGF	
5	MJN061105	Tape,Protect	MJN68092802	COMPLEX LGVS950.AVRZBK ZZ:Without Color VS950 Tape Protection Top 1	
5	MJN061106	Tape,Protect	MJN68124501	COMPLEX LGF100S.ASKTBK ZZ:Without Color F100s_insulator_top2	
5	MJN061108	Tape,Protect	MJN68160601	COMPLEX LGF100S.ASKTBK ZZ:Without Color F100_tape_protection_4	
5	MJN061107	Tape,Protect	MJN68247001	COMPLEX LGF100S.ASKTBK ZZ:Without Color F100_Tape_nsulator_top3	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
5	ABH00	Button Assembly	ABH74560601	LGF100S.ASKTBK TN:TITAN TITAN BUTTON HOLD ASSY	
6	MEV000000	Insulator	MEV64165301	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
6	MBG000000	Button	MBG64582601	PRESS STS PRESS LGF100S.ASKTBK TN:TITAN TITAN HOLD BUTTON METAL	
6	MBG000001	Button	MBG64570301	MOLD PC LGF100S.ASKTBK TN:TITAN TITAN HOLD BUTTON MOLD	
5	MBG00	Button,Side	MBG64563401	MOLD PC LGF100S.ASKTBK BK:BLACK BLACK -	
5	MCK032700	Cover,Front	MCK67054611	MOLD PC LGVS950.AVRZBK BK:Black -	
6	MET099500	INSERT,NUT	MICE0016903	MECH_COMMON ZY,ZZ,PRESS, STS, , , ,	
5	MCQ043300	Damper,LCD	MCQ66907701	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MCQ009400	Damper,Camera	MCQ66986101	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MCR000001	Decor	MCR64768001	PRESS STS 1 LGF100S.ASKTBK ZZ:Without Color -	
5	MCR000000	Decor	MCR64787001	PRESS STS 0.3 LGF100S.ASKTBK ZZ:Without Color -	
5	MDJ000001	Filter	MDJ63405401	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MDJ000000	Filter	MDJ63424401	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MHK000000	Sheet	MHK63765701	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MJN061104	Tape,Protect	MJN68122201	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MJN061102	Tape,Protect	MJN68142901	COMPLEX LGF100S.ASKTBK ZZ:Without Color insulator_r	
5	MJN061103	Tape,Protect	MJN68143001	COMPLEX LGF100S.ASKTBK ZZ:Without Color insulator_l	
4	MEZ000000	Label	MLAZ0038303	COMPLEX LG-LC3200 WA:White PRINTING, PPRI PRINTING	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
4	MJN00	Tape,Protect	MJN68289901	COMPLEX LGP895.AGBRWH ZZ:Without Color P895 USP Film	
6	ADB048600	Dome Assembly,Metal	ADB73838501	LGF100S.ASKTBK ZZ:Without Color Side key Dome Sheet	
6	MGJ000000	Plate	MGJ63372301	PRESS SUS press LGF100S.ASKTBK ZZ:Without Color Side key FPCB Sus	
6	MJN000000	Tape	MJN68146301	COMPLEX LGF100S.ASKTBK ZZ:Without Color Power key FPCB Tape 0.05T	
6	MJN000001	Tape	MJN68104401	COMPLEX LGF100S.ASKTBK ZZ:Without Color Power key FPCB Tape 0.05T	
6	ADB048600	Dome Assembly,Metal	ADB73838401	LGF100S.ASKTBK ZZ:Without Color Dome Sheet with Actuator	
6	MGJ000000	Plate	MGJ63387901	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
6	MJN000002	Tape	MJN68146401	COMPLEX LGF100S.ASKTBK ZZ:Without Color Power key FPCB Tape 0.1T	
6	MJN000000	Tape	MJN68327101	COMPLEX LGP895.ADEUWH ZZ:Without Color -	
6	MJN000002	Tape	MJN68296502	COMPLEX LGP895.AFRAWH ZZ:Without Color P895 TAPE, LED 2	
6	MJN000001	Tape	MJN68296501	COMPLEX LGP895.AFRAWH ZZ:Without Color P895 TAPE, LED 1	
6	MEV000000	Insulator	MEV64190801	COMPLEX LGF100S.ASKTBK ZZ:Without Color LED FPCB OPTION INSULATOR 1	
6	MDS000003	Gasket	MDS63978501	COMPLEX LGF100S.ASKTBK ZZ:Without Color LED FPCB GASKET TAPE 3 - CT41XP	
6	MDS000004	Gasket	MDS63978401	COMPLEX LGF100S.ASKTBK ZZ:Without Color LED FPCB GASKET TAPE- CT41XP	
6	MDS000000	Gasket	MDS63942201	COMPLEX LGF100S.ASKTBK ZZ:Without Color LED FPCB GASKET TAPE 2 - CT41XP	
6	MCQ000001	Damper	MCQ67211802	COMPLEX LGP895.AFRAWH ZZ:Without Color P895 PAD LED 2	
6	MCQ000000	Damper	MCQ67211801	COMPLEX LGP895.AFRAWH ZZ:Without Color P895 PAD LED 1	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
7	ANT1002 ANT1003 CN105 CN106	Contact	MCIZ0008201	COMPLEX LG-VN530 VRZ DW:DARK BROWN PRESS, BeCu, , 3.0, 1.5, 1.5,	
6	MJN000001	Tape	MJN68152101	COMPLEX LGF100S.ASKTBK ZZ:Without Color EAR JACK FPCB ASSY_ TAPE	
6	MJN000000	Tape	MJN68104501	COMPLEX LGF100S.ASKTBK ZZ:Without Color Earjack FPCB tape	
6	ADB048600	Dome Assembly,Metal	ADB73838601	LGF100S.ASKTBK ZZ:Without Color Earjack FPCB Dome Sheet with Actuator	
4	GMEY00	Screw,Machine	GMEY0013901	BH + 1.4mM 4mM MSWR FZB N - ARIMA COMMUNICATIONS CORP.	
4	GMEY01	Screw,Machine	GMEY0014301	GMEY0014301 BH + 1.4mM 3.5mM MSWR NI PLT N - KUMGANG SCREW CO., LTD	
4	MCQ00	Damper	MCQ67024301	COMPLEX LGF100S.ASKTBK ZZ:Without Color F100_pad_gasket	
4	MCQ01	Damper,Camera	MCQ67230701	CUTTING PSR LGP895.AGBRWH ZZ:Without Color P895 GASKET PAD, MAIN CAMERA	
4	MRDY00	Reinforce	MRDY0000601	S5100 CEA LB,WA,COMPLEX, (empty), , , ,	
4	ABH01	Button Assembly	ABH74480211	LGP895.AGBRBK ZY:Color Unfixed P895 power button assy	
5	MBG000000	Button	MBG64563211	PRESS STS 0.3 LGP895.AGBRBK ZZ:Without Color P895 Button, Power (Metal)	
5	MBG000001	Button	MBG64570411	MOLD PC LGP895.AGBRBK ZZ:Without Color P895 BUTTON, POWER MOLD	
4	GMEY02	Screw,Machine	GMEY0010601	GMEY0010601 BH + 1.4mM 2.5mM MSWR FZB N - KUMGANG SCREW CO., LTD	
4	MAZ00	Bracket	MAZ63484001	PRESS STS 0.5 LGF100S.ASKTBK ZZ:Without Color -	
4	MBL00	Cap,Receptacle	MBL65258401	PRESS STS 0.5 LGF100S.ASKTBK BK:BLACK BLACK -	
4	MBL01	Cap	MBL65258511	MOLD URETHANE LGP895.ADEUBK ZZ:Without Color -	
4	MBL02	Cap	MBL65258601	MOLD URETHANE LGF100S.ASKTBK ZZ:Without Color -	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
4	MBL03	Cap	MBL65277401	MOLD URETHANE LGF100S.ASKTBK ZZ:Without Color -	
4	MCQ02	Damper	MCQ66917411	COMPLEX LGP895.ADEUBK ZZ:Without Color -	
4	MCQ03	Damper	MCQ67024801	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
4	MCQ04	Damper	MCQ67226201	COMPLEX LGVS950.AVRZBK ZZ:Without Color VS950 Pad Frame Side	
4	MDS00	Gasket	MDS63934911	COMPLEX LGVS950.AVRZBK ZZ:Without Color VS950 GASKET, LCD 1	
4	MDS01	Gasket	MDS63973901	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
4	MEV00	Insulator	MEV64161801	COMPLEX LGF100S.ASKTBK ZZ:Without Color F100_insulator_earjack	
4	MJN01	Tape,Protect	MJN68124701	COMPLEX LGF100S.ASKTBK ZZ:Without Color F100_Tape_Protection_Window	
4	MJN02	Tape	MJN68134201	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
3	ACQ01	Cover Assembly,Rear	ACQ86088621	LGP895.ADEUBK BK:Black P895 Cover Assy, Rear	
4	ACQ105800	Cover Assembly Rear(SVC)	ACQ86285202	LGP895.AGBRBK ZZ:Without Color P895 COVER ASSY, REAR (SVC) BK	
5	MKC009400	Window,Camera	MKC64339201	MOLD PC LGF100S.ASKTBK ZZ:Without Color -	
5	MEZ000900	Label,After Service	MLAB0004801	COMPLEX LG-LB3300 LGT ZZ:Without Color -	
5	MJN000000	Tape	MJN68078501	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MFB029600	Lens,Flash	MFB62853201	MOLD PMMA LGF100S.ASKTBK ZZ:Without Color -	
5	MCR000000	Decor	MCR64768101	CASTING AL LGF100S.ASKTBK ZO:ZOUGE -	
5	MCQ009400	Damper,Camera	MCQ66916501	CUTTING PSR LGF100S.ASKTBK ZZ:Without Color -	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
5	MCQ049800	Damper, Motor	MCQ66916401	CUTTING PSR LGF100S.ASKTBK ZZ:Without Color -	
5	MAZ000001	Bracket	MAZ63492501	PRESS STS 304 0.15T LGF100S.ASKTBK ZZ:Without Color -	
5	MAZ000000	Bracket	MAZ63464101	PRESS STS 0.3 LGF100S.ASKTBK ZY:Color Unfixed -	
5	MJN020800	Tape, Decor	MJN68078601	COMPLEX LGF100S.ASKTBK ZZ:Without Color -	
5	MCK063300	Cover, Rear	MCK67126011	MOLD PC LGP895.ADEUWH ZZ:Without Color P895 Cover Rear, White	
4	ACQ004100	Cover Assembly, Battery	ACQ86069232	LGP895.AFRABK BK:BLACK BLACK P895 Cover Assy, Battery (France) BK	
5	MJN061100	Tape, Protect	MJN68171912	COMPLEX LGP895.AFRABK ZZ:Without Color P895 Tape, Protection BC (Black)	
5	ACQ105900	Cover Assembly Battery(Sub)	ACQ86137221	LGP895.ADEUBK BK:BLACK BLACK P895 COVER ASSY, BATTERY, SUB, BLACK	
6	MCK004100	Cover, Battery	MCK67241501	MOLD PC LUPOY SC-1004A LGP895.ADEUBK BK:BLACK BLACK P895 Cover Battery	
6	MAZ000000	Bracket	MAZ63484102	PRESS STS 0.5 LGVS950.AVRZBK ZZ:Without Color VS950 Insert, Battery Cover	
5	MBL04	Cap, Multimedia Card	MBL65337121	COMPLEX LGP895.ADEUBK BK:BLACK BLACK P895 Cap, Micro Sim	
5	MCR000000	Decor	MCR64787101	PRESS STS 0.3 LGF100S.ASKTBK ZZ:Without Color -	
5	MEZ000000	Label	MEZ63801601	COMPLEX LGC900N.ASFRBK ZZ:Without Color -	
5	ABM00	Can Assembly, Shield	ABM73916301	LGP895.AGBRWH ZY:Color Unfixed P895 Can Assy, Shield	
6	MBK070300	Can, Shield	MBK63236521	PRESS STS 0.3 LGP895.ADEUBK ZY:Color Unfixed P895 Can, Shield	
6	MEV000000	Insulator	MEV64314001	COMPLEX LGP895.AGBRWH ZZ:Without Color P895 Insulator Can	
6	MBK070301	Can, Shield	MBK63393401	PRESS SUS 301 0.08 LGP895.AGBRWH ZY:Color Unfixed P895 Can, Shield Gasket	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
5	MCQ000000	Damper	MCQ67037101	COMPLEX LGVS950.AVRZBK ZZ:Without Color -	
5	MEZ000000	Label	MLAZ0038301	COMPLEX LG-VX6000 ZZ:Without Color PID Label 4 Array PRINTING,	
6	ANT10000 ANT10001	Contact	MCIZ0008701	COMPLEX L-04C, ANTTWV ZZ:Without Color PRESS, YCUT-FX, 4.2, 2.5, 1.5,	
1	AAD000000	Addition Assembly	AAD86162301	LGP895.AFRABK BK:Black -	
2	MBV000000	Clip	MBV62361601	PRESS STS press LGF100S.ASKTBK ZZ:Without Color OPENER CAP SIM	
2	MGD000000	Stylus Pen	MGD62284611	COMPLEX LGP895.AFRABK BK:BLACK BLACK P895 Stylus Pen	
1	AGF000000	Package Assembly	AGF76644701	LGP895.AFRABK ZZ:Without Color P895 FRA(G1C/FRA USP Label/Seal 2ea/640ea)	
2	MAY047100	Box,Master	MAY65442215	COMPLEX LGP895.AFRAWH ZZ:Without Color P895_G1C (10EA) Master box For Global (GSM)	
2	AAZ084000	Box Assembly,Unit	AAZ73875904	LGP895.AFRAWH ZZ:Without Color P895 Unit Box_Hard Case Assembly (G1C Type)	
3	MAY084001	Box,Unit	MAY65777501	BOX Paper 1 1 1 MULTI COLOR LGP895.ANLDWH ZZ:Without Color LGP895_Hard Case_Upper_G1C	
3	MAY084000	Box,Unit	MAY65777502	BOX Paper 1 1 1 MULTI COLOR LGP895.ANLDWH ZZ:Without Color LGP895_Hard Case_Lower_G1C	
2	MEZ000000	Label	MLAZ0050901	COMPLEX KU990.AGBRBK ZZ:Without Color Battery Warning Label (Lithium ion Battery Label)	
2	MEZ084000	Label,Unit	MLAP0001138	PRINTING LG-RD6100 RLC ZZ:Without Color GSM standard_Seal label	
2	MEZ047200	Label,Master Box	MLAJ0004402	PRINTING CG300 CGR DG ZZ:Without Color LABEL MASTER BOX(for CGR TDR 2VER. mbox_label) GSM standard_master box label	
2	MEZ084101	Label,Unit Box	MEZ64780802	COMPLEX LGP895.AFRABK ZZ:Without Color LG- P895 FRA USP Label (French)	
2	MEZ084100	Label,Unit Box	MEZ64686901	COMPLEX LGP880.ADEUBK ZZ:Without Color UBox Bar_LGP880_STD	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
2	AGJ000000	Pallet Assembly	AGJ73518301	LGP895.AFRABK ZZ:Without Color G1C STD Palletizing_640ea	
3	MAY010800	Box, Carton	MAY65799001	COMPLEX LGP895.AFRABK ZZ:Without Color G1C Type_STD Body_For 1200*800	
3	MCQ000000	Damper	MCQ66486917	COMPLEX LGP895.AFRABK ZZ:Without Color G1C STD Dead Space Sleeve(640EA/1200*800 PALLET)	
3	MBL007000	Cap, Box	MBL65400401	COMPLEX LGP895.AFRABK ZZ:Without Color G1C Type_Cap_For 1200*800	
3	MGA000000	Pallet	MPCY0012403	COMPLEX KG800 FRABK DB:DARK BLUE -	

13. EXPLODED VIEW & REPLACEMENT PART LIST

13.2 ReplacementParts

<Main component>

Note: This Chapter is used for reference, Part order is ordered by SBOM standard on GCSC

Level	LocationNo.	Description	PartNumber	Spec	Remark
3	EBP00	Camera Module	EBP61601901	C8AA-Y412A C8AA-Y412A 8M AF(VCM), Sony(1/4") BSI, 8.5x8.5x4.75t, MIPI, FPCB, 0 degree LG INNOTEK CO., LTD	
4	EAB00	Speaker Module	EAB62691301	EME1810DE08 Nd-Fe-B 700mW 8OHM 90DB 1.15KHZ 69.7x50.7x4.05 FPCB EM-TECH	
5	EBD030100	Touch Window Assembly	EBD61445701	T09ALF05001B CAPACITIVE TOUCH G/G S7020(Synaptics) 5" B to B - Kyoshin Technosonic(Korea)Co.,LTD.	
4	EAC00	Rechargeable Battery,Lithium Polymer	EAC61798903	BL-T3 (BR) Li-Polymer 3.7V 2AH 400mAH 61.3x68.5x4.38 61.5x70x4.5 BLACK Embedded CKD LG Chem,LTD.	
4	EAB01	Receiver	EAB62668301	EMR1307SWB1P 30mW 32OHM 104DB 300HZTO3.4KHZ PIN - EM-TECH	
4	EAD00	Cable,Assembly	EAD62091001	80388-202B-102L-01 UFL-LP-066 UFL-LP-066 0.11M 2 BLACK N N I-PEX CO., LTD	
4	EAJ00	LCD,Module-TFT	EAJ61968401	TX13D100VM0EAA WXGA 5.0INCH 1024X768 650CD COLOR 70% 4/3 800:1 - Inverter N - - - HITACHI DISPLAYS.,LTD	
4	EAU00	Motor,DC	EAU61644401	MVMU-A360FG 2V 90mA 90mA 0RPM 0RPM 60mSEC 0GF.CM 26OHM LG INNOTEK CO., LTD	
4	EBP01	Camera Module	EBP61341901	C1FA-M383A C1FA-M383A 1.26M HD, Aptina 1/6" MIPI, FPCB 0deg. LG INNOTEK CO., LTD	
4	EBR00	PCB Assembly,Flexible	EBR74704001	LGF100S.ASKTBK 1.0 Flexible	
5	EBR070100	PCB Assembly Flexible,Insert	EBR75361601	LGF100S.ASKTBK 1.1 Flexible	
5	EBR070400	PCB Assembly Flexible,SMT	EBR74704101	LGF100S.ASKTBK 1.0 Flexible	
6	EBR070300	PCB Assembly Flexible,SMT Top	EBR74704201	LGF100S.ASKTBK 1.0 Flexible	
7	EAX010500	PCB,Sidekey	EAX64664601	LGF100S.ASKTBK 1.0 POLYI Multi 2 0.18 Sidekey	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
7	CN100	Connector,BtoB	ENBY0050901	GB042-10P-H10-E3000 10P 0.4MM STRAIGHT MALE SMD R/TP 1M - LS Mtron Ltd.	
4	EBR01	PCB Assembly,Flexible	EBR74704401	LGF100S.ASKTBK 1.0 Flexible	
5	EBR070100	PCB Assembly Flexible,Insert	EBR75361701	LGF100S.ASKTBK 1.1 Flexible	
5	EBR070400	PCB Assembly Flexible,SMT	EBR74704501	LGF100S.ASKTBK 1.0 Flexible	
6	EBR070300	PCB Assembly Flexible,SMT Top	EBR74704601	LGF100S.ASKTBK 1.0 Flexible	
7	EAX010500	PCB,Sidekey	EAX64664701	LGF100S.ASKTBK 1.1 POLYI Multi 2 0.18 Sidekey	
7	LD100	LED,Chip	EDLH0011901	SSC-TWH104-HL WHITE 2.7~3.1 20mA 100~220mcd X(0.24~0.34) Y(0.25~0.34) 66mW 1608 R/TP 2P - SEOUL SEMICONDUCTOR CO.,LTD	
7	CN100	Connector,BtoB	ENBY0050901	GB042-10P-H10-E3000 10P 0.4MM STRAIGHT MALE SMD R/TP 1M - LS Mtron Ltd.	
4	EBR02	PCB Assembly,Flexible	EBR75853301	LGP895.ADEUBK 1.0 Flexible	
5	EBR070100	PCB Assembly Flexible,Insert	EBR75695711	LGP895.AGBRWH 1.0 Flexible	
5	EBR070400	PCB Assembly Flexible,SMT	EBR75905801	LGP895.ADEUBK 1.0 Flexible	
6	EBR070300	PCB Assembly Flexible,SMT Top	EBR75905901	LGP895.ADEUBK 1.0 Flexible	
7	EAX010700	PCB,Flexible	EAX64881201	LGP895.ADEUBK 1.0 POLYI Multi 4 0.3 Flexible	
7	LD100 LD101 LD102 LD103	LED,Chip	EDLH0014801	SWAA0B SWAA0B SWAF0B,WHITE ,ETC ,R/TP ,0.4t SEOUL SEMICONDUCTOR CO.,LTD SEOUL SEMICONDUCTOR CO.,LTD	
7	R100 R101 R102 R103	Resistor,Chip	ERHZ0000464	MCR01MZP5J331 330OHM 5% 1/16W 1005 R/TP - ROHM.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
7	MIC100	Microphone Condenser	SUMY0010616	SUMY0010616 FPCB,dB,1.1TO10V, KNOWLES ACOUSTICS	
7	C110	Capacitor Ceramic,Chip	ECZH0000830	C1005C0G1H330JT000F 33pF 5% 50V NP0 - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
7	C109	Capacitor Ceramic,Chip	ECZH0003103	GRM36X7R104K10PT 100nF 10% 10V X7R - 55TO+125C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	EBR070200	PCB Assembly Flexible,SMT Bottom	EBR75853401	LGP895.ADEUBK 1.1 Flexible	
7	D100 D101	Diode,TVS	EAH61693001	uClamp0541Z 5V 6V min 12V 2A 30W SLP0603P2X3 R/TP 2P 1 SEMTECH INTERNATIONAL AG	
7	SW100	Connector,RF	ENWY0005501	20279-001E-01 NONE STRAIGHT SOCKET SMD R/TP AU 50OHM 400mDB I-PEX CO., LTD	
7	CN100	Connector,BtoB	EAG63013801	GB042-14P-H10-E3000 14P 0.40MM STRAIGHT PLUG SMD R/TP 1M - LS Mtron Ltd.	
7	C108	Capacitor Ceramic,Chip	ECCH0009506	MCH032A270JK 27pF 5% 25V NP0 -55TO+125C 0603 R/TP - ROHM.	
7	C103 C112	Capacitor Ceramic,Chip	ECZH0000813	C1005C0G1H101JT 100pF 5% 50V C0G - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
7	C107	Capacitor Ceramic,Chip	ECCH0000182	GRM155R61A104K 0.1uF 10% 10V X5R - 55TO+85C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
7	FB100	Filter,Bead	SFBH0007101	BLM15AG121SN1D 120 ohm 1.0X0.5X0.5 25% 0.25 ohm 0.5A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
4	EBR03	PCB Assembly,Flexible	EBR76029501	LGP895.ADEUWH 1.0 Flexible	
5	EBR070100	PCB Assembly Flexible,Insert	EBR75379411	LGP895.AGBRWH 1.1 Flexible	
5	EBR070400	PCB Assembly Flexible,SMT	EBR76047201	LGP895.ADEUWH 1.0 Flexible	
6	EBR070300	PCB Assembly Flexible,SMT Top	EBR76029701	LGP895.ADEUWH 1.0 Flexible	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
7	EAX010700	PCB,Flexible	EAX65023501	LGP895.ADEUWH 1.0 POLYI SBL 4 0.3 Flexible	
7	U100	IC,Ambient Light Sensor	EUSY0431901	APDS-9900 - - - - - AVAGO TECHNOLOGIES INTERNATIONAL SALES PTE. LIMITED	
7	MIC100	Microphone,Condenser	SUMY0010609	SPU0410HR5H -PB SPU0410HR5H -PB SPU0410HR5H -PB,UNIT , -42 dB,3.76*2.95*1.1 ,mems smd mic KNOWLES ACOUSTICS KNOWLES ACOUSTICS	
7	CN100	Connector,BtoB	ENBY0034101	GB042-24P-H10-E3000 24P 0.40MM STRAIGHT PLUG SMD R/TP 1M - LS Mtron Ltd.	
7	C104	Capacitor Ceramic,Chip	ECCH0009104	C0603C0G1H330JT00NN 33pF 5% 50V C0G - 55TO+125C 0603 R/TP - TDK CORPORATION	
7	C100,C101	Capacitor Ceramic,Chip	ECCH0017301	CL03A105MQ3CSNH 0.000001F 20% 6.3V X5R - 45TO+85C 0603 R/TP - SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	EBR070200	PCB Assembly Flexible,SMT Bottom	EBR76029601	LGP895.ADEUWH 1.0 Flexible	
7	C103 C105	Capacitor Ceramic,Chip	ECCH0009228	GRM033R61A472K 4700pF 10% 10V X5R - 55TO+85C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
7	C104	Capacitor Ceramic,Chip	ECCH0009104	C0603C0G1H330JT00NN 33pF 5% 50V C0G - 55TO+125C 0603 R/TP - TDK CORPORATION	
7	D100 D101	Diode,TVS	EAH61693001	uClamp0541Z 5V 6V min 12V 2A 30W SLP0603P2X3 R/TP 2P 1 SEMTECH INTERNATIONAL AG	
7	FB100 FB101 FB103	Filter,Bead	SFBH0008102	BLM15HD182SN1D 1800 ohm 1.0X0.5X0.5 25% 2.2 ohm 0.2A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
7	J100	Jack,Phone	EAG63070601	KJA-PH-4-0176 5P 2P ANGLE R/TP 3.5M BLACK 5P - KSD CO., LTD	
5	EAA030100	PIFA Antenna Bluetooth	EAA62944801	LS01-I-12036-A0 DUAL -4DB 4 FPCB Type - BT Tape LS Mtron Ltd.	
5	EAA030101	PIFA Antenna,GPS	EAA62945001	LS01-I-12031-A0 DUAL -4DB 4 FPCB Type - GPS Tape LS Mtron Ltd.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
3	EAA00	Antenna Assembly	EAA62944904	LS04-I-12080-A0 LGP895.ADEUWH Black Black NFC NFC FPCB Tape LS Mtron Ltd.	
3	EBR04	PCB Assembly,Main	EBR76049003	LGP895.AFRABK 1.0 Main	
4	EBR071500	PCB Assembly Main,Insert	EBR76057201	LGP895.AGBRWH 1.0 Main	
4	EBR071800	PCB Assembly Main,SMT	EBR76126603	LGP895.AFRAWH 1.0 Main	
5	EBR071600	PCB Assembly Main,SMT Bottom	EBR75886001	LGP895.ADEUBK 1.1 Main	
6	C11029	Capacitor Ceramic,Chip	ECCH0042201	CL03C020CA3GNNH 2pF 0.25PF 25V C0G - 55TO+125C 0603 R/TP 0.3+-0.03 SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C10048 C10049	Capacitor Ceramic,Chip	ECCH0000122	MCH155A470JK 47pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	C1035 C1048	Inductor Multilayer,Chip	ELCH0001035	HK1005 4N7S-T 4.7NH 0.3NH - 300mA 0.21OHM 4GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP TAIYO YUDEN CO.,LTD	
6	C1047 C1050	Capacitor Ceramic,Chip	ECCH0000133	C1005X7R1H221KT000F 0.22nF 10% 50V X7R - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	VA13000 VA13001	Diode,TVS	EDTY0010101	ESD9B5.0ST5G 5V 5.8V min. 12.5V 1A - SOD-923 R/TP 2P 1 SCG HONG KONG SAR LTD.	
6	C1031	Inductor Multilayer,Chip	ELCH0001412	LL1005-FHL1N8S 1.8NH 0.3NH - 400mA 0.14OHM 15GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP TOKO, INC.	
6	C1051	Capacitor Ceramic,Chip	ECCH0000110	MCH155A100D 10pF 0.5PF 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	C5029 C5030	Capacitor Ceramic,Chip	ECCH0042007	GRM0335C1E6R8BD01D 6.8 pF,25V,B,C0G,TC,0603,R/TP,0.00000000000068,0. 1PF,25V,C0G,-55TO+125C,0603,R/TP,0.3 mm MURATA MANUFACTURING CO.,LTD.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C11011 C4003 C4007 C4012 C4013 C4015 C4025 C4027 C4048 C4050 C5027 C5028	Capacitor Ceramic,Chip	ECCH0005604	GRM188R60J106M 10000000 pF,6.3V,M,X5R,TC,1608,R/TP,0.8 mm MURATA MANUFACTURING CO.,LTD.	
6	C11026	Capacitor Ceramic,Chip	ECCH0042002	GRM0335C1E1R2BD01D 1.2pF 0.1PF 25V C0G - 55TO+125C 0603 R/TP 0.3+-0.03 MURATA MANUFACTURING CO.,LTD.	
6	C10002 C10008 C10011 C10021 C10042 C10043 C10044 C10053 C1023 C1072 C13016 C4028 C6015 C6016 C6017 C6018 C6032 C8004 C8005 C8006 C9005 C9008 C9010 C9011 C9019 C9021 C9022	Capacitor Ceramic,Chip	ECCH0017301	CL03A105MQ3CSNH 0.000001F 20% 6.3V X5R - 45TO+85C 0603 R/TP - SAMSUNG ELECTRO- MECHANICS CO., LTD.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C10009 C10041 C10052 C1079 C11009 C5001 C5008 C5009 C5010 C5011 C5014 C5015 C5019 C5026	Capacitor Ceramic,Chip	EAE62762301	CL03A105MP3NSNC 1uF 20% 10V X5R - 55TO+85C 0603 R/TP 0.33 MM - SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C11007 C11008 C11010 C6005 C6013	Capacitor Ceramic,Chip	EAE62506501	CL05A475MP5NRNC 4.7uF 20% 10V X5R - 55TO+85C 1005 R/TP - - SAMSUNG ELECTRO- MECHANICS CO., LTD.	
6	D13000 D13001 D13002 D9000 D9001	Diode,TVS	EAH61794301	ESD5205P6T6G 5V 5.5V min. 10V 2UA 0W SOT- 963 R/TP 6P 5 ON SEMICONDUCTOR	
6	C1040 C1070	Capacitor Ceramic,Chip	ECZH0001216	C1005X5R1A224KT000E 220nF 10% 10V X5R - 55TO+85C 1005 R/TP - TDK KOREA COOPERATION	
6	C10039 C1030 C1044 C1061 C13003 C6008 C6014	Capacitor Ceramic,Chip	ECCH0009106	C0603X7R1C103KT 10nF 10% 10V X7R - 55TO+125C 0603 R/TP - TDK CORPORATION	
6	L5002	Inductor,Wire Wound,Chip	EAP62107701	1269AS-H-1R0M=P2 1UH 20% - 2.7A 2.7(max) 3.4(typ) 2.5(max) 3.0(typ) 0.06OHM - - SHIELD 2.5X2.0X1.0 MM - R/TP TOKO, INC.	
6	R13005 R13006	Resistor,Chip	ERHY0042403	RC0201JR-07130RL 130OHM 5% 1/20W 0603 R/TP - YAGEO CORPORATION	
6	C1080 C6007	Capacitor Ceramic,Chip	ECCH0009103	C0603C0G1H101JT00NN 100pF 5% 50V C0G - 55TO+125C 0603 R/TP - TDK CORPORATION	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	R10000 R10017 R1003 R11000 R11004 R13004 R13012 R13017 R2017 R3060 R4001 R4002 R8003 R8004 R9003	PCB ASSY,MAIN,PAD SHORT	SAFP0000401	LG-LU3000 LGTBK,MAIN,A,	
6	U6000	IC,Charger	EAN62109401	MAX8971EWP 4 to 14V adj 1.4W CSP R/TP 20P - MAXIM INTEGRATED PRODUCTS INC.	
6	ZD13001 ZD13002 ZD13003 ZD13005 ZD13006 ZD13008 ZD9000	Diode,TVS	EDTY0012102	PESD5V0V1BL 5V 5.8V min. 12.5V 4.8A 45W SOD-882 R/TP 2P 1 STC CORP.	
6	R13029 R3012 R3020 R3023 R3049 R4022 R5020 R6002 R6014 R6018 R9004	Resistor,Chip	ERHY0009506	MCR006YZPJ104 100KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	FL8001 FL8002 FL8003 FL9000	Filter,EMI/Power	SFEY0016301	ICMEF112P900M COMMON MODE NOISE FILTER 0HZ 0F 0H SMD R/TP INNOCHIPS TECHNOLOGY	
6	U10004	IC,Magnetic Sensor	EBD60985501	AMI306 1.7 to 3.6V - QFN R/TP 8P - AICHI STEEL CORPORATION	
6	X11000	Crystal	EAW61645401	Q22FA1280013000 37.4MHZ 10PPM 12F , SMD R/TP EPSON TOYOCOM CORP	
6	R3000 R3001 R3002 R3003 R3006 R3007	Resistor,Chip	ERHY0009586	MCR006YZPF2201 2.2KOHM 1% 1/20W 0603 R/TP - ROHM.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	SC4007 SC4102	Connector,Terminal Block	ENZY0026801	25SMT-3645-34 1P - STRAIGHT SMD R/TP - W.L.GORE & ASSOCIATES (HK) LTD.	
6	R13019	Resistor,Chip	EBC61856101	RC0201JR-0722RL 22OHM 5% 1/20W 0603 R/TP - YAGEO CORPORATION	
6	R1004	Resistor,Chip	ERHY0009502	MCR006YZPJ100 10OHM 5% 1/20W 0603 R/TP - ROHM.	
6	R5013 R5014 R5015	Resistor,Chip	ERHZ0000249	MCR01MZP5F22R0 22OHM 1% 1/16W 1005 R/TP - ROHM.	
6	X5000	Crystal	EXXY0026801	NX3215SA 32.768KHZ 20PPM 0F NONE SMD R/TP NIHON DEMPA KOGYO CO.,LTD.	
6	C10038 C6006	Capacitor Ceramic,Chip	ECCH0000143	MCH155CN102KK 1nF 10% 50V X7R -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	U1002	Module,Tx Module	SMRH0006901	RF6260 0DBM 0DB 0% 0A 0A 0DB 0DBM 0DBM 0P 0.0x0.0x0.0MM - RF MICRO DEVICES INC	
6	R3027	Resistor,Chip	ERHZ0000270	MCR01MZP5F33R0 33OHM 1% 1/16W 1005 R/TP - ROHM.	
6	R13009 R13010	Resistor,Chip	ERHY0009541	MCR006YZPF4700 470OHM 1% 1/20W 0603 R/TP - ROHM.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C1001 C1002 C10026 C1003 C10057 C1008 C1009 C1010 C1011 C1012 C1021 C1024 C1042 C13001 C13010 C4018 C4033 C4042 C4044 C4051 C5031 C5035 C5036 C9006 C9007 C9009 C9012	Capacitor Ceramic,Chip	ECCH0009101	C0603X5R0J104KT00NN 0.1uF 10% 6.3V X5R - 55TO+85C 0603 R/TP - TDK CORPORATION	
6	C1073 C1075 C13015	Capacitor Ceramic,Chip	ECCH0000198	CL05A225MQ5NSNC 2.2uF 20% 6.3V X5R - 55TO+85C 1005 R/TP . SAMSUNG ELECTRO- MECHANICS CO., LTD.	
6	C1088 C11012 C12012 C12019	Capacitor Ceramic,Chip	ECZH0000813	C1005C0G1H101JT 100pF 5% 50V C0G - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	R2018	Resistor,Chip	ERHZ0000487	MCR01MZIP5J474 470KOHM 5% 1/16W 1005 R/TP - ROHM.	
6	L11004 L11045	Inductor Multilayer,Chip	EAP62227101	LG HK 0603 1N5S-T 1.5H 0.3NH - 430mA - - 0.13OHM 10GHZ 4 SHIELD - 0.6X0.3X0.3MM R/TP TAIYO YUDEN CO.,LTD	
6	CN13001 CN9000	Connector,BtoB	ENBY0034201	GB042-24S-H10-E3000 24P 0.40MM STRAIGHT SOCKET SMD R/TP 1M - LS Mtron Ltd.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C10027 C10028 C11001 C11002 C11004 C11025 C11056 C11061 C11062 C11063 C11064 C6009	Capacitor Ceramic,Chip	ECCH0009514	MCH032A(AN)100DK 10pF 0.5PF 25V X7R - 55TO+125C 0603 R/TP - ROHM.	
6	C1000 C1005 C1006 C1007	Capacitor Ceramic,Chip	ECCH0009201	GRM033R60J473KE19D 47nF 10% 6.3V X5R - 55TO+85C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	R2015 R3065	PCB ASSY,MAIN PAD OPEN	SAFO0000401	AX3100 ATL SV_SHIPBACK,MAIN,A,0OHM DNI	
6	C11046 C11049 C11057 C11058 C11059 C11060	Capacitor Ceramic,Chip	ECCH0009212	GRM0335C1E4R7C 4.7pF 0.25PF 25V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	FB1001 FB11003 FB8000	Filter,Bead	EAM62071101	BLM15PD121SN1D 120 ohm 1.0X0.5X0.5 25% 0.09 ohm 1.3A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	C1022 C11005 C11006 C11024 C4001 C4005 C4010 C4017 C4034 C4045 C4047 C9020	Capacitor Ceramic,Chip	ECCH0017601	CL05A475MQ5NRNC 4.7uF 20% 6.3V X5R - 55TO+85C 1005 R/TP 0.5MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C13006	Capacitor Ceramic,Chip	ECCH0000182	GRM155R61A104K 0.1uF 10% 10V X5R - 55TO+85C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C6002	Capacitor Ceramic,Chip	ECZH0003503	GRM188R61E105K 1uF 10% 25V X5R -55TO+85C 1608 R/TP - MURATA MANUFACTURING CO.,LTD.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C1053	Inductor Multilayer,Chip	ELCH0003847	LQG15HS1N8S02D 1.8NH 0.3NH - 300mA 0.1OHM 6GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	C11023 C13009	Capacitor Ceramic,Chip	ECZH0025916	GRM0335C1E330J 33pF 5% 25V NP0 - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C5006 C5007	Capacitor Ceramic,Chip	ECCH0007802	CL10A475KP8NNNC 4.7uF 10% 10V X5R - 55TO+85C 1608 R/TP - - SAMSUNG ELECTRO- MECHANICS CO., LTD.	
6	L10000 L10001	Inductor Multilayer,Chip	EAP62167601	MLG1608SR39JT 390NH 5% - 1mA - - 3OHM 300MHZ 10 SHIELD 0 1.6X0.8X0.8MM R/TP TDK KOREA COOPERATION	
6	R13014	Resistor,Chip	ERHY0042402	RC0201JR-0715KL 15KOHM 5% 1/20W 0603 R/TP - YAGEO CORPORATION	
6	U10005 U10008	IC,LDO Voltage Regulator	EUSY0410201	BU30TD4WNVX ROHM.	
6	R11001	Resistor,Chip	ERHZ0000221	MCR01MZP5F1502 15KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	CN11000 CN11001 CN12000 CN12001	Contact	MCIZ0008401	COMPLEX LG-C900 ATTDW ZZ:Without Color PRESS, BeCu, , 3.0, 1.2, 1.5,	
6	VA5001	Varistor	SEVY0003601	ICVL0505101V150FR 5.6V 0% 100pF 1.0*0.5*0.55 NONE SMD R/TP INNOCHIPS TECHNOLOGY	
6	R13015 R3022 R3052 R3054 R3068 R4018 R4019 R4020 R4021	Resistor,Chip	ERHY0009505	MCR006YZPJ103 10KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	C6010	Capacitor Ceramic,Chip	ECCH0009213	GRM0335C1E6R0D 6pF 0.5PF 25V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C11051	Capacitor Ceramic,Chip	ECCH0000112	MCH155C150J 15pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C1028	Capacitor Ceramic,Chip	ECCH0009228	GRM033R61A472K 4700pF 10% 10V X5R - 55TO+85C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	FB13000	Filter,Bead	SFBH0007101	BLM15AG121SN1D 120 ohm 1.0X0.5X0.5 25% 0.25 ohm 0.5A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	R13002 R6003	Resistor,Chip	ERHY0024601	RC0603J151CS 150OHM 5% 1/20W 0603 R/TP - SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C1025 C1041 C1068 C11003 C11015 C11021 C11028 C11030 C11040 C11053 C5012 C5037	Capacitor Ceramic,Chip	EAE62286801	CL03A104KP3NNNC 0.0000001F 10% 10V X5R - 55TO+85C 0603 R/TP 0.3 - SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C1004 C1078 C11020 C5000 C5002 C5013 C5034 C6019	Capacitor Ceramic,Chip	ECCH0007804	CL05A225MP5NSNC 2.2uF 20% 10V X5R - 55TO+85C 1005 R/TP 0.5MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C4000	Capacitor,Low ESL	EAE62781601	LLL153C70G474ME17E 0.47uF 20% 4V X7S - 55TO+125C 1005 R/TP 0.35T MAX. MURATA MANUFACTURING CO.,LTD.	
6	C5003 C5004 C5005	Capacitor Ceramic,Chip	ECCH0005603	GRM188R61A225K 2.2uF 10% 10V X5R - 55TO+85C 1608 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C10047 C10050	Capacitor Ceramic,Chip	ECZH0000841	C1005C0G1H560JT000F 56pF 5% 50V NP0 - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	C1077	Capacitor TA,Polymer	EAE62682901	TCTOM1A225M8R 2.2uF 20% 10V 2.2UA - 55TO+105C 0.8OHM 1.6X0.85X0.9MM : 1.6X0.85X0.9MM NONE SMD R/TP 0.9 MM max. ROHM CO.,LTD.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	U11000	Filter Separator,FEM	SMZY0028001	RF5501 - - - RF5501,QFN,12p,2.0*2.0*0.5,SP3T+LNA for BT/WiFi with BCM4325/29/30 RF MICRO DEVICES INC	
6	L5000 L5001 L6000	Inductor,Wire Wound,Chip	ELCP0014301	1239AS-H-1R0N=P2 1UH 30% - 2.3A 3.0 2.3 0.059OHM - - SHIELD 2.5X2.0X1.2MM NONE R/TP TOKO, INC.	
6	R10015	Resistor,Chip	ERHZ0000437	MCR01MZIP5J202 2KOHM 5% 1/16W 1005 R/TP - ROHM.	
6	C10014 C1069 C1071 C9023 C9024	Capacitor Ceramic,Chip	ECCH0007803	CL10A106MP8NNNC 10uF 20% 10V X5R - 55TO+85C 1608 R/TP 0.8MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	L11003	Inductor Multilayer,Chip	EAP61747501	LQP03TN3N6B02D 3.6NH 0.1NH - 400mA - - 0.30HM 6GHZ 14 SHIELD NONE 0.6X0.3X0.3MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	CN6000	Connector,Terminal Block	EAG63110101	WB22457-1404-7F 4P 2.00MM STRAIGHT SMD R/TP Invaded Battery connector FOXCONN	
6	Q13000	TR,Bipolar	EQBN0013701	NPN 6V 15V 12V 500mA 100mA 680 150mW EMT6 R/TP 6P	
6	C1043 C13004	Capacitor Ceramic,Chip	ECCH0009506	MCH032A270JK 27pF 5% 25V NP0 -55TO+125C 0603 R/TP - ROHM.	
6	C10034 C10035	Capacitor Ceramic,Chip	ECCH0000137	C1005X7R1H331KT000F 0.33nF 10% 50V X7R - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	U10000	IC,NFC	EUSY0397201	PN544 2.3~5.5V 61mA NFC 66P - TFBGA R/TP 66P NXP Semiconductors	
6	L1025 L9001	Inductor,Wire Wound,Chip	ELCP0009408	LQM2HPN1R0MG0 1UH 20% - 1A 1 1.6 0.055OHM - - SHIELD 2.5X2X1MM NONE R/TP MURATA MANUFACTURING CO.,LTD.	
6	C6025	Capacitor Ceramic,Chip	EAE62505701	CL10A105KB8NNNC 1uF 10% 50V X5R - 55TO+85C 1608 R/TP 0.9T max. - SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	L7002 L7003	Inductor Multilayer,Chip	ELCH0003825	LQG15HS56NJ02D 56NH 5% - 200mA 0.82OHM 800MHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP MURATA MANUFACTURING CO.,LTD.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	VA8000 VA8001	Varistor	SEVY0010501	IECS0505C040FR 10V 0% 4E-12F 1.0x0.5x0.3 IEC61000-4-1 (ESD) level #4 SMD R/TP INNOCHIPS TECHNOLOGY	
6	C10032 C10037	Capacitor Ceramic,Chip	ECCH0000127	MCH155A820J 82pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	FL1001	Filter,Separator	EAM62450101	LMSP3XQS-C48 , , , 850,900,1800,1900,SP8T(SPI),3.2x2.8x1.0 MURATA MANUFACTURING CO.,LTD.	
6	C6011	Capacitor TA,Conformal	ECTH0002703	TCTAL1A107M8R-V2 100uF 20% 10V 50UA - 55TO+125C 2.5OHM 3.2X1.6X1.1MM NONE SMD R/TP 1.2T max. ROHM CO.,LTD.	
6	CN9001	Connector,BtoB	ENBY0039601	GB042-20S-H10-E3000 20P 0.4MM STRAIGHT SOCKET SMD R/TP 1M - LS Mtron Ltd.	
6	C1052	Inductor Multilayer,Chip	ELCH0001403	LL1005-FHL1N0S 1NH 0.3NH - 400mA - - 0.1OHM 20GHZ 7 SHIELD NONE 1.0X0.5X0.5MM R/TP TOKO, INC.	
6	C1029	Capacitor Ceramic,Chip	ECCH0009110	C0603X7R0J223KT 22nF 10% 6.3V X7R - 55TO+125C 0603 R/TP - TDK CORPORATION	
6	ZD10000 ZD10001	Diode,TVS	EDTY0012101	PESD5V0F1BL 5.5V 6V min 11V 2.5A - SOD-882 R/TP 2P 1 STC CORP.	
6	L5003 L5004	Inductor,Wire Wound,Chip	EAP62187401	MAKK2016T1R0M 1UH 20% - 2.2A 2.2 2.45 0.075OHM - - SHIELD 2.0X1.6X1.0MM - R/TP TAIYO YUDEN CO.,LTD	
6	C10040 C13019 C6000	Capacitor Ceramic,Chip	ECZH0003103	GRM36X7R104K10PT 100nF 10% 10V X7R - 55TO+125C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	X10000	Resonator Ceramic	EAW61644701	XRCGB27M120F3M10R0 27.12MHZ 30ppm 10pF SMD R/TP 4P MURATA MANUFACTURING CO.,LTD.	
6	S13000	Card Socket	EAG63050901	SCGD1B0202 SIM 8P STRAIGHT SMD T/REEL - ALPS ELECTRIC KOREA CO.,LTD.	
6	FB11001 FB11002	Filter,Bead	EAM62070901	BLM03AX601SN1D 600 ohm 0.6X0.3X0.3 25% 0.85 ohm 0.25A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	CN13000	Connector,BtoB	EAG63013701	GB042-14S-H10-E3000 14P 0.40MM STRAIGHT SOCKET SMD R/TP 1M - LS Mtron Ltd.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	U11001	IC,WiFi	EAN62508401	BCM4330HB2KUBG WiFi 11a/b/g/n Dual Band, BT4.0, FM Rx, 5.33x4.89x0.55 WLBGA R/TP 133P BROADCOM ASIA DISTRIBUTION PTE LTD	
6	C11022	Capacitor,Ceramic, Chip	ECCH0009102	C0603X7R1H221KT 220pF 10% 50V X7R - 55TO+125C 0603 R/TP -- TDK CORPORATION	
6	L1026	Inductor,Wire Wound,Chip	EAP61785901	LQW15CN18NJ00D 18NH 5% - 1.4A -- 0.046OHM 3GHZ - SHIELD 1.0X0.5X0.5MM NONE R/TP MURATA MANUFACTURING CO.,LTD.	
6	C6003 C6004	Capacitor Ceramic,Chip	ECZH0001215	C1005X5R1A105KT000F 1uF 10% 10V X5R - 55TO+85C 1005 R/TP - TDK KOREA COOPERATION	
6	R10002 R15003	Resistor,Chip	ERHY0009507	MCR006YZPJ105 1MOHM 5% 1/20W 0603 R/TP - ROHM.	
6	FB13001	Filter,Bead	SFBH0008102	BLM15HD182SN1D 1800 ohm 1.0X0.5X0.5 25% 2.2 ohm 0.2A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	Q6002	FET	EQFN0005601	KTK5132E N-CHANNEL MOSFET 30V +-20 100mA 70HM 100mW ESM R/TP 3P KEC CORPORATION	
6	L1000 L11018 L11055	Inductor Multilayer,Chip	ELCH0001430	LL1005-FHLR10J 100NH 5% - 150mA 2.2OHM 1.03GHZ 10 SHIELD NONE 1.0X0.5X0.5MM R/TP TOKO, INC.	
6	R13024	Resistor,Chip	ERHZ0000517	MCR01MZP5J910 91OHM 5% 1/16W 1005 R/TP - ROHM.	
6	C1063	Inductor Multilayer,Chip	ELCH0001404	LL1005-FHL1N5S 1.5NH 0.3NH - 400mA 0.13OHM 15GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP TOKO, INC.	
6	C10010 C1026	Capacitor Ceramic,Chip	ECZH0025920	GRM033R71C102K 1nF 10% 16V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	D6000	Diode,TVS	EAH61872501	PESD5V0S1UA 5V 6.2V min. 9.8V 47A 360mW SOD323 R/TP 2P 1 NXP Semiconductors	
6	FB9000 FB9001 FB9002	Filter,Bead	EAM62131001	CIM05J102NC 1000 ohm 1.0X0.5X0.5 25% 0.8 ohm 0.25 SMD R/TP 2P 0 SAMSUNG ELECTRO-MECHANICS CO., LTD.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	CN4000	Connector,BtoB	ENBY0053801	24-5804-030-000-829+ 30P 0.40MM STRAIGHT FEMALE SMD R/TP 900mM - KYOCERA ELCO KOREA SALES CO.,LTD.	
6	R6009 R6010 R9000 R9005	Resistor,Chip	EBC62036001	RC0201FR-0710RL 10OHM 1% 1/20W 0603 R/TP - YAGEO CORPORATION	
6	Q10000 Q10001	FET	EBK61892201	KTK5132V N-CHANNEL MOSFET 30V +-20 100mA 7OHM 100mW VSM R/TP 3P KEC CORPORAITION	
6	R10016	Resistor,Chip	ERHY0003201	MCR01MZIP5F1001 1KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	C10025	Capacitor Ceramic,Chip	ECZH0001217	GRM155R60J474K 470nF 10% 6.3V X5R - 25TO+70C 1005 BK-DUP - MURATA MANUFACTURING CO.,LTD.	
6	R13000 R13001 R6000 R6004 R9002	Resistor,Chip	ERHY0009527	MCR006YZPJ473 47KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	C5018 C5021 C5023	Capacitor Ceramic,Chip	ECCH0017501	CL10A226MQ8NRNE 22uF 20% 6.3V X5R - 55TO+85C 1608 R/TP 0.8MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C10033 C10036 C1032 C1034 C1037 C1045	Capacitor Ceramic,Chip	ECZH0000830	C1005C0G1H330JT000F 33pF 5% 50V NP0 - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	C9025	Capacitor Ceramic,Chip	ECCH0010501	GRM1555C1H7R5D 7.5pF 0.5PF 50V C0G - 55TO+125C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C6024	Capacitor Ceramic,Chip	ECCH0000115	MCH155A220JK 22pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	FL8004 FL9001 FL9002	Filter,EMI/Power	SFEY0015901	ICMEF214P101MFR ICMEF214P101MFR ICMEF214P101MFR,SMD ,ESD Common mode Filter INNOCHIPS TECHNOLOGY INNOCHIPS TECHNOLOGY	
6	U6006	IC,Current Monitor	EAN62344201	HPA01112AIRGTR o to 28V adj 0W QFN R/TP 16P - TEXAS INSTRUMENTS KOREA LTD, HONGKONG BRANCH.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	CN13002 CN13003 CN13004	Connector,BtoB	ENBY0051001	GB042-10S-H10-E3000 10P 0.4MM STRAIGHT FEMALE SMD R/TP 1M - LS Mtron Ltd.	
6	FL11000	Filter,Separator	EAM62251301	LFD182G45DCHD277 0.54 30 - 5GHz BPF, 2.4GHz LPF MURATA MANUFACTURING CO.,LTD.	
6	R1002	Resistor,Chip	ERHY0009503	MCR006YZPJ101 100OHM 5% 1/20W 0603 R/TP - ROHM.	
6	L1003	Capacitor Ceramic,Chip	EAE62621801	C1005NPO758CGTQ 0.75pF 0.25PF 50V C0G - 55TO+125C 1005 R/TP 0.55MM DARFON ELECTRONICS CORP.	
6	U6002	IC,Fuel Gauge	EAN61958601	MAX17043G 2.5 to 4.5V Vbat 0W DFN R/TP 8P - MAXIM INTEGRATED PRODUCTS INC.	
6	C1081, C1082	Capacitor Ceramic,Chip	EAE62524201	GRM0335C1H5R6CD01 5.6pF 0.25PF 50V C0G - 55TO+125C 0603 R/TP 0.33T max. MURATA MANUFACTURING CO.,LTD.	
6	CN8000	Connector,BtoB	ENBY0040701	GB042-30S-H10-E3000 30P 0.4MM STRAIGHT FEMALE SMD R/TP 1M - LS Mtron Ltd.	
6	C1020 C1027	Capacitor Ceramic,Chip	ECZH0001108	C1005X7R1E682KT000F 6.8nF 10% 25V X7R - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	C11052	Capacitor Ceramic,Chip	ECCH0009504	MCH032A180JK 18pF 5% 25V NP0 -55TO+125C 0603 R/TP - ROHM.	
6	C6012	Capacitor Ceramic,Chip	ECCH0000368	CL21B104KBCNNNC 0.1uF 10% 50V Y5V - 30TO+85C 2012 R/TP - SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	R11003	Resistor,Chip	ERHY0009515	MCR006YZPJ221 220OHM 5% 1/20W 0603 R/TP - ROHM.	
6	L11001	Inductor,Wire Wound,Chip	ELCP0008017	CIG21L2R2MNE 2.2UH 20% - 500mA 0.5 0.95 0.16OHM - - SHIELD 2X1.25X1MM NONE R/TP SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	D5000	Diode,Schottky	EAH61794001	KDR720F 350mV 30V 100mA 5NSEC 12pF 100mW TFSC R/TP 2P 1 KEC CORPORATION	
6	VA7000 VA7001	Varistor	SEVY0004301	ICVL0518100Y500FR 18V 0% 10F 1.0*0.5*0.55 NONE SMD R/TP INNOCHIPS TECHNOLOGY	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	U1000	IC,RF Transceiver,3G	EAN62514301	PMB5712 A2 - WFWLB R/TP 138P Intel Semiconductor Ltd. c/o Intel Mobile Communications	
6	R5024 R6001	Resistor,Chip	ERHY0009504	MCR006YZPJ102 1KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	L1014	Inductor Multilayer,Chip	ELCH0001031	HK1005 15NJ-T 15NH 5% - 300mA 0.46OHM 2.3GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP TAIYO YUDEN CO.,LTD	
6	U9001	IC,DC,DC Converter	EAN61850201	LM3559TLX 2.5 to 5.5V adj 0W MICRO SMD R/TP 16P - NATIONAL SEMICONDUCTOR ASIA PACIFIC PTE. LTD.	
6	C11013	Capacitor,Ceramic, Chip	ECCH0000113	MCH155A180J 18pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	U1004	IC,DC,DC Converter	EUSY0264510	RF6560 2.9 to 5.1V adj 0W CSP R/TP 24P - RF MICRO DEVICES INC	
6	C11045	Capacitor Ceramic,Chip	ECCH0009208	GRM0335C1ER50C 0.5pF 0.25PF 25V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	U11002	Module,Tx Module	EAT61473401	MDFE2PFA-023 10DBM 32DB 0% 0A 0A 0DB 0DBM 0DBM 16P 2.5x2.5x0.4MM 5GHz WiFi, SPDT+LNA+PA MURATA MANUFACTURING CO.,LTD.	
6	R6005	Resistor,Chip	EBC62155701	UCR03EWPFSR047 0.047OHM 1% 1/4W 1608 R/TP - ROHM CO.,LTD.	
6	C1019	Inductor Multilayer,Chip	ELCH0004707	1005GC2T1N5SLF 1.5NH 0.3NH - 300mA 0.13OHM 7GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	SW1001	Connector,RF	ENWY0005501	20279-001E-01 NONE STRAIGHT SOCKET SMD R/TP AU 50OHM 400mDB I-PEX CO., LTD	
6	FL11001	Filter,Ceramic	EAM62250401	LFB212G45CG7D227 BPF 2.45KHZ 100Hz SMD R/TP 3P MURATA MANUFACTURING CO.,LTD.	
6	U5000	IC,PMIC	EAN62216701	MAXIM77663LEWJ+T 2.6 to 5.5V adj 2.35W WLP R/TP 90P - MAXIM INTEGRATED PRODUCTS INC.	
6	X1000	Oscillator VCTCXO	EAW61443801	1XXA26000FBA 26MHZ 1PPM 1.8V 2.5x2.0x0.8MM ; SMD R/TP DAISHINKU CORPORATION.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	U1001	Filter,Duplexer	EAM62530601	B40251GY2045L - - - - - 8.6 x 3.6 x 1.0t QUAD SMD R/TP 50P KOREA TAIYO YUDEN.CO., LTD.	
6	C1033 C1036 C1046 C1059 C1084 L1038	Inductor Multilayer,Chip	ELCH0003832	LQG15HS2N2S02D 2.2NH 0.3NH - 300mA - - 0.12OHM 6GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	FB11000	Filter,Bead	EAM62230101	BLM03AX121SN1 120 ohm 0.6X0.3X0.3 25% 0.23 ohm 0.45A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	C1049 L1007	Capacitor Ceramic,Chip	ECZH0001002	C1005CH1H0R5BT000F 0.5pF 0.1PF 50V NP0 - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	C6030	Capacitor Ceramic,Chip	ECCH0034801	CL03A474MQ3NNNH 0.47uF -20TO20% 6.3V X5R -55TO+85C 0603 R/TP 0.3+-0.03 SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	U6001	IC,Over Voltage Protection	EUSY0374601	MAX14528 MAX14528 MAX14528,TDFN ,8 ,R/TP ,Programmable OVP MAXIM INTEGRATED PRODUCTS INC. MAXIM INTEGRATED PRODUCTS INC.	
6	L11044	Inductor Multilayer,Chip	EAP62108001	LQP03TG2N2C02D 2.2NH 0.2NH - 450mA - - 0.25OHM 6GHZ 13 SHIELD - 0.6X0.3X0.3MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	C6001	Capacitor Ceramic,Chip	ECCH0042301	CL10A225KA5LNNC 0.0000022F 10% 25V X5R - 55TO+85C 1608 R/TP - SAMSUNG ELECTRO- MECHANICS CO., LTD.	
6	SW1000	Connector,RF	ENWY0008701	MS-156C NONE STRAIGHT SOCKET SMD T/REEL AU 50OHM 400mDB HIROSE KOREA CO.,LTD	
6	L11002	Inductor,Multilayer, Chip	EAP61767801	LQP03TN2N4B02D 2.4NH 0.1NH - 500mA - - 0.2OHM 6GHZ 14 SHIELD NONE 0.6X0.3X0.3MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	R6008	Resistor,Chip	ERHY0035601	PMR10EZPFU10L0 0.01OHM 1% 1/2W 2012 R/TP - ROHM.	
6	LD9000	LED,Flash	EAV61694901	FCW401Z5L WHITE 3.7~4.3V 1A 160lm - 1170mW 2016 R/TP 2P - SEOUL SEMICONDUCTOR CO.,LTD	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	R5030	Resistor,Chip	ERHY0009526	MCR006YZPJ472 4.7KOHM 5% 1/20W 0603 R/TP - ROHM.	
5	SAD010000	Software,Mobile	SAD33503603	Base V10b - EUROPE NVI-IFX -	
5	EBR071700	PCB Assembly Main,SMT Top	EBR75920601	LGP895.ADEUBK 1.1 Main	
6	C1033 C1036 C1046 C1059 C1084 L1038	Inductor Multilayer,Chip	ELCH0003832	LQG15HS2N2S02D 2.2NH 0.3NH - 300mA - - 0.12OHM 6GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	EAX010000	PCB,Main	EAX64912401	LGP895.ADEUBK 1.0 FR-4 LX-BUMP 12 0.8 Main	
6	FB1001 FB11003 FB8000	Filter,Bead	EAM62071101	BLM15PD121SN1D 120 ohm 1.0X0.5X0.5 25% 0.09 ohm 1.3A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	C1001 C1002 C10026 C1003 C10057 C1008 C1009 C1010 C1011 C1012 C1021 C1024 C1042 C13001 C13010 C4018 C4033 C4042 C4044 C4051 C5031 C5035 C5036 C9006 C9007 C9009 C9012	Capacitor Ceramic,Chip	ECCH0009101	C0603X5R0J104KT00NN 0.1uF 10% 6.3V X5R - 55TO+85C 0603 R/TP - TDK CORPORATION	
6	R2011	Resistor,Chip	ERHY0040202	RC0201FR-074R7L 4.7OHM 1% 1/20W 0603 R/TP - YAGEO CORPORATION	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C14027 C14030 C14032 C2005 C2009 C2010 C2012 C2016 C2040	Capacitor Ceramic,Chip	ECCH0032801	GRM033R60J224M 0.00000022F 20% 6.3V X5R - 55TO+85C 0603 R/TP 0.3MM MURATA MANUFACTURING CO.,LTD.	
6	C10002 C10008 C10011 C10021 C10042 C10043 C10044 C10053 C1023 C1072 C13016 C4028 C6015 C6016 C6017 C6018 C6032 C8004 C8005 C8006 C9005 C9008 C9010 C9011 C9019 C9021 C9022	Capacitor Ceramic,Chip	ECCH0017301	CL03A105MQ3CSNH 0.000001F 20% 6.3V X5R - 45TO+85C 0603 R/TP - SAMSUNG ELECTRO- MECHANICS CO., LTD.	
6	C1022 C11005 C11006 C11024 C4001 C4005 C4010 C4017 C4034 C4045 C4047 C9020	Capacitor Ceramic,Chip	ECCH0017601	CL05A475MQ5NRNC 4.7uF 20% 6.3V X5R - 55TO+85C 1005 R/TP 0.5MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	R13019	Resistor,Chip	EBC61856101	RC0201JR-0722RL 22OHM 5% 1/20W 0603 R/TP - YAGEO CORPORATION	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	R1004	Resistor,Chip	ERHY0009502	MCR006YZPJ100 10OHM 5% 1/20W 0603 R/TP - ROHM.	
6	R6007 R7002	Resistor,Chip	ERHY0009516	MCR006YZPJ222 2.2KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	L7000 L7001	Inductor Multilayer,Chip	ELCH0003813	LQG15HN47NJ02D 47NH 5% - 200mA 1.15OHM 1GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	FB13000	Filter,Bead	SFBH0007101	BLM15AG121SN1D 120 ohm 1.0X0.5X0.5 25% 0.25 ohm 0.5A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	FL6001	Filter,EMI/Power	EAM62272401	ICMEF112P500MFR COMMON MODE NOISE FILTER 0HZ 0.0000000000001F 0H SMD R/TP - INNOCHIPS TECHNOLOGY	
6	L1018 L1020 L1022	Inductor,Wire Wound,Chip	ELCP0008014	MIPSZ2012D4R7 4.7UH 30% - 280mA 0.28 0.7 0.23OHM -- SHIELD 2.0X1.2X0.9 NONE R/TP FDK CORPORATION.	
6	R13029 R3012 R3020 R3023 R3049 R4022 R5020 R6002 R6014 R6018 R9004	Resistor,Chip	ERHY0009506	MCR006YZPJ104 100KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	R3061 R3062 R7004	Resistor,Chip	ERHZ0000463	MCR01MZP5J330 33OHM 5% 1/16W 1005 R/TP - ROHM.	
6	U10005 U10008	IC,LDO Voltage Regulator	EUSY0410201	BU30TD4WNVX ROHM.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	R10000 R10017 R1003 R11000 R11004 R13004 R13012 R13017 R2017 R3060 R4001 R4002 R8003 R8004 R9003	PCB ASSY,MAIN PAD SHORT	SAFP0000401	LG-LU3000 LGTBK,MAIN,A,	
6	L12000	Inductor Multilayer,Chip	ELCH0004721	1005GC2T2N2SLF 2.2NH 0.3NH - 300mA - - 0.16OHM 6GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	R14023 R14024 R14025 R14026	Resistor,Chip	ERHY0024201	RC1005F6041CS 6.04KOHM 1% 1/16W 1005 R/TP - SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	L9000	Inductor,Wire Wound,Chip	ELCP0008013	MIPSZ2012D2R2 2.2UH 30% - 700mA 0.77 0.7 0.23OHM - - SHIELD 2.0X1.2X1.0 MM NONE R/TP FDK CORPORATION.	
6	X12000	Oscillator,TCXO	EAW61824401	1XXB26000CAC 26MHZ 0.5PPM 1.8V 2.5x2.0x0.8MM _ SMD R/TP DAISHINKU CORPORATION.	
6	U12002	IC,GPS	EAN62399001	CSRG05TA03-ICJE-R GPS, Glonass, Size:3.11*2.20*0.6mm,IC WLCSP R/TP 34P CSR	
6	U13000	IC,Gate	EAN62415501	SN74AUP1T97DSFR 0~3.6V 0.000004 LEVEL SHIFTER SON-6 R/TP 6P Configurable Gate Logic TEXAS INSTRUMENTS KOREA LTD, HONGKONG BRANCH.	
6	U10003 U10006 U12001 U13001 U7003 U8000 U8005 U9002	IC,LDO Voltage Regulator	EUSY0407501	BU18TD4WNVX SSON004,4,R/TP,1.8V 150mA Single LDO,IC,LDO Voltage RegulatorIC,LDO Voltage Regulator ROHM.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	FL2000 FL2022 FL2023	Filter,EMI/Power	EAM62451701	NFM15PC105R0J3D EMI 0HZ 1uF 0H SMD R/TP 6.3V, 2A, 0.03 ohm max. MURATA MANUFACTURING CO.,LTD.	
6	C1004 C1078 C11020 C5000 C5002 C5013 C5034 C6019	Capacitor Ceramic,Chip	ECCH0007804	CL05A225MP5NSNC 2.2uF 20% 10V X5R - 55TO+85C 1005 R/TP 0.5MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	R8000 R8013 R8018	Resistor,Chip	ERHY0009518	MCR006YZPJ224 220KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	C6010	Capacitor Ceramic,Chip	ECCH0009213	GRM0335C1E6R0D 6pF 0.5PF 25V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	ZD10000 ZD10001	Diode,TVS	EDTY0012101	PESD5V0F1BL 5.5V 6V min 11V 2.5A - SOD-882 R/TP 2P 1 STC CORP.	
6	SC4007 SC4102	Connector,Terminal Block	ENZY0026801	25SMT-3645-34 1P - STRAIGHT SMD R/TP - W.L.GORE & ASSOCIATES (HK) LTD.	
6	PT2000	Thermistor,NTC	SETY0006301	NCP15XH103J03RC 10KOHM 5% 0V 0A 3.35KK SMD P/TP 1005size MURATA MANUFACTURING CO.,LTD.	
6	R10002 R15003	Resistor,Chip	ERHY0009507	MCR006YZPJ105 1MOHM 5% 1/20W 0603 R/TP - ROHM.	
6	C10009 C10041 C10052 C1079 C11009 C5001 C5008 C5009 C5010 C5011 C5014 C5015 C5019 C5026	Capacitor Ceramic,Chip	EAE62762301	CL03A105MP3NSNC 1uF 20% 10V X5R - 55TO+85C 0603 R/TP 0.33 MM - SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	R5030	Resistor,Chip	ERHY0009526	MCR006YZPJ472 4.7KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	L2000 L2001	Inductor,Wire Wound,Chip	ELCP0008007	MIPS2520D3R3M 3.3UH 30% - 400mA 0.4 1 0.12OHM - - SHIELD 2.5X2X1MM NONE R/TP FDK CORPORATION.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	R3033 R3034 R3036	Resistor,Chip	ERHY0042409	RC0201FR-0749R9L 49.9OHM 1% 1/20W 0603 R/TP - YAGEO CORPORATION	
6	X5000	Crystal	EXXY0026801	NX3215SA 32.768KHZ 20PPM 0F NONE SMD R/TP NIHON DEMPA KOGYO CO.,LTD.	
6	C1073 C1075 C13015	Capacitor Ceramic,Chip	ECCH0000198	CL05A225MQ5NSNC 2.2uF 20% 6.3V X5R - 55TO+85C 1005 R/TP . SAMSUNG ELECTRO- MECHANICS CO., LTD.	
6	Q6001	FET	EBK61952101	KTJ6131V P-CHANNEL MOSFET -30V +-20 -0.05A 40OHM 100mW VSM R/TP 3P KEC CORPORATION	
6	C1025 C1041 C1068 C11003 C11015 C11021 C11028 C11030 C11040 C11053 C5012 C5037	Capacitor Ceramic,Chip	EAE62286801	CL03A104KP3NNNC 0.0000001F 10% 10V X5R - 55TO+85C 0603 R/TP 0.3 - SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	U2000	IC,MCP,NAND	EAN62327101	H9DA1GH25HAMMR-4EM NAND/1G SDRAM/256M 1.7VTO1.95V 9.0*8.0*1.0 TR 130P NAND+DDR SDRAM FBGA 1Gb NAND(48n,1die,2KB,x16,SLC,1bit)+256Mb DDR333(44n,1die,x16) HYNIX SEMICONDUCTOR	
6	R10008 R10009	Resistor,Chip	ERHZ0000235	MCR01MZP5F2000 200OHM 1% 1/16W 1005 R/TP - ROHM.	
6	FL12002	Filter,Separator	EAM62590501	LMTP2HAA-B32 LB : 0.9max / GPS : 2.4max / GNSS : 2.8max / HB : 1.2max 35 35 Triplxer with GPS/GNSS SAW MURATA MANUFACTURING CO.,LTD.	
6	U1003	IC,MM PMIC	EUSY0264511	RF6590 CSP ,16 ,R/TP ,3B,2LDO,CSP,1.732X1.722 ,; ,IC,DC,DC Converter MICRO DEVICES, INC.	
6	R5024 R6001	Resistor,Chip	ERHY0009504	MCR006YZPJ102 1KOHM 5% 1/20W 0603 R/TP - ROHM.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	U6004	IC,Analog Switch	EAN61839701	FSA3200UMX 3.0~4.3V 30NSEC 25NSEC 0W MLP R/TP 16P 1 FAIRCHILD SEMICONDUCTOR HONG KONG LTD.	
6	R13015 R3022 R3052 R3054 R3068 R4018 R4019 R4020 R4021	Resistor,Chip	ERHY0009505	MCR006YZPJ103 10KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	C1088 C11012 C12012 C12019	Capacitor Ceramic,Chip	ECZH0000813	C1005C0G1H101JT 100pF 5% 50V C0G - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	L1055	Inductor Multilayer,Chip	ELCH0003819	LQG15HS12NJ02D 12NH 5% - 300mA - - 0.28OHM 3GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	R3032 R3037	Resistor,Chip	ERHY0009302	MCR006YZPF1001 1KOHM 1% 1/20W 0603 R/TP - ROHM.	
6	VA7000 VA7001	Varistor	SEVY0004301	ICVL0518100Y500FR 18V 0% 10F 1.0*0.5*0.55 NONE SMD R/TP INNOCHIPS TECHNOLOGY	
6	FL6000	Filter,EMI/Power	SFEY0015301	NFM18PC104R1C3 ESD/EMI 0HZ 0.1uF 0H SMD R/TP MURATA MANUFACTURING CO.,LTD.	
6	R13000 R13001 R6000 R6004 R9002	Resistor,Chip	ERHY0009527	MCR006YZPJ473 47KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	R5034	Resistor,Chip	ERHZ0000318	MCR01MZP5F8062 80.6KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	BAT5000	Capacitor Assembly	SMZY0023501	PAS311HR-VG1 3.8 Backup Capacitor 0.03F,Module Assembly, KOREA TAIYO YUDEN.CO., LTD.	
6	C7001	Capacitor Ceramic,Chip	EAE62762401	CL03A224KP3NUNC 220nF 10% 10V X5R - 55TO+85C 0603 R/TP 0.33 MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	U7000	IC,Comparator	EAN62065901	MAX14579E 2.5~5.5V 2uA COMPARATOR TDFN R/TP 8P Headset Jack Detection IC with LDO, 15kV ESD MAXIM INTEGRATED PRODUCTS INC.	
6	R13005 R13006	Resistor,Chip	ERHY0042403	RC0201JR-07130RL 130OHM 5% 1/20W 0603 R/TP - YAGEO CORPORATION	
6	FB7000 FB7001	Filter,Bead	SFBH0008105	BLM15BD182SN1D 1800 ohm 1.0X0.5X0.5 25% 1.4 ohm 0.1A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	R7015	Resistor,Chip	ERHY0009553	MCR006YZPF1004 1MOHM 1% 1/20W 0603 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	R2015 R3065	PCB ASSY,MAIN PAD OPEN	SAFO0000401	AX3100 ATL SV_SHIPBACK,MAIN,A,0OHM DNI	
6	U14000	IC,MCP,eMMC	EAN62497901	H26M64002DQR FLASH 2.7VTO3.6V,1.7VTO1.95V 12.0x16.0x1.0 TR 169P MLC NAND FBGA 32GB eMMC v4.41 (20nm 64Gb MLC x 4, SMI Controller) HYNIX SEMICONDUCTOR	
6	L12001	Inductor Multilayer,Chip	ELCH0001048	1005GC2T10NJLF 10NH 5% - 250mA 0.42OHM 2.5GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	U6007	IC,Temperature Sensor	EUSY0426201	NCT1008 DFN,8,R/TP,Remote Temperature Sensor,IC,A/D Converter - DFN R/TP 8P - ON SEMICONDUCTOR	
6	U6003	IC,MUIC	EUSY0371201	MAX14526EEWP+TCC6 MAX14526EEWP+TCC6,WLP,MUIC for 5Pin Micro USB WLP R/TP 20P MAXIM INTEGRATED PRODUCTS INC.	
6	R1002	Resistor,Chip	ERHY0009503	MCR006YZPJ101 100OHM 5% 1/20W 0603 R/TP - ROHM.	
6	U8003	IC,Serializer/Deserializer	EAN62222401	SSD2825G44R RGB To DSI 4lane BGA R/TP 64P SOLOMON SYSTECH LTD	
6	R3000 R3001 R3002 R3003 R3006 R3007	Resistor,Chip	ERHY0009586	MCR006YZPF2201 2.2KOHM 1% 1/20W 0603 R/TP - ROHM.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	FB12000 FB12001 FB2000 FB2001	Filter,Bead	EAM62150301	CIM05J600NC 60 ohm 1.0X0.5X0.5 25% 0.2 ohm 0.65A SMD R/TP 2P 0 SAMSUNG ELECTRO- MECHANICS CO., LTD.	
6	U10001 U5002	IC,LDO Voltage Regulator	EUSY0407201	BU33TD4WNVX SSON004,4,R/TP,3.3V 150mA Single LDO,IC,LDO Voltage RegulatorIC,LDO Voltage Regulator ROHM.	
6	R5032	Resistor,Chip	ERHZ0000537	MCR01MZP5F6803 680KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	C10014 C1069 C1071 C9023 C9024	Capacitor Ceramic,Chip	ECCH0007803	CL10A106MP8NNNC 10uF 20% 10V X5R - 55TO+85C 1608 R/TP 0.8MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	U3000	IC,Application Processor	EAN62344601	AP33-R-Z-A3 AP33,681PIN,CortexA9,1.5GHz,4Core,36MP,HD10 80P,3D,IC,Digital SignalProcessors BGA R/TP 681P NVIDIA CORP	
6	L1021 L1023	Inductor Multilayer,Chip	ELCH0009105	0402CS-18NXJEW 18NH 5% - 420mA 0.23OHM 3.1GHZ 25 NON SHIELD NONE 1.19X0.64X0.66MM R/TP COILCRAFT SINGAPORE PTE LTD.	
6	U10007	IC,Gyro Sensor	EAN62409401	MPU-6050 Accelerometer embedded Gyro Sensor 4X4 QFN R/TP 24P One Chip Solution INVENSENSE	
6	C5018 C5021 C5023	Capacitor Ceramic,Chip	ECCH0017501	CL10A226MQ8NRNE 22uF 20% 6.3V X5R - 55TO+85C 1608 R/TP 0.8MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C12004	Capacitor Ceramic,Chip	ECCH0009216	GRM0335C1E220J 22pF 5% 25V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C11011 C4003 C4007 C4012 C4013 C4015 C4025 C4027 C4048 C4050 C5027 C5028	Capacitor Ceramic,Chip	ECCH0005604	GRM188R60J106M 10000000 pF,6.3V,M,X5R,TC,1608,R/TP,0.8 mm MURATA MANUFACTURING CO.,LTD.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	FL1000	Filter,Saw	SFSY0035004	B9469 2140 MHz,1.4*1.1*0.45,SMD,2110M~2170M,IL 2.5,5pin,U-B,50-100,BAND I DIVERSITY,2140MHz,1.4*1.1*0.45,SMD,R/TP EPCOS PTE LTD.	
6	FB14000 FB14001	Filter,Bead	SFBH0008101	BLM15AG601SN1D 600 ohm 1.0X0.5X0.5 25% 0.6 ohm 0.3A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	C7008	Capacitor Ceramic,Chip	EAE62502901	CL05A106MP5NUNC 10uF 20% 10V X5R - 55TO+85C 1005 R/TP 0.55T max. SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C1064 C1065	Capacitor Ceramic,Chip	ECCH0006201	C1608X5R0J475KT000N 4.7uF 10% 6.3V X5R - 55TO+85C 1608 R/TP - TDK CORPORATION	
6	U2001	IC,Digital Baseband Processor,3G	EUSY0432001	PMB9811 1.7VTO2V,1.7VTO2V,1.7VTO2V 100mW 300P - BGA P/TP 300P INFINEON TECHNOLOGIES (ASIA PACIFIC) PTE LTD.	
6	Q2000	FET,Array	EBK61693301	SSM6L39TU N/P-CHANNEL 20 +-10 1.6 0.139(0.294) 0.5 SOT363 R/TP 6P 2 TOSHIBA ELECTRONICS KOREA CORPORATION	
6	U7001	IC,Audio Codec	EAN62114201	MAX98089 1.65~5.5V 2.05W WLP R/TP 63P nVidia AP30 Reference Codec MAXIM INTEGRATED PRODUCTS INC.	
6	L12005	Inductor Multilayer,Chip	ELCH0005003	HK1005 12NJ 12NH 5% - 300mA 0.4OHM 2.7GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP TAIYO YUDEN CO.,LTD	
6	CN6001	Connector,I/O	EAG63149901	04-5161-005-101-868+ 5P 0.50MM STRAIGHT RECEPTACLE DIP R/TP Reverse type(New IO) KYOCERA ELCO KOREA SALES CO.,LTD.	
6	R10010 R10011 R5031	Resistor,Chip	ERHY0009537	MCR006YZPF1503 150KOHM 1% 1/20W 0603 R/TP - ROHM.	
6	U14001	IC,Mobile SDRAM	EAN62529201	H9TCNNN8JDMMPR-NGM 8GBIT LPDDR2 38nm 4Gbit Die 2 Stack / 1-Channel / x32 1.7VTO1.95V 533MHz 0 FBGA TR 134P 8Gb LPDDR2 134FBGA 533MHz (38nm 4Gb x 2, 11.5x11.0x1.0, 134ball, 1Ch/2CS) HYNIX SEMICONDUCTOR	
6	C12017	Capacitor Ceramic,Chip	ECCH0033301	GRM1555C1H680F 68pF 1% 50V C0G - 55TO+125C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	R12002	Resistor,Chip	ERHZ0000310	MCR01MZP5F6800 680OHM 1% 1/16W 1005 R/TP - ROHM.	
6	FB1000	Filter,Bead	EAM62070801	BLM15EG221SN1D 220 ohm 1.0X0.5X0.5 25% 0.28 ohm 0.7A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	U5001	IC,Resistive Touch Screen Controller	EUSY0337101	TSC2007IYZGR TSC2007IYZGR TSC2007IYZGR,CSP ,12 PIN,R/TP ,Touchscreen Controller IC , ,IC,A/D Converter TEXAS INSTRUMENTS KOREA LTD, HONGKONG BRANCH. TEXAS INSTRUMENTS KOREA LTD, HONGKONG BRANCH.	
6	C6030	Capacitor Ceramic,Chip	ECCH0034801	CL03A474MQ3NNNH 0.47uF -20TO20% 6.3V X5R -55TO+85C 0603 R/TP 0.3+-0.03 SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C10010 C1026	Capacitor Ceramic,Chip	ECZH0025920	GRM033R71C102K 1nF 10% 16V X7R -55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	L8000	Inductor,Wire Wound,Chip	EAP62106301	1239AS-H-100N=P2 10UH 30% 30V 700mA 1 0.7 0.46OHM - - SHIELD 2.5X2.0X1.2MM NONE R/TP TOKO, INC.	
6	C6024	Capacitor Ceramic,Chip	ECCH0000115	MCH155A220JK 22pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	C11007 C11008 C11010 C6005 C6013	Capacitor Ceramic,Chip	EAE62506501	CL05A475MP5NRNC 4.7uF 20% 10V X5R -55TO+85C 1005 R/TP - - SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C10051	Capacitor,Ceramic, Chip	ECCH0000147	MCH155CN222KK 2.2nF 10% 50V X7R -55TO+125C 1005 R/TP - ROHM.	
6	U10002	IC,Signal Bridge	EAN62095001	SII9244 MHL-to-HDMI bridge,3.5x3.5, 1 MHz, 5 pin BGA R/TP 49P Silicon Image International BV	
6	R3027	Resistor,Chip	ERHZ0000270	MCR01MZP5F33R0 33OHM 1% 1/16W 1005 R/TP - ROHM.	
6	C6025	Capacitor Ceramic,Chip	EAE62505701	CL10A105KB8NNNC 1uF 10% 50V X5R -55TO+85C 1608 R/TP 0.9T max. - SAMSUNG ELECTRO-MECHANICS CO., LTD.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C1000 C1005 C1006 C1007	Capacitor Ceramic,Chip	ECCH0009201	GRM033R60J473KE19D 47nF 10% 6.3V X5R - 55TO+85C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	R2012	Resistor,Chip	ERHY0042405	RC0201FR-074K02L 4.02KOHM 1% 1/20W 0603 R/TP - YAGEO CORPORATION	
6	ZD6000	Diode,TVS	EAH61872601	PESD12VS1UA 12V 13.3V min. 19V 22.5A 360mW SOD323 R/TP 2P 1 NXP Semiconductors	
6	C12001	Capacitor Ceramic,Chip	ECCH0009104	C0603C0G1H330JT00NN 33pF 5% 50V C0G - 55TO+125C 0603 R/TP - TDK CORPORATION	
6	C1083	Inductor Multilayer,Chip	ELCH0001041	HK1005 10NJ-T 10NH 5% - 250mA 0.31OHM 3.2GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP TAIYO YUDEN CO.,LTD	
6	U8004	IC,LDO Voltage Regulator	EUSY0397901	BU12TD2WNVX SSON,4,R/TP,1.2V 150mA Single LDO,IC,LDO Voltage RegulatorIC,LDO Voltage Regulator ROHM.	
6	R6020	Resistor,Chip	ERHY0009513	MCR006YZPJ184 180KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	U13003 U2002	IC,Analog Switch	EUSY0186504	FSA2259UMX QFN ,8 ,R/TP ,Dual SPDT ,; ,IC,Analog Switch FAIRCHILD SEMICONDUCTOR	
6	C10039 C1030 C1044 C1061 C13003 C6008 C6014	Capacitor Ceramic,Chip	ECCH0009106	C0603X7R1C103KT 10nF 10% 10V X7R - 55TO+125C 0603 R/TP - TDK CORPORATION	
6	D7000 D7001	Diode,TVS	EAH61634001	ESD7951ST5G 5V 5.4V min. 12.9V 1A 150mW 1A R/TP 2P 1 ON SEMICONDUCTOR	
6	L1027 L1028	Capacitor Ceramic,Chip	ECCH0000901	C1005C0G1H2R2CT000F 2.2pF 0.25PF 50V NP0 - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	C7020	Capacitor Ceramic,Chip	ECZH0001120	CC1005X7R1H392KT000F 3.9nF 10% 50V X7R - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	R14016	Resistor,Chip	EBC61856201	RC0201FR-07240RL 240OHM 1% 1/20W 0603 R/TP - YAGEO CORPORATION	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	L1050 L1051	Capacitor Ceramic,Chip	EAE62764401	C1005NPO100DGTQ 10pF 0.5PF 50V C0G - 55TO+125C 1005 R/TP 0.55T max. DARFON ELECTRONICS CORP.	
6	U12003	IC,RF Amplifier	EAN62093001	ALM-3012 2.7 0 0 0W 0W 0 0 COB R/TP 8P Gain 17.5/ NF 1.02 AVAGO TECHNOLOGIES INTERNATIONAL SALES PTE. LIMITED	
6	U7002	IC,Motor Driver	EAN61968701	ISA1200 2.4~3.6V 3.3V 95W UQFN R/TP 18P - Auto Haptic Imagis Co.,Ltd.	
6	C10027 C10028 C11001 C11002 C11004 C11025 C11056 C11061 C11062 C11063 C11064 C6009	Capacitor Ceramic,Chip	ECCH0009514	MCH032A(AN)100DK 10pF 0.5PF 25V X7R - 55TO+125C 0603 R/TP - ROHM.	
6	D8000	Diode,Switching	EDSY0011901	SDB310Q 340mV 30V 200mA 1A 0SEC 150mW EMD2 R/TP 2P 1 AUK CORP	
6	U8001	IC,DC,DC Converter	EAN62410501	LM3533TMX-40 2.7 to 5.5V adj 0W CSP R/TP 20P - NATIONAL SEMICONDUCTOR ASIA PACIFIC PTE. LTD.	
6	R3042	Resistor,Chip	ERHZ0000211	MCR01MZP5F1201 1.2KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	X3000	Crystal	EXXY0027401	X1E000021043400 26MHZ 10PPM 0F NONE SMD R/TP EPSON TOYOCOM CORP	
6	VA5001	Varistor	SEVY0003601	ICVL0505101V150FR 5.6V 0% 100pF 1.0*0.5*0.55 NONE SMD R/TP INNOCHIPS TECHNOLOGY	
6	R13024	Resistor,Chip	ERHZ0000517	MCR01MZP5J910 91OHM 5% 1/16W 1005 R/TP - ROHM.	
6	R7017	Resistor,Chip	ERHY0009303	MCR006YZPF1002 10KOHM 1% 1/20W 0603 R/TP - ROHM.	
6	L1014	Inductor Multilayer,Chip	ELCH0001031	HK1005 15NJ-T 15NH 5% - 300mA 0.46OHM 2.3GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP TAIYO YUDEN CO.,LTD	
6	R3035	Resistor,Chip	ERHY0039802	RC0402FR-07453RL 453OHM 1% 1/16W 1005 R/TP - YAGEO CORPORATION	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	R3011	Resistor,Chip	ERHZ0003601	MCR01MZSF2004 2MOHM 1% 1/16W 1005 R/TP - ROHM.	
6	U6005	IC,Analog Switch	EAN61828001	FSUSB104 3.0~4.3V 30NSEC 25NSEC 1W MLP R/TP 10P 1 FAIRCHILD SEMICONDUCTOR	
6	U9000	IC,MM PMIC	EUSY0227205	LP8720TLX 2.7 To 5.5V Adj 1.2W CSP R/TP 20P - NATIONAL SEMICONDUCTOR ASIA PACIFIC PTE. LTD.	
6	C5029 C5030	Capacitor Ceramic,Chip	ECCH0042007	GRM0335C1E6R8BD01D 6.8 pF,25V,B,C0G,TC,0603,R/TP,0.00000000000068,0.1PF,25V,C0G,-55TO+125C,0603,R/TP,0.3 mm MURATA MANUFACTURING CO.,LTD.	
6	Q13000	TR,Bipolar	EQBN0013701	NPN 6V 15V 12V 500mA 100mA 680 150mW EMT6 R/TP 6P	
6	C10033 C10036 C1032 C1034 C1037 C1045	Capacitor Ceramic,Chip	ECZH0000830	C1005C0G1H330JT000F 33pF 5% 50V NP0 - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	FL1002	Filter,Saw	SFSY0040602	B9461 942.5MHz 1.4*1.1*0.45 SMD R/TP 5P EPCOS PTE LTD.	
6	C12018	Capacitor,Ceramic,Chip	ECCH0000183	GRM1555C1H1R8C 1.8pF 0.25PF 50V NP0 - 55TO+125C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
2	EAD010000	Cable,Assembly	EAD62150402	LG0069 USB USB 1.2M 5 BLACK UL N ningbo broad telecommunication co.,ltd	
2	EAA040000	Antenna Assembly	EAA62749901	LS04-I-11109-A0-NFC_tag LGF120S.ASKTBK Black Black Black Tag FPCB Tape LS Mtron Ltd.	
3	EAA030100	PIFA Antenna,RF	EAA62769401	LS01-I-11098-A0 SINGLE -2DB 5.0 FPCB Type - Tag Tape LS Mtron Ltd.	
3	EAA030102	PIFA Antenna,RF	EAA62769403	LS01-I-11100-A0 SINGLE -2DB 5.0 FPCB Type - LS Mtron Ltd.	
3	EAA030101	PIFA Antenna,RF	EAA62769402	LS01-I-11099-A0 SINGLE -2DB 5.0 FPCB Type - LS Mtron Ltd.	

13. EXPLODED VIEW & REPLACEMENT PART LIST

13.3 Accessory

Note: This Chapter is used for reference, Part order is ordered by SBOM standard on GCSC

Level	LocationNo.	Description	PartNumber	Spec	Remark
2	MFL053800	Manual, Operation	MFL67684805	PRINTING LGP895.AFRABK ZZ:Without Color France FRENCH -	
2	EAY060000	Adapters	EAY62769002	MCS-01ER 90Vac~264Vac 4.75Vdc~5.25Vdc (At the end of USB socket) 1.2A 50/60Hz CE WALL 2P USB - SUNLIN ELECTRONICS CO.,LTD	
2	EAB010200	Earphone, Stereo	EAB62491011	EMB-LGE019STKC-2 20mW 32OHM 98DB 20HZ TO 20KHZ 1.15M BLACK 4 POLE PLUG - CRESYN CO.,LTD	
2	AFN053800	Manual Assembly Operation	AFN75894805	LGP895.AFRABK ZZ:Without Color -	
3	MBM068900	Card, Service Guide	MBM63799205	PRINTING LGP895.AFRABK ZZ:Without Color -	
3	MBM087200	Card, Warranty	MCDF0010001	PRINTING LGP920.AFRAML ZZ:Without Color Warranty card for France	